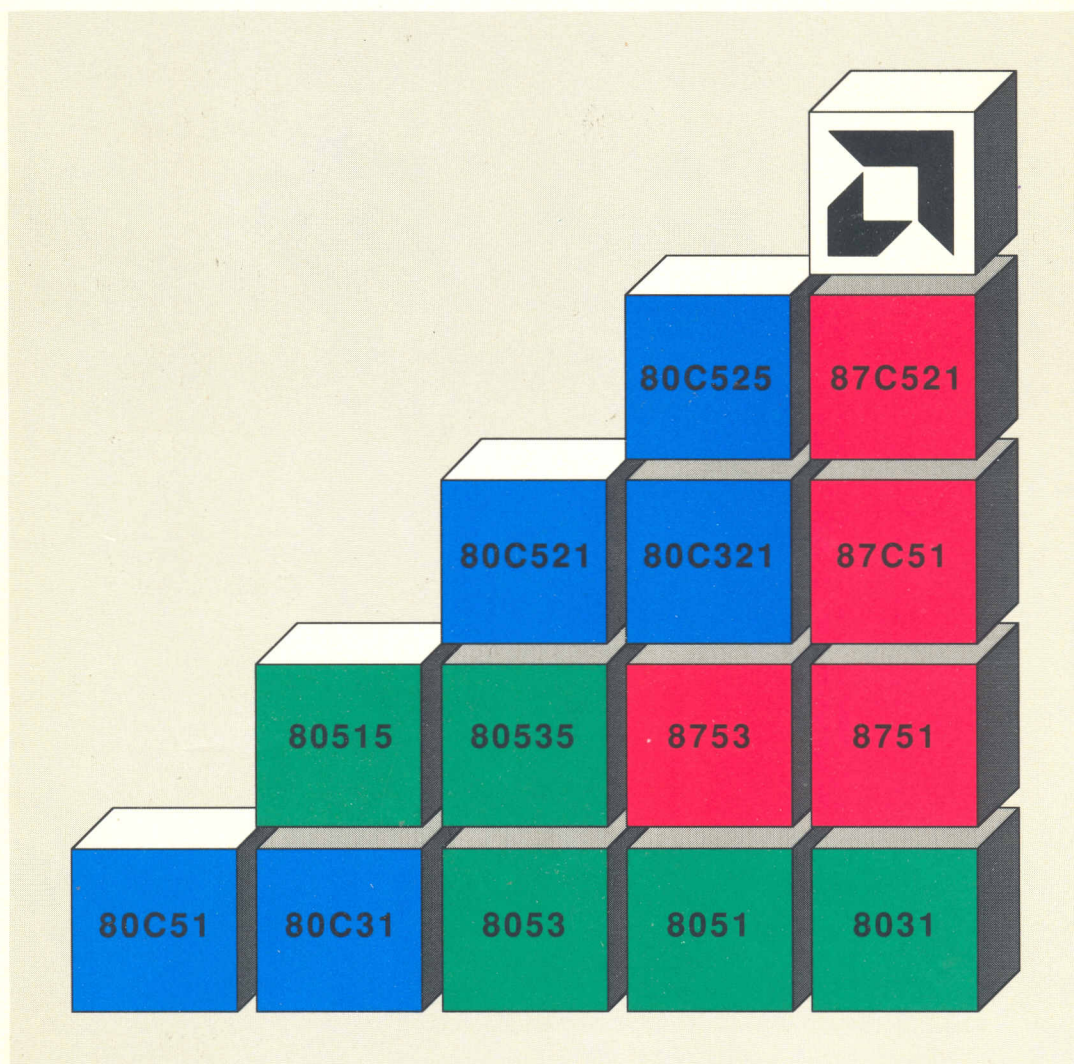




Microcontrollers

1988 Data Book/Handbook

Advanced
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Devices





Advanced Micro Devices

Microcontroller Handbook

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Microcontroller Handbook

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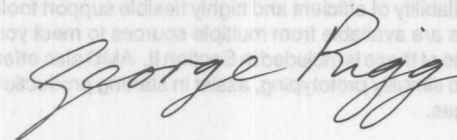
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Advanced Micro Devices provides a wide variety of innovative products. Microcontrollers are no exception. Based on the widely used 8051 family, AMD's 8-bit microprocessor family provides the performance, availability and price you need to bring advanced systems to market.

AMD brings you innovative products and the important support tools to make your job simpler. Our EPROM versions, documentation, development support information and software simplify design and shorten the system-to-market cycle. Much of this information is included in this handbook.

If you need more information or want to investigate new product introductions in this family, call your nearest AMD sales office, representative or distributor.



George Rigg
Vice President
Processor Products Division
Advanced Micro Devices

Preface

This handbook offers complete information on the wide variety of microcontroller products from Advanced Micro Devices. AMD desires not only to offer you the best product, but also the necessary documentation and support tools you require.

Advanced Micro Devices' commitment to the 8051 Family of microcontrollers continues to grow. The most recent introductions include the CMOS 80C521 and the 80515. The 80C521 contains double the ROM and RAM of the 80C51 core device, a programmable Watchdog Timer and Dual Data Pointers. The 80515 features an on-chip analog-to-digital converter and pulse-width modulation capability.

A key to the success of the 8051 Family is the availability of efficient and highly flexible support tools. Excellent emulators, compilers, and programmers are available from multiple sources to meet your individual requirements. A brief description of some of these is included in Section II. AMD also offers compatible EPROM versions of the 8051 Family to simplify prototyping, assist in starting production, or to provide a tool for immediate program changes.

SECTION I

This section contains general information on the 8051 Family of devices and serves as a "core" that is useful for designing with all of AMD's microcontrollers. The term "8051" refers to the entire line of 8051-based microcontrollers, each executing an identical instruction set. The device name "8051AH" refers specifically to the NMOS 8051AH device.

SECTION II

This section focuses on specific products, and includes data sheets, device-specific application information and software routines. The data sheets emphasize features unique to the device and do not generally repeat information common to the entire 8051 Family.

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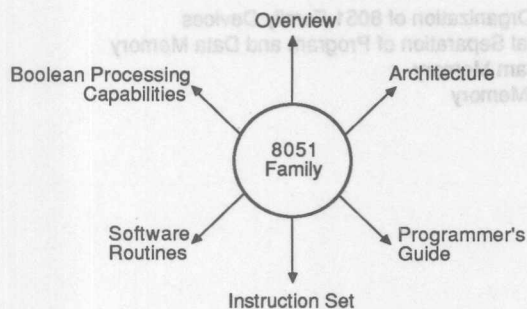


8051 Architectural Description

Section I presents “core” information applicable to all members of the 8051 Microcontroller Family. In Chapter 1, each member is discussed briefly; an in-depth description of the family’s memory organization follows. The information flows naturally into chapters on archi-

ture, programming, the instruction set, software routine, and Boolean processing capabilities.

As AMD adds more devices to the 8051 Family, this section will continue to serve as a one-stop reference for both hardware and software designers.



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CHAPTER 1

8051 Family Overview

1-1

Members of the Family

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8051AH/8031AH/8751H

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8053AH/8753H/8052/80C52T2/80C32T2

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Memory Organization of 8051 Family Devices

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Logical Separation of Program and Data Memory

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Program Memory

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MEMBERS OF THE FAMILY

The block diagram illustrates the architecture of the 8087A-1 microprocessor system. A dashed rectangle encloses the core components: the CPU, ROM/EPROM, RAM, and TWO 16-BIT TIMER/EVENT COUNTERS. The CPU is connected to the ROM/EPROM and RAM via bidirectional data buses. The TWO 16-BIT TIMER/EVENT COUNTERS are connected to the CPU and receive input from COUNTERS. The CPU is also connected to an OSCILLATOR & TIMING block, which provides a FREQUENCY REFERENCE. The CPU receives INTERRUPTS and sends INTERRUPTS. The CPU is connected to a 64K BYTE BUS EXPANSION CONTROL block, which in turn connects to a PROGRAMMABLE I/O block. The PROGRAMMABLE I/O block is connected to the CPU and provides PARALLEL PORTS ADDRESS DATA BUS AND I/O PINS. The PROGRAMMABLE I/O block is also connected to a PROGRAMMABLE SERIAL PORT, which includes a FULL DUPLEX UART and a SYNCHRONOUS SHIFTER. The PROGRAMMABLE SERIAL PORT is connected to SERIAL IN and SERIAL OUT lines. The 64K BYTE BUS EXPANSION CONTROL block is connected to a CONTROL line.

Figure 1-1. Architectural Structure of the 8051 Family

Table 1-1. AMD's 8051 Family Products

Device	Type	Internal Memory			Timers (16-bit)	Other Enhanced Features
		ROM (bytes)	EPROM (bytes)	RAM (bytes)		
8031AH	NMOS	—	—	128	2	—
8051AH	NMOS	4K	—	128	2	—
8053AH	NMOS	8K	—	128	2	—
8751H	NMOS	—	4K	128	2	—
8753H	NMOS	—	8K	128	2	—
80515	NMOS	8K	—	256	3	YES
80535	NMOS	—	—	256	3	YES
80C31BH	CMOS	—	—	128	2	—
80C51BH	CMOS	4K	—	128	2	—
87C51	CMOS	—	4K	128	2	—
80C32T2	CMOS	—	—	256	2	—
80C52T2	CMOS	8K	—	256	2	—
80C321	CMOS	—	—	256	2	YES
80C521	CMOS	8K	—	256	2	YES
80C541	CMOS	16K	—	256	2	YES
87C521	CMOS	—	8K	256	2	YES
87C541	CMOS	—	16K	256	2	YES
80C525	CMOS	8K	—	256	2	YES
87C525	CMOS	—	8K	256	2	YES

8051AH/8031AH/8751H

The 8051AH is the basic NMOS member of the 8051 Family of single-chip microcontrollers. It provides hardware features and instructions that make it a powerful and cost-effective controller for use in computation, communication, industrial and consumer applications. It includes the following features:

- 8-bit CPU optimized for control applications
- 4K bytes of on-chip Program Memory
- 128 bytes of on-chip Data Memory
- Two 16-bit Timer/Counters
- Full duplex UART
- 5-source interrupt structure with two priority levels
- On-chip oscillator
- Boolean processor
- Bit-addressable RAM
- 64K Program-Memory space
- 64K Data-Memory space

The 8031AH is identical to the 8051AH except that it does not have the on-chip program ROM. Instead, the 8031AH fetches all instructions from external program

memory. The 8751H replaces the on-chip program memory with 4K bytes of EPROM. EPROM versions make excellent prototyping tools, and are also useful in production because they allow immediate program changes to be made in a new product. If the 8031AH device is used, the prototyping may be accomplished with an external EPROM.

8053AH/8753H/8052/80C52T2/80C32T2

The 8053AH is identical to the 8051AH, except that it contains 8K bytes of on-chip program ROM. The 8753H is the EPROM version of the 8053AH that contains 8K bytes of on-chip EPROM memory. Both devices are fully pin-compatible with the 8051AH, making upgrading easy.

The "8052" architecture referred to in this manual is an 8051 with 8K bytes of ROM, 256 bytes of RAM, and a third timer. AMD does not produce an 8052; however, if only extra ROM is required, the 8053AH is a more cost-effective solution. If extra RAM is also required the 80C52T2 can be used. If the third timer is also required, the 80515 will fit the bill, since it is a superset of the 8052.

The 80C52T2 is a CMOS 8052 with two rather than three timers. It is pin-compatible and function-compatible with the 80C52 as long as the third timer is not used. The 80C32T2 is the ROM-less version of the 80C52T2.

80515/80535

The 80515, an enhanced version of the 8051AH, offers the following additional features:

- 8K bytes of on-chip ROM
- 256 bytes of on-chip RAM
- Three timer/counters
- 8-bit A/D converter
- Two additional ports
- Watchdog Timer

Because of the A/D converter, the 80515 is ideal for motor control applications ranging from automotive engines to vending machines. The additional timer has excellent PWM capability with four capture/compare registers. The two additional ports are useful to regain the ports lost when external memory is used. The watchdog timer also adds dependability to the system design. The 80535 is the ROM-less version of the 80515.

80C51BH/80C31BH/87C51

The 80C51BH is a CMOS version of the 8051AH, offering approximately 80% less power consumption and faster operating speeds. In addition to the power savings during normal operation, the 80C51BH offers idle and power-down modes. In the idle mode, the CPU is turned off while the RAM and other on-chip peripherals continue to operate. Current draw is typically 15% of the current draw when the device is fully active. In the power-down mode, all on-chip activities are suspended while the RAM holds its data. In this mode, the device typically draws less than 10 μ A.

The 80C51BH and 8051AH are functionally compatible. The 80C31BH is identical to the 80C51BH except that it contains no on-chip ROM. The 87C51 is the EPROM version of the 80C51BH. Further information on the distinctions between the CMOS and NMOS 8051 Family members may be found in chapter 9 (page 9-25): Designing with the 80C51BH.

80C521/80C321/87C521/80C541/87C541

The 80C521 is an enhanced version of the 80C51. Its additional features include the following:

- 8K bytes of on-chip ROM
- 256 bytes of on-chip RAM
- Programmable Watchdog Timer
- Dual Data Pointers
- Software Reset

The 80C521 is pin-compatible and function-compatible with the 80C51. The Programmable Watchdog Timer is specially designed to be both flexible and dependable. It provides needed protection from the effects of electrostatic discharge (ESD), external noise, unexpected external events or program input conditions, and programming anomalies. The Dual Data Pointers facilitate external memory operations such as block moves, saving both time and code space. The 80C321 is the ROM-less version of the 80C521. The 87C521 is the EPROM version of the 80C521, and contains special options for additional Watchdog Timer reliability. The 80C541 is identical to the 80C521 except that it contains 16K bytes of ROM. The 87C541 replaces the 80C541 ROM with 16K bytes of EPROM.

80C525/87C525

The 80C525, an enhanced version of the 80C521, offers the following additional features:

- Slave Interface with
 - 16 bytes of Dual-port RAM
 - Two 20-byte FIFOs
 - Programmable Maskable Address Recognizer
 - General Purpose Interrupt
- Bus Arbitration Unit
- Two and one-half additional ports when the slave interface is not used
- Three additional interrupt sources

The 80C525 excels at processor-to-processor communication. The slave interface allows efficient transfers of data between the 80C525 and an external processor or DMA controller. The bus arbitration unit allows the 80C525 to share its local bus with other bus masters. Also, the part may also function as an 80C521 with two and one-half additional on-chip ports. The 87C525 is the 8K byte EPROM version of the 80C525.

MEMORY ORGANIZATION IN 8051 FAMILY DEVICES

Logical Separation of Program and Data Memory

All 8051 Family devices have separate address spaces for program and Data Memory, as shown in Figure 1-2. The logical separation of Program and Data Memory allows the Data Memory to be accessed by 8-bit addresses, which can be more quickly stored and manipulated by an 8-bit CPU. Nevertheless, 16-bit Data Memory addresses can also be generated through the DPTR register.

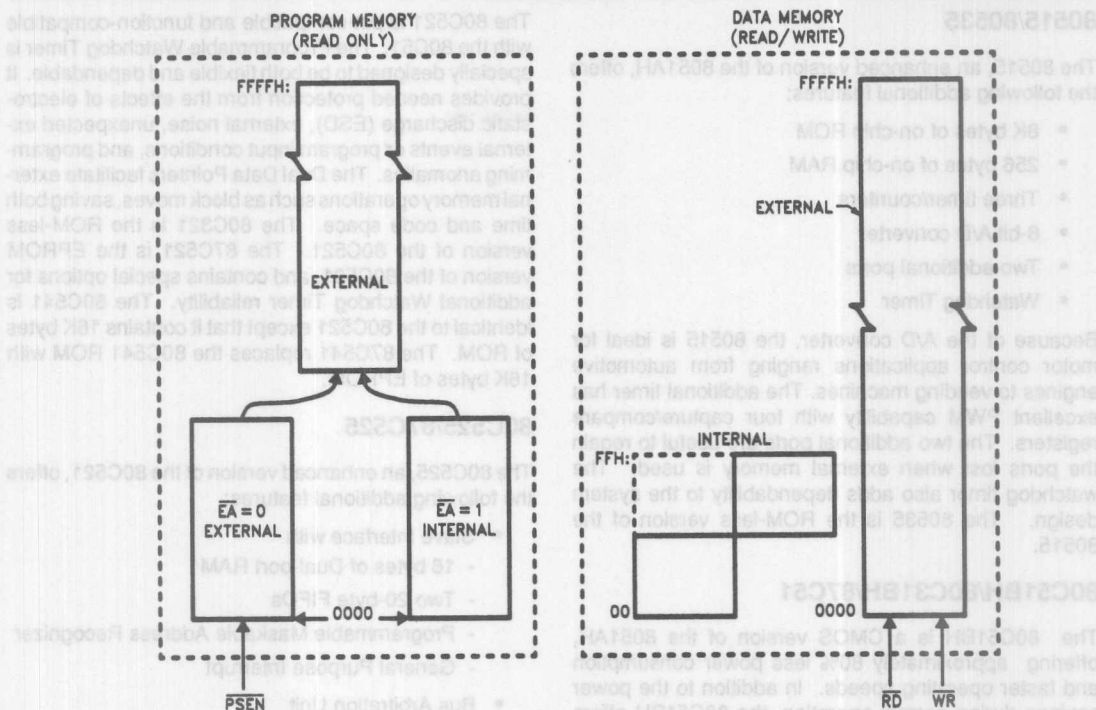


Figure 1-2. 8051 Memory Structure

Program Memory can only be read, not written to. There can be up to 64K bytes of Program Memory. In the 8051AH, 80C51BH, and their EPROM versions, the lowest 4K bytes of Program Memory are on-chip. The read strobe for external Program Memory is the signal PSEN (Program Store Enable).

Data memory occupies a separate address space from Program Memory. Up to 64K bytes of external RAM can be addressed in the external Data Memory space. The CPU generates read and write signals, RD and WR as needed during external Data Memory accesses.

External Program Memory and external Data Memory may be combined if desired by applying the RD and PSEN signals to the inputs of an AND gate and using the output of the gate as a read strobe to the external Program/Data Memory.

Program Memory

Figure 1-3 shows a map of the lower part of Program Memory. After reset, the CPU begins execution from location 0000H.

As shown in Figure 1-3, each interrupt is assigned a fixed location in Program Memory. The interrupt causes the

CPU to jump to that location, where it commences execution of the service routine. External Interrupt 0, for example, is assigned to location 0003H. If External Interrupt 0 is going to be used, its service routine must begin at location 0003H. If the interrupt is not going to be used, its service location is available as general purpose Program Memory.

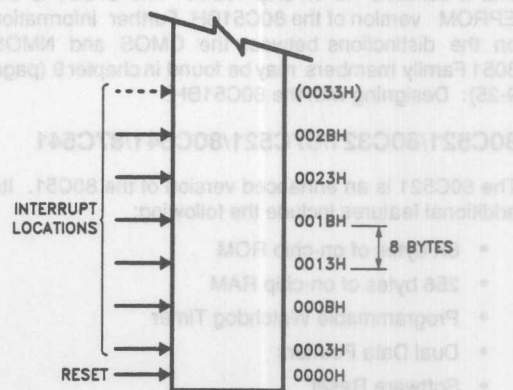


Figure 1-3. 8051 Program Memory

Interrupt service locations are spaced at 8-byte intervals: 0003H for External Interrupt 0, 000BH for Timer 0, 0013H for External Interrupt 1, 001BH for Timer 1, etc. If an interrupt service routine is short enough (as is often the case in control applications), it can reside entirely within that 8-byte interval. Longer service routines can use a jump instruction to skip over subsequent interrupt locations, if other interrupt locations are in use.

The lowest 4K (or 8K in the 8053AH) bytes of Program Memory can be either in the on-chip ROM or in an external ROM. This selection is made by strapping the EA (External Access) pin to either V_{CC} or V_{SS} .

In the 8051, if the \overline{EA} pin is strapped to V_{CC} , then program fetches to addresses 0000H through 0FFFFH are directed to the internal ROM. Program fetches to addresses 1000H through FFFFH are directed to external ROM.

In the 8053AH, $\overline{EA} = V_{CC}$ selects addresses 0000H through 1FFFFH to be internal, and addresses 2000H through FFFFH to be external.

If the \overline{EA} pin is strapped to V_{SS} , then all program fetches are directed to external ROM. The ROMless parts must have this pin externally strapped to V_{SS} to enable them to execute from external Program Memory.

The read strobe to external ROM, \overline{PSEN} , is used for all external program fetches. \overline{PSEN} is not activated for internal program fetches.

The hardware configuration for external program execution is shown in Figure 1-4. Note that 16 I/O lines (Ports 0 and 2) are dedicated to bus functions during external Program Memory fetches. Port 0 (P0 in Figure 1-4) serves as a multiplexed address/data bus. It emits the low byte of the Program Counter (PCL) as an address,

and then goes into a float state awaiting the arrival of the code byte from the Program Memory. During the time that the low byte of the Program Counter is valid on P0, the signal ALE (Address Latch Enable) clocks this byte into an address latch. Meanwhile, Port 2 (P2 in Figure 1-4) emits the high byte of the Program Counter (PCH). Then \overline{PSEN} strobes the EPROM and the code byte is read into the microcontroller.

Program Memory address are always 16 bits wide, even though the actual amount of Program Memory used may be less than 64K bytes. External Program execution sacrifices two of the 8-bit ports, P0 and P2, to the function of addressing the Program Memory.

Data Memory

The right half of Figure 1-2 shows the internal and external Data Memory spaces available to the 8051 Family user.

Figure 1-5 shows a hardware configuration for accessing up to 2K bytes of external RAM. The CPU in this case is executing from internal ROM. Port 0 serves as a multiplexed address/data bus to the RAM, and 3 lines of Port 2 are being used to page the RAM. The CPU generates RD and WR signals as needed during external RAM accesses.

There can be up to 64K bytes of external Data memory. External Data Memory addresses can be either 1 or 2 bytes wide. One-byte addresses are often used in conjunction with one or more other I/O lines to page the RAM, as shown in Figure 1-5. Two-byte addresses can also be used, in which case the high address byte is emitted at Port 2.

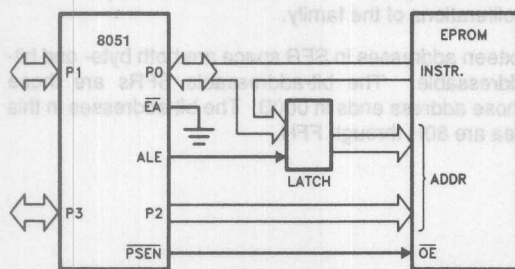


Figure 1-4. Executing from External Program Memory

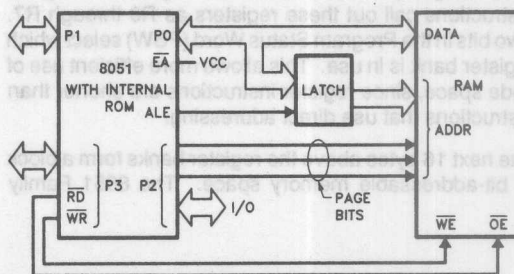


Figure 1-5. Accessing External Data Memory.
If the Program Memory is Internal, the Other Bits of P2 are Available as I/O

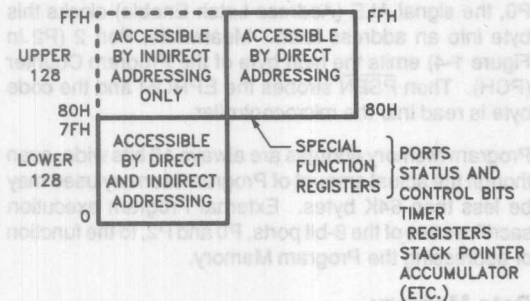


Figure 1-6. Internal Data Memory

Internal Data Memory is mapped in Figure 1-6. The memory space is shown divided into three blocks, which are generally referred to as the Lower 128, the Upper 128, and SFR space.

Internal Data Memory addresses are always one byte wide, which implies an address space of only 256 bytes. However, the addressing modes for internal RAM can in fact accommodate 384 bytes, using a simple trick. Direct addresses higher than 7FH access one memory space, and indirect addresses higher than 7FH access a different memory space. Thus Figure 1-6 shows the Upper 128 and SFR space occupying the same block of addresses, 80H through FFH, although they are physically separate entities.

The Lower 128 bytes of RAM are present in all 8051 Family devices as mapped in Figure 1-7. The lowest 32 bytes are grouped into 4 banks of 8 registers. Program instructions call out these registers as R0 through R7. Two bits in the Program Status Word (PSW) select which register bank is in use. This allows more efficient use of code space, since register instructions are shorter than instructions that use direct addressing.

The next 16 bytes above the register banks form a block of bit-addressable memory space. The 8051 Family

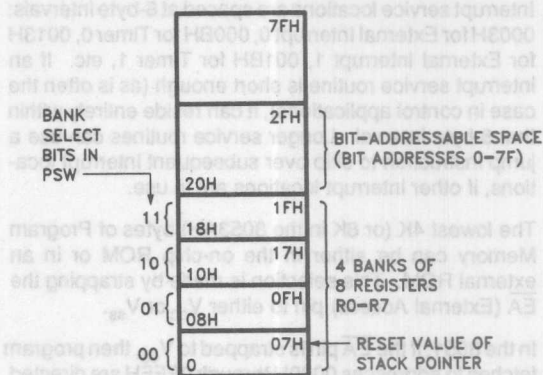


Figure 1-7. The Lower 128 Bytes of Internal RAM

instruction set includes a wide selection of single-bit instructions, and the 128 bits in this area can be directly addressed by these instructions. The bit addresses in this area are 00H through 7FH.

All of the bytes in the Lower 128 can be accessed by either direct or indirect addressing. The Upper 128 (Figure 1-8) can only be accessed by indirect addressing. The Upper 128 bytes of RAM are not implemented in the 8051.

Figure 1-9 gives a brief look at the Special Function Register (SFR) space. SFRs include the Port latches, timers, peripheral controls, etc. These registers can only be accessed by direct addressing. In general, all 8051 Family microcontrollers have the same SFRs as the 8051, and at the same addresses in SFR space. However, enhancements to the 8051 have additional SFRs that are not present in the 8051, nor perhaps in other proliferations of the family.

Sixteen addresses in SFR space are both byte- and bit-addressable. The bit-addressable SFRs are those whose address ends in 000B. The bit addresses in this area are 80H through FFH.

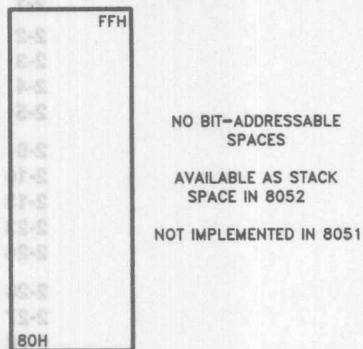


Figure 1-8. The Upper 128 Bytes of Internal RAM

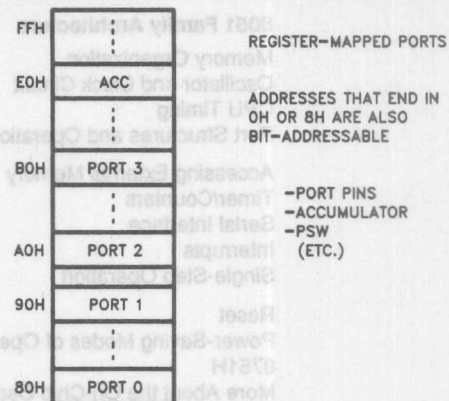


Figure 1-9. SFR Space

CHAPTER 2

8051 Family Architecture

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8051 Family Architecture

INTRODUCTION

The entire 8051 Family of 8-bit microcontrollers is based on the "core" architecture shown in Figure 2-1. The original member of this family is produced under the name 8051AH. The term "8051", however, is often used generically to refer to all of the 8051 Family members.

In this chapter the term "8052" is used to refer to an 8051AH with a double amount of ROM and RAM, and an extra timer

called Timer 2. It is also included in this "core" discussion because its features are often found in other enhanced 8051 Family members. (see Members of the Family in Chapter 1).

The latter section of this data book details both the basic and enhanced 8051 Family members in separate chapters, but concentrates on the new features beyond the basic core architecture. Thus, the new reader should first concentrate on the features discussed in this chapter and the rest of Section I.

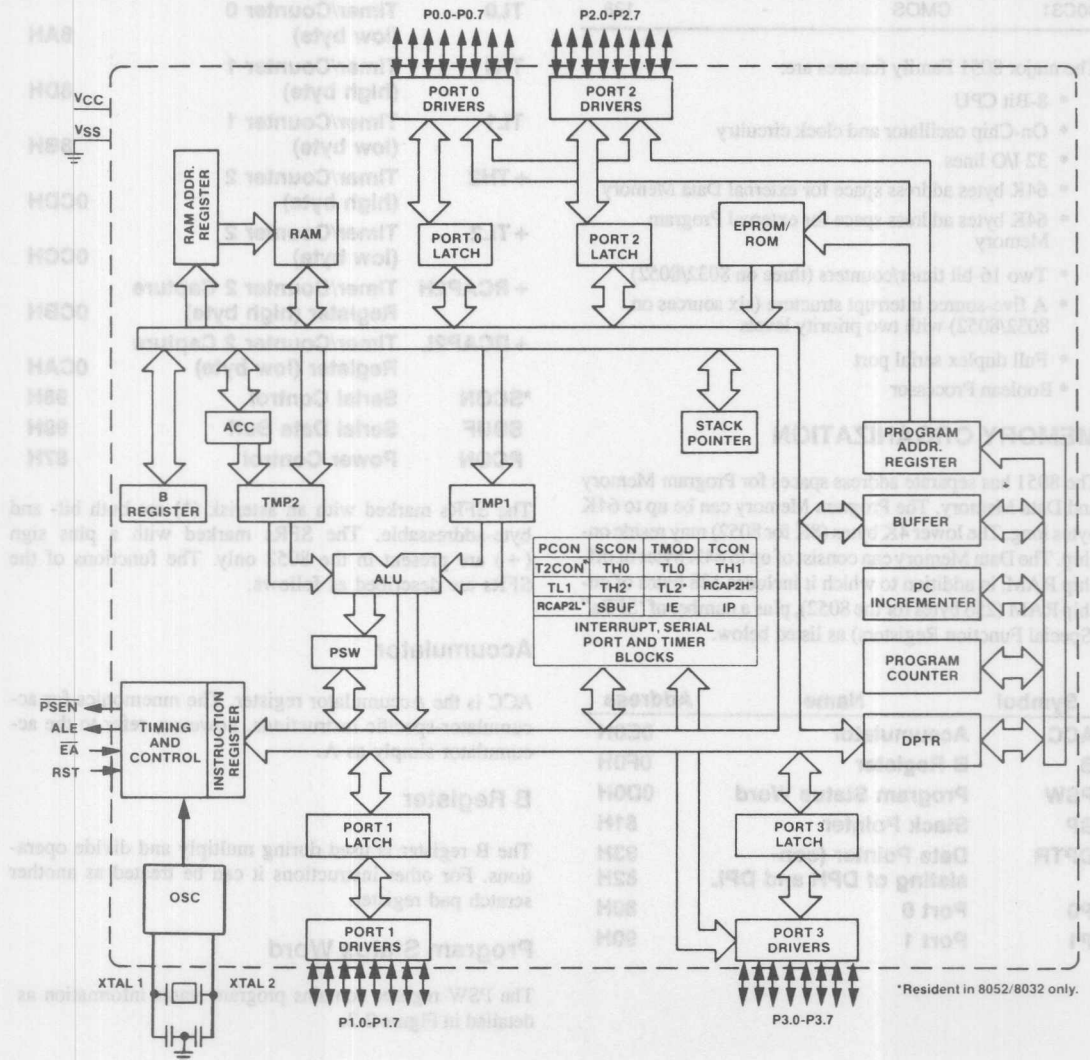


Figure 2-1. 8051 Family Architecture

Table 2-1 8051 Family Core Members

Part	Technology	On-Chip Program Memory (bytes)	On-Chip Data RAM (bytes)
8051AH	NMOS	4K ROM	128
8031AH	NMOS	-	128
8751H	NMOS	4K EPROM	128
8052	NMOS	8K ROM	256
80C51	CMOS	4K ROM	128
80C31	CMOS	-	128

The major 8051 Family features are:

- 8-Bit CPU
- On-Chip oscillator and clock circuitry
- 32 I/O lines
- 64K bytes address space for external Data Memory
- 64K bytes address space for external Program Memory
- Two 16-bit timer/counters (three on 8032/8052)
- A five-source interrupt structure (six sources on 8032/8052) with two priority levels
- Full duplex serial port
- Boolean Processor

MEMORY ORGANIZATION

The 8051 has separate address spaces for Program Memory and Data Memory. The Program Memory can be up to 64K bytes long. The lower 4K bytes (8K for 8052) may reside on-chip. The Data Memory can consist of up to 64K bytes of off-chip RAM, in addition to which it includes 128 bytes of on-chip RAM (256 bytes for the 8052), plus a number of 'SFRs' (Special Function Registers) as listed below.

Symbol	Name	Address
*ACC	Accumulator	0E0H
*B	B Register	0F0H
*PSW	Program Status Word	0D0H
SP	Stack Pointer	81H
DPTR	Data Pointer (consisting of DPH and DPL)	83H 82H
*P0	Port 0	80H
*P1	Port 1	90H

Symbol	Name	Address
*P2	Port 2	0A0H
*P3	Port 3 *	0B0H
*IP	Interrupt Priority Control	0B8H
*IE	Interrupt Enable Control	0A8H
TMOD	Timer/Counter Mode Control	89H
*TCON	Timer/Counter Control	88H
+ *T2CON	Timer/Counter 2 Control	0C8H
TH0	Timer/Counter 0 (high byte)	8CH
TL0	Timer/Counter 0 (low byte)	8AH
TH1	Timer/Counter 1 (high byte)	8DH
TL1	Timer/Counter 1 (low byte)	8BH
+ TH2	Timer/Counter 2 (high byte)	0CDH
+ TL2	Timer/Counter 2 (low byte)	0CCH
+ RCAP2H	Timer/Counter 2 Capture Register (high byte)	0CBH
+ RCAP2L	Timer/Counter 2 Capture Register (low byte)	0CAH
*SCON	Serial Control	98H
SBUF	Serial Data Buff	99H
PCON	Power Control	87H

The SFRs marked with an asterisk (*) are both bit- and byte-addressable. The SFRs marked with a plus sign (+) are present in the 8052 only. The functions of the SFRs are described as follows.

Accumulator

ACC is the Accumulator register. The mnemonics for accumulator-specific instructions, however, refer to the accumulator simply as A.

B Register

The B register is used during multiply and divide operations. For other instructions it can be treated as another scratch pad register.

Program Status Word

The PSW register contains program status information as detailed in Figure 2-2.

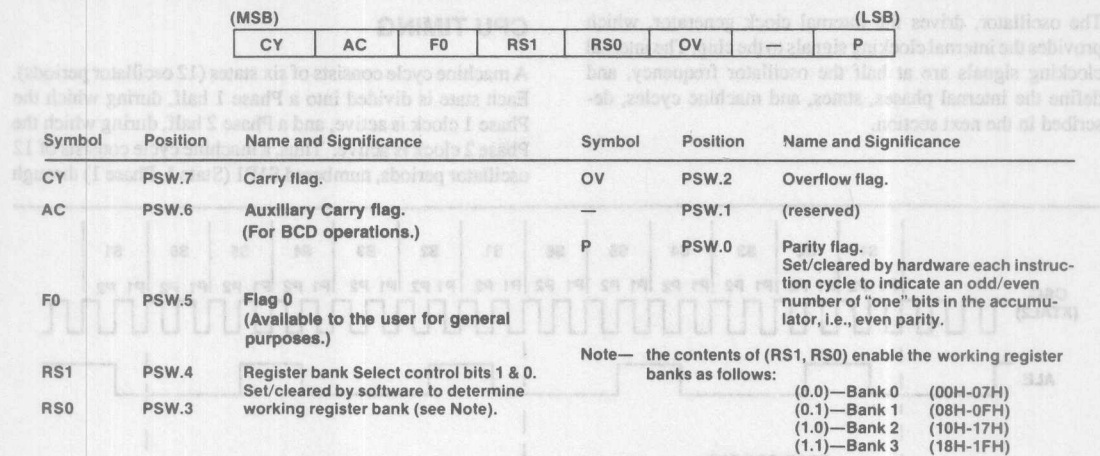


Figure 2-2. PSW: Program Status Word Register

Stack Pointer

The Stack Pointer register is 8 bits wide. It is incremented before data is stored during PUSH and CALL executions. While the stack may reside anywhere in on-chip RAM, the Stack Pointer is initialized to 07H after a reset. This causes the stack to begin at location 08H.

Data Pointer

The Data Pointer (DPTR) consists of a high byte (DPH) and a low byte (DPL). Its intended function is to hold a 16-bit address. It may be manipulated as a 16-bit register or as two independent 8-bit registers.

Ports 0 to 3

P0, P1, P2, and P3 are the SFR latches of Ports 0, 1, 2, and 3, respectively.

Serial Data Buffer

The Serial Data Buffer is actually two separate registers, a transmit buffer and a receive buffer register. When data is moved to SBUF, it goes to the transmit buffer where it is held for serial transmission. (Moving a byte to SBUF is what initiates the transmission.) When data is moved from SBUF, it comes from the receive buffer.

Timer Registers

Register pairs (TH0, TL0), (TH1, TL1), and (TH2, TL2) are the 16-bit counting registers for Timer/Counters 0, 1, and 2, respectively.

Capture Registers

The register pair (RCAP2H, RCAP2L) are the capture registers for the Timer 2 "capture mode." In this mode, in response to a transition at the 8052's T2EX pin, TH2 and TL2 are copied into RCAP2H and RCAP2L. Timer 2 also has a 16-bit auto-reload mode, and RCAP2H and RCAP2L, hold the reload value for this mode. More about Timer 2's features on page 2-12.

Control Registers

Special Function Registers IP, IE, TMOD, TCON, T2CON, SCON, and PCON contain control and status bits for the interrupt system, the timer/counters, and the serial port. They are described in later sections.

OSCILLATOR AND CLOCK CIRCUIT

XTAL1 and XTAL2 are the input and output of a single-stage on-chip inverter, which can be configured with off-chip components as a Pierce oscillator, as shown in Figure 2-3. The on-chip circuitry, and selection of off-chip components to configure the oscillator are discussed on page 2-30.

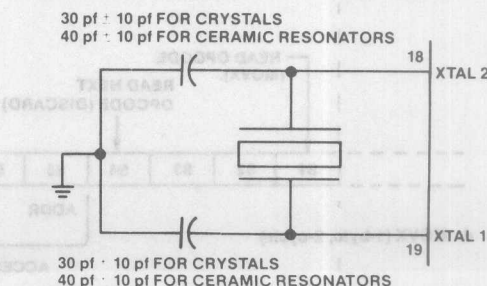


Figure 2-3. Crystal/Ceramic Resonator Oscillator

The oscillator, drives the internal clock generator, which provides the internal clocking signals to the chip. The internal clocking signals are at half the oscillator frequency, and define the internal phases, states, and machine cycles, described in the next section.

CPU TIMING

A machine cycle consists of six states (12 oscillator periods). Each state is divided into a Phase 1 half, during which the Phase 1 clock is active, and a Phase 2 half, during which the Phase 2 clock is active. Thus, a machine cycle consists of 12 oscillator periods, numbered S1P1 (State 1, Phase 1) through

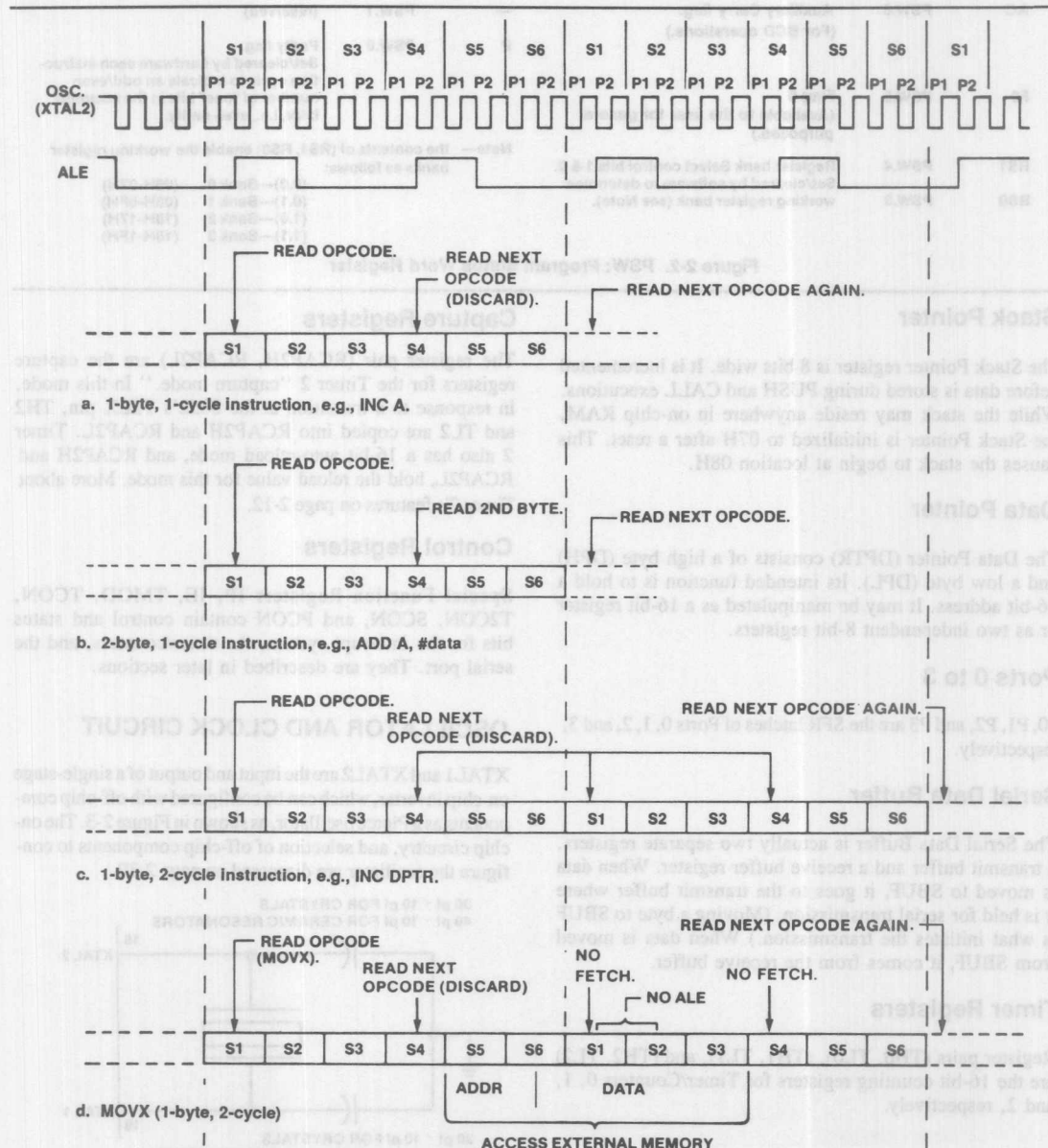


Figure 2-4. 8051 Fetch/Execute Sequences

S6P2 (State 6, Phase 2). Each phase last for one oscillator period. Each state lasts for two oscillator periods. Typically, arithmetic and logical operations take place during Phase 1 and internal register-to-register transfers take place during Phase 2.

The diagrams in Figure 2-4 show the fetch/execute timing referenced to the internal states and phases. Since these internal clock signals are not user accessible, the XTAL2 oscillator signal and the ALE (Address Latch Enable) signal are shown for external reference. ALE is normally activated twice during each machine cycle: one during S1P2 and S2P1, and again during S4P2 and S5P1.

Execution of a one-cycle instruction begins at S1P2, when the opcode is latched into the Instruction Register. If it is a 2-byte instruction, the second byte is read during S4 of the same machine cycle. If it is a 1-byte instruction, there is still a fetch at S4, but the byte read (which would be the next opcode) is ignored, and the Program Counter is not incremented. In any case, execution is complete at the end of S6P2. Figure 2-4a and 2-4b show the timing for a 1-byte, 1-cycle instruction and for a 2-byte, 1-cycle instruction.

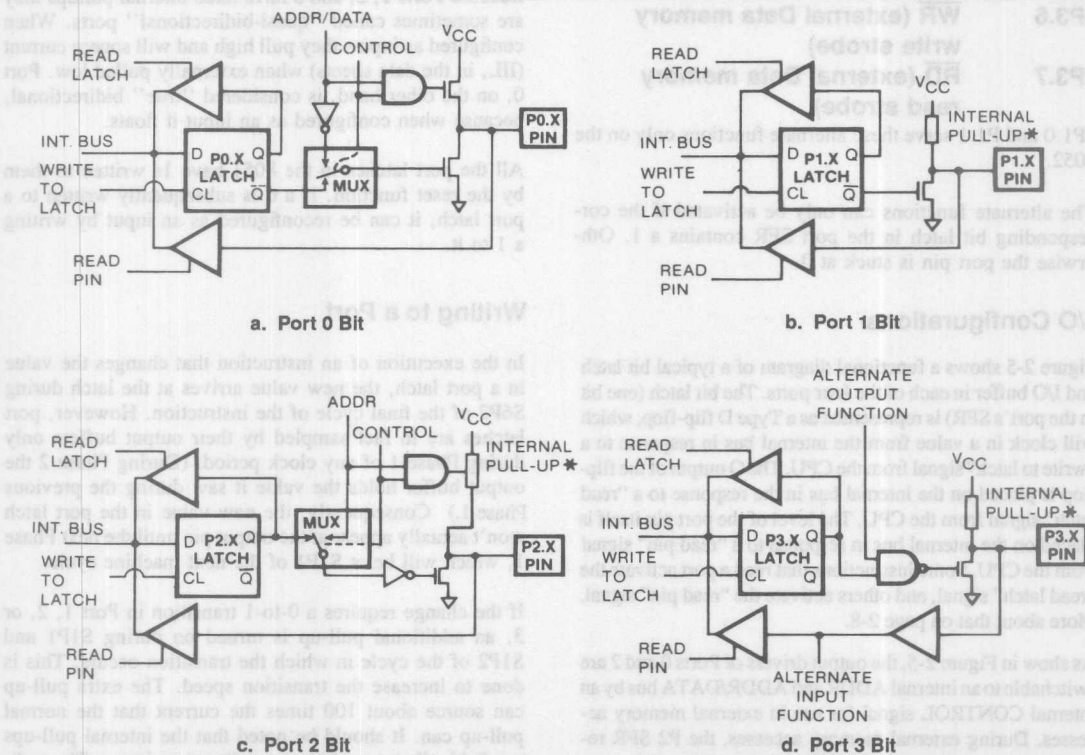
Most 8051 instructions execute in one cycle. MUL (multiply) and DIV (divide) are the only instructions that take more than two cycles to complete. They take four cycles.

Normally, two code bytes are fetched from Program Memory during every machine cycle. The only exception to this is when a MOVX instruction is executed. MOVX is a 1-byte 2-cycle instruction that accesses external Data Memory. During a MOVX, two fetches are skipped while the external Data Memory is being addressed and strobed. Figures 2-4c and 2-4d show the timing for a normal 1-byte, 2-cycle instruction and for a MOVX instruction.

PORT STRUCTURES AND OPERATION

All four ports in the 8051 are bidirectional. Each consists of a latch (Special Function Registers P0 through P3), an output driver, and an input buffer.

The output drivers of Ports 0 and 2, and the input buffers of Port 0, are used in accesses to external memory. In this application, Port 0 outputs the low byte of the external memory address, time-multiplexed with the byte being



*See Figure 2-6 for details of the internal pull up.

Figure 2-5. 8051 Port Bit Latches and I/O Buffers

written or read. Port 2 outputs the high byte of the external memory address when the address is 16 bits wide. Otherwise the Port 2 pins continue to emit the P2 SFR content.

All the Port 3 pins, and (in the 8052) two Port 1 pins are multifunctional. They are not only port pins, but also serve the functions of various special features as listed below:

PORT PIN ALTERNATE FUNCTION

*P1.0	T2 (Timer/Counter 2 external input)
*P1.1	T2EX (Timer/Counter 2 capture/reload trigger)
P3.0	RXD (serial input port)
P3.1	TXD (serial output port)
P3.2	INT0 (external interrupt)
P3.3	INT1 (external interrupt)
P3.4	T0 (Timer/Counter 0 external input)
P3.5	T1 (Timer/Counter 1 external input)
P3.6	WR (external Data memory write strobe)
P3.7	RD (external Data memory read strobe)

*P1.0 and P1.1 serve these alternate functions only on the 8052.

The alternate functions can only be activated if the corresponding bit latch in the port SFR contains a 1. Otherwise the port pin is stuck at 0.

I/O Configurations

Figure 2-5 shows a functional diagram of a typical bit latch and I/O buffer in each of the four ports. The bit latch (one bit in the port's SFR) is represented as a Type D flip-flop, which will clock in a value from the internal bus in response to a "write to latch" signal from the CPU. The Q output of the flip-flop is placed on the internal bus in the response to a "read latch" signal from the CPU. The level of the port pin itself is placed on the internal bus in response to a "read pin" signal from the CPU. Some instructions that read a port activate the "read latch" signal, and others activate the "read pin" signal. More about that on page 2-8.

As show in Figure 2-5, the output drivers of Ports 0 and 2 are switchable to an internal ADDR and ADDR/DATA bus by an internal CONTROL signal for use in external memory accesses. During external memory accesses, the P2 SFR remains unchanged, but the P0 SFR gets 1s written to it.

Also show in Figure 2-5, is that if a P3 bit latch contains a 1, then the output level is controlled by the signal labeled "alternate output functions." The actual P3.X pin level is always available to the pin's alternate input function, if any.

Ports 1, 2, and 3 have internal pull-ups. Port 0 has open-drain outputs. Each I/O line can be independently used as an input or an output. (Ports 0 and 2 may not be used as general purpose I/O when being used as the ADDR/DATA BUS.) To be used as an input, the port bit latch must contain a 1, which turns off the output driver FET. Then, for Ports 1, 2, and 3, the pin is pulled high by the internal pull-up, but can be pulled low by an external source.

Port 0 differs in not having internal pullups. The pullup FET in the P0 output driver (see Figure 2-5a) is used only when the Port is emitting 1s during external memory accesses. Otherwise the pullup FET is off. Consequently P0 lines that are being used as output port lines are open drain. Writing a 1 to the bit latch leaves both output FETs off, so the pin floats. In that condition it can be used as a high-impedance input.

Because Ports 1, 2, and 3 have fixed internal pullups they are sometimes called "quasi-bidirectional" ports. When configured as inputs they pull high and will source current (IIL, in the data sheets) when externally pulled low. Port 0, on the other hand, is considered "true" bidirectional, because when configured as an input it floats.

All the port latches in the 8051 have 1s written to them by the reset function. If a 0 is subsequently written to a port latch, it can be reconfigured as an input by writing a 1 to it.

Writing to a Port

In the execution of an instruction that changes the value in a port latch, the new value arrives at the latch during S6P2 of the final cycle of the instruction. However, port latches are in fact sampled by their output buffers only during Phase 1 of any clock period. (During Phase 2 the output buffer holds the value it saw during the previous Phase 1.) Consequently, the new value in the port latch won't actually appear at the output pin until the next Phase 1, which will be at S1P1 of the next machine cycle.

If the change requires a 0-to-1 transition in Port 1, 2, or 3, an additional pull-up is turned on during S1P1 and S1P2 of the cycle in which the transition occurs. This is done to increase the transition speed. The extra pull-up can source about 100 times the current that the normal pull-up can. It should be noted that the internal pull-ups are field-effect transistors, not linear resistors. The pull-up arrangements are shown in Figure 2-6.

In NMOS versions of the 8051, the fixed part of the pull-up is a depletion-mode transistor with the gate wired to the source. This transistor will allow the pin to source about 0.25 mA when shorted to ground. In parallel with the fixed pull-up is an enhancement-mode transistor, which is activated during S1 whenever the port bit does a 0-to-1 transition. During this interval, if the port pin is shorted to ground, this extra transistor will allow the pin to source an additional 30 mA.

In the CMOS versions, the pull-up consists of three pFETs. It should be noted that an n-channel FET (nFET) is turned on when logical 1 is applied to its gate, and is turned off when a logical 0 is applied to its gate. A p-channel FET (pFET) is the opposite: it is on when its gate sees a 0, and off when its gate sees a 1.

Transistor pFET 1 in Figure 2-6 is turned on for two oscillator periods after a 0-to-1 transition in the port latch. While it's on, it turns on pFET 3 (a weak pull-up) through the inverter. This inverter and pFET 3 form a latch which holds the 1.

Note that if the pin is emitting a 1, a negative glitch on the pin from some external source can turn off pFET 3, causing the pin to go into a float state; pFET 2 is a very weak pull-up which is on whenever the nFET is off, in traditional CMOS style. It's only about 1/10 the strength of pFET 3. Its function is to restore a 1 to the pin in the event the pin had a 1 and lost it to a glitch.

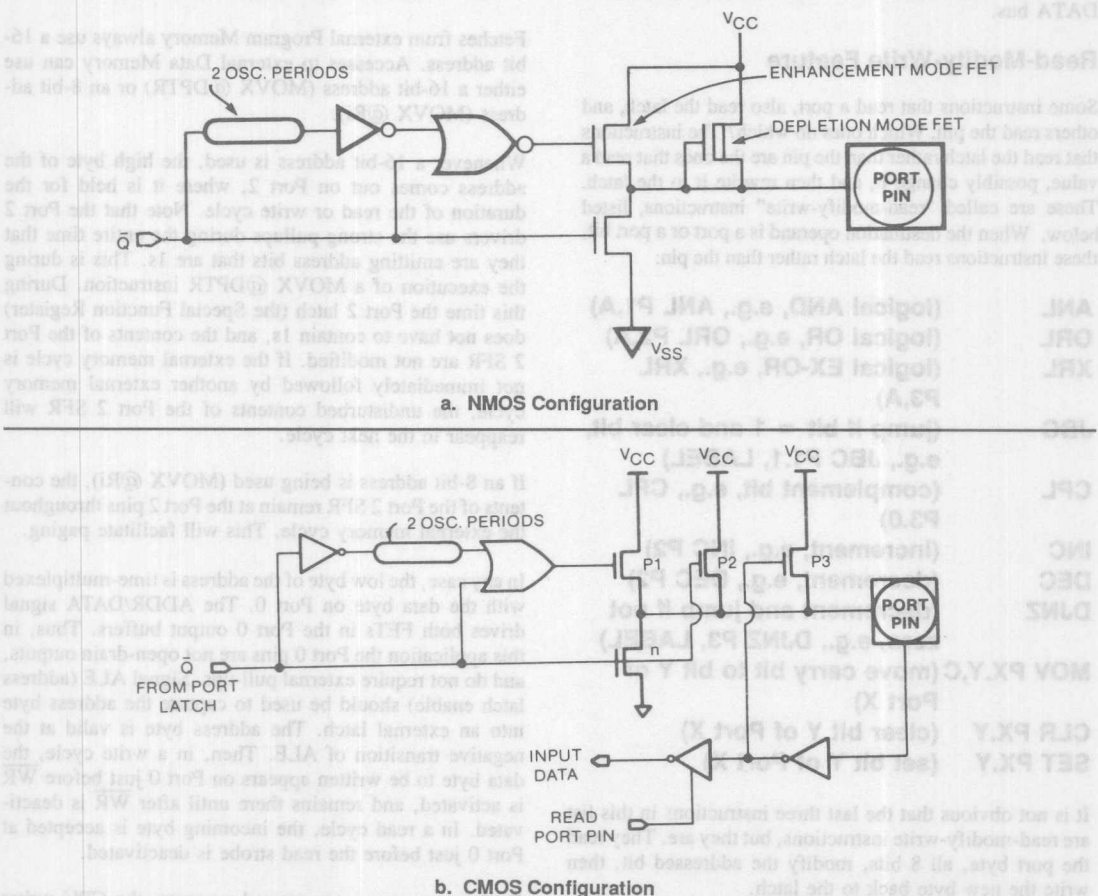


Figure 2-6. Ports 1 and 3 NMOS and CMOS Internal Pull-up Configurations.
(Port 2 is similar except that it holds the strong pull-up on while emitting 1s that are address bits.)

Port Loading and Interfacing

The output buffers of Ports 1, 2, and 3 can each drive four LS TTL inputs. These ports on NMOS versions can be driven in a normal manner by any TTL or NMOS circuit. Both NMOS and CMOS pins can be driven by open-collector and open-drain outputs, but note that 0-to-1 transitions will not be fast. In the NMOS device, if the pin is driven by an open collector output, a 0-to-1 transition will have to be driven by the relatively weak depletion mode FET in Figure 2-6a. In the CMOS device, an input 0 turns off pull-up pFET3, leaving only the very weak pull-up pFET2 to drive the transition.

Port 0 output buffers can each drive 8 LS TTL inputs. They do, however, require external pull-ups to drive NMOS inputs, except when being used as the ADDRESS/DATA bus.

Read-Modify-Write Feature

Some instructions that read a port, also read the latch, and others read the pin. Which ones do which? The instructions that read the latch rather than the pin are the ones that read a value, possibly change it, and then rewrite it to the latch. These are called "read-modify-write" instructions, listed below. When the destination operand is a port or a port bit, these instructions read the latch rather than the pin:

ANL	(logical AND, e.g., ANL P1,A)
ORL	(logical OR, e.g., ORL P2,A)
XRL	(logical EX-OR, e.g., XRL P3,A)
JBC	(jump if bit = 1 and clear bit, e.g., JBC P1.1, LABEL)
CPL	(complement bit, e.g., CPL P3.0)
INC	(increment, e.g., INC P2)
DEC	(decrement, e.g., DEC P2)
DJNZ	(decrement and jump if not zero, e.g., DJNZ P3, LABEL)
MOV PX.Y,C	(move carry bit to bit Y of Port X)
CLR PX.Y	(clear bit Y of Port X)
SET PX.Y	(set bit Y of Port X)

It is not obvious that the last three instructions in this list are read-modify-write instructions, but they are. They read the port byte, all 8 bits, modify the addressed bit, then write the new byte back to the latch.

The reason that read-modify-write instructions are directed to the latch rather than the pin is to avoid a possible misinterpretation of the voltage level at the pin. For ex-

ample, a port bit might be used to drive the base of a transistor. When a 1 is written to the bit, the transistor is turned on. If the CPU then reads the same port bit at the pin rather than the latch, it will read the base voltage of the transistor and interpret it as a 0. Reading the latch rather than the pin will return the correct value of 1.

ACCESSING EXTERNAL MEMORY

Accesses to external memory are of two types: accesses to external Program Memory and accesses to external Data Memory. Accesses to external Program Memory use signal $\overline{\text{PSEN}}$ (program store enable) as the read strobe. Accesses to external Data Memory use $\overline{\text{RD}}$ or $\overline{\text{WR}}$ (alternate functions of P3.7 and P3.6) to strobe the memory.

Fetches from external Program Memory always use a 16-bit address. Accesses to external Data Memory can use either a 16-bit address (**MOVX @DPTR**) or an 8-bit address (**MOVX @Ri**).

Whenever a 16-bit address is used, the high byte of the address comes out on Port 2, where it is held for the duration of the read or write cycle. Note that the Port 2 drivers use the strong pullups during the entire time that they are emitting address bits that are 1s. This is during the execution of a **MOVX @DPTR** instruction. During this time the Port 2 latch (the Special Function Register) does not have to contain 1s, and the contents of the Port 2 SFR are not modified. If the external memory cycle is not immediately followed by another external memory cycle, the undisturbed contents of the Port 2 SFR will reappear in the next cycle.

If an 8-bit address is being used (**MOVX @Ri**), the contents of the Port 2 SFR remain at the Port 2 pins throughout the external memory cycle. This will facilitate paging.

In any case, the low byte of the address is time-multiplexed with the data byte on Port 0. The ADDR/DATA signal drives both FETs in the Port 0 output buffers. Thus, in this application the Port 0 pins are not open-drain outputs, and do not require external pull-ups. Signal ALE (address latch enable) should be used to capture the address byte into an external latch. The address byte is valid at the negative transition of ALE. Then, in a write cycle, the data byte to be written appears on Port 0 just before $\overline{\text{WR}}$ is activated, and remains there until after $\overline{\text{WR}}$ is deactivated. In a read cycle, the incoming byte is accepted at Port 0 just before the read strobe is deactivated.

During any access to external memory, the CPU writes 0FFH to the Port 0 latch (the Special Function Register), thus obliterating whatever information the Port 0 SFR may have been holding.

External Program Memory is accessed under two conditions:

- 1) Whenever signal \overline{EA} is active; or
- 2) Whenever the program counter (PC) contains a number that is larger than 0FFFH (1FFFH for the 8052).

This requires that the ROMless versions have \overline{EA} wired low to enable the lower 4K (8K for the 8032) program bytes to be fetched from external memory.

When the CPU is executing out of external Program Memory, all 8 bits of Port 2 are dedicated to an output function and may not be used for general purpose I/O. During external program fetches they output the high byte of the PC. During this time the Port 2 drivers use the strong pull-ups to emit PC bits that are 1s.

PSEN

The read strobe for external fetches is \overline{PSEN} , which is not activated for internal fetches. When the CPU is accessing

external Program Memory, \overline{PSEN} is activated twice every cycle (except during a MOVX instruction) whether or not the byte fetched is actually needed for the current instruction. When \overline{PSEN} is activated, its timing is not the same as \overline{RD} . A complete \overline{RD} cycle, including activation and deactivation of ALE and \overline{RD} , takes 12 oscillator periods. A complete \overline{PSEN} cycle, including activation and deactivation of ALE, and \overline{PSEN} , take 6 oscillator periods. The execution sequence for these two types of read cycles is shown in Figure 2-7 for comparison.

ALE

The main function of ALE is to provide a properly timed signal to latch the low byte of an address from P0 to an external latch during fetches from external Program Memory. For that purpose ALE is activated twice every machine cycle. This activation takes place even when the cycle involves no external fetch. The only time an ALE pulse doesn't come out is during an access to external

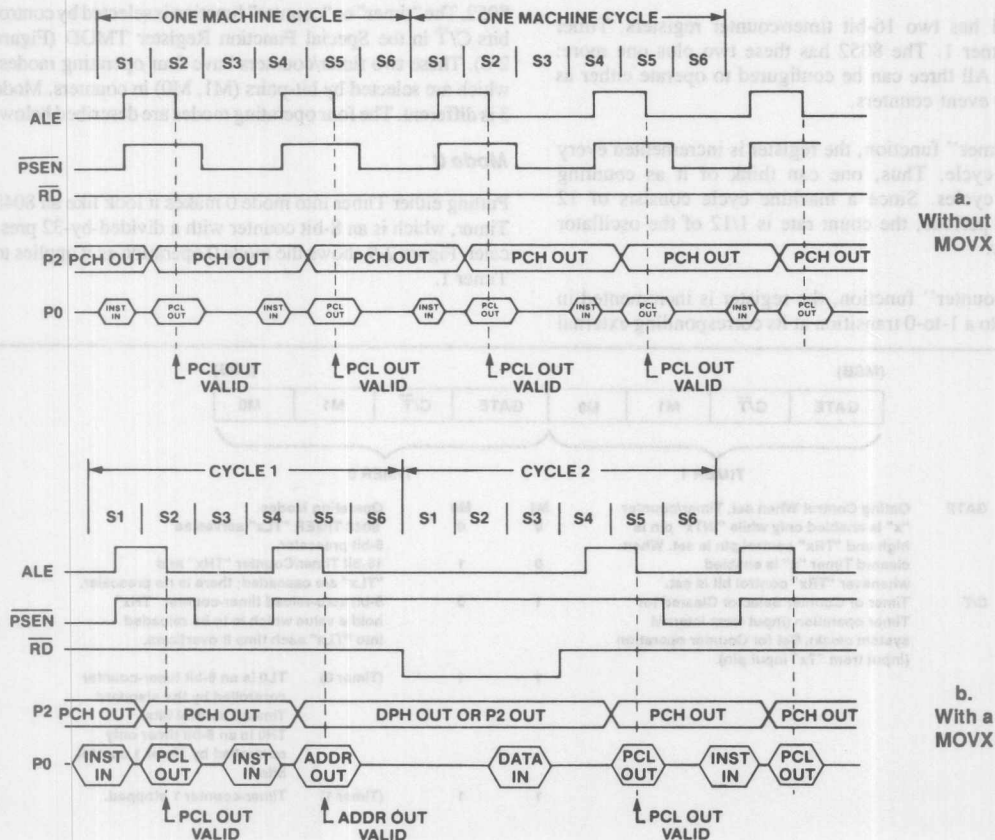


Figure 2-7. External Program Memory Execution

Data Memory. The first ALE of the second cycle of a MOVX instruction is missing (see Figure 2-7). Consequently, in any system that does not use external Data Memory, ALE is activated at a constant rate of 1/6 the oscillator frequency, and can be used for external clocking or timing purposes.

Overlapping External Program and Data Memory Spaces

In some applications it is desirable to execute a program from the same physical memory that is being used to store data. In the 8051, the external Program and Data Memory spaces can be combined by ANDing PSEN and RD. A positive-logic AND of these two signals produces an active-low read strobe that can be used for the combined physical memory. Since the PSEN cycle is faster than the RD cycle, the external memory needs to be fast enough to accommodate the PSEN cycle.

TIMER/COUNTERS

The 8051 has two 16-bit timer/counter registers: Timer 0 and Timer 1. The 8052 has these two plus one more: Timer 2. All three can be configured to operate either as timers or event counters.

In the "timer" function, the register is incremented every machine cycle. Thus, one can think of it as counting machine cycles. Since a machine cycle consists of 12 oscillator periods, the count rate is 1/12 of the oscillator frequency.

In the "counter" function, the register is incremented in response to a 1-to-0 transition at its corresponding external

input pin, T0, T1 or (in the 8052) T2. In this function, the external input is sampled during S5P2 of every machine cycle. When the samples show a high in one cycle and a low in the next cycle, the count is incremented. The new count value appears in the register during S3P1 of the cycle following the one in which the transition was detected. Since it takes 2 machine cycles (24 oscillator periods) to recognize a 1-to-0 transition, the maximum count rate is 1/24 of the oscillator frequency. There are no restrictions on the duty cycle of the external input signal, but to ensure that a given level is sampled at least once before it changes, it should be held for at least one full machine cycle.

In addition to the "timer" or "counter" selection, Timer 0 and Timer 1 have four operating modes from which to select. Timer 2, in the 8052, has three modes of operation: "capture," "auto-reload" and "baud rate generator."

Timer 0 and Timer 1

These timer/counters are present in both the 8051 and the 8052. The "timer" or "counter" function is selected by control bits C/T in the Special Function Register TMOD (Figure 2-8). These two timer/counters have four operating modes, which are selected by bit-pairs (M1, M0) in counters. Mode 3 is different. The four operating modes are described below.

Mode 0

Putting either Timer into mode 0 makes it look like an 8048 Timer, which is an 8-bit counter with a divided-by-32 prescaler. Figure 2-9 shows the mode 0 operation as it applies to Timer 1.

(MSB)				(LSB)			
GATE	C/T	M1	M0	GATE	C/T	M1	M0
TIMER 1				TIMER 0			
GATE	C/T	Operating Modes.					
		8048 TIMER "TLx" serves as 5-bit prescaler.					
		16-bit Timer/Counter "THx" and "TLx" are cascaded; there is no prescaler.					
		8-bit auto-reload timer-counter "THx" hold a value which is to be reloaded into "TLx" each time it overflows.					
		M1	M0				
		0	0				
		0	1				
		1	0				
		1	1	(Timer 0)	TL0 is an 8-bit timer-counter controlled by the standard Timer 0 control bits.		
		1	1	(Timer 1)	TH0 is an 8-bit timer only controlled by Timer 1 control bits.		
					Timer-counter 1 stopped.		

In this mode, the timer register is configured as a 13-bit register. As the count rolls over from all 1s to all 0s, it sets the timer interrupt flag TF1. The counted input is enabled to the Timer when TR1 = 1 and either GATE = 0 or INT1 = 1. (Setting GATE = 1 allows the Timer to be controlled by external input INT1, to facilitate pulse width measurements.) TR1 is a control bit in the Special Function Register TCON (Figure 2-10). GATE is in TMOD.

The 13-bit register consists of all 8 bits of TH1 and the lower 5 bits of TL1. The upper 3 bits of TL1 are indeterminate and should be ignored. Setting the run flag (TR1) does not clear the registers.

Mode 0 operation is the same for Timer 0 as for Timer 1. Substitute TR0, TF0 and INT0 for the corresponding Timer 1 signals in Figure 2-9. There are two different GATE bits, one for Timer 1 (TMOD.7) and one for Timer 0 (TMOD.3).

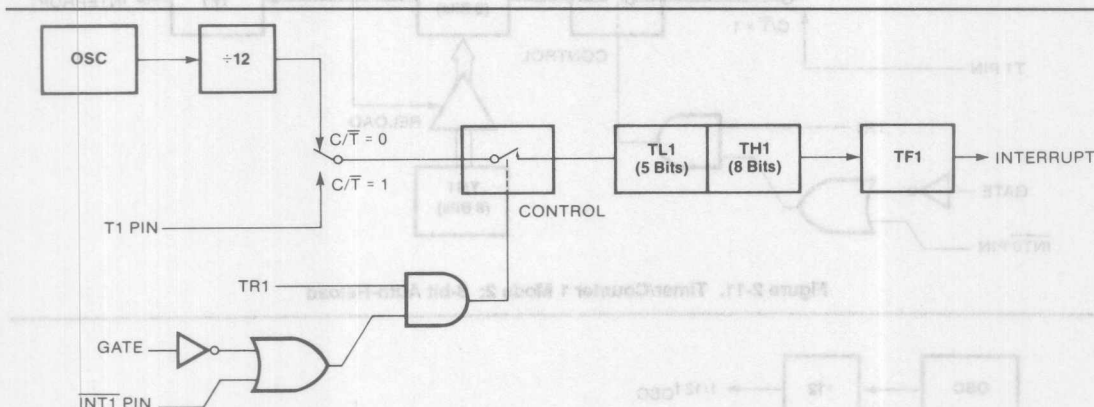


Figure 2-9. Timer/Counter 1 Mode 0: 13-bit Counter

(MSB)				(LSB)			
TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0

Symbol	Position	Name and Significance	Symbol	Position	Name and Significance
TF1	TCON.7	Timer 1 overflow Flag. Set by hardware on timer/counter overflow. Cleared by hardware when processor vectors to interrupt routine.	IE1	TCON.3	Interrupt 1 Edge flag. Set by hardware when external interrupt edge detected. Cleared when interrupt processed.
TR1	TCON.6	Timer 1 Run control bit. Set/cleared by software to turn timer/counter on/off.	IT1	TCON.2	Interrupt 1 Type control bit. Set/cleared by software to specify falling edge/low level triggered external interrupts.
TF0	TCON.5	Timer 0 overflow Flag. Set by hardware on timer/counter overflow. Cleared by hardware when processor vectors to interrupt routine.	IE0	TCON.1	Interrupt 0 Edge flag. Set by hardware when external interrupt edge detected. Cleared when interrupt processed.
TR0	TCON.4	Timer 0 Run control bit. Set/cleared by software to turn timer/counter on/off.	IT0	TCON.0	Interrupt 0 Type control bit. Set/cleared by software to specify falling edge/low level triggered external interrupts.

Figure 2-10. TCON: Timer/Counter Control Register

Mode 1

Mode 1 is the same as Mode 0, except that the Timer register is being run with all 16 bits.

Mode 2

Mode 2 configures the timer register as an 8-bit counter (TL1) with automatic reload, as shown in Figure 2-11. Overflow from TL1 not only sets TF1, but also reloads TL1 with the contents of TH1, which is preset by software. The reload leaves TH1 unchanged.

Mode 2 operation is the same for Timer/Counter 0.

Mode 3

Timer 1 in Mode 3 simply holds its count. The effect is the same as setting TR1 = 0.

Timer 0 in Mode 3 establishes TL0 and TH0 as two separate counters. The logic for Mode 3 on Timer 0 is shown in Figure 2-12. TL0 uses the Timer 0 control bits: C/\bar{T} , GATE, TR0, INT0, and TF0. TH0 is locked into a timer function (counting machine cycles) and takes over the use of TR1 and TF1 from Timer 1. Thus, TH0 now controls the "Timer 1" interrupt.

Mode 3 is provided for applications requiring an extra 8-bit timer or counter. With Timer 0 in Mode 3, an 8051 can look like it has three timer/counters, and an 8052, like it has four. When Timer 0 is in Mode 3, Timer 1 can be

turned on and off by switching it out of and into its own Mode 3, or can still be used by the serial port as a baud rate generator, or in fact, in any application not requiring an interrupt.

Timer 2

Timer 2 is a 16-bit timer/counter which is present only in the 8052. Like Timers 0 and 1, it can operate either as a timer or as an event counter. This is selected by bit C/\bar{T} in the Special Function Register T2CON (Figure 2-13). It has three operating modes: "capture," "auto-

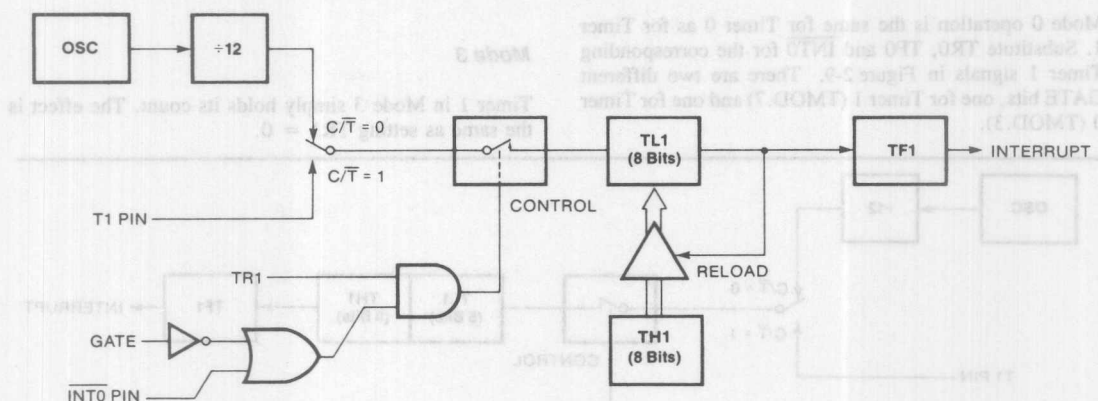


Figure 2-11. Timer/Counter 1 Mode 2: 8-bit Auto-Reload

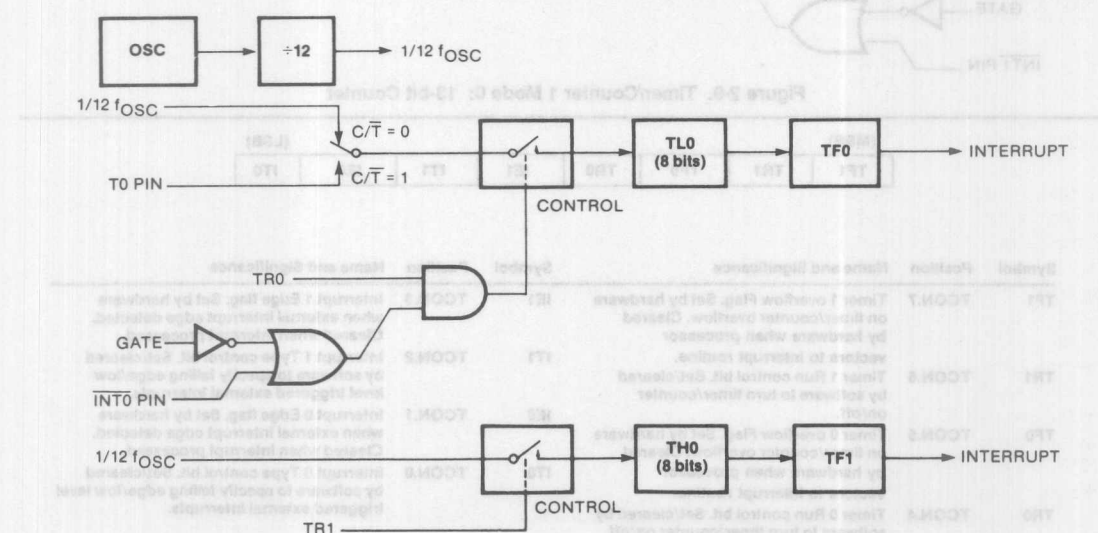


Figure 2-12. Timer/Counter 0 Mode 3: Two 8-bit Counters

(MSB)				(LSB)			
TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2	CP/RL2
Symbol	Position	Name and Significance					
TF2	T2CON.7	Timer 2 overflow flag set by a Timer 2 overflow and must be cleared by software. TF2 will not be set when either RCLK = 1 or TCLK = 1.					
EXF2	T2CON.6	Timer 2 external flag set when either a capture or reload is caused by a negative transition on T2EX and EXEN2 = 1. When Timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the Timer 2 interrupt routine. EXF2 must be cleared by software.					
RCLK	T2CON.5	Receive clock flag. When set, causes the serial port to use Timer 2 overflow pulses for its receive clock in modes 1 and 3. RCLK = 0 causes Timer 1 overflow to be used for the receive clock.					
TCLK	T2CON.4	Transmit clock flag. When set, causes the serial port to use Timer 2 overflow pulses for its transmit clock in modes 1 and 3. TCLK = 0 causes Timer 1 overflows to be used for the transmit clock.					
EXEN2	T2CON.3	Timer 2 external enable flag. When set, allows a capture or reload to occur as a result of a negative transition on T2EX if Timer 2 is not being used to clock the serial port. EXEN2 = 0 causes Timer 2 to ignore events at T2EX.					
TR2	T2CON.2	Start/stop control for Timer 2. A logic 1 starts the timer.					
C/T2	T2CON.1	Timer or counter select. (Timer 2) 0 = Internal timer (OSC/12) 1 = External event counter (falling edge triggered).					
CP/RL2	T2CON.0	Capture/Reload flag. When set, captures will occur on negative transitions at T2EX if EXEN2 = 1. When cleared, auto reloads will occur either with Timer 2 overflows or negative transitions at T2EX when EXEN2 = 1. When either RCLK = 1 or TCLK = 1, this bit is ignored and the timer is forced to auto-reload on Timer 2 overflow.					

Figure 2-13. T2CON: Timer/Counter 2 Control Register

Load" and "baud rate generator" which are selected by bits in T2CON as shown in Table 2-2.

Table 2-2. Timer 2 Operating Modes

RCLK + TCLK	CP/RL2	TR2	MODE
0	0	1	16-bit auto-reload
0	1	1	16-bit capture
1	X	1	baud rate generator
X	X	0	(off)

In the capture mode there are two options which are selected by bit EXEN2 in T2CON. If EXEN2 = 0, then Timer 2 is a 16-bit timer or counter which upon overflowing sets bit TF2, the Timer 2 overflow bit, which can be used to generate an interrupt. If EXEN2 = 1, then Timer 2 still does the above, but with the added feature that a 1-to-0 transition at external input T2EX causes the current value in the Timer 2 registers, TL2 and TH2, to be captured into registers RCAP2L and RCAP2H, respectively. (RCAP2L and RCAP2H are new Special Function Registers in the 8052.) In addition, the transition at T2EX causes bit EXF2 in T2CON to be set, and EXF2, like TF2, can generate an interrupt.

The capture mode is illustrated in Figure 2-14.

In the auto-reload mode there are again two options, which are selected by bit EXEN2 in T2CON. If EXEN2 = 0, then when Timer 2 rolls over it not only sets TF2 but also causes the Timer 2 registers to be reloaded with the 16-bit value in registers RCAP2L and RCAP2H, which are preset by software. If EXEN2 = 1, then Timer 2 still does the above, but with the added feature that a 1-to-0 transition at external input T2EX will also trigger the 16-bit reload and set EXF2.

The auto-reload mode is illustrated in Figure 2-15.

The baud rate generator mode is selected by RCLK = 1 and/or TCLK = 1. It will be described in conjunction with the serial port.

SERIAL INTERFACE

The serial port is full duplex, meaning it can transmit and receive simultaneously. It is also receive-buffered, meaning it can commence reception of a second byte before a previously received byte has been read from the receive register. (However, if the first byte still hasn't been read by the time reception of the second byte is complete, one of the bytes will be lost). The serial port receive and transmit registers are both accessed at Special Function Register SBUF. Writing to SBUF loads the transmit reg-

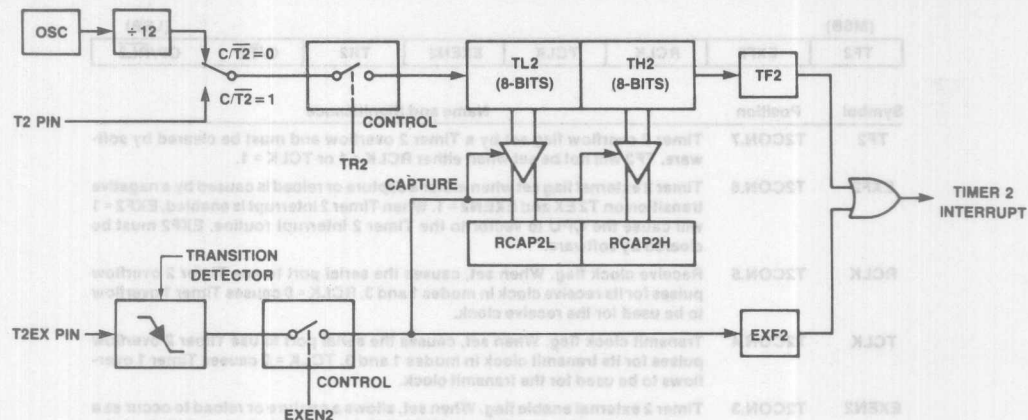


Figure 2-14. Timer 2 in Capture Mode

ister, and reading SBUF accesses a physically separate receive register.

The serial port can operate in 4 modes:

Mode 0: Serial data enters and exits through RXD. TXD outputs the shift clock. 8 bits are transmitted/received: 8 data bits (LSB first). The baud rate is fixed at 1/12 the oscillator frequency.

Mode 1: 10 bits are transmitted (through TXD) or received (through RXD): a start bit (0), 8 data bits (LSB first), and a stop bit (1). On receive, the stop bit goes into RB8 in Special Function Register SCON. The baud rate is variable.

Mode 2: 11 bits are transmitted (through TXD) or received (through RXD): a start bit (0), 8 data bits (LSB first), a programmable 9th data bit, and a stop bit (1). On transmit, the 9th data bit (TB8 in SCON) can be assigned the value of 0 or 1. Or, for example, the parity bit (P, in the PSW) could be moved into TB8. On receive, the 9th data bit goes into RB8 in Special Function Register SCON, while the stop bit is ignored. The baud rate is programmable to either 1/32 or 1/64 the oscillator frequency.

Mode 3: 11 bits are transmitted (through TXD) or received (through RXD): a start bit (0), 8 data bits (LSB first), a programmable 9th data bit and a stop bit (1). In fact, Mode 3 is the same as Mode 2 in all respects except the baud rate. The baud rate in Mode 3 is variable.

In all four modes, transmission is initiated by any instruction that uses SBUF as a destination register. Reception is initiated in Mode 0 by the condition RI=0 and REN=1. Reception is initiated in the other modes by the incoming start bit if REN=1.

Multiprocessor Communications

Modes 2 and 3 have a special provision for multiprocessor communications. In these modes, 9 data bits are received. The 9th one goes into RB8. Then comes a stop bit. The port can be programmed such that when the stop bit is received, the serial port interrupt will be activated only if RB8 = 1. This feature is enabled by setting bit SM2 in SCON. A way to use this feature in multiprocessor systems is as follows.

When the master processor wants to transmit a block of data to one of several slaves, it first sends out an address byte which identifies the target slave. An address byte differs from a data byte in that the 9th bit is 1 in an address byte and 0 in a data byte. With SM2 = 1, no slave will be interrupted by a data byte. An address byte, however, will interrupt all slaves, so that each slave can examine the received byte and see if it is being addressed. The addressed slave will clear its SM2 bit and prepare to receive the data bytes that will be coming. The slaves that weren't being addressed leave their SM2s set and go on about their business, ignoring the coming data bytes.

SM2 has no effect in Mode 0, and in Mode 1 can be used to check the validity of the stop bit. In a Mode 1 reception, if SM2 = 1, the receive interrupt will not be activated unless a valid stop bit is received.

Serial Port Control Register

The serial port control and status is the Special Function Register SCON, shown in Figure 2-16. This register contains not only the mode selection bits, but also the 9th data bit for transmit and receive (TB8 and RB8), and the serial port interrupt bits (TI and RI).

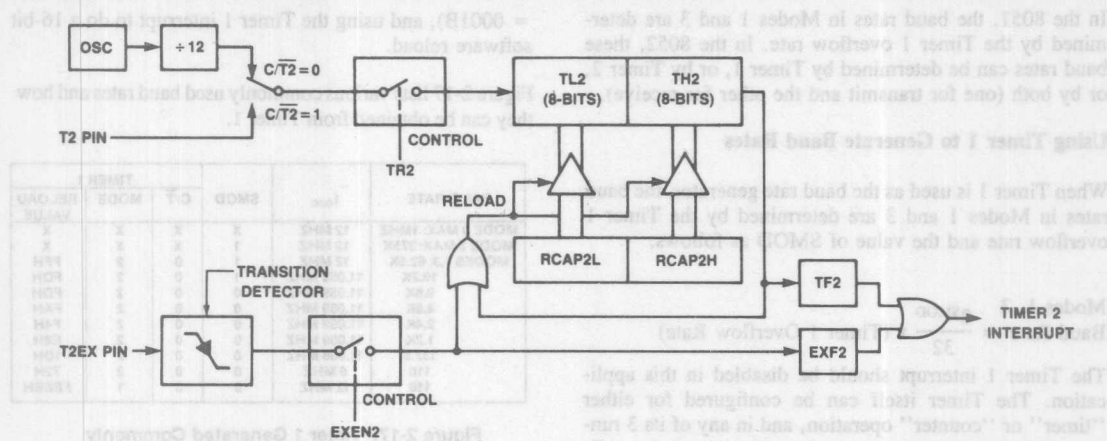


Figure 2-15. Timer 2 in Auto-Reload Mode

(MSB)				(LSB)			
SM0	SM1	SM2	REN	TB8	RB8	TI	RI

where SM0, SM1 specify the serial port mode, as follows:

SM0	SM1	Mode	Description	Baud Rate
0	0	0	shift register	$f_{osc}/12$
0	1	1	8-bit UART	variable
1	0	2	9-bit UART	$f_{osc}/64$ or $f_{osc}/32$
1	1	3	9-bit UART variable	

- SM2 enables the multiprocessor communication feature in modes 2 and 3. In mode 2 or 3, if SM2 is set to 1 then RI will not be activated if the received 9th data bit (RB8) is 0. In mode 1, if SM2 = 1 then RI will not be activated if a valid stop bit was not received. In mode 0, SM2 should be 0.
- REN enables serial reception. Set by software to enable reception. Clear by software to disable reception.
- TB8 is the 9th data bit that will be transmitted in modes 2 and 3. Set or clear by software as desired.
- RB8 in modes 2 and 3, is the 9th data bit that was received. In mode 1, if SM2 = 0, RB8 is the stop bit that was received. In mode 0, RB8 is not used.
- TI is transmit interrupt flag. Set by hardware at the end of the 8th bit time in mode 0, or at the beginning of the stop bit in the other modes, in any serial transmission. Must be cleared by software.
- RI is receive interrupt flag. Set by hardware at the end of the 8th bit time in mode 0, or halfway through the stop bit time in the other modes, in any serial reception (except see SM2). Must be cleared by software.

Figure 2-16. SCON: Serial Port Control Register

Baud Rates

The baud rate in Mode 0 is fixed:

$$\text{Mode 0 Baud Rate} = \frac{\text{Oscillator Frequency}}{12}$$

The baud rate in Mode 2 depends on the value of bit SMOD in Special Function Register PCON. If SMOD = 0 (which is its value on reset), the baud rate is 1/64 the oscillator frequency. If SMOD = 1, the baud rate is 1/32 the oscillator frequency.

$$\text{Mode 2 Baud Rate} = \frac{2^{\text{SMOD}}}{64} \times (\text{Oscillator Frequency})$$

In the 8051, the baud rates in Modes 1 and 3 are determined by the Timer 1 overflow rate. In the 8052, these baud rates can be determined by Timer 1, or by Timer 2, or by both (one for transmit and the other for receive).

Using Timer 1 to Generate Baud Rates

When Timer 1 is used as the baud rate generator, the baud rates in Modes 1 and 3 are determined by the Timer 1 overflow rate and the value of SMOD as follows:

$$\text{Baud Rate} = \frac{2^{\text{SMOD}}}{32} \times (\text{Timer 1 Overflow Rate})$$

The Timer 1 interrupt should be disabled in this application. The Timer itself can be configured for either "timer" or "counter" operation, and in any of its 3 running modes. In the most typical applications, it is configured for "timer" operation, in the auto-reload mode (high nibble of TMOD = 0010B). In that case, the baud rate is given by the formula

$$\text{Modes 1, 3 Baud Rate} = \frac{2^{\text{SMOD}}}{32} \times \frac{\text{Oscillator Frequency}}{12 \times [256 - (\text{TH1})]}$$

One can achieve very low baud rates with Timer 1 by leaving the Timer 1 interrupt enabled, and configuring the Timer to run as a 16-bit timer (high nibble of TMOD

= 0001B), and using the Timer 1 interrupt to do a 16-bit software reload.

Figure 2-17 lists various commonly used baud rates and how they can be obtained from Timer 1.

BAUD RATE	f _{osc}	SMOD	TIMER 1		
			C/T	MODE	RELOAD VALUE
MODE 0 MAX: 1MHZ	12 MHZ	X	X	X	X
MODE 2 MAX: 375K	12 MHZ	1	X	X	X
Modes 1,3: 62.5K	12 MHZ	1	0	2	FFH
19.2K	11.059 MHZ	1	0	2	FDH
9.6K	11.059 MHZ	0	0	2	FDH
4.8K	11.059 MHZ	0	0	2	FAH
2.4K	11.059 MHZ	0	0	2	F4H
1.2K	11.059 MHZ	0	0	2	E8H
137.5	11.986 MHZ	0	0	2	1DH
110	6 MHZ	0	0	2	72H
110	12 MHZ	0	0	1	FE6BH

Figure 2-17. Timer 1 Generated Commonly Used Baud Rates

Using Timer 2 to Generate Baud Rates

In the 8052, Timer 2 is selected as the baud rate generator by setting TCLK and/or RCLK in T2CON (Figure 2-13). Note then the baud rates for transmit and receive can be simultaneously different. Setting RCLK and/or TCLK puts Timer 2 into its baud rate generator mode, as shown in Figure 2-18.

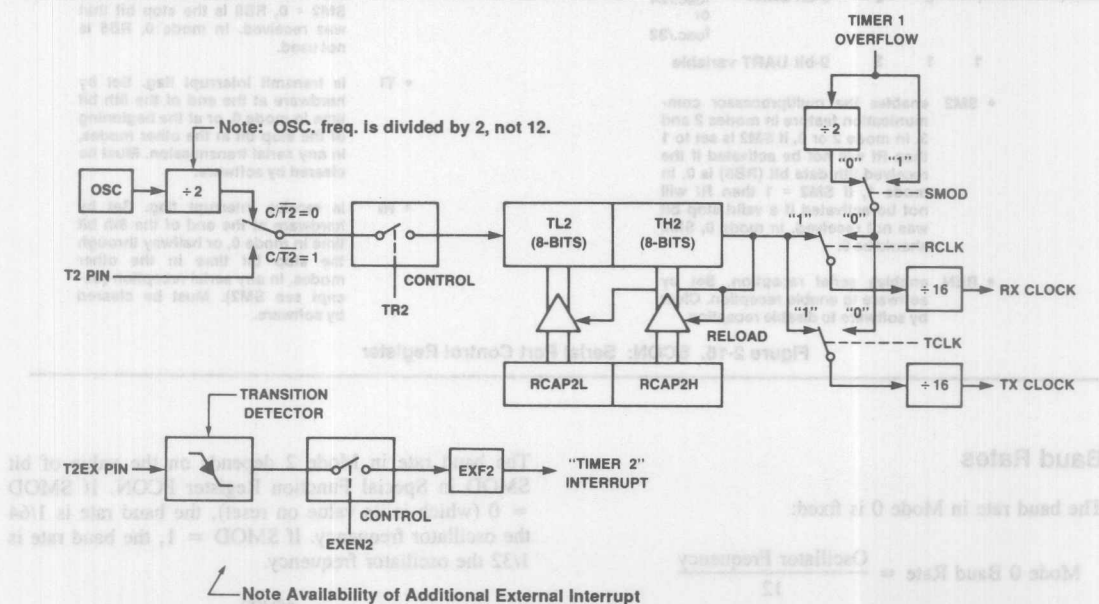


Figure 2-18. Timer 2 in Baud Rate Generator Mode

The baud rate generator mode is similar to the auto-reload mode, in that a rollover in TH2 causes the Timer 2 registers to be reloaded with the 16-bit value in registers RCAP2H and RCAP2L, which are preset by software.

Now, the baud rates in Modes 1 and 3 are determined by Timer 2's overflow rate as follows:

$$\text{Modes 1, 3 Baud Rate} = \frac{\text{Timer 2 Overflow Rate}}{16}$$

The Timer can be configured for either "timer" or "counter" operation. In the most typical applications, it is configured for "timer" operation ($C/\overline{T2} = 0$). "Timer" operation is a little different for Timer 2 when it's being used as a baud rate generator. Normally as a timer it would increment every machine cycle (thus at 1/12 the oscillator frequency). As a baud rate generator, however, it increments every state time (thus at 1/2 the oscillator frequency). In that case the baud rate is given by the formula

$$\text{Modes 1, 3 Baud Rate} = \frac{\text{Oscillator Frequency}}{32 \times [65536 - (\text{RCAP2H}, \text{RCAP2L})]}$$

where (RCAP2H, RCAP2L) is the content of RCAP2H and RCAP2L taken as a 16-bit unsigned integer.

Timer 2 as a baud rate generator is shown in Figure 2-18. This Figure is valid only if $\text{RCLK} + \text{TCLK} = 1$ in T2CON. Note that a rollover in TH2 does not set TF2, and will not generate an interrupt. Therefore, the Timer 2 interrupt does not have to be disabled when Timer 2 is in the baud rate generator mode. Note too, that if EXEN2 is set, a 1-to-0 transition in T2EX will set EXF2 but will not cause a reload from (RCAP2H, RCAP2L) to (TH2, TL2). Thus when Timer 2 is in use as a baud rate generator, T2EX can be used as an extra external interrupt, if desired.

It should be noted that when Timer 2 is running ($\text{TR2} = 1$) in "timer" function in the baud rate generator mode, one should not try to read or write TH2 or TL2. Under these conditions the Timer is being incremented every state time, and the results of a read or write may not be accurate. The RCAP registers may be read, but shouldn't be written to, because a write might overlap a reload and cause write and/or reload errors. Turn the Timer off (clear TR2) before accessing the Timer 2 or RCAP registers, in this case.

More About Mode 0

Serial data enters and exits through RXD. TXD outputs the shift clock. 8 bits are transmitted/received: 8 data bits

(LSB first). The baud rate is fixed at 1/12 the oscillator frequency.

Figure 2-19 shows a simplified functional diagram of the serial port in mode 0, and associated timing.

Transmission is initiated by any instruction that uses SBUF as a destination register. The "write to SBUF" signal at S6P2 also loads a 1 into the 9th bit position of the transmit shift register and tells the TX Control block to commence a transmission. The internal timing is such that one full machine cycle will elapse between "write to SBUF," and activation of SEND.

SEND enables the output of the shift register to the alternate output function line of P3.0, and also enables SHIFT CLOCK to the alternate output function line of P3.1. SHIFT CLOCK is low during S3, S4, and S5 of every machine cycle, and high during S6, S1 and S2. At S6P2 of every machine cycle in which SEND is active, the contents of the transmit shift register are shifted to the right one position.

As data bits shift out to the right, zeros come in from the left. When the MSB of the data byte is at the output position of the shift register, then the 1 that was initially loaded into the 9th position, is just to the left of the MSB, and all positions to the left of that contain zeros. This condition flags the TX Control block to do one last shift and then deactivate SEND and set T1. Both of these actions occur at S1P1 of the 10th machine cycle after "write to SBUF."

Reception is initiated by the condition $\text{REN} = 1$ and $\text{RI} = 0$. At S6P2 of the next machine cycle, the RX Control unit writes the bits 11111110 to the receive shift register, and in the next clock phase activates RECEIVE.

RECEIVE enables SHIFT CLOCK to the alternate output function line of P3.1. SHIFT CLOCK makes transitions at S3P1 and S6P1 of every machine cycle. At S6P2 of every machine cycle in which RECEIVE is active, the contents of the receive shift register are shifted to the left one position. The value that comes in from the right is the value that was sampled at the P3.0 pin at S5P2 of the same machine cycle.

As data bits come in from the right, 1s shift out to the left. When the 0 that was initially loaded into the rightmost position arrives at the leftmost position in the shift register, it flags the RX Control block to do one last shift and load SBUF. At S1P1 of the 10th machine cycle after the write to SCON that cleared RI, RECEIVE is cleared and RI is set.

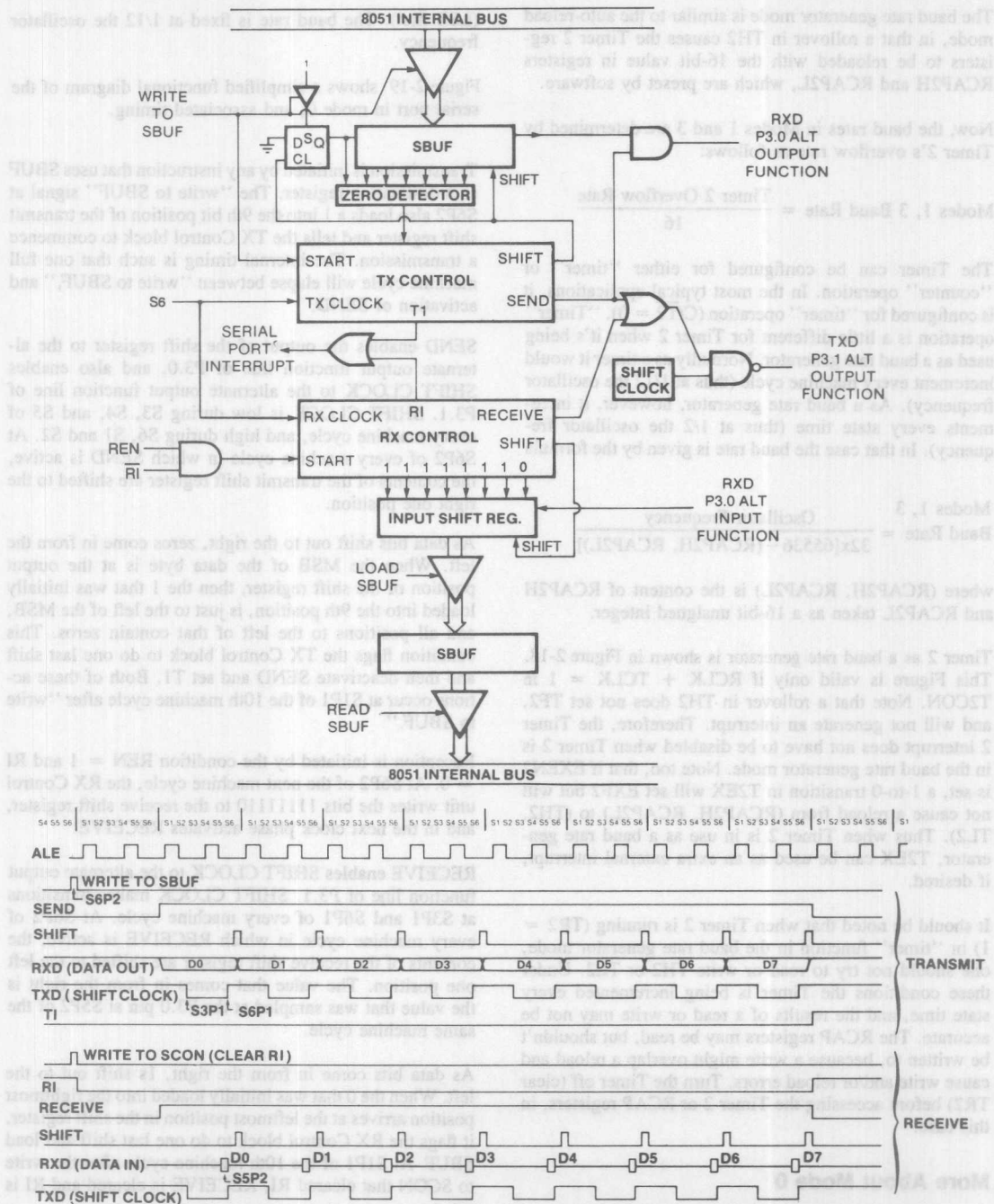


Figure 2-19. Serial Port Mode 0

More About Mode 1

Ten bits are transmitted (through TXD), or received (through RXD): a start bit (0), 8 data bits (LSB first), and a stop bit (1). On receive, the stop bit goes into RB8 in SCON. In the 8051 the baud rate is determined by the Timer 1 overflow rate. In the 8052 it is determined either by the Timer 1 overflow rate, or the Timer 2 overflow rate, or both (one for transmit and the other for receive).

Figure 2-20 shows a simplified functional diagram of the serial port in Mode 1, and associated timings for transmit and receive.

Transmission is initiated by any instruction that uses SBUF as a destination register. The "write to SBUF" signal also loads a 1 into the 9th bit position of the transmit shift register and flags the TX Control unit that a transmission is requested. Transmission actually commences at S1P1 of the machine cycle following the next rollover in the divide-by-16 counter. (Thus, the bit times are synchronized to the divide-by-16 counter, not to the "write to SBUF" signal).

The transmission begins with activation of $\overline{\text{SEND}}$, which puts the start bit at TXD. One bit time later, DATA is activated, which enables the output bit of the transmit shift register to TXD. The first shift pulse occurs one bit time after that.

As data bits shift out to the right, zeros are clocked in from the left. When the MSB of the data byte is at the output position of the shift register, then the 1 that was initially loaded into the 9th position is just to the left of the MSB, and all positions to the left of that contain zeroes. This condition flags the TX Control unit to do one last shift and then deactivate $\overline{\text{SEND}}$ and set TI. This occurs at the 10th divide-by-16 rollover after "write to SBUF."

Reception is initiated by a detected 1-to-0 transition at RXD. For this purpose RXD is sampled at a rate of 16 times whatever baud rate has been established. When a transition is detected, the divide-by-16 counter is immediately reset, and IFFH is written into the input shift register. Resetting the divide-by-16 counter aligns its rollovers with the boundaries of the incoming bit times.

The 16 states of the counter divide each bit time into 16ths. At the 7th, 8th, and 9th counter states of each bit time, the bit detector samples the value of RXD. The value accepted is the value that was seen in at least 2 of the 3 samples. This is done for noise rejection. If the value accepted during the first bit time is not 0, the receive circuits are reset and the unit goes back to looking for another 1-to-0 transition. This is to provide rejection of false start bits. If the start bit proves valid, it is shifted

into the input shift register, and reception of the rest of the frame will proceed.

As data bits come in from the right, 1s shift out to the left. When the start bit arrives at the leftmost position in the shift register, (which in mode 1 is a 9-bit register), it flags the RX Control block to do one last shift, load SBUF and RB8, and set RI. The signal to load SBUF and RB8, and to set RI, will be generated if, and only if, the following conditions are met at the time the final shift pulse is generated.

- 1) RI = 0, and
- 2) Either SM2 = 0, or the received stop bit = 1

If either of these two conditions is not met, the received frame is irretrievably lost. If both conditions are met, the stop bit goes into RB8, the 8 data bits go into SBUF, and RI is activated. At this time, whether the above conditions are met or not, the unit goes back to looking for a 1-to-0 transition in RXD.

More About Modes 2 and 3

Eleven bits are transmitted (through TXD), or received (through RXD): a start bit (0), 8 data bits (LSB first), a programmable 9th data bit, and a stop bit (1). On transmit, the 9th data bit (TB8) can be assigned the value of 0 or 1. On receive, the 9th data bit goes into RB8 in SCON. The baud rate is programmable to either 1/32 or 1/64 the oscillator frequency in mode 2. Mode 3 may have a variable baud rate generated from either Timer 1 or 2 depending on the state of TCLK and RCLK.

Figures 21a and b show a functional diagram of the serial port in modes 2 and 3. The receive portion is exactly the same as in mode 1. The transmit portion differs from mode 1 only in the 9th bit of the transmit shift register.

Transmission is initiated by any instruction that uses SBUF as a destination register. The "write to SBUF" signal also loads TB8 into the 9th bit position of the transmit shift register and flags the TX Control unit that a transmission is requested. Transmission commences at S1P1 of the machine cycle following the next rollover in the divide-by-16 counter. (Thus, the bit times are synchronized to the divide-by-16 counter, not to the "write to SBUF" signal.)

The transmission begins with activation of $\overline{\text{SEND}}$, which puts the start bit at TXD. One bit time later, DATA is activated, which enables the output bit of the transmit shift register to TXD. The first shift pulse occurs one bit time after that. The first shift clocks a 1 (the stop bit) into the 9th bit position of the shift register. Thereafter, only zeroes are clocked in. Thus, as data bits shift out to the

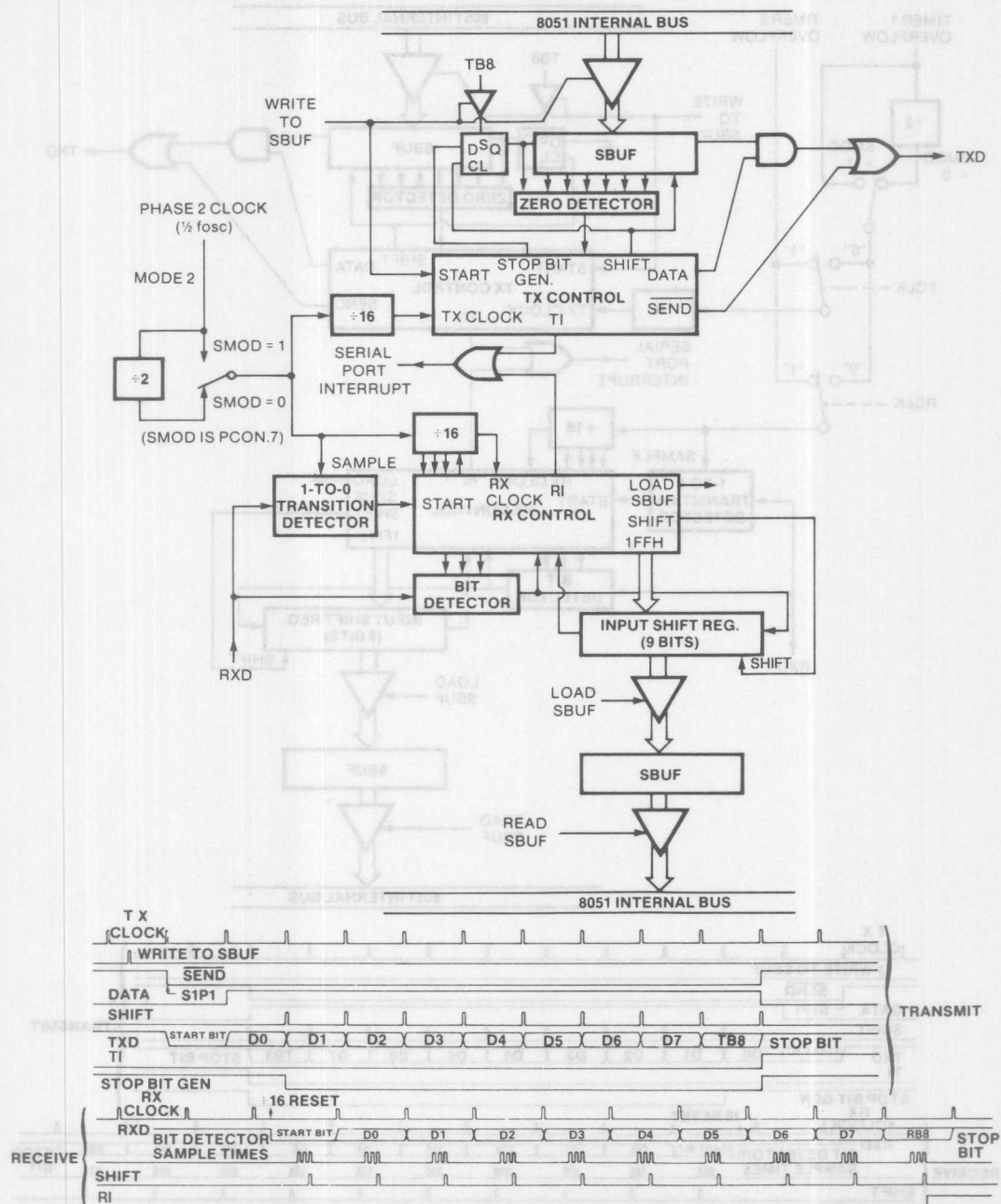


Figure 2-21a. Serial Port Mode 2

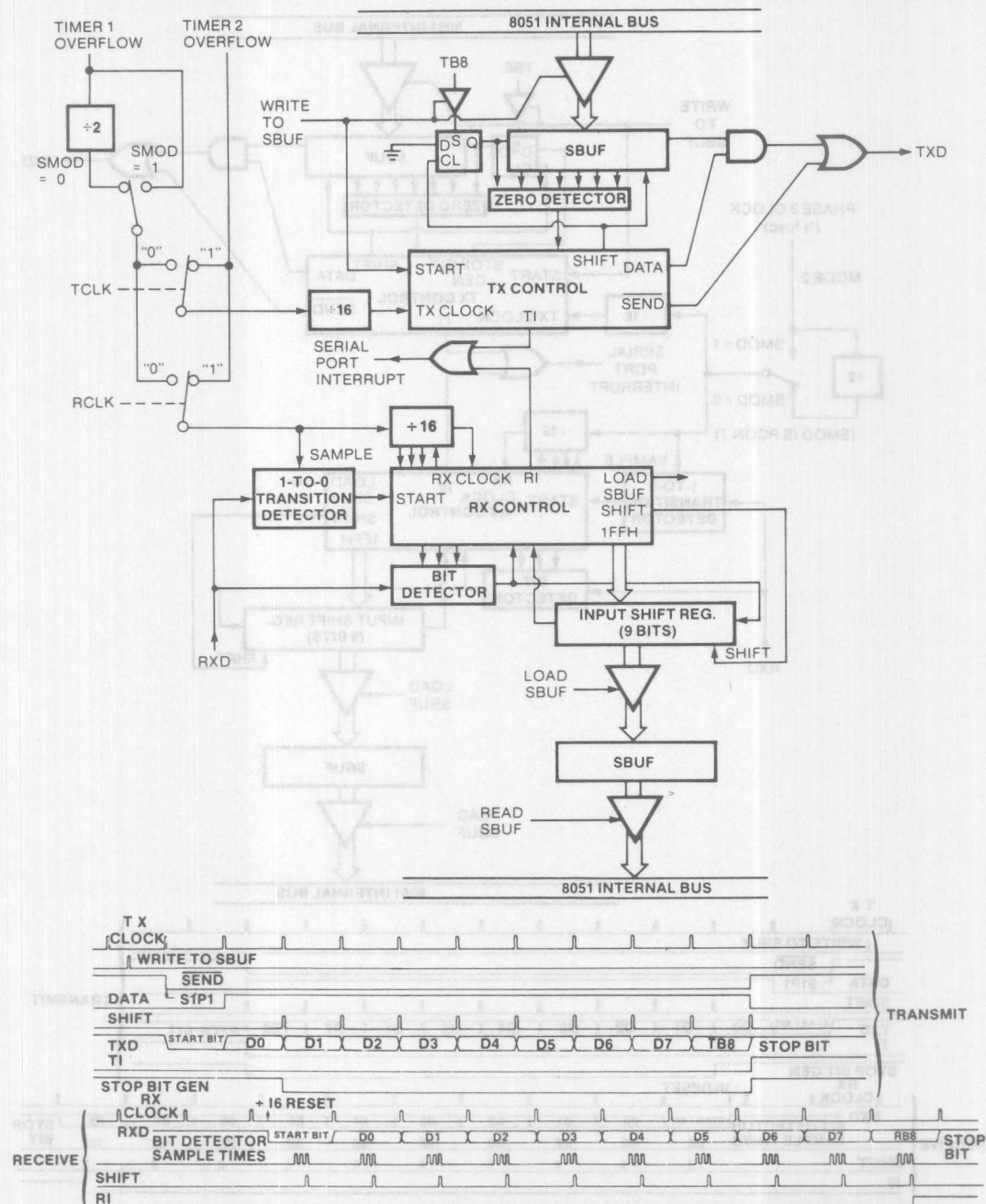


Figure 2-21b. Serial Port Mode 3
(TCLK, RCLK, and Timer 2 are present in the 8052/8032 only.)

right, zeroes are clocked in from the left. When TB8 is at the output position of the shift register, then the stop bit is just to the left of TB8, and all positions to the left of that contain zeroes. This condition flags the TX Control unit to do one last shift and then deactivate SEND and set TI. This occurs at the 11th divide-by-16 rollover after "write to SBUF."

Reception is initiated by a detected 1-to-0 transition at RXD. For this purpose RXD is sampled at a rate of 16 times whatever baud rate has been established. When a transition is detected, the divide-by-16 counter is immediately reset, and 1FFH is written to the input shift register.

At the 7th, 8th, and 9th counter states of each bit time, the bit detector samples the value of RXD. The value accepted is the value that was seen in at least two of the three samples. If the value accepted during the first bit time is not 0, the receive circuits are reset and the unit goes back to looking for another 1-to-0 transition. If the start bit proves valid, it is shifted into the input shift register, and reception of the rest of the frame will proceed.

As data bits come in from the right, 1s shift out to the left. When the start bit arrives at the leftmost position in the shift register (which in modes 2 and 3 is a 9-bit register), it flags the RX Control block to do one last shift, load SBUF and RB8, and set RI. The signal to load SBUF and RB8, and to set RI, will be generated if, and only if, the following conditions are met at the time the final shift pulse is generated:

- 1) RI = 0, and
- 2) Either SM2 = 0 or the received 9th data bit = 1

If either of these conditions is not met, the received frame is irretrievably lost, and RI is not set. If both conditions are met, the received 9th data bit goes into RB8, and the first 8 data bits go into SBUF. One bit time later, whether the above conditions were met or not, the unit goes back to looking for a 1-to-0 transition at the RXD input.

Note that the value of the received stop bit is irrelevant to SBUF, RB8, or RI.

INTERRUPTS

The 8051 provides five interrupt sources. The 8052 provides six. These are shown in Figure 2-22.

The External Interrupts $\overline{\text{INT0}}$ and $\overline{\text{INT1}}$ can each be either level-activated or transition-activated, depending on bits IT0 and IT1 in Register TCON. The flags that actually generate these interrupts are bits IE0 and IE1 in TCON. When an external interrupt is generated, the flag that gen-

erated it is cleared by the hardware when the service routine is vectored to only if the interrupt was transition-activated. If the interrupt was level-activated, then the external requesting source is what controls the request flag, rather than the on-chip hardware.

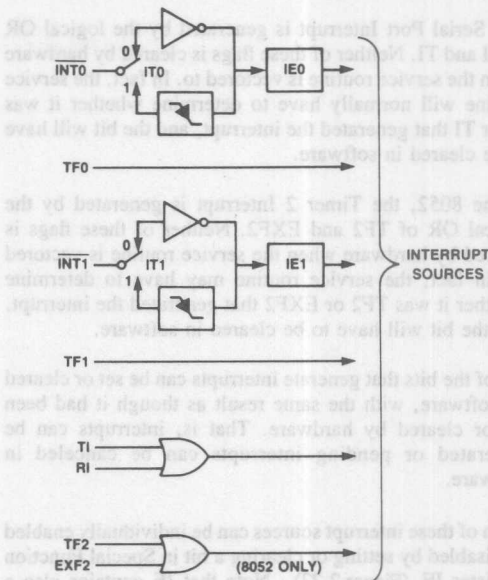


Figure 2-22. 8051 Family Interrupt Sources

(MSB)				(LSB)					
EA		X	ET2	ES	ET1	EX1	ET0	EX0	
Symbol	Position	Function							
EA	IE.7	disables all interrupts. If EA = 0, no interrupt will be acknowledged. If EA = 1, each interrupt source is individually enabled or disabled by setting or clearing its enable bit.							
—	IE.6	reserved							
ET2	IE.5	enables or disables the Timer 2 overflow or capture interrupt. If ET2 = 0, the Timer 2 interrupt is disabled.							
ES	IE.4	enables or disables the Serial Port interrupt. If ES = 0, the Serial Port interrupt is disabled.							
ET1	IE.3	enables or disables the Timer 1 Overflow interrupt. If ET1 = 0, the Timer 1 interrupt is disabled.							
EX1	IE.2	enables or disables External Interrupt 1. If EX1 = 0, External Interrupt 1 is disabled.							
ET0	IE.1	enables or disables the Timer 0 Overflow interrupt. If ET0 = 0, the Timer 0 interrupt is disabled.							
EX0	IE.0	enables or disables External Interrupt 0. If EX0 = 0, External Interrupt 0 is disabled.							

Figure 2-23. IE: Interrupt Enable Register

The timer 0 and Timer 1 Interrupts are generated by TF0 and TF1, which are set by a rollover in their respective timer/counter registers (except see page 2-12 for Timer 0 in mode 3). When a timer interrupt is generated, the flag that generated it is cleared by the on-chip hardware when the service routine is vectored to.

The Serial Port Interrupt is generated by the logical OR of RI and TI. Neither of these flags is cleared by hardware when the service routine is vectored to. In fact, the service routine will normally have to determine whether it was RI or TI that generated the interrupt, and the bit will have to be cleared in software.

In the 8052, the Timer 2 Interrupt is generated by the logical OR of TF2 and EXF2. Neither of these flags is cleared by hardware when the service routine is vectored to. In fact, the service routine may have to determine whether it was TF2 or EXF2 that generated the interrupt, and the bit will have to be cleared in software.

All of the bits that generate interrupts can be set or cleared by software, with the same result as though it had been set or cleared by hardware. That is, interrupts can be generated or pending interrupts can be canceled in software.

Each of these interrupt sources can be individually enabled or disabled by setting or clearing a bit in Special Function Register IE (Figure 2-23). Note that IE contains also a global disable bit, EA, which disables all interrupts at once.

Priority Level Structure

Each interrupt source can also be individually programmed to one of two priority levels by setting or clearing a bit in Special Function Register IP (Figure 2-24). A low-priority interrupt can itself be interrupted by a high-priority interrupt, but not by another low-priority interrupt. A high-priority interrupt can't be interrupted by any other interrupt source.

(MSB)				(LSB)			
X	X	PT2	PS	PT1	PX1	PT0	PX0
Symbol	Position	Function					
—	IP.7	reserved					
—	IP.6	reserved					
PT2	IP.5	defines the Timer 2 interrupt priority level. PT2 = 1 programs it to the higher priority level.					
PS	IP.4	defines the Serial Port interrupt priority level. PS = 1 programs it to the higher priority level.					
PT1	IP.3	defines the Timer 1 interrupt priority level. PT1 = 1 programs it to the higher priority level.					
PX1	IP.2	defines the External Interrupt 1 priority level. PX1 = 1 programs it to the higher priority level.					
PT0	IP.1	defines the Timer 0 interrupt priority level. PT0 = 1 programs it to the higher priority level.					
PX0	IP.0	defines the External Interrupt 0 priority level. PX0 = 1 programs it to the higher priority level.					

Figure 2-24. IP: Interrupt Priority Register

If two requests of different priority levels are received simultaneously, the request of higher priority level is serviced. If requests of the same priority level are received simultaneously, an internal polling sequence determines which request is serviced. Thus within each priority level there is a second priority structure determined by the polling sequence, as follows:

SOURCE	PRIORITY WITHIN LEVEL
1. IE0	(highest)
2. TF0	
3. IE1	
4. TF1	
5. RI + TI	
6. TF2 + EXF2	(lowest)

Note that the “priority within level” structure is only used to resolve multiple requests of the same priority level.

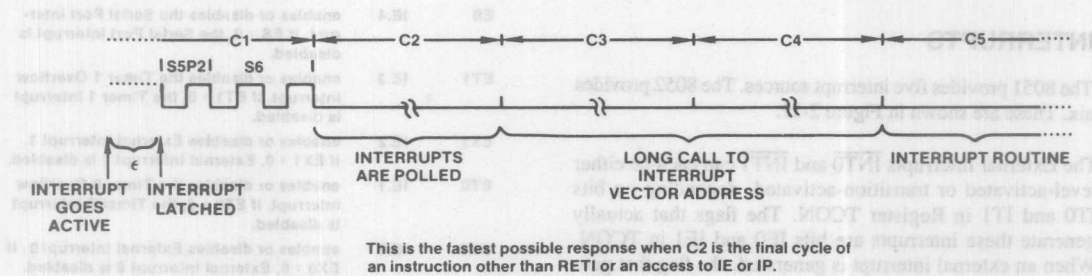


Figure 2-25. Interrupt Response Timing Diagram

How Interrupts Are Handled

The interrupt flags are sampled at S5P2 of every machine cycle. The samples are polled during the following machine cycle. If one of the flags was in a set condition at S5P2 of the preceding cycle, the polling cycle will find it and the interrupt system will generate an LCALL to the appropriate service routine, provided this hardware-generated LCALL is not blocked by any of the following conditions:

1. An interrupt of equal or higher priority level is already in progress.
2. The current (polling) cycle is not the final cycle in the execution of the instruction in progress.
3. The instruction in progress is RETI or any access to the IE or IP registers.

Any of these three conditions will block the generation of the LCALL to the interrupt service routine. Condition 2 ensures that the instruction in progress will be completed before vectoring to any service routine. Condition 3 ensures that if the instruction in progress is RETI or any access to IE or IP, then at least *one more* instruction will be executed before any interrupt is vectored to.

The polling cycle is repeated with each machine cycle, and the values polled are the values that were present at S5P2 of the previous machine cycle. Note then that if an interrupt flag is active but not being responded to for one of the above conditions, if the flag is not *still* active when the blocking condition is removed, the denied interrupt will not be serviced. In other words, the fact that the interrupt flag was once active but not serviced is not remembered. Every polling cycle is new.

The polling cycle/LCALL sequence is illustrated in Figure 2-25.

Note that if an interrupt of higher priority level goes active prior to S5P2 of the machine cycle labeled C3 in Figure 2-25, then in accordance with the above rules it will be vectored to during C5 and C6, without any instruction of the lower priority routine having been executed.

Thus the processor acknowledges an interrupt request by executing a hardware-generated LCALL to the appropriate servicing routine. In some cases it also clears the flag that generated the interrupt, and in other cases it doesn't. It never clears the Serial Port or Timer 2 flags. This has to be done in the user's software. It clears an external interrupt flag (IE0 or IE1) only if it was transition-activated. The hardware-generated LCALL pushes the contents of the Program Counter onto the stack (but it does not save

the PSW) and reloads the PC with an address that depends on the source of the interrupt being vectored to, as shown below.

SOURCE	VECTOR ADDRESS
IE0	0003H
TF0	000BH
IE1	0013H
TF1	001BH
RI + TI	0023H
TF2 + EXF2	002BH

Execution proceeds from that location until the RETI instruction is encountered. The RETI instruction informs the processor that this interrupt routine is no longer in progress, then pops the top two bytes from the stack and reloads the Program Counter. Execution of the interrupted program continues from where it left off.

Note that a simple RET instruction would also have returned execution to the interrupted program, but it would have left the interrupt control system thinking an interrupt was still in progress.

External Interrupts

The external sources can be programmed to be level-activated or transition-activated by setting or clearing bit IT1 or IT0 in Register TCON. If ITx = 0, external interrupt x is triggered by a detected low at the INTx pin. If ITx = 1, external interrupt x is edge-triggered. In this mode if successive samples of the INTx pin show a high in one cycle and a low in the next cycle, interrupt request flag IEx in TCON is set. Flag bit IEx then requests the interrupt.

Since the external interrupt pins are sampled once each machine cycle, an input high or low should hold for at least 12 oscillator periods to ensure sampling. If the external interrupt is transition-activated, the external source has to hold the request pin high for at least one cycle, and then hold it low for at least one cycle to ensure that the transition is seen so that interrupt request flag IEx will be set. IEx will be automatically cleared by the CPU when the service routine is called.

If the external interrupt is level-activated, the external source has to hold the request active until the requested interrupt is actually generated. Then it has to deactivate the request before the interrupt service routine is completed, or else another interrupt will be generated.

Response Time

The $\overline{\text{INT0}}$ and $\overline{\text{INT1}}$ levels are inverted and latched into IEO and IE1 at S5P2 of every machine cycle. The values are not actually polled by the circuitry until the next machine cycle. If a request is active and conditions are right for it to be acknowledged, a hardware subroutine call to the requested service routine will be the next instruction to be executed. The call itself takes two cycles. Thus, a minimum of three complete machine cycles elapse between activation of an external interrupt request and the beginning of execution of the first instruction of the service routine. Figure 2-25 shows interrupt response timings.

A longer response time would result if the request is blocked by one of the 3 previously listed conditions. If an interrupt of equal or higher priority level is already in progress, the additional wait time obviously depends on the nature of the other interrupt's service routine. If the instruction in progress is not in its final cycle, the additional wait time cannot be more than 3 cycles, since the longest instructions (MUL and DIV) are only 4 cycles long, and if the instruction in progress is RETI or an access to IE or IP, the additional wait time cannot be more than 5 cycles (a maximum of one more cycle to complete the instruction in progress, plus 4 cycles to complete the next instruction if the instruction is MUL or DIV).

Thus, in a single-interrupt system, the response time is always more than 3 cycles and less than 9 cycles.

SINGLE-STEP OPERATION

The 8051 interrupt structure allows single-step execution with very little software overhead. As previously noted, an interrupt request will not be responded to while an interrupt of equal priority level is still in progress, nor will it be responded to after RETI until at least one other instruction has been executed. Thus, once an interrupt routine has been entered, it cannot be re-entered until at least one instruction of the interrupted program is executed. One way to use this feature for single-step operation is to program one of the external interrupts e.g., $\overline{\text{INT0}}$ to be level-activated. The service routine for the interrupt will terminate with the following code:

```
JNB P3.2,$ ;WAIT HERE UNTIL INTO
GOES HIGH
JB P3.2,$ ;NOW WAIT HERE UNTIL
IT GOES LOW
RETI ;GO BACK AND
EXECUTE ONE
INSTRUCTION
```

If the $\overline{\text{INT0}}$ pin, which is also the P3.2 pin, is held normally low, the CPU will go right into the External Interrupt 0

routine and stay there until $\overline{\text{INT0}}$ is pulsed (from low to high to low). Then it will execute RETI, go back to the task program execute one instruction, and immediately re-enter the External Interrupt 0 routine to await the next pulsing of P3.2. One step of the task program is executed each time P3.2 is pulsed.

RESET

The reset input is the RST pin, which is the input to a Schmitt Trigger.

A reset is accomplished by holding the RST pin high for at least two machine cycles (24 oscillator periods), while the oscillator is running. The CPU responds by executing an internal reset. It also configures the ALE and $\overline{\text{PSEN}}$ pins as inputs. (They are quasi-bidirectional). The internal reset is executed during the second cycle in which RST is high and is repeated every cycle until RST goes low. It leaves the internal registers as follows:

REGISTER	CONTENT
PC	0000H
ACC	00H
B	00H
PSW	00H
SP	07H
DPTR	0000H
P0—P3	0FFH
IP (8051)	XXX00000B
IP (8052)	XX000000B
IE (8051)	0XX00000B
IE (8052)	0X000000B
TMOD	00H
TCON	00H
T2CON (8052 only)	00H
TH0	00H
TL0	00H
TH1	00H
TL1	00H
TH2	00H
TL2	00H
RCAP2H (8052 only)	00H
RCAP2L (8052 only)	00H
SCON	00H
SBUF	Indeterminate
PCON (NMOS)	0XXXXXXB
PCON (CMOS)	0XXX0000B

The internal RAM is not affected by reset. When VCC is turned on, the RAM content is indeterminate unless the part is returning from a reduced power mode of operation.

Power-On Reset

An automatic reset can be obtained when VCC is turned on by connecting the RST pin to VCC through a 10 μF capacitor and to VSS through an 8.2 k resistor, providing the VCC rise time does not exceed a millisecond and the oscillator start-up time

does not exceed 10 ms. This power-on reset circuit is shown in Figure 2-26. When power comes on, the current drawn by RST commences to charge the capacitor. The voltage at RST is the difference between VCC and the capacitor voltage, and decreases from VCC as the capacitor charges. The larger the capacitor, the more slowly VRST decreases. VRST must remain above the lower threshold of the Schmitt Trigger long enough to effect a complete reset. The time required is the oscillator start-up time, plus 2 machine cycles.

POWER-SAVING MODES OF OPERATION

For applications where power consumption is critical, the NMOS and CMOS versions provide power-reduced modes of operation.

NMOS Power Reduction Mode

To save power when using the NMOS device, VCC may be reduced to zero while the on-chip RAM is saved through a backup supply connected to the RST pin. After saving relevant data in RAM, the user enables the backup power supply to the RST pin before VCC falls below its operating limit. When power returns, the backup supply must stay on long enough to accomplish a reset; it then can be removed and normal operation resumed.

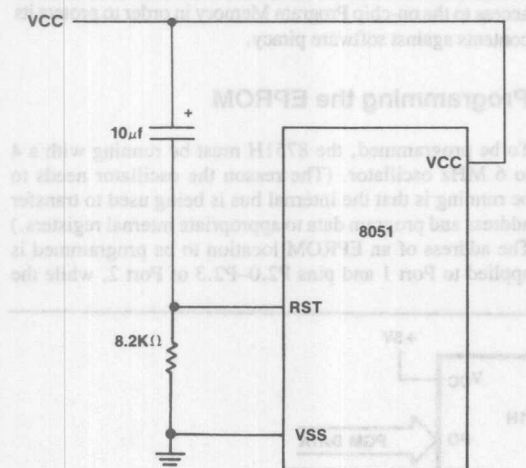


Figure 2-26. Power on Reset Circuit

CMOS Power Reduction Modes

CMOS versions have two power-reducing modes, Idle and Power Down. Backup power is supplied during these operations through VCC. Figure 2-27 shows the internal circuitry which implements these features. In the Idle mode (IDL = 1), the oscillator continues to run and the Interrupt, Serial Port, and Timer blocks continue to be clocked, but the clock signal is gated off to the CPU. In Power Down (PD = 1), the oscillator is frozen. The Idle and Power Down modes are activated by setting bits in Special Function Register PCON. The address of this register is 87H. Figure 2-28 details its contents.

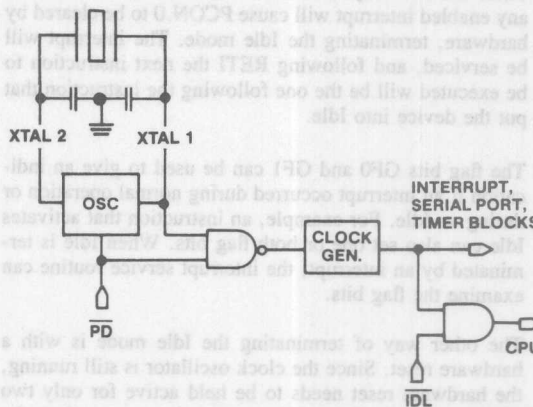


Figure 2-27. Idle and Power Down Hardware

(MSB)				(LSB)			
SMOD	—	—	—	GF1	GF0	PD	IDL
Symbol	Position	Name and Function					
SMOD	PCON.7	Double Baud rate bit. When set to a 1 and Timer 1 is used to generate baud rate, and the Serial Port is used in modes 1, 2, or 3.					
—	PCON.6	(Reserved)					
—	PCON.5	(Reserved)					
—	PCON.4	(Reserved)					
GF1	PCON.3	General-purpose flag bit.					
GF0	PCON.2	General-purpose flag bit.					
PD	PCON.1	Power Down bit. Setting this bit activates power down operation.					
IDL	PCON.0	Idle mode bit. Setting this bit activates idle mode operation.					

If 1s are written to PD and IDL at the same time, PD takes precedence. The reset value of PCON is (0XXX0000).

Figure 2-28. PCON: Power Control Register

Idle Mode

An instruction that sets PCON.0 causes that to be the last instruction executed before going into the Idle mode. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the Interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirety: the Stack Pointer, Program Counter, Program Status Word, Accumulator, and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated. ALE and PSEN hold at logic high levels.

There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into Idle.

The flag bits GF0 and GF1 can be used to give an indication if an interrupt occurred during normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.

The other way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset.

Power Down Mode

An instruction that sets PCON.1 causes that to be the last instruction executed before going into the Power Down mode. In the Power Down mode, the on-chip oscillator

is stopped. With the clock frozen, all functions are stopped, but the on-chip RAM and Special Function Registers are held. The port pins output the values held by their respective SFRs. ALE and PSEN output lows.

The only exit from Power Down is a hardware reset. Reset redefines all the SFRs, but does not change the on-chip RAM.

In the Power down mode of operation, VCC can be reduced to minimize power consumption. Care must be taken, however, to ensure that VCC is not reduced before the Power Down mode is invoked, and that VCC is restored to its normal operating level, before the Power Down mode is terminated. The reset that terminates Power Down also frees the oscillator. The reset should not be activated before VCC is restored to its normal operating level, and must be held active long enough to allow the oscillator to restart and stabilize (normally less than 10 msec).

8751H

The 8751H is the core EPROM member of the 8051 Family. This means that the on-chip Program Memory can be electrically programmed, and can be erased by exposure to ultraviolet light. The 8751H also has provision for denying external access to the on-chip Program Memory in order to protect its contents against software piracy.

Programming the EPROM

To be programmed, the 8751H must be running with a 4 to 6 MHz oscillator. (The reason the oscillator needs to be running is that the internal bus is being used to transfer address and program data to appropriate internal registers.) The address of an EPROM location to be programmed is applied to Port 1 and pins P2.0–P2.3 of Port 2, while the

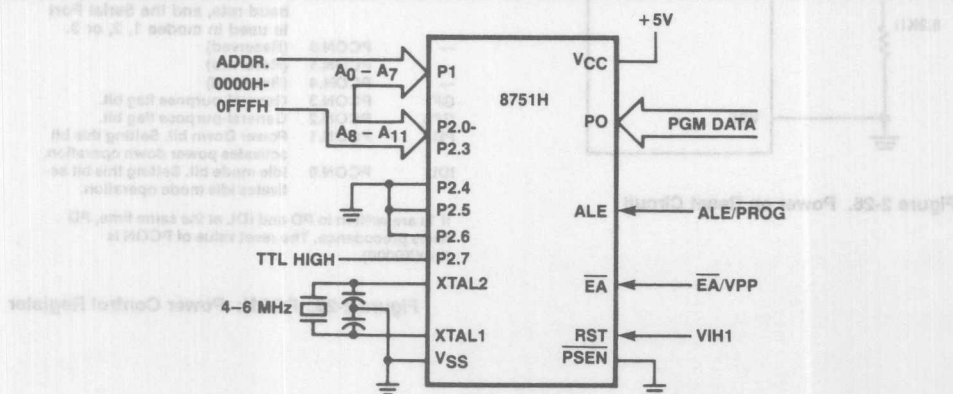


Figure 2-29. Programming the 8751H

data byte is applied to Port 0. Pins P2.4–P2.6 and $\overline{\text{PSEN}}$ should be held low, and P2.7 and RST high. (These are all TTL levels except RST, which requires 2.5V for a logic high.) $\overline{\text{EA}}/\text{VPP}$ is held normally high, and is pulsed to +21V. While $\overline{\text{EA}}/\text{VPP}$ is at 21V, the ALE/PROG pin, which is normally being held high, is pulsed low for 50 msec. Then $\overline{\text{EA}}/\text{VPP}$ is returned to high. This setup is shown in Figure 2-29. Detailed timing specifications are provided in the 8751H data sheet.

Note: The $\overline{\text{EA}}$ pin must not be allowed to go above the maximum specified VPP level of 21.5V for any amount of time. Even a narrow glitch above that voltage level can cause permanent damage to the device. The VPP source should be well regulated and free of glitches.

Program Verification

If the program security bit has not been programmed, the on-chip Program Memory can be read out for verification

purposes, if desired, either during or after the programming operation. The required setup, which is shown in Figure 2-30, is the same as for programming the EPROM except that pin P2.7 is held at TTL low (or used as an active-low read strobe). The address of the Program Memory location to be read is applied to Port 1 and pins P2.0–P2.3. The other Port 2 pins and $\overline{\text{PSEN}}$ are held low. ALE, $\overline{\text{EA}}$, and RST are held high. The contents of the addressed location will come out on Port 0. External pullups are required on Port 0 for this operation.

Program Memory Security

The 8751H contains a security bit, which, once programmed, denies electrical access by any external means to the on-chip Program Memory. The setup and procedure for programming the security bit are the same as for normal programming, except that pin P2.6 is held at TTL high. The setup is shown in Figure 2-31. Port 0, Port 1, and pins P2.0–P2.3 of Port 2 may be in any state.

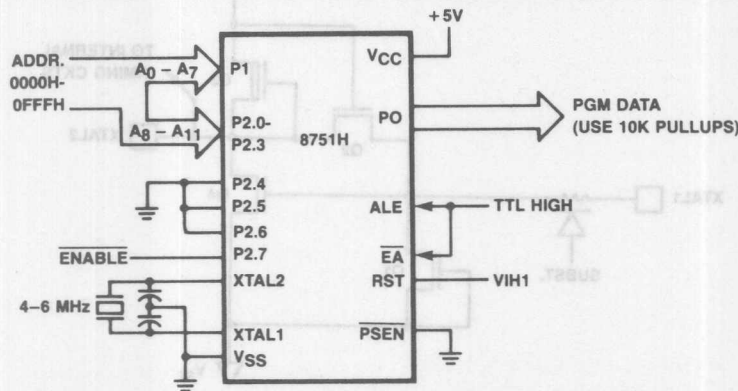


Figure 2-30. Program Verification in the 8751H

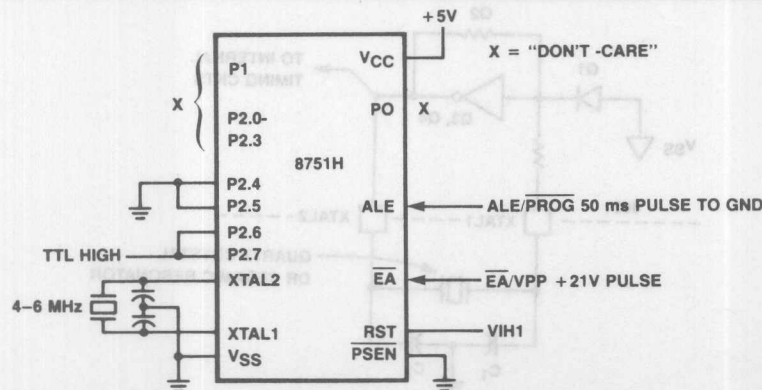


Figure 2-31. Programming the Security Bit in the 8751H

Once the security bit has been programmed, it can be deactivated only by full erasure of the Program Memory. While it is programmed, the internal Program Memory cannot be read out, the device cannot be further programmed, and it *cannot execute external program memory*. Erasing the EPROM, thus deactivating the security bit, restores the device's full functionality. It can then be re-programmed.

Erasure Characteristics

Erasure of the 8751H Program Memory begins to occur when the chip is exposed to light with wavelengths shorter than approximately 4,000 Angstroms. Since sunlight and fluorescent lighting have wavelengths in this range, exposure to these light sources over an extended time (about 1 week in sunlight, or 3 years in room-level fluorescent lighting) could cause inadvertent erasure. If an application subjects the 8751H to this type of exposure, it is suggested that an opaque label be placed over the window.

The recommended erasure procedure is exposure to ultraviolet light (at 2537 Angstroms) to an integrated dose of at least 15 W/cm². Exposing the 8751H to an ultraviolet lamp of 12,000 μ W/cm² rating for 20 to 30 minutes, at a distance of about 1 inch, should be sufficient. Erasure leaves the array in an all 1s state.

MORE ABOUT THE ON-CHIP OSCILLATOR

NMOS Versions

The on-chip oscillator circuitry for the NMOS members of the 8051 Family is a single stage linear inverter (Figure 2-32), intended for use as a crystal-controlled, positive reactance oscillator (Figure 2-33). In this application the crystal is operated in its fundamental response mode as an inductive reactance in parallel resonance with capacitance external to the crystal.

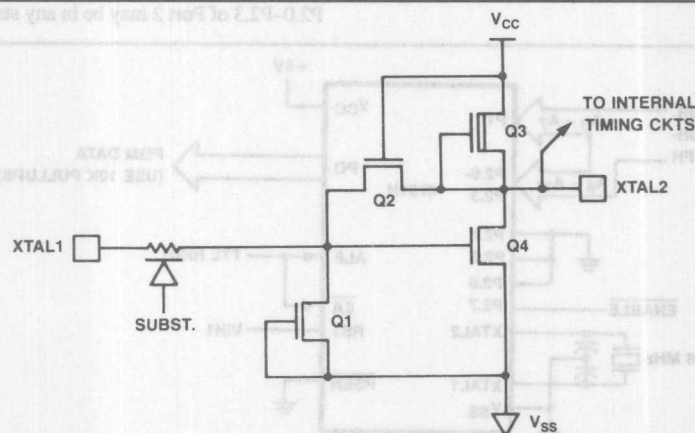


Figure 2-32. On-Chip Oscillator Circuitry in the NMOS Versions of the 8051 Family

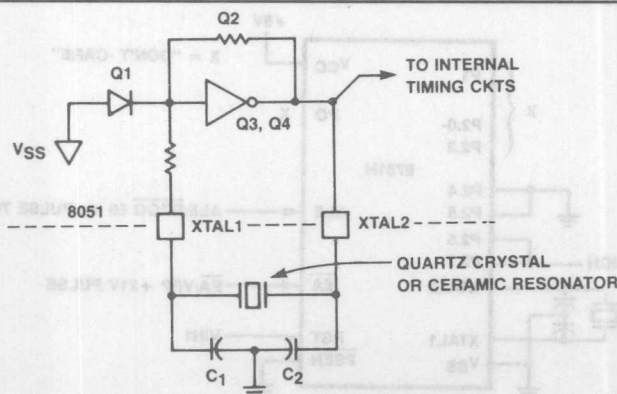


Figure 2-33. Using the NMOS On-Chip Oscillator

The crystal specifications and capacitance values (C1 and C2 in Figure 2-33) are not critical. 30 pF can be used in these positions at any frequency with good quality crystals. A ceramic resonator can be used in place of the crystal in cost-sensitive applications. When a ceramic resonator is used, C1 and C2 are normally selected to be of somewhat higher values, typically, 47 pF. The manufacturer of the ceramic resonator should be consulted for recommendations on the values of these capacitors.

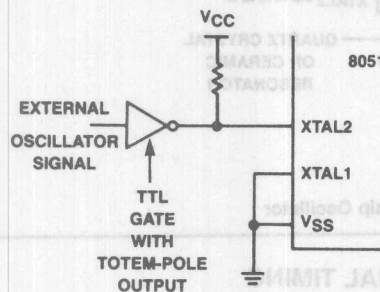


Figure 2-34. Driving the NMOS 8051 Family Parts with an External Clock Source

To drive the NMOS parts with an external clock source, apply the external clock signal to XTAL2, and ground XTAL1, as shown in Figure 2-34. A pull-up resistor may be used (to increase noise margin), but is optional if V_{OH} of the driving gate exceeds the V_{IH}_{MIN} specification of XTAL2.

CMOS

The on-chip oscillator circuitry for the 80C51, shown in Figure 2-35, consists of a single-stage linear inverter intended for use as crystal-controlled, positive reactance oscillator in the same manner as the NMOS parts. However, there are some important differences.

One difference is that the 80C51 is able to turn off its oscillator under software control (by writing a 1 to the PD bit in PCON). Another difference is that in the 80C51 the internal clocking circuitry is driven by the signal at XTAL1, whereas in the NMOS versions it is by the signal at XTAL2.

The feedback resistor R_f in Figure 2-35 consists of paralleled n- and p-channel FETs controlled by the PD bit, such that R_f is opened when PD = 1. The diodes D1 and D2, which act as clamps to VCC and VSS, are parasitic to the R_f FETs.

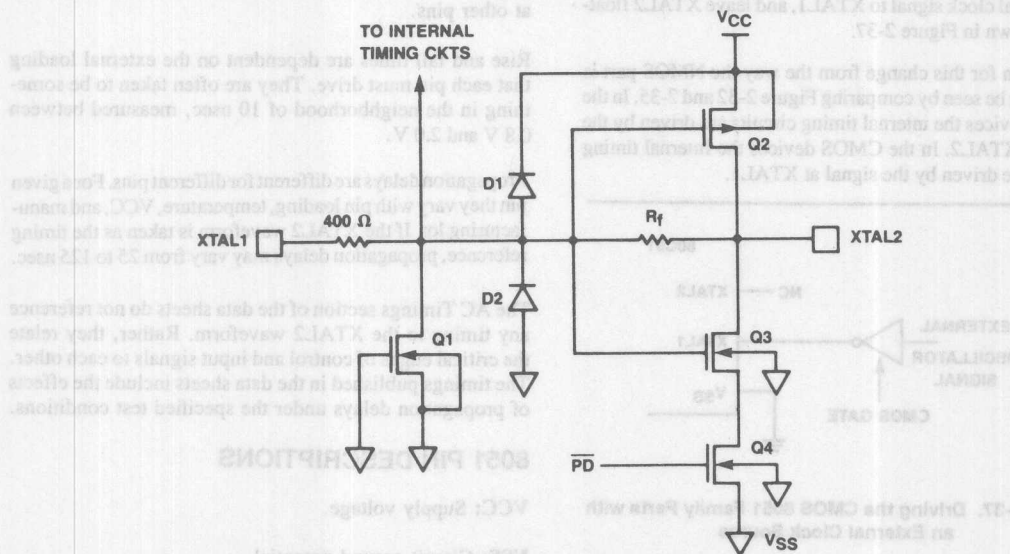


Figure 2-35. On-Chip Oscillator Circuitry in the CMOS Versions of the 8051 Family

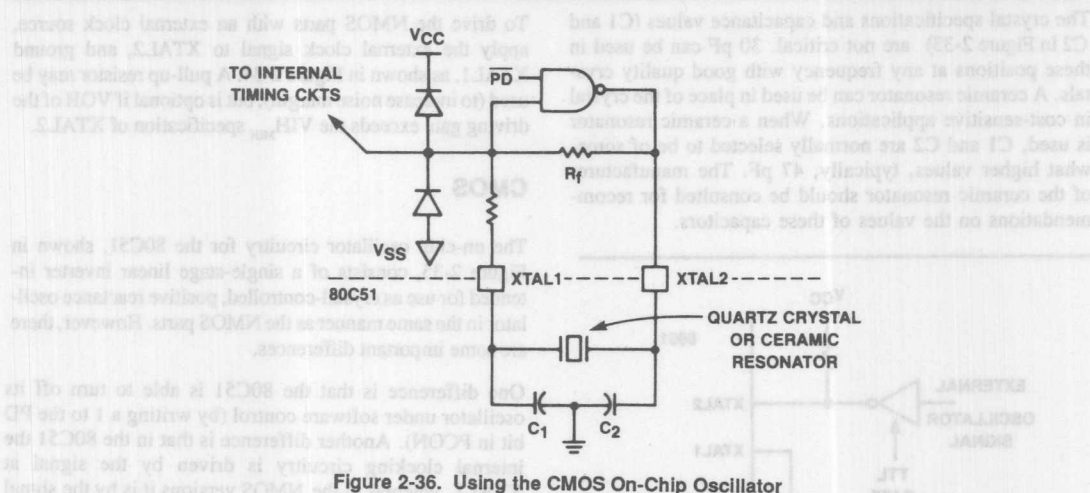


Figure 2-36. Using the CMOS On-Chip Oscillator

The oscillator can be used with the same external components as the NMOS versions, as shown in Figure 2-36. Typically, $C1 = C2 = 30 \text{ pF}$ when the feedback element is a quartz crystal, and $C1 = C2 = 47 \text{ pF}$ when a ceramic resonator is used.

To drive the CMOS parts with an external clock source, apply the external clock signal to XTAL1, and leave XTAL2 floating as shown in Figure 2-37.

The reason for this change from the way the NMOS part is driven can be seen by comparing Figure 2-32 and 2-35. In the NMOS devices the internal timing circuits are driven by the signal at XTAL2. In the CMOS devices the Internal timing circuits are driven by the signal at XTAL1.

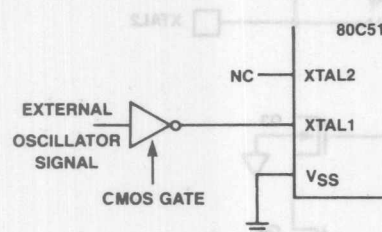


Figure 2-37. Driving the CMOS 8051 Family Parts with an External Clock Source

INTERNAL TIMING

Figures 2-38 through 2-41 show when the various strobe and port signals are clocked internally. The figures do not show rise and fall times of the signals, nor do they show propagation delays between the XTAL2 signal and events at other pins.

Rise and fall times are dependent on the external loading that each pin must drive. They are often taken to be something in the neighborhood of 10 nsec, measured between 0.8 V and 2.0 V.

Propagation delays are different for different pins. For a given pin they vary with pin loading, temperature, VCC, and manufacturing lot. If the XTAL2 waveform is taken as the timing reference, propagation delays may vary from 25 to 125 nsec.

The AC Timings section of the data sheets do not reference any timing to the XTAL2 waveform. Rather, they relate the critical edges of control and input signals to each other. The timings published in the data sheets include the effects of propagation delays under the specified test conditions.

8051 PIN DESCRIPTIONS

VCC: Supply voltage.

VSS: Circuit ground potential.

Port 0: Port 0 is an 8-bit open drain bidirectional I/O port. As an open drain output port it can sink 8 LS TTL loads. Port 0 pins that have 1s written to them float, and in that state will function as high-impedance inputs. Port 0 is also

the multiplexed low-order address and data bus during accesses to external memory. In this application it uses strong internal pull-ups when emitting 1s. Port 0 also emits code bytes during program verification. In that application, external pull-ups are required.

Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. The port 1 output buffers can sink/source four LS TTL loads. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups, and in that state can be used as inputs. As inputs, Port 1 pins that are externally being pulled low will source current (IIL, on the data sheet) because of the internal pull-ups.

In the 8052, pins P1.0 and P1.1 also serve the alternate functions of T2 and T2EX. T2 is the Timer 2 external input. T2EX is the input through which a Timer 2 "capture" is triggered.

Port 2: Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. The Port 2 output buffers can sink/source four LS TTL loads. Port 2 emits the high-order address byte during accesses to external memory that use 16-bit addresses. In this application it uses the strong internal pull-ups when emitting 1s. Port 2 also receives the high-order address and control bits during 8751H programming and verification, and during program verification in the 8051AH.

Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. It also serves the functions of various special features of the 8051 Family, as listed below:

PORT PIN	ALTERNATE FUNCTION
P3.0	RXD (serial input port)
P3.1	TXD (serial output port)
P3.2	INT0 (external interrupt 0)
P3.3	INT1 (external interrupt 1)
P3.4	T0 (Timer 0 external input)
P3.5	T1 (Timer 1 external input)
P3.6	WR (external data memory write strobe)
P3.7	RD (external data memory read strobe)

The Port 3 output buffers can source/sink four LS TTL loads.

RST: Reset input. A high on this pin for two machine cycles while the oscillator is running resets the device.

ALE/PROG: Address Latch Enable is the output pulse for latching the low byte of the address during accesses to external memory. ALE is emitted at a constant rate of 1/6 of the oscillator frequency, for external timing or clocking purposes, even when there are no accesses to external memory. (However, one ALE pulse is skipped during each access to external Data Memory.) This pin is also the program pulse input (PROG) during EPROM programming.

PSEN: Program Store Enable is the read strobe to external Program Memory. When the device is executing out of external Program Memory, PSEN is activated twice each machine cycle (except that two PSEN activations are skipped during accesses to external Data Memory). PSEN is not activated when the device is executing out of internal Program Memory.

EA/VPP: When EA is held high the CPU executes out of internal Program Memory (unless the Program Counter exceeds 0FFFFH in the 8051AH, or 1FFFFH in the 8052). Holding EA low forces the CPU to execute out of external memory regardless of the Program Counter value. In the 8031AH and 8032, EA must be externally wired low. In the 8751H, this pin also receives the 21 V programming supply voltage (VPP) during EPROM programming.

XTAL1: Input to the inverting oscillator amplifier (NMOS devices only).

XTAL2: Output from the inverting oscillator amplifier (NMOS devices only).

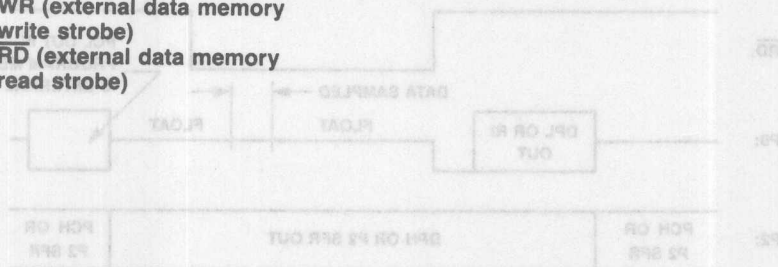


Figure 2-30. External Data Memory Read Cycle

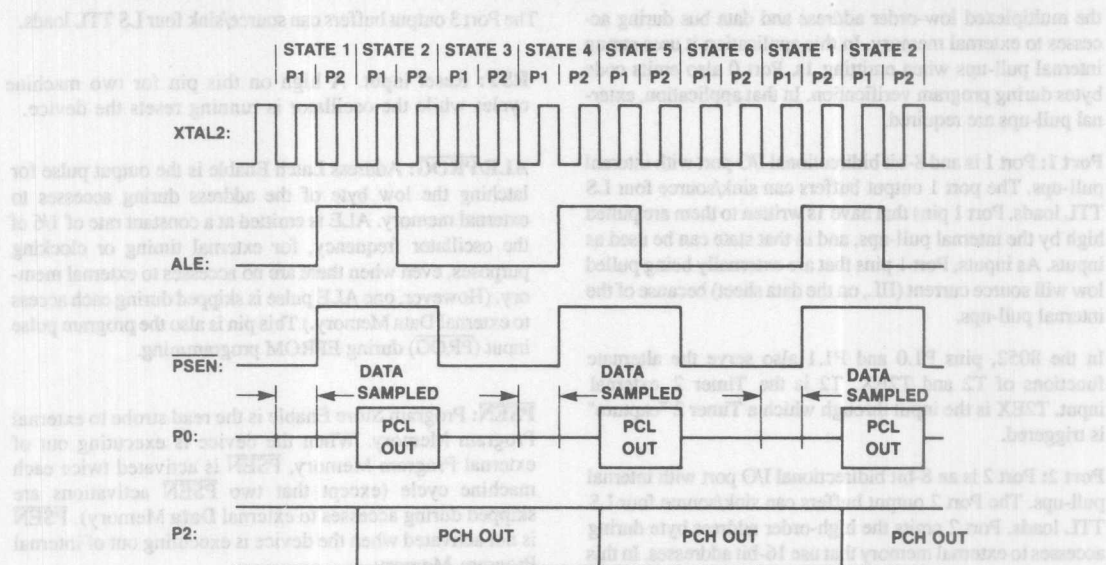


Figure 2-38. External Program Memory Fetches

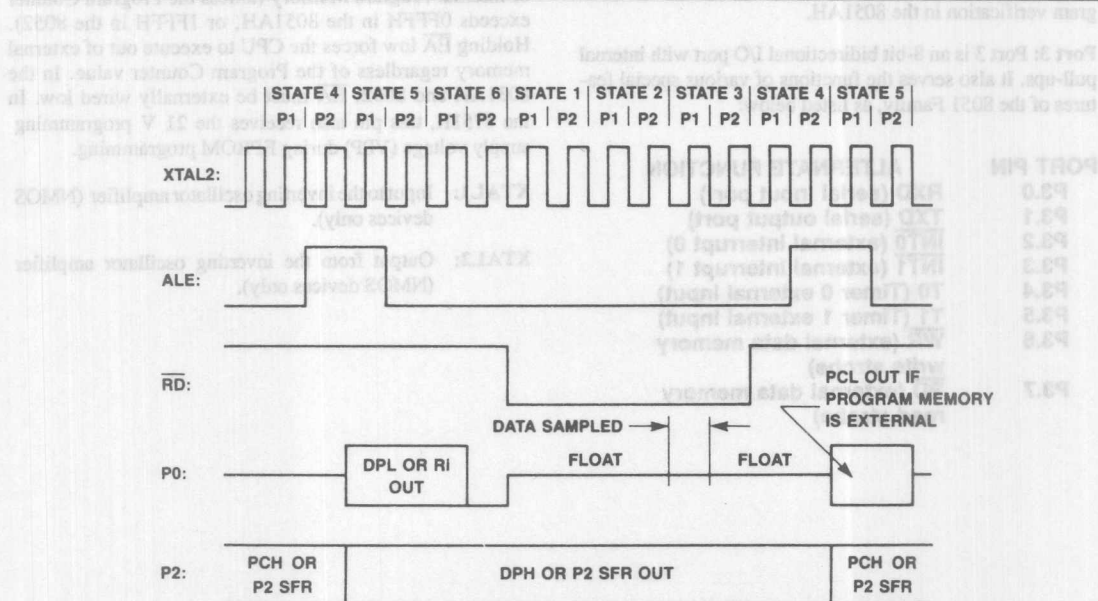


Figure 2-39. External Data Memory Read Cycle

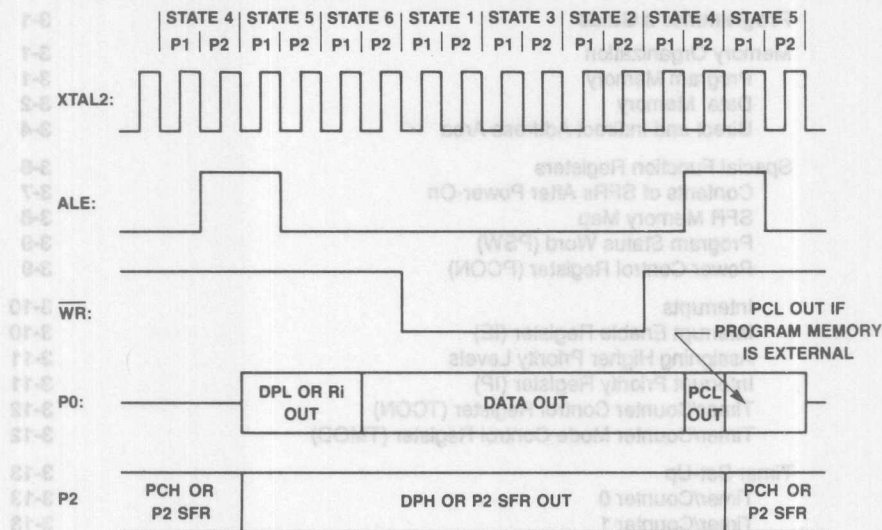


Figure 2-40. External Data Memory Write Cycle

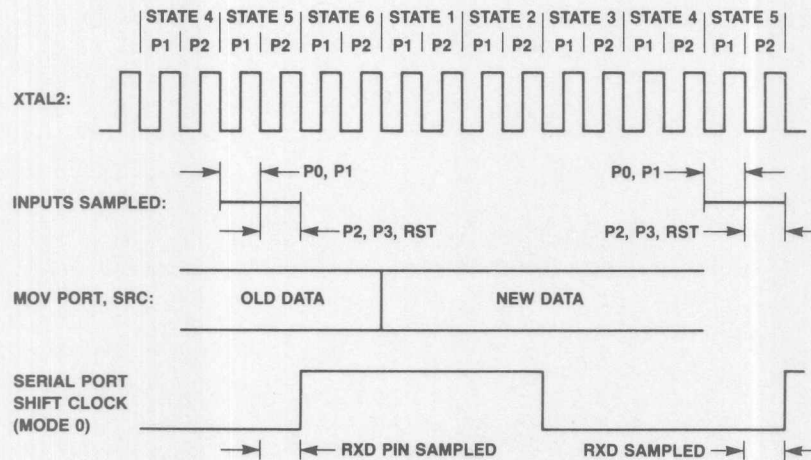


Figure 2-41. Port Operation

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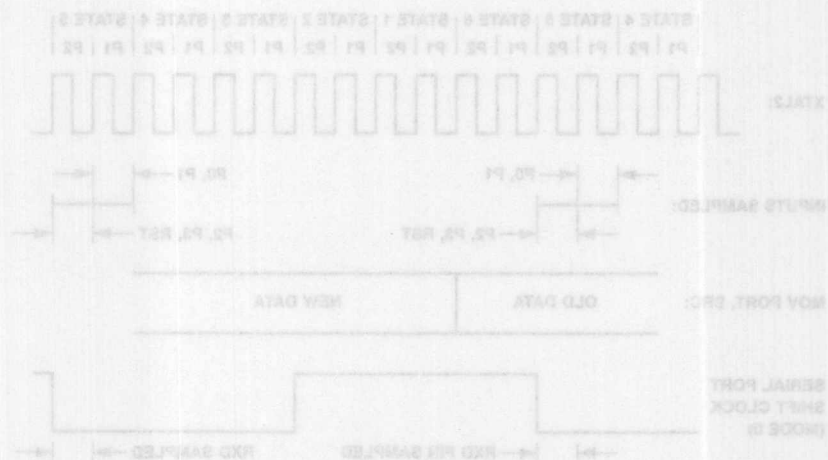


Figure 3-41. Port Operation

Programmer's Guide

INTRODUCTION

This chapter presents a programmer's reference guide to the "core" architecture of the 8051 Family. The description of the "8051" in this chapter applies to all 8051 Family members. The term "8052" is used to refer to an 8051AH with a double amount of ROM and RAM, and an extra timer called Timer 2. It is also included in this "core" discussion because its features are often found in other enhanced 8051 Family members. (See Members of the Family in Chapter 1).

MEMORY ORGANIZATION

Program Memory

The 8051 has separate address spaces for Program Memory and Data Memory. The Program Memory can be up to 64K bytes long. The lower 4K (8K for the 8052) may reside on-chip. Figure 3-1 shows a map of the 8051 program memory; Figure 3-2 shows a map of the 8052 program memory.

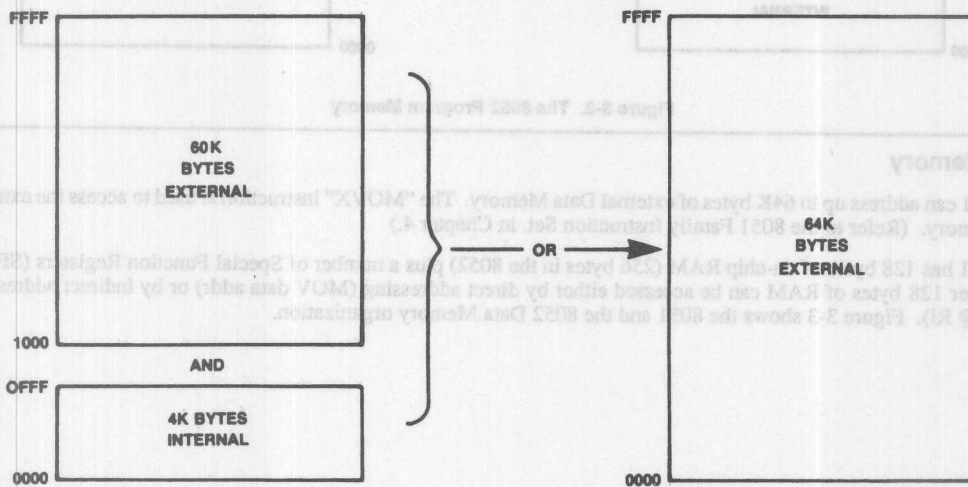


Figure 3-1. The 8051 Program Memory

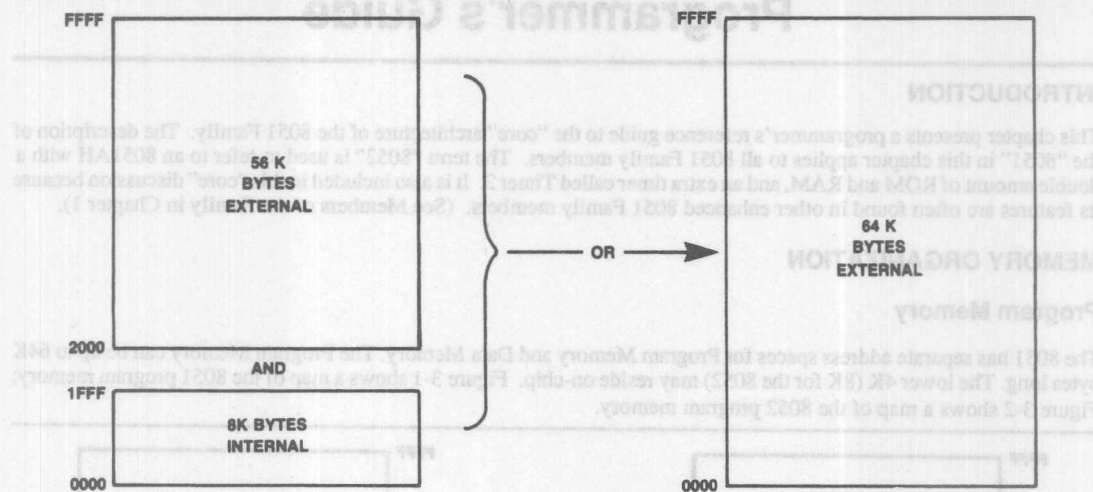


Figure 3-2. The 8052 Program Memory

Data Memory

The 8051 can address up to 64K bytes of external Data Memory. The "MOVX" instruction is used to access the external data memory. (Refer to the 8051 Family Instruction Set, in Chapter 4.)

The 8051 has 128 bytes of on-chip RAM (256 bytes in the 8052) plus a number of Special Function Registers (SFRs). The lower 128 bytes of RAM can be accessed either by direct addressing (MOV data addr) or by indirect addressing (MOV @ Ri). Figure 3-3 shows the 8051 and the 8052 Data Memory organization.

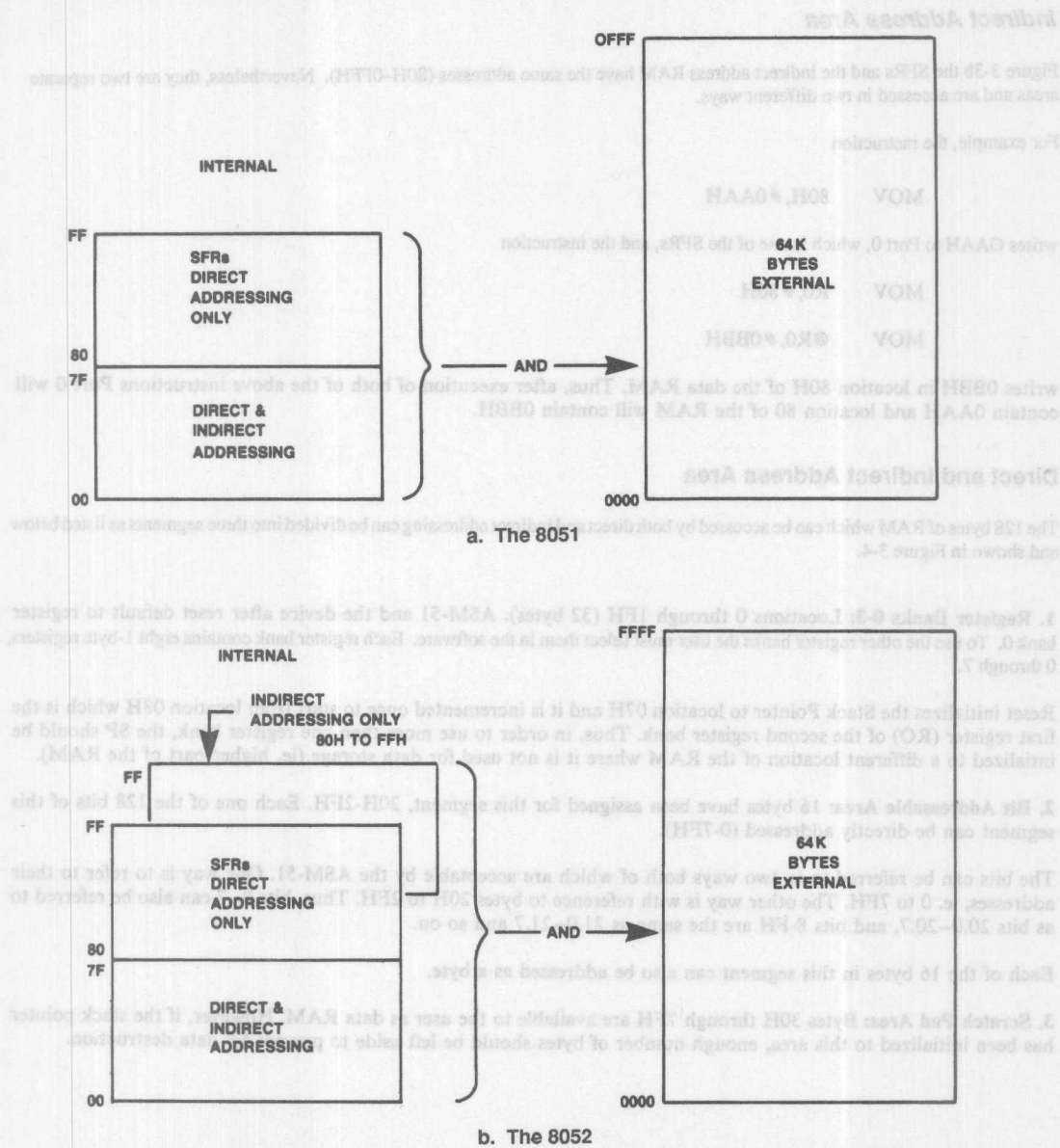


Figure 3-3. Data Memory

Indirect Address Area

Figure 3-3b the SFRs and the indirect address RAM have the same addresses (80H–0FFH). Nevertheless, they are two separate areas and are accessed in two different ways.

For example, the instruction

```
MOV    80H, #0AAH
```

writes 0AAH to Port 0, which is one of the SFRs, and the instruction

```
MOV    R0, #80H
```

```
MOV    @R0, #0BBH
```

writes 0BBH in location 80H of the data RAM. Thus, after execution of both of the above instructions Port 0 will contain 0AAH and location 80 of the RAM will contain 0BBH.

Direct and Indirect Address Area

The 128 bytes of RAM which can be accessed by both direct and indirect addressing can be divided into three segments as listed below and shown in Figure 3-4.

1. Register Banks 0-3: Locations 0 through 1FH (32 bytes). ASM-51 and the device after reset default to register bank 0. To use the other register banks the user must select them in the software. Each register bank contains eight 1-byte registers, 0 through 7.

Reset initializes the Stack Pointer to location 07H and it is incremented once to start from location 08H which is the first register (R0) of the second register bank. Thus, in order to use more than one register bank, the SP should be initialized to a different location of the RAM where it is not used for data storage (ie, higher part of the RAM).

2. Bit Addressable Area: 16 bytes have been assigned for this segment, 20H-2FH. Each one of the 128 bits of this segment can be directly addressed (0-7FH).

The bits can be referred to in two ways both of which are acceptable by the ASM-51. One way is to refer to their addresses, ie. 0 to 7FH. The other way is with reference to bytes 20H to 2FH. Thus, bits 0–7 can also be referred to as bits 20.0–20.7, and bits 8–FH are the same as 21.0–21.7 and so on.

Each of the 16 bytes in this segment can also be addressed as a byte.

3. Scratch Pad Area: Bytes 30H through 7FH are available to the user as data RAM. However, if the stack pointer has been initialized to this area, enough number of bytes should be left aside to prevent SP data destruction.

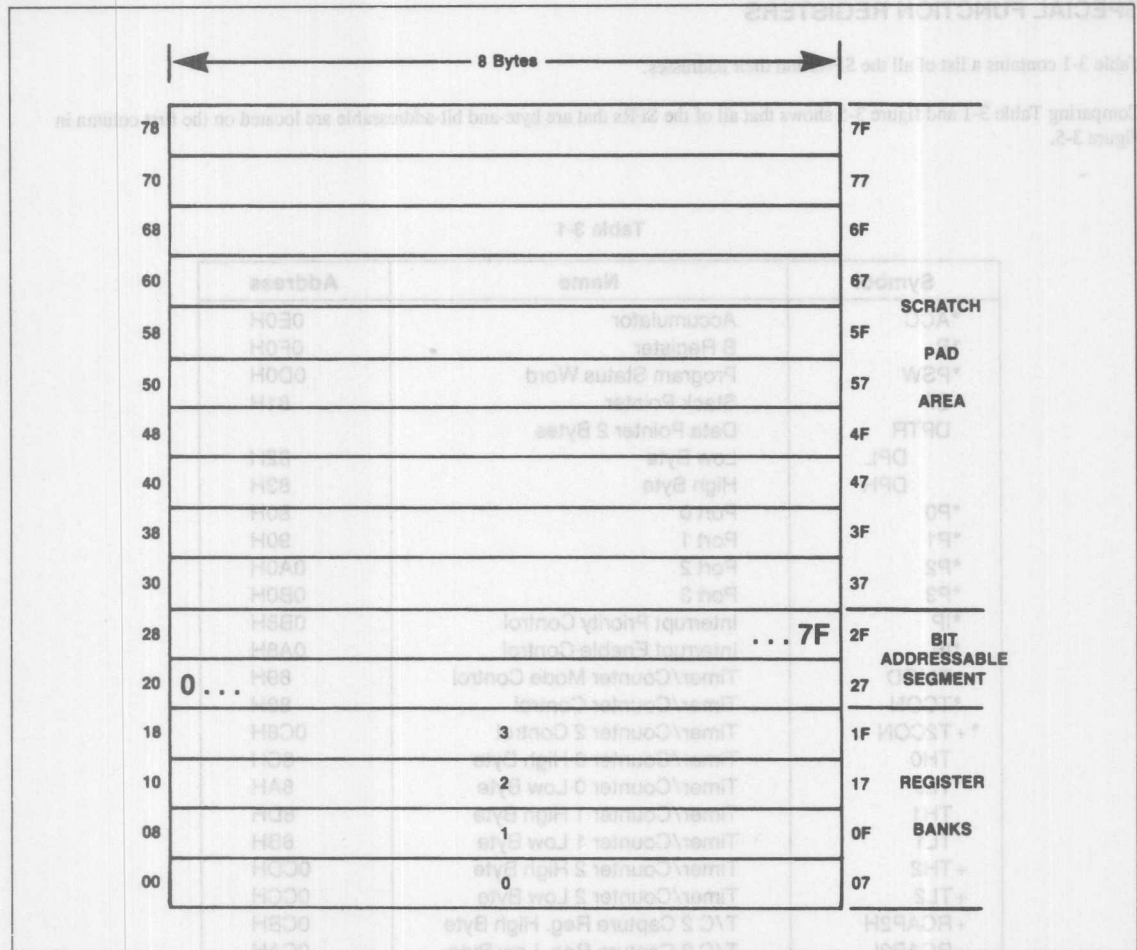


Figure 3-4. 128 Bytes of RAM Direct and Indirect Addressable

SPECIAL FUNCTION REGISTERS

Table 3-1 contains a list of all the SFRs and their addresses.

Comparing Table 3-1 and figure 3-5 shows that all of the SFRs that are byte- and bit-addressable are located on the first column in Figure 3-5.

Table 3-1

Symbol	Name	Address
*ACC	Accumulator	0E0H
*B	B Register	0F0H
*PSW	Program Status Word	0D0H
SP	Stack Pointer	81H
DPTR	Data Pointer 2 Bytes	
DPL	Low Byte	82H
DPH	High Byte	83H
*P0	Port 0	80H
*P1	Port 1	90H
*P2	Port 2	0A0H
*P3	Port 3	0B0H
*IP	Interrupt Priority Control	0B8H
*IE	Interrupt Enable Control	0A8H
TMOD	Timer/Counter Mode Control	89H
*TCON	Timer/Counter Control	88H
*+ T2CON	Timer/Counter 2 Control	0C8H
TH0	Timer/Counter 0 High Byte	8CH
TL0	Timer/Counter 0 Low Byte	8AH
TH1	Timer/Counter 1 High Byte	8DH
TL1	Timer/Counter 1 Low Byte	8BH
+ TH2	Timer/Counter 2 High Byte	0CDH
+ TL2	Timer/Counter 2 Low Byte	0CCH
+ RCAP2H	T/C 2 Capture Reg. High Byte	0CBH
+ RCAP2L	T/C 2 Capture Reg. Low Byte	0CAH
*SCON	Serial Control	98H
SBUF	Serial Data Buffer	99H
PCON	Power Control	87H

* = Bit addressable

+ = 8052 only

What Do the SFRs Contain Just After Power-on or a Reset?

Table 3-2 lists the contents of each SFR after power-on or a hardware reset.

Table 3-2. Contents of the SFRs After Reset

Register	Value in Binary
*ACC	00000000
*B	00000000
*PSW	00000000
SP	00001111
DPTR	
DPH	00000000
DPL	00000000
*P0	11111111
*P1	11111111
*P2	11111111
*P3	11111111
*IP	8051 XXX00000, 8052 XX000000
*IE	8051 0XX00000, 8052 0X000000
TMOD	00000000
*TCON	00000000
*+ T2CON	00000000
TH0	00000000
TL0	00000000
TH1	00000000
TL1	00000000
+ TH2	00000000
+ TL2	00000000
+ RCAP2H	00000000
+ RCAP2L	00000000
*SCON	00000000
SBUF	Indeterminate
PCON	NMOS 0XXXXXXX CMOS 0XXX0000

- X = Undefined
 * = Bit Addressable
 + = 8052 only

SFR Memory Map

8 Bytes							
F8							FF
F0	B						F7
E8							EF
E0	ACC						E7
D8							DF
D0	PSW						D7
C8	T2CON		RCAP2L	RCAP2H	TL2	TH2	CF
C0							C7
B8	IP						BF
B0	P3						B7
A8	IE						AF
A0	P2						A7
98	SCON	SBUF					9F
90	P1						97
88	TCON	TMOD	TL0	TL1	TH0	TH1	8F
80	P0	SP	DPL	DPH			87

Figure 3-5. Memory Map

↑
Bit
Addressable

Those SFRs that have their bits assigned for various functions are listed in this section. A brief description of each bit is provided for quick reference. For more detailed information refer to Architecture, Chapter 2.

PSW: Program Status Word. Bit Addressable.

CY	AC	F0	RS1	RS0	OV	—	P
CY	PSW.7	Carry Flag.					
AC	PSW.6	Auxiliary Carry Flag.					
F0	PSW.5	Flag 0 available to the user for general purpose.					
RS1	PSW.4	Register Bank selector bit 1 (SEE NOTE 1).					
RS0	PSW.3	Register Bank selector bit 0 (SEE NOTE 1).					
OV	PSW.2	Overflow Flag.					
—	PSW.1	Not implemented, reserved for future use.*					
P	PSW.0	Parity flag. Set/cleared by hardware each instruction cycle to indicate an odd/even number of '1' bits in the accumulator.					

NOTE:

1. The value presented by RS0 and RS1 selects the corresponding register bank.

RS1	RS0	Register Bank	Address
0	0	0	00H-07H
0	1	1	08H-0FH
1	0	2	10H-17H
1	1	3	18H-1FH

*User software should not write 1s to reserved bits. These bits may be used in future 8051 Family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1.

PCON: Power Control Register. Not Bit Addressable.

SMOD	—	—	—	GF1	GF0	PD	IDL
------	---	---	---	-----	-----	----	-----

SMOD Double baud rate bit. If Timer 1 is used to generate baud rate and SMOD = 1, the baud rate is doubled when the Serial Port is used in modes 1, 2, or 3.

— Not implemented, reserved for future use.*

— Not implemented, reserved for future use.*

— Not implemented, reserved for future use.*

GF1 General purpose flag bit.

GF0 General purpose flag bit.

PD Power Down bit. Setting this bit activates Power Down operation in the 80C51BH. (Available only in CMOS).

IDL Idle Mode bit. Setting this bit activates Idle Mode operation in the 80C51BH. (Available only in CMOS).

If 1s are written to PD and IDL at the same time, PD takes precedence.

*User software should not write 1s to reserved bits. These bits may be used in future 8051 Family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1.

Interrupts

In order to use any of the interrupts in the 8051 Family, the following three steps must be taken.

1. Set the EA (enable all) bit in the IE register to 1.
2. Set the corresponding individual interrupt enable bit in the IE register to 1.
3. Begin the interrupt service routine at the corresponding Vector Address of that interrupt. See Table below.

Interrupt Source	Vector Address
IE0	0003H
TF0	000BH
IE1	0013H
TF1	001BH
RI & TI	0023H
TF2 & EXF2	002BH

In addition, for external interrupts, pins $\overline{\text{INT0}}$ and $\overline{\text{INT1}}$ (P3.2 and P3.3) must be set to 1, and depending on whether the interrupt is to be level or transition activated, bits IT0 or IT1 in the TCON register may need to be set to 1.

ITx = 0 level activated

ITx = 1 transition activated

IE: Interrupt Enable Register. Bit Addressable.

If the bit is 0, the corresponding interrupt is disabled. If the bit is 1, the corresponding interrupt is enabled.

EA	—	ET2	ES	ET1	EX1	ET0	EX0
----	---	-----	----	-----	-----	-----	-----

EA	IE.7	Disables all interrupts. If EA = 0, no interrupt will be acknowledged. If EA = 1, each interrupt source is individually enabled or disabled by setting or clearing its enable bit.
—	IE.6	Not implemented, reserved for future use.*
ET2	IE.5	Enable or disable the Timer 2 overflow or capture interrupt (8052 only).
ES	IE.4	Enable or disable the serial port interrupt.
ET1	IE.3	Enable or disable the Timer 1 overflow interrupt.
EX1	IE.2	Enable or disable External Interrupt 1.
ET0	IE.1	Enable or disable the Timer 0 overflow interrupt.
EX0	IE.0	Enable or disable External Interrupt 0.

*User software should not write 1s to reserved bits. These bits may be used in future 8051 Family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1.

Assigning Higher Priority to One or More Interrupts

In order to assign higher priority to an interrupt the corresponding bit in the IP register must be set to 1.

Remember that while an interrupt service is in progress, it cannot be interrupted by a lower or same level interrupt.

Priority Within Level

Priority within level is only to resolve simultaneous requests of the same priority level.

From high to low, interrupt sources are listed below:

IE0
TF0
IE1
TF1
RI or TI
TF2 or EXF2

IP: Interrupt Priority Register. Bit Addressable

If the bit is 0, the corresponding interrupt has a lower priority; if the bit is 1 the corresponding interrupt has a higher priority.

		PT2	PS	PT1	PX1	PT0	PX0
—	IP. 7 Not implemented, reserved for future use.*						
—	IP. 6 Not implemented, reserved for future use.*						
PT2	IP. 5 Defines the Timer 2 interrupt priority level (8052 only).						
PS	IP. 4 Defines the Serial Port interrupt priority level.						
PT1	IP. 3 Defines the Timer 1 interrupt priority level.						
PX1	IP. 2 Defines External Interrupt 1 priority level.						
PT0	IP. 1 Defines the Timer 0 interrupt priority level.						
PX0	IP. 0 Defines the External Interrupt 0 priority level.						

*User software should not write 1s to reserved bits. These bits may be used in future 8051 Family products to invoke new features. In that case, the reset or inactive value of the new bit will be 0, and its active value will be 1.

TCON: Timer/Counter Control Register. Bit Addressable

TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0
-----	-----	-----	-----	-----	-----	-----	-----

- TF1 TCON. 7 Timer 1 overflow flag. Set by hardware when the Timer/Counter 1 overflows. Cleared by hardware as processor vectors to the interrupt service routine.
- TR1 TCON. 6 Timer 1 run control bit. Set/cleared by software to turn Timer/Counter 1 ON/OFF.
- TF0 TCON. 5 Timer 0 overflow flag. Set by hardware when the Timer/Counter 0 overflows. Cleared by hardware as processor vectors to the service routine.
- TR0 TCON. 4 Timer 0 run control bit. Set/cleared by software to turn Timer/Counter 0 ON/OFF.
- IE1 TCON. 3 External Interrupt 1 edge flag. Set by hardware when External Interrupt edge is detected. Cleared by hardware when interrupt is processed.
- IT1 TCON. 2 Interrupt 1 type control bit. Set/cleared by software to specify falling edge/low level triggered External Interrupt.
- IE0 TCON. 1 External Interrupt 0 edge flag. Set by hardware when External Interrupt edge detected. Cleared by hardware when interrupt is processed.
- IT0 TCON. 0 Interrupt 0 type control bit. Set/cleared by software to specify falling edge/low level triggered External Interrupt.

TMOD: Timer/Counter Mode Control Register. Not Bit Addressable

GATE	C/ \bar{T}	M1	M0	GATE	C/ \bar{T}	M1	M0
------	--------------	----	----	------	--------------	----	----

TIMER 1

TIMER 0

- GATE When TR_x (in TCON) is set and GATE = 1, TIMER/COUNTER_x will run only while INT_x pin is high (hardware control). When GATE = 0, TIMER/COUNTER_x will run only while TR_x = 1 (software control).
- C/ \bar{T} Timer or Counter selector. Cleared for Timer operation (input from internal system clock). Set for Counter operation (input from Tx input pin).
- M1 Mode selector bit. (NOTE 1)
- M0 Mode selector bit. (NOTE 1)

NOTE 1:

M1	M0	Operating Mode
0	0	0 13-bit Timer (8048 Family compatible)
0	1	1 16-bit Timer/Counter
1	0	2 8-bit Auto-Reload Timer/Counter
1	1	3 (Timer 0) TL0 is an 8-bit Timer/Counter controlled by the standard Timer 0 control bits, TH0 is an 8-bit Timer and is controlled by Timer 1 control bits.
1	1	3 (Timer 1) Timer/Counter 1 stopped.

TIMER SET-UP

Tables 3-3 through 3-6 give some values for TMOD which can be used to set up Timer 0 in different modes.

It is assumed that only one timer is being used at a time. If it is desired to run Timer 0 and 1 simultaneously, in any mode, the value in TMOD for Timer 0 must be Ored with the value shown for Timer 1 (Tables 3-5 and 3-6).

For example, if it is desired to run Timer 0 in mode 1 GATE (external control), and Timer 1 in mode 2 COUNTER, then the value that must be loaded into TMOD is 69H (09H from Table 3-3 Ored with 60H from Table 3-6).

Moreover, it is assumed that the user, at this point, is not ready to turn the timers on and will do that at a different point in the program by setting bit TRx (in TCON) to 1.

Timer/Counter 0

As a Timer:

Table 3-3

MODE	TIMER 0 FUNCTION	TMOD	
		INTERNAL CONTROL (NOTE 1)	EXTERNAL CONTROL (NOTE 2)
0	13-bit Timer	00H	08H
1	16-bit Timer	01H	09H
2	8-bit Auto-Reload	02H	0AH
3	two 8-bit Timers	03H	0BH

As a Counter:

Table 3-4

MODE	COUNTER 0 FUNCTION	TMOD	
		INTERNAL CONTROL (NOTE 1)	EXTERNAL CONTROL (NOTE 2)
0	13-bit Timer	04H	0CH
1	16-bit Timer	05H	0DH
2	8-bit Auto-Reload	06H	0EH
3	one 8-bit Counter	07H	0FH

NOTES:

1. The Timer is turned ON/OFF by setting/clearing bit TR0 in the software.
2. The Timer is turned ON/OFF by the 1 to 0 transition on $\overline{INT0}$ (P3.2) when TR0 = 1 (hardware control).

Timer/Counter 1

As a Timer:

Table 3-5

MODE	TIMER 1 FUNCTION	TMOD	
		INTERNAL CONTROL (NOTE 1)	EXTERNAL CONTROL (NOTE 2)
0	13-bit Timer	00H	80H
1	16-bit Timer	10H	90H
2	8-bit Auto-Reload	20H	A0H
3	does not run	30H	B0H

As a Counter:

Table 3-6

MODE	COUNTER 1 FUNCTION	TMOD	
		INTERNAL CONTROL (NOTE 1)	EXTERNAL CONTROL (NOTE 2)
0	13-bit Timer	40H	C0H
1	16-bit Timer	50H	D0H
2	8-bit Auto-Reload	60H	E0H
3	not available	—	—

NOTES:

1. The Timer is turned ON/OFF by setting/clearing bit TR1 in the software.
2. The timer is turned ON/OFF by the 1-to-0 transition on INT1 (P3.3) when TR1 = 1 (hardware control).

T2CON: TIMER/COUNTER 2 CONTROL REGISTER. BIT ADDRESSABLE.

8052 Only

TF2	EXF2	RCLK	TCLK	EXEN2	TR2	C/T2	CP/RL2
-----	------	------	------	-------	-----	------	--------

TF2	T2CON. 7	Timer 2 overflow flag set by hardware and cleared by software. TF2 cannot be set when either RCLK = 1 or CLK = 1					
EXF2	T2CON. 6	Timer 2 external flag set when either a capture or reload is caused by a negative transition on T2EX, and EXEN2 = 1. When Timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the Timer 2 interrupt routine. EXF2 must be cleared by software.					
RCLK	T2CON. 5	Receive clock flag. When set, causes the Serial Port to use Timer 2 overflow pulses for its receive clock in modes 1 & 3. RCLK = 0 causes Timer 1 overflow to be used for the receive clock.					
TCLK	T2CON. 4	Transmit clock flag. When set, causes the Serial Port to use Timer 2 overflow pulses for its transmit clock in modes 1 & 3. TCLK = 0 causes Timer 1 overflows to be used for the transmit clock.					
EXEN2	T2CON. 3	Timer 2 external enable flag. When set, allows a capture or reload to occur as a result of negative transition on T2EX if Timer 2 is not being used to clock the Serial Port. EXEN2 = 0 causes Timer 2 to ignore events at T2EX.					
TR2	T2CON. 2	Software START/STOP control for Timer 2. A logic 1 starts the Timer.					
C/T2	T2CON. 1	Timer or Counter select. 0 = Internal Timer. 1 = External Event Counter (falling edge triggered).					
CP/RL2	T2CON. 0	Capture/Reload flag. When set, captures will occur on negative transitions at T2EX if EXEN2 = 1. When cleared, Auto-Reloads will occur either with Timer 2 overflows or negative transitions at T2EX when EXEN2 = 1. When either RCLK = 1 or TCLK = 1, this bit is ignored and the Timer is forced to Auto-Reload on Timer 2 overflow.					

(NOTE 2)	(NOTE 1)	
HA0	HS0	16-bit Auto-Reload
HS0	HS0	16-bit Capture

NOTES:
1. Capture/Reload occurs only on Timer/Counter overflow.
2. Capture/Reload occurs on Timer/Counter overflow and a 1 to 0 transition on T2EX.
(P1.1) pin except when Timer 2 is used in the baud rate generating mode.

Timer/Counter 2 Set-up

Except for the baud rate generator mode, the values given for T2CON do not include the setting of the TR2 bit. Therefore, bit TR2 must be set separately to turn the Timer on.

As a Timer:

Table 3-7

MODE	T2CON	
	INTERNAL CONTROL (NOTE 1)	EXTERNAL CONTROL (NOTE 2)
16-bit Auto-Reload	00H	08H
16-bit Capture	01H	09H
BAUD rate generator receive & transmit same baud rate	34H	36H
receive only	24H	26H
transmit only	14H	16H

As a Counter:

Table 3-8

MODE	TMOD	
	INTERNAL CONTROL (NOTE 1)	EXTERNAL CONTROL (NOTE 2)
16-bit Auto-Reload	02H	0AH
16-bit Capture	03H	0BH

NOTES:

1. Capture/Reload occurs only on Timer/Counter overflow.
2. Capture/Reload occurs on Timer/Counter overflow and a 1 to 0 transition on T2EX (P1.1) pin except when Timer 2 is used in the baud rate generating mode.

SCON: SERIAL PORT CONTROL REGISTER. BIT ADDRESSABLE.

SM0	SM1	SM2	REN	TB8	RB8	TI	RI
-----	-----	-----	-----	-----	-----	----	----

SM0	SCON. 7	Serial Port mode specifier. (NOTE 1).
SM1	SCON. 6	Serial Port mode specifier. (NOTE 1).
SM2	SCON. 5	Enables the multiprocessor communication feature in modes 2 & 3. In mode 2 or 3, if SM2 is set to 1 then RI will not be activated if the received 9th data bit (RB8) is 0. In mode 1, if SM2 = 1 then RI will not be activated if a valid stop bit was not received. In mode 0, SM2 should be 0. (See Table 9).
REN	SCON. 4	Set/Cleared by software to Enable/Disable reception.
TB8	SCON. 3	The 9th bit that will be transmitted in modes 2 & 3. Set/Cleared by software.
RB8	SCON. 2	In modes 2 & 3, is the 9th data bit that was received. In mode 1, if SM2 = 0, RB8 is the stop bit that was received. In mode 0, RB8 is not used.
TI	SCON. 1	Transmit interrupt flag. Set by hardware at the end of the 8th bit time in mode 0, or at the beginning of the stop bit in the other modes. Must be cleared by software.
RI	SCON. 0	Receive interrupt flag. Set by hardware at the end of the 8th bit time in mode 0, or halfway through the stop bit time in the other modes (except see SM2). Must be cleared by software.

NOTE 1:

SM0	SM1	Mode	Description	Baud Rate
0	0	0	SHIFT REGISTER	Fosc./12
0	1	1	8-Bit UART	Variable
1	0	2	9-Bit UART	Fosc./64 OR
				Fosc./32
1	1	3	9-Bit UART	Variable

Serial Port Set-up

Table 3-9

MODE	SCON	SM2 VARIATION
0	10H	Single Processor Environment (SM2 = 0)
1	50H	
2	90H	
3	D0H	
0	NA	Multiprocessor Environment (SM2 = 1)
1	70H	
2	B0H	
3	F0H	

GENERATING BAUD RATES

Serial Port in Mode 0

Mode 0 has a fixed baud rate which is 1/12 of the oscillator frequency. To run the serial port in this mode none of the Timer/Counters need to be set up. Only the SCON register needs to be defined.

$$\text{Baud Rate} = \frac{\text{Osc Freq}}{12}$$

Serial Port in Mode 1

Mode 1 has a variable baud rate. The baud rate can be generated by either Timer 1 or Timer 2 (8052 only).

Using Timer/Counter 1 to Generate Baud Rates:

For this purpose, Timer 1 is used in mode 2 (Auto-Reload). Refer to Timer Setup section of this chapter.

$$\text{Baud Rate} = \frac{K \times \text{Oscillator Freq.}}{32 \times 12 \times [256 - (\text{TH1})]}$$

If SMOD = 0, then K = 1.

If SMOD = 1, then K = 2. (SMOD is the PCON register).

Most of the time the user knows the baud rate and needs to know the reload value for TH1. Therefore, the equation to calculate TH1 can be written as:

$$\text{TH1} = 256 - \frac{K \times \text{Osc Freq.}}{384 \times \text{baud rate}}$$

TH1 must be an integer value. Rounding off TH1 to the nearest integer may not produce the desired baud rate. In this case, the user may have to choose another crystal frequency.

Since the PCON register is not bit addressable, one way to set the bit is logical ORing the PCON register. (ie, ORL PCON, #80H). The address of PCON is 87H.

Using Timer/Counter 2 to Generate Baud Rates:

For this purpose, Timer 2 must be used in the baud rate generating mode. Refer to Timer 2 Setup Table in this chapter. If Timer 2 is being clocked through pin T2 (P1.0) the baud rate is:

$$\text{Baud Rate} = \frac{\text{Timer 2 Overflow Rate}}{16}$$

And if it is being clocked internally the baud rate is:

$$\text{Baud Rate} = \frac{\text{Osc Freq}}{32 \times [65536 - (\text{RCAP2H}, \text{RCAP2L})]}$$

To obtain the reload value for RCAP2H and RCAP2L, the above equation can be rewritten as:

$$\text{RCAP2H}, \text{RCAP2L} = 65536 - \frac{\text{Osc Freq}}{32 \times \text{Baud Rate}}$$

Serial Port in Mode 2

The baud rate is fixed in this mode and is $\frac{1}{32}$ or $\frac{1}{64}$ of the oscillator frequency depending on the value of the SMOD bit in the PCON register.

In this mode none of the Timers are used and the clock comes from the internal phase 2 clock.

SMOD = 1, Baud Rate = $\frac{1}{32}$ Osc Freq.

SMOD = 0, Baud Rate = $\frac{1}{64}$ Osc Freq.

To set the SMOD bit: ORL PCON, #80H. The address of PCON is 87H.

Serial Port in Mode 3

The baud rate in mode 3 is variable and sets up exactly the same as in mode 1.

CHAPTER 4

Instruction Set

Program Status Word

Addressing Modes

Arithmetic Instructions

Logical Instructions

Data Transfers

Boolean Instructions

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Instruction Set Summary

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Instruction Set

INTRODUCTION

All members of the 8051 Family execute the same instruction set, optimized for 8-bit control applications. The instruction set provides a variety of fast addressing modes for accessing the internal RAM to facilitate byte operations on small data structures. It provides extensive support for one-bit variables as a separate data type, allowing direct bit manipulation in control and logic systems that require Boolean processing. An overview of the instruction set is presented below, with a brief description of how certain instructions might be used.

PROGRAM STATUS WORD

The Program Status Word (PSW) contains several status bits that reflect the current state of the CPU. The PSW, shown in Figure 4-1, resides in SFR space. It contains the Carry bit, the Auxiliary Carry (for BCD operations), the two register bank select bits, the Overflow flag, a Parity bit, and two user-definable status flags.

The Carry bit, other than serving the functions of a Carry bit in arithmetic operations, also serves as the "Accumulator" for a number of Boolean operations.

The bits RS0 and RS1 are used to select one of the four register banks shown in Figure 1-7. A number of instructions refer to these RAM locations as R0 through R7. The selection of which of the four banks is being referred to is made on the basis of the bits RS0 and RS1 at execution time.

The Parity bit reflects the number of 1s in the Accumulator: $P = 1$ if the Accumulator contains an odd number of 1s, and $P = 0$ if the Accumulator contains an even number of 1s. Thus the number of 1s in the Accumulator plus P is always even.

Two bits in the PSW are uncommitted and may be used as general purpose status flags.

ADDRESSING MODES

The addressing modes in the 8051 Family instruction set are as follows:

Direct Addressing

In direct addressing the operand is specified by an 8-bit address field in the instruction. Only internal Data RAM and SFRs can be directly addressed.

Indirect Addressing

In indirect addressing the instruction specifies a register which contains the address of the operand. Both internal and external RAM can be indirectly addressed.

The address register for 8-bit addresses can be R0 or R1 of the selected register bank, or the Stack Pointer. The address register for 16-bit addresses can only be the 16-bit "data pointer" register, DPTR.

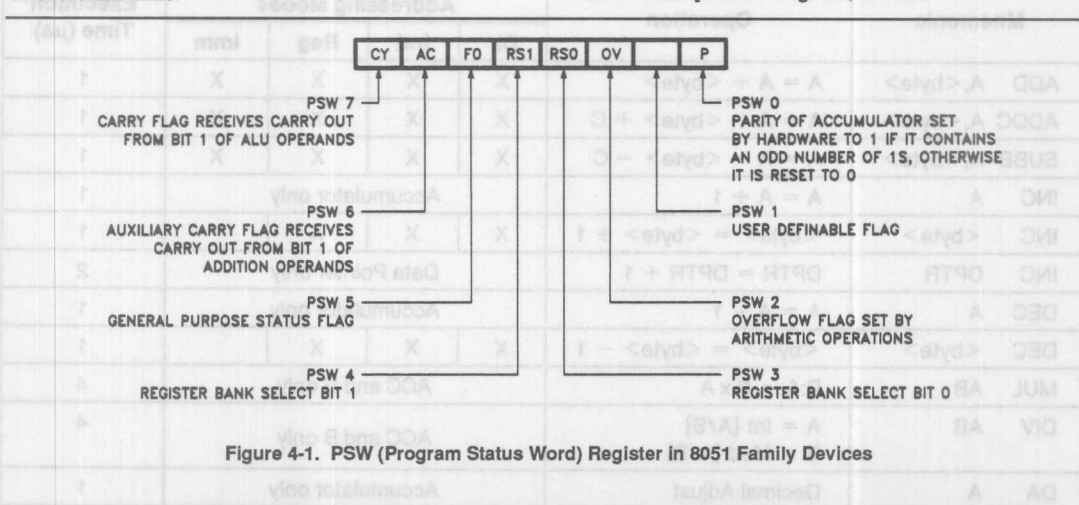


Figure 4-1. PSW (Program Status Word) Register in 8051 Family Devices

Register Instructions

The register banks, containing registers R0 through R7, can be accessed by certain instructions which carry a 3-bit register specification within the opcode of the instruction. Instructions that access the registers this way are code efficient, since this mode eliminates an address byte. When the instruction is executed, one of the eight registers in the selected bank is accessed. One of four banks is selected at execution time by the two bank select bits in the PSW.

Register-Specific Instructions

Some instructions are specific to a certain register. For example, some instructions always operate on the Accumulator, or Data Pointer, etc., so no address byte is needed to point to it. The opcode itself does that. Instructions that refer to the Accumulator as A assemble as accumulator-specific opcodes.

Immediate Constants

The value of a constant can follow the opcode in Program Memory. For example,

MOV A, #100
loads the Accumulator with the decimal number 100. The same number could be specified in hex digits as 64H.

Indexed Addressing

Only Program Memory can be accessed with indexed addressing, and it can only be read. This addressing mode is intended for reading look-up tables in Program Memory. A 16-bit base register (either DPTR or the Program Counter) points to the base of the table, and the Accumulator is set up with the table entry number. The address of the table entry in Program Memory is formed by adding the Accumulator data to the base pointer.

Another type of indexed addressing is used in the "case jump" instruction. In this case the destination address of a jump instruction is computed as the sum of the base pointer and the Accumulator data.

ARITHMETIC INSTRUCTIONS

The menu of arithmetic instructions is listed in Table 4-1. The table indicates the addressing modes that can be used with each instruction to access the <byte> operand. For example, the ADD A, <byte> instruction can be written as:

ADD A, 7FH (direct addressing)
ADD A, @R0 (indirect addressing)
ADD A, R7 (register addressing)
ADD A, #127 (immediate constant)

Table 4-1. A List of the 8051 Family Arithmetic Instructions

Mnemonic	Operation	Addressing Modes				Execution Time (μs)
		Dir	Ind	Reg	Imm	
ADD A, <byte>	A = A + <byte>	X	X	X	X	1
ADDC A, <byte>	A = A + <byte> + C	X	X	X	X	1
SUBB A, <byte>	A = A - <byte> - C	X	X	X	X	1
INC A	A = A + 1				Accumulator only	1
INC <byte>	<byte> = <byte> + 1	X	X	X		1
INC DPTR	DPTR = DPTR + 1				Data Pointer only	2
DEC A	A = A - 1				Accumulator only	1
DEC <byte>	<byte> = <byte> - 1	X	X	X		1
MUL AB	B:A = B x A				ACC and B only	4
DIV AB	A = Int [A/B] B = Mod [A/B]				ACC and B only	4
DA A	Decimal Adjust				Accumulator only	1

The execution times listed in Table 4-1 assume a 12MHz clock frequency. All of the arithmetic instructions execute in 1 μ s except the INC DPTR instruction, which takes 2 μ s, and the Multiply and Divide instructions, which take 4 μ s.

Note that any byte in the internal Data Memory space can be incremented or decremented without going through the Accumulator.

One of the INC instructions operates on the 16-bit Data Pointer. The Data Pointer is used to generate 16-bit addresses for external memory, so being able to increment it in one 16-bit operation is a useful feature.

The MUL AB instruction multiplies the Accumulator by the data in the B register and puts the 16-bit product into the concatenated B and Accumulator registers.

The DIV AB instruction divides the Accumulator by the data in the B register and leaves the 8-bit quotient in the Accumulator, and the 8-bit remainder in the B register.

Oddly enough, DIV AB finds less use in arithmetic "divide" routines than in radix conversions and programmable shift operations. An example of the use of DIV AB in a radix conversion will be given later. In

shift operations, dividing a number by 2^n shifts its n bits to the right. Using DIV AB to perform the division completes the shift in 4 μ s and leaves the B register holding the bits that were shifted out.

The DA A instruction is for BCD arithmetic operations. In BCD arithmetic, ADD and ADDC instructions should always be followed by a DA A operation, to ensure that the result is also in BCD. Note that DA A will not convert a binary number to BCD. The DA A operation produces a meaningful result only as the second step in the addition of two BCD bytes.

LOGICAL INSTRUCTIONS

Table 4-2 shows the list of 8051 Family logical instructions. The instructions that perform Boolean operations (AND, OR, Exclusive OR, NOT) on bytes perform the operation on a bit-by-bit basis. That is, if the Accumulator contains 00110101B and <byte> contains 01010011B, then

ANL A, <byte>

will leave the Accumulator holding 00010001B.

Table 4-2. A List of the 8051 Family Logical Instructions

Mnemonic	Operation	Addressing Modes				Execution Time (μ s)
		Dir	Ind	Reg	Imm	
ANL A, <byte>	A = A .AND. <byte>	X	X	X	X	1
ANL <byte>, A	<byte> = <byte> .AND. A	X				1
ANL <byte>, #data	<byte> = <byte> .AND. #data	X				2
ORL A, <byte>	A = A .OR. <byte>	X	X	X	X	1
ORL <byte>, A	<byte> = <byte> .OR. A	X				1
ORL <byte>, #data	<byte> = <byte> .OR. #data	X				2
XRL A, <byte>	A = A .XOR. <byte>	X	X	X	X	1
XRL <byte>, A	<byte> = <byte> .XOR. A	X				1
XRL <byte>, #data	<byte> = <byte> .XOR. #data	X				2
CRL A	A = 00H				Accumulator only	1
CPL A	A = .NOT. A				Accumulator only	1
RL A	Rotate ACC Left 1 bit				Accumulator only	1
RLC A	Rotate Left through Carry				Accumulator only	1
RR A	Rotate ACC Right 1 bit				Accumulator only	1
RRC A	Rotate Right through Carry				Accumulator only	1
SWAP A	Swap Nibbles in A				Accumulator only	1

The addressing modes that can be used to access the <byte> operand are listed in Table 3. Thus, the ANL A,<byte> instruction may take any of the forms

```
ANL  A,7FH      (direct addressing)
ANL  A,@R1      (indirect addressing)
ANL  A,R6        (register addressing)
ANL  A,#53H     (immediate constant)
```

All of the logical instructions that are Accumulator-specific execute in 1 μ s (using a 12 MHz clock). The others take 2 μ s.

Note that Boolean operations can be performed on any byte in the internal Data Memory space without going through the Accumulator. The XRL <byte>, #data instruction, for example, offers a quick and easy way to invert port bits, as in

```
XRL  P1,#0FFH
```

If the operation is in response to an interrupt, not using the Accumulator saves the time and effort to stack it in the service routine.

The Rotate instructions (RL A, RLC A, etc.) shift the Accumulator 1 bit to the left or right. For a left rotation, the MSB rolls into the LSB position. For a right rotation, the LSB rolls into the MSB position.

The SWAP A instruction interchanges the high and low nibbles within the Accumulator. This is a useful operation in BCD manipulations. For example, if the Accumulator contains a binary number which is known to be less than 100, it can be quickly converted to BCD by the following code:

```
MOV  B,#10
DIV  AB
SWAP A
ADD  A,B
```

Dividing the number by 10 leaves the tens digit in the low nibble of the Accumulator, and the ones digit in the B register. The SWAP and ADD instructions move the tens digit to the high nibble of the Accumulator, and the ones digit to the low nibble.

DATA TRANSFERS

Internal RAM

Table 4-3 shows the menu of instructions that are available for moving data around within the internal memory spaces, and the addressing modes that can be used with each one. With a 12 MHz clock, all of these instructions execute in either 1 or 2 μ s.

The MOV <dest>, <src> instruction allows data to be transferred between any two internal RAM or SFR locations without going through the Accumulator. Remember the Upper 128 bytes of data RAM can be accessed only by indirect addressing, and SFR space only by direct addressing.

Note that in all 8051 Family devices, the stack resides in on-chip RAM, and grows upwards. The PUSH instruction first increments the Stack Pointer (SP), then copies the byte into the stack. PUSH and POP use only direct addressing to identify the byte being saved or restored, but the stack itself is accessed by indirect addressing using the SP register. This means the stack can go into the Upper 128, if they are implemented, but not into SFR space.

Table 4-3. 8051 Family Data Transfer Instructions that Access Internal Data Memory Space

Mnemonic	Operation	Addressing Modes				Execution Time (μ s)
		Dir	Ind	Reg	Imm	
MOV A,<src>	A = <src>	X	X	X	X	1
MOV <dest>,A	<dest> = A	X	X	X		1
MOV <dest>,<src>	<dest> = <src>	X	X	X	X	2
MOV DPTR,#data16	DPTR = 16-bit immediate constant.				X	2
PUSH <src>	INC SP : MOV "@SP",<src>	X				2
POP <dest>	MOV <dest>,"@SP" : DEC SP	X				2
XCH A,<byte>	ACC and <byte> exchange data	X	X	X		1
XCHD A,@Ri	ACC and @Ri exchange low nibbles		X			1

		2A	2B	2C	2D	2E	ACC
MOV	A,2EH	00	12	34	56	78	78
MOV	2EH,2DH	00	12	34	56	56	78
MOV	2DH,2CH	00	12	34	34	56	78
MOV	2CH,2BH	00	12	12	34	56	78
MOV	2BH,#0	00	00	12	34	56	78

(a) Using direct MOVs: 14 bytes, 9 μ s

		2A	2B	2C	2D	2E	ACC
CLR	A	00	12	34	56	78	00
XCH	A,2BH	00	00	34	56	78	12
XCH	A,2CH	00	00	12	56	78	34
XCH	A,2DH	00	00	12	34	78	56
XCH	A,2EH	00	00	12	34	56	78

(b) Using XCHs: 9 bytes, 5 μ s

Figure 4-2. Shifting a BCD Number
Two Digits to the Right

The Upper 128 are not implemented in 8051 Family devices with 128 bytes of RAM. With these devices, if the SP points to the Upper 128, PUSHed bytes are lost, and POPed bytes are indeterminate.

The Data Transfer instructions include a 16-bit MOV that can be used to initialize the Data Pointer (DPTR) for look-up tables in Program Memory, or for 16-bit external Data Memory accesses.

The XCH A, <byte> instruction causes the Accumulator and addressed byte to exchange data. The XCHD A,@Ri instruction is similar, but only the low nibbles are involved in the exchange.

To see how XCH and XCHD can be used to facilitate data manipulations, consider first the problem of shifting an 8-digit BCD number two digits to the right. Figure 4-2 shows how this can be done using direct MOVs, and for comparison how it can be done using XCH instructions. To aid in understanding how the code works, the contents of the registers that are holding the BCD number and the content of the Accumulator are shown alongside each instruction to indicate their status after the instruction has been executed.

After the routine has been executed, the Accumulator contains the two digits that were shifted out on the right. Doing the routine with direct MOVs uses 14 code bytes and 9 μ s of execution time (assuming a 12 MHz clock). The same operation with XCHs uses less code and executes almost twice as fast.

		2A	2B	2C	2D	2E	ACC
MOV	R1,#2EH	00	12	34	56	78	XX
MOV	R0,#2DH	00	12	34	56	78	XX

loop for R1 = 2EH:

LOOP:	MOV A,@R1	00	12	34	56	78	78
	XCHD A,@R0	00	12	34	58	78	76
	SWAP A	00	12	34	58	78	67
	MOV @R1,A	00	12	34	58	67	67
	DEC R1	00	12	34	58	67	67
	DEC R0	00	12	34	58	67	67
	CJNE R1,#2AH,LOOP						

loop for R1 = 2DH:

		00	12	38	45	67	45
--	--	----	----	----	----	----	----

loop for R1 = 2CH:

		00	18	23	45	67	23
--	--	----	----	----	----	----	----

loop for R1 = 2BH:

		08	01	23	45	67	01
--	--	----	----	----	----	----	----

CLR	A	08	01	23	45	67	00
XCH	A,2AH	00	01	23	45	67	08

Figure 4-3. Shifting a BCD Number
One Digit to the Right

To right-shift by an odd number of digits, a one-digit shift must be executed. Figure 4-3 shows a sample of code that will right-shift a BCD number one digit, using the XCHD instruction. Again, the contents of the registers holding the number and of the Accumulator are shown alongside each instruction.

First, pointers R1 and R0 are set up to point to the two bytes containing the last four BCD digits. Then a loop is executed which leaves the last byte, location 2EH, holding the last two digits of the shifted number. The pointers are decremented, and the loop is repeated for location 2DH. The CJNE instruction (Compare and Jump if Not Equal) is a loop control that will be described later.

The loop is executed from LOOP to CJNE for R1 = 2EH, 2DH, 2CH and 2BH. At that point the digit that was originally shifted out on the right has propagated to location 2AH. Since that location should be left with 0s, the lost digit is moved to the Accumulator.

External RAM

Table 4-4 shows a list of the Data Transfer instructions that access external Data Memory. Only indirect addressing can be used. The choice is whether to use a one-byte address, @Ri, where Ri can be either R0 or

MOV A,BA+DPTR	Read Pgm Memory	5
MOV A,BA+PC	Read Pgm Memory	5

R1 of the selected register bank, or a two-byte address, @DPTR. The disadvantage to using 16-bit addresses is that 16-bit addresses use all 8 bits of Port 2 as address bus. On the other hand, 8-bit addresses allow one to address a few K bytes of RAM, as shown in Figure 1-5, without having to sacrifice all of Port 2.

All of these instructions execute in 2 μ s, with a 12 MHz clock.

Table 4-4. 8051 Family Data Transfer Instructions that Access External Data Memory Space

Address Width	Mnemonic	Operation	Execution Time (μ s)
8 bits	MOVX A,@Ri	Read external RAM @Ri	2
8 bits	MOVX @Ri,A	Write external RAM @Ri	2
16 bits	MOVX A,@DPTR	Read external RAM @DPTR	2
16 bits	MOVX @DPTR,A	Write external RAM @DPTR	2

Note that in all external Data RAM accesses, the Accumulator is always either the destination or source of the data.

The read and write strobes to external RAM are activated only during the execution of a MOVX instruction. Normally these signals are inactive, and in fact if they're not going to be used at all, their pins are available as extra I/O lines. More about that later.

Lookup Tables

Table 4-5 shows the two instructions that are available for reading lookup tables in Program Memory. Since these instructions access only Program Memory, the lookup tables can only be read, not updated. The mnemonic is MOVC for "move constant".

If the table access is to external Program Memory, then the read strobe is PSEN.

Table 4-5. The 8051 Family Lookup Table Read Instructions

Mnemonic	Operation	Execution Time (μ s)
MOVC A,@A+DPTR	Read Pgm Memory at (A + DPTR)	2
MOVC A,@A+PC	Read Pgm Memory at (A + PC)	2

The first MOVC instruction in Table 4-5 can accommodate a table of up to 256 entries, numbered 0 through 255. The number of the desired entry is loaded into the Accumulator, and the Data Pointer is set up to point to beginning of the table. Then

```
MOVC A,@A+DPTR
```

copies the desired table entry into the Accumulator.

The other MOVC instruction works the same way, except the Program Counter (PC) is used as the table base, and the table is accessed through a subroutine. First the number of the desired entry is loaded into the Accumulator, and the subroutine is called:

```
MOV A,ENTRY_NUMBER
CALL TABLE
```

The subroutine "TABLE" would look like this:

```
TABLE: MOVC A,@A+PC
RET
```

The table itself immediately follows the RET (return) instruction in Program Memory. This type of table can have up to 255 entries, numbered 1 through 255. Number 0 can not be used, because at the time the MOVC instruction is executed, the PC contains the address of the RET instruction. An entry numbered 0 would be the RET opcode itself.

BOOLEAN INSTRUCTIONS

8051 Family devices contain a complete Boolean (single-bit) processor. The internal RAM contains 128 addressable bits, and the SFR space can support up to 128 other addressable bits. All of the port lines are bit-addressable, and each one can be treated as a separate single-bit port. The instructions that access these bits are not just conditional branches, but a complete menu of move, set, clear, complement, OR, and AND instructions. These kinds of bit operations are not easily obtained in other architectures with any amount of byte-oriented software.

Table 4-6. A List of the 8051 Family
Boolean Instructions

Mnemonic	Operation	Execution Time (μ s)
ANL C,bit	C = C.AND. bit	2
ANL C,/bit	C = C.AND. .NOT. bit	2
ORL C,bit	C = C.OR. bit	2
ORL C,/bit	C = C.OR. .NOT. bit	2
MOV C,bit	C = bit	1
MOV bit,C	bit = C	2
CLR C	C = 0	1
CLR bit	bit = 0	1
SETB C	C = 1	1
SETB bit	bit = 1	1
CPL C	C = .NOT. C	1
CPL bit	bit = .NOT. bit	1
JC rel	Jump if C = 1	2
JNC rel	Jump if C = 0	2
JB bit,rel	Jump if bit = 1	2
JNB bit,rel	Jump if bit = 0	2
JBC bit,rel	Jump if bit = 1; CLR bit	2

The instruction set for the Boolean processor is shown in Table 4-6. All bit accesses are by direct addressing. Bit addresses 00H through 7FH are in the Lower 128, and bit addresses 80H through FFH are in SFR space.

Note how easily an internal flag can be moved to a port pin:

```
MOV C,FLAG
MOV P1.0,C
```

In this example, FLAG is the name of any addressable bit in the Lower 128 or SFR space. An I/O line (the LSB of Port 1, in this case) is set or cleared depending on whether the flag bit is 1 or 0.

The Carry bit in the PSW is used as the single-bit Accumulator of the Boolean processor. Bit instructions that refer to the Carry bit as C assemble as Carry-specific instructions (CLR C, etc). The Carry bit also has a direct address, since it resides in the PSW register, which is bit-addressable.

Note that the Boolean instruction set includes ANL and ORL operations, but not the XRL (Exclusive OR) operation. An XRL operation is simple to implement in software. Suppose, for example, it is required to form the Exclusive OR of two bits:

C = bit1 .XRL. bit2

The software to do that could be as follows:

```
MOV C,bit1
JNB bit2,OVER
CPL C
OVER: (continue)
```

First, bit1 is moved to the Carry. If bit2 = 0, then C now contains the correct result. That is, bit1 .XRL. bit2 = bit1 if bit2 = 0. On the other hand, if bit2 = 1 C now contains the complement of the correct result. It need only be inverted (CPL C) to complete the operation.

This code uses the JNB instruction, one of a series of bit-test instructions which execute a jump if the addressed bit is set (JC, JB, JBC) or if the addressed bit is not set (JNC, JNB). In the above case, bit2 is being tested, and if bit2 = 0 the CPL C instruction is jumped over.

JBC executes the jump if the addressed bit is set, and also clears the bit. Thus a flag can be tested and cleared in one operation.

All the PSW bits are directly addressable, so the Parity bit, or the general purpose flags, for example, are also available to the bit-test instructions.

Relative Offset

The destination address for these jumps is specified to the assembler by a label or by an actual address in Program Memory. However, the destination address assembles to a **relative** offset byte. This is a signed (two's complement) offset byte which is added to the PC in two's complement arithmetic if the jump is executed.

The range of the jump is therefore -128 to +127 Program Memory bytes relative to the first byte following the instruction.

JUMP INSTRUCTIONS

Table 4-7 shows the list of unconditional jumps.

Table 4-7. Unconditional Jumps
In 8051 Family Devices

Mnemonic	Operation	Execution Time (μ s)
JMP addr	Jump to addr	2
JMP @A + DPTR	Jump to A + DPTR	2
CALL addr	Call subroutine at addr	2
RET	Return from subroutine	2
RETI	Return from interrupt	2
NOP	No operation	1

The Table lists a single “JMP addr” instruction, but in fact there are three—SJMP, LJMP and AJMP—which differ in the format of the destination address. JMP is a generic mnemonic which can be used if the programmer does not care which way the jump is encoded.

The SJMP instruction encodes the destination address as a relative offset, as described above. The instruction is 2 bytes long, consisting of the opcode and the relative offset byte. The jump distance is limited to a range of -128 to +127 bytes relative to the instruction following the SJMP.

The LJMP instruction encodes the destination address as a 16-bit constant. The instruction is 3 bytes long, consisting of the opcode and two address bytes. The destination address can be anywhere in the 64K Program Memory space.

The AJMP instruction encodes the destination address as an 11-bit constant. The instruction is 2 bytes long, consisting of the opcode, which itself contains 3 of the 11 address bits, followed by another byte containing the low 8 bits of the destination address. When the instruction is executed, these 11 bits are simply substituted for the low 11 bits in the PC. The high 5 bits stay the same. Hence the destination has to be within the same 2K block as the instruction following the AJMP.

In all cases the programmer specifies the destination address to the assembler in the same way: as a label or as a 16-bit constant. The assembler will put the destination address into the correct format for the given instruction. If the format required by the instruction will not support the distance to the specified destination address, a “Destination out of range” message is written into the List file.

The JMP @A + DPTR instruction supports case jumps. The destination address is computed at execution time as the sum of the 16-bit DPTR register and the Accumulator. Typically, DPTR is set up with the address of a jump table, and the Accumulator is given an index to the table. In a 5-way branch, for example, an integer 0 through 4 is loaded into the Accumulator. The code to be executed might be as follows:

```
MOV    DPTR,#JUMP_TABLE
MOV    A,INDEX_NUMBER
RL     A
JMP    @A + DPTR
```

The RL A instruction converts the index number (0 through 4) to an even number on the range 0 through 8, because each entry in the jump table is 2 bytes long:

```
JUMP_TABLE:
AJMP   CASE_0
AJMP   CASE_1
AJMP   CASE_2
AJMP   CASE_3
AJMP   CASE_4
```

Table 4-7 shows a single “CALL addr” instruction, but there are two of them—LCALL and ACALL—which differ in the format in which the subroutine address is given to the CPU. CALL is a generic mnemonic which can be used if the programmer does not care which way the address is encoded.

The LCALL instruction uses the 16-bit address format, and the subroutine can be anywhere in the 64K Program Memory space. The ACALL instruction uses the 11-bit format, and the subroutine must be in the same 2K block as the instruction following the ACALL.

In any case the programmer specifies the subroutine address to the assembler in the same way: as a label or as a 16-bit constant. The assembler will put the address into the correct format for the given instructions.

Subroutines should end with a RET instruction, which returns execution to the instruction following the CALL.

RETI is used to return from an interrupt service routine. The only difference between RET and RETI is that RETI tells the interrupt control system that the interrupt in progress is done. If there is no interrupt in progress at the time RETI is executed, then the RETI is functionally identical to RET.

Table 4-8. Conditional Jumps in 8051 Family Devices

Mnemonic	Operation	Addressing Modes				Execution Time (μs)
		Dir	Ind	Reg	Imm	
JZ rel	Jump if A = 0					2
JNZ rel	Jump if A ≠ 0					2
DJNZ <byte>,rel	Decrement and jump if not zero	X		X		2
CJNE A,<byte>,rel	Jump if A ≠ <byte>	X			X	2
CJNE <byte>,#data,rel	Jump if <byte> ≠ #data		X	X		2

Table 4-8 shows the list of conditional jumps available to the 8051 Family user. All of these jumps specify the destination address by the relative offset method, and so are limited to a jump distance of -128 to +127 bytes from the instruction following the conditional jump instruction. Important to note, however, the user specifies to the assembler the actual destination address the same way as the other jumps: as a label or a 16-bit constant.

There is no Zero bit in the PSW. The JZ and JNZ instructions test the Accumulator data for that condition.

The DJNZ instruction (Decrement and Jump if Not Zero) is for loop control. To execute a loop N times, load a counter byte with N and terminate the loop with a DJNZ to the beginning of the loop, as shown below for N = 10:

	MOV	COUNTER,#10
LOOP:	(begin loop)	
	*	
	*	
	(end loop)	
	DJNZ	COUNTER,LOOP
	(continue)	

The CJNE instruction (Compare and Jump if Not Equal) can also be used for loop control as in Figure 4-3. Two bytes are specified in the operand field of the instruction. The jump is executed only if the two bytes are not equal. In the example of Figure 4-3, the two bytes were the data in R1 and the constant 2AH. The initial data in R1 was 2EH. Every time the loop was executed, R1 was decremented, and the looping was to continue until the R1 data reached 2AH.

Another application of this instruction is in “greater than, less than” comparisons. The two bytes in the operand field are taken as unsigned integers. If the first is less than the second, then the Carry bit is set (1). If the first is greater than or equal to the second, then the Carry bit is cleared.

Table 4-9. 8051 Instruction Set Summary

Interrupt Response Time: Refer to Chapter 2, page 2-24							
Instructions that Affect Flag Settings ⁽¹⁾							
Instruction	Flag			Instruction	Flag		
	C	OV	AC		C	OV	AC
ADD	X	X	X	CLR C	O		
ADDC	X	X	X	CPL C	X		
SUBB	X	X	X	ANL C,bit	X		
MUL	O	X		ANL C,/bit	X		
DIV	O	X		ORL C,bit	X		
DA	X			ORL C,bit	X		
RRC	X			MOV C,bit	X		
RLC	X			CJNE	X		
SETB C	1						
⁽¹⁾ Note that operations on SFR byte address 208 or bit addresses 209-215 (i.e., the PSW or bits in the PSW) will also affect flag settings.							
Note on instruction set and addressing modes: Rn — Register R7–R0 of the currently selected Register Bank. direct — 8-bit internal data location's address. This could be an Internal Data RAM location (0–127) or a SFR [i.e., I/O port, control register, status register, etc. (128–255)]. @Ri — 8-bit internal data RAM location (0–255) addressed indirectly through register R1 or R0. #data — 8-bit constant included in instruction. #data 16 — 16-bit constant included in instruction. addr 16 — 16-bit destination address. Used by LCALL & LJMP. A branch can be anywhere within the 64K-byte Program Memory address space. addr 11 — 11-bit destination address. Used by ACALL & AJMP. The branch will be within the same 2K-byte page of program memory as the first byte of the following instruction. rel — Signed (two's complement) 8-bit offset byte. Used by SJMP and all conditional jumps. Range is –128 to +127 bytes relative to first byte of the following instruction. bit — Direct Addressed bit in Internal Data RAM or Special Function Register. * — New operation not provided by 8048AH/8049AH.							
ARITHMETIC OPERATIONS							
Mnemonic	Description			Byte	Oscillator Period		
ADD A,Rn	Add register to Accumulator			1	12		
ADD A,direct	Add direct byte to Accumulator			2	12		
ADD A,@Ri	Add indirect RAM to Accumulator			1	12		
ADD A,#data	Add immediate data to Accumulator			2	12		
ADDC A,Rn	Add register to Accumulator with Carry			1	12		
ADDC A,direct	Add direct byte to Accumulator with Carry			2	12		
ADDC A,@Ri	Add indirect RAM to Accumulator with Carry			1	12		
ADDC A,#data	Add immediate data to Acc with Carry			2	12		
SUBB A,Rn	Subtract Register from Acc with borrow			1	12		
SUBB A,direct	Subtract direct byte from Acc with borrow			2	12		
SUBB A,@Ri	Subtract indirect RAM from ACC with borrow			1	12		
SUBB A,#data	Subtract immediate data from Acc with borrow			2	12		
INC A	Increment Accumulator			1	12		
INC Rn	Increment register			1	12		
INC direct	Increment direct byte			2	12		
INC @Ri	Increment direct RAM			1	12		
DEC A	Decrement Accumulator			1	12		
DEC Rn	Decrement Register			1	12		
DEC direct	Decrement direct byte			2	12		
DEC @Ri	Decrement indirect RAM			1	12		

Table 4-9. 8051 Instruction Set Summary (Continued)

Mnemonic	Description	Byte	Oscillator Period
ARITHMETIC OPERATIONS (Continued)			
INC DPTR	Increment Data Pointer	1	24
MUL AB	Multiply A & B	1	48
DIV AB	Divide A by B	1	48
DA A	Decimal Adjust Accumulator	1	12
LOGICAL OPERATIONS			
ANL A,Rn	AND Register to Accumulator	1	12
ANL A,direct	AND direct byte to Accumulator	2	12
ANL A,@Ri	AND indirect RAM to Accumulator	1	12
ANL A,#data	AND immediate data to Accumulator	2	12
ANL direct,A	AND Accumulator to direct byte	2	12
ANL direct,#data	AND immediate data to direct byte	3	24
ORL A,Rn	OR register to Accumulator	1	12
ORL A,direct	OR direct byte to Accumulator	2	12
ORL A,@Ri	OR indirect RAM to Accumulator	1	12
ORL A,#data	OR immediate data to Accumulator	2	12
ORL direct,A	OR Accumulator to direct byte	2	12
ORL direct,#data	OR immediate data to direct byte	3	24
XRL A,Rn	Exclusive-OR register to Accumulator	1	12
XRL A,direct	Exclusive-OR direct byte to Accumulator	2	12
XRL A,@Ri	Exclusive-OR indirect RAM to Accumulator	1	12
XRL A,#data	Exclusive-OR immediate data to Accumulator	2	12
XRL direct,A	Exclusive-OR Accumulator to direct byte	2	12
LOGICAL OPERATIONS (Continued)			
XRL direct,#data	Exclusive-OR immediate data to direct byte	3	24
CLR A	Clear Accumulator	1	12
CPL A	Complement Accumulator	1	12
RL A	Rotate Accumulator Left	1	12
RLC A	Rotate Accumulator Left through the Carry	1	12
RR A	Rotate Accumulator Right	1	12
RRC A	Rotate Accumulator Right through the Carry	1	12
SWAP A	Swap nibbles within the Accumulator	1	12
DATA TRANSFER			
MOV A,Rn	Move register to Accumulator	1	12
MOV A,direct	Move direct byte to Accumulator	2	12
MOV A,@Ri	Move indirect RAM to Accumulator	1	12
MOV A,#data	Move immediate data to Accumulator	2	12
MOV Rn,A	Move Accumulator to register	1	12
MOV Rn,direct	Move direct byte to register	2	24
MOV Rn,#data	Move immediate data to register	2	12
MOV direct,A	Move Accumulator to direct byte	2	12

Table 4-9. 8051 Instruction Set Summary (Continued)

Mnemonic	Description	Byte	Oscillator Period	Mnemonic	Description	Byte	Oscillator Period
DATA TRANSFER (Continued)				XCH A,Rn	Exchange register with Accumulator	1	12
MOV direct,Rn	Move register to direct byte	2	24	XCH A,direct	Exchange direct byte with Accumulator	2	12
MOV direct,direct	Move direct byte to direct RAM	3	24	XCH A,@Ri	Exchange indirect RAM with Accumulator	1	12
MOV direct,@Ri	Move indirect RAM to direct byte	2	24	XCHD A,@Ri	Exchange low-order Digit indirect RAM with Acc	1	12
MOV direct,#data	Move immediate data to direct byte	3	24	BOOLEAN VARIABLE MANIPULATION			
MOV @Ri,A	Move Accumulator to indirect RAM	1	12	CLR C	Clear Carry	1	12
MOV @Ri,direct	Move direct byte to indirect RAM	2	24	CLR bit	Clear direct bit	2	12
MOV @Ri,#data	Move immediate data to indirect RAM	2	12	SETB C	Set Carry	1	12
MOV DPTR,#data16	Load Data Pointer with a 16-bit constant	3	24	SETB bit	Set direct bit	2	12
MOVC A,@A+DPTR	Move Code byte relative to DPTR to Acc	1	24	CPL C	Complement Carry	1	12
MOVC A,@A+PC	Move Code byte relative to PC to Acc	1	24	CPL bit	Complement direct bit	2	12
MOVX A,@Ri	Move External RAM (8-bit addr) to Acc	1	24	ANL C,bit	AND direct bit to CARRY	2	24
MOVX A,@DPTR	Move External RAM (16-bit addr) to Acc	1	24	ANL C,/bit	AND complement of direct bit to Carry	2	24
MOVX @Ri,A	Move Acc to External RAM (8-bit addr)	1	24	ORL C,bit	OR direct bit to Carry	2	24
MOVX @DPTR,A	Move Acc to External RAM (16-bit addr)	1	24	ORL C,/bit	OR complement of direct bit to Carry	2	24
PUSH direct	Push direct byte onto stack	2	24	MOV C,bit	Move direct bit to Carry	2	12
POP direct	Pop direct byte from stack	2	24	MOV bit,C	Move Carry to direct bit	2	24
				JC rel	Jump if Carry is set	2	24
				JNC rel	Jump if Carry not set	2	24
				JB bit,rel	Jump if direct Bit is set	3	24
				JNB bit,rel	Jump if direct Bit is Not set	3	24
				JBC bit,rel	Jump if direct Bit is set & clear bit	3	24

Table 4-9. 8051 Instruction Set Summary (Continued)

Mnemonic	Description	Byte	Oscillator Period	Mnemonic	Description	Byte	Oscillator Period
PROGRAM BRANCHING				PROGRAM BRANCHING (Continued)			
ACALL addr11	Absolute Subroutine Call	2	24	CJNE Rn, #data,rel	Compare immediate to register and Jump if Not Equal	3	24
LCALL addr16	Long Subroutine Call	3	24	CJNE @Ri, #data,rel	Compare immediate to indirect and Jump if Not Equal	3	24
RET	Return from Subroutine	1	24	DJNZ Rn,rel	Decrement register and Jump if Not Zero	2	24
RETI	Return from interrupt	1	24	DJNZ direct,rel	Decrement direct byte and Jump if Not Zero	3	24
AJMP addr11	Absolute Jump	2	24	NOP	No Operation	1	12
LJMP addr16	Long Jump	3	24				
SJMP rel	Short Jump (relative addr)	2	24				
JMP @A + DPTR	Jump indirect relative to the DPTR	1	24				
JZ rel	Jump if Accumulator is Zero	2	24				
JNZ rel	Jump if Accumulator is Not Zero	2	24				
CJNE A, direct,rel	Compare direct byte to Acc and Jump if Not Equal	3	24				
CJNE A, #data,rel	Compare immediate to Acc and Jump if Not Equal	3	24				

INSTRUCTION DEFINITIONS

ACALL addr11

Function: Absolute Call

Description: ACALL unconditionally calls a subroutine located at the indicated address. The instruction increments the PC twice to obtain the address of the following instruction, then pushes the 16-bit result onto the stack (low-order byte first) and increments the Stack Pointer twice. The destination address is obtained by successively concatenating the five high-order bits of the incremented PC, opcode bits 7-5, and the second byte of the instruction. The subroutine called must therefore start within the same 2K block of the program memory as the first byte of the instruction following ACALL. No flags are affected.

Example: Initially SP equals 07H. The label "SUBRTN" is at program memory location 0345 H. After executing the instruction,

ACALL SUBRTN

at location 0123H, SP will contain 09H, internal RAM locations 08H and 09H will contain 25H and 01H, respectively, and the PC will contain 0345H.

Bytes: 2

Cycles: 2

Encoding: a10 a9 a8 1 0 0 0 1

a7 a6 a5 a4 a3 a2 a1 a0

Operation: ACALL
(PC) ← (PC) + 2
(SP) ← (SP) + 1
((SP)) ← (PC₇₋₀)
(SP) ← (SP) + 1
((SP)) ← (PC₁₅₋₈)
(PC₁₀₋₀) ← page address

ADD A,<src-byte>

Function: Add

Description: ADD adds the byte variable indicated to the Accumulator, leaving the result in the Accumulator. The carry and auxiliary-carry flags are set, respectively, if there is a carry-out from bit 7 or bit 3, and cleared otherwise. When adding unsigned integers, the carry flag indicates an overflow occurred.

OV is set if there is a carry-out of bit 6 but not out of bit 7, or a carry-out of bit 7 but not bit 6; otherwise OV is cleared. When adding signed integers, OV indicates a negative number produced as the sum of two positive operands, or a positive sum from two negative operands.

Four source operand addressing modes are allowed: register, direct, register-indirect, or immediate.

Example: The Accumulator holds 0C3H (11000011B) and register 0 holds 0AAH (10101010B). The instruction,

ADD A,R0

will leave 6DH (01101101B) in the Accumulator with the AC flag cleared and both the carry flag and OV set to 1.

ADD A,Rn

Bytes: 1

Cycles: 1

Encoding:

0	0	1	0
---	---	---	---

1	r	r	r
---	---	---	---

Operation: ADD
 $(A) \leftarrow (A) + (Rn)$

ADD A,direct

Bytes: 2

Cycles: 1

Encoding:

0	0	1	0
---	---	---	---

0	1	0	1
---	---	---	---

direct address			
----------------	--	--	--

Operation: ADD
 $(A) \leftarrow (A) + (\text{direct})$

ADD A,@Ri

Bytes: 1

Cycles: 1

Encoding: 0 0 1 0 0 1 1 i

Operation: ADD
 $(A) \leftarrow (A) + ((R_i))$

ADD A,#data

Bytes: 2

Cycles: 1

Encoding: 0 0 1 0 0 1 0 0 immediate data

Operation: ADD
 $(A) \leftarrow (A) + \#data$

ADDC A,<src-byte>

Function: Add with Carry

Description: ADCc simultaneously adds the byte variable indicated, the carry flag and the Accumulator contents, leaving the result in the Accumulator. The carry and auxiliary-carry flags are set, respectively, if there is a carry-out from bit 7 or bit 3, and cleared otherwise. When adding unsigned integers, the carry flag indicates an overflow occurred.

OV is set if there is a carry-out of bit 6 but not out of bit 7, or a carry-out of bit 7 but not out of bit 6; otherwise OV is cleared. When adding signed integers, OV indicates a negative number produced as the sum of two positive operands or a positive sum from two negative operands.

Four source operand addressing modes are allowed: register, direct, register-indirect, or immediate.

Example: The Accumulator holds 0C3H (11000011B) and register 0 holds 0AAH (10101010B) with the carry flag set. The instruction,

ADDC A,R0

will leave 6EH (01101110B) in the Accumulator with AC cleared and both the Carry flag and OV set to 1.

Operation: ADDC
 $(A) \leftarrow (A) + (C) + \#data$

AJMP addr11

Function: Absolute Jump

Description: AJMP transfers program execution to the indicated address, which is formed at run-time by concatenating the high-order five bits of the PC (*after* incrementing the PC twice), opcode bits 7-5, and the second byte of the instruction. The destination must therefore be within the same 2K block of program memory as the first byte of the instruction following AJMP.

Example: The label "JMPADR" is at program memory location 0123H. The instruction,

AJMP JMPADR

is at location 0345H and will load the PC with 0123H.

Bytes: 2

Cycles: 2

Encoding:

a10 a9 a8 0	0 0 0 1	a7 a6 a5 a4	a3 a2 a1 a0
-------------	---------	-------------	-------------

Operation: AJMP
 $(PC) \leftarrow (PC) + 2$
 $(PC_{10-0}) \leftarrow \text{page address}$

ANL <dest-byte>, <src-byte>

Function: Logical-AND for byte variables

Description: ANL performs the bitwise logical-AND operation between the variables indicated and stores the results in the destination variable. No flags are affected.

The two operands allow six addressing mode combinations. When the destination is the Accumulator, the source can use register, direct, register-indirect, or immediate addressing; when the destination is a direct address, the source can be the Accumulator or immediate data.

Note: When this instruction is used to modify an output port, the value used as the original port data will be read from the output data latch, *not* the input pins.

Example: If the Accumulator holds 0C3H (11000011B) and register 0 holds 55H (01010101B) then the instruction,

ANL A,R0

will leave 41H (01000001B) in the Accumulator.

When the destination is a directly addressed byte, this instruction will clear combinations of bits in any RAM location or hardware register. The mask byte determining the pattern of bits to be cleared would either be a constant contained in the instruction or a value computed in the Accumulator at run-time. The instruction,

ANL P1,#01110011B

will clear bits 7, 3, and 2 of output port 1.

ANL A,Rn

Bytes: 1

Cycles: 1

Encoding: 0 1 0 1 1 r r r

Operation: ANL
(A) ← (A) ∧ (Rn)

ANL A,direct

Bytes: 2

Cycles: 1

Encoding: 0 1 0 1 0 1 0 1 direct address

Operation: ANL
(A) ← (A) ∧ (direct)

ANL A,@Ri

Bytes: 1

Cycles: 1

Encoding: 0 1 0 1 0 1 1 i

Operation: ANL
(A) ← (A) ∧ ((Ri))

ANL A,#data

Bytes: 2

Cycles: 1

Encoding: 0 1 0 1 0 1 0 0 immediate data

Operation: ANL
(A) ← (A) ∧ #data

ANL direct,A

Bytes: 2

Cycles: 1

Encoding:

0	1	0	1
---	---	---	---

0	0	1	0
---	---	---	---

direct address			
----------------	--	--	--

Operation: ANL
 $(\text{direct}) \leftarrow (\text{direct}) \wedge (A)$

ANL direct,#data

Bytes: 3

Cycles: 2

Encoding:

0	1	0	1
---	---	---	---

0	0	1	1
---	---	---	---

direct address			
----------------	--	--	--

immediate data			
----------------	--	--	--

Operation: ANL
 $(\text{direct}) \leftarrow (\text{direct}) \wedge \#data$

ANL C,<src-bit>

Function: Logical-AND for bit variables

Description: If the Boolean value of the source bit is a logical 0 then clear the carry flag; otherwise leave the carry flag in its current state. A slash ("/") preceding the operand in the assembly language indicates that the logical complement of the addressed bit is used as the source value, *but the source bit itself is not affected*. No other flags are affected.

Example: Only direct addressing is allowed for the source operand.
 Set the carry flag if, and only if, P1.0 = 1, ACC. 7 = 1, and OV = 0:

```
MOV C,P1.0 ;LOAD CARRY WITH INPUT PIN STATE
ANL C,ACC.7 ;AND CARRY WITH ACCUM. BIT 7
ANL C,/OV ;AND WITH INVERSE OF OVERFLOW FLAG
```

ANL C,bit

Bytes: 2

Cycles: 2

Encoding:

1	0	0	0
---	---	---	---

0	0	1	0
---	---	---	---

bit address			
-------------	--	--	--

Operation: ANL
 $(C) \leftarrow (C) \wedge (\text{bit})$

ANL C,/bit

Bytes: 2

Cycles: 2

Encoding:

1 0 1 1 0 0 0 0

bit address

Operation:

ANL
(C) ← (C) ∧ 1 (bit)

CJNE <dest-byte>, <src-byte>, rel

Function: Compare and Jump if Not Equal.

Description: CJNE compares the magnitudes of the first two operands, and branches if their values are not equal. The branch destination is computed by adding the signed relative-displacement in the last instruction byte to the PC, after incrementing the PC to the start of the next instruction. The carry flag is set if the unsigned integer value of <dest-byte> is less than the unsigned integer value of <src-byte>; otherwise, the carry is cleared. Neither operand is affected.

The first two operands allow four addressing mode combinations: the Accumulator may be compared with any directly addressed byte or immediate data, and any indirect RAM location or working register can be compared with an immediate constant.

Example: The Accumulator contains 34H. Register 7 contains 56H. The first instruction in the sequence,

```

CJNE R7,#60H,NOT_EQ
;
NOT_EQ: JC REQ_LOW      ; R7 = 60H.
;                   ; IF R7 < 60H.
;                   ; R7 > 60H.

```

sets the carry flag and branches to the instruction at label NOT_EQ. By testing the carry flag, this instruction determines whether R7 is greater or less than 60H.

If the data being presented to Port 1 is also 34H, then the instruction,

WAIT: CJNE A,P1,WAIT

clears the carry flag and continues with the next instruction in sequence, since the Accumulator does equal the data read from P1. (If some other value was being input on P1, the program will loop at this point until the P1 data changes to 34H.)

Cycles: 2

Encoding:

1	0	1	1
---	---	---	---

0	1	0	1
---	---	---	---

direct address			
----------------	--	--	--

rel. address			
--------------	--	--	--

Operation: $(PC) \leftarrow (PC) + 3$
 IF (A) \neq (direct)
 THEN
 $(PC) \leftarrow (PC) + \text{relative offset}$

IF (A) < (direct)
 THEN

(C) \leftarrow 1

ELSE

(C) \leftarrow 0

CJNE A, #data, rel

Bytes: 3

Cycles: 2

Encoding:

1	0	1	1
---	---	---	---

0	1	0	0
---	---	---	---

immediate data			
----------------	--	--	--

rel. address			
--------------	--	--	--

Operation: $(PC) \leftarrow (PC) + 3$
 IF (A) \neq data
 THEN
 $(PC) \leftarrow (PC) + \text{relative offset}$

IF (A) < data
 THEN

(C) \leftarrow 1

ELSE

(C) \leftarrow 0

CJNE Rn, #data, rel

Bytes: 3

Cycles: 2

Encoding:

1	0	1	1
---	---	---	---

1	r	r	r
---	---	---	---

immediate data			
----------------	--	--	--

rel. address			
--------------	--	--	--

Operation: $(PC) \leftarrow (PC) + 3$
 IF (Rn) \neq data
 THEN
 $(PC) \leftarrow (PC) + \text{relative offset}$

IF (Rn) < data
 THEN

(C) \leftarrow 1

ELSE

(C) \leftarrow 0

CJNE @Ri, #data, rel

Bytes: 3

Cycles: 2

Encoding:

1 0 1 1 0 1 1 i

immediate data

rel. address

Operation:

$(PC) \leftarrow (PC) + 3$

IF $((Ri)) < > data$

THEN

$(PC) \leftarrow (PC) + relative\ offset$

IF $((Ri)) < data$

THEN

$(C) \leftarrow 1$

ELSE

$(C) \leftarrow 0$

CLR A

Function: Clear Accumulator

Description: The Accumulator is cleared (all bits set on zero). No flags are affected.

Example: The Accumulator contains 5CH (01011100B). The instruction,

CLR A

will leave the Accumulator set to 00H (00000000B).

Bytes: 1

Cycles: 1

Encoding:

1 1 1 1 0 1 0 0

Operation:

CLR

$(A) \leftarrow 0$

CLR bit

Function: Clear bit

Description: The indicated bit is cleared (reset to zero). No other flags are affected. CLR can operate on the carry flag or any directly addressable bit.

Example: Port 1 has previously been written with 5DH (01011101B). The instruction,

CLR P1.2

will leave the port set to 59H (01011001B).

CLR C

Bytes: 1

Cycles: 1

Encoding:

1	1	0	0
---	---	---	---

0	0	1	1
---	---	---	---

Operation: CLR
(C) ← 0

CLR bit

Bytes: 2

Cycles: 1

Encoding:

1	1	0	0
---	---	---	---

0	0	1	0
---	---	---	---

bit address			
-------------	--	--	--

Operation: CLR
(bit) ← 0

CPL A

Function: Complement Accumulator

Description: Each bit of the Accumulator is logically complemented (one's complement). Bits which previously contained a one are changed to a zero and vice-versa. No flags are affected.

Example: The Accumulator contains 5CH (01011100B). The instruction,

CPL A

will leave the Accumulator set to 0A3H (10100011B).

Bytes: 1

Cycles: 1

Encoding:

1	1	1	1
---	---	---	---

0	1	0	0
---	---	---	---

Operation: CPL
(A) ← \neg (A)

CPL bit

Function: Complement bit

Description: The bit variable specified is complemented. A bit which had been a one is changed to zero and vice-versa. No other flags are affected. CLR can operate on the carry or any directly addressable bit.

Note: When this instruction is used to modify an output pin, the value used as the original data will be read from the output data latch, *not* the input pin.

Example: Port 1 has previously been written with 5BH (0101101B). The instruction sequence,

CPL P1.1

CPL P1.2

will leave the port set to 5BH (01011011B).

CPL C

Bytes: 1

Cycles: 1

Encoding: 1 0 1 1 0 0 1 1

Operation: CPL
(C) ← \neg (C)

CPL bit

Bytes: 2

Cycles: 1

Encoding: 1 0 1 1 0 0 1 0 bit address

Operation: CPL
(bit) ← \neg (bit)

Function: Decimal-adjust Accumulator for Addition

Description: DA A adjusts the eight-bit value in the Accumulator resulting from the earlier addition of two variables (each in packed-BCD format), producing two four-bit digits. Any ADD or ADDC instruction may have been used to perform the addition.

If Accumulator bits 3-0 are greater than nine (xxxx1010-xxxx1111), or if the AC flag is one, six is added to the Accumulator producing the proper BCD digit in the low-order nibble. This internal addition would set the carry flag if a carry-out of the low-order four-bit field propagated through all high-order bits, but it would not clear the carry flag otherwise.

If the carry flag is now set, or if the four high-order bits now exceed nine (1010xxxx-111xxxx), these high-order bits are incremented by six, producing the proper BCD digit in the high-order nibble. Again, this would set the carry flag if there was a carry-out of the high-order bits, but wouldn't clear the carry. The carry flag thus indicates if the sum of the original two BCD variables is greater than 100, allowing multiple precision decimal addition. OV is not affected.

All of this occurs during the one instruction cycle. Essentially, this instruction performs the decimal conversion by adding 00H, 06H, 60H, or 66H to the Accumulator, depending on initial Accumulator and PSW conditions.

Note: DA A cannot simply convert a hexadecimal number in the Accumulator to BCD notation, nor does DA A apply to decimal subtraction.

Example: The Accumulator holds the value 56H (01010110B) representing the packed BCD digits of the decimal number 56. Register 3 contains the value 67H (01100111B) representing the packed BCD digits of the decimal number 67. The carry flag is set. The instruction sequence.

```
ADDC A,R3
DA A
```

will first perform a standard two's-complement binary addition, resulting in the value 0BEH (10111110) in the Accumulator. The carry and auxiliary carry flags will be cleared.

The Decimal Adjust instruction will then alter the Accumulator to the value 24H (00100100B), indicating the packed BCD digits of the decimal number 24, the low-order two digits of the decimal sum of 56, 67, and the carry-in. The carry flag will be set by the Decimal Adjust instruction, indicating that a decimal overflow occurred. The true sum 56, 67, and 1 is 124.

BCD variables can be incremented or decremented by adding 01H or 99H. If the Accumulator initially holds 30H (representing the digits of 30 decimal), then the instruction sequence,

```
ADD A,#99H
DA A
```

will leave the carry set and 29H in the Accumulator, since $30 + 99 = 129$. The low-order byte of the sum can be interpreted to mean $30 - 1 = 29$.

Bytes: 1

Cycles: 1

Encoding:	1 1 0 1	0 1 0 0
Operation:	DA -contents of Accumulator are BCD IF $[(A_{3-0}) > 9] \vee [(AC) = 1]$ THEN $(A_{3-0}) \leftarrow (A_{3-0}) + 6$ AND IF $[(A_{7-4}) > 9] \vee [(C) = 1]$ THEN $(A_{7-4}) \leftarrow (A_{7-4}) + 6$	
DEC byte		
Function:	Decrement	
Description:	The variable indicated is decremented by 1. An original value of 00H will underflow to 0FFH. No flags are affected. Four operand addressing modes are allowed: accumulator, register, direct, or register-indirect.	
Example:	Register 0 contains 7FH (01111111B). Internal RAM locations 7EH and 7FH contain 00H and 40H, respectively. The instruction sequence,	
	DEC @R0 DEC R0 DEC @R0	
	will leave register 0 set to 7EH and internal RAM locations 7EH and 7FH set to 0FFH and 3FH.	
DEC A		
Bytes:	1	
Cycles:	1	
Encoding:	0 0 0 1	0 1 0 0
Operation:	DEC $(A) \leftarrow (A) - 1$	
DEC Rn		
Bytes:	1	
Cycles:	1	
Encoding:	0 0 0 1	1 r r r
Operation:	DEC $(Rn) \leftarrow (Rn) - 1$	

DEC direct

Bytes: 2

Cycles: 1

Encoding:

0 0 0 1	0 1 0 1
---------	---------

direct address

Operation: DEC
(direct) \leftarrow (direct) - 1

DEC @RI

Bytes: 1

Cycles: 1

Encoding:

0 0 0 1	0 1 1 i
---------	---------

Operation: DEC
(RI) \leftarrow (RI) - 1

DIV AB

Function: Divide

Description: DIV AB divides the unsigned eight-bit integer in the Accumulator by the unsigned eight-bit integer in register B. The Accumulator receives the integer part of the quotient; register B receives the integer remainder. The carry and OV flags will be cleared.

Exception: if B had originally contained 00H, the values returned in the Accumulator and B-register will be undefined and the overflow flag will be set. The carry flag is cleared in any case.

Example: The Accumulator contains 251 (0FBH or 11111011B) and B contains 18 (12H or 00010010B). The instruction,

DIV AB

will leave 13 in the Accumulator (0DAH or 00001101B) and the value 17 (11H or 00010001B) in B, since $251 = (13 \times 18) + 17$. Carry and OV will both be cleared.

Bytes: 1

Cycles: 4

Encoding:

1 0 0 0	0 1 0 0
---------	---------

Operation: DIV
(A)₁₅₋₈
(B)₇₋₀ \leftarrow (A)/(B)

DJNZ <byte>, <rel-addr>

Function: Decrement and Jump if Not Zero

Description: DJNZ decrements the location indicated by 1, and branches to the address indicated by the second operand if the resulting value is not zero. An original value of 00H will underflow to 0FFH. No flags are affected. The branch destination would be computed by adding the signed relative-displacement value in the last instruction byte to the PC, after incrementing the PC to the first byte of the following instruction.

The location decremented may be a register or directly addressed byte.

Note: When this instruction is used to modify an output port, the value used as the original port data will be read from the output data latch, *not* the input pins.

Example: Internal RAM locations 40H, 50H, and 60H contain the values 01H, 70H, and 15H, respectively. The instruction sequence,

```
DJNZ 40H, LABEL__1
DJNZ 50H, LABEL__2
DJNZ 60H, LABEL__3
```

will cause a jump to the instruction at label LABEL__2 with the values 00H, 6FH, and 15H in the three RAM locations. The first jump was *not* taken because the result was zero.

This instruction provides a simple way of executing a program loop a given number of times, or for adding a moderate time delay (from 2 to 512 machine cycles) with a single instruction. The instruction sequence,

```
TOGGLE:  MOV     R2, #8
          CPL     P1.7
          DJNZ    R2, TOGGLE
```

will toggle P1.7 eight times, causing four output pulses to appear at bit 7 of output Port 1. Each pulse will last three machine cycles; two for DJNZ and one to alter the pin.

DJNZ Rn, rel

Bytes: 2

Cycles: 2

Encoding:

1	1	0	1
---	---	---	---

1	r	r	r
---	---	---	---

rel. address			
--------------	--	--	--

Operation: DJNZ
 $(PC) \leftarrow (PC) + 2$
 $(Rn) \leftarrow (Rn) - 1$
 IF $(Rn) > 0$ or $(Rn) < 0$
 THEN
 $(PC) \leftarrow (PC) + rel$

Cycles: 2

Encoding:

1 1 0 1

0 1 0 1

direct address

rel. address

Operation:

DJNZ

$(PC) \leftarrow (PC) + 2$

$(direct) \leftarrow (direct) - 1$

IF $(direct) > 0$ or $(direct) < 0$

THEN

$(PC) \leftarrow (PC) + rel$

INC <byte>

Function: Increment

Description: INC increments the indicated variable by 1. An original value of 0FFH will overflow to 00H. No flags are affected. Three addressing modes are allowed: register, direct, or register-indirect.

Note: When this instruction is used to modify an output port, the value used as the original port data will be read from the output data latch, *not* the input pins.

Example: Register 0 contains 7EH (01111110B). Internal RAM locations 7EH and 7FH contain 0FFH and 40H, respectively. The instruction sequence,

INC @R0

INC R0

INC @R0

will leave register 0 set to 7FH and internal RAM locations 7EH and 7FH holding (respectively) 00H and 41H.

INC A

Bytes: 1

Cycles: 1

Encoding:

0 0 0 0

0 1 0 0

Operation:

INC

$(A) \leftarrow (A) + 1$

INC Rn	INC DPTR																
<p>Bytes: 1</p> <p>Cycles: 1</p> <p>Encoding: <table><tr><td>0</td><td>0</td><td>0</td><td>0</td><td>1</td><td>r</td><td>r</td><td>r</td></tr></table></p> <p>Operation: INC (Rn) ← (Rn) + 1</p>	0	0	0	0	1	r	r	r	<p>Function: Increment Data Pointer</p> <p>Description: Increment the 16-bit data pointer by 1. A 16-bit increment (modulo 2¹⁶) is performed on the low-order byte of the data pointer. The high-order byte (DPH) is unaffected. No flags are affected.</p> <p>Example: Registers DPH and DPL contain 12H and 0F0H, respectively. The instruction sequence:</p> <p>INC DPTR INC DPTR INC DPTR</p> <p>will change DPH and DPL to 13H and 0F1H.</p> <p>Byte: 1</p> <p>Cycles: 1</p> <p>Encoding: <table><tr><td>1</td><td>0</td><td>1</td><td>0</td><td>0</td><td>0</td><td>1</td></tr></table></p> <p>Operation: INC (DPTR) ← (DPTR) + 1</p>	1	0	1	0	0	0	1	
0	0	0	0	1	r	r	r										
1	0	1	0	0	0	1											
<p>INC direct</p> <p>Bytes: 2</p> <p>Cycles: 1</p> <p>Encoding: <table><tr><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>1</td><td>0</td><td>1</td></tr></table> direct address</p> <p>Operation: INC (direct) ← (direct) + 1</p>	0	0	0	0	0	1	0	1									
0	0	0	0	0	1	0	1										
<p>INC @RI</p> <p>Bytes: 1</p> <p>Cycles: 1</p> <p>Encoding: <table><tr><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td><td>1</td><td>1</td><td>i</td></tr></table></p> <p>Operation: INC ((Ri)) ← ((Ri)) + 1</p>	0	0	0	0	0	1	1	i	<p>Function: Jump if bit set</p> <p>Description: If the indicated bit is set, jump to the address indicated by the 16-bit displacement. The branch destination is computed by adding the 16-bit displacement to the third instruction byte in the PC, after incrementing the PC to the first byte of the next instruction. The bit tested is not modified. No flags are affected.</p> <p>Example: The data present at input port 1 is 1100101010H. The Accumulator holds 0101011010H. The instruction sequence:</p> <p>JB ACC, LABEL1 JB P1, LABEL1</p> <p>will cause program execution to branch to the instruction at label LABEL1.</p> <p>Byte: 3</p> <p>Cycles: 3</p> <p>Encoding: <table><tr><td>0</td><td>0</td><td>1</td><td>0</td><td>0</td><td>0</td><td>0</td><td>0</td></tr></table> bit address rel. address</p> <p>Operation: JB (PC) ← (PC) + 3 IF (bit) = 1 THEN (PC) ← (PC) + rel</p>	0	0	1	0	0	0	0	0
0	0	0	0	0	1	1	i										
0	0	1	0	0	0	0	0										

INC DPTR

Function: Increment Data Pointer

Description: Increment the 16-bit data pointer by 1. A 16-bit increment (modulo 2^{16}) is performed; an overflow of the low-order byte of the data pointer (DPL) from 0FFH to 00H will increment the high-order byte (DPH). No flags are affected.

This is the only 16-bit register which can be incremented.

Example: Registers DPH and DPL contain 12H and 0FEH, respectively. The instruction sequence,

```
INC DPTR
INC DPTR
INC DPTR
```

will change DPH and DPL to 13H and 01H.

Bytes: 1

Cycles: 2

Encoding:

1	0	1	0	0	0	1	1
---	---	---	---	---	---	---	---

Operation: INC
(DPTR) \leftarrow (DPTR) + 1

JB bit,rel

Function: Jump if Bit set

Description: If the indicated bit is a one, jump to the address indicated; otherwise proceed with the next instruction. The branch destination is computed by adding the signed relative-displacement in the third instruction byte to the PC, after incrementing the PC to the first byte of the next instruction. *The bit tested is not modified.* No flags are affected.

Example: The data present at input port 1 is 11001010B. The Accumulator holds 56 (01010110B). The instruction sequence,

```
JB P1.2,LABEL1
```

```
JB ACC.2,LABEL2
```

will cause program execution to branch to the instruction at label LABEL2.

Bytes: 3

Cycles: 2

Encoding:

0	0	1	0	0	0	0	0
---	---	---	---	---	---	---	---

bit address

rel. address

Operation: JB
(PC) \leftarrow (PC) + 3
IF (bit) = 1
THEN
(PC) \leftarrow (PC) + rel

JBC bit,rel

Function: Jump if Bit is set and Clear bit

Description: If the indicated bit is one, branch to the address indicated; otherwise proceed with the next instruction. *The bit will not be cleared if it is already a zero.* The branch destination is computed by adding the signed relative-displacement in the third instruction byte to the PC, after incrementing the PC to the first byte of the next instruction. No flags are affected.

Note: When this instruction is used to test an output pin, the value used as the original data will be read from the output data latch, *not* the input pin.

Example: The Accumulator holds 56H (01010110B). The instruction sequence,

```
JBC ACC.3,LABEL1
JBC ACC.2,LABEL2
```

will cause program execution to continue at the instruction identified by the label LABEL2, with the Accumulator modified to 52H (01010010B).

Bytes: 3

Cycles: 2

Encoding:



Operation:

```
JBC
(PC) ← (PC) + 3
IF (bit) = 1
  THEN
    (bit) ← 0
    (PC) ← (PC) + rel
```

Function: Jump if Carry is set

Description: If the carry flag is set, branch to the address indicated; otherwise proceed with the next instruction. The branch destination is computed by adding the signed relative-displacement in the second instruction byte to the PC, after incrementing the PC twice. No flags are affected.

Example: The carry flag is cleared. The instruction sequence,

```
JC LABEL1  
CPL C  
JC LABEL2
```

will set the carry and cause program execution to continue at the instruction identified by the label LABEL2.

Bytes: 2

Cycles: 2

Encoding:

0	1	0	0
---	---	---	---

0	0	0	0
---	---	---	---

rel. address

Operation: JC
(PC) \leftarrow (PC) + 2
IF (C) = 1
THEN
(PC) \leftarrow (PC) + rel

JMP @A + DPTR

Function: Jump indirect

Description: Add the eight-bit unsigned contents of the Accumulator with the sixteen-bit data pointer, and load the resulting sum to the program counter. This will be the address for subsequent instruction fetches. Sixteen-bit addition is performed (modulo 2^{16}): a carry-out from the low-order eight bits propagates through the higher-order bits. Neither the Accumulator nor the Data Pointer is altered. No flags are affected.

Example: An even number from 0 to 6 is in the Accumulator. The following sequence of instructions will branch to one of four AJMP instructions in a jump table starting at JMP_TBL:

```

MOV     DPTR, #JMP_TBL
JMP     @A + DPTR
JMP_TBL: AJMP LABEL0
          AJMP LABEL1
          AJMP LABEL2
          AJMP LABEL3

```

If the Accumulator equals 04H when starting this sequence, execution will jump to label LABEL2. Remember that AJMP is a two-byte instruction, so the jump instructions start at every other address.

Bytes: 1

Cycles: 2

Encoding:

0	1	1	1
---	---	---	---

0	0	1	1
---	---	---	---

Operation: JMP
(PC) ← (A) + (DPTR)

JNB bit,rel

Function: Jump if Bit Not set

Description: If the indicated bit is a zero, branch to the indicated address; otherwise proceed with the next instruction. The branch destination is computed by adding the signed relative-displacement in the third instruction byte to the PC, after incrementing the PC to the first byte of the next instruction. *The bit tested is not modified.* No flags are affected.

Example: The data present at input port 1 is 11001010B. The Accumulator holds 56H (01010110B). The instruction sequence,

```
JNB P1.3,LABEL1
JNB ACC.3,LABEL2
```

will cause program execution to continue at the instruction at label LABEL2.

Bytes: 3

Cycles: 2

Encoding:

0	0	1	1
---	---	---	---

0	0	0	0
---	---	---	---

bit address			
-------------	--	--	--

rel. address			
--------------	--	--	--

Operation: JNB
 $(PC) \leftarrow (PC) + 3$
 IF (bit) = 0
 THEN $(PC) \leftarrow (PC) + rel.$

JNC rel

Function: Jump if Carry not set

Description: If the carry flag is a zero, branch to the address indicated; otherwise proceed with the next instruction. The branch destination is computed by adding the signed relative-displacement in the second instruction byte to the PC, after incrementing the PC twice to point to the next instruction. The carry flag is not modified.

Example: The carry flag is set. The instruction sequence,

```
JNC LABEL1
CPL C
JNC LABEL2
```

will clear the carry and cause program execution to continue at the instruction identified by the label LABEL2.

Bytes: 2

Cycles: 2

Encoding:

0	1	0	1
---	---	---	---

0	0	0	0
---	---	---	---

rel. address			
--------------	--	--	--

Operation: JNC
 $(PC) \leftarrow (PC) + 2$
 IF (C) = 0
 THEN $(PC) \leftarrow (PC) + rel$

JNZ rel

Function: Jump if Accumulator Not Zero

Description: If any bit of the Accumulator is a one, branch to the indicated address; otherwise proceed with the next instruction. The branch destination is computed by adding the signed relative-displacement in the second instruction byte to the PC, after incrementing the PC twice. The Accumulator is not modified. No flags are affected.

Example: The Accumulator originally holds 00H. The instruction sequence,

```
JNZ LABEL1
INC A
JNZ LABEL2
```

will set the Accumulator to 01H and continue at label LABEL2.

Bytes: 2

Cycles: 2

Encoding:

0 1 1 1	0 0 0 0	rel. address
---------	---------	--------------

Operation:

```
JNZ
(PC) ← (PC) + 2
IF (A) ≠ 0
THEN (PC) ← (PC) + rel
```

JZ rel

Function: Jump if Accumulator Zero

Description: If all bits of the Accumulator are zero, branch to the address indicated; otherwise proceed with the next instruction. The branch destination is computed by adding the signed relative-displacement in the second instruction byte to the PC, after incrementing the PC twice. The Accumulator is not modified. No flags are affected.

Example: The Accumulator originally contains 01H. The instruction sequence,

```
JZ LABEL1
DEC A
JZ LABEL2
```

will change the Accumulator to 00H and cause program execution to continue at the instruction identified by the label LABEL2.

Bytes: 2

Cycles: 2

Encoding:

0 1 1 0	0 0 0 0	rel. address
---------	---------	--------------

Operation:

```
JZ
(PC) ← (PC) + 2
IF (A) = 0
THEN (PC) ← (PC) + rel
```

Function: Long call

Description: LCALL calls a subroutine located at the indicated address. The instruction adds three to the program counter to generate the address of the next instruction and then pushes the 16-bit result onto the stack (low byte first), incrementing the Stack Pointer by two. The high-order and low-order bytes of the PC are then loaded, respectively, with the second and third bytes of the LCALL instruction. Program execution continues with the instruction at this address. The subroutine may therefore begin anywhere in the full 64K-byte program memory address space. No flags are affected.

Example: Initially the Stack Pointer equals 07H. The label "SUBRTN" is assigned to program memory location 1234H. After executing the instruction,

LCALL SUBRTN

at location 0123H, the Stack Pointer will contain 09H, internal RAM locations 08H and 09H will contain 26H and 01H, and the PC will contain 1235H.

Bytes: 3

Cycles: 2

Encoding:

0 0 0 1 0 0 1 0

addr15-addr8

addr7-addr0

Operation:

LCALL

$(PC) \leftarrow (PC) + 3$

$(SP) \leftarrow (SP) + 1$

$((SP)) \leftarrow (PC_{7:0})$

$(SP) \leftarrow (SP) + 1$

$((SP)) \leftarrow (PC_{15:8})$

$(PC) \leftarrow \text{addr}_{15:0}$

LJMP addr16

Function:	Long Jump				
Description:	LJMP causes an unconditional branch to the indicated address, by loading the high-order and low-order bytes of the PC (respectively) with the second and third instruction bytes. The destination may therefore be anywhere in the full 64K program memory address space. No flags are affected.				
Example:	The label “JMPADR” is assigned to the instruction at program memory location 1234H. The instruction, LJMP JMPADR at location 0123H will load the program counter with 1234H.				
Bytes:	3				
Cycles:	2				
Encoding:	<table><tr><td>0 0 0 0</td><td>0 0 1 0</td><td>addr15-addr8</td><td>addr7-addr0</td></tr></table>	0 0 0 0	0 0 1 0	addr15-addr8	addr7-addr0
0 0 0 0	0 0 1 0	addr15-addr8	addr7-addr0		
Operation:	LJMP (PC) ← addr _{15:0}				

MOV <dest-byte>,<src-byte>

Function:	Move byte variable
Description:	The byte variable indicated by the second operand is copied into the location specified by the first operand. The source byte is not affected. No other register or flag is affected. This is by far the most flexible operation. Fifteen combinations of source and destination addressing modes are allowed.
Example:	Internal RAM location 30H holds 40H. The value of RAM location 40H is 10H. The data present at input port 1 is 11001010B (0CAH). <pre> MOV R0,#30H ;R0 <= 30H MOV A,@R0 ;A <= 40H MOV R1,A ;R1 <= 40H MOV R,@R1 ;B <= 10H MOV @R1,P1 ;RAM (40H) <= 0CAH MOV P2,P1 ;P2 #0CAH </pre> leaves the value 30H in register 0, 40H in both the Accumulator and register 1, 10H in register B, and 0CAH (11001010B) both in RAM location 40H and output on port 2.

MOV A,Rn

Bytes: 1

Cycles: 1

Encoding:

1	1	1	0
1	r	r	r

Operation: MOV
(A) ← (Rn)

MOV A,direct

Bytes: 2

Cycles: 1

Encoding:

1	1	1	0
0	1	0	1

direct address

Operation: MOV
(A) ← (direct)

MOV A,ACC is not a valid instruction.

MOV A,@Ri

Bytes: 1

Cycles: 1

Encoding:

1	1	1	0
0	1	1	i

Operation: MOV
(A) ← ((Ri))

MOV A,#data

Bytes: 2

Cycles: 1

Encoding:

0	1	1	1
0	1	0	0

immediate data

Operation: MOV
(A) ← #data

Instruction	Operation	Bytes	Cycles	Encoding
MOV Rn,A	$(Rn) \leftarrow (A)$	1	1	1 1 1 1 1 r r r
MOV Rn,direct	$(Rn) \leftarrow (direct)$	2	2	1 0 1 0 1 r r r direct addr.
MOV Rn,#data	$(Rn) \leftarrow \#data$	2	1	0 1 1 1 1 r r r immediate data
MOV direct,A	$(A) \leftarrow (direct)$	2	1	1 1 1 1 0 1 0 1 direct address
MOV direct,Rn	$(direct) \leftarrow (Rn)$	2	2	1 0 0 0 1 r r r direct address

Bytes: 3
Cycles: 2
Encoding:

1	0	0	0
---	---	---	---

0	1	0	1
---	---	---	---

dir. addr. (src)			
------------------	--	--	--

dir. addr. (dest)			
-------------------	--	--	--

Operation: MOV
 (direct) ← (direct)

MOV direct,@Ri

Bytes: 2
Cycles: 2
Encoding:

1	0	0	0
---	---	---	---

0	1	1	i
---	---	---	---

direct addr.			
--------------	--	--	--

Operation: MOV
 (direct) ← ((Ri))

MOV direct,#data

Bytes: 3
Cycles: 2
Encoding:

0	1	1	1
---	---	---	---

0	1	0	1
---	---	---	---

direct address			
----------------	--	--	--

immediate data			
----------------	--	--	--

Operation: MOV
 (direct) ← #data

MOV @Ri,A

Bytes: 1
Cycles: 1
Encoding:

1	1	1	1
---	---	---	---

0	1	1	i
---	---	---	---

Operation: MOV
 ((Ri)) ← (A)

MOV @Ri,direct

Bytes: 2
Cycles: 2
Encoding:

1	0	1	0
---	---	---	---

0	1	1	i
---	---	---	---

direct addr.			
--------------	--	--	--

Operation: MOV
 ((Ri)) ← (direct)

MOV @RI,#data

Bytes: 2

Cycles: 1

Encoding:

0	1	1	1
---	---	---	---

0	1	1	i
---	---	---	---

immediate data

Operation: MOV
((RI)) ← #data

MOV <dest-bit>,<src-bit>

Function: Move bit data

Description: The Boolean variable indicated by the second operand is copied into the location specified by the first operand. One of the operands must be the carry flag; the other may be any directly addressable bit. No other register or flag is affected.

Example: The carry flag is originally set. The data present at input Port 3 is 11000101B. The data previously written to output Port 1 is 35H (00110101B).

```
MOV P1.3,C
MOV C,P3.3
MOV P1.2,C
```

will leave the carry cleared and change Port 1 to 39H (00111001B).

MOV C,bit

Bytes: 2

Cycles: 1

Encoding:

1	0	1	0
---	---	---	---

0	0	1	0
---	---	---	---

bit address

Operation: MOV
(C) ← (bit)

MOV bit,C

Bytes: 2

Cycles: 2

Encoding:

1	0	0	1
---	---	---	---

0	0	1	0
---	---	---	---

bit address

Operation: MOV
(bit) ← (C)

MOV DPTR,#data16

Function: Load Data Pointer with a 16-bit constant

Description: The Data Pointer is loaded with the 16-bit constant indicated. The 16-bit constant is loaded into the second and third bytes of the instruction. The second byte (DPH) is the high-order byte, while the third byte (DPL) holds the low-order byte. No flags are affected.

This is the only instruction which moves 16 bits of data at once.

Example: The instruction,

```
MOV DPTR,#1234H
```

will load the value 1234H into the Data Pointer: DPH will hold 12H and DPL will hold 34H.

Bytes: 3

Cycles: 2

Encoding:

1	0	0	1	0	0	0	0	immed. data15-8	immed. data7-0
---	---	---	---	---	---	---	---	-----------------	----------------

Operation:

```
MOV
(DPTR) ← #data15-0
DPH □ DPL ← #data15-8 □ #data7-0
```

MOVC A,@A+ <base-reg>

- Function:** Move Code byte
- Description:** The MOVC instructions load the Accumulator with a code byte, or constant from program memory. The address of the byte fetched is the sum of the original unsigned eight-bit Accumulator contents and the contents of a sixteen-bit base register, which may be either the Data Pointer or the PC. In the latter case, the PC is incremented to the address of the following instruction before being added with the Accumulator; otherwise the base register is not altered. Sixteen-bit addition is performed so a carry-out from the low-order eight bits may propagate through higher-order bits. No flags are affected.
- Example:** A value between 0 and 3 is in the Accumulator. The following instructions will translate the value in the Accumulator to one of four values defined by the DB (define byte) directive.

REL_PC: INC A

MOVC A,@A+PC

RET

DB 66H

DB 77H

DB 88H

DB 99H

If the subroutine is called with the Accumulator equal to 01H, it will return with 77H in the Accumulator. The INC A before the MOVC instruction is needed to “get around” the RET instruction above the table. If several bytes of code separated the MOVC from the table, the corresponding number would be added to the Accumulator instead.

MOVC A,@A+DPTR

Bytes: 1

Cycles: 2

Encoding: 1 0 0 1 0 0 1 1

Operation: MOVC
(A) ← ((A) + (DPTR))

Bytes:	1	
Cycles:	2	
Encoding:	1 0 0 0	0 0 1 1
Operation:	MOVX $(PC) \leftarrow (PC) + 1$ $(A) \leftarrow ((A) + (PC))$	
MOVX <dest-byte>,<src-byte>		

Function: Move External

Description: The MOVX instructions transfer data between the Accumulator and a byte of external data memory, hence the "X" appended to MOV. There are two types of instructions, differing in whether they provide an eight-bit or sixteen-bit indirect address to the external data RAM.

In the first type, the contents of R0 or R1 in the current register bank provide an eight-bit address multiplexed with data on P0. Eight bits are sufficient for external I/O expansion decoding or for a relatively small RAM array. For somewhat larger arrays, any output port pins can be used to output higher-order address bits. These pins would be controlled by an output instruction preceding the MOVX.

In the second type of MOVX instruction, the Data Pointer generates a sixteen-bit address. P2 outputs the high-order eight address bits (the contents of DPH) while P0 multiplexes the low-order eight bits (DPL) with data. The P2 Special Function Register retains its previous contents while the P2 output buffers are emitting the contents of DPH. This form is faster and more efficient when accessing very large data arrays (up to 64K bytes), since no additional instructions are needed to set up the output ports.

It is possible in some situations to mix the two MOVX types. A large RAM array with its high-order address lines driven by P2 can be addressed via the Data Pointer, or with code to output high-order address bits to P2 followed by a MOVX instruction using R0 or R1.

Example: An external 256 byte RAM using multiplexed address/data lines (e.g., an Intel 8155 RAM/I/O/Timer) is connected to the 8051 Port 0. Port 3 provides control lines for the external RAM. Ports 1 and 2 are used for normal I/O. Registers 0 and 1 contain 12H and 34H. Location 34H of the external RAM holds the value 56H. The instruction sequence,

```
MOVX A,@R1
```

```
MOVX @R0,A
```

copies the value 56H into both the Accumulator and external RAM location 12H.

MOVX A,@RI	
Bytes: 1	
Cycles: 2	
Encoding:	1 1 1 0 0 0 1 i
Operation:	MOVX (A) ← ((RI))
MOVX A,@DPTR	
Bytes: 1	
Cycles: 2	
Encoding:	1 1 1 0 0 0 0 0
Operation:	MOVX (A) ← ((DPTR))
MOVX @RI,A	
Bytes: 1	
Cycles: 2	
Encoding:	1 1 1 1 0 0 0 1 i
Operation:	MOVX ((RI)) ← (A)
MOVX @DPTR,A	
Bytes: 1	
Cycles: 2	
Encoding:	1 1 1 1 0 0 0 0
Operation:	MOVX (DPTR) ← (A)

NOP

Function: No Operation

Description: Execution continues at the following instruction. Other than the PC, no registers or flags are affected.

Example: It is desired to produce a low-going output pulse on bit 7 of Port 2 lasting exactly 5 cycles. A simple SETB/CLR sequence would generate a one-cycle pulse, so four additional cycles must be inserted. This may be done (assuming no interrupts are enabled) with the instruction sequence,

```
CLR    P2.7
NOP
NOP
NOP
NOP
SETB   P2.7
```

Bytes: 1

Cycles: 1

Encoding:

0 0 0 0	0 0 0 0
---------	---------

Operation: NOP
(PC) \leftarrow (PC) + 1

MUL AB

Function: Multiply

Description: MUL AB multiplies the unsigned eight-bit integers in the Accumulator and register B. The low-order byte of the sixteen-bit product is left in the Accumulator, and the high-order byte in B. If the product is greater than 255 (OFFH) the overflow flag is set; otherwise it is cleared. The carry flag is always cleared.

Example: Originally the Accumulator holds the value 80 (50H). Register B holds the value 160 (0A0H). The instruction,

```
MUL AB
```

will give the product 12,800 (3200H), so B is changed to 32H (00110010B) and the Accumulator is cleared. The overflow flag is set, carry is cleared.

Bytes: 1

Cycles: 4

Encoding:

1 0 1 0	0 1 0 0
---------	---------

Operation: MUL
(A)₇₋₀ \leftarrow (A) X (B)
(B)₁₅₋₈

ORL <dest-byte> <src-byte>

Function: Logical-OR for byte variables

Description: ORL performs the bitwise logical-OR operation between the indicated variables, storing the results in the destination byte. No flags are affected.

The two operands allow six addressing mode combinations. When the destination is the Accumulator, the source can use register, direct, register-indirect, or immediate addressing; when the destination is a direct address, the source can be the Accumulator or immediate data.

Note: When this instruction is used to modify an output port, the value used as the original port data will be read from the output data latch, *not* the input pins.

Example: If the Accumulator holds 0C3H (11000011B) and R0 holds 55H (01010101B) then the instruction,

ORL A,R0

will leave the Accumulator holding the value 0D7H (11010111B).

When the destination is a directly addressed byte, the instruction can set combinations of bits in any RAM location or hardware register. The pattern of bits to be set is determined by a mask byte, which may be either a constant data value in the instruction or a variable computed in the Accumulator at run-time. The instruction,

ORL P1,#00110010B

will set bits 5, 4, and 1 of output Port 1.

ORL A,Rn

Bytes: 1

Cycles: 1

Encoding: 0 1 0 0 1 r r r

Operation: ORL
(A) ← (A) V (Rn)

Bytes:	2			
Cycles:	1			
Encoding:	0 1 0 0	0 1 0 1	direct address	
Operation:	ORL (A) ← (A) ∨ (direct)			
ORL A,@RI				
Bytes:	1			
Cycles:	1			
Encoding:	0 1 0 0	0 1 1 i		
Operation:	ORL (A) ← (A) ∨ ((Ri))			
ORL A,#data				
Bytes:	2			
Cycles:	1			
Encoding:	0 1 0 0	0 1 0 0	immediate data	
Operation:	ORL (A) ← (A) ∨ #data			
ORL direct,A				
Bytes:	2			
Cycles:	1			
Encoding:	0 1 0 0	0 0 1 0	direct address	
Operation:	ORL (direct) ← (direct) ∨ (A)			
ORL direct,#data				
Bytes:	3			
Cycles:	2			
Encoding:	0 1 0 0	0 0 1 1	direct addr.	immediate data
Operation:	ORL (direct) ← (direct) ∨ #data			

ORL C,<src-bit>

Function: Logical-OR for bit variables

Description: Set the carry flag if the Boolean value is a logical 1; leave the carry in its current state otherwise. A slash ("/") preceding the operand in the assembly language indicates that the logical complement of the addressed bit is used as the source value, but the source bit itself is not affected. No other flags are affected.

Example: Set the carry flag if and only if P1.0 = 1, ACC. 7 = 1, or OV = 0:

MOV C,P1.0 ;LOAD CARRY WITH INPUT PIN P1.0

ORL C,ACC.7 ;OR CARRY WITH THE ACC. BIT 7

ORL C,/OV ;OR CARRY WITH THE INVERSE OF OV.

ORL C,bit

Bytes: 2

Cycles: 2

Encoding:

0	1	1	1
---	---	---	---

0	0	1	0
---	---	---	---

bit address			
-------------	--	--	--

Operation: ORL
(C) ← (C) ∨ (bit)

ORL C,/bit

Bytes: 2

Cycles: 2

Encoding:

1	0	1	0
---	---	---	---

0	0	0	0
---	---	---	---

bit address			
-------------	--	--	--

Operation: ORL
(C) ← (C) ∨ ($\overline{\text{bit}}$)

POP direct

Function: Pop from stack.

Description: The contents of the internal RAM location addressed by the Stack Pointer is read, and the Stack Pointer is decremented by one. The value read is then transferred to the directly addressed byte indicated. No flags are affected.

Example: The Stack Pointer originally contains the value 32H, and internal RAM locations 30H through 32H contain the values 20H, 23H, and 01H, respectively. The instruction sequence,

POP DPH

POP DPL

will leave the Stack Pointer equal to the value 30H and the Data Pointer set to 0123H. At this point the instruction,

POP SP

will leave the Stack Pointer set to 20H. Note that in this special case the Stack Pointer was decremented to 2FH before being loaded with the value popped (20H).

Bytes: 2

Cycles: 2

Encoding:

1 1 0 1 0 0 0 0

direct address

Operation:

POP

(direct) \leftarrow ((SP))

(SP) \leftarrow (SP) - 1

PUSH direct

Function: Push onto stack

Description: The Stack Pointer is incremented by one. The contents of the indicated variable is then copied into the internal RAM location addressed by the Stack Pointer. Otherwise no flags are affected.

Example: On entering an interrupt routine the Stack Pointer contains 09H. The Data Pointer holds the value 0123H. The instruction sequence,

PUSH DPL

PUSH DPH

will leave the Stack Pointer set to 0BH and store 23H and 01H in internal RAM locations 0AH and 0BH, respectively.

Bytes: 2

Cycles: 2

Encoding:

1	1	0	0	0	0	0	0
---	---	---	---	---	---	---	---

direct address

Operation:

PUSH
 $(SP) \leftarrow (SP) + 1$
 $((SP)) \leftarrow (\text{direct})$

RET

Function: Return from subroutine

Description: RET pops the high- and low-order bytes of the PC successively from the stack, decrementing the Stack Pointer by two. Program execution continues at the resulting address, generally the instruction immediately following an ACALL or LCALL. No flags are affected.

Example: The Stack Pointer originally contains the value 0BH. Internal RAM locations 0AH and 0BH contain the values 23H and 01H, respectively. The instruction,

RET

will leave the Stack Pointer equal to the value 09H. Program execution will continue at location 0123H.

Bytes: 1

Cycles: 2

Encoding:

0	0	1	0	0	0	1	0
---	---	---	---	---	---	---	---

Operation:

RET
 $(PC_{15-8}) \leftarrow ((SP))$
 $(SP) \leftarrow (SP) - 1$
 $(PC_{7-0}) \leftarrow ((SP))$
 $(SP) \leftarrow (SP) - 1$

Description: RETI pops the high- and low-order bytes of the PC successively from the stack, and restores the interrupt logic to accept additional interrupts at the same priority level as the one just processed. The Stack Pointer is left decremented by two. No other registers are affected; the PSW is *not* automatically restored to its pre-interrupt status. Program execution continues at the resulting address, which is generally the instruction immediately after the point at which the interrupt request was detected. If a lower- or same-level interrupt had been pending when the RETI instruction is executed, that one instruction will be executed before the pending interrupt is processed.

Example: The Stack Pointer originally contains the value 0BH. An interrupt was detected during the instruction ending at location 0122H. Internal RAM locations 0AH and 0BH contain the values 23H and 01H, respectively. The instruction,

RETI

will leave the Stack Pointer equal to 09H and return program execution to location 0123H.

Bytes: 1

Cycles: 2

Encoding: 0 0 1 1 0 0 1 0

Operation: RETI
 $(PC_{15-8}) \leftarrow ((SP))$
 $(SP) \leftarrow (SP) - 1$
 $(PC_{7-0}) \leftarrow ((SP))$
 $(SP) \leftarrow (SP) - 1$

RL A

Function: Rotate Accumulator Left

Description: The eight bits in the Accumulator are rotated one bit to the left. Bit 7 is rotated into the bit 0 position. No flags are affected.

Example: The Accumulator holds the value 0C5H (11000101B). The instruction,

RL A

leaves the Accumulator holding the value 8BH (10001011B) with the carry unaffected.

Bytes: 1

Cycles: 1

Encoding: 0 0 1 0 0 0 1 1

Operation: RL
 $(A_n + 1) \leftarrow (A_n) \quad n = 0 - 6$
 $(A_0) \leftarrow (A_7)$

RLC A

Function: Rotate Accumulator Left through the Carry flag

Description: The eight bits in the Accumulator and the carry flag are together rotated one bit to the left. Bit 7 moves into the carry flag; the original state of the carry flag moves into the bit 0 position. No other flags are affected.

Example: The Accumulator holds the value 0C5H (11000101B), and the carry is zero. The instruction,

RLC A

leaves the Accumulator holding the value 8BH (10001010B) with the carry set.

Bytes: 1

Cycles: 1

Encoding:

0 0 1 1	0 0 1 1
---------	---------

Operation: RLC
 $(A_n + 1) \leftarrow (A_n) \quad n = 0 - 6$
 $(A_0) \leftarrow (C)$
 $(C) \leftarrow (A_7)$

RR A

Function: Rotate Accumulator Right

Description: The eight bits in the Accumulator are rotated one bit to the right. Bit 0 is rotated into the bit 7 position. No flags are affected.

Example: The Accumulator holds the value 0C5H (11000101B). The instruction,

RR A

leaves the Accumulator holding the value 0E2H (11100010B) with the carry unaffected.

Bytes: 1

Cycles: 1

Encoding:

0 0 0 0	0 0 1 1
---------	---------

Operation: RR
 $(A_n) \leftarrow (A_n + 1) \quad n = 0 - 6$
 $(A_7) \leftarrow (A_0)$

RRC A

Function: Rotate Accumulator Right through Carry flag

Description: The eight bits in the Accumulator and the carry flag are together rotated one bit to the right. Bit 0 moves into the carry flag; the original value of the carry flag moves into the bit 7 position. No other flags are affected.

Example: The Accumulator holds the value 0C5H (11000101B), the carry is zero. The instruction,

RRC A

leaves the Accumulator holding the value 62 (01100010B) with the carry set.

Bytes: 1

Cycles: 1

Encoding:

0	0	0	1
---	---	---	---

0	0	1	1
---	---	---	---

Operation: RRC
 $(A_n) \leftarrow (A_n + 1) \quad n = 0 - 6$
 $(A_7) \leftarrow (C)$
 $(C) \leftarrow (A_0)$

SETB <bit>

Function: Set Bit

Description: SETB sets the indicated bit to one. SETB can operate on the carry flag or any directly addressable bit. No other flags are affected.

Example: The carry flag is cleared. Output Port 1 has been written with the value 34H (00110100B). The instructions,

SETB C

SETB P1.0

will leave the carry flag set to 1 and change the data output on Port 1 to 35H (00110101B).

SETB C

Bytes: 1

Cycles: 1

Encoding:

1	1	0	1
---	---	---	---

0	0	1	1
---	---	---	---

Operation: SETB
 $(C) \leftarrow 1$

SETB bit

Bytes: 2

Cycles: 1

Encoding: 1 1 0 1 0 0 1 0 bit address

Operation: SETB
(bit) ← 1

SJMP rel

Function: Short Jump

Description: Program control branches unconditionally to the address indicated. The branch destination is computed by adding the signed displacement in the second instruction byte to the PC, after incrementing the PC twice. Therefore, the range of destinations allowed is from 128 bytes preceding this instruction to 127 bytes following it.

Example: The label "RELADR" is assigned to an instruction at program memory location 0123H. The instruction,

SJMP RELADR

will assemble into location 0100H. After the instruction is executed, the PC will contain the value 0123H.

(Note: Under the above conditions the instruction following SJMP will be at 102H. Therefore, the displacement byte of the instruction will be the relative offset (0123H-0102H) = 21H. Put another way, an SJMP with a displacement of 0FEH would be a one-instruction infinite loop.)

Bytes: 2

Cycles: 2

Encoding: 1 0 0 0 0 0 0 0 rel. address

Operation: SJMP
(PC) ← (PC) + 2
(PC) ← (PC) + rel

Description:

SUBB subtracts the indicated variable and the carry flag together from the Accumulator, leaving the result in the Accumulator. SUBB sets the carry (borrow) flag if a borrow is needed for bit 7, and clears C otherwise. (If C was set *before* executing a SUBB instruction, this indicates that a borrow was needed for the previous step in a multiple precision subtraction, so the carry is subtracted from the Accumulator along with the source operand.) AC is set if a borrow is needed for bit 3, and cleared otherwise. OV is set if a borrow is needed into bit 6, but not into bit 7, or into bit 7, but not bit 6.

When subtracting signed integers OV indicates a negative number produced when a negative value is subtracted from a positive value, or a positive result when a positive number is subtracted from a negative number.

The source operand allows four addressing modes: register, direct, register-indirect, or immediate.

Example:

The Accumulator holds 0C9H (11001001B), register 2 holds 54H (01010100B), and the carry flag is set. The instruction,

SUBB A,R2

will leave the value 74H (01110100B) in the accumulator, with the carry flag and AC cleared but OV set.

Notice that 0C9H minus 54H is 75H. The difference between this and the above result is due to the carry (borrow) flag being set before the operation. If the state of the carry is not known before starting a single or multiple-precision subtraction, it should not be explicitly cleared by a CLR C instruction.

SUBB A,Rn

Bytes: 1

Cycles: 1

Encoding:

1	0	0	1
---	---	---	---

1	r	r	r
---	---	---	---

Operation: SUBB
 $(A) \leftarrow (A) - (C) - (Rn)$

SUBB A,direct

Bytes: 2

Cycles: 1

Encoding:

1	0	0	1
---	---	---	---

0	1	0	1
---	---	---	---

direct address

Operation: SUBB
 $(A) \leftarrow (A) - (C) - (\text{direct})$

SUBB A,@RI	<Byte>
Bytes:	1
Cycles:	1
Encoding:	1 0 0 1 0 1 1 i
Operation:	SUBB (A) ← (A) - (C) - ((Ri))
SUBB A,#data	
Bytes:	2
Cycles:	1
Encoding:	1 0 0 1 0 1 0 0 immediate data
Operation:	SUBB (A) ← (A) - (C) - #data
SWAP A	
Function:	Swap nibbles within the Accumulator
Description:	SWAP A interchanges the low- and high-order nibbles (four-bit fields) of the Accumulator (bits 3-0 and bits 7-4). The operation can also be thought of as a four-bit rotate instruction. No flags are affected.
Example:	The Accumulator holds the value 0C5H (11000101B). The instruction, SWAP A leaves the Accumulator holding the value 5CH (01011100B).
Bytes:	1
Cycles:	1
Encoding:	1 1 0 0 0 1 0 0
Operation:	SWAP (A ₃₋₀) ↔ (A ₇₋₄)

XCH A,<byte>

Function: Exchange Accumulator with byte variable

Description: XCH loads the Accumulator with the contents of the indicated variable, at the same time writing the original Accumulator contents to the indicated variable. The source/destination operand can use register, direct, or register-indirect addressing.

Example: R0 contains the address 20H. The Accumulator holds the value 3FH (00111111B). Internal RAM location 20H holds the value 75H (01110101B). The instruction,

XCH A,@R0

will leave RAM location 20H holding the values 3FH (00111111B) and 75H (01110101B) in the accumulator.

XCH A,Rn

Bytes: 1

Cycles: 1

Encoding: 1 1 0 0 1 r r r

Operation: XCH
(A) \leftrightarrow (Rn)

XCH A,direct

Bytes: 2

Cycles: 1

Encoding: 1 1 0 0 0 1 0 1 direct address

Operation: XCH
(A) \leftrightarrow (direct)

XCH A,@Ri

Bytes: 1

Cycles: 1

Encoding: 1 1 0 0 0 1 1 i

Operation: XCH
(A) \leftrightarrow ((Ri))

XCHD A,@RI

Function:	Exchange Digit								
Description:	XCHD exchanges the low-order nibble of the Accumulator (bits 3-0), generally representing a hexadecimal or BCD digit, with that of the internal RAM location indirectly addressed by the specified register. The high-order nibbles (bits 7-4) of each register are not affected. No flags are affected.								
Example:	<p>R0 contains the address 20H. The Accumulator holds the value 36H (00110110B). Internal RAM location 20H holds the value 75H (01110101B). The instruction,</p> <p>XCHD A,@R0</p> <p>will leave RAM location 20H holding the value 76H (01110110B) and 35H (00110101B) in the Accumulator.</p>								
Bytes:	1								
Cycles:	1								
Encoding:	<table><tr><td>1</td><td>1</td><td>0</td><td>1</td></tr><tr><td>0</td><td>1</td><td>1</td><td>1</td></tr></table>	1	1	0	1	0	1	1	1
1	1	0	1						
0	1	1	1						
Operation:	XCHD (A ₃₋₀) ↔ ((R _{i3-0}))								

XRL <dest-byte>,<src-byte>

Function:	Logical Exclusive-OR for byte variables
Description:	<p>XRL performs the bitwise logical Exclusive-OR operation between the indicated variables, storing the results in the destination. No flags are affected.</p> <p>The two operands allow six addressing mode combinations. When the destination is the Accumulator, the source can use register, direct, register-indirect, or immediate addressing; when the destination is a direct address, the source can be the Accumulator or immediate data.</p> <p>(Note: When this instruction is used to modify an output port, the value used as the original port data will be read from the output data latch, <i>not</i> the input pins.)</p>
Example:	<p>If the Accumulator holds 0C3H (11000011B) and register 0 holds 0AAH (10101010B) then the instruction,</p> <p>XRL A,R0</p> <p>will leave the Accumulator holding the value 69H (01101001B).</p> <p>When the destination is a directly addressed byte, this instruction can complement combinations of bits in any RAM location or hardware register. The pattern of bits to be complemented is then determined by a mask byte, either a constant contained in the instruction or a variable computed in the Accumulator at run-time. The instruction,</p> <p>XRL P1,#00110001B</p> <p>will complement bits 5, 4, and 0 of output Port 1.</p>

CHAPTER 4

Cycles: 1

Encoding: 0 1 1 0 1 r r r

Operation: XRL
(A) ← (A) ∨ (Rn)

XRL A, direct

Bytes: 2

Cycles: 1

Encoding: 0 1 1 0 0 1 0 1

direct address

Operation: XRL
(A) ← (A) ∨ (direct)

XRL A, @Ri

Bytes: 1

Cycles: 1

Encoding: 0 1 1 0 0 1 1 i

Operation: XRL
(A) ← (A) ∨ ((Ri))

XRL A, #data

Bytes: 2

Cycles: 1

Encoding: 0 1 1 0 0 1 0 0

immediate data

Operation: XRL
(A) ← (A) ∨ #data

XRL direct, A

Bytes: 2

Cycles: 1

Encoding: 0 1 1 0 0 0 1 0

direct address

Operation: XRL
(direct) ← (direct) ∨ (A)

XRL **direct,#data**

Bytes: 3

Cycles: 2

Encoding:

0 1 1 0 0 0 1 1

direct address

immediate data

Operation:

XRL
(direct) ← (direct) ∨ #data

CHAPTER 5

Software Routines

8051 Programming Techniques

- Radix Conversion Routines
- Multiple Precision Arithmetic
- Table Look-Up Sequences

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0 1 0 0 1 1

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CHAPTER 5

Software Routines

Chapter 5 contains two sections:

- 8051 Programming Techniques
- Peripheral Interfacing Techniques.

The first section has 8051 software examples for some common routines in controller applications. Some routines included are multiple-precision arithmetic and table look-up techniques.

Peripheral Interfacing Techniques include routines for handling the 8051's I/O ports, serial channel and timer/counters. Discussed in this section is I/O port reconfiguration, software delay timing, and transmitting serial port character strings along with other routines.

8051 PROGRAMMING TECHNIQUES

Radix Conversion Routines

The divide instruction can be used to convert a number from one radix to another. BINBCD is a short subroutine to convert an 8-bit unsigned binary integer in the accumulator (between 0 & 255) to a 3-digit (2 byte) BCD representation. The hundred's digit is returned in one variable (HUND) and the ten's and one's digits returned as packed BCD in another (TENONE).

```
;
;BINBCD      CONVERT 8-BIT BINARY VARIABLE IN ACCUMULATOR
;            TO 3-DIGIT PACKED BCD FORMAT.
;            HUNDREDS' PLACE LEFT IN VARIABLE 'HUND',
;            TENS' AND ONES' PLACES IN 'TENONE'.
;
;HUND        DATA    21H
;TENONE      DATA    22H
;
;BINBCD:     MOV      B, #100          ;DIVIDED BY 100 TO
;                               DIV     AB          ;DETERMINE NUMBER OF HUNDREDS
;                               MOV     HUND, A
;                               MOV     A, #10      ;DIVIDE REMAINDER BY TEN TO
;                               XCH     A, B         ;DETERMINE NUMBER OF TENS LEFT
;                               DIV     AB         ;TEN'S DIGIT IN ACC, REMAINDER IS
;                               ;ONE'S DIGIT
;                               SWAP     A
;                               ADD     A, B        ;PACK BCD DIGITS IN ACC
;                               MOV     TENONE, A
;                               RET
;
```

The divide instruction can also separate data in the accumulator into sub-fields. For example, dividing packed BCD data by 16 will separate the two nibbles, leaving the high-order digit in the accumulator and the low-order digit (remainder) in B. Each is right-justified, so

the digits can be processed individually. This example receives two packed BCD digits in the accumulator, separates the digits, computes their product, and returns the product in packed BCD format in the accumulator.

```
;
;MULBCD      UNPACK TWO BCD DIGITS RECEIVED IN ACCUMULATOR
;            FIND THEIR PRODUCT, AND RETURN PRODUCT
;            IN PACKED BCD FORMAT IN ACCUMULATOR
;
;MULBCD:     MOV      B, #10H          ;DIVIDE INPUT BY 16
;                               DIV     AB          ;A & B HOLD SEPARATED DIGITS
;                               ;(EACH RIGHT JUSTIFIED IN REGISTER).
;                               MUL     AB          ;A HOLDS PRODUCT IN BINARY FORMAT
;                               ;(0 TO 99 (DECIMAL) = 0 TO 63H)
;                               MOV     B, #10      ;DIVIDE PRODUCT BY 10
;                               DIV     AB          ;A HOLDS NUMBER OF TENS, B HOLDS
;                               ;REMAINDER
```

```

SWAP      A
ORL       A,B          ;PACK DIGITS
RET

```

Multiple Precision Arithmetic

The ADDC and SUBB instructions incorporate the previous state of the carry (borrow) flag to allow multiple-precision calculations by repeating the operation with successively higher-order operand bytes. If the input data for a multiple-precision operation is an unsigned

string of integers, the carry flag will be set upon completion if an overflow (for ADDC) or underflow (for SUBB) occurs. With two's complement signed data, the most significant bit of the original input data's most significant byte indicates the sign of the string, so the overflow flag (OV) will indicate if overflow or underflow occurred.

```

;
; SUBSTR      SUBTRACT STRING INDICATED BY R1
;             FROM STRING INDICATED BY R0 TO
;             PRECISION INDICATED BY R2.
;             CHECK FOR SIGNED UNDERFLOW WHEN DONE.
;
SUBSTR:      CLR      C          ;BORROW = 0.
SUBS1:       MOV      A,@R0      ;LOAD MINUEND BYTE
             SUBB     A,@R1      ;SUBTRACT SUBTRAHEND BYTE
             MOV      @R0,A      ;STORE DIFFERENCE BYTE
             INC      R0         ;BUMP POINTERS TO NEXT PLACE
             INC      R1
             DJNZ     R2,SUBS1    ;LOOP UNTIL DONE
;
;             WHEN DONE, TEST IF OVERFLOW OCCURRED
;             ON LAST ITERATION OF LOOP.
;
             JNB     OV,OV_OK    ;
;
;             ...              (OVERFLOW RECOVERY ROUTINE)
OV_OK:       RET                ;RETURN

```

Table Look-Up Sequences

The two versions of the MOVC instructions are used as part of a 3-step sequence to access look-up tables in ROM. To use the DPTR version, load the Data Pointer with the starting address of a look-up table; load the accumulator with (or compute) the index of the entry desired; and execute MOVC A, @A + DPTR. The data pointer may be loaded with a constant for short tables, or to allow more complicated data structures, and tables with more than 256 entries, the values for DPH and DPL may be computed or modified with the standard arithmetic instruction set.

The PC-based version is used with smaller, "local" tables, and has the advantage of not affecting the data pointer. This makes it useful in interrupt routines or other situations where the DPTR contents might be significant. Again, a look-up sequence takes three steps: load the accumulator with the index; compensate for the offset from the look-up instruction's address to the start of the table by adding that offset to the accumulator; then execute the MOVC A,@A + PC instruction.

As a non-trivial situation where this instruction would be used, consider applications which store large multi-

dimensional look-up tables of dot matrix patterns, non-linear calibration parameters, and so on in the linear (one-dimensional) program memory. To retrieve data from the tables, variables representing matrix indices must be converted to the desired entry's memory address. For a matrix of dimensions (MDIMEN x NDIMEN) starting at address BASE and respective indices INDEXI and INDEXJ, the address of element (INDEXI, INDEXJ) is determined by the formula,

$$\text{Entry Address} = [\text{BASE} + (\text{NDIMEN} \times \text{INDEXI}) + \text{INDEXJ}]$$

The subroutine MATRX1 can access an entry in any array with less than 255 elements, e.g., an 11x21 array with 231 elements. The table entries are defined using the Data Byte ("DB") directive, and will be contained in the assembly object code as part of the accessing subroutine itself.

To handle the more general case, subroutine MATRX2 allows tables to be unlimited in size, by combining the MUL instruction, double-precision addition, and the data pointer-based version of MOVC. The only restriction is that each index be between 0 and 255.

```

;
;MATRIX LOAD CONSTANT READ FROM TWO DIMENSIONAL LOOK-UP
;TABLE IN PROGRAM MEMORY INTO ACCUMULATOR
;USING LOCAL TABLE LOOK-UP INSTRUCTION, 'MOVC A,@A + PC'.
;THE TOTAL NUMBER OF TABLE ENTRIES IS ASSUMED TO
;BE SMALL, I.E. LESS THAN ABOUT 255 ENTRIES.
;TABLE USED IN THIS EXAMPLE IS 11 x 21.
;DESIRED ENTRY ADDRESS IS GIVEN BY THE FORMULA,
;[(BASE ADDRESS) + (21 X INDEXI) + (INDEXJ)]
;
INDEXI EQU R6 ;FIRST COORDINATE OF ENTRY (0-10).
INDEXJ DATA 23H ;SECOND COORDINATE OF ENTRY (0-20).
;
;MATRIX1: MOV A,INDEXI
;MOV B,#21
;MUL AB ;(21 X INDEXI)
;ADD A,INDEXJ ;ADD IN OFFSET WITHIN ROW
;
;ALLOW FOR INSTRUCTION BYTE BETWEEN "MOVC" AND
;ENTRY (0,0).
;
;INC A
;MOVC A,@A + PC
;RET
BASE1: DB 1 ;(entry 0,0)
;DB 2 ;(entry 0,1)
;
;DB 21 ;(entry 0,20)
;DB 22 ;(entry 1,0)
;
;DB 42 ;(entry 1,20)
;
;DB 231 ;(entry 10,20)
MATRIX2: MOV A,INDEXI ;LOAD FIRST COORDINATE
;MOV B,#NDIMEN
;MUL AB ;INDEXI X NDIMEN
;ADD A,#LOW(BASE2) ;ADD IN 16-BIT BASE ADDRESS
;MOV DPL,A
;MOV A,B
;ADDC A,#HIGH(BASE2)
;MOV DPH,A ;DPTR=(BASE ADDR) + (INDEXI + NDIMEN)
;MOV A,INDEXJ
;MOVC A,@A + DPTR ;ADD INDEXJ AND FETCH BYTE
;RET
;
;BASE2 DB 0 ;(entry 0,0)
;DB 0 ;(entry 0,1)
;
;DB 0 ;(entry 0, NDIMEN-1)
;DB 0 ;(entry 1,0)
;
;DB 0 ;(entry 1, NDIMEN-1)
;
;DB 0 ;(entry MDIMEN-1, NDIMEN-1)

```

Figure 5-4. Stack Contents During Interrupt

Saving CPU Status During Interrupts

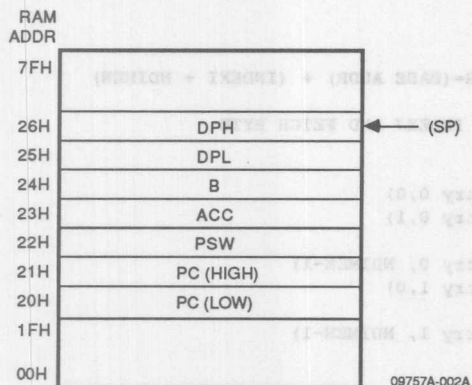
When the 8051 hardware recognizes an interrupt request, program control branches automatically to the corresponding service routine, by forcing the CPU to process a Long CALL (LCALL) instruction to the appropriate address. The return address is stored on the top of the stack. After completing the service routine, an RETI instruction returns the processor to the background program at the point from which it was interrupted.

Interrupt service routines must not change any variable or hardware registers modified by the main program, or else the program may not resume correctly. (Such a change might look like a spontaneous random error. An example of this will be given later in this section, in the second method of I/O port reconfiguration.) Resources used or altered by the service routine (Accumulator, PSW, etc.) must be saved and restored to their previous value before returning from the service routine. PUSH and POP provide an efficient and convenient way to save such registers on the stack.

```

;
; LOC_TMP EQU $ ;REMEMBER LOCATION COUNTER
;
; ORG 0003H ;STARTING ADDRESS FOR INTERRUPT ROUTINE
LJMP SERVER ;JUMP TO ACTUAL SERVICE ROUTINE LOCATE
; ELSEWHERE
;
; ...
; ORG LOC_TMP ;RESTORE LOCATION COUNTER
SERVER: PUSH PSW
      PUSH ACC ;SAVE ACCUMULATOR (NOTE DIRECT ADDRESS
              ;NOTATION)
      PUSH B ;SAVE B REGISTER
      PUSH DPL ;SAVE DATA POINTER
      PUSH DPH ;
      MOV PSW,#00001000B ;SELECT REGISTER BANK 1
;
; ...
;
      POP DPH ;RESTORE REGISTERS IN REVERSE ORDER
      POP DPL
      POP B
      POP ACC
      POP PSW ;RESTORE PSW AND RE-SELECT ORIGINAL
              ;REGISTER BANK
      RETI ;RETURN TO MAIN PROGRAM AND RESTORE
          ;INTERRUPT LOGIC

```



If the SP register held 1FH when the interrupt was detected, then while the service routine was in progress the stack would hold the registers shown in Figure 5-1; SP would contain 26H. This is the most general case; if the service routine doesn't alter the B-register and data pointer, for example, the instruction saving and restoring those registers could be omitted.

Passing Parameters on the Stack

The stack may also pass parameters to and from subroutines. The subroutine can indirectly address the parameters derived from the contents of the stack pointer, or simply pop the stack into registers before processing.

Figure 5-1. Stack Contents During Interrupt

HEXASC:	MOV	R0, SP	;ACCUMULATOR
	DEC	R0	;STACK
	DEC	R0	;READ INPUT PARAMETER AND SAVE
	XCH	A, @R0	;ACCUMULATOR
	ANL	A, #0FH	;MASK ALL BUT LOW-ORDER 4 BITS
	ADD	A, #2	;ALLOW FOR OFFSET FROM MOV C TO TABLE
	MOVC	A, @A + PC	;READ LOOK-UP TABLE ENTRY
	XCH	A, @R0	;PASS BACK TRANSLATED VALUE AND RESTORE
			;ACCUMULATOR
	RET		;RETURN TO BACKGROUND PROGRAM
ASCTBL:	DB	'0'	;ASCII CODE FOR 00H
	DB	'1'	;ASCII CODE FOR 01H
	DB	'2'	;ASCII CODE FOR 02H
	DB	'3'	;ASCII CODE FOR 03H
	DB	'4'	;ASCII CODE FOR 04H
	DB	'5'	;ASCII CODE FOR 05H
	DB	'6'	;ASCII CODE FOR 06H
	DB	'7'	;ASCII CODE FOR 07H
	DB	'8'	;ASCII CODE FOR 08H
	DB	'9'	;ASCII CODE FOR 09H
	DB	'A'	;ASCII CODE FOR 0AH
	DB	'B'	;ASCII CODE FOR 0BH
	DB	'C'	;ASCII CODE FOR 0CH
	DB	'D'	;ASCII CODE FOR 0DH
	DB	'E'	;ASCII CODE FOR 0EH
	DB	'F'	;ASCII CODE FOR 0FH

One advantage here is simplicity. Variables need not be allocated for specific parameters, a potentially large number of parameters may be passed, and different calling programs may use different techniques for determining or handling the variables.

For example, the subroutine HEXASC converts a hexadecimal value to ASCII code for its low-order digit. It first reads a parameter stored on the stack by the calling program, then uses the low-order bits to access a local 16-entry look-up table holding ASCII codes, stores the appropriate code back in the stack and then returns. The accumulator contents are left unchanged.

The background program may reach this subroutine with several different calling sequences, all of which PUSH a value before calling the routine and POP the result to any destination register or port later. There is even the option of leaving a value on the stack if it won't be needed until later. The example below converts the three-digit BCD value computed in the Radix Conversion example above to a three-character string, calling a subroutine SP_OUT to output an 8-bit code in the accumulator.

```

;
...          .....
PUSH        HUND
CALL        HEXASC                ;CONVERT HUNDREDS DIGIT
POP         ACC
CALL        SP_OUT                 ;TRANSMIT HUNDREDS CHARACTER
PUSH        TENONE
CALL        HEXASC                ;CONVERT ONE'S PLACE DIGIT
                                   ;BUT LEAVE ON STACK!
MOV         A,TENONE
SWAP        A                     ;RIGHT-JUSTIFY TEN'S PLACE
PUSH        ACC                   ;CONVERT TEN'S PLACE DIGIT
CALL        HEXASC
POP         ACC
CALL        SP_OUT                 ;TRANSMIT TEN'S PLACE CHARACTER
POP         ACC
CALL        SP_OUT                 ;TRANSMIT ONE'S PLACE CHARACTER
;
...          .....

```

N-Way Branching

There are several different means for branching to sections of code determined or selected at run time. (The single destination addresses incorporated into conditional and unconditional jumps are, of course, fixed at assembly time.) Each has advantages for different applications.

In a typical N-way branch situation, the potential destinations are generally known at assembly time. One of a number of small routines is selected according to the value of an index variable determined while the program is running. The most efficient way to solve this problem is with the MOVC and an indirect jump instruction, using a short table of offset values in ROM to indicate the relative starting addresses of the several routines.

JMP @A + DPTR is an instruction which performs an indirect jump to an address determined during program

execution. The instruction adds the 8-bit unsigned accumulator contents with the contents of the 16-bit data pointer, just like MOV A,@A + DPTR. The resulting sum is loaded into the program counter and is used as the address for subsequent instruction fetches. Again, a 16-bit addition is performed: a carry-out from the low-order eight bits may propagate through the higher-order bits. In this case, neither the accumulator contents nor the data pointer is altered.

The example subroutine below reads a byte of RAM into the accumulator from one of four alternate address spaces, as selected by the contents of the variable MEMSEL. The address of the byte to be read is determined by the contents of R0 (and optionally R1). It might find use in a printing terminal application, where four different model printers all use the same ROM code but use different types (and sizes) of buffer memory for different speeds and options.

;			
;	MEMSEL	EQU	R3
;			
JUMP_4:	MOV	A, MEMSEL	
	MOV	DPTR, #JMPTBL	
	MOVC	A, @A + DPTR	
	JMP	@A + DPTR	
JMPTBL:	DB	MEMSP0-JMPTBL	
	DB	MEMSP1-JMPTBL	
	DB	MEMSP2-JMPTBL	
	DB	MEMSP3-JMPTBL	
MEMSP0:	MOV	A, @R0	; READ FROM INTERNAL RAM
	RET		
MEMSP1:	MOVX	A, @R0	; READ FROM 256 BYTE EXTERNAL RAM
	RET		
MEMSP2:	MOV	DPL, R0	; READ 64K BYTE EXTERNAL RAM
	MOV	DPH, R1	
	MOVX	A, @DPTR	
	RET		
MEMSP3:	MOV	A, R1	; READ 4K BYTE EXTERNAL RAM
	ANL	A, #07H	
	ANL	P1, #11111000B	
	ORL	P1, A	
	MOVX	A, @R0	
	RET		

To use this approach, the size of the jump table plus the length of the alternate routines must be less than 256 bytes. The jump table and routines may be located anywhere in program memory and are independent of 256-byte program memory pages.

For applications where up to 128 destinations must be selected, all residing in the same 2K page of program memory, the following technique may be used. In the

printing terminal example, this sequence could process 128 different codes for ASCII characters arriving via the 8051 serial port.

The destinations in the jump table (PROC00-PROC7F) are not all necessarily unique routines. A large number of special control codes could each be processed with their own unique routine, with the remaining printing characters all causing a branch to a common routine for entering the character into the output queue.

```

;
; OPTION EQU R3
;
; .....
;
; JMP128: MOV A,OPTION
;          RL A
;          MOV DPTR,#INSTBL
;          JMP @A + DPTR
;
; .....
INSTBL:   AJP  PROC00
;          AJP  PROC01
;          AJP  PROC02
;
; .....
;          AJP  PROC7E
;          AJP  PROC7F

```

Computing Branch Destinations at Run Time

In some rare situations, 128 options are insufficient, the destination routines may cross a 2K page boundary, or a branch destination is not known at assembly time (for whatever reason), and therefore cannot be easily included in the assembled code. These situations can all be handled by computing the destination address at run-time with standard arithmetic or table look-up instructions, then performing an indirect branch to that address.

There are two simple ways to execute this last step, assuming the 16-bit destination address has already been computed. The first is to load the address into the DPH and DPL registers, clear the accumulator and branch using the `JMP @A + DPTR` instruction; the second is to push the destination address onto the stack, low-order byte first (so as to mimic a call instruction) then pop that address into the PC by performing a return instruction. This also adjusts the stack pointer to its previous value. The code segment below illustrates the latter possibility.

```
RTEMP      EQU      R7
;
JMP256:    MOV      DPTR,#ADRTBL      ;FIRST ADDRESS TABLE ENTRY
            MOV      A,OPTION          ;LOAD INDEX INTO TABLE
            CLR      C
            RLC                       ;MULTIPLY BY 2 FOR 2-BYTE JUMP TABLE
            JNC      LOW128
LOW128:     INC      DPH                ;FIX BASE IF INDEX >127.
            MOV      RTEMP,A           ;SAVE ADJUSTED ACC FOR SECOND READ
            INC      A                 ;READ LOW-ORDER BYTE FIRST
            MOVC     A,@A + DPTR       ;GET LOW-ORDER BYTE FROM TABLE
            PUSH     ACC
            MOV      A,RTEMP          ;RELOAD ADJUSTED ACC
            MOVC     A,@A + DPTR       ;GET HIGH-ORDERED BYTE FROM TABLE
            PUSH     ACC

;
; THE TWO ACC PUSHES HAVE PRODUCED
; A "RETURN ADDRESS" ON THE STACK WHICH CORRESPONDS
; TO THE DESIRED STARTING ADDRESS.
; IT MAY BE REACHED BY POPPING THE STACK
; INTO THE PC.
RET

;
; .....
; .....
; .....
; .....
ADRTBL:    DW        PROC00             ;UP TO 256 CONSECUTIVE DATA
            DW        PROC01             ;WORDS INDICATING STARTING ADDRESSES
;
; .....
; .....
DW         PROCCF
```

In-Line-Code Parameter-Passing

Parameters can be passed by loading appropriate registers with values before calling the subroutine. This technique is inefficient if a lot of the parameters are constants, since each would require a separate register to carry it, and a separate instruction to load the register each time the routine is called.

If the routine is called frequently, a more code-efficient way to transfer constants is "in-line-code" parameter-passing. The constants are actually part of the program code, immediately following the call instruction. The subroutine determines where to find them from the return address on the stack, and then reads the parameters it needs from program memory.

For example, assume a utility named ADD-BCD adds a 16-bit packed-BCD constant with a 2-byte BCD variable

in internal RAM and stores the sum in a different 2-byte buffer. The utility must be given the constant and both buffer addresses. Rather than using four working registers to carry this information, all 4 bytes could be inserted into program memory each time the utility is called. Specifically, the calling sequence below invokes the utility to add 1234 (decimal) with the string at internal RAM address 56H, and store the sum in a buffer at location 78H.

The ADDBCD subroutine determines at what point the call was made by popping the return address from the stack into the data pointer high- and low-order bytes. A MOV instruction then reads the parameters from program memory as they are needed. When done, ADDBCD resumes execution by jumping to the instruction following the last parameter.

Address	Instruction	Comment
0000	CALL	ADDBCD
0001	DW	1234H
0002	DB	56H
0003	DB	78H
0004
0005	;	BCD CONSTANT
0006	;	SOURCE STRING ADDRESS
0007	;	DESTINATION STRING ADDRESS
0008	;	CONTINUATION OF PROGRAM
0009	;	
0010	;	
0011	ADDBCD:	POP DPH ;POP RETURN ADDRESS INTO DPTR
0012	POP	DPL
0013	MOV	A,#2 ;INDEX FOR SOURCE STRING PARAMETER
0014	MOVC	A,@A + DPTR ;GET SOURCE STRING LOCATION
0015	MOV	R0,A
0016	MOV	A,#3 ;INDEX FOR DESTINATION STRING PARAMETER
0017	MOVC	A,@A + DPTR ;GET DESTINATION ADDRESS
0018	MOV	R1,A
0019	MOV	A,#1 ;INDEX FOR 16-BIT CONSTANT LOW BYTE
0020	MOVC	A,@A + DPTR ;GET LOW-ORDER VALUE
0021	ADD	A,@R0 ;COMPUTE LOW-ORDER BYTE OF SUM
0022	DA	A ;DECIMAL ADJUST FOR ADDITION
0023	MOV	@R1,A ;SAVE IN BUFFER
0024	INC	R0
0025	INC	R1
0026	CLR	A ;INDEX FOR HIGH-BYTE = 0
0027	MOVC	A,@A + DPTR ;GET HIGH-ORDER CONSTANT
0028	ADDC	A,@R0
0029	DA	A ;DECIMAL ADJUST FOR ADDITION
0030	MOV	@R1,A ;SAVE IN BUFFER
0031	MOV	A,#4 ;INDEX FOR CONTINUATION OF PROGRAM
0032	JMP	@A + DPTR ;JUMP BACK INTO MAIN PROGRAM

This example illustrates several points:

1. The "subroutine" does not end with a normal return statement; instead, an indirect jump relative to the data pointer returns execution to the first instruction following the parameter list. The two initial POP instructions correct the stack-pointer contents.
2. Either an ACALL or LCALL works with the subroutine, since each pushes the address of the *next* instruction or data byte onto the stack. The call may be made from anywhere in the full 8051 address space, since the MOVC instruction accesses all 64K bytes.
3. The parameters passed to the utility can be listed in whatever order is most convenient, which may not be that in which they're used. The utility has essentially "random access" to the parameter list, by loading the appropriate constant into the accumulator before each MOVC instruction.
4. Other than the data pointer, the whole calling and processing sequence only affects the accumulator, PSW and pointer registers. The utility could have pushed these registers onto the stack (after popping the parameter list starting address), and popped before returning.

Passing parameters through in-line-code can be used in conjunction with other variable passing techniques.

The utility can also get input variables from working registers or from the stack, and return output variables to registers or to the stack.

PERIPHERAL INTERFACING TECHNIQUES

I/O Port Reconfiguration (First Approach)

I/O ports must often transmit or receive parallel data in formats other than as 8-bit bytes. For example, if an application requires three 5-bit latched output ports (called X, Y, and Z), these "virtual" ports could be mapped onto the pins of "physical" ports 1 and 2 (see example at bottom of page).

This pin assignment leaves P2.7 free for use as a test pin, input data pin, or control output through software.

Notice that the bits of port Z are reversed. The highest-order port Z pin corresponds to pin P2.2, and the lowest-order pin of port Z is P2.6, due to PC board layout considerations. When connecting an 8051 to an immediately adjacent keyboard column decoder or another device with weighted inputs, the corresponding pins may not be aligned. The interconnections must be "scrambled" to compensate either with interwoven circuit board traces or through software (as shown below and on the following page).

	PORT "Z"					PORT "Y"					PORT "X"				
	PZ0	PZ1	PZ2	PZ3	PZ4	PY4	PY3	PY2	PY1	PY0	PX4	PX3	PX2	PX1	PX0
P2.7	P2.6	P2.5	P2.4	P2.3	P2.2	P2.1	P2.0	P1.7	P1.6	P1.5	P1.4	P1.3	P1.2	P1.1	P1.0

```

PX_MAP      DATA      20H
PY_MAP      DATA      21H
PZ_MAP      DATA      22H
;
OUT_PX:     ANL        A,#00011111B      ;CLEAR BITS ACC.7 - ACC.5
            MOV        PX_MAP,A          ;SAVE DATA IN MAP BYTE
            ACALL      OUT_P1            ;UPDATE PORT 1 OUTPUT LATCH
            RET
;
OUT_PY:     MOV        PY_MAP,A          ;SAVE IN MAP BYTE
            ACALL      OUT_P1            ;UPDATE PORT 1
            ACALL      OUT_P2            ;AND PORT 2 OUTPUT LATCHES
            RET
;
OUT_PZ:     MOV        PZ_MAP,A          ;SAVE DATA IN MAP BYTE
            ACALL      OUT_P2            ;UPDATE PORT 2.
            RET
;
;
;

```

```

RL      A
ANL     A,#11100000B      ;SHIFT PY_MAP LEFT 5 BITS
ORL     A,PX_MAP          ;MASK OUT GARBAGE
MOV     P1,A              ;INCLUDE PX_MAP BITS
RET

;
OUT_P2: MOV     C,PZ_MAP.0  ;LOAD CY WITH P2.6 BIT
RLC     A                 ;AND SHIFT INTO ACC.
MOV     C,PZ_MAP.1        ;LOAD CY WITH P2.5 BIT
RLC     A                 ;AND SHIFT INTO ACC.
MOV     C,PZ_MAP.2        ;LOAD CY WITH P2.4 BIT
RLC     A                 ;AND SHIFT INTO ACC.
MOV     C,PZ_MAP.3        ;LOAD CY WITH P2.3 BIT
RLC     A                 ;AND SHIFT INTO ACC.
MOV     C,PZ_MAP.4        ;LOAD CY WITH P2.2 BIT
RLC     A                 ;AND SHIFT INTO ACC.
MOV     C,PZ_MAP.4        ;LOAD CY WITH P2.1 BIT
RLC     A                 ;AND SHIFT INTO ACC.
MOV     C,PZ_MAP.3        ;LOAD CY WITH P2.0 BIT
RLC     A                 ;AND SHIFT INTO ACC.
SETB    ACC.7              ;(ASSUMING INPUT ON P2.7)
MOV     P2,A
RET

```

Writing to the virtual ports must not affect any other pins. Since the virtual output algorithms are non-trivial, a subroutine is needed for each port: OUT_PX, OUT_PY and OUT_PZ. Each is called with data to output right-justified in the accumulator, and any data in bits ACC.7-ACC.5 is insignificant. Each subroutine saves the data in a "map" variable for the virtual port, then calls other subroutines which use the data in the various map bytes to compute and output the 8-bit pattern needed for each physical port affected. The two level structure of the above subroutines can be modified somewhat if code efficiency and execution speed are critical: incorporate the code shown as subroutines OUT_P1 and OUT_P2 directly into the code for OUT_PX and OUT_PZ, in place of the corresponding CALL instructions. OUT_PY would not be changed, but now the destinations for its ACALL instructions would be alternate entry points in OUT_PX and OUT_PZ, instead of isolated subroutines.

I/O Port Reconfiguration (Second Approach)

A trickier situation arises if two sections of code which write to the same port or register, or call virtual output routines like those above, need to be executed at different interrupt levels. For example, suppose the background program wants to rewrite Port X (using the port associations in the previous example), and has computed the bit pattern needed for P1. An interrupt is

detected just before the MOV P1,A instruction, and the service routine tries to write Port Y. The service routine would correctly update P1 and P2, but upon returning to the background program P1 is immediately *re-written* with the data computed *before* the interrupt! Now pins P2.1 and P2.0 indicate (correctly) data written to port Y in the interrupt routine, but the earlier data written to P.7-P1.5 is no longer valid. The same sort of confusion could arise if a high-level interrupt disrupted such an output sequence.

One solution is to disable interrupts around any section of code which must not be interrupted (called a "critical section"), but this would adversely affect interrupt latency. Another is to have interrupt routines set or clear a flag ("semaphore") when a common resource is altered — a rather complex and elaborate system.

An easier way to ensure that any instruction which writes the port X field of P1 does not change the port Y field pins from their state *at the beginning of that instruction*, is shown next. A number of 8051 operations read, modify, and write the output port latches all in one instruction. These are the arithmetic and logical instructions (INC, DEC, ANL, ORL, etc.), where an addressed byte is both the destination variable and one of the source operands. Using these instructions, instead of data moves, eliminates the critical section problem entirely.

```

OUT_PX:  ANL    P1,#11100000B    ;CLEAR BITS P1.4-P1.0
        ORL    P1,A              ;SET P1 PIN FOR EACH ACC BIT SET
        RET
;
;
OUT_PY:  MOV    B,#20H
        MUL    AB                ;SHIFT B A LEFT 5 BITS
        ANL    P1,#00011111B    ;CLEAR PY FIELD OF PORT 1
        ORL    P1,A              ;SET PY BITS ON PORT 1
        MOV    A,B              ;'LOAD 2 BITS SHIFTED INTO B
        ANL    P2,#1111100B    ;AND UPDATE P2
        ORL    P2,A
        RET
;
;
OUT_PZ:  RRC    A                ;MOVE ORIGINAL ACC.0 INTO CY
        MOV    P2.6,C           ;AND STORE TO PIN P2.6.
        RRC    A                ;MOVE ORIGINAL ACC.1 INTO CY
        MOV    P2.5,C           ;AND STORE TO PIN P2.5.
        RRC    A                ;MOVE ORIGINAL ACC.2 INTO CY
        MOV    P2.4,C           ;AND STORE TO PIN P2.4.
        RRC    A                ;MOVE ORIGINAL ACC.3 INTO CY
        MOV    P2.3,C           ;AND STORE TO PIN P2.3.
        RRC    A                ;MOVE ORIGINAL ACC.4 INTO CY
        MOV    P2.2,C           ;AND STORE TO PIN P2.2.
        RET

```

Simulating a Third Priority Level in Software

Some applications require more than the two priority levels that are provided by on-chip hardware in 8051 devices. In these cases, relatively simple software can be written to produce the same effect as a third priority level.

First, interrupts that are to have higher priority than 1 are assigned to priority 1 in the IP (Interrupt Priority) register. The service routines for priority 1 interrupts that are supposed to be interruptible by "priority 2" interrupts are written to include the following code:

```

        PUSH    IE
        MOV     IE,#MASK
        CALL    LABEL
;
;      (execute service routine)
;
        POP     IE
        RET
LABEL:  RETI

```

As soon as any priority 1 interrupt is acknowledged, the IE (Interrupt Enable) register is re-defined as to disable all but "priority 2" interrupts. Then, a CALL to LABEL executes the RETI instruction, which clears the priority 1

interrupt-in-progress flip-flop. At this point any priority 1 interrupt that is enabled can be serviced, but only "priority 2" interrupts are enabled.

POPPing IE restores the original enable byte. Then a normal RET (rather than another RETI) is used to terminate the service routine. The additional software adds 10 μ s (at 12 MHz) to priority 1 interrupts.

Software Delay Timing

Many 8051 applications invoke exact control over output timing. A software-generated output strobe, for instance, might have to be *exactly* 50 μ s wide. The DJNZ operation can insert a one instruction software delay into a piece of code, adding a moderate time delay of two instruction cycles per iteration. For example, two instructions can add a 49- μ sec. software delay loop to code to generate a pulse on the WR pin.

```

CLR     WR
MOV     R2,#24
DJNZ    R2,$
SETB    WR

```

The dollar sign in this example is a special character meaning "the address of this instruction". It can be used to eliminate instruction labels on nearby source lines.

Serial Port and Timer Mode Configuration

Configuring the 8051's Serial Port for a given data rate and protocol requires essentially three short sections of software. On power-up or hardware reset the serial port and timer control words must be initialized to the appropriate values. Additional software is also needed in the transmit routine to load the serial port data register and in the receive routine to unload the data as it arrives.

To choose one arbitrary example, assume the 8051 should communicate with a standard CRT operating at 2400 baud (bits per second). Each character is transmitted as seven data bits, odd parity, and one stop bit. The resulting character rate is 2400 baud/9 bits, approximately 265 characters per second.

For the sake of clarity, the transmit and receive subroutines here are driven by simple-minded software status

polling code rather than interrupts. The serial port must be initialized to 8-bit UART mode (SM0, SM1 = 01), enabled to receive all messages (SM2=0, REN=1). The flag indicating that the transmit register is free for more data will be artificially set in order to let the output software know the output register is available. All this can be set up with the instruction at label SPINIT.

Timer 1 will be used in auto-reload mode as a baud rate generator. To achieve a data rate of 2400 baud, the timer must divide the 1 MHz internal clock by

$$\frac{1 \times 10^6}{(32) (2400)}$$

which equals 13 (actually, 13.02) instruction cycles. The timer must reload the value 13, or 0F3H, as shown by the code at label TIINIT. (ASM51 will accept both the signed decimal or hexadecimal representations.)

```
;      INITIALIZE SERIAL PORT
;      FOR 8-BIT UART MODE
;      & SET TRANSMIT READY FLAG.
SPINIT:  MOV     SCON,#01010010B
;
;      INITIALIZE TIMER 1 FOR
;      AUTO-RELOAD AT 32 X 2400 HZ
;      (TO USED AS GATED 16-BIT COUNTER.)
;
TIINIT:  MOV     TCON,#11010010B
;      MOV     TH1,#13
;      SETB    TR1
;      ...
;      .....
```

Simple Serial I/O Drivers

SP_OUT is a simple subroutine to transmit the character passed to it in the accumulator. First it must compute the parity bit, insert it into the data byte, wait until the transmitter is available, output the character, and then return.

SP_IN is an equally simple routine which waits until a character is received, sets the carry flag if there is an odd-parity error, and returns the masked seven-bit code in the accumulator.

```
;
; SP_OUT      ADD ODD PARITY TO ACC AND
;             TRANSMIT WHEN SERIAL PORT READY
;
;
SP_OUT:  MOV     C,P           ;MOVE PARITY BIT TO CARRY BIT
;      CPL     C
;      MOV     ACC.7,C        ;INSERT INTO DATA BYTE
;      JNB     TI,$           ;WAIT FOR TRANSMITTER AVAILABLE
;      CLR     TI
;      MOV     SBUF,A         ;OUTPUT THE CHARACTER
;      RET
;
;
;
```

```

SP_IN:  JNB    RI,$      ;WAIT FOR A CHARACTER TO BE RECEIVED
        CLR    RI
        MOV    A,SBUF    ;MOVE CHARACTER TO THE ACCUMULATOR
        MOV    C,P
        CPL    C
        ANL    A,#7FH    ;SET CARRY BIT TO ONE IF ODD-PARITY ERROR
        RET              ;MASK OUT PARITY BIT FROM CHARACTER

```

Transmitting Serial Port Character Strings

Any application which transmits characters through a serial port to an ASCII output device will on occasion need to output "canned" messages, including error

messages, diagnostics, or operator instructions. These character strings are most easily defined with in-line data bytes defined with the DB directive.

```

CR      EQU    0DH      ;ASCII CARRIAGE RET
LF      EQU    0AH      ;ASCII LINE-FEED
ESC     EQU    1BH      ;ASCII ESCAPE CODE
;
;      ...
CALL    XSTRING
DB      CR,LF          ;NEW LINES
DB      'AMD QUALITY'  ;MESSAGE
DB      ESC            ;ESCAPE CHARACTER
;
;      (CONTINUATION OF PROGRAM)
;
;      ...
XSTRING: POP    DPH      ;LOAD DPTR WITH FIRST CHARACTER
        POP    DPL
XSTR_1:  CLR    A        ;(ZERO OFFSET)
        MOVC   A,@A + DPTR ;FETCH FIRST CHARACTER OF STRING
XSTR_2:  JNB    TI,$      ;WAIT UNTIL TRANSMITTER READY
        CLR    TI        ;MARK AS NOT READY
        MOV    SBUF,A     ;OUTPUT NEXT CHARACTER
        INC    DPTR      ;BUMP POINTER
        CLR    A
        MOVC   A,@A + DPTR ;GET NEXT OUTPUT CHARACTER
        CJNE   A,#ESC,XSTR_2 ;LOOP UNTIL ESCAPE READ
        MOV    A,#1
        JMP    @A + DPTR ;RETURN TO CODE AFTER ESCAPE

```

Recognizing and Processing Special Cases

Before operating on the data it receives, a subroutine might give "special handling" to certain input values. Consider a word processing device which receives ASCII characters through the 8051 serial port and drives a thermal hard-copy printer. A standard routine translates most printing characters to bit patterns, but certain

control characters (, <CR>, <LF>, <BEL>, <ESC>, or <SP>) must invoke corresponding special routines. Any other character with an ASCII code less than 20H should be translated into the <NUL> value, 00H, and processed with the printing characters. The CJNE operation provides essentially a one-instruction CASE statement.

```

;
CHAR    EQU    R7      ;CHARACTER CODE VARIABLE
;
INTERP: CJNE   CHAR,#7FH,INTP_1 ;SKIP UNLESS RUBOUT
;      ...
;      RET              (SPECIAL ROUTINE FOR RUBOUT CODE)
INTP_1: CJNE   CHAR,#0H,INTP_2 ;SKIP UNLESS BELL
;      ...
;      RET              (SPECIAL ROUTINE FOR BELL CODE)

```

```

;----- (SPECIAL ROUTINE FOR FEED CODE)
RET
INTP_3: CJNE CHAR,#0DH,INTP_4 ;SKIP UNLESS RETURN
; ... (SPECIAL ROUTINE FOR RETURN CODE)
RET
INTP_4: CJNE CHAR,#1BH,INTP_5 ;SKIP UNLESS ESCAPE
; ... (SPECIAL ROUTINE FOR ESCAPE CODE)
RET
INTP_5: CJNE CHAR,#20H,INTP_6 ;SKIP UNLESS SPACE
; ... (SPECIAL ROUTINE FOR SPACE CODE)
RET
INTP_6: JC PRINTC ;JUMP IF CODE 20H
MOV CHAR,#0 ;REPLACE CONTROL CHARACTER WITH
;NULL CODE
PRINTC: ;PROCESS STANDARD PRINTING
; ... CHARACTER
RET
;

```

Buffering Serial Port Output Characters

It is not always efficient to transmit characters through the serial port one-at-a-time. Most applications generate a short burst of characters all at once (English words or multi-digit numbers, for instance), with the bursts themselves occurring at longer intervals. Instead of waiting while the UART outputs each character, it would be more efficient if the background program could enter all the characters into a first-in first-out (FIFO) data structure,

and continue about its business, letting an interrupt routine transmit each character as the serial port becomes available.

Assume there is a 16-byte output data buffer starting at 70H. QHEAD and QTAIL keep track of the head and tail portion of the buffer being used. The subroutine ENTERQ waits until there is space in the queue, then copies a character code from the accumulator to the queue.

```

QHEAD DATA 6EH ;LAST BYTE ENTERED INTO QUEUE
QTAIL DATA 6FH ;LAST BYTE READ FROM QUEUE
BOTLIM EQU 70H
TOPLIM EQU 7FH
;
; QUEUE IS EMPTY WHEN QHEAD = QTAIL AND
; FULL WHEN Q HEAD + 1 (WITHIN RANGE) = QTAIL.
MOV QHEAD,#TOPLIM
MOV QTAIL,#TOPLIM
;
;
ENTERQ: MOV R0,A ;SAVE ACC DATA
MOV A,QHEAD ;LOAD HEAD POINTER
INC A ;PRE-INCREMENT POINTER
CJNE A,#TOPLIM+1,ENTQ_1
MOV A,#BOTLIM ;RELOAD ON OVERFLOW
ENTQ_1: CJNE A,QTAIL,ENTQ_2 ;TEST IF QUEUE FULL
SJMP ENTQ_1 ;LOOP UNTIL SPACE AVAILABLE
ENTQ_2: XCH A,R0 ;STORE POINTER AND RELOAD ACC
MOV @R0,A ;ENTER INTO QUEUE
MOV QHEAD,R0 ;UPDATE HEAD POINTER
SETB ES ;ENABLE SERIAL PORT INTERRUPTS
RET

```

The interrupt routine DQUEUE is invoked when the transmitter is ready for another character. First it determines if any characters are available for transmission, indicated by QHEAD and QTAIL being not equal. If more data is available, it is written to the transmit buffer (SBUF)

and the pointers are updated. If not, DQUEUE disables serial port interrupts and returns to the background program. ENTERQ will re-enable such interrupts as more data is available. (This example does not consider interrupt-driven serial input.)

```

ORG      0023H
PUSH     ACC      ;SAVE CPU STATUS
PUSH     PSW
MOV      PSW,#300 ;SELECT BANK 3
DQUEUE:  MOV      A,QTAIL
          CJNE     A,QHEAD,DQ_1
          CLR      ES
          SJMP     TI_RET
          ;TEST IF QUEUE EMPTY
          ;IF SO, CLEAR ENABLE BIT AND RETURN

DQ_1:    CLR      TI      ;ELSE ACKNOWLEDGE REQUEST
          INC      A      ;COMPUTE NEXT BYTE'S ADDRESS
          CJNE     A,#TOPLIM+1,DQ_2
          MOV      A,#BOTLIM
          ;REVISE ACC IF POINTER OVERFLOWED
DQ_2:    MOV      R0,A
          ;LOAD INDEX REGISTER
          MOV      SBUF,@R0
          ;RELOAD TRANSMITTER
          MOV      QTAIL,A
          ;SAVE LAST POINTER USED.
          POP      PSW
          ;RESTORE STATUS AND RETURN
          POP      ACC
          RETI

```

Synchronizing Timer Overflows

8051 timer overflows automatically generate an internal interrupt request, which will vector program execution to the appropriate interrupt service routine if interrupts are enabled and no other service routines are in progress at the time. However, it is not predictable *exactly* how long it will take to reach the service routine. The service routine call takes two instruction cycles, but 1, 2, or 4 additional cycles may be needed to complete the instruction in progress. If the background program ever disables interrupts, the response latency could further increase by a few instruction cycles. (Critical sections generally involve simple instruction sequences — rarely multiplies or divides.) Interrupt response delay is generally negligible, but certain time-critical applications must take the exact delay into account. For example, generating interrupts with timer 1 every millisecond (1000 in-

struction cycles) or so would normally call for reloading it with the value, -1000 (0FC18H). But if the interrupt interval (average over time) must be accurate to 1 instruction cycle, the 16-bit value reload into the timer must be computed, taking into account when the timer actually overflowed.

This simply requires reading the appropriate timer, which has been incremented each cycle since the overflow occurred. A sequence like the one below can stop the timer, compute how much time should elapse before the next interrupt, and reload and restart the timer. The double-precision calculation shown here compensates for any amount of timer overrun within the maximum interval. Note that it also takes into account that the timer is stopped for seven instruction cycles in the process. All interrupts are disabled, so a higher priority request will not be able to disrupt the time-critical code section.

```

;      ...      .....
          CLR      EA      ;DISABLE ALL INTERRUPTS
          CLR      TR1      ;STOP TIMER 1
          MOV      A,#LOW(-1000+7)
          ;LOAD LOW-ORDER DESIRED COUNT
          ADD      A,TL1
          ;CORRECT FOR TIMER OVERRUN
          MOV      TL1,A
          ;RELOAD LOW-ORDER BYTE
          MOV      A,#HIGH(-1000+7)
          ;REPEAT FOR HIGH-ORDER BYTE
          ADDC     A,TH1
          MOV      TH1,A
          SETB     TH1
          ;RESTART TIMER
;      ...      .....

```


CHAPTER 6

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8051 Family Boolean Processing Capabilities

The 8051 incorporates a number of special features that support the direct manipulation and testing of individual bits and allow the use of single-bit variables in performing logical operations. Taken together, these features are referred to as the 8051 Family *Boolean Processor*. While the bit-processing capabilities alone would be adequate to solve many control applications, their true power comes when they are used in conjunction with the microcomputer's byte-processing and numerical capabilities. The purpose of this discussion is to explain these concepts and show how they are used.

BOOLEAN PROCESSOR OPERATION

The Boolean Processing capabilities of the 8051 are based on concepts that have been around for sometime. Digital computer systems of widely varying designs all have four functional elements in common (Figure 6-1):

- a central processor (CPU) with the control, timing, and logic circuits needed to execute stored instructions,
- a memory to store the sequence of instructions making up a program or algorithm,
- data memory to store variables used by the program, and
- some means of communicating with the outside world.

The CPU usually includes one or more accumulators or special registers for computing or storing values during program execution. The instruction set of such a processor generally includes, at the minimum, operation classes to perform arithmetic or logical functions on program variables, to move variables from one place to another, to cause program execution to jump or conditionally branch based on register or variable states, and to call and return from subroutines. The program and data memory functions sometimes share a single memory space, but this is not always the case. When the address spaces are separated, program and data memory need not even have the same basic word width.

A digital computer's flexibility comes in part from its ability to combine simple, fast operations to produce more complex (albeit slower) ones, which in turn link together to eventually solve the problem at hand. A 4-bit CPU executing multiple precision subroutines can, for example, perform 64-bit addition and subtraction. The subroutines could in turn be building blocks for floating-point multiplication and division routines. Eventually, the 4-bit CPU can simulate a far more complex "virtual" machine.

In fact, any digital computer with the above four functional elements can (given time) complete *any* algorithm (though the proverbial room full of chimpanzees at word

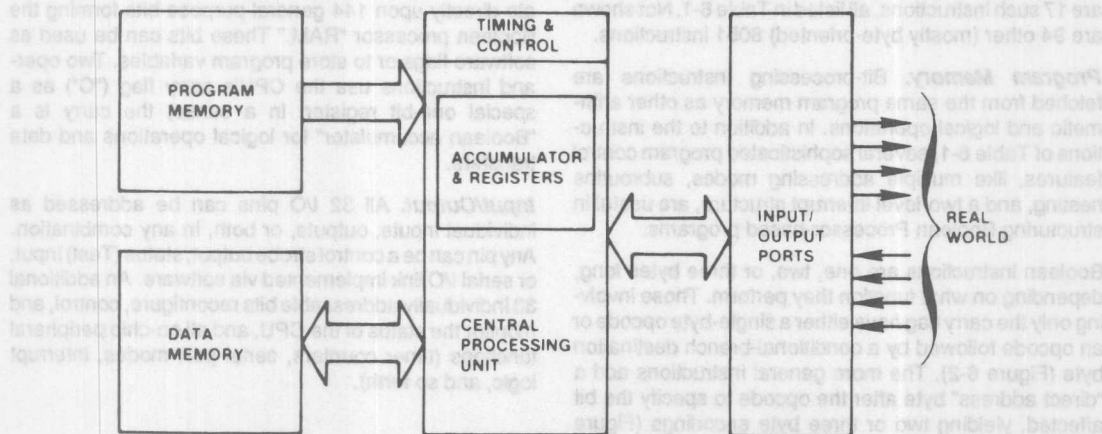


Figure 6-1. Block Diagram for Abstract Digital Computer

processors might first re-create Shakespeare's classics and this chapter)! This fact offers little consolation to product designers who want programs to run as quickly as possible. By definition, a real-time control algorithm *must* proceed quickly enough to meet the preordained speed constraints of other equipment.

One of the factors determining how long it will take a microcomputer to complete a given task is the number of instructions it must execute. What makes a given computer architecture particularly well- or poorly-suited for a class of problems is how well its instruction set matches the tasks to be performed. The better the "primitive" operations correspond to the steps taken by the control algorithm, the lower the number of instructions needed, and the quicker the program will run. All else being equal, a CPU supporting 64-bit arithmetic directly could clearly perform floating-point math faster than a machine bogged down by multiple-precision subroutines. In the same way, direct support for bit manipulation naturally leads to more efficient programs handling the binary input and output conditions inherent in digital-control problems.

Processing Elements

The following shows how the four basic elements of a digital computer — a CPU with associated registers, program memory, addressable data RAM, and I/O capabilities — relate to Boolean variables.

CPU. The 8051 CPU incorporates special logic devoted to executing several bit-wide operations. All told, there are 17 such instructions, all listed in Table 6-1. Not shown are 94 other (mostly byte-oriented) 8051 instructions.

Program Memory. Bit-processing instructions are fetched from the same program memory as other arithmetic and logical operations. In addition to the instructions of Table 6-1, several sophisticated program control features, like multiple addressing modes, subroutine nesting, and a two-level interrupt structure, are useful in structuring Boolean Processor-based programs.

Boolean instructions are one, two, or three bytes long, depending on what function they perform. Those involving only the carry flag have either a single-byte opcode or an opcode followed by a conditional-branch destination byte (Figure 6-2). The more general instructions add a "direct address" byte after the opcode to specify the bit affected, yielding two or three byte encodings (Figure 6-2). Though this format allows potentially 256 directly addressable bit locations, not all of them are implemented in the 8051 Family.

Table 6-1. 8051 Family Boolean Processing Instruction Subset

Mnemonic		Description	Byte	Cyc
SETB	C	Set Carry flag	1	1
SETB	bit	Set direct bit	2	1
CLR	C	Clear Carry flag	1	1
CLR	bit	Clear direct bit	2	1
CPL	C	Complement Carry flag	1	1
CPL	bit	Complement direct bit	2	1
MOV	C,bit	Move direct bit to Carry flag	2	1
MOV	bit,C	Move Carry flag to direct bit	2	2
ANL	C,bit	AND direct bit to Carry flag	2	2
ANL	C,bit	AND complement of direct bit to Carry flag	2	2
ORL	C,bit	OR direct bit to Carry flag	2	2
ORL	C,bit	OR complement of direct bit to Carry flag	2	2
JC	rel	Jump if Carry flag is set	2	2
JNC	rel	Jump if No Carry flag	2	2
JB	bit,rel	Jump if direct bit set	3	2
JNB	bit,rel	Jump if direct bit not set	3	2
JBC	bit,rel	Jump if direct bit is set & Clear bit	3	2

Address mode abbreviations

- C — Carry flag.
- bit — 128 software flags, any I/O pin, control or status bit.
- rel — All conditional jumps include an 8-bit offset byte. Range is +127 -128 bytes relative to first byte of the following instruction.

Data Memory. The instructions in Figure 6-2 can operate directly upon 144 general-purpose bits forming the Boolean processor "RAM." These bits can be used as software flags or to store program variables. Two operations and instructions use the CPU's carry flag ("C") as a special one-bit register; in a sense, the carry is a "Boolean accumulator" for logical operations and data transfers.

Input/Output. All 32 I/O pins can be addressed as individual inputs, outputs, or both, in any combination. Any pin can be a control strobe output, status (Test) input, or serial I/O link implemented via software. An additional 33 individually addressable bits reconfigure, control, and monitor the status of the CPU, and all on-chip peripheral functions (timer counters, serial port modes, interrupt logic, and so forth).

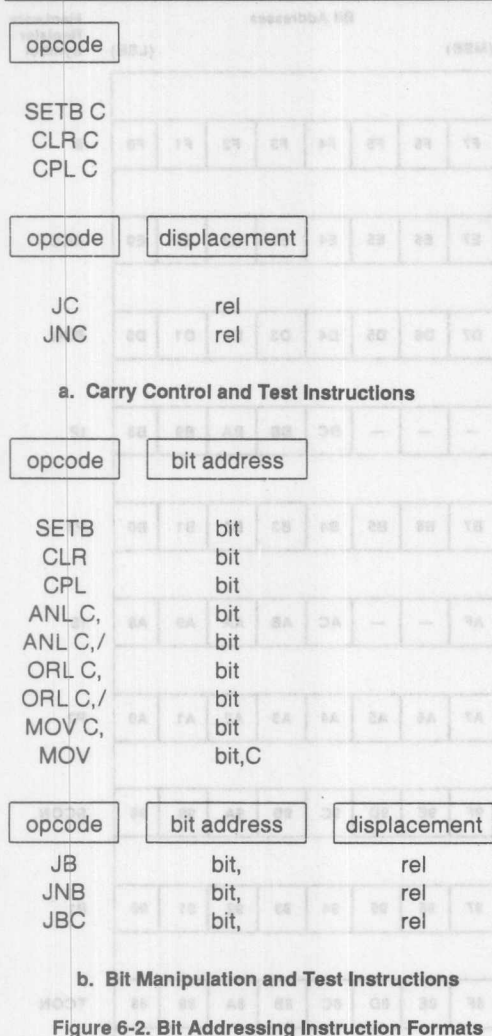


Figure 6-2. Bit Addressing Instruction Formats

Direct Bit Addressing

The most significant bit of the direct-address byte selects one of two groups of bits. Values between 0 and 127 (00H and 7FH) define bits in a block of 16 bytes of on-chip RAM, between RAM addresses 20H and 2FH (Figure 6-3a). They are numbered consecutively from the lowest-order byte's lowest-order bit through the highest-order byte's highest-order bit.

Bit addresses between 128 and 255 (80H and 0FFH) correspond to bits in a number of special registers, mostly used for I/O or peripheral control. These positions are numbered with a different scheme than RAM; the five high-order address bits match those of the register's own

address, while the three low-order bits identify the bit position within that register (Figure 6-3b).

Notice the column labeled "Symbol" in Figure 6-4. Bits with special meanings in the PSW and other registers have corresponding symbolic names. General-purpose (as opposed to carry-specific) instructions may access the carry like any other bit by using the mnemonic CY in place of C. P0, P1, P2, and P3 are the 8051's four I/O ports; secondary functions assigned to each of the eight pins of P3 are shown in Figure 6-5.

Figure 6-6 shows the last four bit-addressable registers. TCON (Timer Control) and SCON (Serial-Port Control) control and monitor the corresponding peripherals, while IE (Interrupt Enable) and IP (Interrupt Priority) enable and prioritize the five hardware interrupt sources. Like the reserved hardware register addresses, the five bits not implemented in IE and IP should not be accessed; they *cannot* be used as software flags.

Addressable Register Set. There are 20 special-function registers in the 8051, but the advantages of bit addressing only relate to the 11 described below. Five potentially bit-addressable register addresses (0C0H, 0C8H, 0D8H, 0E8H, & 0F8H) are reserved for expansion in microcomputers based on the 8051 Family architecture. Reading or writing non-existent registers in the 8051 series is pointless, and may cause unpredictable results. Byte-wide logic operations can be used to manipulate bits in all *non*-bit-addressable registers and RAM.

The accumulator and B registers (A and B) are normally involved in byte-wide arithmetic, but their individual bits can also be used as 16 general software flags. Added with the 128 flags in RAM, this gives 144 general purpose variables for bit-intensive programs. The program status word (PSW) in Figure 6-4 is a collection of flags and machine status bits including the carry flag itself. Byte operations acting on the PSW can, therefore, affect the carry.

Instruction Set

Having looked at the bit variables available to the Boolean Processor, we will now look at the four classes of instructions that manipulate these bits. It may be helpful to refer back to Table 6-1 while reading this section.

State Control. Addressable bits or flags may be set, cleared, or logically complemented in one instruction cycle with the two-byte instructions SETB, CLR, and CPL. The "B" affixed to SETB distinguishes it from the assembler "SET" directive used for symbol definition. SETB and CLR are analogous to loading a bit with a constant, 1 or 0. Single byte versions perform the same three operations on the carry.

a. Ram Bit Addresses

b. Special Function Register Bit Addresses

Figure 6-3. Bit Address Maps

(MSB)				(LSB)			
CY	AC	F0	RS1	RS0	OV	—	P
Symbol Position Name and Significance							
CY	PSW.7	Carry flag.					
		Set/cleared by hardware or software during certain arithmetic and logical instructions.					
AC	PSW.6	Auxiliary Carry flag.					
		Set/cleared by hardware during addition or subtraction instructions to indicate carry or borrow out of bit 3.					
F0	PSW.5	Flag 0.					
		Set/cleared/tested by software as a user-defined status flag.					
RS1	PSW.4	Register bank Select control bits.					
RS0	PSW.3	1 & 0. Set/cleared by software to determine working register bank (see Note).					
				OV	PSW.2	Overflow flag.	
						Set/cleared by hardware during arithmetic instructions to indicate overflow conditions.	
				—	PSW.1	(reserved)	
				P	PSW.0	Parity flag.	
						Set/cleared by hardware each instruction cycle to indicate an odd/even number of “one” bits in the accumulator, i.e., even parity.	
						Note- the contents of (RS1, RS0) enable the working register banks as follows:	
						(0,0) - Bank 0 (00H–07H)	
						(0,1) - Bank 1 (08H–0FH)	
						(1,0) - Bank 2 (10H–17H)	
						(1,1) - Bank 3 (18H–1FH)	

Figure 6-4. PSW — Program Status Word Organization

(MSB)				(LSB)			
RD	WR	T1	T0	INT1	INT0	TXD	RXD
Symbol Position Name and Significance							
RD	P3.7	Read data control output. Active low pulse generated by hardware when external data memory is read.					
WR	P3.6	Write data control output. Active low pulse generated by hardware when external data memory is written.					
T1	P3.5	Timer/counter 1 external input or test pin.					
T0	P3.4	Timer/counter 0 external input or test pin.					
				INT1	P3.3	Interrupt 1 input pin. Low-level or falling-edge triggered.	
				INT0	P3.2	Interrupt 0 input pin. Low-level or falling-edge triggered.	
				TXD	P3.1	Transmit Data pin for serial port in UART mode. Clock output in shift register mode.	
				RXD	P3.0	Receive Data pin for serial port in UART mode. Data I/O pin in shift register mode.	

Figure 6-5. P3 — Alternate I/O Functions of Port 3

(MSB)				(LSB)			
TF1	TR1	TF0	TR0	IE1	IT1	IE0	IT0
Symbol Position Name and Significance							
TF1	TCON.7	Timer 1 overflow Flag. Set by hardware on timer/counter overflow. Cleared when interrupt processed.					
TR1	TCON.6	Timer 1 Run control bit. Set/cleared by software to turn timer/counter on/off.					
TF0	TCON.5	Timer 0 overflow Flag. Set by hardware on timer/counter overflow. Cleared when interrupt processed.					
TR0	TCON.4	Timer 0 Run control bit. Set/cleared by software to turn timer/counter on/off.					
a. TCON—Timer/Counter Control/Status Register							

(MSB)				(LSB)			
SM0	SM1	SM2	REN	TB8	RB8	TI	RI
Symbol Position Name and Significance							
SM0	SCON.7	Serial port Mode control bit 0. Set/cleared by software (see note).					
SM1	SCON.6	Serial port Mode control bit 1. Set/cleared by software (see note).					
SM2	SCON.5	Serial port Mode control bit 2. Set by software to disable reception of frames for which bit 8 is zero.					
REN	SCON.4	Receiver Enable control bit. Set/cleared by software to enable/disable serial data reception.					
TB8	SCON.3	Transmit Bit 8. Set/cleared by hardware to determine state of ninth data bit transmitted in 9-bit UART mode.					
IE1	TCON.3	Interrupt 1 Edge flag. Set by hardware when external interrupt edge detected. Cleared when interrupt processed.					
IT1	TCON.2	Interrupt 1 Type control bit. Set/cleared by software to specify falling edge/low level triggered external interrupts.					
IE0	TCON.1	Interrupt 0 Edge flag. Set by hardware when external interrupt edge detected. Cleared when interrupt processed.					
IT0	TCON.0	Interrupt 0 Type control bit. Set/cleared by software to specify falling edge/low level triggered external interrupts.					
RB8	SCON.2	Receive Bit 8. Set/cleared by hardware to indicate state of ninth data bit received.					
TI	SCON.1	Transmit Interrupt flag. Set by hardware when byte transmitted. Cleared by software after servicing.					
RI	SCON.0	Receive Interrupt flag. Set by hardware when byte received. Cleared by software after servicing.					
Note- the state of (SM0, SM1) selects: (0,0)—Shift register I/O expansion. (0,1)—8-bit UART, variable data rate. (1,0)—9-bit UART, fixed data rate. (1,1)—9-bit UART, variable data rate.							

Figure 6-6. Peripheral Configuration Registers

(MSB)				(LSB)			
EA	—	—	ES	ET1	EX1	ET1	EX0
Symbol Position Name and Significance							
EA	IE.7						
—	IE.6						
—	IE.5						
ES	IE.4						
ET1	IE.3						

EX1	IE.2	Enable External interrupt 1 control bit. Set/cleared by software to enable/disable interrupts from INT1.
ET0	IE.1	Enable Timer 0 control bit. Set/cleared by software to enable/disable interrupts from timer/counter 0.
EX0	IE.0	Enable External interrupt 0 control bit. Set/cleared by software to enable/disable interrupts from INT0.

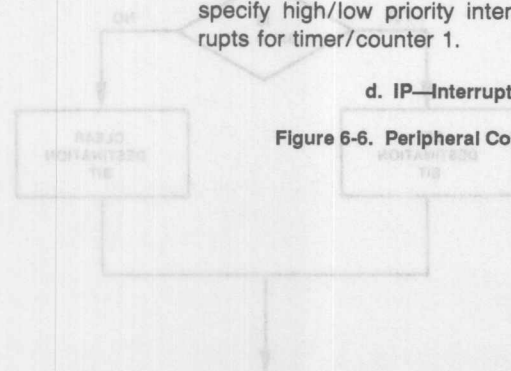
c. IE—Interrupt Enable Register

(MSB)				(LSB)			
—	—	—	PS	PT1	PX1	PT0	PX0
Symbol Position Name and Significance							
—	IP.7						
—	IP.6						
—	IP.5						
PS	IP.4						
PT1	IP.3						

PX1	IP.2	External interrupt 1 Priority control bit. Set/cleared by software to specify high/low priority interrupts for INT1.
PT0	IP.1	Timer 0 Priority control bit. Set/cleared by software to specify high/low priority interrupts for timer/counter 0.
PX0	IP.0	External interrupt 0 Priority control bit. Set/cleared by software to specify high/low priority interrupts for INT0.

d. IP—Interrupt Priority Control Register

Figure 6-6. Peripheral Configuration Registers (continued)



ASM51 specifies a bit address in any of three ways:

- by the number or expression corresponding to the direct bit address (0-255);
- by the name or address of the register containing the bit, the *dot operator* symbol (a period: "."), and the bit's position in the register (7-0);
- in the case of control and status register, by the predefined assembler symbols listed in the first columns of Figures 6-4 through 6-6.

Bits may also be given user-defined names with the assembler "BIT" directive and any of the above techniques. For example, bit 5 of the PSW may be cleared by any of the four instructions.

```

USR_FLG BIT PSW.5 ; User Symbol Definition
; ...
CLR 0D5H ; Absolute Addressing
CLR PSW.5 ; Use of Dot Operator
CLR F0 ; Pre-Defined Assembler Symbol
CLR USR_FLG ; User-Defined Symbol

```

Data Transfers. The two-byte MOV instructions can transport any addressable bit to the carry in one cycle, or copy the carry to the bit in two cycles. A bit can be moved between two arbitrary locations via a carry by combining the two instructions. (If necessary, one may push and pop the PSW to preserve the previous contents of the carry.) These instructions can replace the multi-instruction sequence of Figure 6-7, which shows a program structure appearing in controller applications whenever flags or outputs are conditionally switched on or off.

Logical Operations. Four instructions perform the logical-AND and logical-OR operations between the carry and another bit, and leave the results in the carry. The instruction mnemonics are ANL and ORL; the absence or presence of a slash mark ("/") before the source operand indicates whether to use the positive-logic value or the logical complement of the addressed bit. (The source operand itself is never affected.)

Bit-test Instructions. The conditional jump instructions "JC rel" (Jump on Carry) and "JNC rel" (Jump on Not Carry) test the state of the carry flag, branching if it is a one or zero, respectively. The letters "rel" denote relative code addressing. The 3-byte instructions "JB bit, rel" and "JNB bit, rel" (Jump on Bit and Jump on Not Bit) test the state of any addressable bit in a similar manner. A fifth instruction combines the Jump on Bit and Clear operations. "JBC bit, rel" conditionally branches to the indicated address, then clears the bit in the same 2-cycle instruction. This operation is the same as the 8048-family "JTF" instructions.

All 8051 conditional jump instructions use program counter-relative addressing, and all execute in two cycles. The last instruction byte encodes a signed displacement ranging from -128 to +127. During execution, the CPU adds this value to the incremented program counter to produce the jump destination. Put another way, a conditional jump to the immediately following instruction would encode 00H in the offset byte.

A section of program or subroutine written using only relative jumps to nearby addresses will have the same machine code independent of the code's location. An assembled routine may be repositioned anywhere in memory, even crossing memory page boundaries, without having to modify the program or recompute destination addresses. To facilitate this flexibility, there is an unconditional "Short Jump" (SJMP) which uses relative addressing as well. Since a programmer would have quite a chore trying to compute relative offset values from one instruction to another, ASM51 automatically computes the displacement needed, giving only the destination address or label. An error message will alert the programmer if the destination is "out of range."

The so-called "Bit Test" instructions implemented on many other microprocessors simply perform the logic-AND operation between a byte variable and a constant mask, and set or clear a zero flag depending on the result.

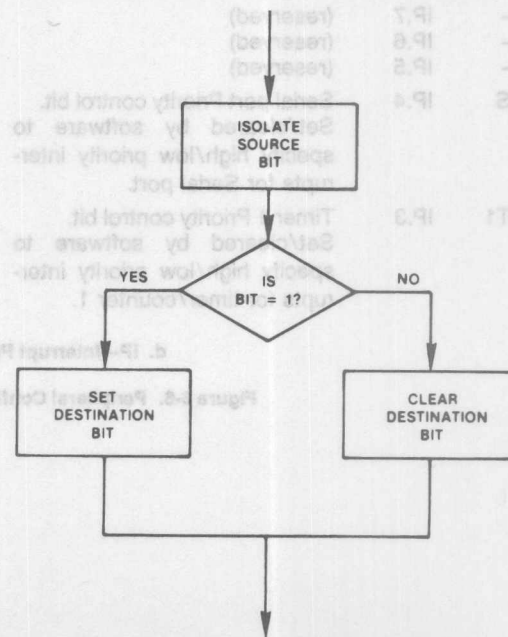


Figure 6-7. Bit Transfer Instruction Operation

This is essentially equivalent to the 8051 "MOV C,bit" instruction. A second instruction is then needed to conditionally branch based on the state of the zero flag. This does *not* constitute abstract bit-addressing in the 8051 Family sense. A flag exists only as a field within a register; to reference a bit the programmer must know and specify both the encompassing register and the bit's position therein. This constraint severely limits the flexibility of symbolic bit addressing and reduces the machine's code-efficiency and speed.

Interaction with Other Instructions. The carry flag is also affected by the instructions listed in Table 6-2. It can be rotated through the accumulator, and altered as a side effect of arithmetic instructions. Refer to the User's Manual for details on how these instructions operate.

Simple Instruction Combinations

By combining general purpose bit operations with certain addressable bits, one can "custom build" several hundred useful instructions. All eight bits of the PSW can be tested directly with conditional jump instructions to monitor (among other things) parity and overflow status. Programmers can take advantage of 128 software flags to keep track of operating modes, resource usage, and so forth.

The Boolean instructions are also the most efficient way to control or reconfigure peripheral and I/O registers. All 32 I/O lines become "test pins," for example, tested by conditional jump instructions. Any output pin can be toggled (complemented) in a single instruction cycle. Setting or clearing the Timer Run flags (TR0 and TR1) turn the timer-counters on or off; polling the same flags elsewhere lets the program determine if a timer is running. The respective overflow flag (TF0 and TF1) can be tested to determine when the desired period or count has elapsed, then cleared in preparation for the next repetition. These bits are all part of the TCON register, Figure 6-6a. Thanks to symbolic bit addressing, the programmer only needs to remember the mnemonic associated with each function, and does not need to memorize control word layouts.

In the 8048-family, instructions corresponding to some of the above functions require specific opcodes. Ten different opcodes serve to clear and complement the software flags F0 and F1, enable and disable each interrupt, and start/stop the timer. In the 8051 instruction set, just three opcodes (SETB, CLR, CPL) with a direct bit address appended perform the same functions. Two test instructions (JB and JNB) can be combined with bit addresses to test the 8048 software flags, the I/O pins, T0, T1, and INT, and the eight accumulator bits, replacing 15 more different instructions.

Table 6-2. Other Instructions Affecting the Carry Flag

Mnemonic		Description	Byte	Cyc
ADD	A,Rn	Add register to Accumulator	1	1
ADD	A,direct	Add direct byte to Accumulator	2	1
ADD	A,@Ri	Add indirect RAM to Accumulator	1	1
ADD	A,#data	Add immediate data to Accumulator	2	1
ADDC	A,Rn	Add register to Accumulator with Carry flag	1	1
ADDC	A,direct	Add direct byte to Accumulator with Carry flag	2	1
ADDC	A,@Ri	Add indirect RAM to Accumulator with Carry flag	1	1
ADDC	A,#data	Add immediate data to Acc with Carry flag	2	1
SUBB	A,Rn	Subtract register from Accumulator with borrow	1	1
SUBB	A,direct	Subtract direct byte from Acc with borrow	2	1
SUBB	A,@Ri	Subtract indirect RAM from Acc with borrow	1	1
SUBB	A,#data	Subtract immediate data from Acc with borrow	2	1
MUL	AB	Multiply A & B	1	4
DIV	AB	Divide A by B	1	4
DA	A	Decimal Adjust Accumulator	1	1
RLC	A	Rotate Accumulator Left through the Carry flag	1	1
RRC	A	Rotate Accumulator Right through Carry flag	1	1
CJNE	A,direct,rel	Compare direct byte to Acc & Jump if Not Equal	3	2
CJNE	A,#data,rel	Compare immediate to Acc & Jump if Not Equal	3	2
CJNE	Rn,#data,rel	Compare immed to register & Jump if Not Equal	3	2
CJNE	@Ri,#data,rel	Compare immed to indirect & Jump if Not Equal	3	2

CHAPTER 6
8051 Family Boolean Processing Capabilities

Table 6-3a shows how 8051 programs implement software flag and machine control functions associated with special opcodes in the 8048. In every case the 8051

Family solution requires the same number of machine cycles, and executes 2.5 times faster.

Table 6-3a. Contrasting 8048 and 8051 Bit Control and Testing Instructions

8048 Instruction	Bytes	Cycles	μs	8051 Instruction	Bytes	Cycles & μs
Flag Control						
CLR C	1	1	2.5	CLR C	1	1
CPL F0	1	1	2.5	CPL F0	2	1
Flag Testing						
JNC offset	2	2	5.0	JNC rel	2	2
JF0 offset	2	2	5.0	JB F0,rel	3	2
JB7 offset	2	2	5.0	JB ACC.7,rel	3	2
Peripheral Polling						
JT0 offset	2	2	5.0	JB T0,rel	3	2
JN1 offset	2	2	5.0	JNB INT0,rel	3	2
JTF offset	2	2	5.0	JBC TF0,rel	3	2
Machine and Peripheral Control						
STRT T	1	1	2.5	SETB TR0	2	1
EN 1	1	1	2.5	SETB EX0	2	1
DIS TCNT1	1	1	2.5	CLR ET0	2	1

Table 6-3b. Replacing 8048 Instruction Sequences with Single 8051 Instructions

8048 Instruction	Bytes	Cycles	μs	8051 Instruction	Bytes	Cycles & μs
Flag Control						
Set carry						
CLR C				SETB C	1	1
CPL C	= 2	2	5.0			
Set Software Flag						
CLR F0				SETB F0	2	1
CPL F0	= 2	2	5.0			
Turn Off Output Pin						
ANL P1, #0FBH	= 2	2	5.0	CLR P1.2	2	1
Complement Output Pin						
IN A,P1						
XRL A, #04H				CPL P1.2	2	1
OUTL P1,A	= 4	6	15.0			
Clear Flag in RAM						
MOV R0, #FLGADR				CLR USER_FLG	2	1
MOV A,@R0						
ANL A, #FLGMASK						
MOV @R0,A	= 6	6	15.0			

Table 6-3b. Replacing 8048 Instruction Sequences with Single 8051 Instructions (continued)

8048 Instruction	Bytes	Cycles	μs	8051 Instruction	Bytes	Cycles & μs
Flag Testing:						
Jump if Software Flag is 0						
JF0 \$ + 4				JNB F0,rel	3	2
JMP offset = 4	4	4	10.0			
Jump if Accumulator bit is 0						
CPL A				JNB ACC.7,rel	3	2
JB7 offset						
CPL A = 4	4	4	10.0			
Peripheral Polling						
Test if Input Pin is Grounded						
IN A.P1				JNB P1.3,rel	3	2
CPL A						
JB3 offset = 4	4	5	12.5			
Test if Interrupt Pin is High						
JN1 \$ + 4				JB INT0,rel	3	2
JMP offset = 4	4	4	10.0			

BOOLEAN PROCESSOR APPLICATIONS

So what does all this buy you?

Qualitatively, nothing. All the same capabilities *could* be (and often have been) implemented on other machines using awkward sequences of other basic operations. As mentioned earlier, any CPU can solve any problem given enough time.

Quantitatively, the differences between a solution provided by the 8051 and those required by previous architectures are numerous. The 8051 Family solution is a faster, cleaner, lower-cost solution to microcontroller applications.

The opcode space freed by condensing many specific 8048 instructions in a few general operations has been used to add new functionality to the 8051 family architecture — both for byte and bit operations. 144 software flags replace the 8048's two. These flags (and the carry) may be directly set, not just cleared and complemented, and all can be tested for either state, not just one. Operating mode bits previously inaccessible may be read, tested, or saved. Situations where the 8051 instruction set provides new capabilities are contrasted with 8048 instruction sequences in Table 6-3b. Here the 8051 speed advantage ranges from 5x to 15x!

Combining Boolean and byte-wide instructions can produce great synergy. An 8051 Family based application will prove to be:

- simpler to write since the architecture correlates more closely with the problems being solved;
- easier to debug because more individual instructions have no unexpected or undesirable side-effects;
- more byte efficient due to direct bit addressing and program counter relative branching;
- faster running because fewer bytes of instructions need to be fetched and fewer conditional jumps are processed;
- lower cost because of the high level of system-integration within one component.

These rather unabashed claims of excellence shall not go unsubstantiated. The rest of this chapter examines less trivial tasks simplified by the Boolean processor. The first three compare the 8051 with other microprocessors; the last two go into 8051-based system designs in much greater depth.

Design Example #1 — Bit Permutation

First, we'll use the bit-transfer instructions to permute a lengthy pattern of bits.

A steadily increasing number of data communication products use encoding methods to protect the security of sensitive information. By law, interstate financial transactions involving federal banking system must be transmitted using the Federal Information Processing *Data Encryption Standard* (DES).

Basically, the DES combines eight bytes of "plaintext" data (in binary ASCII, or any other format) with a 56-bit "key", producing a 64-bit encrypted value for transmission. At the receiving end the same algorithm is applied to the incoming data using the same key, reproducing the original eight byte message. The algorithm used for these permutations is fixed; different user-defined keys ensure data privacy.

It is not the purpose here to describe the DES in any detail. Suffice it to say that encryption/decryption is a long, iterative process consisting of rotations, exclusive-OR operations, function table look-ups, and an extensive sequence of bit permutation, packing, and unpacking steps. The bit manipulation steps are included, it is rumored, to impede a general purpose digital supercomputer trying to "break" the code. Any algorithm implementing the DES with previous generation microprocessors would spend virtually all of its time diddling bits.

The bit manipulation performed is typified by the Key Schedule Calculation represented in Figure 6-8. This step is repeated 16 times for each key used in the course of a transmission. In essence, a 7-byte, 56-bit "Shift Key Buffer" is transformed into an 8-byte, "Permutation Buffer" without altering the shifted key. The arrows in Figure 6-8 indicate a few of the translation steps. Only six bits of each byte of the Permutation Buffer are used;

the two high-order bits of each byte are cleared. This means only 48 of the 56 Shifted Key Buffer bits are used in any one iteration.

Different microprocessor architectures would best implement this type of permutation in different ways. Most approaches would share the steps of Figure 6-9a:

- Initialize the Permutation Buffer to default state (ones or zeroes);
- Isolate the state of a bit of a byte from the Key Buffer. Depending on the CPU, this might be accomplished by rotating a word of the Key Buffer through a carry flag or testing a bit in memory or an accumulator against a mask byte;
- Perform a conditional jump based on the carry or zero flag if the Permutation Buffer default state is correct;
- Otherwise reverse the corresponding bit in the permutation buffer with logical operations and mask bytes.

Each step above may require several instructions. The last three steps must be repeated for all 48 bits. Most microprocessors would spend 300 to 3,000 μ s on each of the 16 iterations.

Notice, though, that this flow chart looks a lot like Figure 6-7. The Boolean Processor can permute bits by simply moving them from the source to the carry to the destination — a total of two instructions taking 4 bytes and 3 μ s per bit. Assume the Shifted Key Buffer and Permutation Buffer both reside in bit-addressable RAM, with the bits of the former assigned symbolic names SKB_1, SKB_2 . . . SKB_56. Then working from Figure 6-8, the software for the permutation algorithm would be that of Example 6-1a. The total routine length would be 192 bytes, requiring 144 μ s.

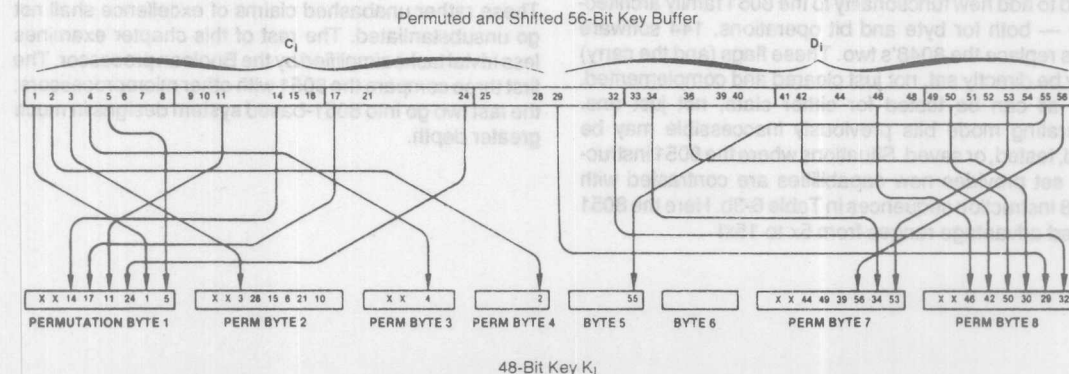


Figure 6-8. DES Key Schedule Transformation

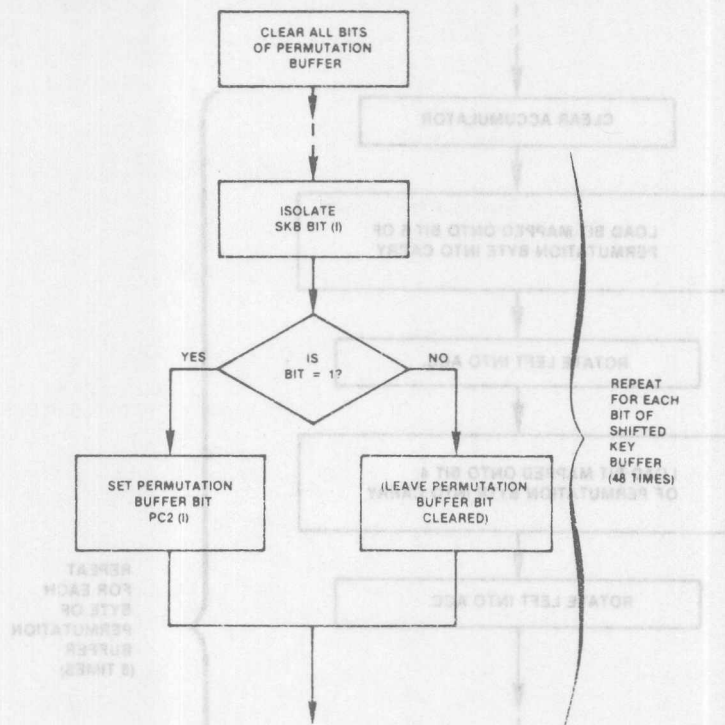


Figure 6-9a. Flowchart for Key Permutation Attempted with a Byte Processor

The algorithm of Figure 6-9b is just slightly more efficient in this time-critical application and illustrates the synergy of an integrated byte and bit processor. The bits needed for each byte of the Permutation Buffer are assimilated by loading each bit into the carry (1 μ s.) and shifting it into the accumulator (1 μ s.). Each byte is stored in RAM when completed. Forty-eight bits thus need a total of 112 instructions, some of which are listed in

Example 6-1b. Worst-case execution time would be 112 μ s, since each instruction takes a single cycle. Routine length should also decrease, to 168 bytes. Actually, in the context of the complete encryption algorithm, each permuted byte would be processed as soon as it is assimilated — saving memory and cutting execution time by another 8 μ s.

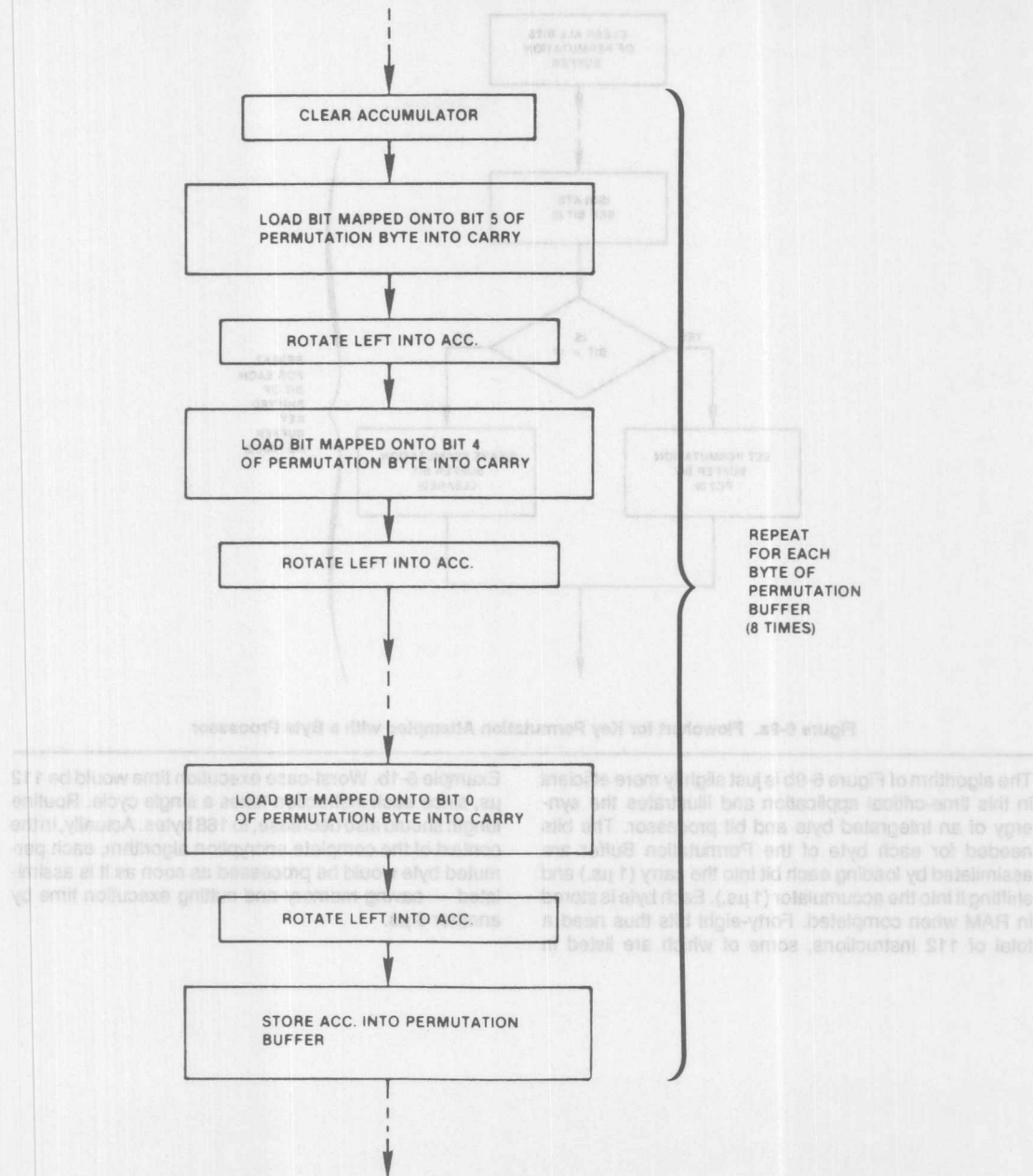


Figure 6-9b. DES Key Permutation with Boolean Processor

Example 6-1. DES Key Permutation Software

a. "Brute Force" technique

```

MOV    C,SKB_1
MOV    PB_1.1,C
MOV    C,SKB_2
MOV    PB_4.0,C
MOV    C,SKB_3
MOV    PB_2.5,C
MOV    C,SKB_4
MOV    PB_1.0,C
...
...
MOV    C,SKB_55
MOV    PB_5.0,C
MOV    C,SKB_56
MOV    PB_7.2,C

```

b. Using Accumulator to Collect Bits

```

CLR    A
MOV    C,SKB_14
RLC    A
MOV    C,SKB_17
RLC    A
MOV    C,SKB_11
RLC    A
MOV    C,SKB_24
RLC    A
MOV    C,SKB_1
RLC    A
MOV    C,SKB_5
RLC    A
MOV    PB_1,A
...
...
MOV    C,SKB_29
RLC    A
MOV    C,SKB_32
RLC    A
MOV    PB_8,A

```

To date, most banking terminals and other systems using the DES have needed special boards or peripheral controller chips just for the encryption decryption process, and still more hardware to form a serial bit stream for transmission (Figure 6-10a). An 8051 solution could pack most of the entire system onto the one chip (Figure 6-10b). The whole DES algorithm would require less than one-fourth of the on-chip program memory, with the remaining bytes free for operating the banking terminal (or whatever) itself.

Moreover, since transmission and reception of data is performed through the on-board UART, the unencrypted data (plaintext) never even exists outside the microcomputer! Naturally, this would afford a high degree of security from data interception.

Design Example #2 — Software Serial I/O

An example often imposed on beginning microcomputer students is to write a program simulating a UART. Though doing this with the 8051 Family may appear to be a moot point (given that the hardware for a full UART is on-chip), it is still instructive to see how it would be done, and maintains a product-line tradition.

As it turns out, the 8051 microcomputers can receive or transmit serial data via software very efficiently using the Boolean instruction set. Since any I/O pin may be a serial input or output, several serial links could be maintained at once.

Figure 6-11a and 11b, show algorithms for receiving or transmitting a byte of data. (Another section of program would invoke this algorithm eight times, synchronizing it with a start bit, clock signal, software delay, or timer interrupt.) Data is received by testing an input pin, setting the carry to the same state, shifting the carry into a data buffer, and saving the partial frame in internal RAM. Data is transmitted by shifting an output buffer through the carry, and generating each bit on an output pin.

A side-by-side comparison of the software for this common application with three different microprocessor architectures is shown in Table 6-4a and 6-4b. The 8051 solution is more efficient than the others on every count!

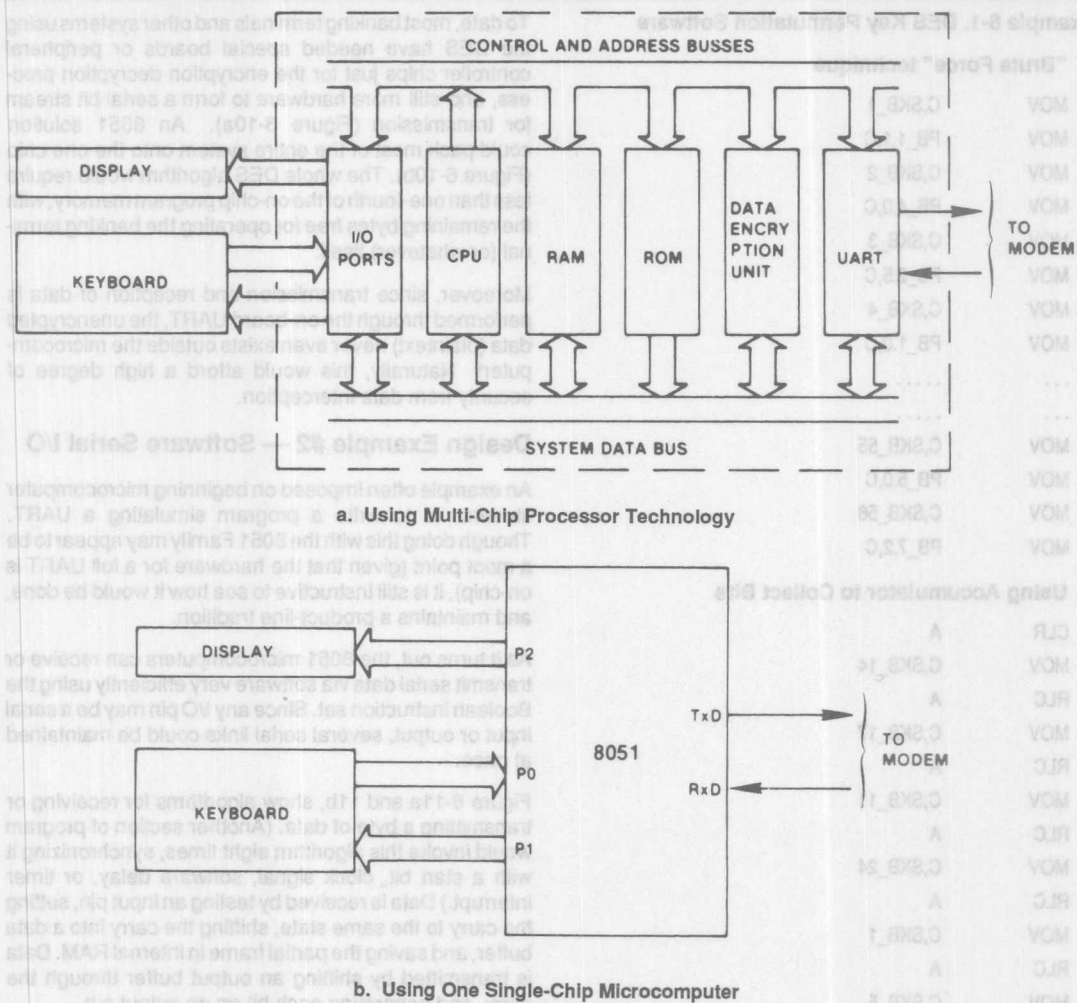


Figure 6-10. Secure Banking Terminal Block Diagram

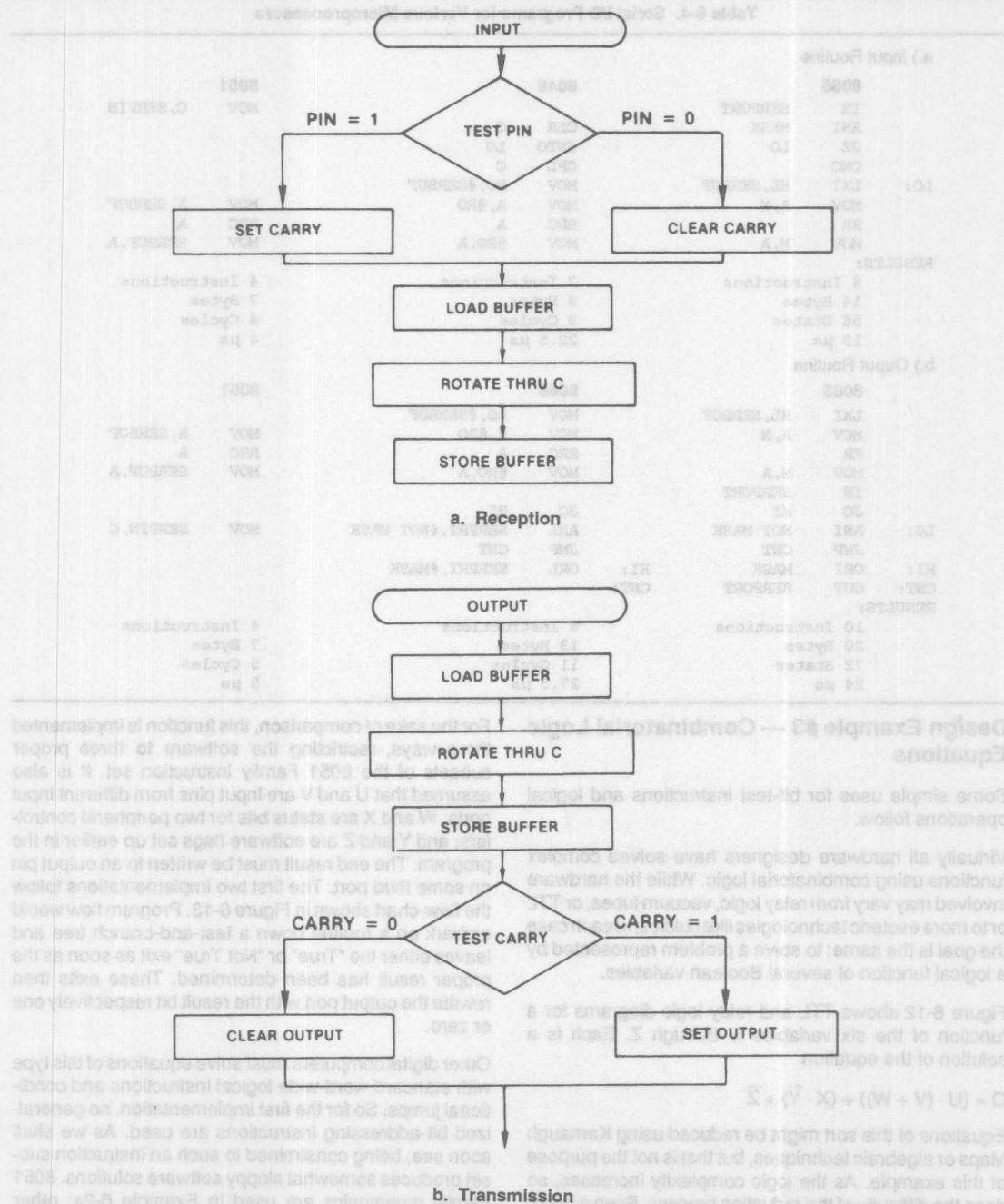


Figure 6-11. Serial I/O Algorithms

Table 6-4. Serial I/O Programs for Various Microprocessors

a.) Input Routine

8085	8048	8051
IN SERPORT	CLR C	MOV C, SERPIN
ANI MASK	JNTO LO	
JZ LO	CPL C	
CMC	MOV RO, #SERBUF	
LO: LXI HL, SERBUF	MOV A, @RO	MOV A, SERBUF
MOV A, M	RRC A	RRC A
RR	MOV @RO, A	MOV SERBUF, A
MOV M, A		
RESULTS:	7 Instructions	4 Instructions
8 Instructions	9 Bytes	7 Bytes
14 Bytes	9 Cycles	4 Cycles
56 States	22.5 μ s	4 μ s
19 μ s		

b.) Output Routine

8085	8048	8051
LXI HL, SERBUF	MOV RO, #SERBUF	
MOV A, M	MOV A, @RO	MOV A, SERBUF
RR	RRC A	RRC A
MOV M, A	MOV @RO, A	MOV SERBUF, A
IN SERPORT		
JC HI	JC HI	
LO: ANI NOT MASK	ANL SERPRT, #NOT MASK	MOV SERPIN, C
JMP CNT	JMP CNT	
HI: ORI MASK	ORL SERPRT, #MASK	
CNT: OUT SERPORT	HI: ORL SERPRT, #MASK	
RESULTS:	8 Instructions	4 Instructions
10 Instructions	13 Bytes	7 Bytes
20 Bytes	11 Cycles	5 Cycles
72 States	27.5 μ s	5 μ s
24 μ s		

Design Example #3 — Combinatorial Logic Equations

Some simple uses for bit-test instructions and logical operations follow.

Virtually all hardware designers have solved complex functions using combinatorial logic. While the hardware involved may vary from relay logic, vacuum tubes, or TTL or to more esoteric technologies like fluidics, in each case the goal is the same: to solve a problem represented by a logical function of several Boolean variables.

Figure 6-12 shows TTL and relay logic diagrams for a function of the six variables U through Z. Each is a solution of the equation

$$Q = (U \cdot (V + W)) + (X \cdot \bar{Y}) + \bar{Z}$$

Equations of this sort might be reduced using Karnaugh Maps or algebraic techniques, but that is not the purpose of this example. As the logic complexity increases, so does the difficulty of the reduction process. Even a minor change to the function equations as the design evolves would require tedious re-reduction from scratch.

For the sake of comparison, this function is implemented three ways, restricting the software to three proper subsets of the 8051 Family instruction set. It is also assumed that U and V are input pins from different input ports, W and X are status bits for two peripheral controllers, and Y and Z are software flags set up earlier in the program. The end result must be written to an output pin on some third port. The first two implementations follow the flow-chart shown in Figure 6-13. Program flow would embark on a routine down a test-and-branch tree and leaves either the "True" or "Not True" exit as soon as the proper result has been determined. These exits then rewrite the output port with the result bit respectively one or zero.

Other digital computers must solve equations of this type with standard word-wide logical instructions and conditional jumps. So for the first implementation, no generalized bit-addressing instructions are used. As we shall soon see, being constrained to such an instruction subset produces somewhat sloppy software solutions. 8051 Family mnemonics are used in Example 6-2a; other machines might further cloud the situation by requiring operation-specific mnemonics like INPUT, OUTPUT, LOAD, STORE, etc., instead of the MOV mnemonic used for all variable transfers in the 8051 instruction set.

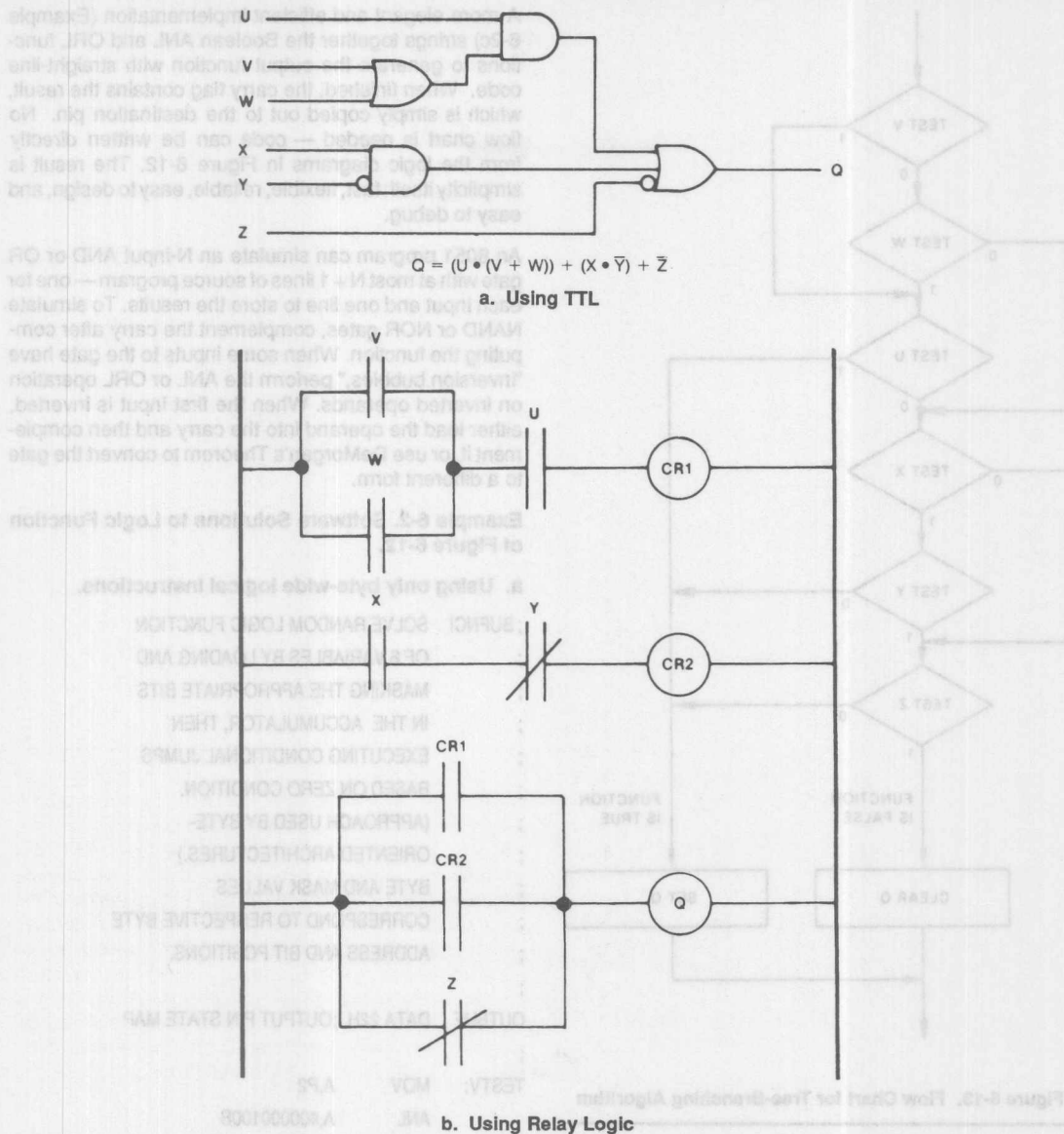


Figure 6-12. Hardware Implementations of Boolean Functions

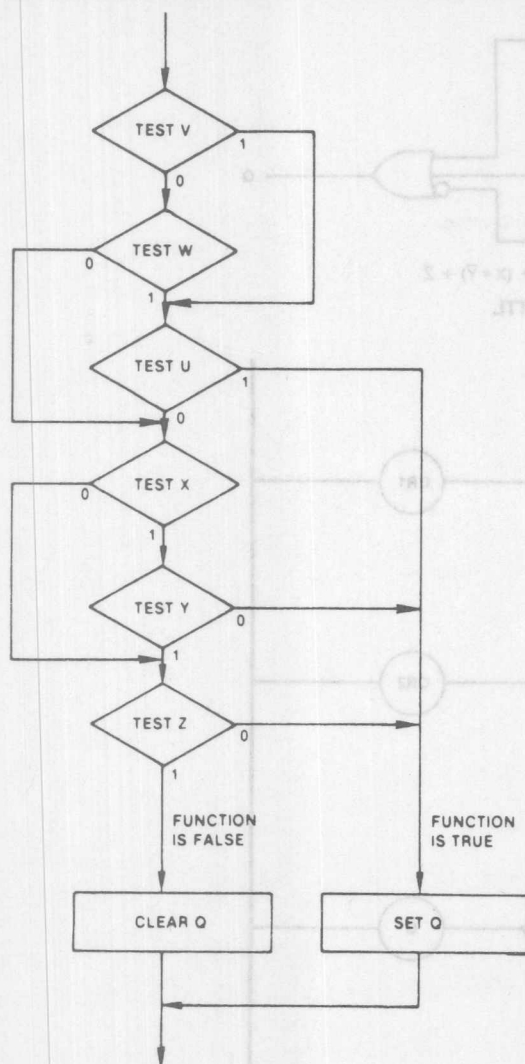


Figure 6-13. Flow Chart for Tree-Branching Algorithm

The code that results is cumbersome and error prone. It would be difficult to prove whether the software worked for all input combinations in programs of this sort. Furthermore, execution time varies widely with input data.

Thanks to the direct bit-test operations, a single instruction can replace each move mask conditional jump sequence in Example 6-2a, but the algorithm would be equally convoluted (see Example 6-2b). To lessen the confusion, "a bit" each input variable is assigned a symbolic name.

A more elegant and efficient implementation (Example 6-2c) strings together the Boolean ANL and ORL functions to generate the output function with straight-line code. When finished, the carry flag contains the result, which is simply copied out to the destination pin. No flow chart is needed — code can be written directly from the logic diagrams in Figure 6-12. The result is simplicity itself; fast, flexible, reliable, easy to design, and easy to debug.

An 8051 program can simulate an N-input AND or OR gate with at most $N + 1$ lines of source program — one for each input and one line to store the results. To simulate NAND or NOR gates, complement the carry after computing the function. When some inputs to the gate have "inversion bubbles," perform the ANL or ORL operation on inverted operands. When the first input is inverted, either load the operand into the carry and then complement it, or use DeMorgan's Theorem to convert the gate to a different form.

Example 6-2. Software Solutions to Logic Function of Figure 6-12.

a. Using only byte-wide logical instructions.

```

; BUFNCI SOLVE RANDOM LOGIC FUNCTION
;         OF 6 VARIABLES BY LOADING AND
;         MASKING THE APPROPRIATE BITS
;         IN THE ACCUMULATOR, THEN
;         EXECUTING CONDITIONAL JUMPS
;         BASED ON ZERO CONDITION.
;         (APPROACH USED BY BYTE-
;         ORIENTED ARCHITECTURES.)
;         BYTE AND MASK VALUES
;         CORRESPOND TO RESPECTIVE BYTE
;         ADDRESS AND BIT POSITIONS.

```

OUTBUF DATA 22H ; OUTPUT PIN STATE MAP

```

TESTV: MOV A,P2
      ANL A,#00000100B
      JNZ TESTU
      MOV A,TCON
      ANL A,#00100000B
      JZ TESTX
TESTU: MOV A,P1
      ANL A,#00000010B
      JNZ SETQ

```

```

TESTX: MOV A, TCON
      ANL A, #00001000B
      JZ TESTZ
      MOV A, 20H
      ANL A, #00000001B
      JZ SETQ
TESTZ: MOV A, 21H
      ANL A, #00000010B
      JZ SETQ
CLRQ:  MOV A, OUTBUF
      ANL A, #11110111B
      JMP OUTQ
SETQ:  MOV A, OUTBUF
      ORL A, #00001000B
OUTQ:  MOV OUTBUF, A
      MOV P3, A

```

b. Using only bit-test instructions.

```

;BFUNC2 SOLVE RANDOM LOGIC FUNCTION
;
; OF 6 VARIABLES BY DIRECTLY
;
; POLLING EACH BIT.
;
; (APPROACH USING 8051-FAMILY UNIQUE
;
; BIT-TEST INSTRUCTION CAPABILITY.)
;
; SYMBOLS USED IN LOGIC DIAGRAM
;
; ASSIGNED TO CORRESPONDING 8x51
;
; BIT ADDRESSES.
;
U      BIT P1.1
V      BIT P2.2
W      BIT TF0
X      BIT 1E1
Y      BIT 20H.0
Z      BIT 21H.1
Q      BIT P3.3
;
; ...
TEST_V: JB V, TEST_U
      JNB W, TEST_X
TEST_U: JB U, SET_Q
TEST_X: JNB X, TEST_Z
      JNB Y, SET_Q
TEST_Z: JNB Z, SET_Q

```

```

CLR_Q: CLR Q
      JMP NXTTST
SET_Q: SETB Q
NXTTST: ;CONTINUATION OF PROGRAM

```

c. Using logical operations on Boolean variables.

```

;FUNC3 SOLVE A RANDOM LOGIC FUNCTION
;
; OF 6 VARIABLES USING
;
; STRAIGHT_LINE LOGICAL
;
; INSTRUCTIONS ON 8051 BOOLEAN
;
; VARIABLES.
;
MOV C, V
ORL C, W ; OUTPUT OF OR GATE
ANL C, U ; OUTPUT OF TOP AND GATE
MOV F0, C ; SAVE INTERMEDIATE STATE
MOV C, X
ANL C, Y ; OUTPUT OF BOTTOM AND GATE
ORL C, F0 ; INCLUDE VALUE SAVED ABOVE
ORL C, Z ; INCLUDE LAST INPUT VARIABLE
MOV Q, C ; OUTPUT COMPUTED RESULT

```

An upper limit can be placed on the complexity of software to simulate a large number of gates by summing the total number of inputs and outputs. The *actual* total should be somewhat shorter, since calculations can be "chained," as shown above. The output of one gate is often the first input to another, bypassing the intermediate variable to eliminate two lines of source.

Design Example #4 — Automotive Dashboard Functions

Now let's apply these techniques to designing the software for a complete controller system. This application is patterned after a familiar real-world application which isn't nearly as trivial as it might first appear: automobile turn signals.

Imagine the 3-position turn lever on the steering column as a single-pole, triple-throw toggle switch. In its central position all contacts are open. In the up or down position, contacts close causing corresponding lights in the rear of the car to blink. So far very simple.

Two more turn signals blink in the front of the car, and two others in the dashboard. All six bulbs flash when an emergency switch is closed. A thermo-mechanical relay (accessible under the dashboard in case it wears out) causes the blinking.

Applying the brake pedal turns the tail light filaments on constantly — unless a turn is in progress, in which case the blinking tail light is not affected. (Of course, the front turn signals and dashboard indicators are not affected by the brake pedal.) Table 6-5 summarizes these operating modes.

But we're not done yet. Each of the exterior turn signal (but not the dashboard) bulbs has a second, somewhat dimmer filament for the parking lights. Figure 6-14 shows TTL circuitry which could control all six bulbs. The signals labeled "High Freq." and "Low Freq." represent two square-wave inputs. Basically, when one of the turn switches is closed or the emergency switch is activated, the low frequency signal (about 1 Hz) is gated through to the appropriate dashboard indicator(s) and turn signal(s). The rear signals are also activated when the brake pedal is depressed provided a turn is not being made in the same direction. When the parking light switch is closed the higher frequency oscillator is gated to each front and rear turn signal, sustaining a low-intensity background level. (This is to eliminate the need for additional parking light filaments.)

In most cars, the switching logic to generate these functions requires a number of multiple-throw contacts. As many as 18 conductors thread the steering column of some automobiles solely for turn-signal and emergency blinker functions.

A multiple-conductor wiring harness runs to each corner of the car, behind the dash, up the steering column, and down to the blinker relay below. Connectors at each termination for each filament lead to extra cost and labor during construction, lower reliability and safety, and more costly repairs. And considering the system's present complexity, increasing its reliability or detecting failures would be quite difficult.

There are two reasons for going into such painful detail describing this example. First, it shows that the hardest part of many system designs is determining what the controller should do. Writing the software to solve these functions is comparatively easy. Secondly, it shows the many potential failure points in the system. Later we'll see how the peripheral functions and intelligence built into a microcomputer (with a little creativity) can greatly reduce external interconnections and mechanical parts count.

Table 6-5. Truth Table for Turn-Signal Operation

Input Signals				Output Signals			
Brake Switch	Emerg. Switch	Left Turn Switch	Right Turn Switch	Left Front & Dash	Right Front & Dash	Left Rear	Right Rear
0	0	0	0	Off	Off	Off	Off
0	0	0	1	Off	Blink	Off	Blink
0	0	1	0	Blink	Off	Blink	Off
0	1	0	0	Blink	Blink	Blink	Blink
0	1	0	1	Blink	Blink	Blink	Blink
0	1	1	0	Blink	Blink	Blink	Blink
1	0	0	0	Off	Off	On	On
1	0	0	1	Off	Blink	On	Blink
1	0	1	0	Blink	Off	Blink	On
1	1	0	0	Blink	Blink	On	On
1	1	0	1	Blink	Blink	On	Blink
1	1	1	0	Blink	Blink	Blink	On

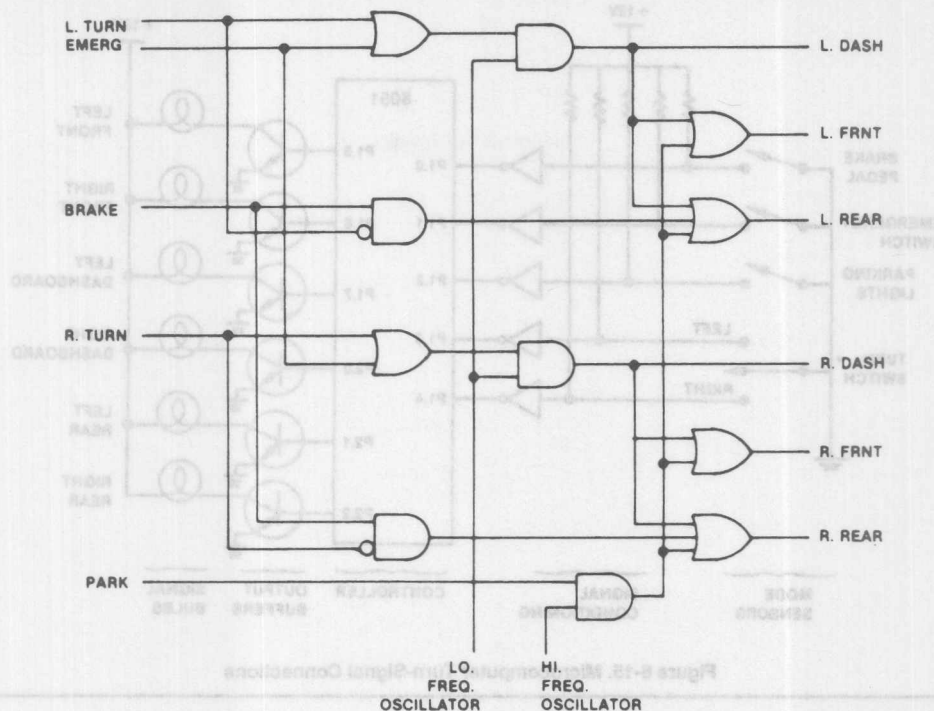


Figure 6-14. TTL Logic Implementation of Automotive Turn Signals

The Single-Chip Solution

The circuit shown in Figure 6-15 indicates five input pins to the five input variables — left-turn select, right-turn select, brake pedal down, emergency switch on, and parking lights on. Six output pins turn on the front, rear, and dashboard indicators for each side. The microcomputer implements all logical functions through software, which periodically updates the output signals as time elapses and input conditions change.

Design Example #3 demonstrated that symbolic addressing with user-defined bit names makes code and documentation easier to write and maintain. Accordingly, we'll assign these I/O pins names for use throughout the program. (The format of this example will differ somewhat from the others. Segments of the overall program will be presented in sequence as each is described.)

```
;
;
; INPUT PIN DECLARATIONS:
; (ALL INPUTS ARE POSITIVE-TRUE LOGIC)
;
;
BRAKE BIT P1.0 ;BRAKE PEDAL DEPRESSED
```

```
EMERG BIT P1.1 ;EMERGENCY BLINKER
ACTIVATED
PARK BIT P1.2 ;PARKING LIGHTS ON
L_TURN BIT P1.3 ;TURN LEVER DOWN
R_TURN BIT P1.4 ;TURN LEVER UP
;
; OUTPUT PIN DECLARATIONS
;
L_FRNT BIT P1.5 ;FRONT LEFT-TURN
INDICATOR
R_FRNT BIT P1.6 ;FRONT RIGHT-TURN
INDICATOR
L_DASH BIT P1.7 ;DASHBOARD LEFT-TURN
INDICATOR
R_DASH BIT P2.0 ;DASHBOARD RIGHT-TURN
INDICATOR
L_REAR BIT P2.1 ;REAR LEFT-TURN
INDICATOR
R_REAR BIT P2.2 ;REAR RIGHT-TURN
INDICATOR
```

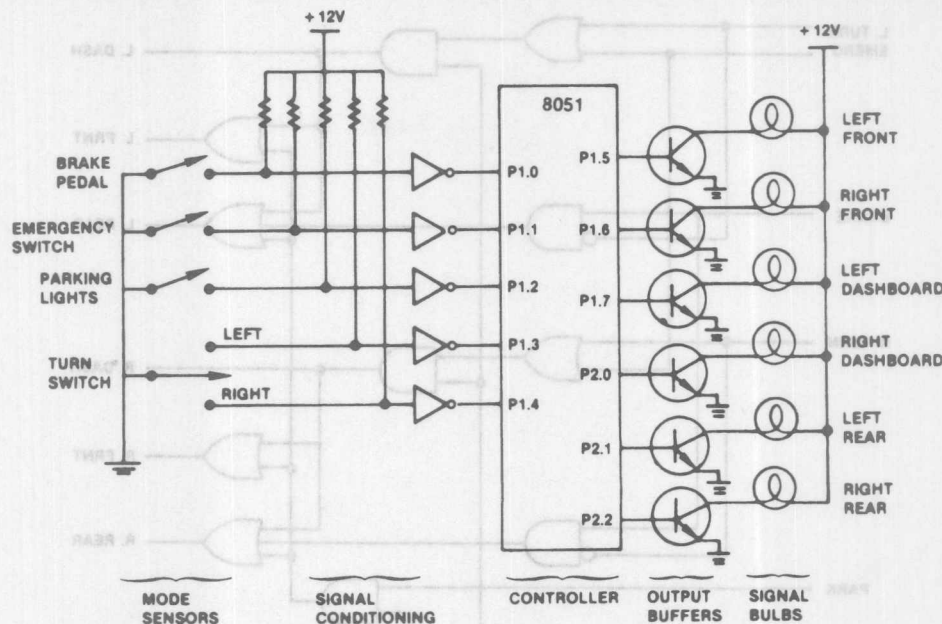


Figure 6-15. Microcomputer Turn-Signal Connections

Another key advantage of symbolic addressing appears further on in the design cycle. The locations of cable connectors, signal conditioning circuitry, voltage regulators, and heat sinks, etc., all affect PC board layout. It is quite likely that the somewhat arbitrary pin assignment defined early in the software design cycle will prove to be less than optimum; rearranging the I/O pin assignment could well allow a more compact module, or eliminate costly jumpers on a single-sided board. (These considerations apply especially to automotive and other cost-sensitive applications needing single-chip controllers.) Since other architectures use mask bytes or "clever" algorithms to isolate bits by rotating them into the carry, re-routing an input signal (from P1.1, for example, to P3.4) could require extensive modifications throughout the software.

The Boolean Processor's direct bit addressing makes such changes trivial. The number of the port containing the pin is irrelevant, and masks and complex program structures are not needed. Only the initial Boolean variable declarations need to be changed; ASM51 automatically adjusts all addresses and symbolic references to the reassigned variables. The user is assured that no additional debugging or software verification will be required.

```
;
; ...
; INTERRUPT RATE SUBDIVIDER
SUB_DIV DATA 20H
; HIGH-FREQUENCY OSCILLATOR BIT
HI_FREQ BIT SUB_DIV.0
; LOW-FREQUENCY OSCILLATOR BIT
LO_FREQ BIT SUB_DIV.7
;
; ORG 0000H
JMP INIT
;
; ORG 100H
; PUT TIMER 0 IN MODE 1
INIT: MOV TMOD,#0000001B
; INITIALIZE TIMER REGISTERS
MOV TLO,#0
MOV TH0,#16
; SUBDIVIDE INTERRUPT RATE BY 244
MOV SUB_DIV,#244
; ENABLE TIMER INTERRUPTS
SETB ET0
```

```
; GLOBALLY ENABLE ALL INTERRUPTS
    SETB    EA
; START TIMER
    SETB    TRO
; (CONTINUE WITH BACKGROUND PROGRAM)
;
; PUT TIMER 0 IN MODE 1
; INITIALIZE TIMER REGISTERS
```

```
; SUBDIVIDE INTERRUPT RATE BY 244
; ENABLE TIMER INTERRUPTS
; GLOBALLY ENABLE ALL INTERRUPTS
; START TIMER
```

Timer 0 (one of the two on-chip timer/counters) replaces the thermo-mechanical blinker relay in the dashboard controller. During system initialization, it is configured as a timer in mode 1 by setting the least significant bit of the timer mode register (TMOD). In this configuration the low-order byte (TL0) is incremented every machine cycle, overflowing and incrementing the high-order byte (TH0) every 256 μ s. Timer-interrupt 0 is enabled so that a hardware interrupt will occur each time TH0 overflows.

An 8-bit variable in the bit-addressable RAM array is needed to further subdivide the interrupts via software. The lowest-order bit of this counter toggles very fast to modulate the parking lights; bit 7 is "turned" to approximately 1 Hz for the turn- and emergency-indicator blinking rate.

Loading TH0 with -16 will cause an interrupt after 4,096 ms. The interrupt service routine reloads the high-order byte of timer 0 for the next interval, saves the CPU registers likely to be affected on the stack, and then decrements SUB_DIV. Loading SUB_DIV with 244 initially and each time it decrements to zero, will produce a 0.999 second period for the highest-order bit.

```
ORG    000BH    ; TIMER 0 SERVICE VECTOR
MOV     TH0,#-16
PUSH    PSW
PUSH    ACC
PUSH    B
DJNZ    SUB_DIV,T0SERV
MOV     SUB_DIV,#244
```

The code to sample inputs, performs calculations, and update outputs — the real essence of the signal-controller algorithm — may be performed either as part of the

interrupt-service routine or as part of a background-program loop. The only concern is that it must be executed at least several dozen times per second to prevent parking light flickering. We will assume the former case, and insert the code into the timer 0 service routine.

First, notice from the logic diagram (Figure 6-14) that the subterm (PARK · H_FREQ), asserted when the parking lights are to be on dimly, figures into four of the six output functions. Accordingly, we will first compute that term and save it in a temporary location named "DIM". The PSW contains two general purpose flags: F0, which corresponds to the 8048 flag of the same name, and PSW.1. Since the PSW has been saved and will be restored to its previous state after servicing the interrupt, we can use either bit for temporary storage.

```
DIM    BIT    PSW.1    ; DECLARE TEMP STORAGE FLAG
; ...
MOV     C,PARK    ; GATE PARKING LIGHT SWITCH
ANL     HI_FREQ    ; WITH HIGH FREQUENCY SIGNAL
MOV     DIM,C    ; AND SAVE IN TEMP VARIABLE.
```

This simple 3-line selection of code illustrates a remarkable point. The software indicates in very abstract terms exactly what function is being performed, independent of the hardware configuration. The fact that these three bits include an input pin, a bit within a program variable, and a software flag in the PSW is totally invisible to the programmer.

Now generate and output the dashboard left turn signal.

```
;
MOV     C,L_TURN    ; SET CARRY IF TURN
ORL     C,EMERG    ; OR EMERGENCY SELECTED.
ANL     C,LO_FREQ    ; GATE IN 1 HZ SIGNAL
MOV     L_DASH,C    ; AND OUTPUT TO DASHBOARD.
```

To generate the left-front turn signal, we only need to add the parking light function in F0. But notice that the function in the carry will also be needed for the rear signal. We can save effort later by saving its current state in F0.

```
;
MOV     F0,C    ; SAVE FUNCTION SO FAR.
ORL     C,DIM    ; ADD IN PARKING LIGHT FUNCTION
MOV     L_FRNT,C    ; AND OUTPUT TO TURN SIGNAL.
```

CHAPTER 6

8051 Family Boolean Processing Capabilities

Finally, the rear left-turn signal should also be on when the brake pedal is depressed, provided a left turn is not in progress.

```
MOV C,BRAKE ; GATE BRAKE PEDAL SWITCH
ANL C,L_TURN ; WITH TURN LEVER.
ORL C,F0 ; INCLUDE TEMP. VARIABLE
; FROM DASH
ORL C,DIM ; AND PARKING LIGHT FUNCTION
MOV L_REAR,C ; AND OUTPUT TO TURN SIGNAL
```

Now we have to go through a similar sequence for the right-hand equivalents to all the left-turn lights. This also gives us a chance to see how the code segments above look when combined.

```
MOV C,R_TURN ; SET CARRY IF TURN
ORL C,EMERG ; OR EMERGENCY SELECTED.
ANL C,LO_FREQ ; IF SO, GATE IN 1 HZ SIGNAL
MOV R_DASH,C ; AND OUTPUT TO DASHBOARD.
MOV F0,C ; SAVE FUNCTION SO FAR.
ORL C,DIM ; ADD IN PARKING LIGHT
; FUNCTION
MOV R_FRNT,C ; AND OUTPUT TO TURN SIGNAL.
MOV C,BRAKE ; GATE BRAKE PEDAL SWITCH
ANL C,R_TURN ; WITH TURN LEVER.
ORL C,F0 ; INCLUDE TEMP.VARIABLE FROM
; DASH
ORL C,DIM ; AND PARKING LIGHT FUNCTION
MOV R_REAR,C ; AND OUTPUT TO TURN SIGNAL.
```

The perceptive reader may notice that simply rearranging the steps could eliminate one instruction from each sequence.

Now that all six bulbs are in the proper states, we can return from the interrupt routine, and the program is finished. This code essentially needs to reverse the status saving steps at the beginning of the interrupt.

```
POP B ; RESTORE CPU REGISTERS.
POP ACC
POP PSW
RETI
```

Program Refinements. The luminescence of an incandescent light bulb filament is generally non-linear; the 50% duty cycle of HI_FREQ may not produce the desired intensity. If the application requires, duty cycles of 25%, 75%, etc., are easily achieved by ANDing and ORing in additional low-order bits of SUB_DIV. For example, 30 Hz signals of seven different duty cycles could be produced by considering bits 2-0 as shown in Table 6-6. The only software change required would be to the code which sets-up variable DIM:

```
MOV C,SUB_DIV.1 ; START WITH 50 PERCENT
ANL C,SUB_DIV.0 ; MASK DOWN TO 25
ORL C,SUB_DIV.2 ; AND BUILD BACK TO 62
; PERCENT
MOV DIM,C ; DUTY CYCLE FOR PARKING
; LIGHTS.
```

Table 6-6. Non-trivial Duty Cycles

Sub_Div Bits								Duty Cycles						
7	6	5	4	3	2	1	0	12.5%	25.0%	37.5%	50.0%	62.5%	75.0%	87.5%
X	X	X	X	X	0	0	0	Off	Off	Off	Off	Off	Off	Off
X	X	X	X	X	0	0	1	Off	Off	Off	Off	Off	Off	On
X	X	X	X	X	0	1	0	Off	Off	Off	Off	Off	On	On
X	X	X	X	X	0	1	1	Off	Off	Off	Off	On	On	On
X	X	X	X	X	1	0	0	Off	Off	Off	On	On	On	On
X	X	X	X	X	1	0	1	Off	Off	On	On	On	On	On
X	X	X	X	X	1	1	0	Off	On	On	On	On	On	On
X	X	X	X	X	1	1	1	On	On	On	On	On	On	On

Interconnections increase cost and decrease reliability. The simple buffered pin-per-function circuit in Figure 6-15 is insufficient when many outputs require higher-than-TTL drive levels. A lower-cost solution uses the 8051 serial port in the shift-register mode to augment I/O. In mode 0, writing a byte to the serial port data buffer (SBUF) causes the data to be output sequentially through the "RXD" pin while a burst of eight clock pulses is generated on the "TXD" pin. A shift register connected to these pins (Figure 6-16) will load the data byte as it is shifted out. A number of special peripheral driver circuits combining shift-register inputs with high drive level outputs are available.

Cascading multiple shift registers end-to-end will expand the number of outputs even further. The data rate in the I/O expansion mode is 1 Mb/s, or 8 μ s per byte. This is the mode which the serial port defaults to following a reset, so no initialization is required.

The software for this technique uses the B register as a "map" corresponding to the different output functions. The program manipulates these bits instead of the output pins. After all functions have been calculated, the B register is shifted by the serial port to the shift-register drive. The outputs may glitch as data is shifted through them; at 1 Mb/s, however, the results (blinking lights) will not be noticed. Many shift registers provide an "enable" bit to hold the output states while new data is being shifted in.

This is where the earlier decision to address bits symbolically throughout the program pays off. This major I/O restructuring is nearly as simple to implement as rearranging the input pins. Again, only the bit declarations need to be changed.

L_FRNT	BIT	B.0	; FRONT LEFT-TURN INDICATOR
R_FRNT	BIT	B.1	; FRONT RIGHT-TURN INDICATOR
L_DASH	BIT	B.2	; DASHBOARD LEFT-TURN INDICATOR
R_DASH	BIT	B.3	; DASHBOARD RIGHT-TURN INDICATOR
L_REAR	BIT	B.4	; REAR LEFT-TURN INDICATOR
R_REAR	BIT	B.5	; REAR RIGHT-TURN INDICATOR

The original program to compute the functions need not change. After computing the output variables, the control map is transmitted to the buffered shift register through the serial port:

```
MOV    SBUF,B ;LOAD BUFFER AND TRANSMIT
```

The Boolean Processor solution holds a number of advantages over older methods. Fewer switches are required. Each is simpler, requiring fewer poles and lower current contacts. The flasher relay is eliminated entirely. Only six filaments are driven, rather than ten. The wiring harness is, therefore, simpler and less expensive — one conductor for each of the six lamps and each of the five sensor switches. The fewer conductors use far fewer connectors. The whole system is more reliable.

And since the system is much simpler it would be feasible to implement redundancy and or fault detection on the four main turn indicators. Each could *still* be a standard double filament bulb, but with the filaments driven in parallel to tolerate single-element failures.

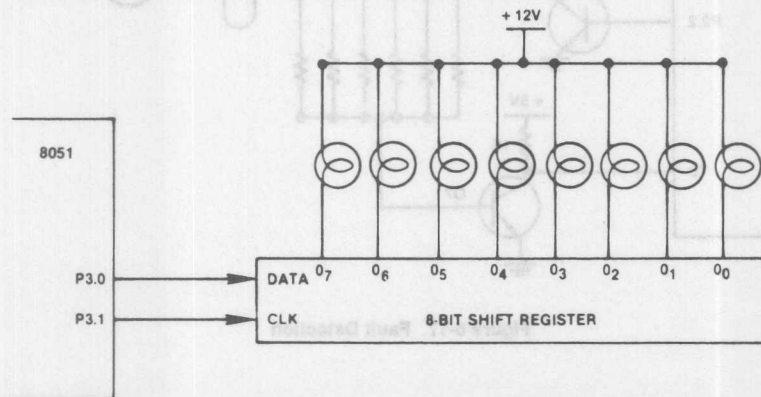


Figure 6-16. Output Expansion Using Serial Port

Even with redundancy, the lights will eventually fail. To handle this inescapable fact, current or voltage sensing circuits on each main drive wire can verify that each bulb and its high-current driver is functioning properly. Figure 6-17 shows one such circuit.

Assume all of the lights are turned on except one, i.e., all but one of the collectors are grounded. For the bulb that is turned off, if there is continuity from + 12 V through the bulb base and filament, the control wire, all connectors, and the PC boards traces; and if the transistor is indeed not shorted to ground, then the collector will be pulled to + 12 V. This turns on the base of Q7 through the

corresponding resistor, and grounds the input pin, verifying that the bulb circuit is operational. The continuity of each circuit can be checked by software in this way.

Now turn *all* the bulbs on, grounding all the collectors. Q7 should be turned off, and the Test pin (T0) should be high. However, a control wire shorted to + 12 V or an open-circuited drive transistor would leave one of the collectors at the higher voltage even now. This too would turn on Q7, indicating a different type of failure. Software could perform these checks once per second by executing the routine every time the software counter SUB_DIV is reloaded by the interrupt routine.

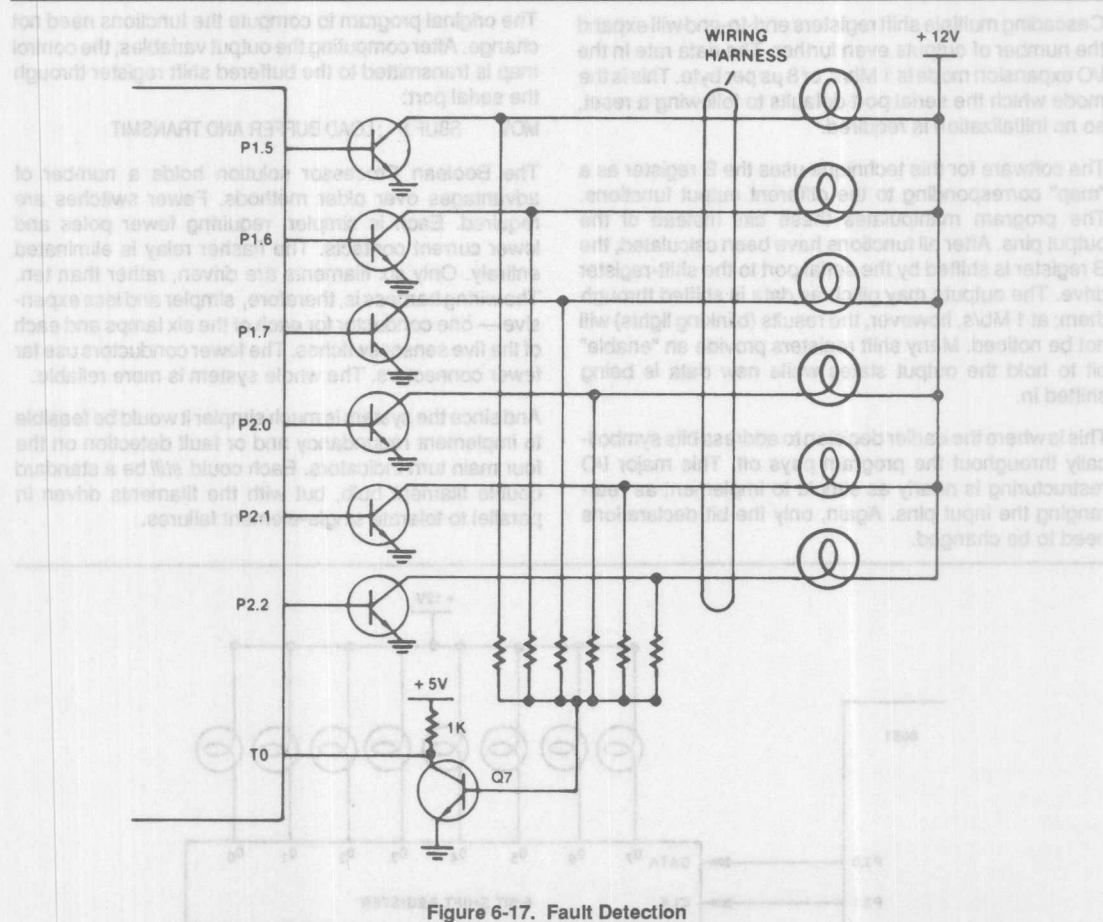


Figure 6-17. Fault Detection

```

DJNZ SUB_DIV,T0SERV
MOV SUB_DIV,#244 ; RELOAD COUNTER
ORL P2,#11100000B ; SET CONTROL OUTPUTS HIGH

ORL P2,#0000111B
CLR L_FRNT ; FLOAT DRIVE COLLECTOR
JB T0,FAULT ; T0 SHOULD BE PULLED LOW

SETB L_FRNT ; PULL COLLECTOR BACK DOWN

CLR L_DASH
JB T0,FAULT
SETB L_DASH
CLR L_REAR
JB T0,FAULT
SETB L_REAR
CLR R_FRNT
JB T0,FAULT
SETB R_FRNT
CLR R_DASH
JB T0,FAULT
SETB R_DASH
CLR R_REAR
JB T0,FAULT
SETB R_REAR
;
; WITH ALL COLLECTORS GROUNDED, T0 SHOULD BE HIGH
; IF SO, CONTINUE WITH INTERRUPT ROUTINE.
JB T0,T0SERV

FAULT: ; ELECTRICAL FAILURE
; PROCESSING ROUTINE

T0SERV: ; CONTINUE WITH INTERRUPT PROCESSING

```

The resulting code consists of 67 program statements, not counting declarations and comments, which assemble into 150 bytes of object code. Each pass through the service routine requires (coincidentally) 67 μ s, plus 32 μ s once per second for the electrical test. If executed every 4 ms as suggested, this software would typically reduce the throughput of the background program by less than 2%.

Once a microcomputer has been designed into a system, new features suddenly become virtually free. Software could make the emergency blinkers flash alternately or at a rate faster than the turn signals. Turn signals could override the emergency blinkers. Adding more bulbs would allow multiple tail light sequencing and syncopation.

Design Example #5 — Complex Control Functions

Finally, we'll mix byte and bit operations to extend the use of the 8051 into extremely complex applications.

Programmers can arbitrarily assign I/O pins to input and output functions only if the total does not exceed 32, which is insufficient for applications with a very large number of input variables. One way to expand the number of inputs is with a technique similar to multiplexed-keyboard scanning.

Figure 6-18 shows a block diagram for a moderately complex programmable industrial controller with the following characteristics:

- 64 input variable sensors;
- 12 output signals;
- Combinational and sequential logic computations;
- Remote operation with communications to a host processor via a high-speed full-duplex serial link;
- Two prioritized external interrupts;
- Internal real-time and time-of-day clocks.

While many microprocessors could be programmed to provide these capabilities with assorted peripheral support chips, an 8051 microcomputer needs *no* other integrated circuits!

The 64 input sensors are logically arranged as an 8 x 8 matrix. The pins of Port 1 sequentially enable each column of the sensor matrix; as each is enabled Port 0 reads in the state of each sensor in that column. An eight-byte block in bit-addressable RAM remembers the data as it is read in so that after each complete scan cycle there is an internal map of the current state of all sensors. Logic functions can then directly address the elements of the bit map.

The computer's serial port is configured as a nine-bit UART, transferring data at 17,000 bytes-per-second. The ninth bit may distinguish between address and data bytes.

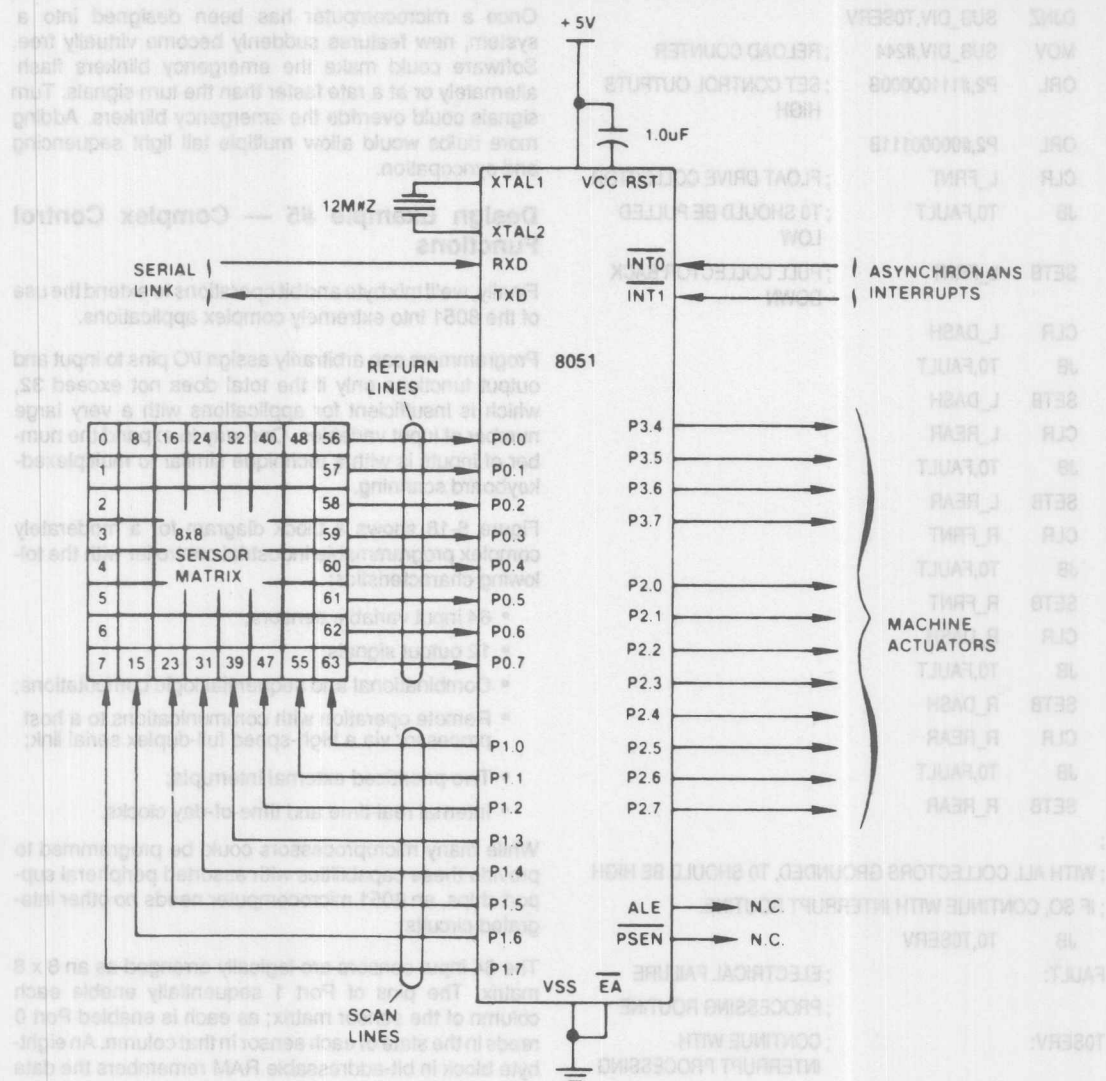


Figure 6-18. Block Diagram of 64-Input Machine Controller

The 8051 serial port can be configured to detect bytes with the address bit set, automatically ignoring all others. Pins INT0 and INT1 are interrupts configured respectively as high-priority, falling-edge triggered and low-priority, low-level triggered. The remaining 12 I/O pins output TTL-level control signals to 12 actuators.

There are several ways to implement the sensor matrix circuitry, all logically similar. Figure 6-19a shows one possibility. Each of the 64 sensors consists of a pair of simple switch contacts in series with a diode to permit multiple contact closures throughout the matrix.

The scan lines from Port 1 provide eight un-encoded active-high scan signals for enabling columns of the matrix. The return lines on rows where a contact is closed are pulled high and read as logic ones. Open return lines are pulled to ground by one of the 40 k Ω resistors and are read as zeros. The resistor values must be chosen to ensure all return lines are pulled above the 2.0 V logic threshold, even in the worst case, where all contacts in an enabled column are closed. Since P0 is provided open-collector outputs and high-impedance MOS inputs, its input loading may be considered negligible.

The circuits in Figures 6-19b and d are variations on this theme. When input signals must be electrically isolated from the computer circuitry as in noisy industrial environments, phototransistors can replace the switch diode pairs and provide optical isolation as in Figure 6-19b. Additional opto-isolators could also be used on the control output and special signal lines.

The other circuits assume that input signals are already at TTL levels. Figure 6-19c uses octal 3-state buffers enabled by active-low scan signals to gate eight signals onto Port 0. Port 0 is available for memory expansion or peripheral chip interfacing between sensor matrix scans. The 8-to-1 multiplexers in Figure 6-19d select one of eight inputs for each return line as determined by encoded address bits output on three pins of Port 1. Five more output pins are thus freed for more control functions. Each output can drive at least one standard TTL or up to 10 low-power TTL loads without additional buffering.

Going back to the original matrix circuit, Figure 6-20 shows the method used to scan the sensor matrix. Two complete bit maps are maintained in the bit-addressable

region of the RAM; one for the current state and one for the previous state read for each sensor. If the need arises, the program could then sense input transitions and/or debounce contact closures by comparing each bit with its earlier value.

The code in Example 6-3 implements the scanning algorithm for the circuits in Figure 6-19. Each column is enabled by setting a single bit in a field of zeroes. The bit maps are positive logic; ones represent contacts that are closed or isolators turned on.

Example 6-3.

```

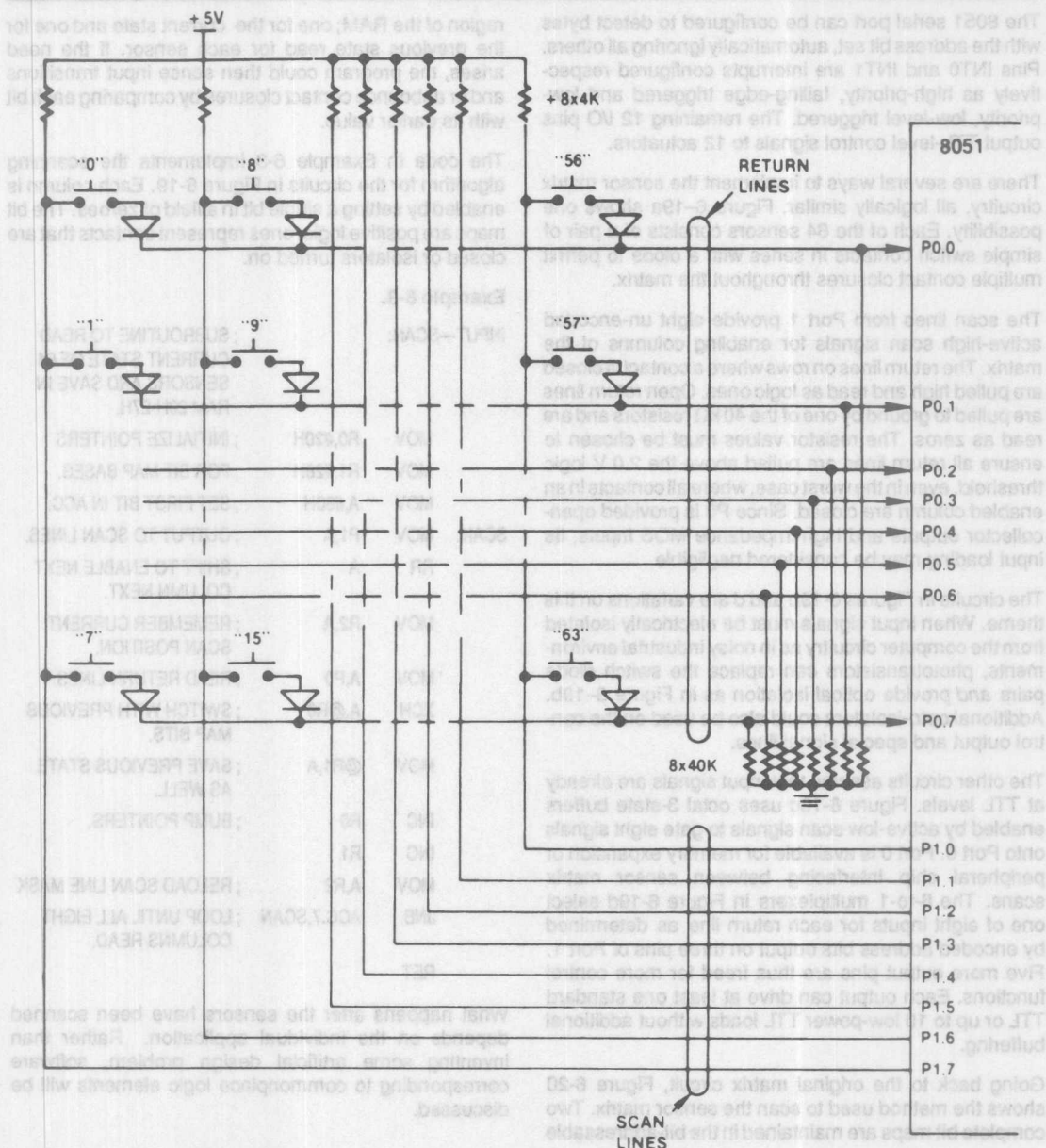
INPUT—SCAN:                ; SUBROUTINE TO READ
                              ; CURRENT STATE OF 64
                              ; SENSORS AND SAVE IN
                              ; RAM 20H-27H.

MOV R0,#20H                  ; INITIALIZE POINTERS
MOV R1,#28H                  ; FOR BIT MAP BASES.
MOV A,#80H                   ; SET FIRST BIT IN ACC.
SCAN: MOV P1,A               ; OUTPUT TO SCAN LINES.
RR A                         ; SHIFT TO ENABLE NEXT
                              ; COLUMN NEXT.
MOV R2,A                     ; REMEMBER CURRENT
                              ; SCAN POSITION.
MOV A,P0                     ; READ RETURN LINES.
XCH A,@R0                    ; SWITCH WITH PREVIOUS
                              ; MAP BITS.
MOV @R1,A                    ; SAVE PREVIOUS STATE
                              ; AS WELL.
INC R0                       ; BUMP POINTERS.
INC R1
MOV A,R2                      ; RELOAD SCAN LINE MASK
JNB ACC.7,SCAN               ; LOOP UNTIL ALL EIGHT
                              ; COLUMNS READ.

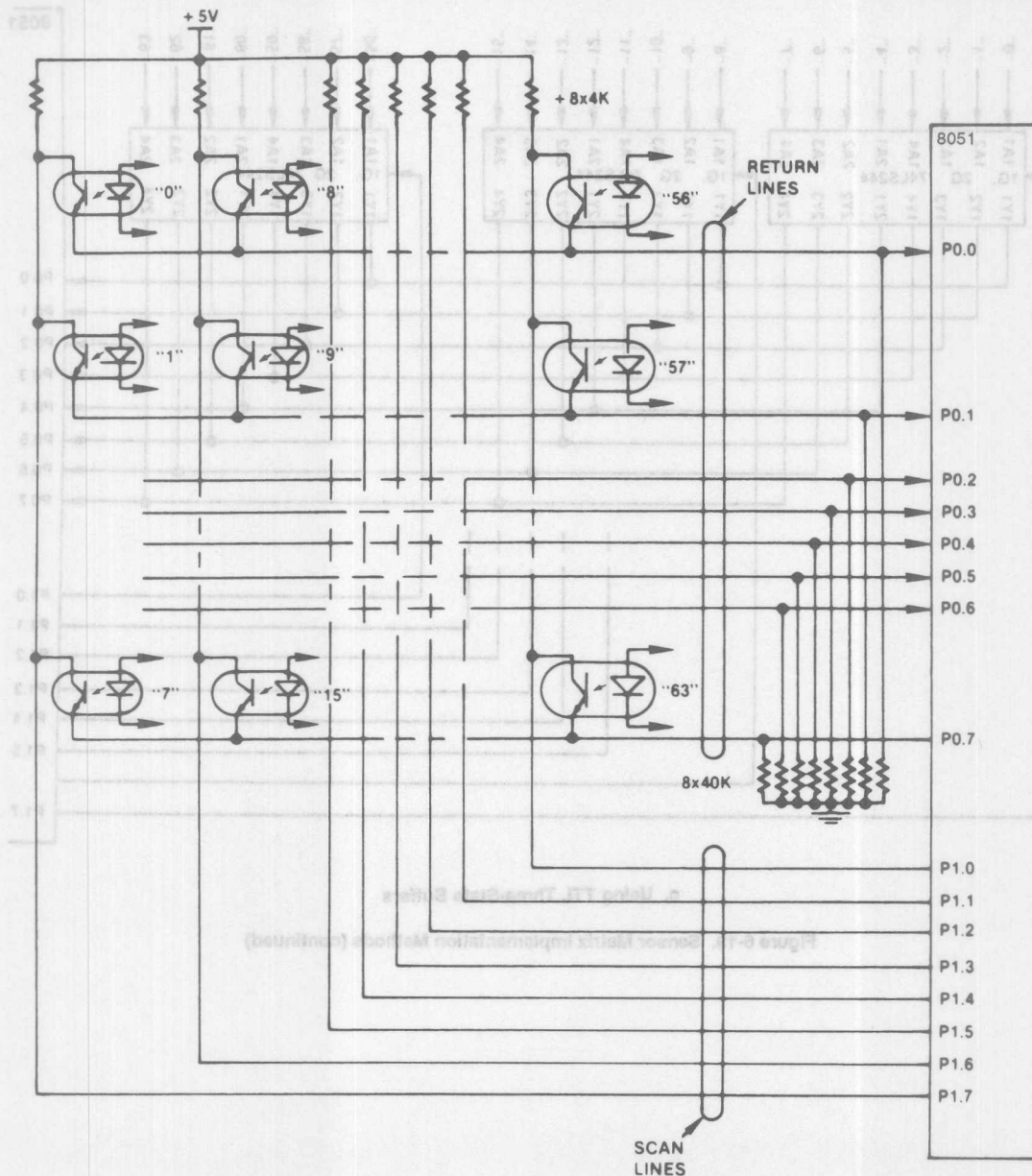
RET

```

What happens after the sensors have been scanned depends on the individual application. Rather than inventing some artificial design problem, software corresponding to commonplace logic elements will be discussed.

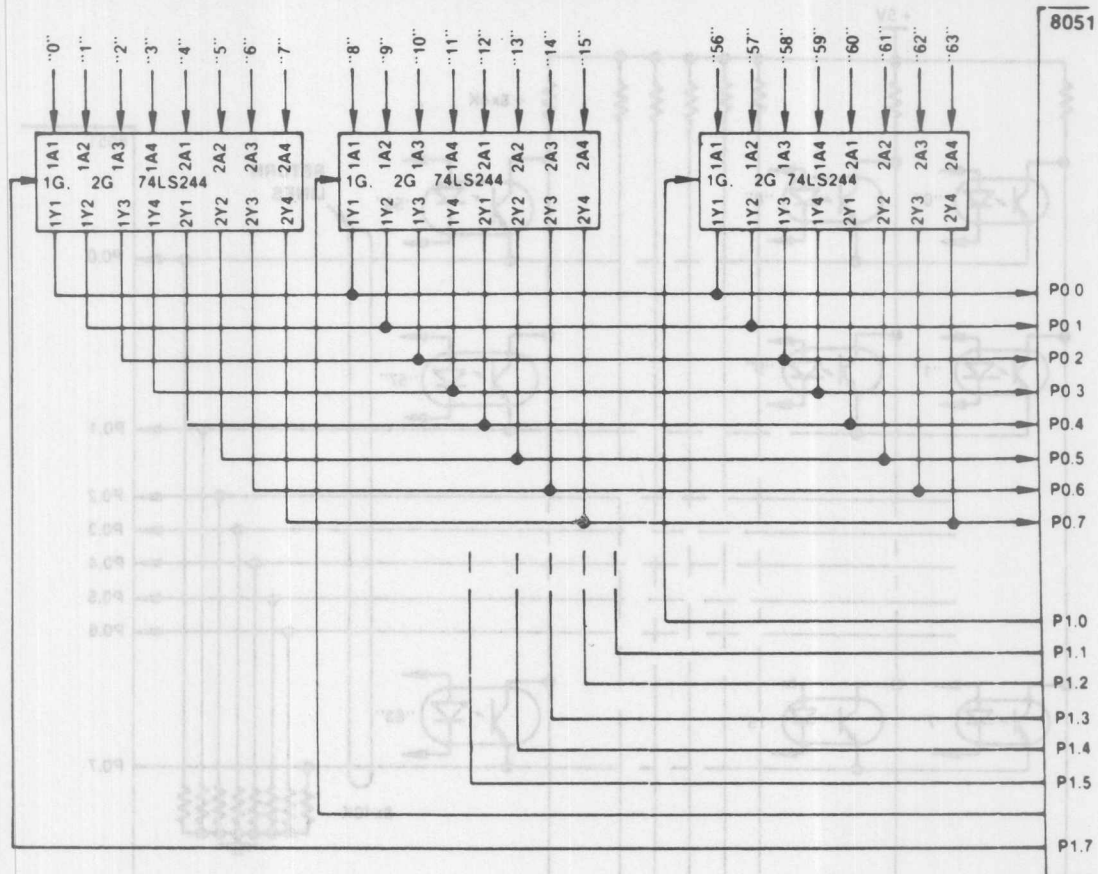


a. Using Switch Contact/Diode Matrix
Figure 6-19. Sensor Matrix Implementation Methods



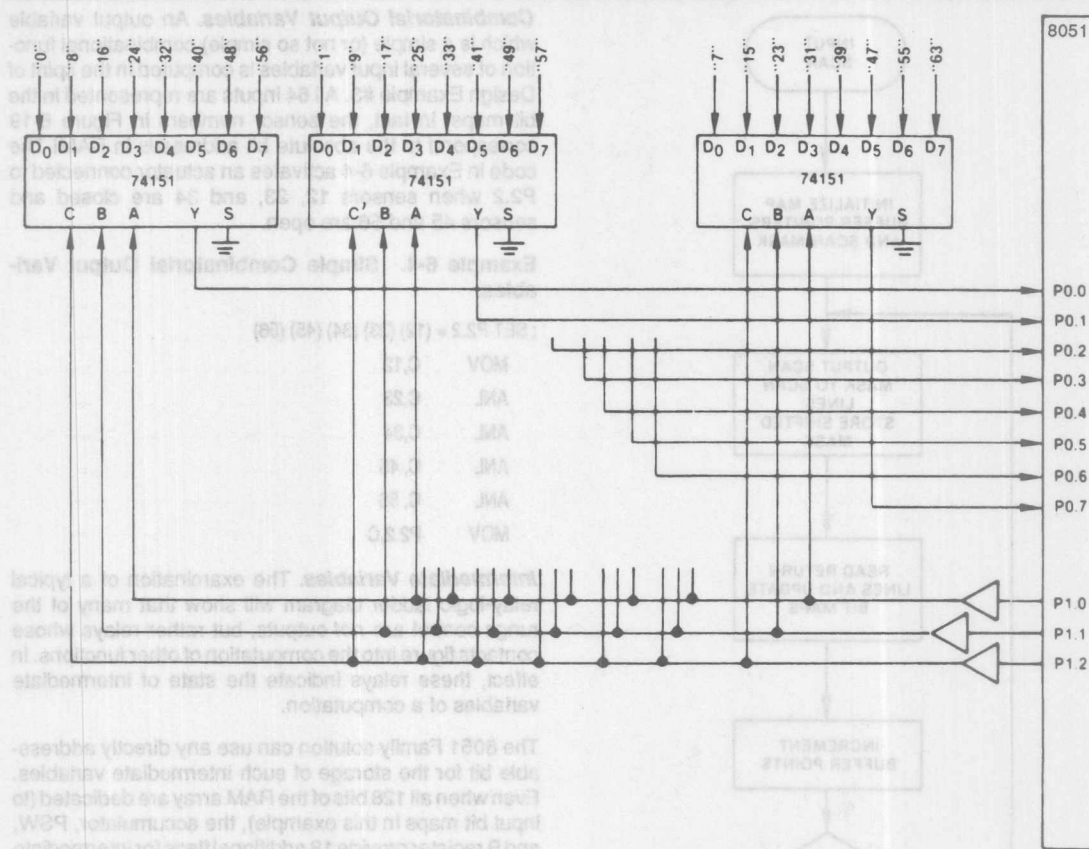
b. Using Optically-Coupled Isolators

Figure 6-19. Sensor Matrix Implementation Methods (continued)



c. Using TTL Three-State Buffers

Figure 6-19. Sensor Matrix Implementation Methods (continued)



d. Using TTL Data Selectors

Figure 6-19. Sensor Matrix Implementation Methods (continued)

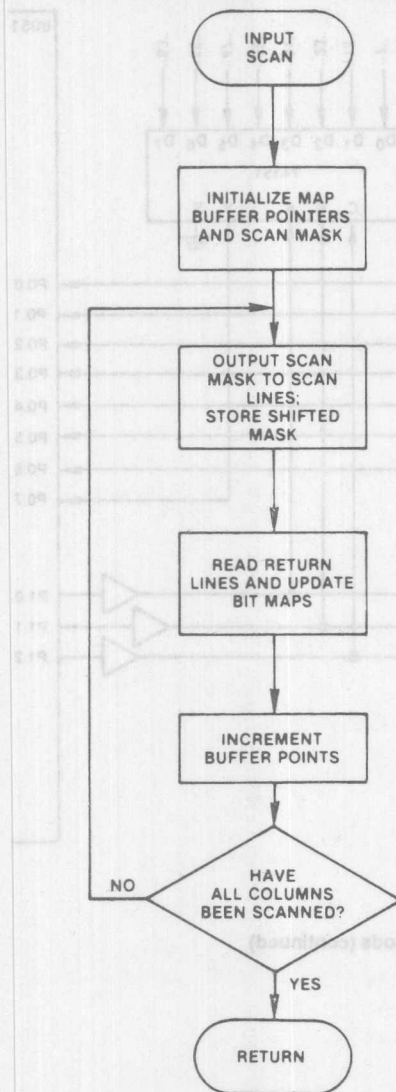


Figure 6-20. Flowchart for Reading in Sensor Matrix

Combinatorial Output Variables. An output variable which is a simple (or not so simple) combinational function of several input variables is computed in the spirit of Design Example #3. All 64 inputs are represented in the bit maps; in fact, the sensor numbers in Figure 6-19 correspond to the absolute bit addresses in RAM! The code in Example 6-4 activates an actuator connected to P2.2 when sensors 12, 23, and 34 are closed and sensors 45 and 56 are open.

Example 6-4. Simple Combinatorial Output Variables.

; SET P2.2 = (12) (23) (34) (45) (56)

```

MOV    C,12
ANL    C,23
ANL    C,34
ANL    C,45
ANL    C,56
MOV    P2.2,C
  
```

Intermediate Variables. The examination of a typical relay-logic ladder diagram will show that many of the rungs control are *not* outputs, but rather relays whose contacts figure into the computation of other functions. In effect, these relays indicate the state of intermediate variables of a computation.

The 8051 Family solution can use any directly addressable bit for the storage of such intermediate variables. Even when all 128 bits of the RAM array are dedicated (to input bit maps in this example), the accumulator, PSW, and B register provide 18 additional flags for intermediate variables.

For example, suppose switches 0 through 3 control a safety interlock system. Closing any of them should deactivate certain outputs. Figure 6-21 is a ladder diagram for this situation. The interlock function could be recomputed for every output affected, or it may be computed once and saved (as implied by the diagram). As the program proceeds this bit can qualify each output.

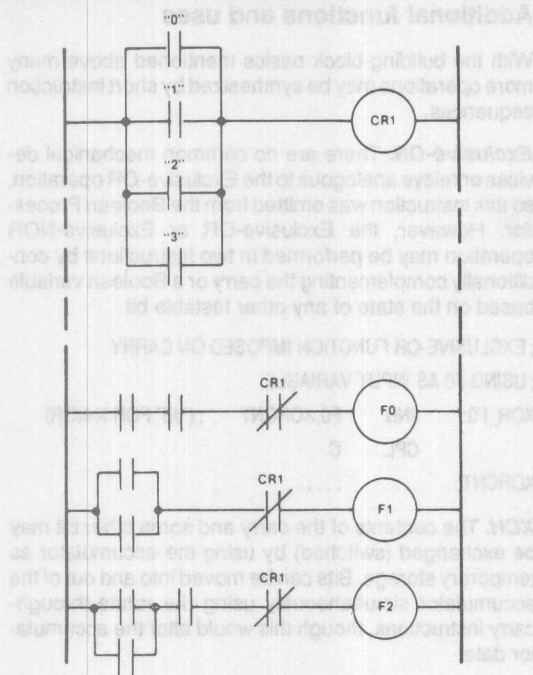


Figure 6-21. Ladder Diagram for Output Override Circuitry

Example 6-5. Incorporating Override signal into actuator outputs.

```
CALL    INPUT_SCAN
MOV     C,0
ORL     C,1
ORL     C,2
ORL     C,3
MOV     F0,C
;
; COMPUTE FUNCTION 0
;
ANL     C,F0
MOV     P1.0,C
;
;
; COMPUTE FUNCTION 1
;
ANL     C,F0
MOV     P1.1,C
;
;
; .....
```

```
; COMPUTE FUNCTION 2
;
ANL     C,F0
MOV     P1.2,C
;
; .....
```

Latching Relays. A latching relay can be forced into either the ON or OFF state by two corresponding input signals, where it will remain until forced onto the opposite state — analogous to a TTL Set-Reset flip-flop. The relay is used as an intermediate variable for other calculations. In the previous example, the emergency condition could be remembered and remain active until an “emergency cleared” button is pressed.

Any flag or addressable bit may represent a latching relay with a few lines of code (see Example 6-6).

Example 6-6. Simulating a latching relay.

```
; L_SET      SET FLAG 0 IF C = 1
L_SET:    ORL     C,F0
          MOV     F0,C
;
; L_RESET    RESET FLAG 0 IF C = 1
L_RESET:  CPS     C
          ANL     C,F0
          MOV     F0,C
```

Time Delay Relays. A time delay relay does not respond to an input signal until it has been present (or absent) for some predefined time. For example, a ballast or load resistor may be switched in series with a dc motor when it is first turned on, and shunted from the circuit after one second. This sort of time delay may be simulated by an interrupt routine driven by one of the two 8051 timer/counters. The procedure followed by the routine depends heavily on the details of the exact function needed; time-outs or time delays with resettable or non-resettable inputs are possible. If the interrupt routine is executed every 10 ms the code in Example 6-7 will clear an intermediate variable set by the background program after it has been active for 2 s.

Example 6-7. Code to clear USRFLG after a fixed time delay.

```
JNB     USR_FLG,NXTTST
DJNZ    DELAY_COUNT,NXTTST
CLR     USR_FLG
MOV     DELAY_COUNT,#200
NXTTST: .....
```

Serial Interface to Remote Processor. When it detects emergency conditions represented by certain input combinations (such as the earlier Emergency Override), the controller could shut down the machine immediately and/or alert the host processor via the serial port. Code bytes indicating the nature of the problem could be transmitted to a central computer. In fact, at 17,000 bytes-per-second, the entire contents of both bit maps could be sent to the host processor for further analysis in less than a millisecond! If the host decides that conditions warrant, it could alert other remote processors in the system that a problem exists and specify which shut-down sequence each should initiate.

Response Timing. One difference between relay and programmed industrial controllers (when each is considered as a "black box") is their respective reaction times to input changes. As reflected by a ladder diagram, relay systems contain a large number of "rungs" operating in parallel. A change in input conditions will begin propagating through the system immediately, possibly affecting the output state within milliseconds.

Software, on the other hand, operates sequentially. A change in input states will not be detected until the next time an input scan is performed, and will not affect the outputs until that section of the program is reached. For that reason the raw speed of computing the logical functions is of extreme importance.

Here the Boolean processor pays off. *Every instruction mentioned in this chapter* completes in 1 or 2 μ s at 12 MHz — the *minimum* instruction execution time for many other microcontrollers! A ladder diagram containing a hundred rungs, with an average of four contacts per rung can be replaced by approximately five hundred lines of software. A complete pass through the entire matrix scanning routine and all computation would require about a millisecond; less than the time it takes for most relays to change state.

A programmed controller which simulates each Boolean function with a subroutine would be less efficient by at least an order of magnitude. Extra software is needed for the simulation routines, and each step takes longer to execute for three reasons: several byte-wide logical instructions are executed per user program step (rather than one Boolean operation); most of those instructions take longer to execute with microprocessors performing multiple off-chip accesses; and calling and returning from the various subroutines requires overhead for stack operations.

In fact, the speed of the Boolean Processor solution is likely to be much faster than the system requires. The CPU might use the time left over to compute feedback parameters, collect and analyze execution statistics, or perform system diagnostics.

Additional functions and uses

With the building-block basics mentioned above many more operations may be synthesized by short instruction sequences.

Exclusive-OR. There are no common mechanical devices or relays analogous to the Exclusive-OR operation, so this instruction was omitted from the Boolean Processor. However, the Exclusive-OR or Exclusive-NOR operation may be performed in two instructions by conditionally complementing the carry or a Boolean variable based on the state of any other testable bit.

; EXCLUSIVE-OR FUNCTION IMPOSED ON CARRY

; USING F0 AS INPUT VARIABLE.

```
XOR_F0:  JNB    F0,XORCNT    ;("JB" FOR X-NOR)
          CPL    C
XORCNT:  ...      .....
```

XCH. The contents of the carry and some other bit may be exchanged (switched) by using the accumulator as temporary storage. Bits can be moved into and out of the accumulator simultaneously using the rotate-through-carry instructions, though this would alter the accumulator data.

; EXCHANGE CARRY WITH USRFLG

```
XCHBIT:  RLC    A
          MOV    C,USR_FLG
          RRC    A
          MOV    USR_FLG,C
          RLC    A
```

Extended Bit Addressing. The 8051 can directly address 144 general-purpose bits for all instructions in Figure 6-2b. Similar operations may be extended to any bit anywhere on the chip with some loss of efficiency.

The logical operations AND, OR, and Exclusive-OR are performed on byte variables using six different addressing modes, one of which lets the source be an immediate mask, and the destination any directly addressable byte. Any bit may thus be set, cleared, or complemented with a three-byte, two-cycle instruction if the mask has all bits but one set or cleared.

Byte variables, registers, and indirectly addressed RAM may be moved to a bit addressable register (usually the accumulator) in one instruction. Once transferred, the bits may be tested with a conditional jump, allowing any bit to be polled in 3 μ s — still much faster than most architectures — or used for logical calculations. This technique can also simulate additional bit addressing modes with byte operations.

Parity of bytes or bits. The parity of the current accumulators contents is always available in the PSW, from whence it may be moved to the carry and further processed. Error-correcting Hamming codes and similar applications require computing parity on groups of isolated bits. This can be done by conditionally complementing the carry flag based on those bits or by gathering the bits into the accumulator (as shown in the DES example) and then testing the parallel parity flag.

Multiple byte shift and CRC codes. Though the 8051 serial port can accommodate 8- or 9-bit data transmissions, some protocols involve much longer bit streams. The algorithms presented in Design Example 6-2 can be extended quite readily to 16 or more bits by using multi-byte input and output buffers.

Many mass data storage peripherals and serial communications protocols include Cyclic Redundancy (CRC) codes to verify data integrity. The function is generally computed serially by hardware using shift registers and Exclusive-OR gates, but it can be done with software. As each bit is received into the carry, appropriate bits in the multi-byte data buffers are conditionally complemented based on the incoming data bit. When finished, the CRC register contents may be checked for zero by ORing the two bytes in the accumulator.

SUMMARY

A unique facet of the 8051 Family microcomputer family design is the collection of features optimized for the one-bit operations so often desired in real-world, real-time control applications. Included are 17 special instructions, a Boolean accumulator, implicit and direct-addressing modes, program and mass-data storage, and many I/O options. These are the world's first single-chip microcomputers able to efficiently manipulate, operate on, and transfer either bytes or individual bits as data.

This chapter has detailed the information needed by a microcomputer system designer to make full use of these capabilities. Five design examples were used to contrast the solutions allowed by the 8051 and those required by previous architectures. Depending on the individual application, the 8051 solution will be easier to design; more reliable to implement, debug, and verify; use less program memory; and run up to an order-of-magnitude faster than the same function implemented on previous digital-computer architectures.

Combining byte- and bit-handling capabilities in a single microcomputer has a strong synergistic effect; the power of the result exceeds the power of byte- and bit-processors laboring individually. Virtually all user applications will benefit in some ways from this duality. Data-intensive applications will use bit addressing for test pin monitoring or program control flags; control applications will use byte manipulation for parallel I/O expansion or arithmetic calculations.



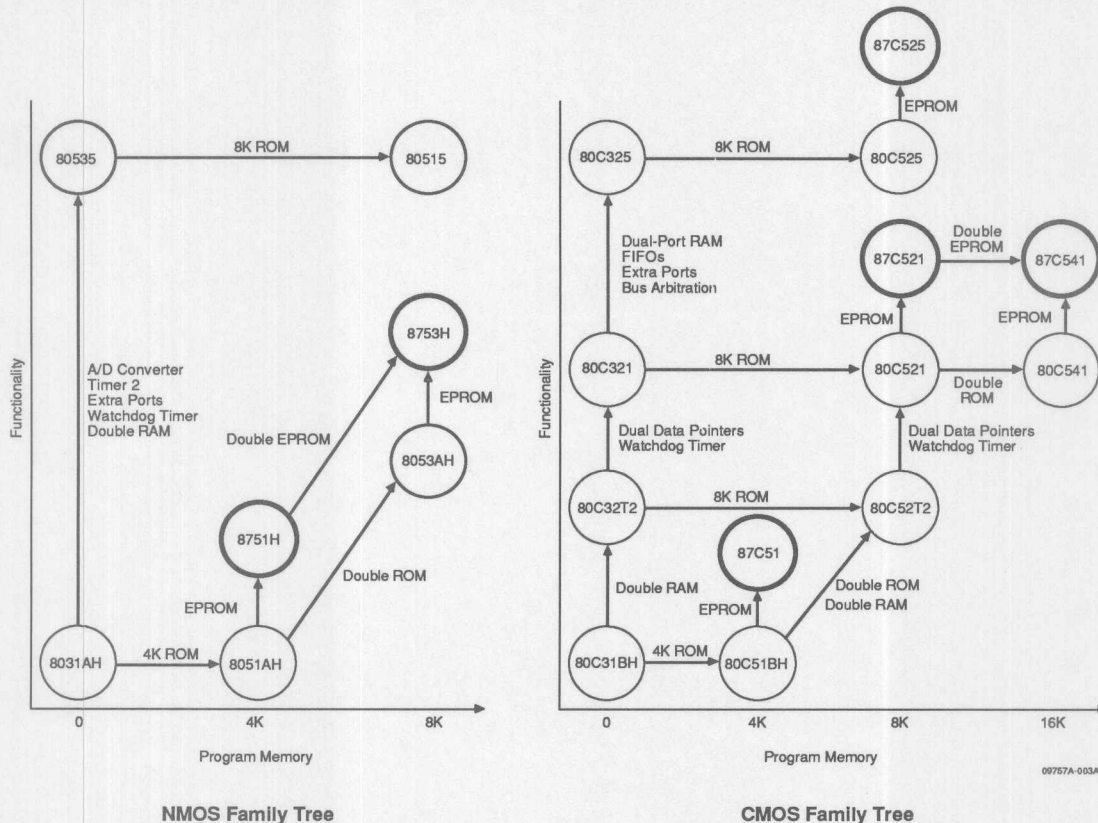
8051 Family Device Description

Section II contains the data sheets, device-specific application information, software routines, third-party development support, and package outlines.

The data sheets are divided into two groups: NMOS and CMOS. Each has a basic and enhanced device chapter. In general, devices are listed in order of increasing

functionality. EPROM data sheets follow the ROM data sheets with which they are associated.

Application information and software routines immediately follow the data sheets for which they are most closely intended, although they will also be of use with data sheets of more enhanced devices.



CHAPTER 7

Basic NMOS Devices

7-1

8031AH/8051AH/8053AH(data sheet)

7-1

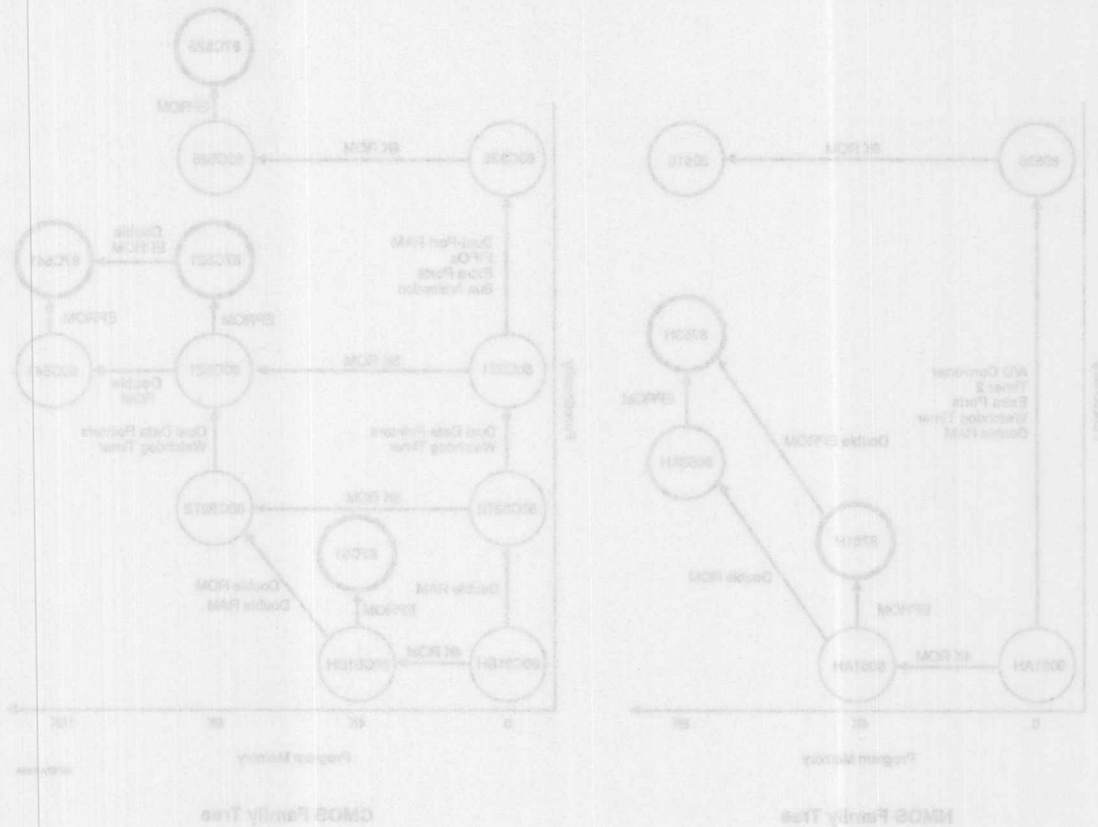
8751H/8753H (data sheet)

7-21

Single Chip Microcontroller with 8K Bytes of EPROM

Offers Important Design Advantages

7-37



8031AH/8051AH/8053AH



Single-Chip 8-Bit Microcontroller

DISTINCTIVE CHARACTERISTICS

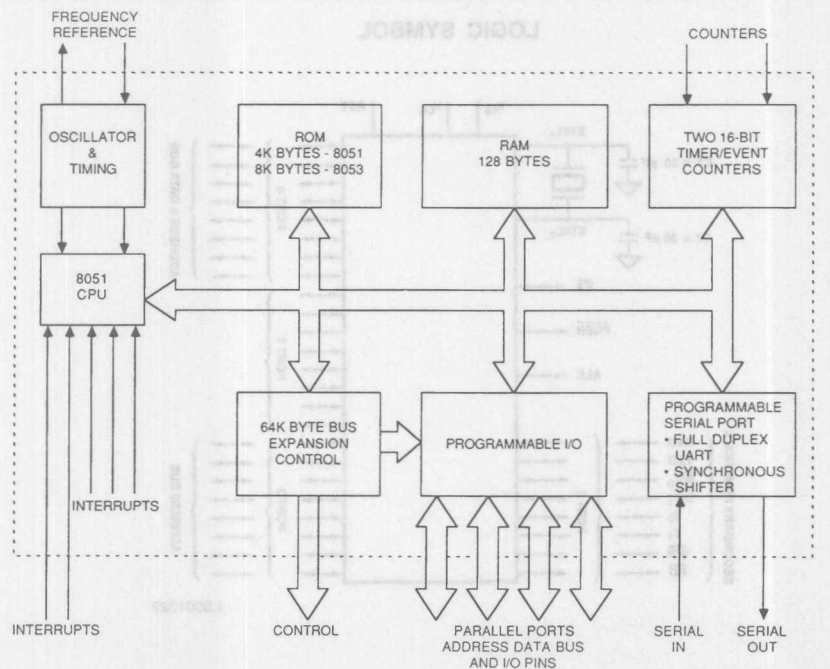
- 4K x 8 ROM (8051 only)
- 8K x 8 ROM (8053 only)
- 128 x 8 RAM
- Four 8-bit ports, 32 I/O lines
- Two 16-bit timer/event counters
- 64K addressable Program Memory
- All versions are pin-compatible
- Boolean processor
- Programmable Serial Port
- Five interrupt sources/two priority levels
- On-chip Oscillator/Clock Circuit
- 64K addressable Data Memory

GENERAL DESCRIPTION

The 8051 Family is optimized for control applications. Byte processing and numerical operations on small data structures are facilitated by a variety of fast addressing modes for accessing the internal RAM. The instruction set provides a convenient menu of 8-bit arithmetic instructions, including multiply and divide instructions. Extensive on-chip support is provided for 1-bit variables as a separate data

type. This allows direct bit manipulation and testing in control and logic systems that require Boolean processing. Efficient use of program memory results from an instruction set consisting of 44% 1-byte, 41% 2-byte, and 15% 3-byte instructions. With a 12 MHz crystal, 58% of the instructions execute in 1 μ s, 40% in 2 μ s, and multiply and divide require only 4 μ s.

BLOCK DIAGRAM



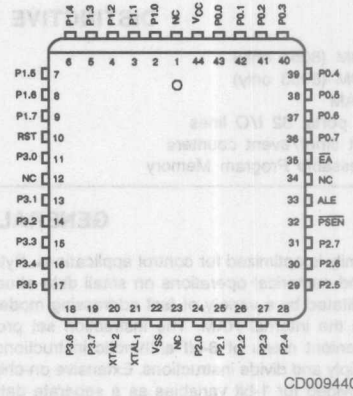
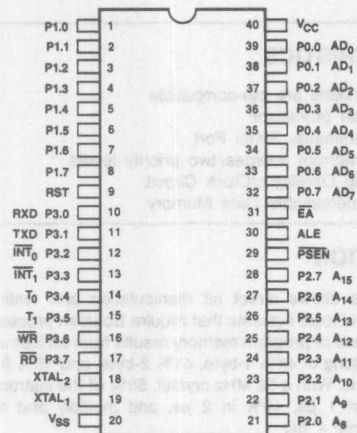
BD007260

CONNECTION DIAGRAMS

Top View

DIPS

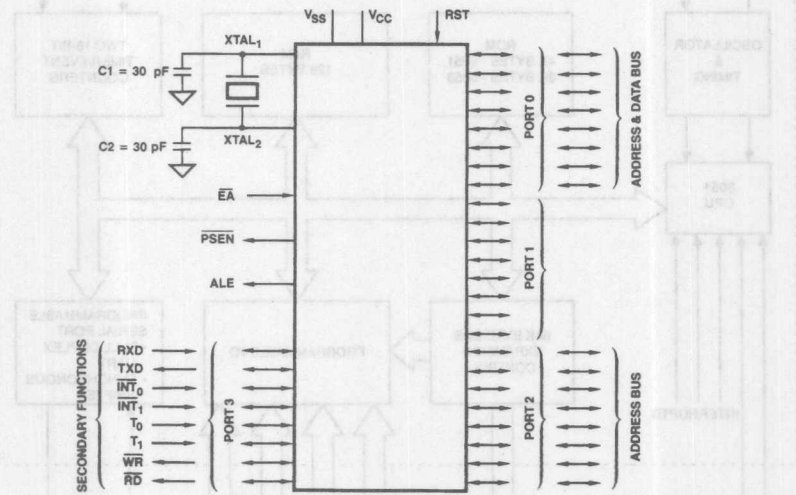
PLCC



CD005551

CD009440

LOGIC SYMBOL



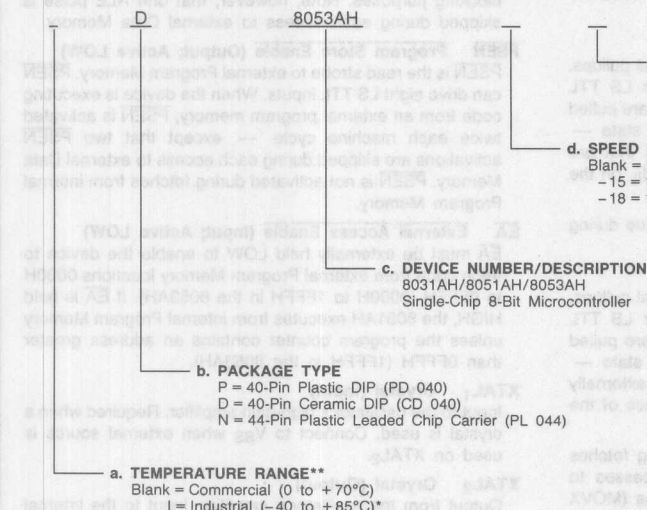
LS001322

ORDERING INFORMATION

Commodity Products

AMD commodity products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:

- Temperature Range
- Package Type
- Device Number
- Speed Option
- Optional Processing



Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released valid combinations, and to obtain additional data on AMD's standard military grade products.

*Available only for the 8031AH at time of printing.

**This device is also available in Military temperature range. See MOS Microprocessors and Peripherals Military Handbook (Order # 09275A/0) for electrical performance characteristics.

Valid Combinations	
P, D, N	8031AH-18
	8031AH-15
	8031AH
	8051AH
ID	8053AH
	8031AHB

PIN DESCRIPTION

Port 0 (Bidirectional, Open Drain)

Port 0 is an open-drain I/O port. As an Output Port, each pin can sink eight LS TTL inputs. Port 0 pins that have "1"s written to them float, and in that state can be used as high-impedance inputs.

Port 0 is also the multiplexed LOW-order address and data bus during accesses to external Program and Data Memory. In this application it uses strong internal pullups when emitting "1"s. Port 0 also outputs the code bytes during program verification in the 8051AH and 8053AH. External pullups are required during program verification.

Port 1 (Bidirectional)

Port 1 is an 8-bit bidirectional I/O port with internal pullups. The Port 1 output buffers can sink/source four LS TTL inputs. Port 1 pins that have "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 1 pins that are externally being pulled LOW will source current (I_{IL} on the data sheet) because of the internal pullups.

Port 1 also receives the LOW-order address bytes during program verification.

Port 2 (Bidirectional)

Port 2 is an 8-bit bidirectional I/O port with internal pullups. The Port 2 output buffers can sink/source four LS TTL inputs. Port 2 pins that have "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 2 pins externally being pulled LOW will source current (I_{IL}) because of the internal pullups.

Port 2 emits the HIGH-order address byte during fetches from external Program Memory and during accesses to external Data Memory that use 16-bit addresses (MOVX @DPTR). In this application it uses strong internal pullups when emitting "1"s. During accesses to external Data Memory that use 8-bit addresses (MOVX @Ri), Port 2 emits the contents of the P2 Special Function register.

Port 2 also receives the HIGH-order address bits during ROM verification.

Port 3 (Bidirectional)

Port 3 is an 8-bit bidirectional I/O port with internal pullups. The Port 3 output buffers can sink/source four LS TTL inputs. Port 3 pins having "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 3 pins externally being pulled LOW will source current (I_{IL}) because of pullups.

Port 3 also serves the functions of various special features as listed below:

Port Pin	Alternate Function
P3.0	RxD (Serial Input Port)
P3.1	TxD (Serial Output Port)
P3.2	$\overline{INT_0}$ (External Interrupt 0)
P3.3	$\overline{INT_1}$ (External Interrupt 1)
P3.4	T ₀ (Timer 0 External Input)
P3.5	T ₁ (Timer 1 External Input)
P3.6	\overline{WR} (External Data Memory Write Strobe)
P3.7	\overline{RD} (External Data Memory Read Strobe)

RST Reset (Input; Active HIGH)

A HIGH on this pin — for two machine cycles while the oscillator is running — resets the device.

ALE Address Latch Enable (Output; Active HIGH)

Address Latch Enable output pulse for latching the LOW byte of the address during accesses to external memory. ALE can drive eight LS TTL inputs.

In normal operation ALE is emitted at a constant rate of 1/6 the oscillator frequency, allowing use for external-timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external Data Memory.

PSEN Program Store Enable (Output; Active LOW)

PSEN is the read strobe to external Program Memory. PSEN can drive eight LS TTL inputs. When the device is executing code from an external program memory, PSEN is activated twice each machine cycle — except that two PSEN activations are skipped during each access to external Data Memory. PSEN is not activated during fetches from internal Program Memory.

EA External Access Enable (Input; Active LOW)

EA must be externally held LOW to enable the device to fetch code from external Program Memory locations 0000H to 0FFFFH (0000H to 1FFFFH in the 8053AH). If EA is held HIGH, the 8051AH executes from internal Program Memory unless the program counter contains an address greater than 0FFFFH (1FFFFH in the 8053AH).

XTAL₁ Crystal (Input)

Input to the oscillator's high-gain amplifier. Required when a crystal is used. Connect to V_{SS} when external source is used on XTAL₂.

XTAL₂ Crystal (Output)

Output from the oscillator's amplifier. Input to the internal timing circuitry. A crystal or external source can be used.

VCC Power Supply

VSS Circuit Ground

FUNCTIONAL DESCRIPTION

The term "8051" shall be used to refer collectively to the 8051AH, 8031AH, and 8053AH.

8051 CPU Architecture

The 8051 CPU manipulates operands in three memory spaces. These are the 64K-byte Program Memory, 64K-byte External Data Memory and 256-byte Internal Data Memory. Of the 64K bytes of Program Memory space, the lower 4K bytes on the 8051AH (addr. 0000H to 0FFFH) and the lower 8K bytes of the 8053AH (addr. 0000H to 1FFFH) may reside on-chip. The Internal Data Memory address space is further divided into the 128-byte Internal Data RAM and 128-byte Special Function Register (SFR) address spaces shown in Figure 1.

Four Register Banks (each with eight registers), 128 addressable bits and the stack reside in the Internal Data RAM. The stack depth is limited only by the available Internal Data RAM and its location is determined by the 8-bit stack pointer. All registers except the four 8-Register Banks reside in the Special Function Register address space. These memory mapped registers include arithmetic registers, pointers, I/O ports, interrupt system registers, timers, and a serial port. Ninety-two bit locations in the SFR address space are addressable as bits. The 8051 contains 128 bytes of Internal Data RAM and 20 SFRs.

The 8051 provides a non-paged Program Memory address space to accommodate relocatable code. Conditional branches are performed relative to the Program Counter. The base-register-plus-index register-indirect jump permits branching

relative to a 16-bit base register with an offset provided by an 8-bit index register. Sixteen-bit jumps and calls permit branching to any location in the contiguous 64K Program Memory address space.

The 8051 has five methods for addressing source operands: Register, Direct, Register-Indirect, Immediate, and Base-Register-plus-Index-Register-Indirect Addressing. The first three methods can be used for addressing destination operands. Most instructions have a "destination, source" field that specifies the data type, addressing methods, and operands involved. For operations other than moves, the destination operand is also a source operand.

Registers in the four 8-Register Banks can be accessed through Register, Direct, or Register-Indirect Addressing; the 128 bytes of Internal Data RAM through Direct or Register-Indirect Addressing; and the Special Function Registers through Direct Addressing. External Data Memory is accessed through Register-Indirect Addressing. Look-Up-Tables resident in Program Memory can be accessed through Base-Register-plus-Index-Register-Indirect Addressing.

The 8051 is classified as an 8-bit machine since the internal ROM, RAM, Special Function Registers, Arithmetic Logic Unit, and external data bus are each 8-bits wide. The 8051 performs operations on bit, nibble, byte, and double-byte data types.

The 8051 has extensive facilities for byte transfer, logic, and integer arithmetic operations. It excels at bit handling since data transfer, logic, and conditional branch operations can be performed directly on Boolean variables.

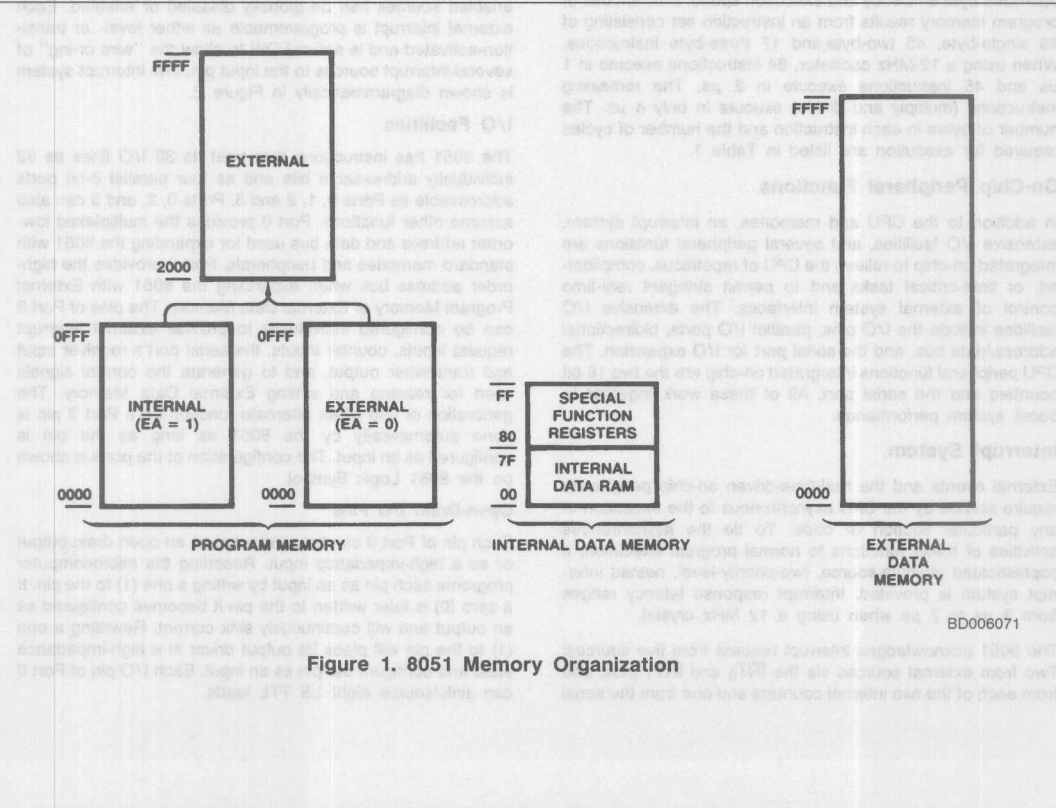


Figure 1. 8051 Memory Organization

Special Function Register Map

Addr (Hex)	Symbol	Name	Default Power-On Reset
80 *	P0	Port 0	11111111
81	SP	Stack Pointer	00000111
82	DPL	Data Pointer Low	00000000
83	DPH	Data Pointer High	00000000
87	PCON	Power Control	0XXX0000
88 *	TCON	Timer/Counter Control	00000000
89	TMOD	Timer/Counter Mode Control	00000000
8A	TLO	Timer/Counter 0 Low Byte	00000000
8B	TL1	Timer/Counter 1 Low Byte	00000000
8C	TH0	Timer/Counter 0 High Byte	00000000
8D	TH1	Timer/Counter 1 High Byte	00000000
90 *	P1	Port 1	11111111
98 *	SCON	Serial Control	00000000
99	SBUF	Serial Data Buffer	Indeterminate
A0 *	P2	Port 2	11111111
A8 *	IE	Interrupt Enable Control	0XX00000
B0 *	P3	Port 3	11111111
B8 *	IP	Interrupt Priority Control	XXX00000
D0 *	PSW	Program Status Word	00000000
E0 *	ACC	Accumulator	00000000
F0 *	B	B Register	00000000

* Bit Addressable

8051 Instruction Set

The 8051AH, 8031AH, and 8053AH share the same instruction set. It allows expansion of on-chip CPU peripherals and optimizes byte efficiency and execution speed. Efficient use of program memory results from an instruction set consisting of 49 single-byte, 45 two-byte, and 17 three-byte instructions. When using a 12-MHz oscillator, 64 instructions execute in 1 μ s and 45 instructions execute in 2 μ s. The remaining instructions (multiply and divide) execute in only 4 μ s. The number of bytes in each instruction and the number of cycles required for execution are listed in Table 1.

On-Chip Peripheral Functions

In addition to the CPU and memories, an interrupt system, extensive I/O facilities, and several peripheral functions are integrated on-chip to relieve the CPU of repetitious, complicated, or time-critical tasks and to permit stringent real-time control of external system interfaces. The extensive I/O facilities include the I/O pins, parallel I/O ports, bidirectional address/data bus, and the serial port for I/O expansion. The CPU peripheral functions integrated on-chip are the two 16-bit counters and the serial port. All of these work together to boost system performance.

Interrupt System

External events and the real-time-driven on-chip peripherals require service by the CPU asynchronous to the execution of any particular section of code. To tie the asynchronous activities of these functions to normal program execution, a sophisticated multiple-source, two-priority-level, nested interrupt system is provided. Interrupt response latency ranges from 3 μ s to 7 μ s when using a 12 MHz crystal.

The 8051 acknowledges interrupt request from five sources: Two from external sources via the INT_0 and INT_1 pins, one from each of the two internal counters and one from the serial

I/O port. Each interrupt vectors to a separate location in Program Memory for its service program. Each of the five sources can be assigned to either of two priority levels and can be independently enabled and disabled. Additionally all enabled sources can be globally disabled or enabled. Each external interrupt is programmable as either level- or transition-activated and is active-LOW to allow the "wire-or-ing" of several interrupt sources to the input pin. The interrupt system is shown diagrammatically in Figure 2.

I/O Facilities

The 8051 has instructions that treat its 32 I/O lines as 32 individually addressable bits and as four parallel 8-bit ports addressable as Ports 0, 1, 2 and 3. Ports 0, 2, and 3 can also assume other functions. Port 0 provides the multiplexed low-order address and data bus used for expanding the 8051 with standard memories and peripherals. Port 2 provides the high-order address bus when expanding the 8051 with External Program Memory or External Data Memory. The pins of Port 3 can be configured individually to provide external interrupt request inputs, counter inputs, the serial port's receiver input and transmitter output, and to generate the control signals used for reading and writing External Data Memory. The generation or use of an alternate function on a Port 3 pin is done automatically by the 8051 as long as the pin is configured as an input. The configuration of the ports is shown on the 8051 Logic Symbol.

Open-Drain I/O Pins

Each pin of Port 0 can be configured as an open drain output or as a high-impedance input. Resetting the microcomputer programs each pin as an input by writing a one (1) to the pin. If a zero (0) is later written to the pin it becomes configured as an output and will continuously sink current. Rewriting a one (1) to the pin will place its output driver in a high-impedance state and configure the pin as an input. Each I/O pin of Port 0 can sink/source eight LS TTL loads.

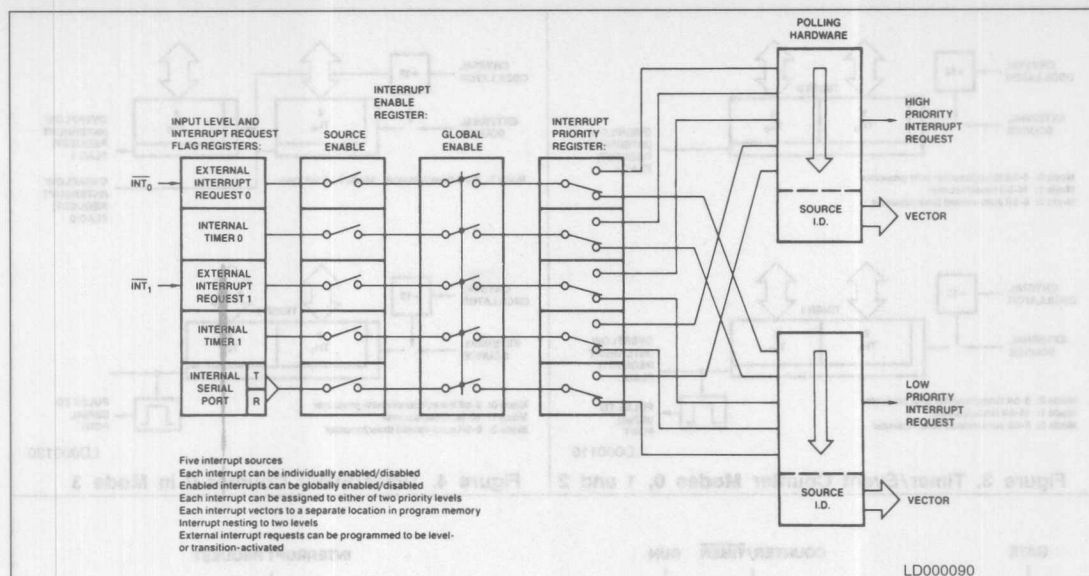


Figure 2. 8051 Interrupt System

Quasi-Bidirectional I/O Pins

Ports 1, 2 and 3 are quasi-bidirectional buffers. Resetting the microcomputer programs each pin as an input by writing a one (1) to the pin. If a zero (0) is later written to the pin it becomes configured as an output and will continuously sink current. Any pin that is configured as an output will be reconfigured as an input when a one (1) is written to the pin. Simultaneous to this reconfiguration, the output driver of the quasi-bidirectional port will source current for two oscillator periods. Since current is sourced only when a bit previously written to a zero (0) is updated to a one (1), a pin programmed as an input will not source current into the TTL gate that is driving it if the pin is later written with another one (1). Since the quasi-bidirectional output driver sources current for only two oscillator periods, an internal pull-up resistor of approximately 20 to 40 k Ω is provided to hold the external driver's loading at a TTL HIGH level. Ports 1, 2, and 3 can sink/source four LS TTL loads.

Microprocessor Bus

When accessing external memory the HIGH-order address is emitted on Port 2 and the LOW-order address on Port 0. The ALE signal is provided for strobing the address into an external latch. The program store enable (PSEN) signal is provided for enabling an external memory device to Port 0 during a read from the Program Memory address space. When the MOVX instruction is executed, Port 3 automatically generates the read (\overline{RD}) signal for enabling an External Data Memory device to Port 0 or generates the write (\overline{WR}) signal for strobing the external memory device with the data emitted by Port 0. Port 0 emits the address and data to the external memory through a push/pull driver that can sink/source eight LS TTL loads. At the end of the read/write bus cycle, Port 0 is automatically reprogrammed to its high-impedance state and Port 2 is returned to the state it had prior to the bus cycle. The 8053AH generates the address, data, and control signals needed by memory and I/O devices in a manner that minimizes the requirements placed on external program and data memories.

Timer Event Counters

The 8051 contains two 16-bit counters for measuring time intervals and pulse widths, for counting events, as well as for generating precise, periodic interrupt requests. Each can be programmed independently to one of the following three modes:

Mode 0 – similar to an 8048 8-bit timer or counter with divide by 32 prescaler.

Mode 1 – 16-bit time-interval or event counter.

Mode 2 – 8-bit time-interval or event counter with automatic reload upon overflow.

Additionally, counter 0 can be programmed to a mode that divides it into one 8-bit time-interval or event counter and one 8-bit time-interval counter (Mode 3). When counter 0 is in Mode 3, counter 1 can be programmed to any of the three aforementioned modes, although it cannot set an interrupt request flag or generate an interrupt. This mode is useful because counter 1's overflow can be used to pulse the serial port's transmission-rate generator. Along with their multiple operating modes and 16-bit precision, the counters can also handle very high input frequencies. These range from 0.1 MHz to 1.0 MHz (from 1.2 MHz to 12 MHz crystal) when programmed to increment once every machine cycle and from 0 Hz to an upper limit of 50 kHz to 0.5 MHz (for 1.2 MHz to 12 MHz crystal) when programmed for external inputs. Both internal and external inputs can be gated to the counter by a second external source for directly measuring pulse widths.

The counters are started and stopped under software control. Each counter sets its interrupt request flag when it overflows from all ones to all zeroes (or auto-reload value). The operating modes and input sources are summarized in Figures 3 and 4. The effects of the configuration flags and the status flags are shown in Figures 5 and 6.

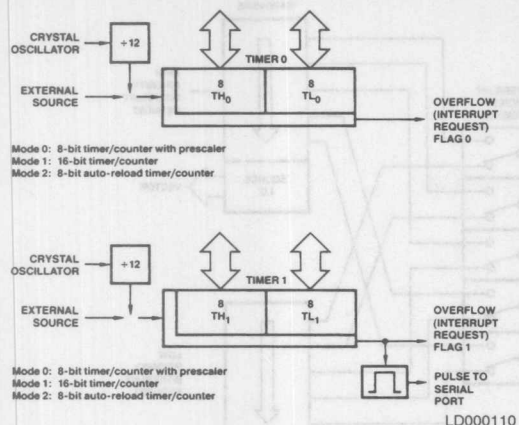


Figure 3. Timer/Event Counter Modes 0, 1 and 2

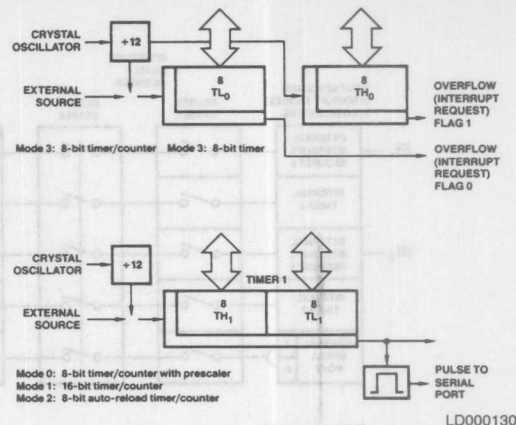


Figure 4. Timer/Event Counter 0 in Mode 3

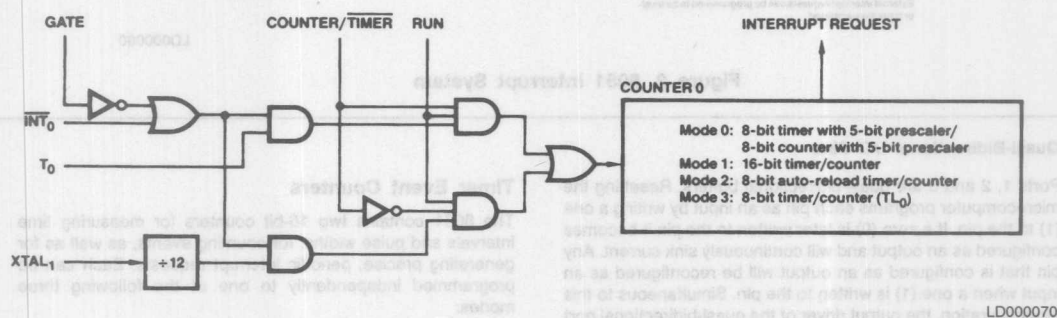


Figure 5. Timer/Counter 0 Control and Status Flag Circuitry

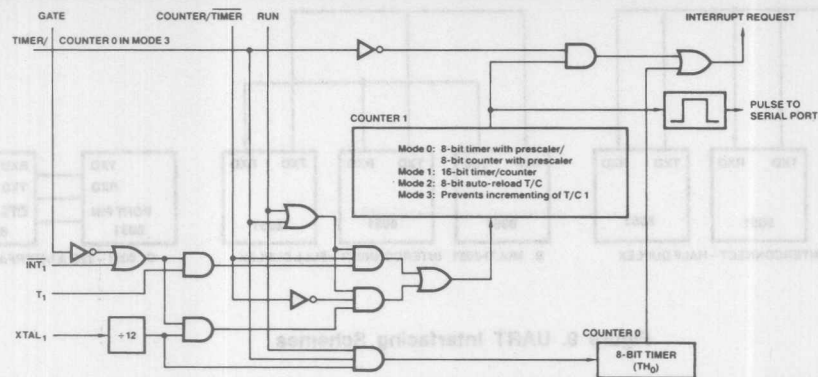
Serial Communications

The 8051's serial I/O port is useful for serially linking peripheral devices as well as multiple 8051s through standard asynchronous protocols with full-duplex operation. The serial port also has a synchronous mode for expansion of I/O lines using CMOS and TTL shift registers. This hardware serial communications interface saves ROM code and permits a much higher transmission rate than could be achieved through software. In response to a serial port interrupt request, the CPU has only to read/write the serial port's buffer to service the serial link. A block diagram of the serial port is shown in Figures 7 and 8. Methods for linking UART (universal asynchronous receiver/transmitter) devices are shown in Figure 9 and a method for I/O expansion is shown in Figure 10.

The full-duplex serial I/O port provides asynchronous modes to facilitate communications with standard UART devices, such as printers and CRT terminals, or communications with other 8051s in multi-processor systems. The receiver is double buffered to eliminate the overrun that would occur if the CPU failed to respond to the receiver's interrupt before the beginning of the next frame. The 8051 can generally maintain the serial link at its maximum rate so double buffering of the

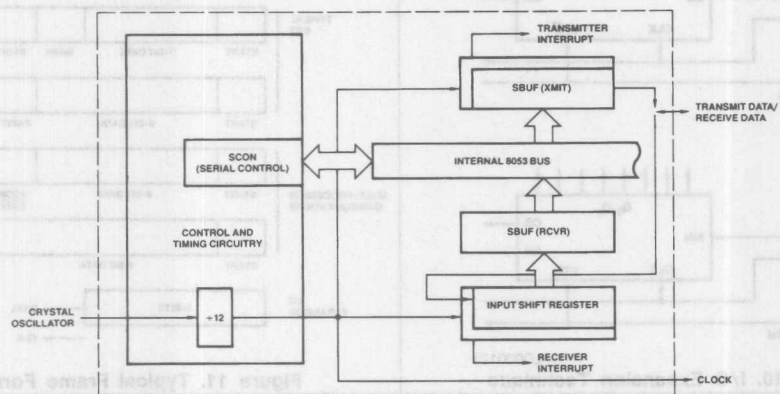
transmitter is not needed. A minor degradation in transmission rate can occur in rare events such as when the servicing of the transmitter has to wait for a lengthy interrupt service program to complete. In asynchronous modes, false start-bit rejection is provided on received frames. For noise rejection a best two-out-of-three vote is taken on three samples near the center of each received bit.

When interfacing with standard UART devices, the serial channel can be programmed to Mode 1 which transmits/receives a ten-bit frame or programmed to Mode 2 or 3 which transmits/receives an eleven-bit frame as shown in Figure 11. The frame consists of a start bit, eight or nine data bits, and one stop bit. In modes 1 and 3, the transmission-rate timing circuitry receives a pulse from counter 1 each time the counter overflows. The input to counter 1 can be an external source or a division by 12 of the oscillator frequency. The auto-reload mode of the counter provides communication rates of 0.05 to 62,500 bits per second (including start and stop bits) for a 12-MHz crystal. In Mode 2 the communication rate is a division by 64 or 32 of the oscillator frequency yielding a transmission rate of 187,500 bits per second or 375,000 bits per second (including start and stop bits) for a 12-MHz crystal.



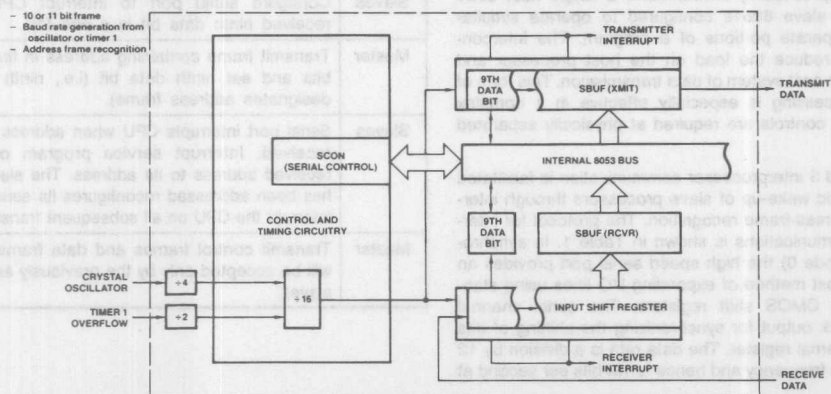
LD000080

Figure 6. Timer/Counter 1 Control and Status Flag Circuitry



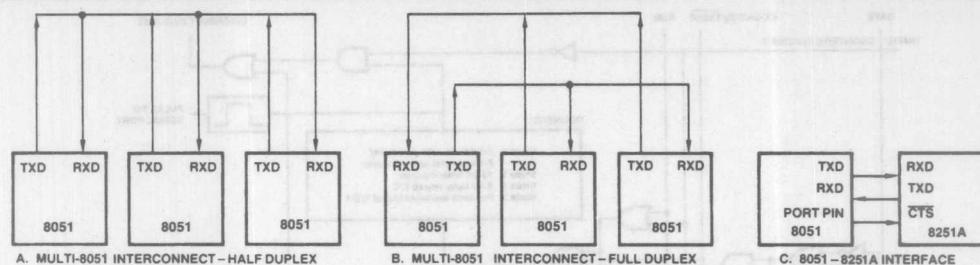
BD006050

Figure 7. Serial Port — Synchronous Mode 0



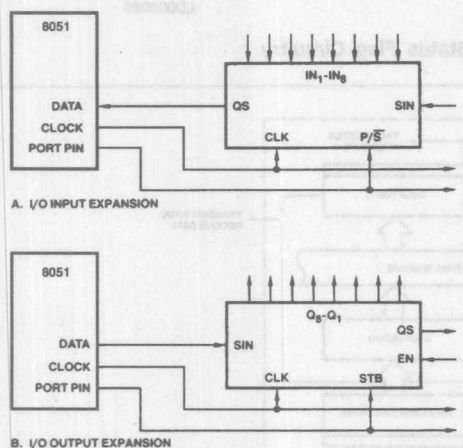
LD000100

Figure 8. Serial Port — UART Modes 1, 2 and 3



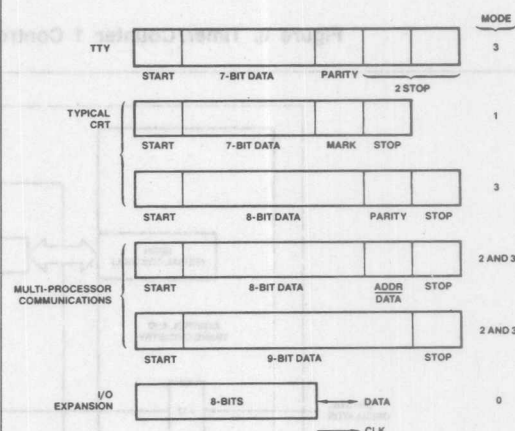
LD000062

Figure 9. UART Interfacing Schemes



LD000121

Figure 10. I/O Expansion Technique



BD006060

Figure 11. Typical Frame Formats

Distributed processing offers a faster, more powerful system than a single CPU can provide. This results from hierarchy of interconnected processors, each with its own memories and I/O. In a multiprocessing environment, a single host 8051 controls other slave 8051s configured to operate simultaneously on separate portions of a program. The interconnected 8051s reduce the load on the host processor and result in a lower-cost system of data transmission. This form of distributed processing is especially effective in a complex process where controls are required at physically separated locations.

In Modes 2 and 3 interprocessor communication is facilitated by the automatic wake-up of slave processors through interrupt driven address-frame recognition. The protocol for interprocessor communications is shown in Table 1. In synchronous mode (Mode 0) the high speed serial port provides an efficient, low-cost method of expanding I/O lines using standard TTL and CMOS shift registers. The serial channel provides a clock output for synchronizing the shifting of bits to/from an external register. The data rate is a division by 12 of the oscillator frequency and hence is 1M bits per second at 12 MHz.

TABLE 1. PROTOCOL FOR MULTI-PROCESSOR COMMUNICATIONS

Slaves	Configure serial port to interrupt CPU if the received ninth data bit is a one (1).
Master	Transmit frame containing address in first 8 data bits and set ninth data bit (i.e., ninth data bit designates address frame).
Slaves	Serial port interrupts CPU when address frame is received. Interrupt service program compares received address to its address. The slave which has been addressed reconfigures its serial port to interrupt the CPU on all subsequent transmissions.
Master	Transmit control frames and data frames (these will be accepted only by the previously addressed slave).

Oscillator Characteristics

XTAL₁ and XTAL₂ are the input and output, respectively, of an inverting amplifier which can be configured for use as an on-chip oscillator, as shown in Figure 12. Either a quartz crystal or ceramic resonator may be used.

To drive the device from an external clock source, XTAL₁ should be grounded, while XTAL₂ is driven, as shown in Figure 13. There are no requirements on the duty cycle of the external clock signal, since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum HIGH and LOW times specified on the data sheet must be observed.

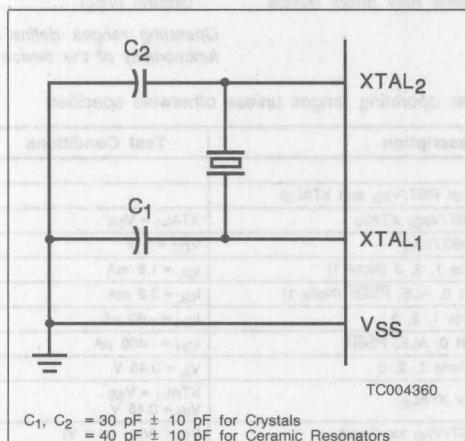


Figure 12. Oscillator Connections

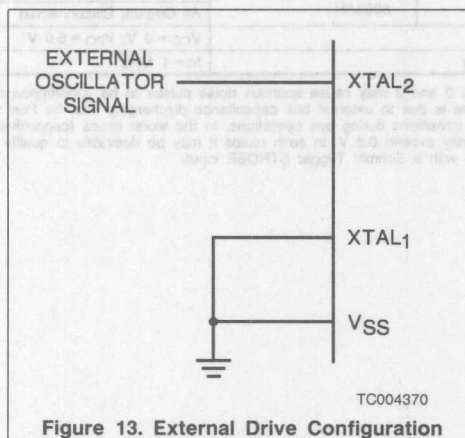


Figure 13. External Drive Configuration

ABSOLUTE MAXIMUM RATINGS

Storage Temperature -65 to +150°C
 Voltage on Any Pin
 with Respect to Ground -0.5 to +7.0 V
 Power Dissipation 1 W

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Temperature (T_A) 0 to +70°C
 Supply Voltage (V_{CC}) +4.5 to +5.5 V
 Ground (V_{SS}) 0 V

Industrial (I) Devices (8031AH only)

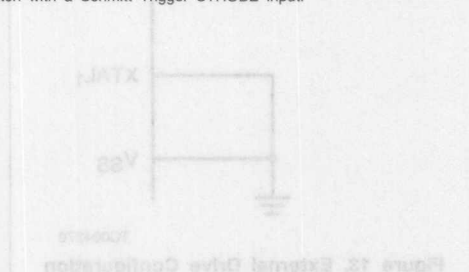
Temperature (T_A) -40 to +85°C
 Supply Voltage (V_{CC}) +4.5 to +5.5 V
 Ground (V_{SS}) 0 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over operating ranges unless otherwise specified

Parameters	Description	Test Conditions	Min.	Max.	Units
V _{IL}	Input LOW Voltage		-0.5	0.8	V
V _{IH}	Input HIGH Voltage (Except RST/V _{PD} and XTAL ₂)		2.0	V _{CC} + 0.5	V
V _{IH1}	Input HIGH Voltage to RST/V _{PD} , XTAL ₂	XTAL ₁ = V _{SS}	2.5	V _{CC} + 0.5	V
V _{PD}	Power-Down Voltage to RST/V _{PD}	V _{CC} = 0 V	4.5	5.5	V
V _{OL}	Output LOW Voltage, Ports 1, 2, 3 (Note 1)	I _{OL} = 1.6 mA		0.45	V
V _{OL1}	Output LOW Voltage, Port 0, ALE, PSEN (Note 1)	I _{OL} = 3.2 mA		0.45	V
V _{OH}	Output HIGH Voltage, Ports 1, 2, 3	I _{OH} = -80 μA	2.4		V
V _{OH1}	Output HIGH Voltage, Port 0, ALE, PSEN	I _{OH} = -400 μA	2.4		V
I _{IL}	Logical 0 Input Current, Ports 1, 2, 3	V _{IL} = 0.45 V		-500	μA
I _{IL2}	Logical 0 Input Current for XTAL ₂	XTAL ₁ = V _{SS} V _{IN} = 0.45 V		-3.2	mA
I _{IH1}	Input HIGH Current to RST/V _{PD} for Reset	V _{IN} < (V _{CC} - 1.5 V)		500	μA
I _{LI}	Input Leakage Current to Port 0, EA	0.45 < V _{IN} < V _{CC}		±10	μA
I _{CC}	Power-Supply Current	EA = V _{CC} All Outputs Disconnected		125 160	mA
I _{PD}	Power-Down Current	V _{CC} = 0 V; V _{PD} = 5.0 V		10	mA
C _{IO}	Capacitance of I/O Buffer	f _c = 1 MHz		10	pF

Notes: 1. Capacitive load on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL}s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100 pF), the noise pulse on the ALE line may exceed 0.8 V. In such cases it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input.



SWITCHING CHARACTERISTICS over operating ranges unless otherwise specified (Load Capacitance for Port 0, ALE, and PSEN = 100 pF; Load Capacitance for all other outputs = 80 pF)

Parameter Symbol	Parameter Description	12 MHz Clock		18 MHz Clock (Note 1)		Variable Clock		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
TCY 1/TCLCL	Oscillator Frequency					1.2	18	MHz
TLHLL	ALE Pulse Width	127		71		2TCLCL-40		ns
TAVLL	Address Setup to ALE	43		15		TCLCL-40		ns
TLLAX	Address Hold After ALE	48		20		TCLCL-35		ns
TLLIV	ALE to Valid Instruction In		233		122		4TCLCL-100	ns
TLLPL	ALE to PSEN	58		30		TCLCL-25		ns
TPLPH	PSEN Pulse Width	215		131		3TCLCL-35		ns
TPLIV	PSEN to Valid Instruction In		125		41		3TCLCL-125	ns
TPXIX	Input Instruction Hold After PSEN	0		0		0		ns
TPXIZ	Input Instruction Float After PSEN		63		35		TCLCL-20	ns
TPXAV	Address Valid After PSEN	75		47		TCLCL-8		ns
TAVIV	Address to Valid Instruction In		302		162		5TCLCL-115	ns
TPLAZ	Address Float After PSEN		20		20		20	ns
TRLRH	RD Pulse Width	400		233		6TCLCL-100		ns
TWLWH	WR Pulse Width	400		233		6TCLCL-100		ns
TRLDV	RD to Valid Data In		250		112		5TCLCL-165	ns
TRHDX	Data Hold After RD	0		0		0		ns
TRHDZ	Data Float After RD		97		41		2TCLCL-70	ns
TLLDV	ALE to Valid Data In		517		294		8TCLCL-150	ns
TAVDV	Address to Valid Data In		585		334		9TCLCL-165	ns
TLLWL	ALE to WR or RD	200	300	116	216	3TCLCL-50	3TCLCL+50	ns
TAVWL	Address to WR or RD	203		92		4TCLCL-130		ns
TQVWX	Data Valid to WR Transition	23		0		TCLCL-60		ns
TQVWH	Data Setup Before WR	433		238		7TCLCL-150		ns
TWHQX	Data Hold After WR	33		5		TCLCL-50		ns
TRLAZ	Address Float After RD		20		20		20	ns
TWHLH	WR or RD High to ALE High	43	123	16	96	TCLCL-40	TCLCL+40	ns

Notes: 1. 18 MHz clock pertains only to 8031AH in the Commercial operating range.

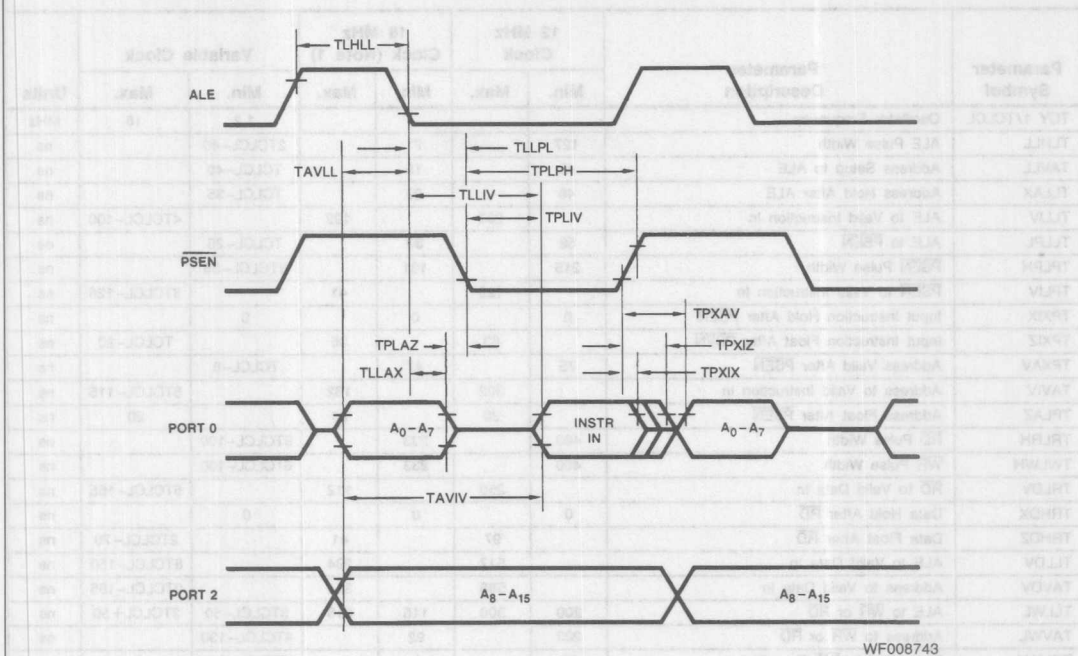
SWITCHING WAVEFORMS

KEY TO SWITCHING WAVEFORMS

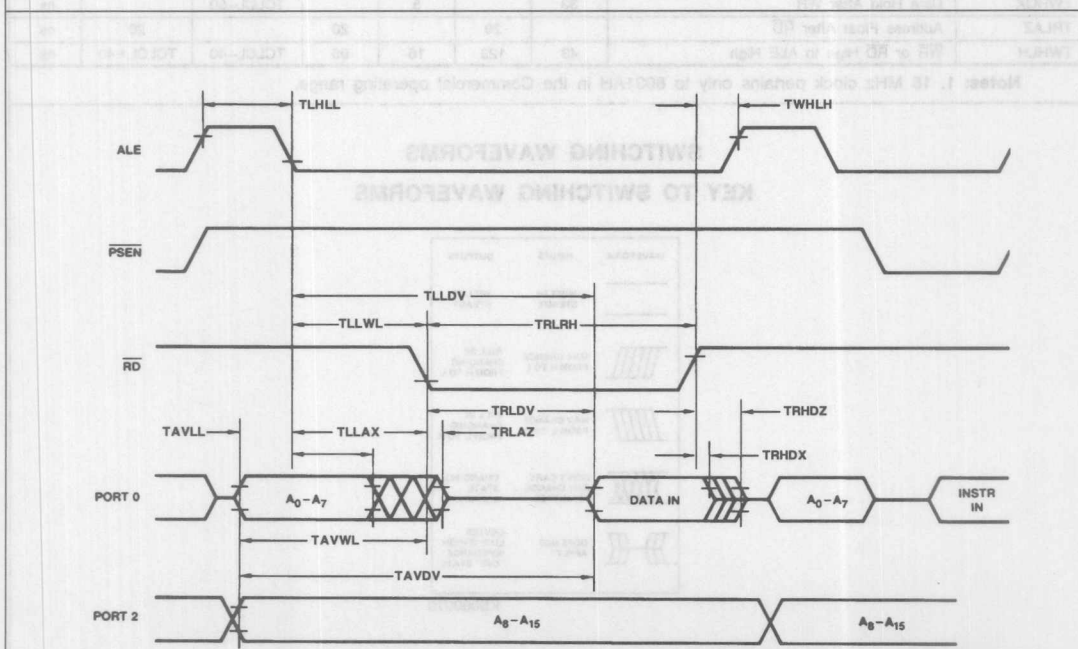
WAVEFORM	INPUTS	OUTPUTS
	MUST BE STEADY	WILL BE STEADY
	MAY CHANGE FROM H TO L	WILL BE CHANGING FROM H TO L
	MAY CHANGE FROM L TO H	WILL BE CHANGING FROM L TO H
	DON'T CARE; ANY CHANGE PERMITTED	CHANGING; STATE UNKNOWN
	DOES NOT APPLY	CENTER LINE IS HIGH IMPEDANCE "OFF" STATE

KS000010

SWITCHING WAVEFORMS (Cont'd.)

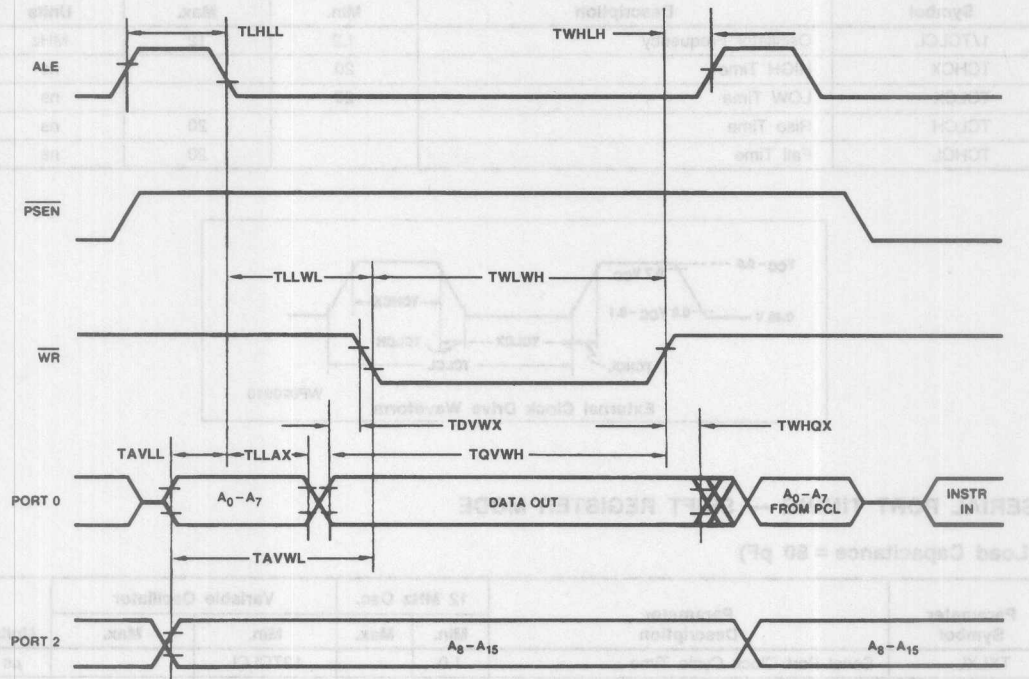


External Program Memory Read Cycle



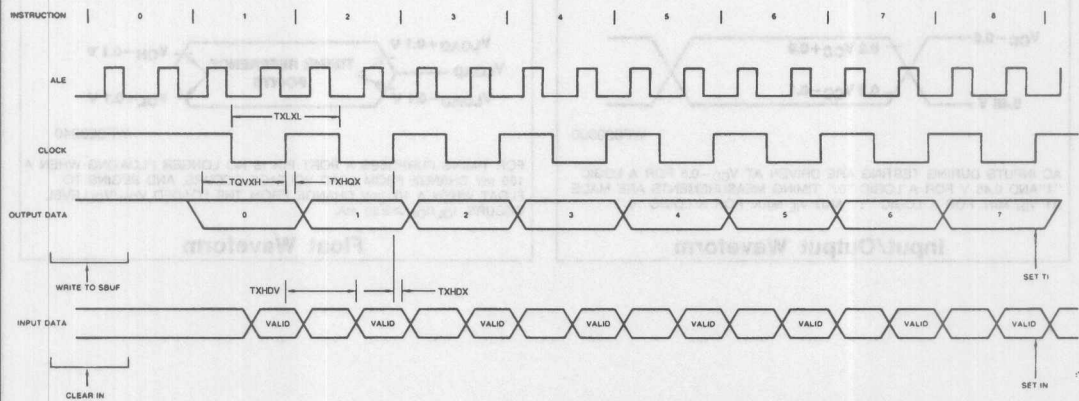
External Data Memory Read Cycle

SWITCHING WAVEFORMS (Cont'd.)



WF008754

External Data Memory Write Cycle

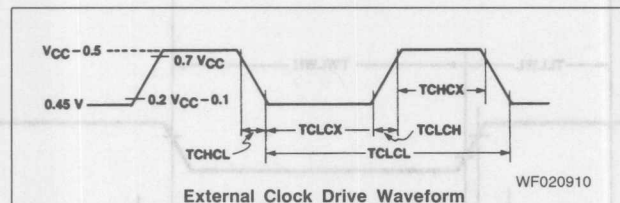


WF008722

Shift Register Timing Waveforms

EXTERNAL CLOCK DRIVE

Parameter Symbol	Parameter Description	Min.	Max.	Units
1/TCLCL	Oscillator Frequency	1.2	12	MHz
TCHCX	HIGH Time	20		ns
TCLCX	LOW Time	20		ns
TCLCH	Rise Time		20	ns
TCHCL	Fall Time		20	ns

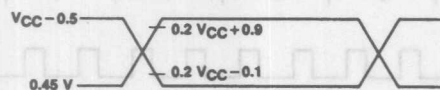


SERIAL PORT TIMING — SHIFT REGISTER MODE

(Load Capacitance = 80 pF)

Parameter Symbol	Parameter Description	12 MHz Osc.		Variable Oscillator		Units
		Min.	Max.	Min.	Max.	
TXLXL	Serial Port Clock Cycle Time	1.0		12TCLCL		μ s
TQVXH	Output Data Setup to Clock Rising Edge	700		10TCLCL - 133		ns
TXHQX	Output Data Hold After Clock Rising Edge	50		2TCLCL - 117		ns
TXHDX	Input Data Hold After Clock Rising Edge	0		0		ns
TXHDV	Clock Rising Edge to Input Data Valid		700		10TCLCL - 133	ns

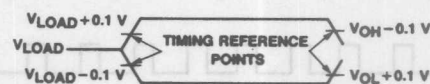
AC Testing



WF020900

AC INPUTS DURING TESTING ARE DRIVEN AT $V_{CC} - 0.5$ FOR A LOGIC "1" AND 0.45 V FOR A LOGIC "0." TIMING MEASUREMENTS ARE MADE AT V_{IH} MIN. FOR A LOGIC "1" AND V_{IL} MAX. FOR A LOGIC "0."

Input/Output Waveform

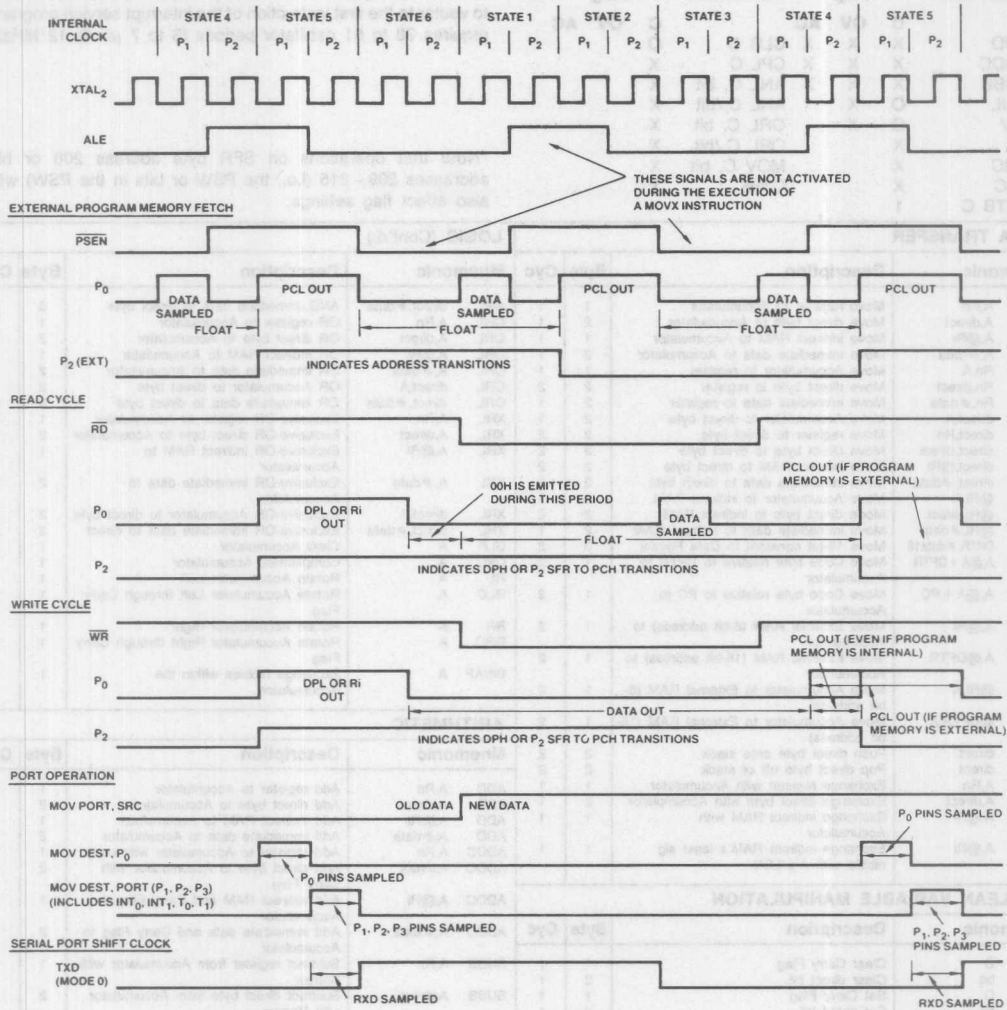


WF020940

FOR TIMING PURPOSES A PORT PIN IS NO LONGER FLOATING WHEN A 100 mV CHANGE FROM LOAD VOLTAGE OCCURS, AND BEGINS TO FLOAT WHEN A 100 mV CHANGE FROM THE LOADED V_{OH}/V_{OL} LEVEL OCCURS. $I_{OL}/I_{OH} \geq \pm 20$ mA.

Float Waveform

CLOCK WAVEFORMS



WF007070

All internal timing is referenced to the internal time state shown on the top of the page. This waveform represents the signal on the X₂ input of the oscillator. This diagram represents when these signals are actually clocked within the chip. However, the time it takes a signal to propagate to the pins is in the range of 25 to 125 ns. Prop delays are dependent on many variables, such as temperature, pin loading. Propagation also varies from output to output and component to component. Typically though, /RD and /WR have prop delays of approximately 50 ns and the other timing signals approximately 85 ns, at room temperature, fully loaded. These differences in prop delays between signals have been integrated into the timing specs.

TABLE 3. 8051 FAMILY INSTRUCTION SET

Instructions That Affect Flag Setting*				Instruction				Flag			
Instruction		Flag		Instruction		Flag		Flag		Flag	
		C	OV	AC			C	OV	AC		
ADD		X	X	X	CLR C		O				
ADDC		X	X	X	CPL C		X				
SUBB		X	X	X	ANL C, bit		X				
MUL		O	X		ANL C, /bit		X				
DIV		O	X		ORL C, bit		X				
DA		X			ORL C, /bit		X				
RRC		X			MOV C, bit		X				
RLC		X			CJNE		X				
SETB C		1									

Interrupt Response Time: To finish execution of current instruction, respond to the interrupt request and push the PC; to vector to the first instruction of the interrupt service program requires 38 to 81 oscillator periods (3 to 7 μ s @ 12 MHz).

*Note that operations on SFR byte address 208 or bit addresses 209–215 (i.e., the PSW or bits in the PSW) will also affect flag settings.

DATA TRANSFER					LOGIC (Cont'd.)				
Mnemonic	Description	Byte	Cyc		Mnemonic	Description	Byte	Cyc	
MOV A,Rn	Move register to Accumulator	1	1		ANL direct,#data	AND immediate data to direct byte	3	2	
MOV A,direct	Move direct byte to Accumulator	2	1		ORL A,Rn	OR register to Accumulator	1	1	
MOV A,@Ri	Move indirect RAM to Accumulator	1	1		ORL A,direct	OR direct byte to Accumulator	2	1	
MOV A,#data	Move immediate data to Accumulator	2	1		ORL A,@Ri	OR indirect RAM to Accumulator	1	1	
MOV Rn,A	Move Accumulator to register	1	1		ORL A,#data	OR immediate data to Accumulator	2	1	
MOV Rn,direct	Move direct byte to register	2	2		ORL direct,A	OR Accumulator to direct byte	2	1	
MOV Rn,#data	Move immediate data to register	2	1		ORL direct,#data	OR immediate data to direct byte	3	2	
MOV direct,A	Move Accumulator to direct byte	2	1		XRL A,Rn	Exclusive-OR register to Accumulator	1	1	
MOV direct,Rn	Move register to direct byte	2	2		XRL A,direct	Exclusive-OR direct byte to Accumulator	2	1	
MOV direct,direct	Move direct byte to direct byte	3	2		XRL A,@Ri	Exclusive-OR indirect RAM to Accumulator	1	1	
MOV direct,@Ri	Move indirect RAM to direct byte	2	2		XRL A,#data	Exclusive-OR immediate data to Accumulator	2	1	
MOV direct,#data	Move immediate data to direct byte	3	2		XRL direct,A	Exclusive-OR Accumulator to direct byte	2	1	
MOV @Ri,A	Move Accumulator to indirect RAM	1	1		XRL direct,#data	Exclusive-OR immediate data to direct	3	2	
MOV @Ri,direct	Move direct byte to indirect RAM	2	2		CLR A	Clear Accumulator	1	1	
MOV @Ri,#data	Move immediate data to indirect RAM	2	1		CPL A	Complement Accumulator	1	1	
MOV DPTR,#data16	Move 16-bit constant to Data Pointer	3	2		RL A	Rotate Accumulator Left	1	1	
MOVC A,@A + DPTR	Move Code byte relative to DPTR to Accumulator	1	2		RLC A	Rotate Accumulator Left through Carry Flag	1	1	
MOVC A,@A + PC	Move Code byte relative to PC to Accumulator	1	2		RR A	Rotate Accumulator Right	1	1	
MOVX A,@Ri	Move External RAM (8-bit address) to Accumulator	1	2		RRC A	Rotate Accumulator Right through Carry Flag	1	1	
MOVX A,@DPTR	Move External RAM (16-bit address) to Accumulator	1	2		SWAP A	Exchange nibbles within the Accumulator	1	1	
MOVX @Ri,A	Move Accumulator to External RAM (8-bit address)	1	2						
MOVX @DPTR,A	Move Accumulator to External RAM (16-bit address)	1	2						
PUSH direct	Push direct byte onto stack	2	2						
POP direct	Pop direct byte off of stack	2	2						
XCH A,Rn	Exchange register with Accumulator	1	1						
XCH A,direct	Exchange direct byte with Accumulator	2	1						
XCH A,@Ri	Exchange indirect RAM with Accumulator	1	1						
XCHD A,@Ri	Exchange indirect RAM's least sig nibble with A's LSN	1	1						

BOOLEAN VARIABLE MANIPULATION					ARITHMETIC				
Mnemonic	Description	Byte	Cyc		Mnemonic	Description	Byte	Cyc	
CLR C	Clear Carry Flag	1	1		ADD A,Rn	Add register to Accumulator	1	1	
CLR bit	Clear direct bit	2	1		ADD A,direct	Add direct byte to Accumulator	2	1	
SETB C	Set Carry Flag	1	1		ADD A,@Ri	Add indirect RAM to Accumulator	1	1	
SETB bit	Set direct bit	2	1		ADD A,#data	Add immediate data to Accumulator	2	1	
CPL C	Complement Carry Flag	1	1		ADDC A,Rn	Add register to Accumulator with carry	1	1	
CPL bit	Complement direct bit	2	1		ADDC A,direct	Add direct byte to Accumulator with Carry Flag	2	1	
ANL C,bit	AND direct bit to Carry Flag	2	2		ADDC A,@Ri	Add indirect RAM and Carry Flag to Accumulator	1	1	
ANL C,/bit	AND complement of direct bit to Carry	2	2		ADDC A,#data	Add immediate data and Carry Flag to Accumulator	2	1	
ORL C,bit	OR direct bit to Carry Flag	2	2		SUBB A,Rn	Subtract register from Accumulator with Borrow	1	1	
ORL C,/bit	OR complement of direct bit to Carry	2	2		SUBB A,direct	Subtract direct byte from Accumulator with Borrow	2	1	
MOV C,bit	Move direct bit to Carry Flag	2	1		SUBB A,@Ri	Subtract indirect RAM from Accumulator with Borrow	1	1	
MOV bit,C	Move Carry flag to direct bit	2	2		SUBB A,#data	Subtract immediate data from Accumulator with Borrow	2	1	

LOGIC (Cont'd.)					OTHER				
Mnemonic	Description	Byte	Cyc		Mnemonic	Description	Byte	Cyc	
ANL A,Rn	AND register to Accumulator	1	1		NOP	No Operation	1	1	
ANL A,direct	AND direct byte to Accumulator	2	1						
ANL A,@Ri	AND indirect RAM to Accumulator	1	1						
ANL A,#data	AND immediate data to Accumulator	2	1						
ANL direct,A	AND Accumulator to direct byte	2	1						

CONTROL TRANSFER (BRANCH)					Notes on Data Addressing Modes:				
Mnemonic		Description	Byte	Cyc					
AJMP	addr11	Absolute Jump	2	2	Rn	-Working register R0 – R7 of the currently selected Register bank.			
LJMP	addr16	Long Jump	3	2	direct	-128 internal RAM locations, any I/O port, control, or status register.			
SJMP	rel	Short Jump (relative addr)	2	2	@Ri	-Indirect internal RAM location addressed by register R0 or R1.			
JMP	@A + DPTR	Jump indirect relative to the DPTR	1	2	#data	-8-bit constant included in instruction.			
JZ	rel	Jump if Accumulator is zero	2	2	#data16	-16-bit constant included as bytes 2 and 3 of instruction.			
JNZ	rel	Jump if Accumulator is not zero	2	2	bit	-128 software flags, any I/O pin, control, or status bit.			
JC	rel	Jump if Carry Flag is set	2	2					
JNC	rel	Jump if carry is not set	2	2					
JB	bit,rel	Jump relative if direct bit is set	3	2					
JNB	bit,rel	Jump relative if direct bit is not set	3	2					
JBC	bit,rel	Jump relative if direct bit is set, then clear bit	3	2					
CJNE	A,direct,rel	Compare direct byte to Accumulator and Jump if not Equal	3	2					
CJNE	A,#data,rel	Compare immediate to Accumulator and Jump if not Equal	3	2					
CJNE	Rn,#data,rel	Compare immediate to reg and Jump if not Equal	3	2					
CJNE	@Ri,#data,rel	Compare immediate to indirect RAM and Jump if not Equal	3	2					
DJNZ	Rn,rel	Decrement register and Jump if not zero	2	2					
DJNZ	direct,rel	Decrement direct byte and Jump if not zero	3	2					
CONTROL TRANSFER (SUBROUTINE)					Notes on Program Addressing Modes:				
Mnemonic		Description	Byte	Cyc					
ACALL	addr11	Absolute Subroutine Call	2	2	addr16	-Destination address for LCALL and LJMP may be anywhere within the 64-Kilobyte program memory address space.			
LCALL	addr16	Long Subroutine Call	3	2	addr11	-Destination address for ACALL and AJMP will be within the same 2-Kilobyte page of program memory as the first byte of the following instruction.			
RET		Return from Subroutine Call	1	2	rel	-SJMP and all conditional jumps include a 8-bit offset by Range is +127, -128 bytes relative to first byte of the following instruction.			
RETI		Return from Interrupt Call	1	2					
TABLE 4. INSTRUCTION OPCODES IN HEXADECIMAL ORDER (Cont'd.)									
Hex Code	Bytes	Mnemonic	Operands	Hex Code	Bytes	Mnemonic	Operands	Hex Code	Bytes
00	1	NOP		2E	1	ADD	A,R6	50	2
01	2	AJMP	Code addr	2F	1	ADD	A,R7	51	2
02	3	LJMP	Code addr	30	3	JNB	Bit addr,code addr	52	2
03	1	RR	A	31	2	ACALL	Code addr	53	3
04	1	INC	A	32	1	RETI		54	2
05	2	INC	Data addr	33	1	RLC	A	55	2
06	1	INC	@R0	34	2	ADDC	A,#data	56	1
07	1	INC	@R1	35	2	ADDC	A,data addr	57	1
08	1	INC	R0	36	1	ADDC	A,@R0	58	1
09	1	INC	R1	37	1	ADDC	A,@R1	59	1
0A	1	INC	R2	38	1	ADDC	A,R0	5A	1
0B	1	INC	R3	39	1	ADDC	A,R1	5B	1
0C	1	INC	R4	3A	1	ADDC	A,R2		
0D	1	INC	R5	3B	1	ADDC	A,R3		
0E	1	INC	R6	3C	1	ADDC	A,R4		
0F	1	INC	R7	3D	1	ADDC	A,R5		
10	3	JBC	Bit addr,code addr	3E	1	ADDC	A,R6		
11	2	ACALL	Code addr	3F	1	ADDC	A,R7		
12	3	LCALL	Code addr	40	2	JC	Code addr		
13	1	RRC	A	41	2	AJMP	Code addr		
14	1	DEC	A	42	2	ORL	Data addr,A		
15	2	DEC	Data addr	43	3	ORL	Data addr,#data		
16	1	DEC	@R0	44	2	ORL	A,#data		
17	1	DEC	@R1	45	2	ORL	A,data addr		
18	1	DEC	R0	46	1	ORL	A,@R0		
19	1	DEC	R1	47	1	ORL	A,@R1		
1A	1	DEC	R2	48	1	ORL	A,R0		
1B	1	DEC	R3	49	1	ORL	A,R1		
1C	1	DEC	R4	4A	1	ORL	A,R2		
1D	1	DEC	R5	4B	1	ORL	A,R3		
1E	1	DEC	R6	4C	1	ORL	A,R4		
1F	1	DEC	R7	4D	1	ORL	A,R5		
20	3	JB	Bit addr,code addr	4E	1	ORL	A,R6		
21	2	AJMP	Code addr	4F	1	ORL	A,R7		
22	1	RET		50	2	JNC	Code addr		
23	1	RL	A	51	2	ACALL	Code addr		
24	2	ADD	A,#data	52	2	ANL	Data addr,A		
25	2	ADD	A,data addr	53	3	ANL	Data addr,#data		
26	1	ADD	A,@R0	54	2	ANL	A,#data		
27	1	ADD	A,@R1	55	2	ANL	A,data addr		
28	1	ADD	A,R0	56	1	ANL	A,@R0		
29	1	ADD	A,R1	57	1	ANL	A,@R1		
2A	1	ADD	A,R2	58	1	ANL	A,R0		
2B	1	ADD	A,R3	59	1	ANL	A,R1		
2C	1	ADD	A,R4	5A	1	ANL	A,R2		
2D	1	ADD	A,R5	5B	1	ANL	A,R3		

Hex Code	Bytes	Mnemonic	Operands	Hex Code	Bytes	Mnemonic	Operands
5C	1	ANL	A,R4	AF	2	MOV	R7,data addr
5D	1	ANL	A,R5	B0	2	ANL	C,/bit addr
5E	1	ANL	A,R6	B1	2	ACALL	Code addr
5F	1	ANL	A,R7	B2	2	CPL	Bit addr
60	2	JZ	Code addr	B3	1	CPL	C
61	2	AJMP	Code addr	B4	3	CJNE	A,#data,code addr
62	2	XRL	Data addr,A	B5	3	CJNE	A,data addr,code addr
63	3	XRL	Data addr,#data	B6	3	CJNE	@R0,#data,code addr
64	2	XRL	A,#data	B7	3	CJNE	@R1,#data,code addr
65	2	XRL	A,data addr	B8	3	CJNE	R0,#data,code addr
66	1	XRL	A,@R0	B9	3	CJNE	R1,#data,code addr
67	1	XRL	A,@R1	BA	3	CJNE	R2,#data,code addr
68	1	XRL	A,R0	BB	3	CJNE	R3,#data,code addr
69	1	XRL	A,R1	BC	3	CJNE	R4,#data,code addr
6A	1	XRL	A,R2	BD	3	CJNE	R5,#data,code addr
6B	1	XRL	A,R3	BE	3	CJNE	R6,#data,code addr
6C	1	XRL	A,R4	BF	3	CJNE	R7,#data,code addr
6D	1	XRL	A,R5	C0	2	PUSH	Data addr
6E	1	XRL	A,R6	C1	2	AJMP	Code addr
6F	1	XRL	A,R7	C2	2	CLR	Bit addr
70	2	JNZ	Code addr	C3	1	CLR	C
71	2	ACALL	Code addr	C4	1	SWAP	A
72	2	ORL	C,bit addr	C5	2	XCH	A,data addr
73	1	JMP	@A + DPTR	C6	1	XCH	A,@R0
74	2	MOV	A,#data	C7	1	XCH	A,@R1
75	3	MOV	Data addr,#data	C8	1	XCH	A,R0
76	2	MOV	@R0,#data	C9	1	XCH	A,R1
77	2	MOV	@R1,#data	CA	1	XCH	A,R2
78	2	MOV	R0,#data	CB	1	XCH	A,R3
79	2	MOV	R1,#data	CC	1	XCH	A,R4
7A	2	MOV	R2,#data	CD	1	XCH	A,R5
7B	2	MOV	R3,#data	CE	1	XCH	A,R6
7C	2	MOV	R4,#data	CF	1	XCH	A,R7
7D	2	MOV	R5,#data	D0	2	POP	Data addr
7E	2	MOV	R6,#data	D1	2	ACALL	Code addr
7F	2	MOV	R7,#data	D2	2	SETB	Bit addr
80	2	SJMP	Code addr	D3	1	SETB	C
81	2	AJMP	Code addr	D4	1	DA	A
82	2	ANL	C,bit addr	D5	3	DJNZ	Data addr,code addr
83	1	MOVC	A,@A + PC	D6	1	XCHD	A,@R0
84	1	DIV	AB	D7	1	XCHD	A,@R1
85	3	MOV	Data addr,data addr	D8	2	DJNZ	R0,code addr
86	2	MOV	Data addr,@R0	D9	2	DJNZ	R1,code addr
87	2	MOV	Data addr,@R1	DA	2	DJNZ	R2,code addr
88	2	MOV	Data addr,R0	DB	2	DJNZ	R3,code addr
89	2	MOV	Data addr,R1	DC	2	DJNZ	R4,code addr
8A	2	MOV	Data addr,R2	DD	2	DJNZ	R5,code addr
8B	2	MOV	Data addr,R3	DE	2	DJNZ	R6,code addr
8C	2	MOV	Data addr,R4	DF	2	DJNZ	R7,code addr
8D	2	MOV	Data addr,R5	E0	1	MOVX	A,@DPTR
8E	2	MOV	Data addr,R6	E1	2	AJMP	Code addr
8F	2	MOV	Data addr,R7	E2	1	MOVX	A,@R0
90	3	MOV	DPTR,#data	E3	1	MOVX	A,@R1
91	2	ACALL	Code addr	E4	1	CLR	A
92	2	MOV	Bit addr,C	E5	2	MOV	A,data addr
93	1	MOVC	A,@A + DPTR	E6	1	MOV	A,@R0
94	2	SUBB	A,#data	E7	1	MOV	A,@R1
95	2	SUBB	A,data addr	E8	1	MOV	A,R0
96	1	SUBB	A,@R0	E9	1	MOV	A,R1
97	1	SUBB	A,@R1	EA	1	MOV	A,R2
98	1	SUBB	A,R0	EB	1	MOV	A,R3
99	1	SUBB	A,R1	EC	1	MOV	A,R4
9A	1	SUBB	A,R2	ED	1	MOV	A,R5
9B	1	SUBB	A,R3	EE	1	MOV	A,R6
9C	1	SUBB	A,R4	EF	1	MOV	A,R7
9D	1	SUBB	A,R5	F0	1	MOVX	@DPTR,A
9E	1	SUBB	A,R6	F1	2	ACALL	Code addr
9F	1	SUBB	A,R7	F2	1	MOVX	@R0,A
A0	2	ORL	C,/bit addr	F3	1	MOVX	@R1,A
A1	2	AJMP	Code addr	F4	1	CPL	A
A2	2	MOV	C,bit addr	F5	2	MOV	Data addr,A
A3	1	INC	DPTR	F6	1	MOV	@R0,A
A4	1	MUL	AB	F7	1	MOV	@R1,A
A5		Reserved		F8	1	MOV	R0,A
A6	2	MOV	@R0,data addr	F9	1	MOV	R1,A
A7	2	MOV	@R1,data addr	FA	1	MOV	R2,A
A8	2	MOV	R0,data addr	FB	1	MOV	R3,A
A9	2	MOV	R1,data addr	FC	1	MOV	R4,A
AA	2	MOV	R2,data addr	FD	1	MOV	R5,A
AB	2	MOV	R3,data addr	FE	1	MOV	R6,A
AC	2	MOV	R4,data addr	FF	1	MOV	R7,A
AD	2	MOV	R5,data addr				
AE	2	MOV	R6,data addr				

8751H/8753H

Single-Chip 8-Bit Microcontroller with
4K/8K Bytes of EPROM

DISTINCTIVE CHARACTERISTICS

- 4K x 8 EPROM (8751H); 8K x 8 EPROM (8753H)
- 128 x 8 RAM
- Four 8-bit ports, 32 I/O lines; programmable serial port
- Two 16-bit Timer/Event counters
- 64K addressable Program and Data Memory
- Boolean processor
- Five interrupt sources/two priority levels
- 4-cycle multiply and divide
- Program memory security feature
- Fast EPROM programming: 12 sec for 4K bytes
- Supports silicon signature verification
- Pin compatible with 8051

GENERAL DESCRIPTION

The 8751H and 8753H are members of a family of advanced single-chip microcontrollers. Both the 8751H, which has 4K bytes of EPROM, and the 8753H, which has 8K bytes of EPROM, are pin-compatible EPROM versions of the 8051AH and 8053AH, respectively. Thus, the 8751H/8753H are full-speed prototyping tools which provide effective single-chip solutions for controller applications that require code modification flexibility. Refer to the block diagram of the 8051 family.

The 8751H/8753H devices feature: thirty-two I/O lines; two 16-bit timer/event counters; a Boolean processor; a 5-source, bi-level interrupt structure; a full-duplex serial channel; and on-chip oscillator and clock circuitry.

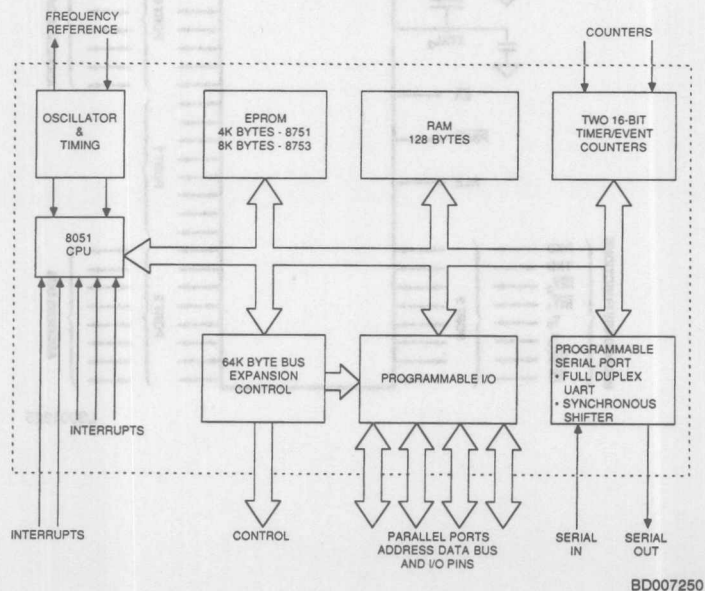
Program and Data Memory are located in independent addresses. The AMD family of microcontrollers can access up to 64K bytes of external Program Memory and up to 64K

bytes of external Data Memory. The 8751H and the 8753H contain the lower 4K and 8K bytes of Program Memory, respectively, on-chip. Both parts have 128 bytes of on-chip read/write data memory.

The AMD 8051 Microcontroller Family is specifically suited for control applications. A variety of fast addressing modes, which access the internal RAM, facilitates byte processing and numerical operations on small data structures. Included in the instruction set is a menu of 8-bit arithmetic instructions, including 4-cycle multiply and divide instructions.

Extensive on-chip support enables direct bit manipulation and testing of 1-bit variables as separate data types. Thus, the device is also suited for control and logic systems that require Boolean processing.

BLOCK DIAGRAM

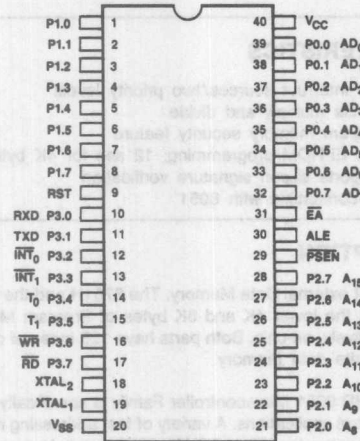


Publication #	Rev.	Amendment
03896	D	/0
Issue Date: July 1987		

CONNECTION DIAGRAMS

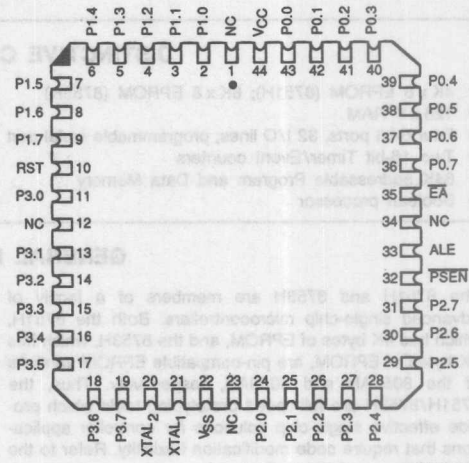
Top View

DIP



CD005551

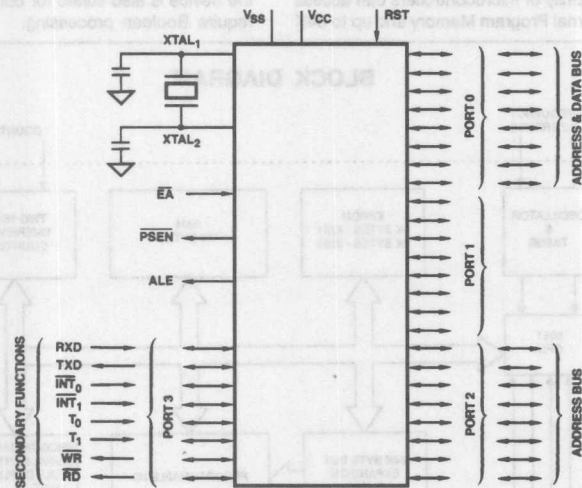
LCC



CD010870

Note: Pin 1 is marked for orientation.

LOGIC SYMBOL



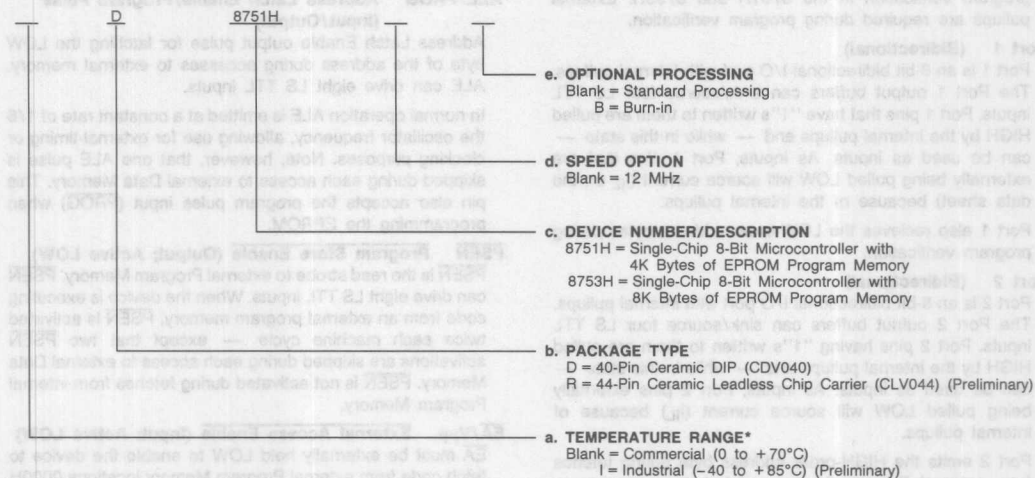
LS001325

ORDERING INFORMATION

Commodity Products

AMD commodity products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:

- a. Temperature Range
- b. Package Type
- c. Device Number
- d. Speed Option
- e. Optional Processing



Valid Combinations

D, R	8751H
	8753H
ID	8751HB
	8753H
	8753HB

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released valid combinations, and to obtain additional data on AMD's standard military grade products.

*This device is also available in Military temperature range. See MOS Microprocessors and Peripherals Military Handbook (Order #09275A/0) for electrical performance characteristics.

Port Pin	Alternate Function
Pin 1	Pin 1 (Ground) and Pin 2
Pin 2	Pin 2 (Ground) and Pin 1
Pin 3	Pin 3 (Ground) and Pin 4
Pin 4	Pin 4 (Ground) and Pin 3
Pin 5	Pin 5 (Ground) and Pin 6
Pin 6	Pin 6 (Ground) and Pin 5
Pin 7	Pin 7 (Ground) and Pin 8
Pin 8	Pin 8 (Ground) and Pin 7
Pin 9	Pin 9 (Ground) and Pin 10
Pin 10	Pin 10 (Ground) and Pin 9

I/O PIN DESCRIPTION

Port 0 (Bidirectional; Open Drain)

Port 0 is an open-drain I/O port. Port 0 pins that have "1"s written to them float, and in that state can be used as high-impedance inputs.

Port 0 is also the multiplexed LOW-order address and data bus during accesses to external Program and Data Memory. In this application it uses strong internal pullups when emitting "1"s. Port 0 also outputs the code bytes during program verification in the 8751H and 8753H. External pullups are required during program verification.

Port 1 (Bidirectional)

Port 1 is an 8-bit bidirectional I/O port with internal pullups. The Port 1 output buffers can sink/source four LS TTL inputs. Port 1 pins that have "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 1 pins that are externally being pulled LOW will source current (I_{IL} on the data sheet) because of the internal pullups.

Port 1 also receives the LOW-order address bytes during program verification.

Port 2 (Bidirectional)

Port 2 is an 8-bit bidirectional I/O port with internal pullups. The Port 2 output buffers can sink/source four LS TTL inputs. Port 2 pins having "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 2 pins externally being pulled LOW will source current (I_{IL}) because of internal pullups.

Port 2 emits the HIGH-order address byte during fetches from external Program Memory and during accesses to external Data Memory that use 16-bit addresses (MOVX @DPTR). In this application it uses strong internal pullups when emitting "1"s. During accesses to external Data Memory that use 8-bit addresses (MOVX @Ri), Port 2 emits the contents of the P2 Special Function register.

Port 2 also receives the HIGH-order address bits during the programming of the EPROM and during program verification of the EPROM.

Port 3 (Bidirectional)

Port 3 is an 8-bit bidirectional I/O port with internal pullups. The Port 3 output buffers can sink/source four LS TTL inputs. Port 3 pins having "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 3 pins externally being pulled LOW will source current (I_{IL}) because of the pullups.

Port 3 also serves the functions of various special features as listed below:

Port Pin	Alternate Function
P _{3,0}	RxD (Serial Input Port)
P _{3,1}	TxD (Serial Output Port)
P _{3,2}	INT ₀ (External Interrupt 0)
P _{3,3}	INT ₁ (External Interrupt 1)
P _{3,4}	T ₀ (Timer 0 External Input)
P _{3,5}	T ₁ (Timer 1 External Input)
P _{3,6}	WR (External Data Memory Write Strobe)
P _{3,7}	RD (External Data Memory Read Strobe)

RST/V_{PD} Reset (Input; Active HIGH)

This pin is used to reset the device when held HIGH for two machine cycles while the oscillator is running. If RST/V_{PD} is held within the V_{PD} spec, it will supply standby power to the RAM in the event that V_{CC} drops below its spec. When RST/V_{PD} is LOW, the RAM's bias is drawn from V_{CC}.

ALE/PROG Address Latch Enable/Program Pulse (Input/Output)

Address Latch Enable output pulse for latching the LOW byte of the address during accesses to external memory. ALE can drive eight LS TTL inputs.

In normal operation ALE is emitted at a constant rate of 1/6 the oscillator frequency, allowing use for external-timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external Data Memory. This pin also accepts the program pulse input (PROG) when programming the EPROM.

PSEN Program Store Enable (Output; Active LOW)

PSEN is the read strobe to external Program Memory. PSEN can drive eight LS TTL inputs. When the device is executing code from an external program memory, PSEN is activated twice each machine cycle — except that two PSEN activations are skipped during each access to external Data Memory. PSEN is not activated during fetches from internal Program Memory.

EA/V_{pp} External Access Enable (Input; Active LOW)

EA must be externally held LOW to enable the device to fetch code from external Program Memory locations 0000H to 0FFFFH (0000H to 1FFFFH in the 8753H). If EA is held HIGH, the 8751H executes from internal Program Memory unless the program counter contains an address greater than 0FFFFH (1FFFFH in the 8753H).

XTAL₁ Crystal (Input)

Input to the inverting oscillator amplifier. When an external oscillator is used, XTAL₁ should be grounded.

XTAL₂ Crystal (Output)

Output of the inverting oscillator amplifier. XTAL₂ is also the input for the oscillator signal when using an external oscillator.

V_{CC} Power Supply

V_{SS} Circuit Ground

PROGRAMMING

Programming the EPROM

To program the EPROM, either the internal or external oscillator must be running at 4 to 6 MHz because the internal bus is used to transfer address and program data to the appropriate internal registers.

The 8751H and 8753H devices support an adaptive EPROM programming algorithm in addition to the conventional EPROM programming algorithm. Adaptive device programming (sometimes called interactive or intelligent programming) adapts to the actual charge storage efficiency of each byte, so that no wasted programming time occurs and minimum device programming time is realized.

The typical resulting device programming time is a mere 7% of what is required for a conventional programming algorithm. For example, to program a 4K byte EPROM using the conventional programming algorithm will require $4K \times 50 \text{ ms} = 200 \text{ sec}$. If adaptive programming is used, the theoretical programming time required will be $4K \times 3 \text{ ms} = 12 \text{ sec}$. The actual speed advantage of the adaptive programming is still very significant even allowing for the additional software overhead to implement the adaptive algorithm (2 to 8 sec depending on the brand of EPROM programmer).

To program the 8751H, pins $P_{2,4} - P_{2,6}$ and \overline{PSEN} should be held LOW, and $P_{2,7}$ and RST held HIGH as shown in Table 2. The address of the location to be programmed is applied to Port 1 and $P_{2,0} - P_{2,3}$ while the code byte to be programmed is applied to Port 0 (see Figure 1).

V_{pp} should be at 21 V during device programming and the ALE/ \overline{PROG} pin should be pulsed LOW for 1 ms to program the code byte into the addressed EPROM location. The programmed byte is verified immediately after programming.

Figure 3 illustrates the flow of the adaptive programming algorithm. At each address, up to 15 program/verify loops are attempted to verify the programmability of the byte using 1 ms \overline{PROG} pulses. After the programmability of a byte is determined, an overprogramming pulse of 2 ms is applied to \overline{PROG} to guarantee data retention. (This conforms with the AMD standard of 2 ms/byte overprogramming for all N-channel EPROMs.)

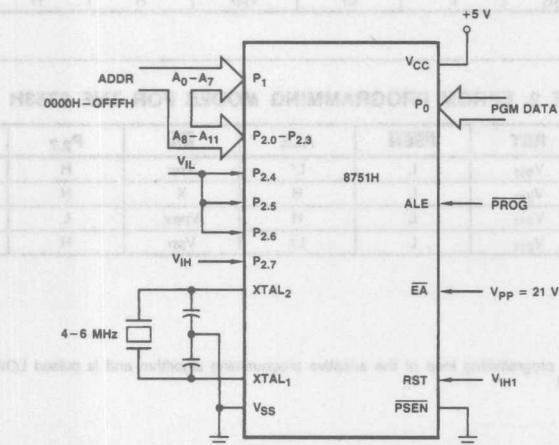
The programming of 8753H is similar to the above procedures except that pin $P_{2,4}$ is the additional address pin (A_{12}) for accessing the upper 4K bytes of the EPROM (see Figure 2).

The 8751H and 8753H can also be programmed using the less efficient conventional EPROM programming algorithm. In this method, V_{pp} is held at 21 V and \overline{PROG} is pulsed low for 50 ms to program each code byte into the addressed EPROM location. After the memory is programmed, all addresses would be sequenced and verified.

A Note of Caution When Programming

The maximum voltage applied to the \overline{EA}/V_{pp} pin must not exceed 21.5 V at any time as specified for V_{pp} . Even a slight spike can cause permanent damage to the device. The V_{pp} source should thus be well-regulated and glitch-free.

When programming, a $0.1 \times 10^{-6} \text{ F}$ capacitor is required across V_{pp} and ground to suppress spurious transients which may damage the device.



LS001453

Figure 1. 8751H Programming Configuration

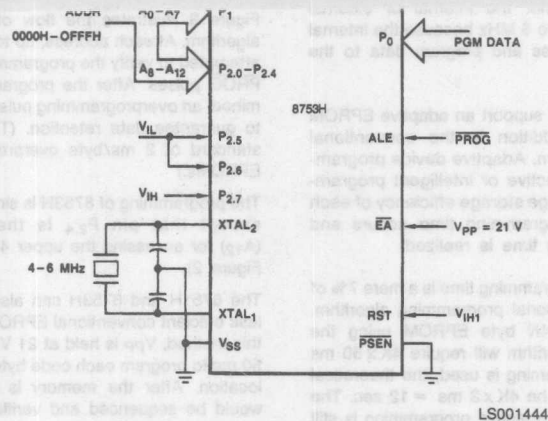


TABLE 1. EPROM PROGRAMMING MODES FOR THE 8751H

Mode	RST	PSEN	ALE	EA	P2.7	P2.6	P2.5	P2.4
Program	V _{IH1}	L	L*	V _{PP}	H	L	L	L
Inhibit	V _{IH1}	L	H	X	H	L	L	L
Verify	V _{IH1}	L	H	V _{PPX}	L	L	L	L
Security Set	V _{IH1}	L	L†	V _{PP}	H	H	L	X

Note: See notes below Table 2.

TABLE 2. EPROM PROGRAMMING MODES FOR THE 8753H

Mode	RST	PSEN	ALE	EA	P2.7	P2.6	P2.5
Program	V _{IH1}	L	L*	V _{PP}	H	L	L
Inhibit	V _{IH1}	L	H	X	H	L	L
Verify	V _{IH1}	L	H	V _{PPX}	L	L	L
Security Set	V _{IH1}	L	L†	V _{PP}	H	H	L

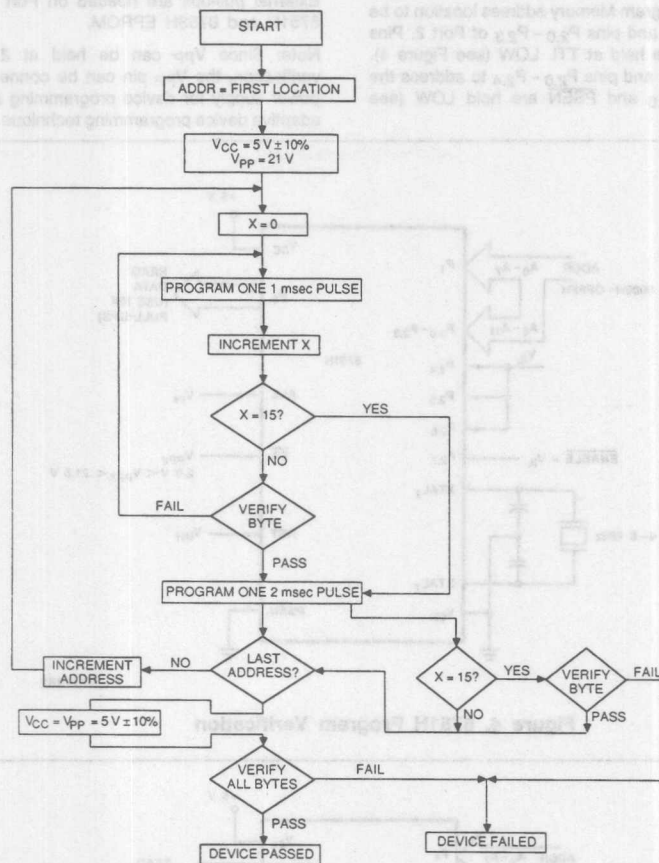
Note: H = Logic HIGH for that pin

L = Logic LOW
X = Don't Care

$$V_{PP} = +21 \text{ V} \pm 0.5 \text{ V}$$
$$2.0 \text{ V} < V_{PPX} < 21.5 \text{ V}$$

*ALE is pulsed LOW for 1 msec in the programming loop of the adaptive programming algorithm and is pulsed LOW for 50 msec if conventional EPROM programming algorithm is used.

†ALE is pulsed LOW for 50 msec.



PF002510

Figure 3. Adaptive Programming Algorithm for 8751H and 8753H

Program Verification

The Program Memory may be read out for verification purposes when the security bit has not been programmed. Reading the Program Memory may occur during or after programming of the EPROM. When the oscillator is running at 4 – 6 MHz, the 8751H Program Memory address location to be read is applied to Port 1 and pins P_{2.0} – P_{2.3} of Port 2. Pins P_{2.4} – P_{2.6} and $\overline{\text{PSEN}}$ are held at TTL LOW (see Figure 4). The 8753H utilizes Port 1 and pins P_{2.0} – P_{2.4} to address the EPROM, while P_{2.5} – P_{2.6} and $\overline{\text{PSEN}}$ are held LOW (see Figure 5).

The ALE/ $\overline{\text{PROG}}$ and RST pins of both devices are held HIGH (RST requires only 2.5 V for HIGH) and the $\overline{\text{EA}}/\text{V}_{\text{pp}}$ pin voltage can have any value from 2.0 V to 21.5 V as shown in Tables 1 and 2.

Port 0 will then output the contents of the address location. External pull-ups are needed on Port 0 when verifying the 8751H and 8753H EPROM.

Note: Since V_{pp} can be held at 21 V during program verification, the V_{pp} pin can be connected to a static 21 V power supply for device programming and verification in the adaptive device programming technique (see Figures 4 and 5).

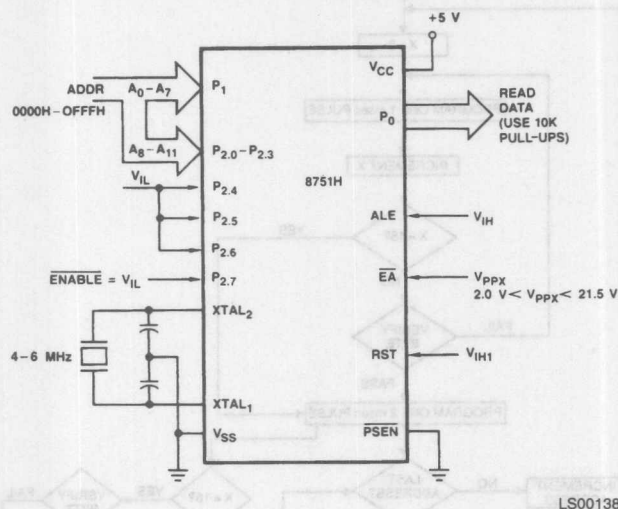


Figure 4. 8751H Program Verification

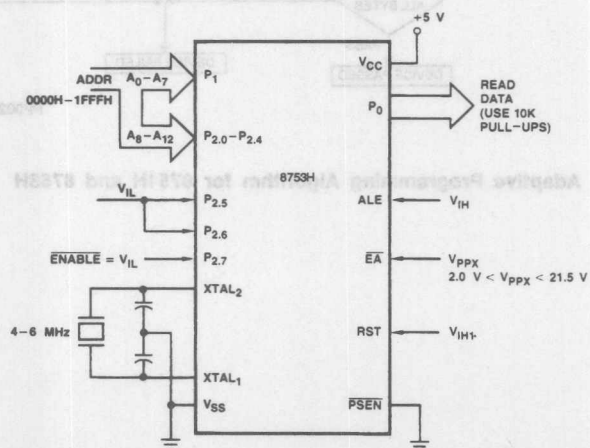


Figure 5. 8753H Program Verification

The 8751H and 8753H incorporates a security bit, which when activated, prohibits all external readout of the on-chip EPROM contents. Figure 6 illustrates the security bit programming configuration for both the 8751H and 8753H. To activate the security bit, the same setup is used as when programming the EPROM except that $P_{2,6}$ is held HIGH. Port 0, Port 1 and pins $P_{2,0} - P_{2,3}$ may assume any state. V_{pp} should be at 21 V and the ALE/PROG pin should be pulsed LOW for 50 msec. The logic states of the other pins are detailed in Tables 1 and 2.

A secured Program Memory looks like a blank array of all ones, and this property can be used to verify that the EPROM is secured. The programmed security bit also prohibits further device programming and the execution of external Program Memory.

Full functionality and programmability may be restored by erasing the EPROM and thus clearing the security bit.



Figure 6. Programming the Security Bit

Silicon Signature Verification

AMD will support silicon signature verification for the 8751H/8753H. To ensure that the device can be programmed according to the adaptive EPROM programming algorithm, the manufacturer code and part code can be read from the device before any programming is done.

To read the silicon signature, set up the conditions as specified in Figure 7. Note that P_{2,5} is now required to be a TTL high level. Read the first byte of the silicon signature by applying address 0000H to the device; the byte should be a 01H, indicating AMD as the manufacturer. Then read the second byte of the silicon signature by applying address 0001H to the device; the byte should be 0DH, indicating the AMD 8751H/8753H product family.

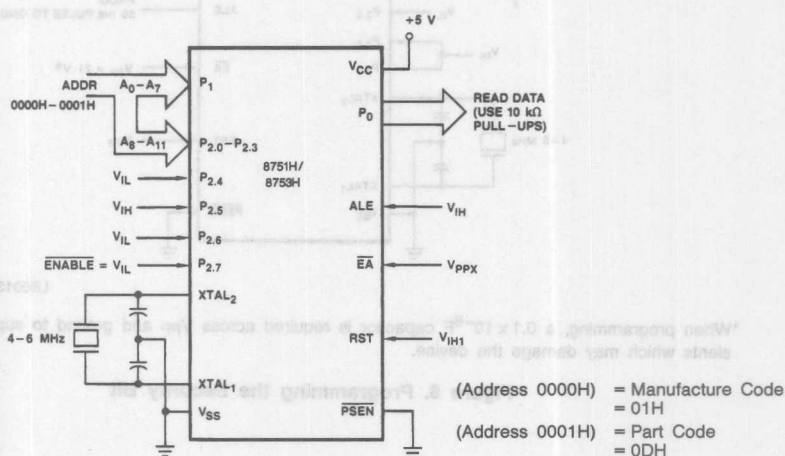
Erasure Characteristics

Light and other forms of electromagnetic radiation can lead to erasure of the EPROM when exposed for extended periods of time.

Wavelengths of light shorter than 4000 angstroms, such as sunlight or indoor fluorescent lighting, can ultimately cause inadvertent erasure and should, therefore, not be allowed to expose the EPROM for lengthy durations (approximately one week in sunlight or three years in room-level fluorescent lighting). It is suggested that the window be covered with an opaque label if an application is likely to subject the device to this type of radiation.

It is recommended that ultraviolet light (of 2537 angstroms) be used to a dose of at least 15 W-sec/cm² when erasing the EPROM. An ultraviolet lamp rated at 12,000 μ W/cm² held one inch away for 20–30 minutes should be sufficient.

EPROM erasure leaves the Program Memory in an "all ones" state.



LS001404

Figure 7. 8751H/8753H Silicon Signature Verification Configuration

ABSOLUTE MAXIMUM RATINGS

Storage Temperature -65 to +150°C
 Voltage on \overline{EA}/V_{PP} Pin to V_{SS} -0.5 to +21.5 V
 Voltage on Any Other Pin to V_{SS} -0.5 to +7 V
 Power Dissipation 1.5 W

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Temperature (T_A) 0 to +70°C
 Supply Voltage (V_{CC}) +4.5 to +5.5 V
 Ground (V_{SS}) 0 V

Industrial (I) Devices (Preliminary)

Temperature (T_A) -40 to +85°C
 Supply Voltage (V_{CC}) +4.5 to +5.5 V
 Ground (V_{SS}) 0 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over operating range unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Units
V_{IL}	Input LOW Voltage (Except \overline{EA})		-0.5	0.8	V
V_{IL1}	Input LOW Voltage to \overline{EA}		0	0.7	V
V_{IH}	Input HIGH Voltage (Except XTAL ₂ , RST)		2.0	$V_{CC} + 0.5$	V
V_{IH1}	Input HIGH Voltage to XTAL ₂ , RST	$XTAL_1 = V_{SS}$	2.5	$V_{CC} + 0.5$	V
V_{OL}	Output LOW Voltage (Ports 1, 2, 3) (Note 1)	$I_{OL} = 1.6$ mA		0.45	V
V_{OL1}	Output LOW Voltage (Port 0, ALE, \overline{PSEN})	$I_{OL} = 3.2$ mA $I_{OL} = 2.4$ mA		0.60 0.45	V
V_{OH}	Output HIGH Voltage (Ports 1, 2, 3)	$I_{OH} = -80$ μ A	2.4		V
V_{OH1}	Output HIGH Voltage (Port 0 in External Bus Mode, ALE, \overline{PSEN})	$I_{OH} = -400$ μ A	2.4		V
I_{IL}	Logical 0 Input Current (Ports 1, 2, 3)	$V_{IN} = 0.45$ V		-500	μ A
I_{IL1}	Logical 0 Input Current (\overline{EA})			-15	mA
I_{IL2}	Logical 0 Input Current (XTAL ₂)	$V_{IN} = 0.45$ V		-3.2	mA
I_{LI}	Input Leakage Current (Port 0)	$0.45 < V_{IN} < V_{CC}$		± 100	μ A
I_{IH}	Logical 1 Input Current (\overline{EA})			500	μ A
I_{IH1}	Input Current to RST to Activate Reset	$V_{IN} < (V_{CC} - 1.5$ V)		500	μ A
I_{CC}	Power Supply Current	All Outputs Disconnected; $\overline{EA} = V_{CC}$		250	mA
C_{IO}	Pin Capacitance	Test Freq = 1 MHz		10	pF
I_{PD}	Power Down Current	$V_{CC} = 0$ V, $V_{PD} = 5$ V		10	mA

Notes: 1. Capacitive loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL} s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100 pF), the noise pulse on the ALE line may exceed 0.8 V. In such cases it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input.



SWITCHING CHARACTERISTICS over operating range unless otherwise specified
(Load Capacitance for Port 0, ALE, and PSEN = 100 pF, Load Capacitance for All Other Outputs = 80 pF)

Parameter Symbol	Parameter Description	12 MHz Osc.		Variable Oscillator		Units
		Min.	Max.	Min.	Max.	
1/TCLCL	Oscillator Frequency			1.2	12	MHz
TLHLL	ALE Pulse Width	127		2TCLCL-40		ns
TAVLL	Address Setup to ALE	43		TCLCL-40		ns
TLLAX	Address Hold After ALE	48		TCLCL-35		ns
TLLIV	ALE to Valid Instr In		183		4TCLCL-150	ns
TLLPL	ALE to PSEN	58		TCLCL-25		ns
TPLPH	PSEN Pulse Width	190		3TCLCL-60		ns
TPLIV	PSEN to Valid Instr In		100		3TCLCL-150	ns
TPXIX	Input Instr Hold After PSEN	0		0		ns
TPXIZ	Input Instr Float After PSEN		63		TCLCL-20	ns
TPXAV	Address Valid After PSEN	75		TCLCL-8		ns
TAVIV	Address to Valid Instr In		267		5TCLCL-150	ns
TPLAZ	Addr Float After PSEN		20		20	ns
TRLRH	RD Pulse Width	400		6TCLCL-100		ns
TWLWH	WR Pulse Width	400		6TCLCL-100		ns
TRLDV	RD to Valid Data In		252		5TCLCL-165	ns
TRHDX	Data Hold After RD	0		0		ns
TRHDZ	Data Float After RD		97		2TCLCL-70	ns
TLLDV	ALE to Valid Data In		517		8TCLCL-150	ns
TAVDV	Address to Valid Data In		585		9TCLCL-165	ns
TLLWL	ALE to RD or WR	200	300	3TCLCL-50	3TCLCL+50	ns
TAVWL	Address to RD or WR	203		4TCLCL-130		ns
TQVWX	Data Valid to WR Transition	13		TCLCL-70		ns
TQVWH	Data Setup Before WR	433		7TCLCL-150		ns
TWHQX	Data Hold After WR	33		TCLCL-50		ns
TRLAZ	Address Float After RD		20		20	ns
TWHLH	RD or WR HIGH to ALE HIGH	33	133	TCLCL-50	TCLCL+50	ns

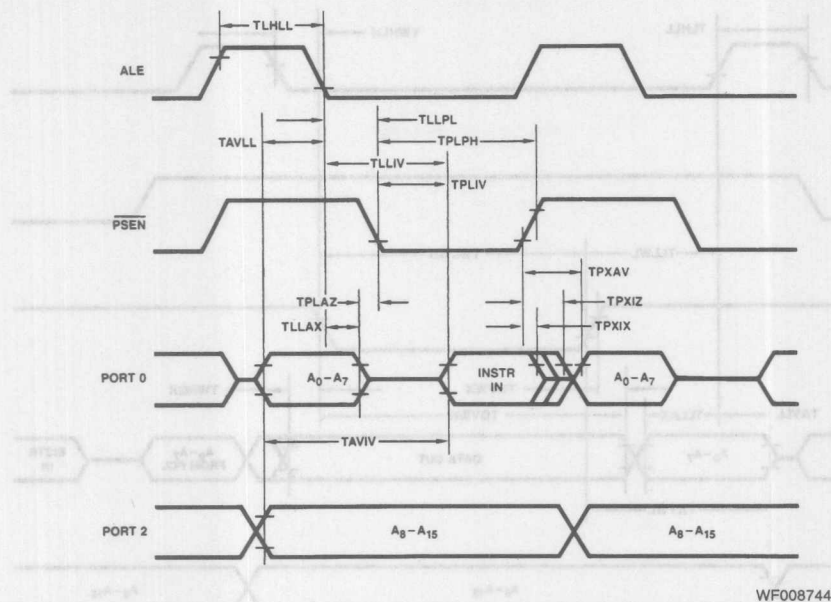
SWITCHING WAVEFORMS

KEY TO SWITCHING WAVEFORMS

WAVEFORM	INPUTS	OUTPUTS
	MUST BE STEADY	WILL BE STEADY
	MAY CHANGE FROM H TO L	WILL BE CHANGING FROM H TO L
	MAY CHANGE FROM L TO H	WILL BE CHANGING FROM L TO H
	DON'T CARE; ANY CHANGE PERMITTED	CHANGING; STATE UNKNOWN
	DOES NOT APPLY	CENTER LINE IS HIGH IMPEDANCE "OFF" STATE

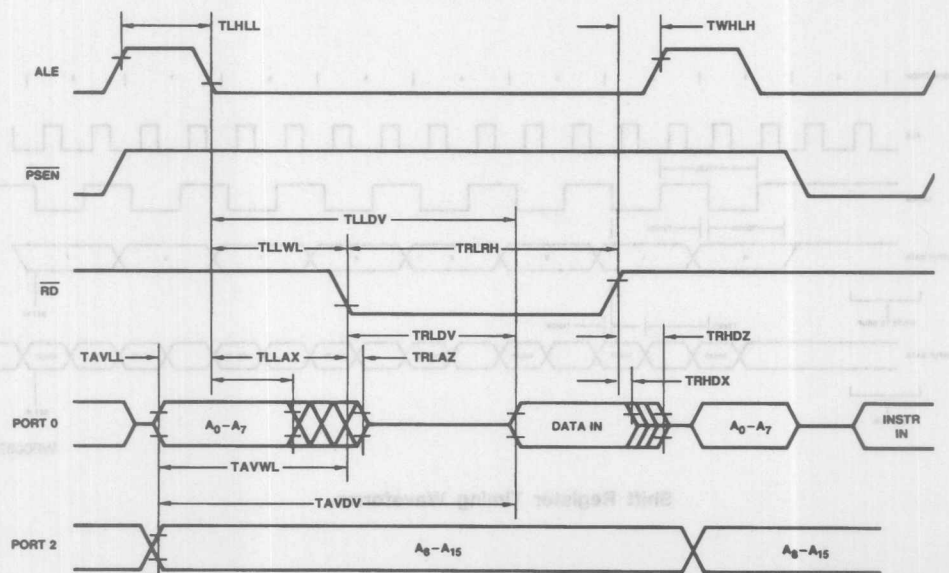
KS000010

SWITCHING WAVEFORMS



WF008744

External Program Memory Read Cycle



WF008733

External Data Memory Read Cycle

SWITCHING WAVEFORMS (Cont'd)



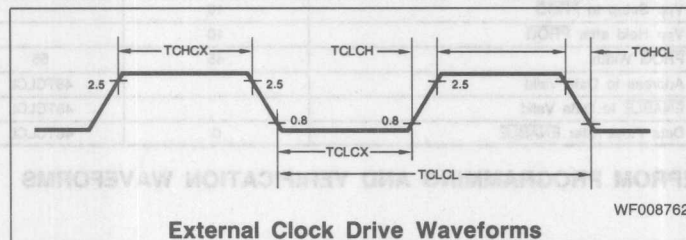
External Data Memory Write Cycle



Shift Register Timing Waveforms

EXTERNAL CLOCK DRIVE

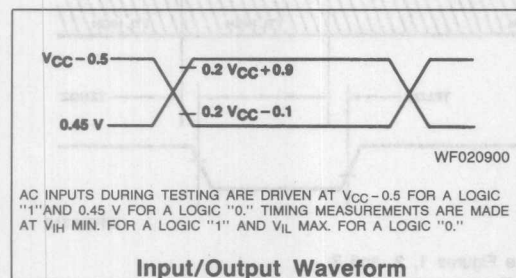
Parameter Symbol	Parameter Description	Min.	Max.	Units
1/TCLCL	Oscillator Frequency	1.2	12	MHz
TCHCX	HIGH Time	20		ns
TCLCX	LOW Time	20		ns
TCLCH	Rise Time		20	ns
TCHCL	Fall Time		20	ns



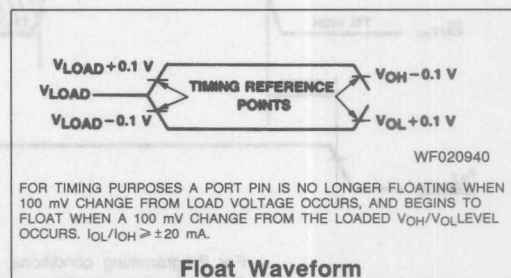
SERIAL PORT TIMING — SHIFT REGISTER MODE (Load Capacitance = 80 pF)

Parameter Symbol	Parameter Description	12 MHz Osc.		Variable Oscillator		Units
		Min.	Max.	Min.	Max.	
TXLXL	Serial Port Clock Cycle Time	1.0		12TCLCL		μ s
TQVXH	Output Data Setup to Clock Rising Edge	700		10TCLCL-133		ns
TXHQX	Output Data Hold After Clock Rising Edge	50		2TCLCL-117		ns
TXHDX	Input Data Hold After Clock Rising Edge	0		0		ns
TXHDV	Clock Rising Edge to Input Data Valid		700		10TCLCL-133	ns

AC Testing



AC INPUTS DURING TESTING ARE DRIVEN AT $V_{CC}-0.5$ FOR A LOGIC "1" AND 0.45 V FOR A LOGIC "0." TIMING MEASUREMENTS ARE MADE AT V_{IH} MIN. FOR A LOGIC "1" AND V_{IL} MAX. FOR A LOGIC "0."



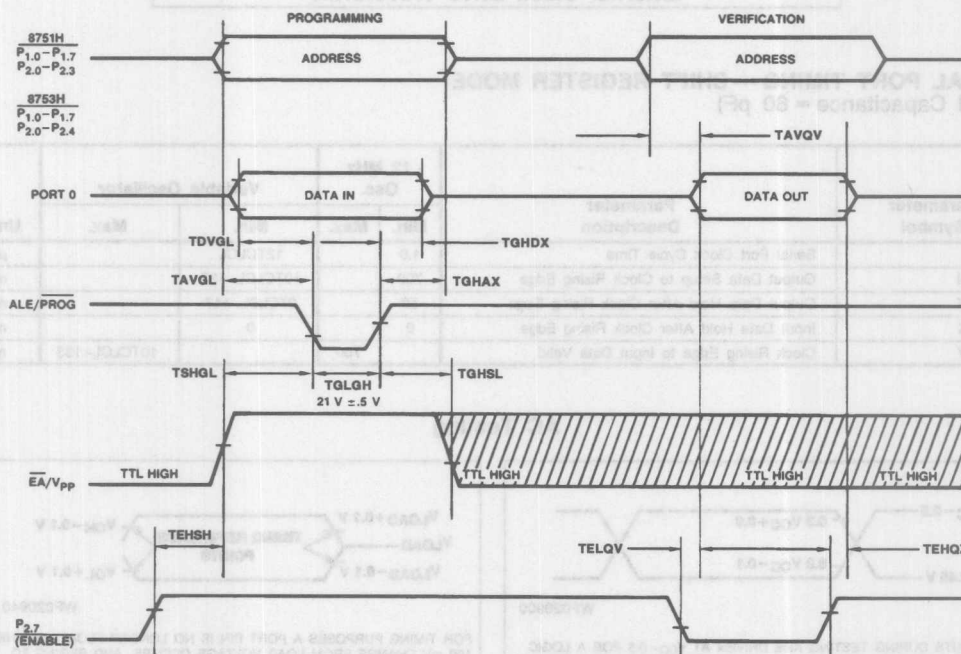
FOR TIMING PURPOSES A PORT PIN IS NO LONGER FLOATING WHEN A 100 mV CHANGE FROM LOAD VOLTAGE OCCURS, AND BEGINS TO FLOAT WHEN A 100 mV CHANGE FROM THE LOADED V_{OH}/V_{OL} LEVEL OCCURS. $I_{OL}/I_{OH} \geq \pm 20$ mA.

EPROM PROGRAMMING AND VERIFICATION CHARACTERISTICS

($T_A = +21$ to $+27^\circ\text{C}$, $V_{CC} = +5\text{ V} \pm 10\%$, $V_{SS} = 0\text{ V}$)

Parameter Symbol	Parameter Description	Min.	Max.	Units
V_{pp}	Programming Supply Voltage	20.5	21.5	V
I_{pp}	Programming Supply Current		30	mA
$1/TCLCL$	Oscillator Frequency	4	6	MHz
TAVGL	Address Setup to PROG	48TCLCL		
TGHAX	Address Hold After PROG	48TCLCL		
TDVGL	Data Setup to PROG	48TCLCL		
TGHDX	Data Hold After PROG	48TCLCL		
TEHSH	$P_{2.7}$ (ENABLE) HIGH to V_{pp}	48TCLCL		
TSHGL	V_{pp} Setup to PROG	10		μsec
TGHSL	V_{pp} Hold after PROG	10		μsec
TGLGH	PROG Width	45	55	msec
TAVQV	Address to Data Valid		48TCLCL	
TELQV	ENABLE to Data Valid		48TCLCL	
TEHQZ	Data Float After ENABLE	0	48TCLCL	

EPROM PROGRAMMING AND VERIFICATION WAVEFORMS



WF008713

For Programming conditions, see Figures 1, 2, and 3.
For Verification conditions, see Figures 4 and 5.
For Security Bit Programming, see Figure 6.

Single-Chip Microcontroller With 8K Bytes of EPROM Offers Important Design Advantages

by Gordon Burk, Product Marketing Engineer and Rajesh Tanna, Applications Engineer

The Am8753 is a member of the very popular 8051 Family of single-chip microcomputers. Advanced Micro Devices brought its superior EPROM technology to the single chip area to answer a very real need for more on-board EPROM, which gives designers the flexibility they are looking for.

Because it is a pin-compatible EPROM version of the 8053, any 8051 Family customer will find the Am8753 easy to adapt to all of the traditional 8051, 8053, and 8751 applications. The instruction set is identical, and the designer's previous experience with the 8051 Family is directly applicable.

The 8K bytes of EPROM, and the flexibility that gives the designer, is an obvious advantage. The scenario is familiar — move the contents of off-board memory to on-board, reduce the chip count by one EPROM, and save valuable board space. Familiar, but nonetheless valuable to customers. Many designers will be afforded the luxury of adding that feature which was previously sacrificed for economy.

As is often the case, an R&D advancement precedes a better, faster, or in this case, denser, product. AMD's advanced NS19 process technology has given birth to a superior EPROM, and now it is incorporated into proprietary microcomputers. The introduction of this technology to microcontrollers made the Am8753 feasible.

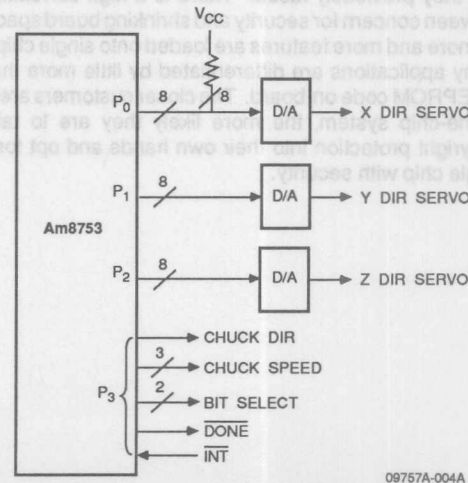
Beyond the familiar advantages of reduced chip count and board space, there is also an improvement in a traditional tradeoff. As with most microcontrollers there exists an I/O versus memory tradeoff in using the 8051 Family. When only on-board memory is used, the designer has four I/O ports at his disposal. However, when off-board memory is accessed, the designer sacrifices two of the four I/O ports to fetch external code. There exist many applications that require both the additional memory and the available I/O lines.

In the case of the 8751, there are 4K bytes of on-board EPROM, and once the designer expands the program off-board, he is restricted to 16 I/O lines. The Am8753 expands the range by 4K bytes for which a designer can have both memory and I/O. Sufficient memory and I/O in a single chip means a reduced parts count. An EPROM, address latch and external I/O can be eliminated. The following application serves as an example:

Numerical machine control is an area in which many I/O ports are very useful. A typical numerical machine takes a piece of metal and cuts it into its final shape. A machine must perform different opera-

tions, including cutting, planing and drilling. To be able to do this accurately, precise motion control is required in the X, Y and Z planes. The cutting, planing and drilling are accomplished by attaching different 'bits' to a chuck that can spin at different speeds in either direction. Typically movement in the X and Y lanes is achieved by moving the surface on which the work piece is mounted. Movement in the Z plane is accomplished by either moving the same surface up/down or by moving the chuck up/down.

Figure 7-1 shows a simple block diagram illustrating how the ports of the Am8753 can be used to control such a numerical machine. To achieve precise motion in the X, Y and Z directions, three of the ports (0, 1 and 2) are used to control three D/A converters, which in turn control three servo motors. Port 3 is then used to control other functions. Three port-3 bits control rotation speed of the chuck, two bits are used to select the correct 'bit' or cutting tool, to be fitted into the chuck, and one bit guides the direction of rotation of the chuck. The INT₀ pin on port 3 is used as a start input. When the user hits a button, the Am8753 is interrupted and initiates the cutting of the workpiece. An eighth port-3 bit can be used to indicate when the job is finished. If the application is of a slightly different kind, where the final product is a result of several numerical machines performing specific parts of the job, it may be necessary to use the port-3 serial port to interface with the user.



00757A-004A

Figure 7-1. The Am8753 in a Machine Control Application

As this example illustrates, having all the ports available for I/O simplifies matters a great deal. If external program memory is needed, ports 0 and 2 would be multiplexed to enable instruction fetching, making the design much more complicated.

The 8K bytes of EPROM is the primary advantage, and certainly the motivation for producing the part, but the Am8753 has some other nice features too. In an industry that is becoming increasingly security conscious, the on-board security feature of the Am8753 is a real plus.

Keeping algorithms and programs out of the wrong hands is no small concern to many customers. Whether it means keeping your printer algorithm from your competitors or protecting the integrity of smart credit cards, security can be a paramount concern.

The security feature on both the Am8753 and the 8751 is activated with a single bit, and prohibits all external read-out of the on-chip EPROM contents. After programming the Am8753, the security bit is activated by using the same programming setup, except that $P_{2,6}$ is held High.

With the EPROM security bit programmed, retrieval of internal program memory is not possible. A secured program memory looks like a blank array of all ones, and this property can be used to verify that the EPROM is secured. The programmed security bit also prohibits further device programming and the execution of external program memory. Full functionality and programmability may be restored by erasing the EPROM, thus clearing the security bit.

With 8K bytes of EPROM on the Am8753, many designers overcome the program size versus security dilemma that they previously faced. There is a high correlation between concern for security and shrinking board space. As more and more features are loaded onto single chips, many applications are differentiated by little more than the EPROM code on-board. The closer customers are to a one-chip system, the more likely they are to take copyright protection into their own hands and opt for a single chip with security.

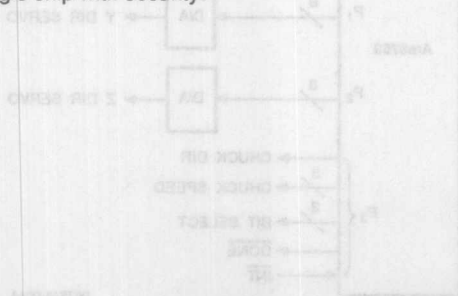


Figure 7-1: The Am8753 in a Machine Control Application

AMD's state-of-the-art EPROM technology also offers an advantage when it comes to programming time. The Am8753 uses a fast adaptive programming algorithm rather than a conventional "dumb" programming technique, where every byte is programmed with a 50 ms, 21 V pulse. To program 8K bytes with a conventional algorithm takes 6.82 minutes (50 ms/byte X 8K bytes).

Conventional programming can be used for the Am8753, but AMD found the lengthy programming time unacceptable for its manufacturing test flow, and knows that volume 8751 users have already come to the same conclusion in their applications. AMD's adaptive programming algorithm pulses each byte with the same 21 V, but only a 3 ms pulse is required.

Because of AMD's developments in EPROM technology, the typical EPROM cell will program to threshold in less than 1 ms plus 2 ms of "overprogramming" to insure data retention. Thus with adaptive programming, AMD's typical programming time will be 3 ms/byte x 8K byte/Am8753 = 24 s. This represents a 15-to-1 speed advantage.

This time savings, 24 seconds for the Am8753 compared to conventional programming of 6.82 minutes, and 12 seconds for the AMD's 8751 compared to 3.41 minutes is a tremendous advantage. To pass this time savings on to the customer, AMD has arranged with Data I/O to support the adaptive algorithm. Data I/O has Am8753-compatible software available today.

If the designer needs more memory, without sacrificing I/O or security, the Am8753 is a worthy candidate. For those familiar with the 8051 Family, previous experience is directly applicable. Designers can take advantage of the familiar chip-count reduction and board-space savings possible with increased on-board memory. They will also find the programming support, with its inherent time savings, a valuable addition.

CHAPTER 8

Enhanced NMOS Devices

8-1

80515/80535 (data sheet)

8-1

Heating and Air Conditioning Control in Cars with the
80515 Microcontroller

8-35

80515/80535

8-Bit Single-Chip Microcontroller



DISTINCTIVE CHARACTERISTICS

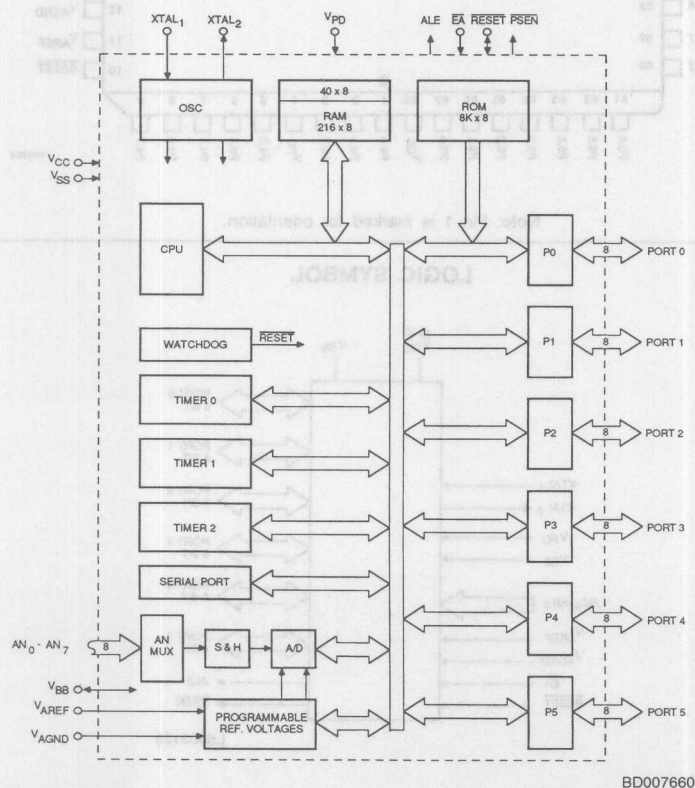
- 8K x 8 ROM (80515 only)
- 256 x 8 RAM
- Six 8-bit ports; 48 I/O lines
- Three 16-bit Timer/Event Counters
- Reload, capture, compare capabilities on Timer 2
- Full-Duplex Serial Port
- Twelve Interrupt Sources; four priority levels
- 8-bit A/D Converter
- Upward-compatible with 8051
- 16-bit Watchdog Timer
- VPD provides standby current for 40 bytes of RAM
- Boolean processor
- 256 bit-addressable locations
- Most instructions execute in 1 μ s
- 64K bytes Program Memory space
- 64K bytes Data Memory space

GENERAL DESCRIPTION

The 80515/80535 is a stand-alone, high-performance, single-chip microcontroller based on the 8051 architecture. While maintaining all the 8051 operating characteristics, the 80515/80535 incorporates several enhancements which significantly increase design flexibility and overall system

performance. With on-board A/D Converter and Watchdog Timer, the 80515 is ideal for motor control applications ranging from automotive engines to vending machines. The 80535 is identical to the 80515 except that it lacks the on-chip ROM.

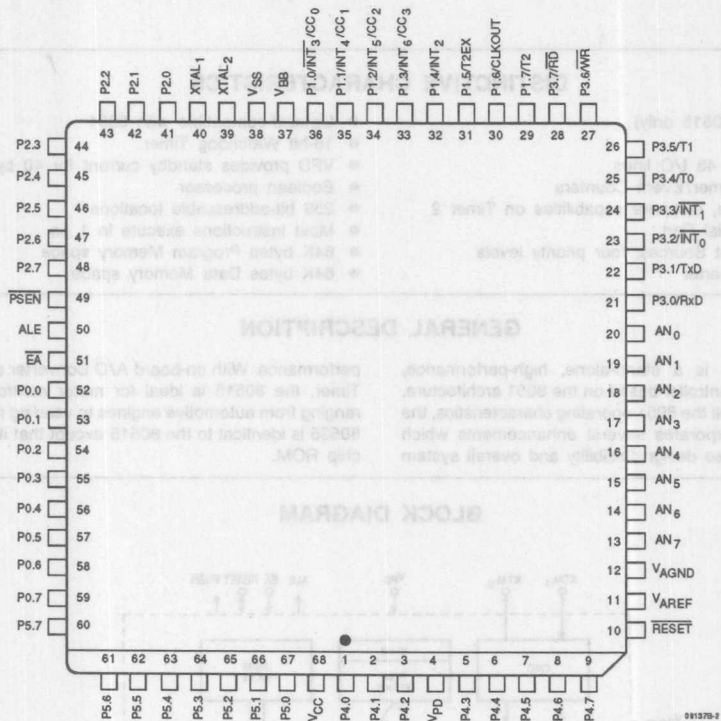
BLOCK DIAGRAM



BD007660

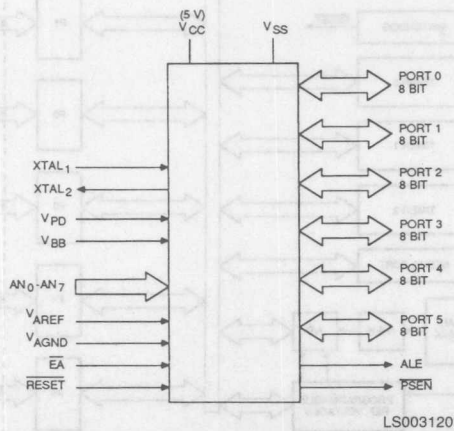
Publication # 09137 Rev. B Amendment /0
Issue Date: December 1987

CONNECTION DIAGRAM Top View



Note: Pin 1 is marked for orientation.

LOGIC SYMBOL



ORDERING INFORMATION

Commodity Products

AMD commodity products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of: **a. Temperature Range**

b. Package Type

c. Device Number

Port	Symbol	Function
P2.0	RD	External Data Memory Read
P2.1	RD	External Data Memory Read
P2.2	RD	External Data Memory Read
P2.3	RD	External Data Memory Read
P2.4	RD	External Data Memory Read
P2.5	RD	External Data Memory Read
P2.6	RD	External Data Memory Read
P2.7	RD	External Data Memory Read
P2.8	RD	External Data Memory Read
P2.9	RD	External Data Memory Read
P2.10	RD	External Data Memory Read
P2.11	RD	External Data Memory Read
P2.12	RD	External Data Memory Read
P2.13	RD	External Data Memory Read
P2.14	RD	External Data Memory Read
P2.15	RD	External Data Memory Read
P2.16	RD	External Data Memory Read
P2.17	RD	External Data Memory Read
P2.18	RD	External Data Memory Read
P2.19	RD	External Data Memory Read
P2.20	RD	External Data Memory Read
P2.21	RD	External Data Memory Read
P2.22	RD	External Data Memory Read
P2.23	RD	External Data Memory Read
P2.24	RD	External Data Memory Read
P2.25	RD	External Data Memory Read
P2.26	RD	External Data Memory Read
P2.27	RD	External Data Memory Read
P2.28	RD	External Data Memory Read
P2.29	RD	External Data Memory Read
P2.30	RD	External Data Memory Read
P2.31	RD	External Data Memory Read
P2.32	RD	External Data Memory Read
P2.33	RD	External Data Memory Read
P2.34	RD	External Data Memory Read
P2.35	RD	External Data Memory Read
P2.36	RD	External Data Memory Read
P2.37	RD	External Data Memory Read
P2.38	RD	External Data Memory Read
P2.39	RD	External Data Memory Read
P2.40	RD	External Data Memory Read
P2.41	RD	External Data Memory Read
P2.42	RD	External Data Memory Read
P2.43	RD	External Data Memory Read
P2.44	RD	External Data Memory Read
P2.45	RD	External Data Memory Read
P2.46	RD	External Data Memory Read
P2.47	RD	External Data Memory Read
P2.48	RD	External Data Memory Read
P2.49	RD	External Data Memory Read
P2.50	RD	External Data Memory Read
P2.51	RD	External Data Memory Read
P2.52	RD	External Data Memory Read
P2.53	RD	External Data Memory Read
P2.54	RD	External Data Memory Read
P2.55	RD	External Data Memory Read
P2.56	RD	External Data Memory Read
P2.57	RD	External Data Memory Read
P2.58	RD	External Data Memory Read
P2.59	RD	External Data Memory Read
P2.60	RD	External Data Memory Read
P2.61	RD	External Data Memory Read
P2.62	RD	External Data Memory Read
P2.63	RD	External Data Memory Read
P2.64	RD	External Data Memory Read
P2.65	RD	External Data Memory Read
P2.66	RD	External Data Memory Read
P2.67	RD	External Data Memory Read
P2.68	RD	External Data Memory Read
P2.69	RD	External Data Memory Read
P2.70	RD	External Data Memory Read
P2.71	RD	External Data Memory Read
P2.72	RD	External Data Memory Read
P2.73	RD	External Data Memory Read
P2.74	RD	External Data Memory Read
P2.75	RD	External Data Memory Read
P2.76	RD	External Data Memory Read
P2.77	RD	External Data Memory Read
P2.78	RD	External Data Memory Read
P2.79	RD	External Data Memory Read
P2.80	RD	External Data Memory Read
P2.81	RD	External Data Memory Read
P2.82	RD	External Data Memory Read
P2.83	RD	External Data Memory Read
P2.84	RD	External Data Memory Read
P2.85	RD	External Data Memory Read
P2.86	RD	External Data Memory Read
P2.87	RD	External Data Memory Read
P2.88	RD	External Data Memory Read
P2.89	RD	External Data Memory Read
P2.90	RD	External Data Memory Read
P2.91	RD	External Data Memory Read
P2.92	RD	External Data Memory Read
P2.93	RD	External Data Memory Read
P2.94	RD	External Data Memory Read
P2.95	RD	External Data Memory Read
P2.96	RD	External Data Memory Read
P2.97	RD	External Data Memory Read
P2.98	RD	External Data Memory Read
P2.99	RD	External Data Memory Read
P2.100	RD	External Data Memory Read

Valid Combinations

N80515
N80535

c. DEVICE NUMBER/DESCRIPTION

80515 (ROM Version)
80535 (ROM-less Version)
8-Bit Single-Chip Microcontrollers

b. PACKAGE TYPE

N = 68-Pin Plastic Leaded Chip Carrier (PL 068)

a. TEMPERATURE RANGE

Blank = Commercial (0 to +70°C)

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released valid combinations, and to obtain additional data on AMD's standard military grade products.

PIN DESCRIPTION

Port 0 Port 0 (Input/Output; Open Drain)

Port 0 is an open-drain bidirectional I/O port. Port 0 pins that have "1"s written to them float, and in that state can be used as high-impedance inputs.

Port 0 is also the multiplexed LOW-order address and data bus during accesses to external Program and Data Memory. In this application it uses strong internal pullups when emitting "1"s. Port 0 can sink/source eight LS TTL inputs. Port 0 also outputs the code bytes during program verification in the 80515. External pullups are required during program verification.

Port 1 Port 1 (Input/Output)

Port 1 is an 8-bit bidirectional I/O port with internal pullups. Port 1 output buffers can sink/source four LS TTL inputs. Port 1 pins that have "1"s written to them are pulled HIGH by the internal pullups and — when in this state — can be used as inputs. As inputs, Port 1 pins that are externally being pulled LOW will source current (I_{IL} on the data sheet) because of the internal pullups. Port 1 also receives the LOW-order address bytes during program verification.

Port 1 also serves the functions of various special features as listed below:

Port	Symbol	Alternate Function
P1.0	INT3/CC0	External interrupt 3 input, compare 0 output, capture 0 input
P1.1	INT4/CC1	External interrupt 4 input, compare 1 output, capture 1 input
P1.2	INT5/CC2	External interrupt 5 input, compare 2 output, capture 2 input
P1.3	INT6/CC3	External interrupt 6 input, compare 3 output, capture 3 input
P1.4	INT2	External interrupt 2 input
P1.5	T2EX	Timer 2 external reload trigger input
P1.6	CLKOUT	System clock output
P1.7	T2	Timer 2 external counter input

Port 2 Port 2 (Input/Output)

Port 2 is an 8-bit bidirectional I/O port with internal pullups. The Port 2 output buffers can sink/source four LS TTL inputs. Port 2 pins having "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 2 pins externally being pulled LOW will source current (I_{IL}) because of the internal pullups.

Port 2 emits the HIGH-order address byte during fetches from External Program Memory and during accesses to External Data Memory that use 16-bit addresses (MOVX @ DPTR). In this application it uses strong internal pullups when emitting "1"s. During accesses to External Data Memory that use 8-bit addresses (MOVX @ Ri), Port 2 emits the contents of the P2 Special Function register.

Port 2 also receives the HIGH-order address bits during ROM verification.

Port 3 Port 3 (Input/Output)

Port 3 is an 8-bit bidirectional I/O port with internal pullups. The Port 3 output buffers can sink/source four LS TTL inputs. Port 3 pins that have "1"s written to them are pulled

HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 3 pins externally being pulled LOW will source current (I_{IL}) because of the pullups.

Port 3 also serves the functions of various special features as listed below:

Port	Symbol	Alternate Function
P3.0	RXD	Serial input port
P3.1	TXD	Serial output port
P3.2	INT0	External interrupt 0 input, timer 0 gate control
P3.3	INT1	External interrupt 1 input, timer 1 gate control
P3.4	T0	Timer 0 external counter input
P3.5	T1	Timer 1 external counter input
P3.6	WR	External Data Memory write strobe
P3.7	RD	External Data Memory read strobe

Port 4 Port 4 (Input/Output)

Port 4 is an 8-bit quasi-bidirectional I/O port. Port 4 can sink/source four LS-TTL loads.

Port 5 Port 5 (Input/Output)

Port 5 is an 8-bit quasi-bidirectional I/O port. Port 5 can sink/source four LS-TTL loads.

RST Reset (Input; Active LOW)

A LOW level on this pin for the duration of two machine cycles while the oscillator is running resets the 80515. A small internal pullup resistor permits power-on reset using only a capacitor connected to V_{SS} .

ALE Address Latch Enable (Output; Active HIGH)

Address Latch Enable output pulse for latching the LOW byte of the address during accesses to external memory.

In normal operation ALE is emitted at a constant rate of 1/6 the oscillator frequency, allowing use for external-timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external Data Memory.

PSEN Program Store Enable (Input; Active LOW)

PSEN is the read strobe to External Program Memory. When the 80515 is executing code from External Program Memory, PSEN is activated twice each machine cycle — except that two PSEN activations are skipped during each access to External Data Memory. PSEN is not activated during fetches from Internal Program Memory.

EA External Access Enable (Input; Active LOW)

EA must be externally held LOW to enable the device to fetch code from external Program Memory locations 0000H to 1FFFFH. If EA is held HIGH, the device executes from Internal Program Memory unless the program counter contains an address greater than 1FFFFH. For the 80535, EA must be LOW.

XTAL1 Crystal (Input)

Input to the inverting oscillator amplifier. When an external oscillator is used, XTAL1 should be grounded.

XTAL2 Crystal (Output)

Output of the inverting oscillator amplifier. XTAL2 is also the input for the oscillator signal when using an external oscillator.

VCC Power Supply

Supply voltage during normal operations.

VSS Circuit Ground

V_{PD} Power-Down Supply

If V_{PD} is held within its specs while V_{CC} drops below specs, V_{PD} will provide standby power to 40 bytes of the internal RAM. When V_{PD} is LOW, the RAM's current is drawn from V_{CC}.

V_{AREF} Reference Voltage for the A/D Converter**V_{AGND} Reference Ground for the A/D Converter****AN₀ — AN₇ Multiplexed Analog Inputs****V_{BB} Substrate Pin**

Must be connected to V_{SS} through a capacitor (100 to 1000 nF) for proper operation of the A/D converter.

FUNCTIONAL DESCRIPTION

The architecture of the 80515 is based on the 8051 Microcontroller. The following 8051 features are retained in the 80515:

- Instruction set
- External memory expansion interface (Port 0 and Port 2)
- Full-duplex serial port
- Timer/counters 0 and 1
- Alternate functions on Port 3
- The lower 128 bytes of internal RAM and the lower 4 Kbytes of internal ROM.

The 80515 contains an additional 128 byte of internal RAM and 4 Kbyte of internal ROM; thus a total of 256 byte RAM and 8 Kbyte ROM on-chip. The 80515 has a third 16-bit timer/controller with a 2:1 prescaler, reload mode, compare and capture capability. It also contains a 16-bit watchdog timer, an 8-bit A/D converter with 8 analog inputs and programmable reference voltages, two additional quasi-bidirectional 8-bit ports, a programmable clock output (fosc/12), a RAM power-down supply, which supplies 40 byte with a typical current of 1 mA, and a powerful interrupt structure with 12 sources and 4 priority levels.

Figure 2 shows a detailed block diagram of the 80515.

CPU

The 80515 is efficient both as a controller and as an arithmetic processor. It has extensive facilities for binary and BCD arithmetic and excels in bit-handling capabilities. Efficient use of Program Memory results from an instruction set consisting of 44% one-byte, 41% two-byte, and 15% three-byte instructions. With a 12-MHz crystal, 58% of the instructions execute in 1.0 μ s.

Memory Organization

The 80515 manipulates operands in the four memory address spaces described below:

Program Memory

The 80515 has 8 Kbyte of on-chip ROM, while the 80535 has no internal ROM. The Program Memory can be externally expanded up to 64 Kbyte. If the EA pin is held HIGH, the 80515 executes out of internal ROM unless the address exceeds 1FFFFH. Locations 2000H through FFFFH are then fetched from the External Program Memory. If the EA pin is held LOW, the 80515 fetches all instructions from the External Program Memory. Since the 80535 has no internal ROM, pin EA must be tied LOW when using this device.

Data Memory

The Data Memory address space consists of an internal and an external memory space. The Internal Data Memory is divided into three physically separate and distinct blocks: the lower 128 byte of RAM; the upper 128 byte of RAM; and the 128-byte special function register (SFR) area. While the upper 128 byte of Data Memory and the SFR area share the same address locations, they are accessed only through different addressing modes. The lower 128 byte of Data Memory can be accessed through direct or register-indirect addressing; the upper 128 byte of RAM can be accessed through register-indirect addressing; and the special function registers are accessible only through direct addressing.

Four 8-register banks occupy locations 0 through 1FH in the lower RAM area. The next 16 bytes, locations 20H through 2FH, contain 128 directly accessible bit locations. The stack can be located anywhere in the Internal Data Memory address space, and the stack depths can be expanded up to 256 byte.

The External Data Memory can be expanded up to 64 Kbyte and can be accessed by instructions that use a 16-bit or 8-bit address.

All registers, except the program counter and the four 8-register banks, reside in the special function register area. The 41 special function registers (SFRs) include arithmetic registers, pointers, and registers that provide an interface between the CPU and the on-chip peripheral functions. There are also 128 directly addressable bits within the SFR area. The special function registers are listed in Table 1.

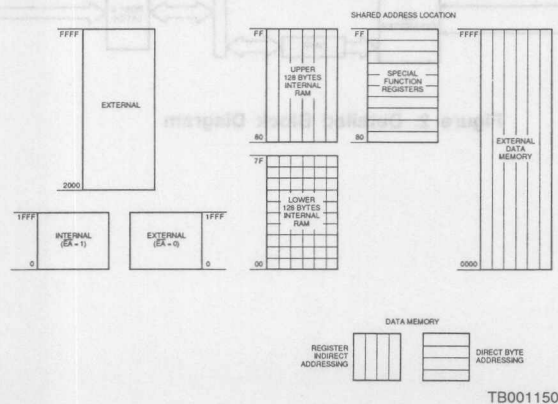


Figure 1. Memory Address Spaces

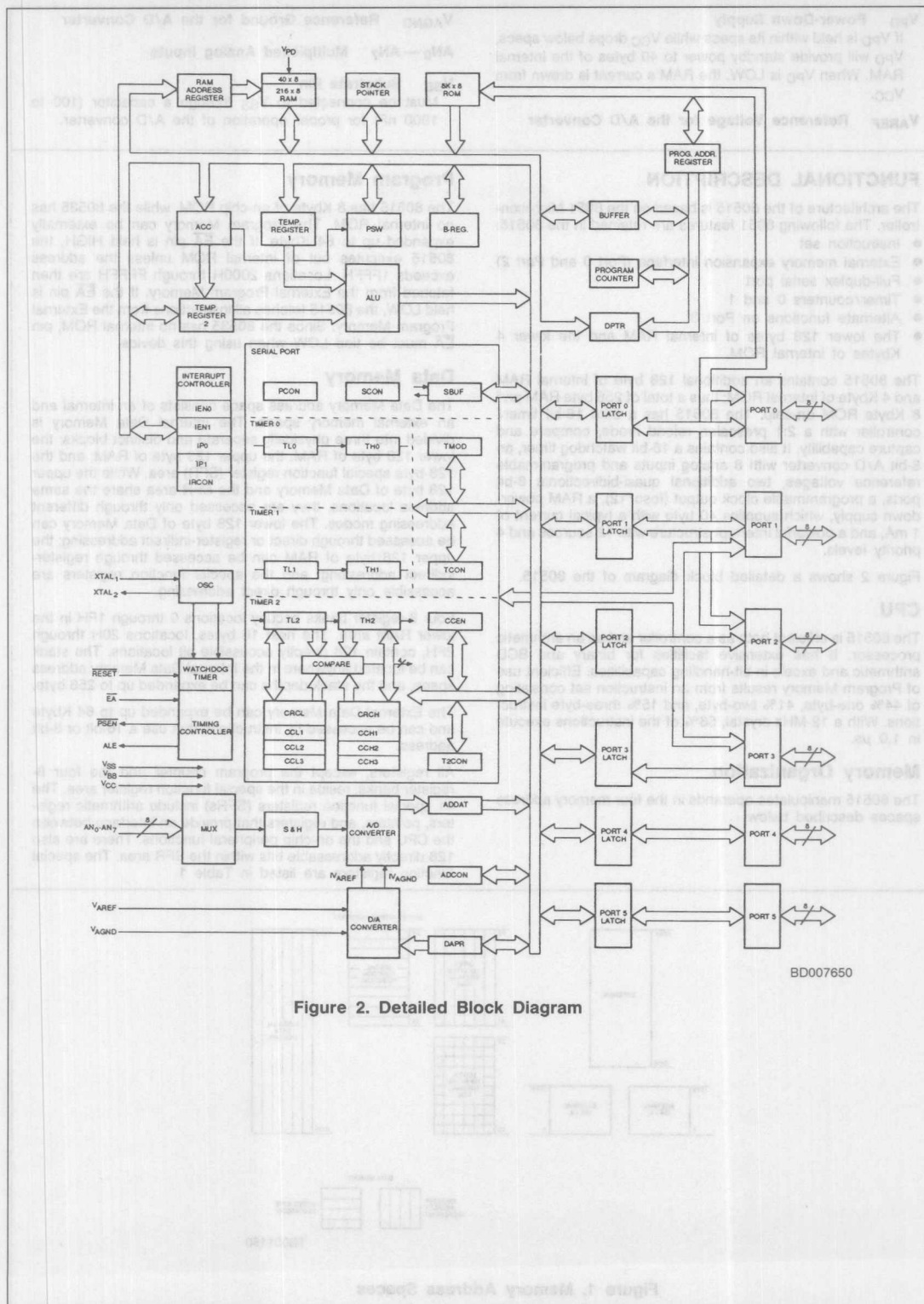


Figure 2. Detailed Block Diagram

TABLE 1. SPECIAL FUNCTION REGISTERS

Addr (HEX)	Symbol	Name	Default After Power-On Reset
* 80	P0	Port 0	11111111
81	SP	Stack Pointer	00000111
82	DPL	Data Pointer, LOW Byte	00000000
83	DPH	Data Pointer, HIGH Byte	00000000
87	PCON	Power Control Register	0XXXXXXX
* 88	TCON	Timer Control Register	00000000
89	TMOD	Timer Mode Register	00000000
8A	TL0	Timer 0, LOW Byte	00000000
8B	TL1	Timer 1, LOW Byte	00000000
8C	TH0	Timer 0, HIGH Byte	00000000
8D	TH1	Timer 1, HIGH Byte	00000000
* 90	P1	Port 1	11111111
* 98	SCON	Serial Port Control Register	00000000
99	SBUF	Serial Port Buffer Register	Indeterminate
* 0A0	P2	Port 2	11111111
* 0A9	IEN0	Interrupt Enable Register 0	00000000
0A9	IP0	Interrupt Priority Register 0	00000000
* 0B0	P3	Port 3	11111111
* 0B9	IEN1	Interrupt Enable Register 1	00000000
0B9	IP1	Interrupt Priority Register 1	00000000
* 0C0	IRCON	Interrupt Request Control Register	00000000
0C1	CCEN	Compare/Capture Enable Register	00000000
0C2	CCL1	Compare/Capture Register 1, LOW Byte	00000000
0C3	CCH1	Compare/Capture Register 1, HIGH Byte	00000000
0C4	CCL2	Compare/Capture Register 2, LOW Byte	00000000
0C5	CCH2	Compare/Capture Register 2, HIGH Byte	00000000
0C6	CCL3	Compare/Capture Register 3, LOW Byte	00000000
0C7	CCH3	Compare/Capture Register 3, HIGH Byte	00000000
* 0C8	T2CON	Timer 2 Control Register	00000000
0CA	CRCL	Compare/Reload/Capture Register, LOW Byte	00000000
0CB	CRCH	Compare/Reload/Capture Register, HIGH Byte	00000000
0CC	TL2	Timer 2, LOW Byte	00000000
0CD	TH2	Timer 2, HIGH Byte	00000000
* 0D0	PSW	Program Status Word Register	00000000
* 0D8	ADCON	A/D-Converter Control Register	00000000
0D9	ADDAT	A/D-Converter Data Register	00000000
0DA	DAPR	D/A-Converter Program Register	00000000
* 0E0	ACC	Accumulator	00000000
* 0E8	P4	Port 4	11111111
* 0F0	B	B Register	00000000
* 0F8	P5	Port 5	11111111

The SFRs marked with an asterisk (*) are both bit and byte-addressable.

Figure 1 illustrates the memory address spaces of the 80515.

I/O Ports

The 80515 has six 8-bit ports. Port 0 is an open-drain bidirectional I/O port, while Ports 1 through 5 are quasi-bidirectional I/O ports with internal pullups. That means, when configured as inputs, Ports 1 through 5 will pull HIGH and will source current when externally pulled LOW. Port 0 will float when configured as input.

Port 0 and Port 2 can be used to expand the Program and Data Memory externally. During an access to external memory, Port 0 emits the LOW-order address byte and reads/writes the data byte, while Port 2 emits the HIGH-order address byte. In this function, Port 0 is an open-drain port, but uses a strong internal pullup FET.

Timer/Counters

The 80515 contains three 16-bit timer/counters which are useful in many applications for timing and counting. The input

clock for each timer/counter is 1/12 of the oscillator frequency in the timer operation or can be taken from an external clock source for the counter operation (maximum count rate is 1/24 of the oscillator frequency).

Timer/Counters 0 and 1

These timer/counters can operate in four modes:

Mode 0: 8-bit timer/counter with 32:1 prescaler

Mode 1: 16-bit timer/counter

Mode 2: 8-bit timer/counter with 8-bit auto-reload

Mode 3: Timer/counter 0 is configured as one 8-bit timer/counter and one 8-bit timer; timer/counter 1 in this mode holds its count.

External inputs $\overline{INT_0}$ and $\overline{INT_1}$ can be programmed to function as a gate for timer/counters 0 and 1 to facilitate pulse width measurements.

Timer 2

The term "timer 2" refers to a complex circuit consisting of the following registers:

T2CON	Timer 2 control register
TL2	Timer 2 register, low-byte
TH2	Timer 2 register, high-byte
CRCL	Compare/reload/capture register, low-byte
CRCH	Compare/reload/capture register, high-byte
CCL1	Compare/capture register 1, low-byte
CCH1	Compare/capture register 1, high-byte
CCL2	Compare/capture register 2, low-byte
CCH2	Compare/capture register 2, high-byte
CCL3	Compare/capture register 3, low-byte
CCH3	Compare/capture register 3, high-byte
CCEN	Compare/capture enable register

For brevity, the double-byte compare/reload/capture register is called the CRC register, the three double-byte compare/capture registers are called CC registers 1 to 3.

Six bits of Port 1 are used by the timer 2 circuit for special functions:

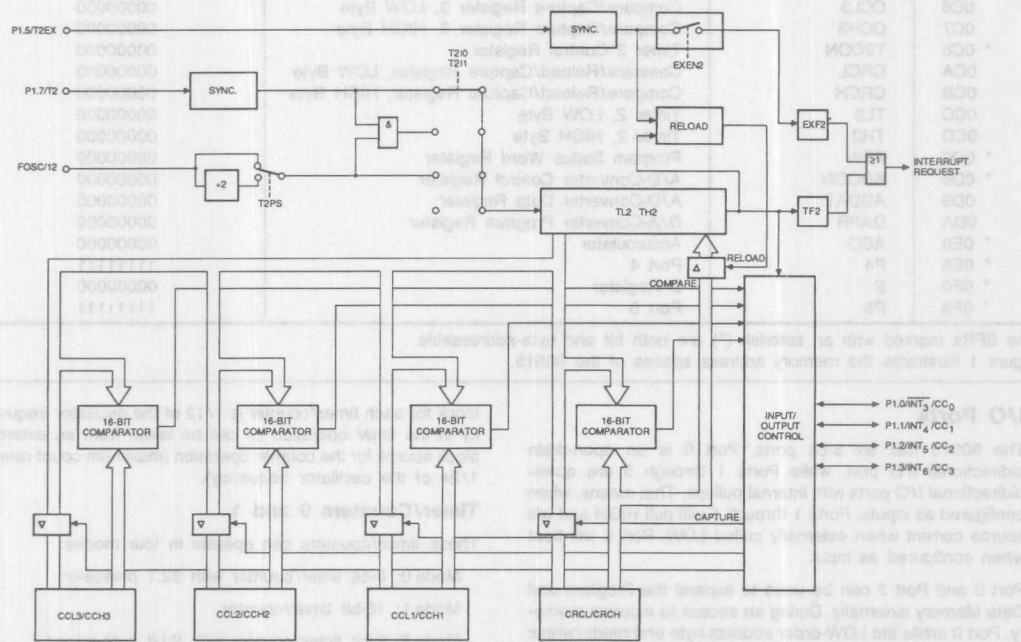
P1.0/INT ₃ /CC ₀	Compare output/capture input for the CRC register
P1.1/INT ₄ /CC ₁	Compare output/capture input for CC register 1
P1.2/INT ₅ /CC ₂	Compare output/capture input for CC register 2
P1.3/INT ₆ /CC ₃	Compare output/capture input for CC register 3
P1.5/T2EX	External reload trigger input
P1.7/T2	External count or gate input to timer 2

To use the special functions on pins P1.5/T2EX and P1.7/T2 a one (1) must first be written into the appropriate bit latches. For pins P1.0 to P1.3, it depends on the special function whether the bit latches must contain a one (1) or not. Should those pins be used as interrupt or capture inputs, the corresponding bit latches must contain a one (1). If those pins are used as compare outputs, the value written to the bit latches depends on the compare modes established.

In addition to the operational modes "timer" or "counter," timer 2 provides the features of:

- 16-bit reload
- 16-bit compare
- 16-bit capture

Figure 3 shows a block diagram of the timer 2 circuit.



BD007640

Figure 3. Block Diagram of Timer/Counter 2

The timer 2 can operate either as timer, event counter, or gated timer. In timer function, the count rate is derived from the oscillator frequency. A 2:1 prescaler offers the possibility to select a count rate of 1/12 or 1/24 of the oscillator frequency. Thus, the 16-bit timer 2 register (consisting of TL2 and TH2) is incremented every machine cycle or every second machine cycle. The prescaler is selected by bit T2PS in special function register T2CON (see Figure 4). If T2PS is

cleared, the input frequency is 1/12 of the oscillator frequency; if T2PS is set, the 2:1 prescaler gates 1/24 of the oscillator frequency to the timer.

In gated timer function, the external input pin T2 (P1.7) functions as a gate to the input of timer 2. If T2 is high, the counted input is gated to the timer. T2 = 0 stops the counting procedure. This will facilitate pulse width measurements.

T2PS	I3FR	I2FR	T2RI	T2R0	T2CM	T2I1	T2I0	BIT
0CFH	0CEH	0CDH	0CCH	0CBH	0CAH	0C9H	0C8H	ADDRESS
SYMBOL		POSITION	FUNCTION					
T2I0	T2I1	T2CON.0 T2CON.1	Timer 2 Input Selection. See Table 2.					
T2CM		T2CON.2	Compare Mode Bit. When set, compare mode 1 is selected. T2CM = 0 selects compare mode 0.					
T2R0	T2R1	T2CON.3 T2CON.4	Timer 2 Reload Mode Selection. See Table 3.					
I2FR		T2CON.5	External Interrupt 2 Falling/Rising Edge Flag. When set, the interrupt 2 request flag IEX2 will be set on a positive transition at pin P1.4/INT ₂ . I2FR = 0 specifies external interrupt 2 to be negative-transition active.					
I3FR		T2CON.6	External Interrupt 3 Falling/Rising Edge Flag. When set, the interrupt 3 request flag IEX3 will be set on a positive transition at pin P1.0/INT ₃ /CC ₀ . I3FR = 0 specifies external interrupt 3 to be negative-transition active.					
T2PS		T2CON.7	Prescaler Select Bit. When set, timer 2 is clocked in the "timer" or "gated timer" function with 1/24 of the oscillator frequency. T2PS = 0 gates fosc/12 to timer 2. T2PS must be 0 for the counter operation of timer 2.					

Figure 4. Timer 2 Control Register T2CON (0C8H)

In counter function, the timer 2 register is incremented in response to a 1-to-0 transition at its corresponding external input pin T2 (P1.7). In this function, the external input is sampled during S5P2 of every machine cycle. When the samples show a HIGH in one cycle and a LOW in the next cycle, the count is incremented. The new count value appears in the register during S1P1 of the cycle following the one in which the transition was detected. Since it takes two machine cycles (24 oscillator periods) to recognize a 1-to-0 transition, the maximum count rate is 1/24 of the oscillator frequency. There are no restrictions on the duty cycle of the external input signal, but to ensure that a given level is sampled at least once before it changes, it should be held for at least one full machine cycle.

Note: The prescaler must be off for proper counter operation of timer 2, that means T2PS must be 0.

In either case, no matter whether timer 2 is configured as timer, event counter, or gated timer, a rolling over of the count from all 1s to all 0s sets the timer 2 overflow flag TF2 (bit 6 in SFR IRCON, Interrupt Request Control) which can generate an interrupt.

The input clock to timer 2 is selected by bits T2I0, T2I1, and T2PS as listed in Table 2.

TABLE 2. TIMER 2 INPUT SELECTION

T2I1	T2I0	Function
0	0	No Input Selected, Timer 2 Stops
0	1	Timer Function, Input Frequency = fosc/12 (T2PS = 0) or fosc/24 (T2PS = 1)
1	0	Counter Function, External Input Signal at Pin T2/P1.7
1	1	Gated Timer Function. Input Controlled by Pin T2/P1.7

Reload

The reload mode for timer 2 is selected by bits T2R0 and T2R1 in SFR T2CON as illustrated in Table 3. In mode 0, when timer 2 rolls over from all 1s to all 0s, it not only sets TF2 but also causes the timer 2 registers to be loaded with the 16-bit value in the CRC register which is preset by software. The reload will happen in the same machine cycle in which TF2 is set, thus overwriting the count value 0000H. In mode 1, a 16-bit reload from the CRC register is caused by a negative transition at the corresponding input pin T2EX/P1.5. In addition, this transition will set flag EXF2 if bit EXEN2 in SFRIEN1 is set. If the timer 2 interrupt is enabled, setting EXF2 will generate an interrupt. The external input pin T2EX is sampled

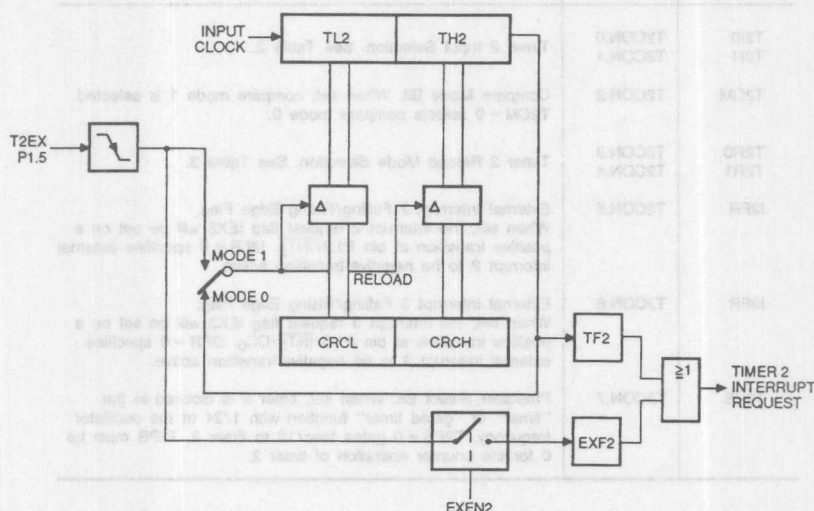
during S5P2 of every machine cycle. When the sampling shows a HIGH in one cycle and a LOW in the next cycle, a transition will be recognized. The reload of the timer 2 registers will then take place during S2P1 of the cycle following the one in which the transition was detected.

Figure 5 shows a functional diagram of the timer 2 reload modes.

TABLE 3. TIMER 2 RELOAD MODE SELECTION

T2R1	T2R0	Mode
0	X	Reload Disabled
1	0	Mode 0: Auto-Reload upon Timer 2 Overflow (TF2)
1	1	Mode 1: Reload upon Falling Edge at Pin T2EX/P1.5

T2R1 = 0 disables the reload modes 0 and 1. If the reload modes are disabled, and if EXEN2 is set, a negative transition at pin T2EX/P1.5 can be used as additional external interrupt input.



TB001180

Figure 5. Timer 2 in Reload Mode

Compare

In compare mode, the 16-bit values stored in the dedicated compare registers are compared with the contents of the timer 2 registers (TL2 and TH2). If the count value in the timer 2 registers matches the stored one, an appropriate output signal is generated at the corresponding Port 1 pin, and interrupt is requested.

The compare modes are enabled by setting the appropriate bits in SFR CCEN (compare/capture enable register, see Figure 11). There are two different compare modes which are selected by bit T2CM in T2CON.

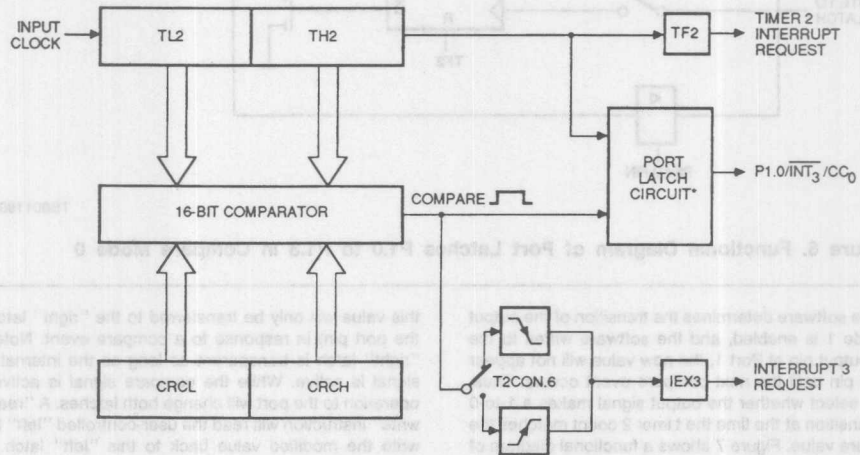
In mode 0, upon a match, the output signal changes from LOW to HIGH. It goes back to a LOW level on timer 2 overflow. As long as compare mode 0 is enabled, the appropriate output pin is controlled by the timer 2 circuit, and not by the user. Writing to the port will operate as a "dummy" instruction. Figure 6 shows a functional diagram of the Port 1 latches P1.0 to P1.3 in compare mode 0. The port latch is directly controlled by the two signals TF2 and compare. The input line from the internal bus and the "write-to-latch" line are disconnected when compare mode 0 is enabled.

Figure 8 shows a functional diagram of timer 2 in the compare mode using the CRC register. Figure 9 shows the compare modes with reference to the CC register 1. Except for the symbolic names, this diagram applies also to the CC registers 2 and 3.

Note that the compare signal is active as long as the timer 2 contents are equal to the one of the appropriate compare register, and that it has a rising and a falling edge. Thus, when using the CRC register, it can be selected whether an interrupt should be caused when the compare signal goes active or inactive, depending on the status of bit I3FR in T2CON. For

the CC registers 1 to 3 an interrupt is always requested when the compare signal goes active.

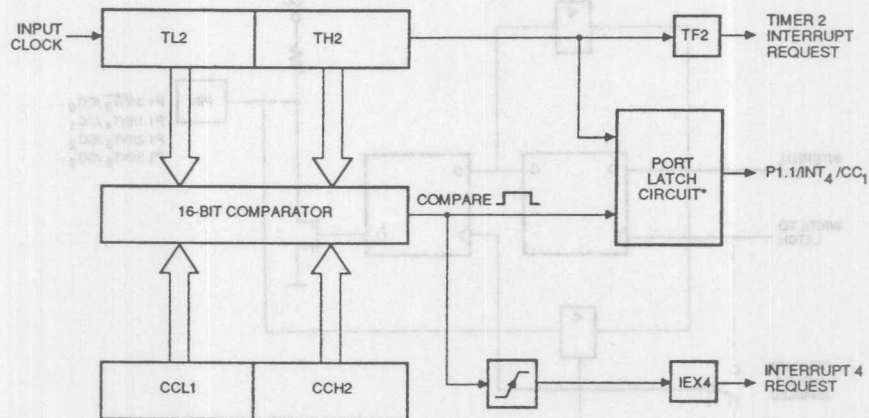
If the compare function is enabled, the corresponding Port 1 pin is dedicated to act as output. The level at the port pin can be read under software control, but the input line from the port pin to the interrupt system is disconnected. Thus, a change of the pin's level will not cause a setting of the corresponding interrupt flag. In the compare modes, the external interrupt request flags can only be set by the internally generated compare signal.



TB001210

*See Figures 6 and 7.

Figure 8. Functional Diagram of Timer 2 in Compare Mode Using CRC Register



TB001220

*See Figures 6 and 7.

Figure 9. Functional Diagram of Timer 2 in Compare Mode Using CC Register 1

Capture

Each of the three compare/capture registers and the CRC register can be used to latch the current 16-bit value in the timer 2 registers TL2 and TH2. Two different modes are provided for this function. In mode 0, an external event causes a latching of the timer 2 contents to a dedicated capture register. In mode 1, a capture will occur upon writing to the low-order byte of the dedicated 16-bit capture register. This mode is provided to allow the software to read the timer 2 contents "on the fly."

In mode 0, the external event causing a capture is:

- for CC registers 1 to 3: a positive transition at pins CC1 to CC3 of CC registers 1 to 3;
- for the CRC register: a positive or negative transition, depending on the status of bit I3FR in SFR T2CON, at pin CC0. If bit I3FR is cleared, a capture occurs in response to a negative transition, if bit I3FR is set in response to a positive transition at pin P1.0/INT₃/CC₀.

In this mode, the appropriate Port 1 pin is used as input, and the port latch must be programmed to contain a one (1). The external input is sampled during S5P2 in every machine cycle. When the sampling shows a LOW (HIGH for input CC0, if it is programmed to be negative-transition-active) in one cycle and a HIGH (LOW) in the next cycle, a transition is recognized. The timer 2 contents are latched to the appropriate capture register during S3P1 in the cycle following the one in which the transition was identified.

In mode 0, a transition on the external capture inputs CC0 to CC3 will also cause setting of the corresponding external

interrupt request flags IEX3 to IEX6. If the interrupts are enabled, an external capture signal will cause the CPU to vector to the appropriate interrupt service routine.

In mode 1, a capture occurs in response to a MOV instruction to the low-order byte of a capture register. The "write-to-register" signal (e.g., "write to CRCL") is used to initiate a capture. The value written to the dedicated capture register is irrelevant for this function. The timer 2 contents will be latched into the appropriate capture register in the cycle following the MOV instruction. In this mode no interrupt request will be generated.

In both capture modes the value latched in the machine cycle in which the capture occurs will be the actual contents of timer 2 in that machine cycle.

Figures 10-1 and 10-2 show functional diagrams of the capture function of timer 2. Figure 10-1 illustrates the operation for the CRC register, while Figure 10-2 shows the operation applying to the compare/capture register 1. This operation is the same for CC register 1 as well as for the CC registers 2 and 3. Substitute the symbols for the corresponding signals and names of CC registers 2 and 3 in Figure 10-2.

The two capture modes can be established individually for each capture register by bits in SFR CCEN (compare/capture enable register), with 2 bits for each capture register. That means, other than for the compare modes, it is possible to select mode 0 for one capture register and mode 1 for another register simultaneously. The bit positions and functions of CCEN are listed in Figure 11.

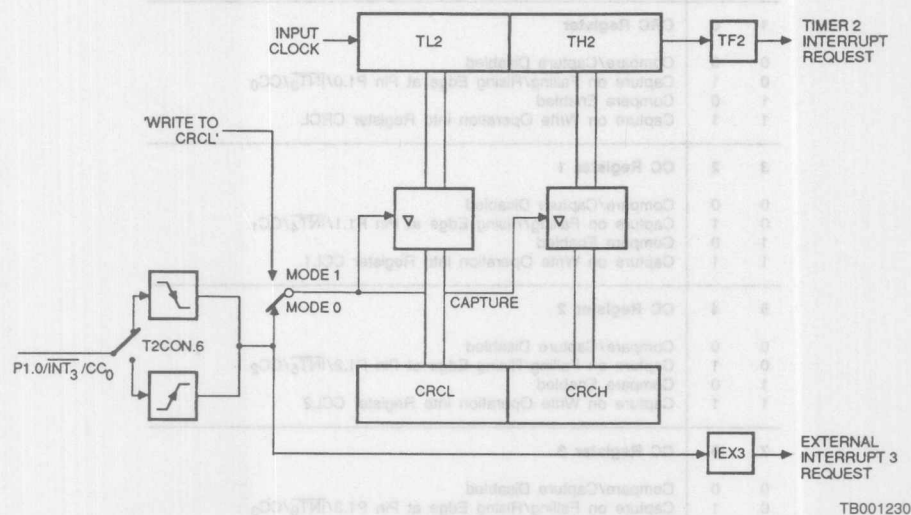


Figure 10-1. Functional Diagram of Timer 2 in Capture Mode Using CRC Register

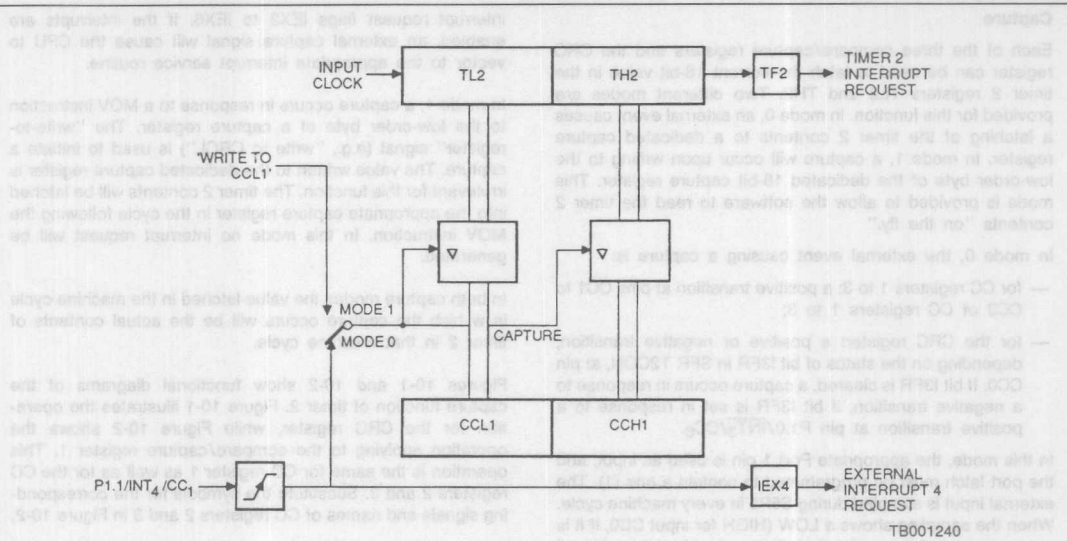


Figure 10-2. Functional Diagram of Timer 2 in Capture Mode Using CC Register 1

7	6	5	4	3	2	1	0	BIT
---	---	---	---	---	---	---	---	-----

BIT	FUNCTION
1 0	CRC Register
0 0	Compare/Capture Disabled
0 1	Capture on Falling/Rising Edge at Pin P1.0/ $\overline{\text{INT}}_3/\text{CC}_0$
1 0	Compare Enabled
1 1	Capture on Write Operation into Register CRCL
3 2	CC Register 1
0 0	Compare/Capture Disabled
0 1	Capture on Falling/Rising Edge at Pin P1.1/ $\overline{\text{INT}}_4/\text{CC}_1$
1 0	Compare Enabled
1 1	Capture on Write Operation into Register CCL1
5 4	CC Register 2
0 0	Compare/Capture Disabled
0 1	Capture on Falling/Rising Edge at Pin P1.2/ $\overline{\text{INT}}_5/\text{CC}_2$
1 0	Compare Enabled
1 1	Capture on Write Operation into Register CCL2
7 6	CC Register 3
0 0	Compare/Capture Disabled
0 1	Capture on Falling/Rising Edge at Pin P1.3/ $\overline{\text{INT}}_6/\text{CC}_3$
1 0	Compare Enabled
1 1	Capture on Write Operation into Register CCL3

Figure 11. Compare/Capture Enable Register CCEN (0C1H)

Watchdog Timer

As a means of safe recovery from software or hardware upset, a watchdog timer is provided in the 80515. If the software fails to clear the watchdog timer at least every 65,532 μ s, an internal hardware reset will be initiated. The software can be designed such that the watchdog times out if the program does not progress properly. The watchdog will also time out if the software error was due to hardware-related problems. This prevents the controller from malfunctioning for longer than 65 ms if a 12 MHz oscillator is used.

The watchdog timer is a 16-bit counter which is incremented once every machine cycle. After an external reset, the watchdog timer is disabled and cleared to 0000H. The counter is started by setting bit SWDT (bit 6 in SFR IEN1). After having been started, the watchdog timer 0000H by cannot be stopped by software. It can only be cleared to 0000H by first setting bit WDT (IEN0.6) and with the next instruction setting SWDT. Bit WDT will automatically be cleared during the third machine cycle after having been set. This double instruction clearing of the watchdog timer was implemented to minimize the chance of unintentionally clearing the watchdog. To prevent the watchdog from overflowing, it must be cleared periodically.

If the software fails to clear the watchdog in time, an internally generated watchdog reset is entered at the counter state FFFCH, which lasts four machine cycles. This internal reset differs from an external reset only to the extent that the watchdog timer is not disabled and bit WDTS (watchdog timer status, bit 6 in SFR IPO) is set. Bit WDTS allows the software to examine from which source the reset was initiated. If it is set, the reset was caused by a watchdog timer overflow.

Serial Port

The serial port of the 80515 permits the full-duplex communication between microcontrollers or between microcontrollers and peripheral devices. The serial port can operate in four modes:

Mode 0: Shift register mode. Serial data enters and exits through Rx/D. Tx/D outputs the shift clock. Eight bits are transmitted/received — eight data bits (LSB) first. The baud rate is fixed at 1/12 of the oscillator frequency.

Mode 1: Ten bits are transmitted (through Rx/D) or received (through Tx/D) — a start bit (0), eight data bits (LSB first), and a stop bit (1). The baud rate is variable.

Mode 2: Eleven bits are transmitted (through Rx/D) or received (through Tx/D) — a start bit (0), eight data bits (LSB first), a programmable 9th data bit, and a stop bit (1). The baud rate is programmable to either 1/32 or 1/64 of the oscillator frequency.

Mode 3: Eleven bits are transmitted (through Tx/D) or received (through Rx/D) — a start bit (0), eight data bits (LSB first), a programmable 9th data bit, and a stop bit (1). Mode 3 is the same as mode 2 in all respects except the baud rate; the baud rate in mode 3 is variable.

The variable baud rates can be generated by timer 1 or an internal baud rate generator.

A/D Converter

The 80515 provides an 8-bit A/D converter with eight multiplexed analog input channels on-chip. In addition, the A/D converter has a sample and hold circuit and offers the feature of software-programmable reference voltages. For the conversion, the method of successive approximation with a capacitor network is used.

Figure 12 shows a block diagram of the A/D converter. There are three user-accessible special function registers: ADCON (A/D converter control register), ADDAT (A/D converter data register), and DAPR (D/A converter program register) for the programmable reference voltages.

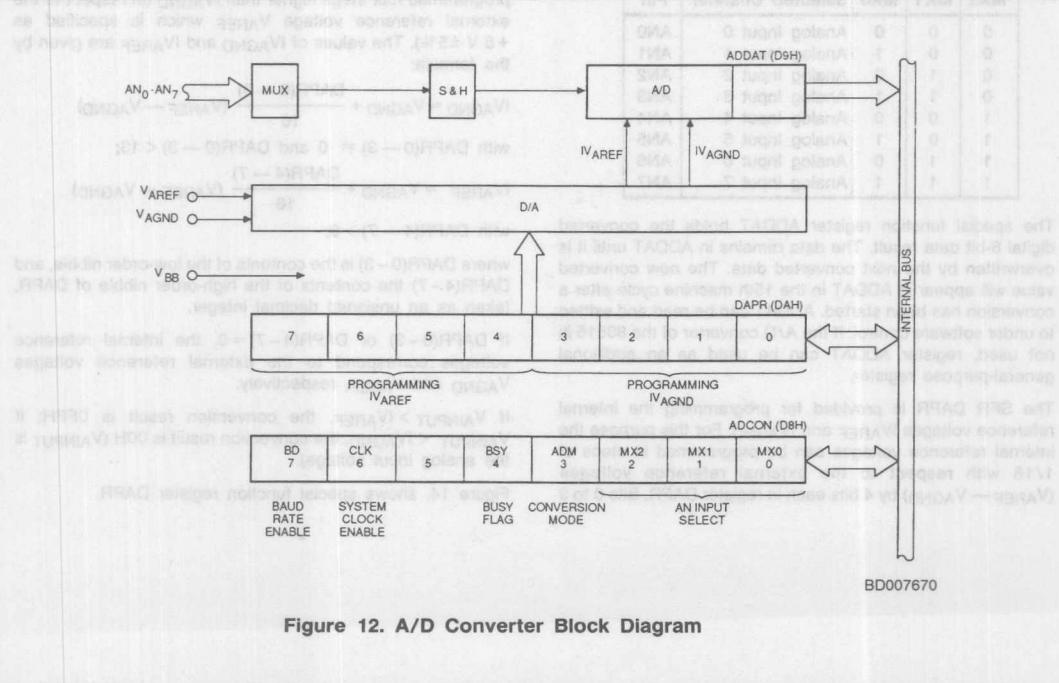


Figure 12. A/D Converter Block Diagram

Special function register ADCON, which is illustrated in Figure 13, is used to select one of the eight analog input channels to be converted, to specify a single or continuous conversion,

and to check the status bit BSY, which signals whether a conversion is in progress or not.

BD	CLK	-	BSY	ADM	MX2	MX1	MX0	BIT
0DFH	0DEH	0DDH	0DCH	0DBH	0DAH	0D9H	0D8H	ADDRESS
SYMBOL	POSITION	FUNCTION						
MX0	ADCON.0	} Analog Input Channel Selection (see Table 4).						
MX1	ADCON.1							
MX2	ADCON.2							
ADM	ADCON.3	A/D Conversion Mode. When set, a continuous is selected. If ADM = 0, the converter stops after one conversion.						
BSY	ADCON.4	Busy Flag. This flag indicates whether a conversion is in progress (BSY = 1) or not (BSY = 0).						
-	ADCON.5	Reserved (must be 0).						
CLK	ADCON.6	System Clock Enable. When set, a clock signal with 1/12 the oscillator frequency is gated to pin P1.6/CLKOUT. CLK = 0 disables the clock output.						
BD	ADCON.7	Baud Rate Enable. When set, the baud rate in mode 1 and 3 of the serial port is taken from the internal baud rate generator.						

Figure 13. A/D Converter Control Register ADCON (0D8H)

TABLE 4. SELECTION OF THE ANALOG INPUT CHANNELS

MX2	MX1	MX0	Selected Channel	Pin
0	0	0	Analog Input 0	AN0
0	0	1	Analog Input 1	AN1
0	1	0	Analog Input 2	AN2
0	1	1	Analog Input 3	AN3
1	0	0	Analog Input 4	AN4
1	0	1	Analog Input 5	AN5
1	1	0	Analog Input 6	AN6
1	1	1	Analog Input 7	AN7

The special function register ADDAT holds the converted digital 8-bit data result. The data remains in ADDAT until it is overwritten by the next converted data. The new converted value will appear in ADDAT in the 15th machine cycle after a conversion has been started. ADDAT can be read and written to under software control. If the A/D converter of the 80515 is not used, register ADDAT can be used as an additional general-purpose register.

The SFR DAPR is provided for programming the internal reference voltages V_{AREF} and V_{AGND} . For this purpose the internal reference voltages can be programmed in steps of 1/16 with respect to the external reference voltages ($V_{AREF} - V_{AGND}$) by 4 bits each in register DAPR. Bits 0 to 3

specify V_{AGND} , while bits 4 to 7 specify V_{AREF} . A minimum of 1 V difference is required between the internal reference voltages for proper operation of the A/D converter. That means the internal reference voltage V_{AREF} must always be programmed four steps higher than V_{AGND} (in respect to the external reference voltage V_{AREF} which is specified as $+5V \pm 5\%$). The values of V_{AGND} and V_{AREF} are given by the formula:

$$V_{AGND} = V_{AGND} + \frac{DAPR(0-3)}{16} (V_{AREF} - V_{AGND})$$

with $DAPR(0-3) \neq 0$ and $DAPR(0-3) < 13$;

$$V_{AREF} = V_{AGND} + \frac{DAPR(4-7)}{16} (V_{AREF} - V_{AGND})$$

with $DAPR(4-7) > 3$;

where $DAPR(0-3)$ is the contents of the low-order nibble, and $DAPR(4-7)$ the contents of the high-order nibble of DAPR, taken as an unsigned decimal integer.

If $DAPR(0-3)$ or $DAPR(4-7) = 0$, the internal reference voltages correspond to the external reference voltages V_{AGND} and V_{AREF} , respectively.

If $V_{AINPUT} > V_{AREF}$, the conversion result is 0FFH; if $V_{AINPUT} < V_{AGND}$, the conversion result is 00H (V_{AINPUT} is the analog input voltage).

Figure 14. shows special function register DAPR.

7	6	5	4	3	2	1	0	BIT
DIGITAL VALUE FOR IVAREF				DIGITAL VALUE FOR IVAGND				

If the external reference voltages $V_{AGND} = 0$ and $V_{AREF} = +5$ V are applied, then the internal reference voltages IV_{AGND} and IV_{AREF} (shown in Table 5) can be adjusted via the special function register DAPR.

Figure 14. D/A Converter Program Register DAPR (0DAH)

TABLE 5. ADJUSTABLE INTERNAL REFERENCE VOLTAGES

Step	DAPR(0 - 3) DAPR(4 - 7)	IVAGND (V)	IVAREF (V)
0	0000	0.0	5.0
1	0001	0.3125	—
2	0010	0.625	—
3	0011	0.9375	—
4	0100	1.25	1.25
5	0101	1.5625	1.5625
6	0110	1.875	1.875
7	0111	2.1875	2.1875
8	1000	2.5	2.5
9	1001	2.8125	2.8125
10	1010	3.125	3.125
11	1011	3.4375	3.4375
12	1100	3.75	3.75
13	1101	—	4.0625
14	1110	—	4.375
15	1111	—	4.6875

Items marked with "—" are not allowed according to the rules listed above (IV_{AREF} at least four steps higher than IV_{AGND}).

A/D Converter Timing and Conversion Time

A conversion is started by writing into special function register DAPR. A "write-to-DAPR" will start a new conversion even if a conversion is currently in progress. The conversion begins with the next machine cycle. The busy flag will be set in the same machine cycle that the "write-to-DAPR" operation occurs. If the value written to DAPR is 00H, meaning that no

adjustment of the internal reference voltages is desired, the conversion needs 15 machine cycles to be completed. Thus, the conversion time is $15 \mu\text{s}$ for 12-MHz oscillator frequency. For each adjustment of the internal reference voltages the conversion takes an additional time of $7 \mu\text{s}$. Thus, if only one reference voltage needs to be programmed, the total conversion time takes 22 machine cycles; if both reference voltages are to be programmed the conversion time lasts 29 machine cycles.

After a conversion has been started by writing into SFR DAPR, the analog voltage at the selected input channel is sampled for five machine cycles ($5 \mu\text{s}$ at 12-MHz oscillator frequency), which will then be held at the sampled level for the rest of the conversion time. The external analog source must be strong enough to source the current in order to load the sample and hold capacitance, being 25 pF , within those five machine cycles.

Conversion of the sampled analog voltage takes place between the 6th and 15th machine cycle after sampling has been completed. In the 15th machine cycle the converted result is moved to ADDAT, the busy flag (BSY) is cleared, and the A/D converter interrupt request flag IADC (bit 0 in SFR interrupt control register IRCON) is set. If a continuous conversion is established, the next conversion is automatically started in the following machine cycle.

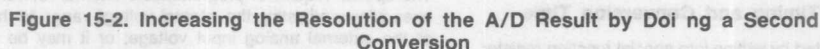
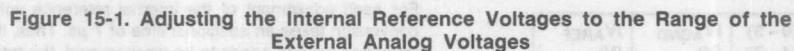
The special feature of programmable internal reference voltages allows adjusting the internal voltage range to the range of the external analog input voltage; or it may be used to increase the resolution of the converted analog input voltage by starting a second conversion with a compressed internal reference voltage range close to the previously measured analog value.

Figures 15-1 and 15-2 illustrate these applications.

TABLE 6. INTERRUPT SOURCES

External Interrupt 0	— A/D Converter Interrupt
Time 0 Interrupt	— Channel Interrupt 5
Channel Interrupt 1	— Channel Interrupt 3
Time 1 Interrupt	— External Interrupt 4
Serial Port Interrupt	— External Interrupt 5
Time 2 Interrupt	— Channel Interrupt 6

Some of these interrupt sources are activated by one, others are activated by two internal or external events. Each interrupt source has its own vector location in the program memory address space 00H to 00FH in the following section. The interrupt sources are classified separately.



The interrupt structure of the 80515 provides 12 interrupt sources and 4 priority levels. The 12 interrupt sources are organized as 6 pairs. Table 6 lists the interrupt sources and pairs of the 80515.

External Interrupt 0	— A/D Converter Interrupt
Timer 0 Interrupt	— External Interrupt 2
External Interrupt 1	— External Interrupt 3
Timer 1 Interrupt	— External Interrupt 4
Serial Port Interrupt	— External Interrupt 5
Timer 2 Interrupt	— External Interrupt 6

The external interrupts 0 and 1 ($\overline{\text{INT}}_0$ and $\overline{\text{INT}}_1$) can each be either level-activated or negative transition-activated, depending on bits IT0 and IT1 in register TCON. The flags that actually generate these interrupts are bits IE0 and IE1 in TCON. When an external interrupt is generated, the flag that generated this interrupt is cleared by the hardware when the service routine is vectored to only if the interrupt was transition-activated. If the interrupt was level-activated, then the external requesting source directly controls the request flag, rather than the on-chip hardware.

The serial port interrupt is generated by the logical OR of RI and TI. Neither of these flags is cleared by hardware when the service routine is vectored to. In fact, the service routine will normally have to determine whether it was RI or TI that generated the interrupt, and the bit will have to be cleared in software.

The timer 2 interrupt is generated by the logical OR of bits TF2 and EXF2 in register IRCON. Neither of these flags is cleared by hardware when the service routine is vectored to. In fact, the service routine may have to determine whether it was TF2 or EXF2 that generated the interrupt, and the bit will have to be cleared in software.

The A/D converter interrupt is generated by bit IADC in register IRCON. It is set in the 15th, 22nd or 29th machine cycle, after a conversion has been started by a "write-to-DAPR," or, if continuous conversions are established, after the last conversion has been completed, depending on whether the internal reference voltages IVAGND and IVAREF have to be adjusted or not. When an A/D converter interrupt is generated, flag IADC will have to be cleared in software.

The external interrupt 2 ($\overline{\text{INT}}_2$) can be either positive or negative transition-activated, depending on bit I2FR in register T2CON. The flag that actually generates this interrupt is bit IEX2 in register IRCON. If an external interrupt 2 is generated, flag IEX2 is cleared by hardware when the service routine is vectored to.

Like the external interrupt 2, the external interrupt 3 can be either positive or negative transition-activated, depending on bit I3FR in register T2CON. The flag that actually generates this interrupt is bit IEX3 in register IRCON. In addition, this flag will be set if a compare event occurs at pin P1.0/ $\overline{\text{INT}}_3$ /CC₀ (timer 2 registers contents matches the contents of the CRC register), regardless of the compare mode established, the transition occurring at the pin, and of the external interrupt 3 being positive or negative transition-activated. Flag IEX3 is cleared by the on-chip hardware when the service routine is vectored to.

The external interrupts 4 ($\overline{\text{INT}}_4$), 5 ($\overline{\text{INT}}_5$), and 6 ($\overline{\text{INT}}_6$) are positive transition-activated. The flags that actually generate these interrupts are bits IEX4, IEX5, and IEX6 in register IRCON. In addition, these flags will be set if a compare event occurs at the corresponding output pin P1.1/ $\overline{\text{INT}}_4$ /CC₁, P1.2/ $\overline{\text{INT}}_5$ /CC₂, and P1.3/ $\overline{\text{INT}}_6$ /CC₃, regardless of the compare mode established and the transition at the respective pin. When an interrupt is generated, the flag that generated it is cleared by the on-chip hardware when the service routine is vectored to.

All of these bits that generate interrupts can be set or cleared by software, with the same result as though they had been set or cleared by hardware. That is, interrupts can be generated or pending interrupts can be canceled in software. The only exceptions are request flags IE0 and IE1. If the external interrupts 0 and 1 are programmed to be level-activated, IE0 and IE1 are controlled by the external source via pin $\overline{\text{INT}}_0$ and $\overline{\text{INT}}_1$, respectively. Thus, writing a one to these bits will not set the request flags IE0 and/or IE1. In this mode, external interrupts 0 and 1 can only be generated in software by writing a 0 to the corresponding pins $\overline{\text{INT}}_0$ (P3.2) and $\overline{\text{INT}}_1$ (P3.3), provided this will not affect any peripheral circuit connected to the pins. Figure 16 shows the special function register IRCON.

Each of these interrupt sources can be individually enabled or disabled by setting or clearing a bit in the special function registers IEN0 and IEN1 (Figures 17-1 and 17-2). Note that IEN0 also contains a global disable bit, EAL, which disables all interrupts at once. Also note that in the 8051 the interrupt priority register IP is located at address 0B8H; in the 80515 this location is occupied by register IEN1.

EXF2	TF2	IEX6	IEX5	IEX4	IEX3	IEX2	IADC	BIT
0C7H	0C6H	0C5H	0C4H	0C3H	0C2H	0C1H	0C0H	ADDRESS
SYMBOL		POSITION	FUNCTION					
IADC		IRCON.0	A/D Converter Interrupt Request Flag. Set by hardware at the end of a conversion. Must be cleared by software.					
IEX2		IRCON.1	External Interrupt 2 Edge Flag. Set by hardware when external interrupt edge was detected. Cleared when interrupt processed.					
IEX3		IRCON.2	External Interrupt 3 Edge Flag. Set by hardware when external interrupt edge was detected or when a compare event occurred at pin P1.0/ $\overline{\text{INT}}_3$ /CC ₀ . Cleared when interrupt processed.					
IEX4		IRCON.3	External Interrupt 4 Edge Flag. Set by hardware when external interrupt edge was detected or when a compare event occurred at pin P1.1/ $\overline{\text{INT}}_4$ /CC ₁ . Cleared when interrupt processed.					
IEX5		IRCON.4	External Interrupt 5 Edge Flag. Set by hardware when external interrupt edge was detected or when a compare event occurred at pin P1.2/ $\overline{\text{INT}}_5$ /CC ₂ . Cleared when interrupt processed.					
IEX6		IRCON.5	External Interrupt 6 Edge Flag. Set by hardware when external interrupt edge was detected or when a compare event occurred at pin P1.3/ $\overline{\text{INT}}_6$ /CC ₃ . Cleared when interrupt processed.					
TF2		IRCON.6	Timer 2 Overflow Flag. Set by a timer 2 overflow and must be cleared by software. If the timer 2 interrupt is enabled, TF2 = 1 will cause an interrupt.					
EXF2		IRCON.7	Timer 2 External Reload Flag. Set when a reload is caused by a negative transition on pin T2EX and EXEN2 = 1. When the timer 2 interrupt is enabled, EXF2 = 1 will cause the CPU to vector to the timer 2 interrupt routine. Can be used as an additional external interrupt when the reload function is not used. EXF2 must be cleared by software.					

Figure 16. Interrupt Request Control Register IRCON (0C0H)

EAL	WDT	ET2	ES	ET1	EX1	ET0	EX0	BIT
0AFH	0AEH	0ADH	0ACH	0ABH	0AAH	0A9H	0A8H	ADDRESS
SYMBOL	POSITION	FUNCTION						
EX0	IEN0.0	Enables or Disables External Interrupt 0. If EX0 = 0, external interrupt 0 is disabled.						
ET0	IEN0.1	Enables or Disables the Timer 0 Overflow Interrupt. If ET0=0, the timer 0 interrupt is disabled.						
EX1	IEN0.2	Enables or Disables External Interrupt 1. If EX1 = 0, external interrupt 1 is disabled.						
ET1	IEN0.3	Enables or Disables the Timer 1 Overflow Interrupt. If ET1=0, the timer 1 interrupt is disabled.						
ES	IEN0.4	Enables or Disables the Serial Port Interrupt. If ES = 0, the serial port interrupt is disabled.						
ET2	IEN0.5	Enables or Disables Timer 2 Overflow or External Reload Interrupt. If ET2 = 0, the timer 2 interrupt is disabled.						
WDT	IEN0.6	Watchdog Timer Reset Flag. Set to initiate a reset of the watchdog timer.						
EAL	IEN0.7	Enables and Disables All Interrupts. If EAL = 0, no interrupt will be acknowledged. If EAL = 1, each interrupt is individually enabled or disabled by setting or clearing its enable bit.						

Figure 17-1. Interrupt Enable Register IEN0 (0A8H)

EXEN2	SWDT	EX6	EX5	EX4	EX3	EX2	EADC	BIT
0BFH	0BEH	0BDH	0BCH	0BBH	0BAH	0B9H	0B8H	ADDRESS
SYMBOL	POSITION	FUNCTION						
EADC	IEN1.0	Enables or Disables the A/D Converter Interrupt 0. If EADC = 0, the A/D converter is disabled.						
EX2	IEN1.1	Enables or Disables External Interrupt 2. If EX2 = 0, external interrupt 2 is disabled.						
EX3	IEN1.2	Enables or Disables External Interrupt 3/Capture/Compare Interrupt 0. If EX3 = 0, external interrupt 3 is disabled.						
EX4	IEN1.3	Enables or Disables External Interrupt 4/Capture/Compare Interrupt 1. If EX4 = 0, external interrupt 4 is disabled.						
EX5	IEN1.4	Enables or Disables External Interrupt 5/Capture/Compare Interrupt 2. If EX5 = 0, external 5 is disabled.						
EX6	IEN1.5	Enables or Disables External Interrupt 6/Capture/Compare Interrupt 3. If EX6 = 0, external 6 is disabled.						
SWDT	IEN1.6	Watchdog Timer Start/Reset Bit. Set to start/reset the watchdog timer.						
EXEN2	IEN1.7	Enables or Disables the Timer 2 External Reload Interrupt. EXEN2 = 0 disables the timer 2 external reload interrupt. The external reload function is not affected by EXEN2.						

Figure 17-2. Interrupt Enable Register IEN1 (0B8H)

Priority Level Structure

Each pair of interrupt sources can be programmed individually to one of four priority levels by setting or clearing one bit in the special function register IP0 and one in IP1 (Figure 18). A low-priority interrupt can itself be interrupted by a high-priority interrupt, but not by another interrupt of the same or a lower priority. An interrupt of the highest priority level cannot be interrupted by another interrupt source.

If two or more requests of different priority levels are received simultaneously, the request of the highest priority is serviced first. If requests of the same priority level are received simultaneously, an internal polling sequence determines which request is serviced first. If requests from two interrupt sources of one interrupt pair are received simultaneously, the "left" interrupt source of each pair is serviced first. Thus within each priority level there is a second priority structure determined by the polling sequence, as follows:

High	→	Low	Priority
Interrupt Source Pair			
IE0		IADC	High ↓ Low
TF0		IEX2	
IE1		IEX3	
TF1		IEX4	
RI + TI		IEX5	
TF2 + EXF2		IEX6	

Note that the "priority within level" structure is only used to resolve simultaneous requests within the same priority level.

Figure 19 shows a block diagram of the priority level structure and Figure 20 illustrates the queuing sources of the 80515's interrupt structure.

-	WDTS	IP0.5	IP0.4	IP0.3	IP0.2	IP0.1	IP0.0
---	------	-------	-------	-------	-------	-------	-------

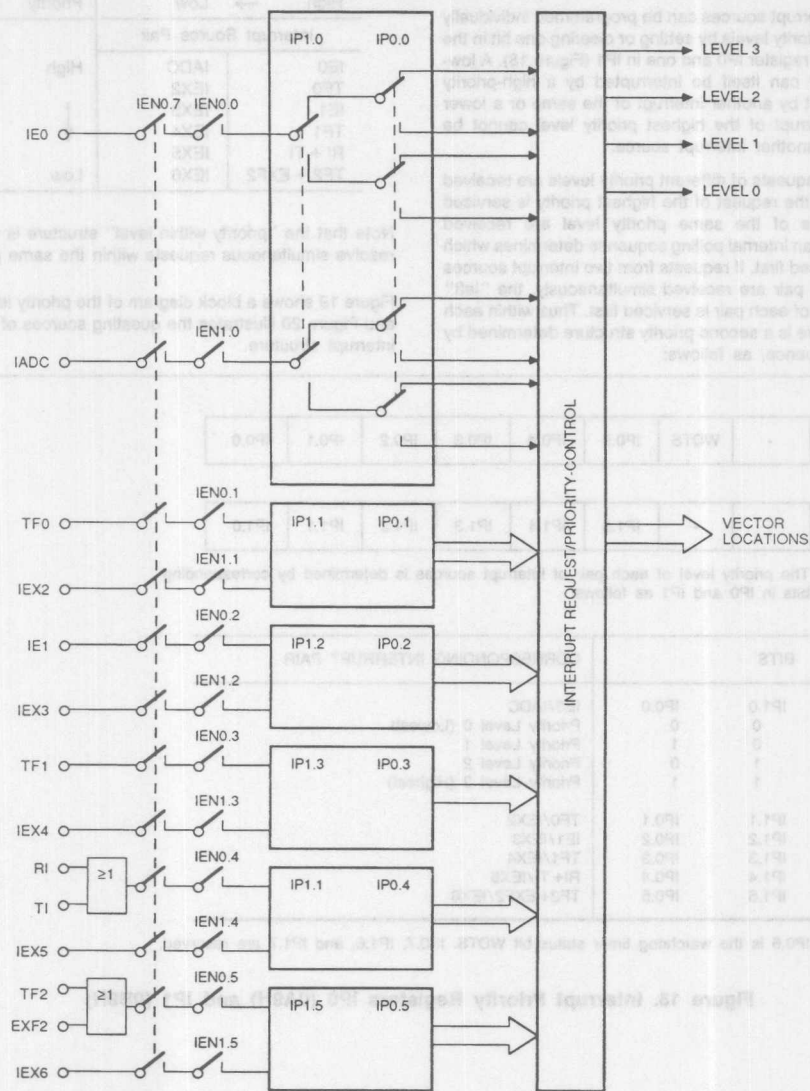
-	IP1.5	IP1.4	IP1.3	IP1.2	IP1.1	IP1.0
---	-------	-------	-------	-------	-------	-------

The priority level of each pair of interrupt sources is determined by corresponding bits in IP0 and IP1 as follows:

BITS		CORRESPONDING INTERRUPT PAIR
IP1.0	IP0.0	IE0/IADC
0	0	Priority Level 0 (Lowest)
0	1	Priority Level 1
1	0	Priority Level 2
1	1	Priority Level 3 (Highest)
IP1.1	IP0.1	TF0/IEX2
IP1.2	IP0.2	IE1/IEX3
IP1.3	IP0.3	TF1/IEX4
IP1.4	IP0.4	RI + TI/IEX5
IP1.5	IP0.5	TF2 + EXF2/IEX6

IP0.6 is the watchdog timer status bit WDTS. IP0.7, IP1.6, and IP1.7 are reserved.

Figure 18. Interrupt Priority Registers IP0 (0A9H) and IP1 (0B9H)



BD007620

Figure 19. Priority Level Structure



How Interrupts Are Handled

The interrupt flags are sampled at S5P2 in every machine cycle. The samples are polled during the following machine cycle. If one of the flags was in a set condition at S5P2 of the preceding cycle, the polling cycle will find it and the interrupt system will generate an LCALL to the appropriate service routine, provided this hardware-generated LCALL is not blocked by any of the following conditions:

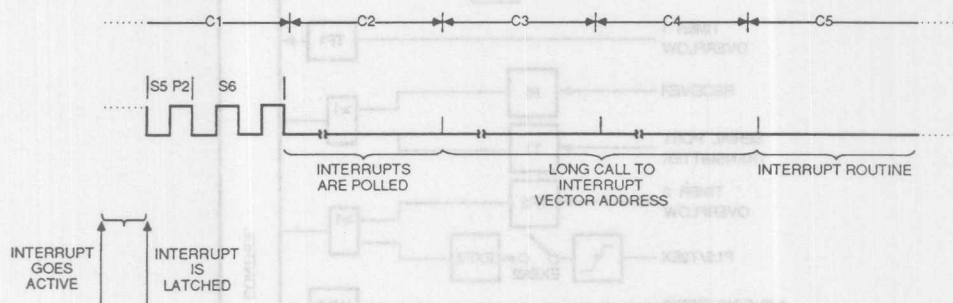
- 1) An interrupt of equal or higher priority is already in progress.
- 2) The current (polling) cycle is not the final cycle in the execution of the instruction in progress.
- 3) The instruction in progress is RETI or any access to registers IEN0, IEN1, IP0, or IP1.

Any of these three conditions will block the generation of the LCALL to the interrupt service routine. Condition 2 ensures

that the instruction in progress will be completed before vectored to any service routine. Condition 3 ensures that if the instruction in progress is RETI or any access to registers IEN0, IEN1, IP0, or IP1, then at least one more instruction will be executed before any interrupt is vectored to.

The polling cycle is repeated with every machine cycle, and the values polled are the values that were present at S5P2 of the previous machine cycle. Note then that if any interrupt flag is active but not being responded to for one of the above conditions, or if the flag is not still active when the blocking condition is removed, the denied interrupt will not be serviced. In other words, the fact that the interrupt flag was once active but not serviced is not remembered. Every polling cycle is new.

The polling cycle/LCALL sequence is illustrated in Figure 21.



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Figure 21. Interrupt Response Timing Diagram

Note that if an interrupt of higher priority level goes active prior to S5P2 in the machine cycle labeled C3 in Figure 21, then in accordance with the above rules it will be vectored to during C5 and C6, without any instruction of the lower priority routine being executed.

Thus the processor acknowledges an interrupt request by executing a hardware-generated LCALL to the appropriate servicing routine. In some cases it also clears the flag that generated the interrupt, and in other cases it doesn't. It never clears the serial port (RI, TI), timer 2 (TF0, EXF2), or A/D converter flags. This has to be done in the user's software. It clears an external interrupt flag (IE0 or IE1) only if it was transition-activated. External interrupt flags IEX2 to IEX6 are always cleared. The hardware-generated LCALL pushes the contents of the program counter onto the stack (but it does not save the PSW) and reloads the PC with an address that depends on the source of the interrupt being vectored to, as shown below.

Source	Vector Address
IE0	0003H
TF0	000BH
IE1	0013H
TF1	001BH
RI + TI	0023H
TF2 + EXF2	002BH
IADC	0043H
IEX2	004BH
IEX3	0053H
IEX4	005BH
IEX5	0063H
IEX6	006BH

Execution proceeds from that location until the RETI instruction is encountered. The RETI instruction informs the processor that this interrupt routine is no longer in progress, then pops the top 2 bytes from the stack and reloads the program counter. Execution of the interrupted program continues from where it was left off.

Note that a simple RET instruction would also have returned execution to the interrupted program, but it would have left the interrupt control system thinking an interrupt was still in progress.

External Interrupts

The external interrupts 0 and 1 can be programmed to be level-activated or negative transition-activated by setting or clearing bit IT0 or IT1, respectively, in register TCON. If ITx = 0 (x = 0 or 1), external interrupt x is triggered by a detected LOW at the INTx pin. If ITx = 1, external interrupt x is negative edge-triggered. In this mode, if successive samples of the INTx pin show a HIGH in one cycle and a LOW in the next cycle, interrupt request flag IEx in TCON is set. Flag bit IEx then requests the interrupt.

If the external interrupt 0 or 1 is level-activated, the external source has to hold the request active until the requested interrupt is actually generated. Then it has to de-activate the request before the interrupt service routine is completed, or else another interrupt will be generated.

The external interrupts 2 and 3 can be programmed to be negative or positive transition-activated by setting or clearing bit I2FR or I3FR in register T2CON. If IxFR = 0 (x = 2 or 3), external interrupt x is negative transition-activated. If IxFR = 1, external interrupt x is triggered by a positive transition.

The external interrupts 4, 5, and 6 are activated by a positive transition. The external timer 2 reload trigger interrupt request flag EXF2 will be activated by a negative transition at pin P1.5/T2EX, but only if bit EXEN2 is set.

Since the external interrupt pins (INT₂ to INT₆) are sampled once each machine cycle, an input HIGH or LOW should hold for at least 12 oscillator periods to ensure sampling. If the external interrupt is transition-activated, the external source has to hold the request pin LOW (HIGH for INT₂ and INT₃, if they are programmed to be negative transition-active) for at least one cycle, and then hold it HIGH (LOW) for at least one cycle to ensure that the transition is recognized so that the corresponding interrupt request flag will be set. The external interrupt request flags will automatically be cleared by the CPU when the service routine is called.

Response Time

If an external interrupt is recognized, its corresponding request flag is set at S5P2 in every machine cycle. The value is not actually polled by the circuitry until the next machine cycle. If the request is active and conditions are right for it to be acknowledged, a hardware subroutine call to the requested service routine will be the next instruction to be executed. The call itself takes two cycles. Thus, a minimum of three complete machine cycles will elapse between activation of an external interrupt request and the beginning of executing the first instruction of the service routine. Figure 21 shows interrupt response timings.

A longer response time would result if the request is blocked by one of the three previously listed conditions. If an interrupt

of equal or higher priority level is already in progress, the additional wait time obviously depends on the nature of the other interrupt's service routine. If the instruction in progress is not in its final cycle, the additional wait time cannot be more than three cycles, since the longest instructions (MUL and DIV) are only four cycles long; and, if the instruction in progress is RETI or an access to registers IEN0, IEN1, IP0, or IP1, the additional wait time cannot be more than five cycles (a maximum of one more cycle to complete the instruction in progress, plus four cycles to complete the next instruction if the instruction is MUL or DIV).

Thus, in a single interrupt system, the response time is always more than three cycles and less than nine cycles.

RAM Backup Power Supply

The power-down mode in the 80515 allows reduction of V_{CC} to zero while saving 40 bytes of the on-chip RAM through a backup supply connected to the V_{PD} pin. In the following, the terms V_{CC} and V_{PD} are used to specify the voltages on pin V_{CC} and pin V_{PD}, respectively.

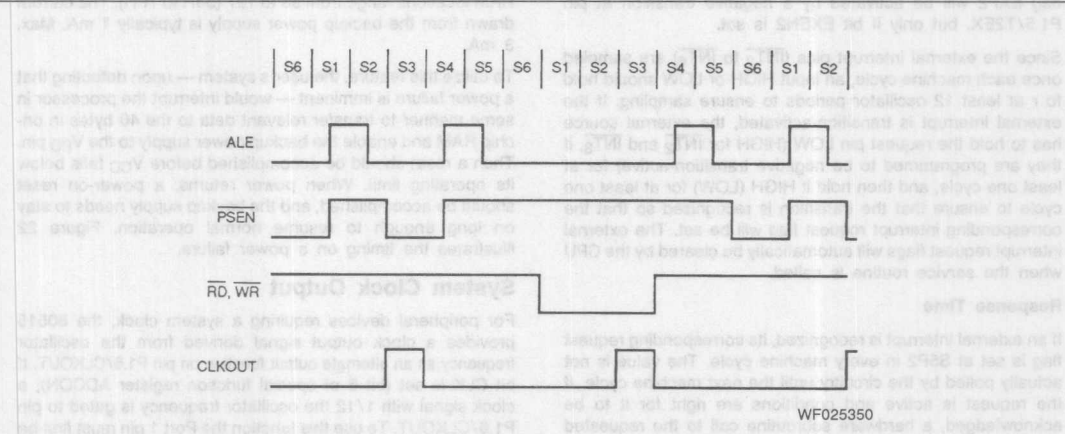
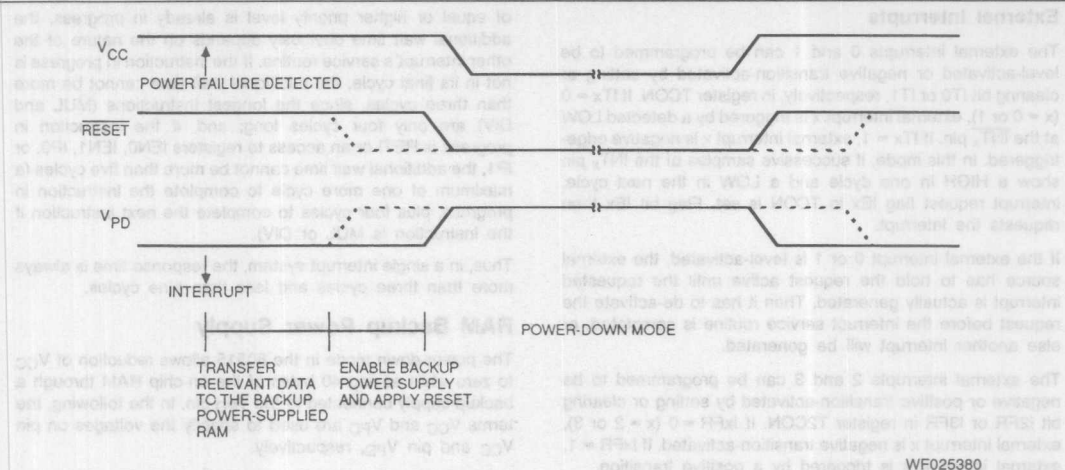
If V_{CC} > V_{PD}, the 40 bytes are supplied from V_{CC}. V_{PD} may then be LOW. If V_{CC} < V_{PD}, the current for the 40 bytes is drawn from V_{PD}. The addresses of these backup-powered RAM locations range from 88 to 127 (58H to 7FH). The current drawn from the backup power supply is typically 1 mA, Max. 3 mA.

To utilize this feature, the user's system — upon detecting that a power failure is imminent — would interrupt the processor in some manner to transfer relevant data to the 40 bytes in on-chip RAM and enable the backup power supply to the V_{PD} pin. Then a reset should be accomplished before V_{CC} falls below its operating limit. When power returns, a power-on reset should be accomplished, and the backup supply needs to stay on long enough to resume normal operation. Figure 22 illustrates the timing on a power failure.

System Clock Output

For peripheral devices requiring a system clock, the 80515 provides a clock output signal derived from the oscillator frequency as an alternate output function on pin P1.6/CLKOUT. If bit CLK is set (bit 6 of special function register ADCON), a clock signal with 1/12 the oscillator frequency is gated to pin P1.6/CLKOUT. To use this function the Port 1 pin must first be programmed to a one (1).

Figure 23 shows the timing of this system clock signal with respect to signal ALE and the internal states. The system clock is HIGH during S3P1 and S3P2 of every machine cycle and LOW during all other states. Thus, the duty cycle of the clock signal is 1:6. Also shown is the timing with respect to an external data memory access. The system clock coincides with the last state (S3) in which an RD or WR signal is active.



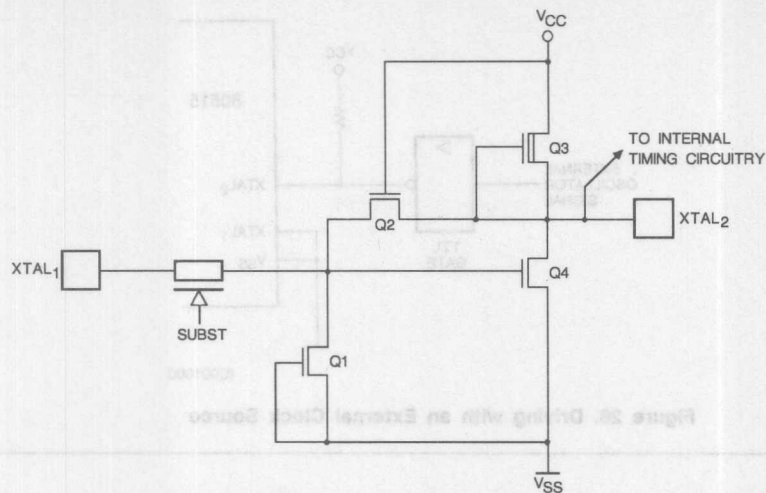
More About the On-Chip Oscillator

The on-chip oscillator of the 80515, like the 8051, is a single-stage inverter (Figure 24), intended for use as a crystal-controlled, positive-reactance oscillator (Figure 25). In this application the crystal is operated in its fundamental response mode as an inductive reactance in parallel resonance with a capacitance external to the crystal. The crystal specifications and capacitance values (C_1 and C_2 in Figure 25) are not critical. 30 pF can be used in these positions at any frequency with good quality crystals. A ceramic resonator can be used in place of the crystal in cost-critical applications. When a ceramic resonator is used, C_1 and C_2 are normally selected to be of somewhat higher values, typically 47 pF. The manufac-

turer of the ceramic resonator should be consulted for recommendations on the values of these capacitors.

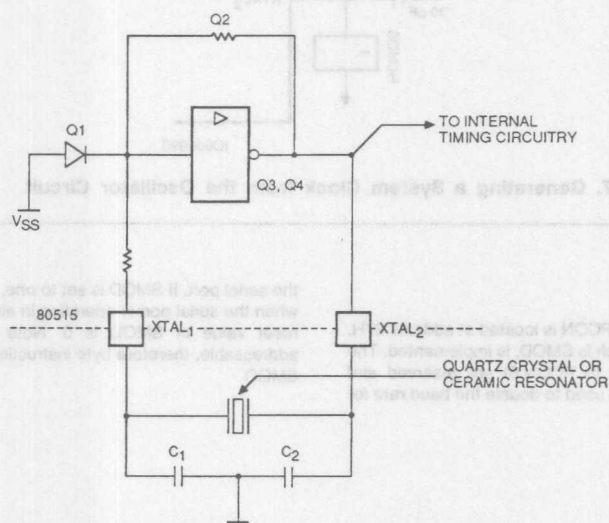
To drive the 80515 with an external clock source, apply the external clock signal to XTAL₂ and ground XTAL₁, as shown in Figure 26. A pullup resistor is suggested because the logic levels at XTAL₂ are not TTL.

Sometimes an external clock with the frequency of the oscillator is needed. For this application the circuit shown in Figure 27 is recommended. The CMOS driver (or inverter) should be placed as close as possible to the oscillator circuit. Be sure to take into account the impedances of the circuit and the CMOS driver input.



IC001020

Figure 24. On-Chip Oscillator Circuitry



IC001010

Figure 25. Using the On-Chip Oscillator

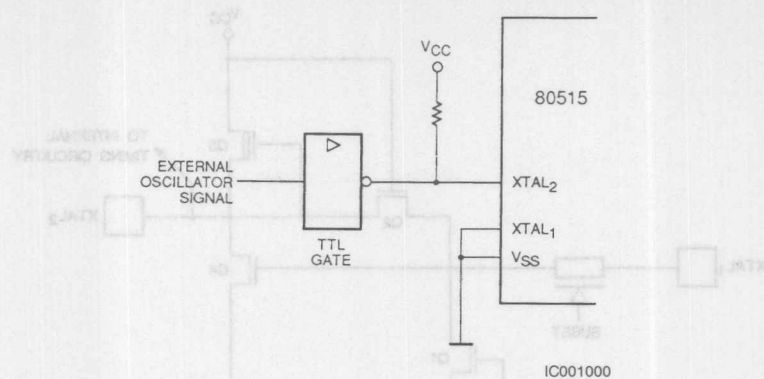


Figure 26. Driving with an External Clock Source

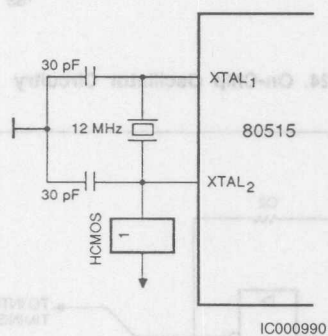


Figure 27. Generating a System Clock from the Oscillator Circuit

Register PCON

The special function register PCON is located at address 87H. In this register only bit 7, which is SMOD, is implemented. The other bit positions (PCON.0 to PCON.6) are reserved and should not be used. SMOD is used to double the baud rate for

the serial port. If SMOD is set to one, the baud rate is doubled when the serial port is operating in either mode 1, 2, or 3. The reset value of SMOD is 0. Note that PCON is not bit-addressable, therefore byte instructions must be used to alter SMOD.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature -65 to +150°C
 Voltage on Any Pin
 with Respect to Ground (V_{SS}) -0.5 to +7.0 V
 Power Dissipation 2 W

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices
 Temperature (T_A) 0 to +70°C
 Supply Voltage (V_{CC}) 5.0 V \pm 10%
 Ground (V_{SS}) 0 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

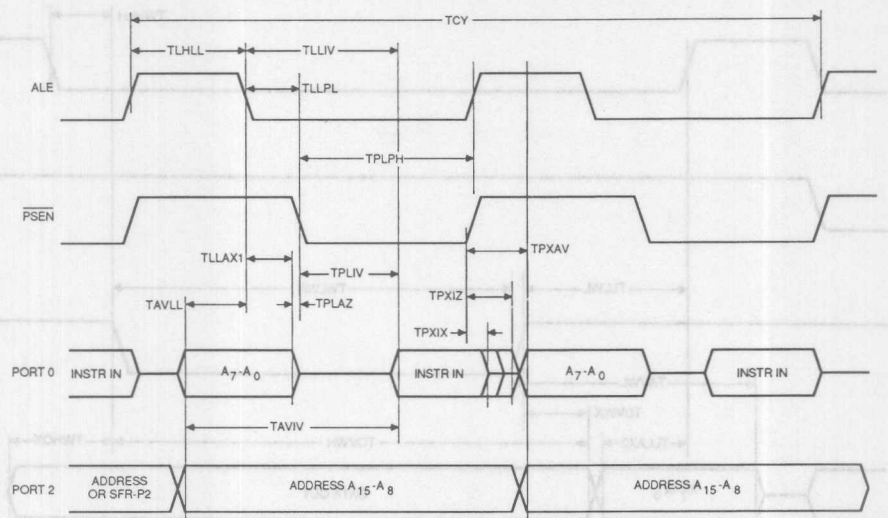
DC CHARACTERISTICS over operating range unless otherwise specified

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Unit
V_{IL}	Input LOW Voltage		-0.5	0.8	V
V_{IH}	Input HIGH Voltage (Except RESET and XTAL ₂)		2.0	$V_{CC} + 0.5$	V
V_{IH1}	Input HIGH Voltage to XTAL ₂)	XTAL ₁ to V_{SS}	2.5	$V_{CC} + 0.5$	V
V_{IH2}	Input HIGH Voltage to RESET		3.0		V
V_{PD}	Power-Down Voltage	$V_{CC} = 0$ V	3	5.5	V
V_{OL}	Output LOW Voltage, Ports 1, 2, 3, 4, 5	$I_{OL} = 1.6$ mA		0.45	V
V_{OL1}	Output LOW Voltage, Port 0, ALE, PSEN	$I_{OL} = 3.2$ mA		0.45	V
V_{OH}	Output HIGH Voltage, Ports 1, 2, 3, 4, 5	$I_{OH} = -80$ μ A	2.4		V
V_{OH1}	Output HIGH Voltage, Port 0, ALE, PSEN	$I_{OH} = -400$ μ A	2.4		V
I_{IL}	Logic 0 Input Current, Ports 1, 2, 3, 4, 5	$V_{IL} = 0.45$ V		-800	μ A
I_{IL2}	Logic 0 Input Current, XTAL ₂	XTAL ₁ = V_{SS} $V_{IL} = 0.45$ V		-2.5	mA
I_{IL3}	Input LOW Current to RESET for Reset	$V_{IL} = 0.45$ V		-500	μ A
I_{L1}	Input Leakage Current to Port 0, EA	$0V < V_{IN} < V_{CC}$		± 10	μ A
I_{CC}	Power Supply Current 80515/80535	All Outputs Disconnected		210	mA
I_{PD}	Power-Down Current	$V_{CC} = 0$ V		3	mA
C_{IO}	Capacitance of I/O Buffer	$f_c = 1$ MHz		10	pF

Parameter Symbol	Parameter Description	12 MHz Clock		Variable Clock		Unit
		Min.	Max.	Min.	Max.	
1/TCLCL	Cycle Time			1.2	12	MHz
TLHLL	ALE Pulse Width	127		2TCLCL-40		ns
TAVLL	Address Setup to ALE	53		TCLCL-30		ns
TLLAX1	Address Hold After ALE	48		TCLCL-35		ns
TLLIV	ALE to Valid Instruction In		233		4TCLCL-100	ns
TLLPL	ALE to $\overline{\text{PSEN}}$	58		TCLCL-25		ns
TPLPH	$\overline{\text{PSEN}}$ Pulse Width	215		3TCLCL-35		ns
TPLIV	$\overline{\text{PSEN}}$ to Valid Instruction In		150		3TCLCL-100	ns
TPXIX	Input Instruction Hold After $\overline{\text{PSEN}}$	0		0		ns
TPXIZ*	Input Instruction Float After $\overline{\text{PSEN}}$		63		TCLCL-20	ns
TPXAV*	Address Valid After $\overline{\text{PSEN}}$	75		TCLCL-8		ns
TAVIV	Address to Valid Instruction In		302		5TCLCL-115	ns
TPLAZ	Address Float to $\overline{\text{PSEN}}$		20		20	ns
TRLRH	$\overline{\text{RD}}$ Pulse Width	400		6TCLCL-100		ns
TWLWH	$\overline{\text{WR}}$ Pulse Width	400		6TCLCL-100		ns
TLLAX2	Address Hold After ALE	132		2TCLCL-35		ns
TRLDV	$\overline{\text{RD}}$ to Valid Data In		252		5TCLCL-165	ns
TRHDX	Data Hold After $\overline{\text{RD}}$	0		0		ns
TRHDZ	Data Float After $\overline{\text{RD}}$		97		2TCLCL-70	ns
TLLDV	ALE to Valid Data In		517		8TCLCL-150	ns
TAVDV	Address to Valid Data In		585		9TCLCL-165	ns
TLLWL	ALE to $\overline{\text{WR}}$ or $\overline{\text{RD}}$	200	300	3TCLCL-50	3TCLCL + 50	ns
TAVWL	Address to $\overline{\text{WR}}$ or $\overline{\text{RD}}$	203		4TCLCL-130		ns
TWHLH	$\overline{\text{WR}}$ or $\overline{\text{RD}}$ HIGH to ALE HIGH	43	123	TCLCL-40	TCLCL + 40	ns
TQVWX	Data Valid to $\overline{\text{WR}}$ Transition	33		TCLCL-50		ns
TQVWH	Data Setup Before $\overline{\text{WR}}$	433		7TCLCL-150		ns
TWHQX	Data Hold After $\overline{\text{WR}}$	33		TCLCL-50		ns
TRLAZ	Address Float After $\overline{\text{RD}}$		20		20	ns

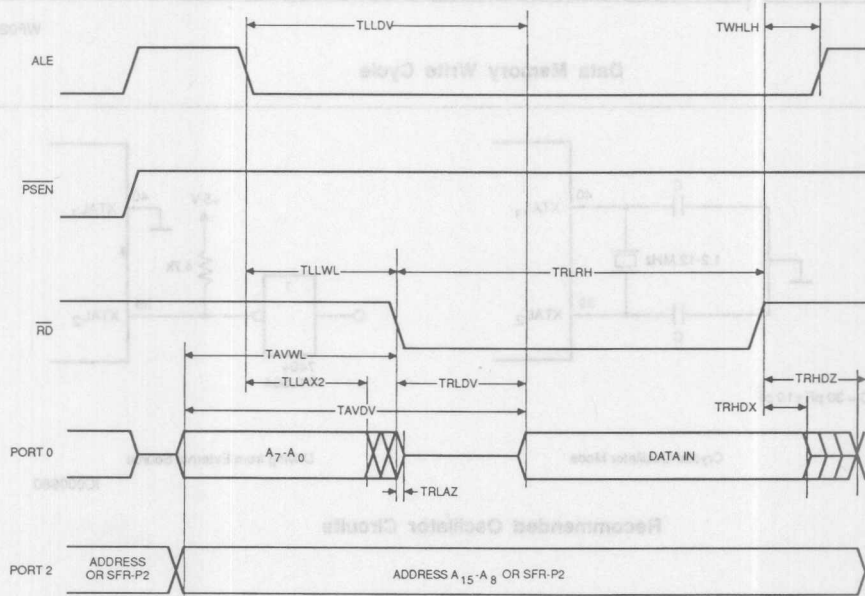
* Interfacing the 80515 to devices with float times up to 75 ns is permissible. This limited bus contention will not cause any damage to Port 0 drivers.

SWITCHING WAVEFORMS



WF025420

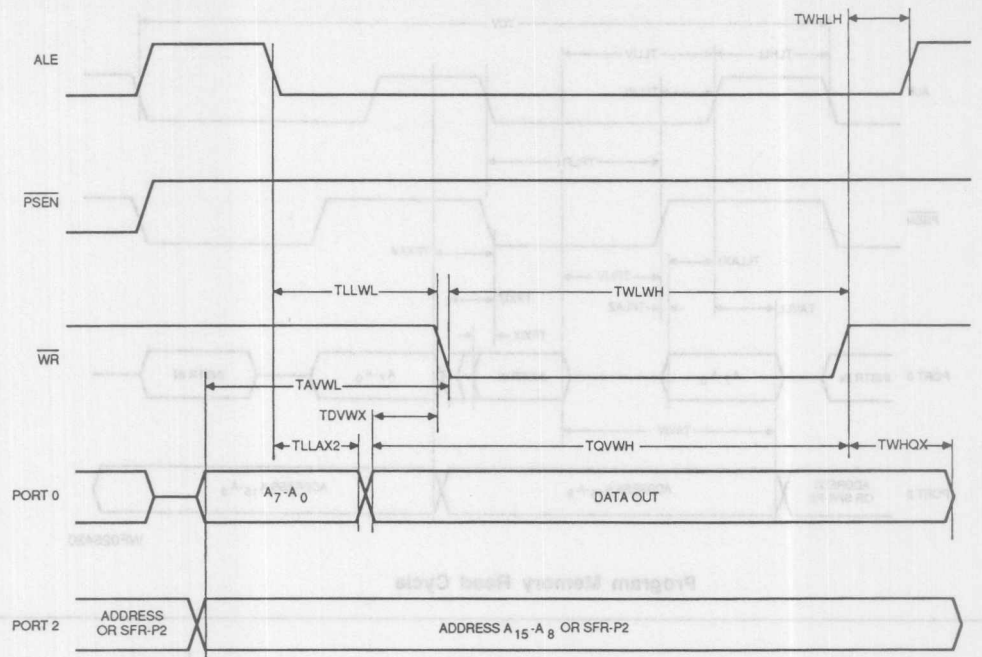
Program Memory Read Cycle



WF025360

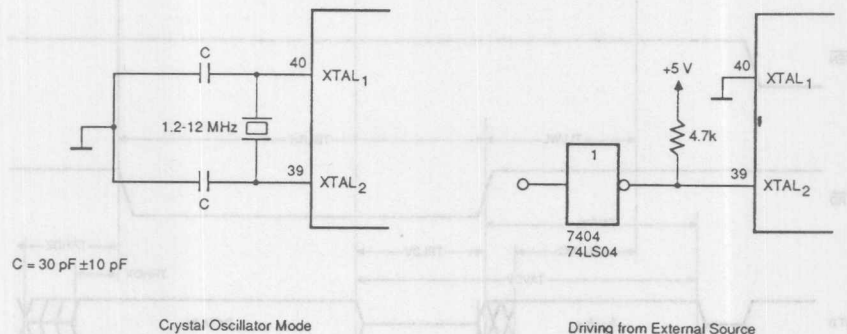
Data Memory Read Cycle

SWITCHING WAVEFORMS (Cont'd.)



WF025370

Data Memory Write Cycle

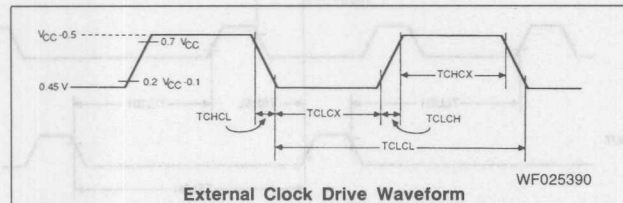


IC000980

Recommended Oscillator Circuits

EXTERNAL CLOCK DRIVE

Parameter Symbol	Parameter Description	Min.	Max.	Unit
1/TCLCL	Oscillator Frequency	1.2	12	MHz
TCHCX	HIGH Time	20		ns
TCLCX	LOW Time	20		ns
TCLCH	Rise Time		20	ns
TCHCL	Fall Time		20	ns

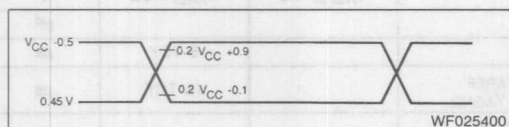


SERIAL PORT TIMING — SHIFT REGISTER MODE

(Load Capacitance = 80 pF)

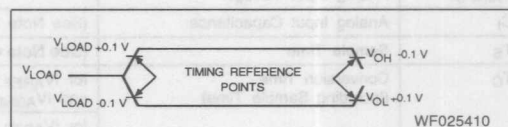
Parameter Symbol	Parameter Description	12 MHz Osc.		Variable Oscillator		Unit
		Min.	Max.	Min.	Max.	
TXLXL	Serial Port Clock Cycle Time	1.0		12TCLCL		μ s
TQVXH	Output Data Setup to Clock Rising Edge	700		10TCLCL – 133		ns
TXHQX	Output Data Hold After Clock Rising Edge	50		2TCLCL – 117		ns
TXHDX	Input Data Hold After Clock Rising Edge	0		0		ns
TXHDV	Clock Rising Edge to Input Data Valid		700		10TCLCL – 133	ns

AC Testing



AC INPUTS DURING TESTING ARE DRIVEN AT $V_{CC}-0.5$ FOR A LOGIC "1" AND 0.45 V FOR A LOGIC "0." TIMING MEASUREMENTS ARE MADE AT V_{IH} MIN. FOR A LOGIC "1" AND V_{IL} MAX. FOR A LOGIC "0."

Input/Output Waveform

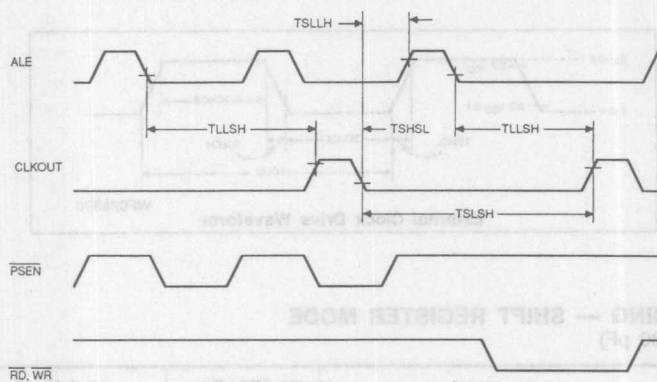


FOR TIMING PURPOSES, A PORT PIN IS NO LONGER FLOATING WHEN A 100 mV CHANGE FROM LOAD OCCURS. IT BEGINS TO FLOAT WHEN A 100 mV CHANGE FROM THE LOADED V_{OH}/V_{OL} LEVEL OCCURS. $I_{OL}/I_{OH} \geq \pm 20$ mA.

Float Waveform

SYSTEM CLOCK TIMING

Parameter Symbol	Parameter Description	12 MHz clock		Variable Clock 1/TCLCL = 1.2 MHz to 12 MHz		Unit
		Min.	Max.	Min.	Max.	
TLLSH	ALE to CLKOUT	543		7TCLCL-40		ns
TSHSL	CLKOUT HIGH Time	127		2TCLCL-40		ns
TSLSH	CLKOUT LOW Time	793		10TCLCL-40		ns
TSLH	CLKOUT LOW to ALE HIGH	43	123	TCLCL-40	TCLCL + 40	ns



System Clock Timing

WF025430

A/D Converter Characteristics ($V_{CC} = 5 \text{ V} \pm 10\%$; $V_{SS} = 0 \text{ V}$; $V_{AREF} = V_{CC} \pm 5\%$; $V_{AGND} = V_{SS} \pm 0.2 \text{ V}$; $T_A = 0 \text{ to } +70^\circ\text{C}$)

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Unit
V _{AINPUT}	Analog Input Voltage		$V_{AGND} - 0.2$	$V_{AREF} + 0.2$	V
C _i	Analog Input Capacitance	(See Note 3)			pF
T _s	Sample Time	(See Note 4)		5 TCY	μs
T _C	Conversion Time (Including Sample Time)	for $V_{AREF} = V_{AREF}$ and $V_{AGND} = V_{AGND}$		15 TCY	μs
		for $V_{AREF} \neq V_{AREF}$ and $V_{AGND} = V_{AGND}$ or for $V_{AREF} = V_{AREF}$ and $V_{AGND} \neq V_{AGND}$		22 TCY	μs
		for $V_{AREF} \neq V_{AREF}$ and $V_{AGND} \neq V_{AGND}$		29 TCY	μs
	Differential Non-Linearity	$V_{AREF} = V_{AREF}$ $V_{AGND} = V_{AGND}$		±1	LSB
	Integral Non-Linearity	$V_{AREF} = V_{AREF}$ $V_{AGND} = V_{AGND}$		±1	LSB
	Offset Error	$V_{AREF} = V_{AREF}$ $V_{AGND} = V_{AGND}$ R_i of Analog Input Source ≤ 10 kΩ		±1	LSB
	Gain Error	$V_{AREF} = V_{AREF}$ $V_{AGND} = V_{AGND}$ R_i of Analog Input Source ≤ 10 kΩ		±1	LSB
I _{REF}	V _{AREF} Supply Current			5	mA

- Notes:**
- The internal resistance of the analog source must be less than 10 kΩ to assure full loading of the sample capacitance during sample time.
 - The internal resistance of the analog reference voltage source must be less than 1 kΩ.
 - Typical values are 25 pF.
 - TCY = 1 μs at 12 MHz = 12 TCLCL.

Heating and Air Conditioning Control in Cars With the 80515 Microcontroller

The heating and air-conditioning unit in a car should provide the driver with conditions of comfortable temperature, fresh air flow, defogged and defrosted windows, low energy consumption and easy operation.

Its performance-oriented processor and flexible on-chip periphery, e.g., analog-to-digital converter, timer function, large number of inputs/outputs make the 80515 especially suitable for this type of application. The majority of the peripheral components are fully utilized in this application.

The temperature in the car reaches its nominal value and is kept constant by means of a two-stage mixing valve control. A rise in the outside temperature automatically activates the compressor of the air conditioning unit. The air entering the car is distributed upward and downward by an electrically controlled valve, depending on the temperature of the air. The optimal speed is also deter-

mined by the microcontroller as a function of the various input values. The electronics also control actuators such as air circulation and the water valve.

The device is operated by means of several keys. An LED display indicates the nominal or outside temperature. Individual LEDs indicate special conditions which can be selected by the user independent of the automatic functions.

CONTROL ELEMENTS AND SENSORS

The temperature inside the car is controlled in accordance with a selectable nominal value. The most important actuators for this purpose are the mixing valve and the compressor of the air conditioning unit. The mixing valve determines which part of the air entering the passenger area must pass through the heat exchanger of the heating unit. The valve can be fine-tuned by the microcomputer.

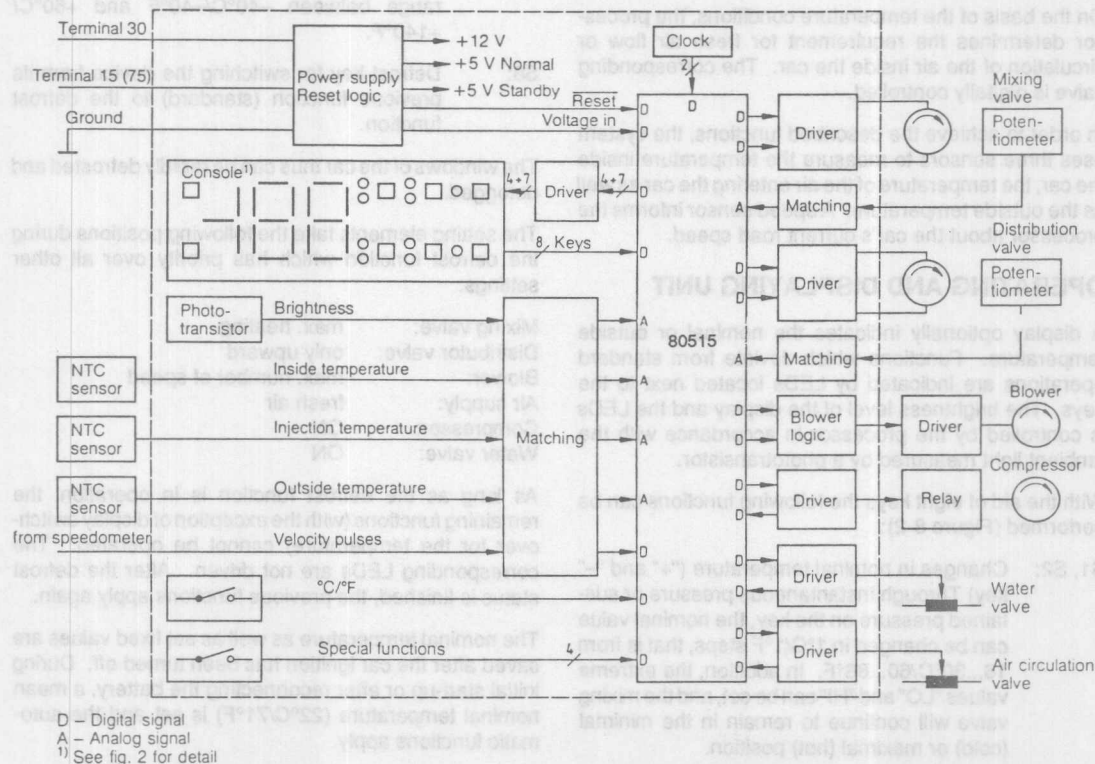


Figure 8-1. Block Diagram

09757A 8-1

If there is no heating requirement, the water flow to the heat exchanger is stopped by a digitally controlled valve. As a result, the temperature is further reduced in the summer time.

Depending on the output of the system, the air conditioning unit ensures that the nominal value of the temperature inside the car is obtained despite higher outside temperatures. The compressor of the air conditioning unit is enabled/disabled by the microcontroller.

In addition, the electronics influences the distribution of the temperature layers inside the car by a nearly stepless adjustable distribution valve. The valve determines whether the air is to be moved towards the roof or the floor of the car. Through this type of control, the air close to the roof of the car should be at a temperature lower than that close to the floor.

The fresh air flow is also electronically controlled. Depending on the different temperatures and the road speed of the car, the microcontroller computes the optimal speed for the blower, which can be changed almost continuously.

On the basis of the temperature conditions, the processor determines the requirement for fresh air flow or circulation of the air inside the car. The corresponding valve is digitally controlled.

In order to achieve the described functions, the system uses three sensors to measure the temperature inside the car, the temperature of the air entering the car as well as the outside temperature. A speed sensor informs the processor about the car's current road speed.

OPERATING AND DISPLAYING UNIT

A display optionally indicates the nominal or outside temperature. Functions which deviate from standard operations are indicated by LEDs located next to the keys. The brightness level of the display and the LEDs is controlled by the processor in accordance with the ambient light measured by a phototransistor.

With the aid of eight keys the following functions can be performed (Figure 8-2):

- S1, S2: Changes in nominal temperature ("+" and "-" key) Through instantaneous pressure or sustained pressure on the key, the nominal value can be changed in 1°C/1°F steps, that is from 16...30°C/60...86°F. In addition, the extreme values "LO" and "HI" can be set, and the mixing valve will continue to remain in the minimal (cold) or maximal (hot) position.

By depressing the keys, the following functions allow the user to switch over from normal (automatic) setting to one, two or three fixed values. After a fixed value has been selected, the corresponding LED or a combination of two LEDs lights up.

- S3: Distribution key for switching the air distribution to automatic, only upward, in the center (upward and downward, both LEDs light up) or only downward.
- S4: Blower key for switching the blower to automatic, full speed, half speed (both LEDs light up) and "OFF".
- S5: Air supply key for switching the air supply to automatic, air circulation, or fresh air.
- S6: Compressor key for switching compressor to automatic "ON" and "OFF".
- S7: Outside temperature key for switching the display to nominal temperature (standard function) or outside temperature. The outside temperature is displayed in 1°C/°F steps at a range between -40°C/-40°F and +60°C/+140°F.
- S8: Defrost key for switching the device from its previous function (standard) to the defrost function.

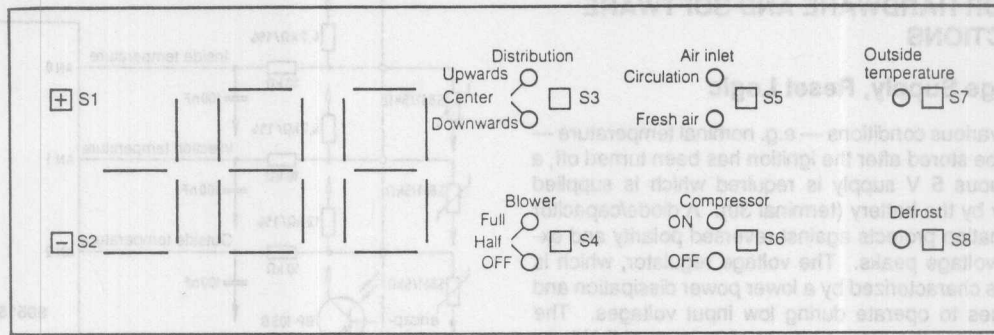
The windows of the car thus can be rapidly defrosted and defogged.

The setting elements take the following positions during the defrost function which has priority over all other settings:

Mixing valve:	max. heating
Distributor valve:	only upward
Blower:	max. number of speed
Air supply:	fresh air
Compressor:	ON
Water valve:	ON

As long as the defrost function is in operation, the remaining functions (with the exception of display switch-over for the temperature) cannot be operated. The corresponding LEDs are not driven. After the defrost status is finished, the previous functions apply again.

The nominal temperature as well as set fixed values are saved after the car ignition has been turned off. During initial start-up or after reconnecting the battery, a mean nominal temperature (22°C/71°F) is set and the automatic functions apply.

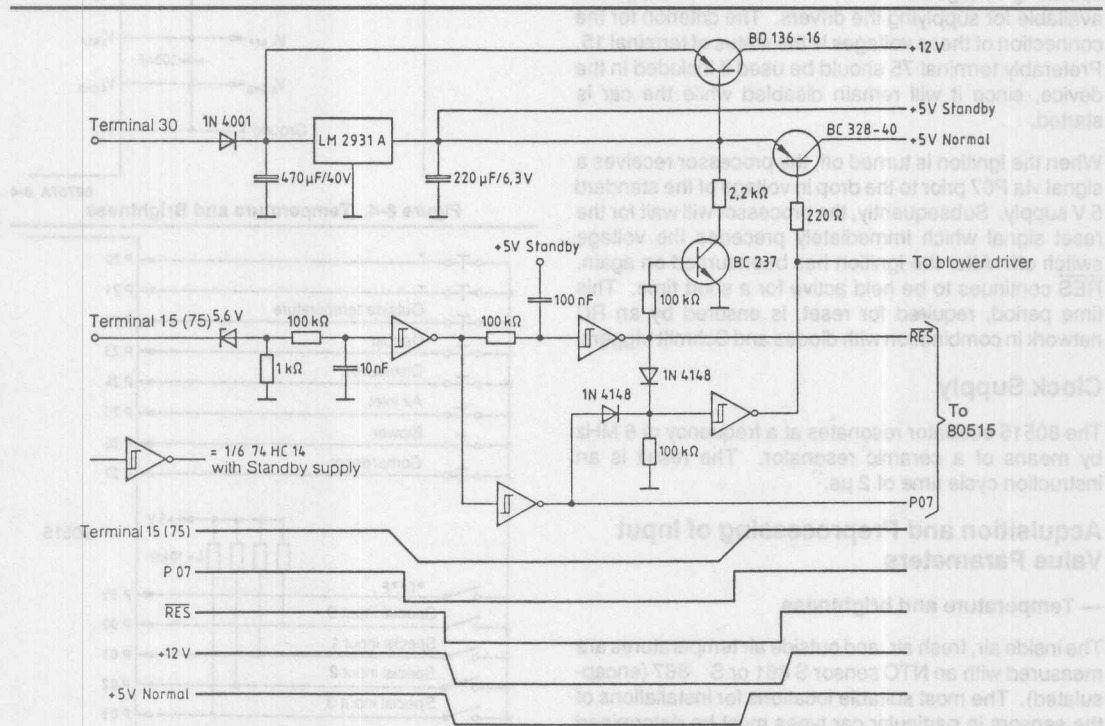


□ = Key

○ = LED

09757A 8-2

Figure 8-2. Console



09757A 8-3

Figure 8-3. Voltage Supply, Reset Logic

Voltage Supply, Reset Logic

Since various conditions — e.g. nominal temperature — are to be stored after the ignition has been turned off, a continuous 5 V supply is required which is supplied directly by the battery (terminal 30). A diode/capacitor combination protects against reversed polarity and extreme voltage peaks. The voltage regulator, which is used, is characterized by a lower power dissipation and continues to operate during low input voltages. The 80515 stores the data; 40 bytes of its internal RAM are saved during standby operation with a typical supply current of 1 mA. See Figure 8-3.

When the car ignition is turned on, the normal 5 V operating voltage as well as a filtered 12 V voltage are available for supplying the drivers. The criterion for the connection of these voltages is the status of terminal 15. Preferably terminal 75 should be used if included in the device, since it will remain disabled while the car is started.

When the ignition is turned off, the processor receives a signal via P07 prior to the drop in voltage of the standard 5 V supply. Subsequently, the processor will wait for the reset signal which immediately precedes the voltage switch off. After the ignition has been turned on again, RES continues to be held active for a short time. This time period, required for reset, is ensured by an RC network in combination with diodes and Schmitt triggers.

Clock Supply

The 80515 oscillator resonates at a frequency of 6 MHz by means of a ceramic resonator. The result is an instruction cycle time of 2 μ s.

Acquisition and Preprocessing of Input Value Parameters

— Temperature and brightness

The inside air, fresh air, and outside air temperatures are measured with an NTC sensor S 861 or S 867 (encapsulated). The most suitable locations for installations of the sensors in particular car types must be determined experimentally. The values of the pull-up resistors between the signal line and the analog reference voltage have been selected to ensure optimal accuracy within the required temperature range. Short-term interference pulses are filtered out by an RC network. The phototransistor BP 103 B on the face of the device generates a voltage across a resistor in accordance with the ambient light. See Figure 8-4

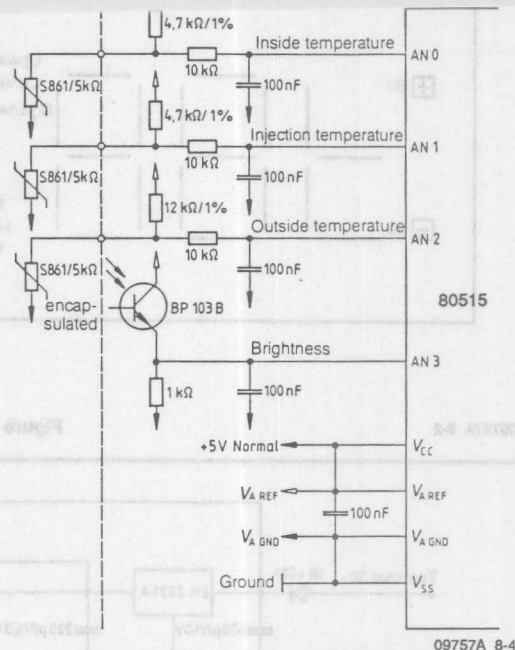
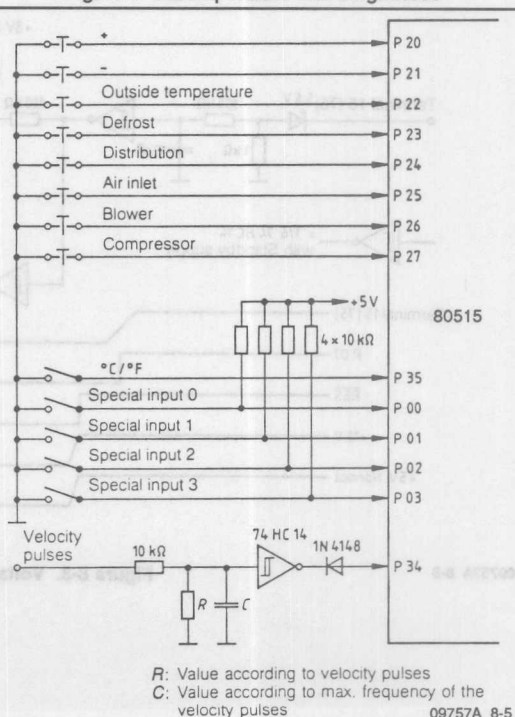


Figure 8-4. Temperature and Brightness



R: Value according to velocity pulses
C: Value according to max. frequency of the velocity pulses

Figure 8-5. Inputs for Keys, Switches and Speed

The 80515 reads these analog units at regular intervals via the multiplexer and the analog-to-digital converter located on the chip. Since the sensors are connected to the analog references, the result is not affected by the absolute value of these voltages. After the conversion low-frequency fluctuations are suppressed via software averaging. On the basis of tables and linear interpolation, the 80515 computes the values required, i.e. the temperature and the value for control of the display brightness.

— Speed

The speed is derived from the transducer for electronic speedometers included in most cars. An RC network (perhaps with voltage division) and a Schmitt trigger filter out interference in the sensor pulses and adjust the voltage amplitude. Using timer 1, the processor counts the pulses received within a defined time period. See Figure 8-5.

— Keys/Switch

Since these components are located inside the device, they can be protected against bouncing using software.

Because of its many I/O ports, the 80515 can read in information directly. A matrix with decoupling diodes is not required. Also, pull-up resistors are not required at the inputs of the 80515 — with the exception of P0. With the hidden °F switch, the unit for displaying the nominal and outside temperatures can be selected. The special inputs are used for activating special test functions (see section on "Testing and Optimization Support"). See Figure 8-5.

— Display

The display comprises a 3-digit 7-segment LED display (configured from HG 1107 elements). The foremost digit utilizes only four segments. There are also 10 single LEDs LG 3160 for indicating special conditions. The processor drives the display in a four-step multiplex method. For selecting the digit, the outputs P54...P57 go to HIGH in successive order. During this time the information for the segments is present at outputs P40...P46. Four Darlington transistors BC 517 are used as actuator drivers, and seven transistors BC 237 as segment drivers. The voltage source is the 12 V supply. See Figure 8-6.

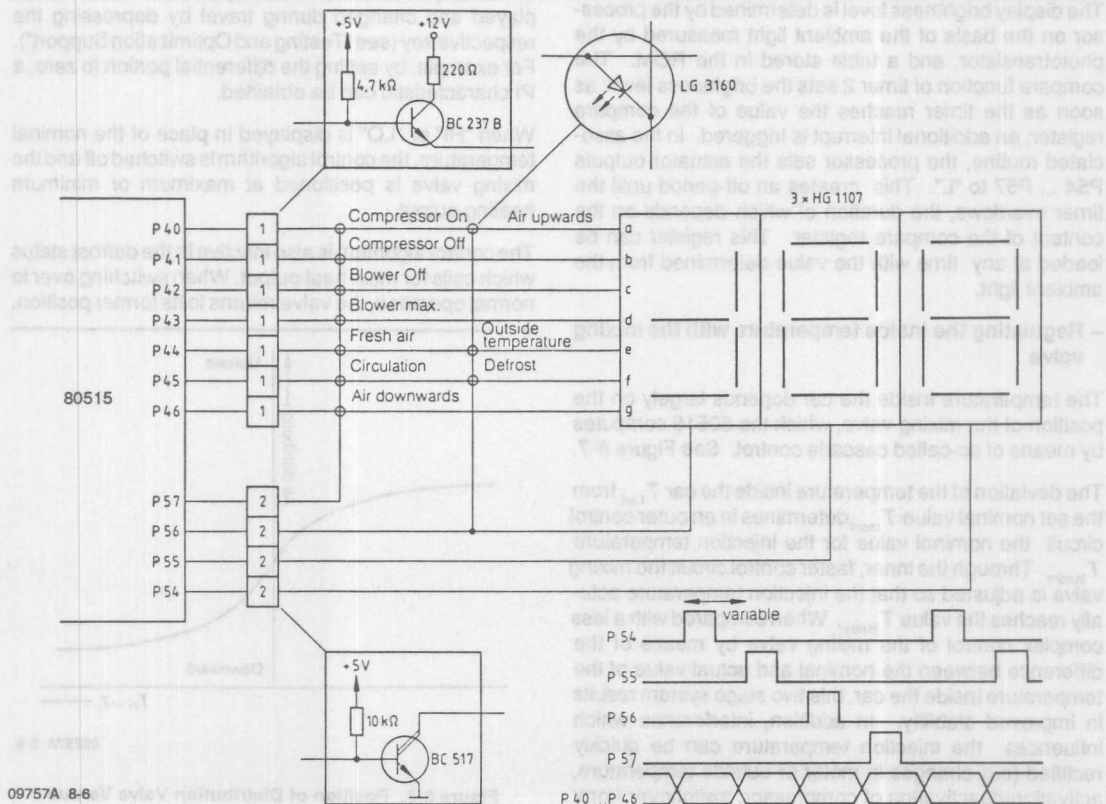


Figure 8-6. Display

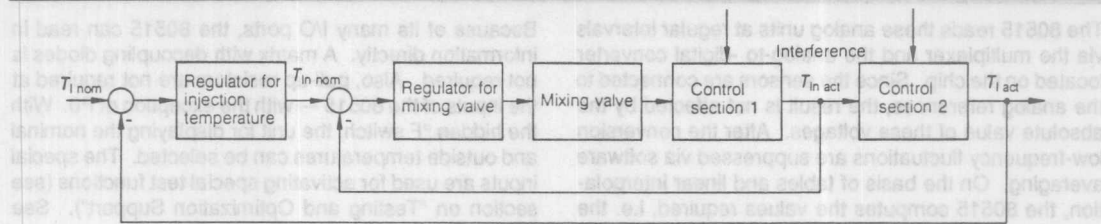


Figure 8-7. Block Diagram of Temperature Regulation

09757A 8-7

The multiplexed display and the brightness are controlled by time r_2 of the 80515. This is used as a timer in the auto-reload mode with the oscillator frequency divided by 12. During each overflow the timer is automatically loaded with the content of the CRC register — in this case FF00. This leads to a time interval of $256 \times 2 = 512 \mu s$ between two overflows.

The interval determines the length of the multiplex clock. The interrupt triggered by each overflow results in the output of the new segment information at port 4. The allocated multiplex location is released through port 5.

The display brightness level is determined by the processor on the basis of the ambient light measured by the phototransistor, and a table stored in the ROM. The compare function of timer 2 sets the brightness level: as soon as the timer reaches the value of the compare register, an additional interrupt is triggered. In the associated routine, the processor sets the actuator outputs P54 ... P57 to "L". This creates an off-period until the timer overflows, the duration of which depends on the content of the compare register. This register can be loaded at any time with the value determined from the ambient light.

– Regulating the inside temperature with the mixing valve

The temperature inside the car depends largely on the position of the mixing valve, which the 80515 computes by means of so-called cascade control. See Figure 8-7.

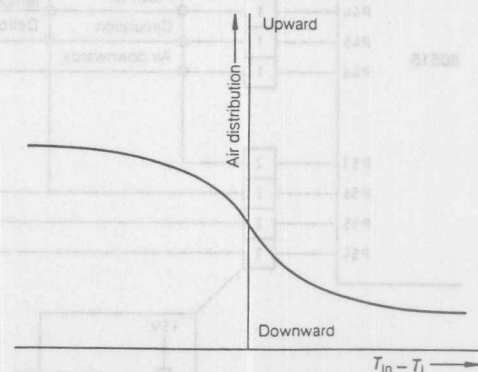
The deviation of the temperature inside the car $T_{i act}$ from the set nominal value $T_{i nom}$ determines in an outer control circuit the nominal value for the injection temperature $T_{in nom}$. Through the inner, faster control circuit the mixing valve is adjusted so that the injection temperature actually reaches the value $T_{in nom}$. When compared with a less complex control of the mixing valve by means of the difference between the nominal and actual value of the temperature inside the car, this two stage system results in improved stability. In addition, interference which influences the injection temperature can be quickly rectified (e.g. changes in motor or outside temperature, activation/deactivation of compressor, switchover from/to fresh air/air circulation). Also, the min. and max.

ratings for the injection temperature can easily be established providing the necessary comfort for the passengers. With properly set parameters the time characteristics as compared to a simple control are equally satisfactory.

The nominal values for the injection temperature and the mixing valve position are computed according to a digital PID (proportional, integral, and differential) algorithm. Although the variety of parameters which can be set for both controls permit a wide range of adjustments, the expenditure is considerable. Therefore, to facilitate the test and optimization phase, all parameters can be displayed and changed during travel by depressing the respective key (see "Testing and Optimization Support"). For example, by setting the differential portion to zero, a PI characteristic can be obtained.

When "HI" or "LO" is displayed in place of the nominal temperature, the control algorithm is switched off and the mixing valve is positioned at maximum or minimum heating output.

The control algorithm is also inactive in the defrost status which calls for max. heat output. When switching over to normal operation, the valve returns to its former position.



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Figure 8-8. Position of Distribution Valve Versus Injection and Inside Temperature

Establishing the Nominal Value for the Distribution Valve

As can be seen in Figure 8-8, the position of the distribution valve normally depends on the differences between the injection temperature and the temperature inside the car. Cooler air is usually directed upwards while heating air is injected downwards towards the floor of the car. The effective nominal value is set by the 80515 with reference to the actual end positions of the valve. (See "Setting the Mixing and Distribution Valve").

During the special functions "upward air distribution" and "defrost", the air is blown only upward or during "downward air distribution" only downward at floor level. When "center air distribution" has been selected, half of the air volume is blown upward and half downward.

Setting the Mixing and Distribution Valve

Both valves are set in the same manner, that is by motors and gears which run or stop in both directions. The components TLE 4201 drive the motor, while the μC controls them via ports P50 and P51 (mixing valve) as well as P52 and P53 (distribution valve). The analog-

to-digital converter of the processor is informed of the valve position by means of the voltage on a potentiometer which is connected to the valve and supplied by the analog reference voltages. An RC network filters out the interference. When the difference between the nominal and the actual value of a valve exceeds a certain tolerance margin, the motor is driven in the respective direction. See Figure 8-9.

The valves should reach their end positions (mechanical stops) but the motor, for mechanical reasons, should not be driven continuously in these positions. Since it is difficult to solve this problem by an accurate adjustment of the potentiometer, the system recognizes a mechanical stop when the difference between the actual and the nominal value remains the same although the motor is running. In response, the motor is switched off and the actual value is stored. Thereafter, the system will stop when this value has been reached. Only after a certain period of time (approx. 10 minutes) or each time the ignition has been turned on, the user can change the stop by depressing the respective key for selection of a max. position. As a prerequisite for this type of stop recognition, the electrical region of the potentiometer should not be fully utilized by the valve angle.

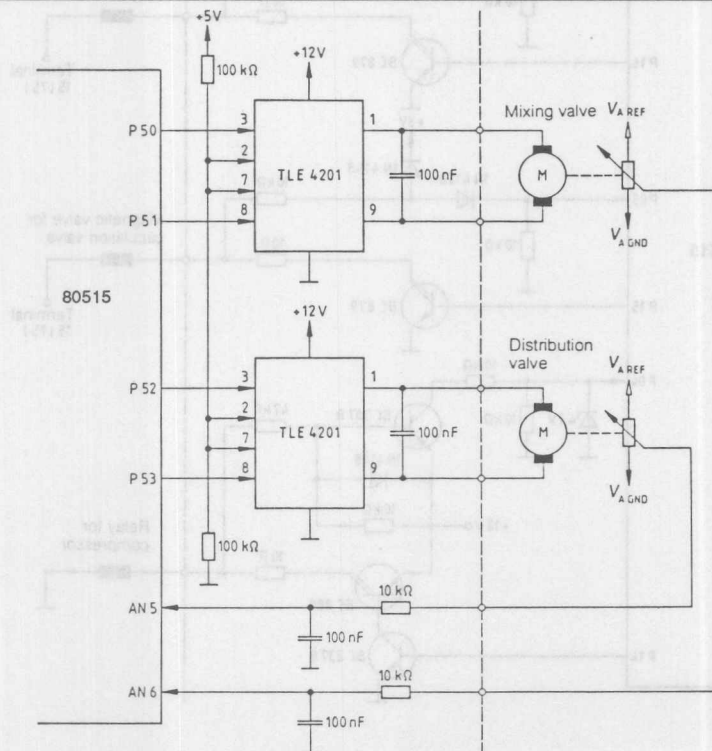


Figure 8-9. Control of Mixing and Distribution Valve

Switching Over the Air Supply

During the automatic function, fresh air will be supplied when the following conditions for air circulation are not met:

- outside temperature > nominal temperature + 10°C
- outside temperature > inside temperature.

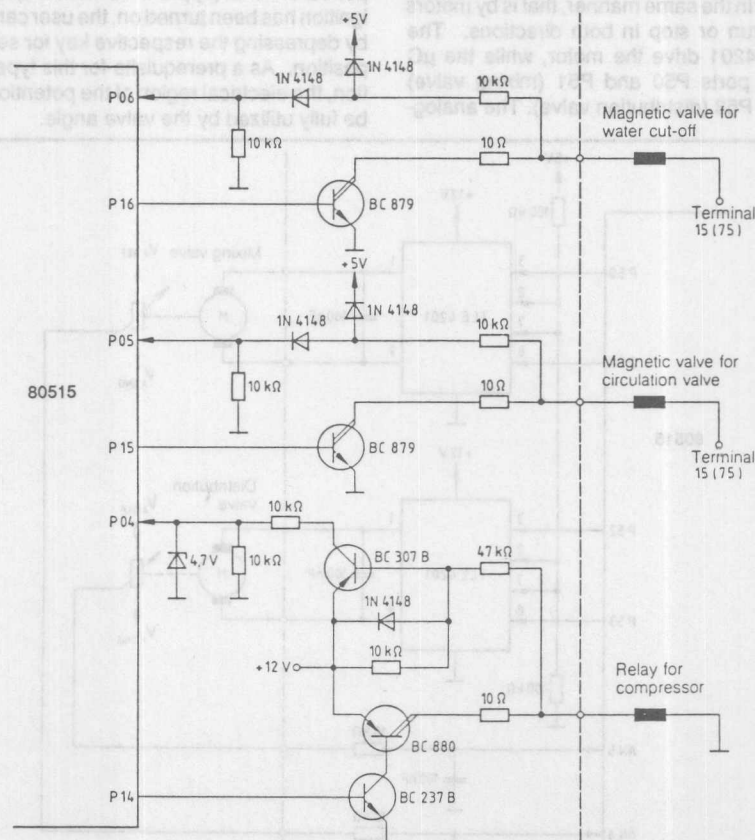
To prevent the valve from switching continuously, a hysteresis of 2°C in each direction is used.

During "defrost" or "fresh air supply" the system takes in fresh air; during "ambient air supply", the air in the car is recirculated.

transistor protects against short-term interference (see Figure 8-10). A short-circuit in the electrical supply can be detected via P05. In this case the processor immediately stops the control of the valve, but periodically attempts to reactivate it every few seconds. The magnetic valve controls a vacuum motor for activating the air circulation valve.

Water Valve Activation

When there is no heating requirement, the electronics inhibit the water flow to the heat exchanger by means of a valve. As a result, the temperature inside the car can be reduced by several degrees in the summer when compared to operation with a closed mixing valve. The criterion for inhibiting the water flow is the mixing valve's



09757A 8-10

Figure 8-10. Control of Water Valve, Circulation Valve and Compressor

position at the lower stop. Only after the mixing valve has changed its position by a defined distance from the stop, will the processor enable the valve again.

The magnetic valve for inhibiting the water flow is controlled in a manner similar to that used for the air circulation valve (see Figure 8-10). P16 and P06 are used as outputs or feedback pins. As can be seen in Figure 8-10, the magnetic valve pneumatically activates the inhibit valve.

Enabling/Disabling the Compressor

During the automatic function the compressor is disabled only if the outside temperature drops by more than 10°C below the nominal temperature. Again a hysteresis of 2°C is applied for the switching procedure.

During "defrost" or "compressor ON", the air conditioning unit operates continuously, but stops completely during "compressor OFF".

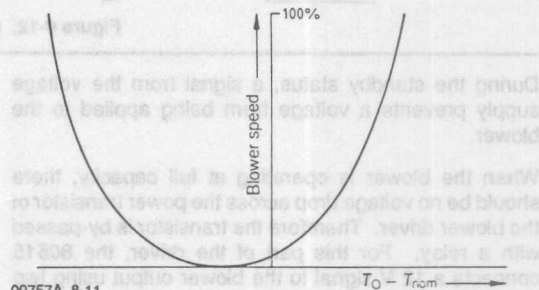
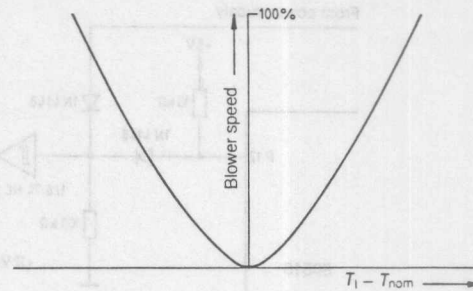
The compressor relay is driven (see Figure 8-10) by P14 of the 80515 as well as two transistors BC 237 and BC 880 for increasing the current and converting the levels. A drive signal short-circuited to ground — after level conversion by transistor BC 307 — can be detected via P04 and the system is then switched off for several seconds. The external compressor relay activates the magnetic coupling for driving the compressor, however, only if the (electronically independent) defroster for the carburetor does not respond.

To Drive the Blower

Initially the speed of the blower is a function of two variables as can be seen in Figure 8-11. An increase in speed as a function of the nominal-actual temperature difference leads to rapid temperature adjustment. During extreme outside temperatures, the heating or air conditioning effect has to be supported continuously by the blower. The curve minimum is therefore displaced since the average thermal effect of sun rays has been taken into account. The two functions are actively combined.

When both the inside temperature and the injection temperature lie below or above the nominal value for the inside temperature, the blower speed is reduced. Otherwise the already uncomfortably cold car would get colder or, if already too hot, hotter.

Two points were included when considering the dependence on the road speed: during higher speeds the dynamic air pressure increasingly replaces the blower output. In response the blower speed is reduced in proportion to the speed or set to zero, if required. How-



09757A 8-11

Figure 8-11. Examples for Blower Speed Characteristics

ever, during lower speeds or when the car is parked, the noise generated by the blower is irritating and polluted air is brought in, e.g., during heavy traffic. The speed of the blower is therefore reduced.

These automatic functions can be overridden with the blower or defrost key. The blower reaches its max. speed during "fullspeed blower capacity" or "defrost", operates at a medium speed at "half blower capacity," or not at all in "blower off".

The blower is driven (Figure 8-12) by the pulse-width modulated signal generated by the microcontroller at P12 with the aid of timer 2. The timer has been programmed for an overflow every $512 \mu\text{s}$. The compare/capture register 2 operates in the compare mode (mode 0), port 12 is inactive during timer overflow, or active when the content of the timer and compare register is the same. Therefore, by changing the content of the compare register, the pulse duty factor at P12 can be varied. An HCMOS inverter and an RC combination convert the microcontroller output signal into an analog voltage ranging between 0 and 5 V. This voltage drives the blower driver located outside the electronics.

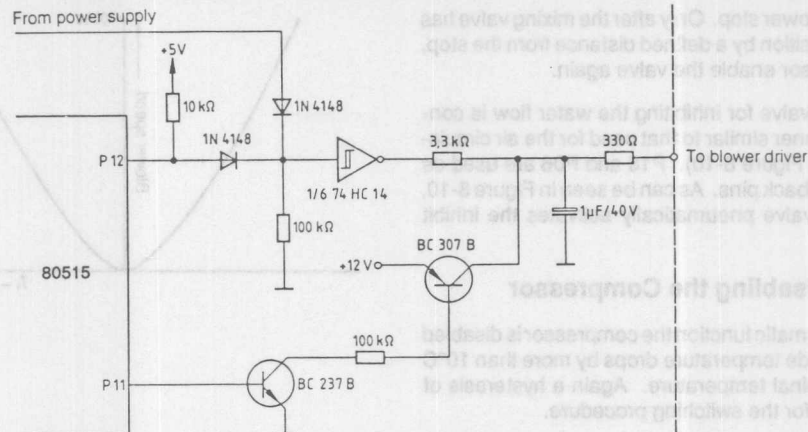


Figure 8-12. Blower Control

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During the standby status, a signal from the voltage supply prevents a voltage from being applied to the blower.

When the blower is operating at full capacity, there should be no voltage drop across the power transistor of the blower driver. Therefore the transistor is by-passed with a relay. For this part of the driver, the 80515 connects a 12 V signal to the blower output using two transistors (BC 237 and BC 307). The relay is switched off — to prevent wear and tear — when the speed of the blower is reduced.

Testing and Optimization Support

By encoding at ports P00–P02, the following quantities can be displayed in place of the nominal or outside temperature:

- 1) Inside temperature T_i in °C
- 2) Injection temperature T_{in} in °C
- 3) Mixing valve setting in %
- 4) Distribution valve setting in %
- 5) Blower drive in %
- 6) Status of compressor, air circulation as well as water valve
- 7 a) Memory address of internal RAM, which can be set
- 7 b) Memory content associated with this address, which can be varied

The controlling and regulating procedures of the system can be monitored with displays 1 through 6.

During operation, the system can be accessed and all memory contents indicated with display 7. The settings are performed in the same manner as the changes in nominal temperature, namely with keys “+” and “-”. The outside temperature key is used to switch between the memory address and content. There are functions suitable for manual control, and there are those which should be left in the automatic mode.

The possibility of user access has been provided for adjusting the parameters of the two-stage PID control to the respective vehicle. The parameters are not established by the program. Instead they are stored in the RAM in the memory area saved during standby operation. Only after the voltage has been switched off, the parameters can be loaded with fixed values during initialization. The test engineer can therefore change the parameters according to the test results, although the device has already been installed.

In order to provide defined start conditions for a test, all controlling and regulating functions can be switched off during the setting procedures with P03.

After the test has been completed, the established optimal parameter values can be permanently programmed in the EPROM or in the masked ROM.

Use of the on-chip periphery of the 80515

Table 8-1 includes the functions of the integrated periphery of the 80515. As can be seen, almost all elements are utilized.

Table 8-1 Use of the 80515 On-Chip Periphery

Periphery	Application
Analog-to-digital converter	for measuring – temperatures – brightness level and for setting mixing and distribution valve
Timer 0	for generating a standard time clock
Timer 1	for measuring road speed
Timer 2	for controlling the time for LED multiplex display (with brightness control) for controlling the pulse/pause ratio for the blower
Watchdog timer	for system monitoring
Serial interface	for diagnostic purposes
Ports	for interrogating and driving digital and time analog inputs/outputs

ALTERNATIVES AND UPGRADES

Changes in the functions of the described sample — provided the sensors and actuators remain the same — can be easily realized by merely modifying the program or the stored tables. However, when different or additional sensors or actuators are used, the hardware must be changed as well.

For example the mixing valve can be replaced by a clocked valve which alternately releases and interrupts the water flow between the cooler and heat exchanger. According to the pulse/pause ratio of the drive signal the heat exchanger temperature changes and thus the air injected into the car. The previously described hot water valve is in this case omitted.

Also, in addition to the distribution valve, other elements for changing the air distribution can be controlled, e.g. the vent flaps at the dashboard.

If the serial interface of the 80515 is not used, the system could be diagnosed during practical application and inspections.

80C51 (data sheet) Designing with the 80C51BH

9-12
9-27

Table 8-1 Use of the 80C51 On-Chip Peripherals

Peripheral	Application
Analog-to-digital converter	for measuring — temperature — pressure level and for setting mixing and distribution valve
Timer 0	for generating a standard time clock
Timer 1	for measuring road speed
Timer 2	for controlling the time for LED matrix display (with brightness control) for controlling the out-pulse ratio for the blower
Watchdog timer	for system monitoring
Serial interface	for diagnostic purposes
Ports	for transmitting and driving digital and time analog inputs outputs

For example, the mixing valve can be replaced by a closed valve which alternately releases and interrupts the water flow between the cooler and heat exchanger. According to the pulse-width ratio of the drive signal, the heat exchanger temperature changes and thus the air injected into the car. The previously described hot water valve is in the case control.

Also, in addition to the distribution valve, other elements for changing the air distribution can be controlled, e.g. the vent flap at the dashboard.

If the serial interface of the 80C51 is not used, the system could be diagnosed during practical application and inspections.

80C51BH/80C31BH

CMOS Single-Chip Microcontroller

DISTINCTIVE CHARACTERISTICS

- CMOS versions of 8051 and 8031
- 80C51 = 80C31 + 4K bytes ROM
- 128 bytes of RAM
- 32 programmable I/O lines
- CMOS and TTL compatible
- Two 16-bit timer/counters
- Low-power consumption:
 - Normal operation: 16 mA @ 5 V, 12 MHz
 - Idle mode: 3.7 mA @ 5 V, 12 MHz
 - Power-Down mode: 50 μ A @ 2 V to 6 V
- 64K bytes Program Memory space
- 64 K bytes Data Memory space
- Boolean processor

GENERAL DESCRIPTION

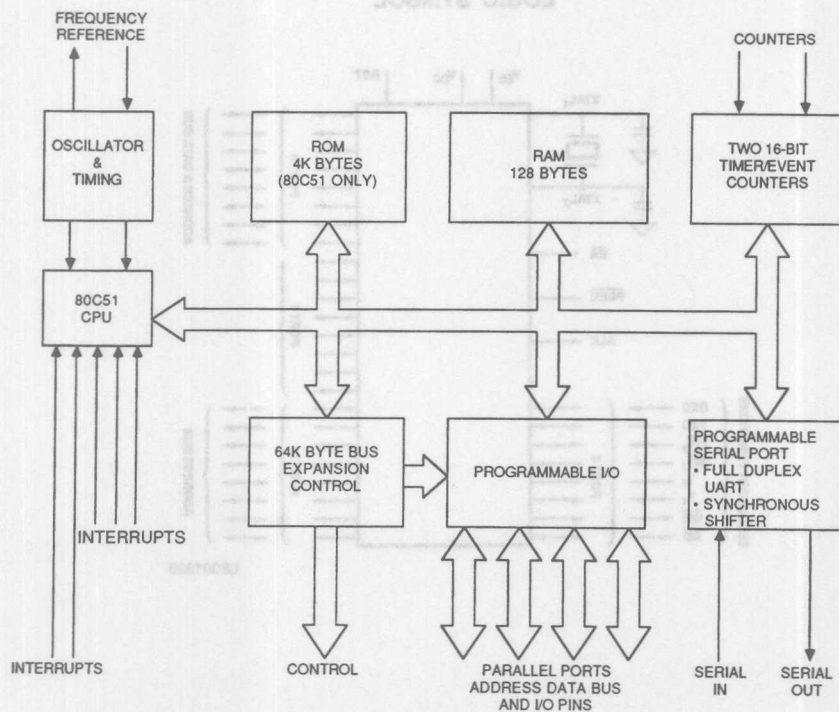
The AMD 80C51 and 80C31 are CMOS versions of the 8051 and 8031 8-bit microcontrollers. They combine the power savings of CMOS with the powerful 8051/31 microcontroller.

These CMOS versions retain all the features of their NMOS counterparts: 4K bytes on-chip ROM (80C51 only); 128 bytes RAM; 32 I/O lines; two 16-bit timers; a five-source,

two level interrupt structure; a full-duplex serial port; and on-chip oscillator and clock circuits.

In addition, the 80C51/31 has two software-selectable modes of reduced activity for further power conservation — Idle and Power-Down. In the Idle mode, the CPU is frozen while the RAM, timers, serial port, and the interrupt system continue to function. In the Power-Down mode, the RAM is saved and all other functions are inoperative.

BLOCK DIAGRAM

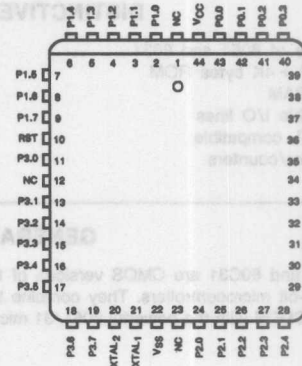
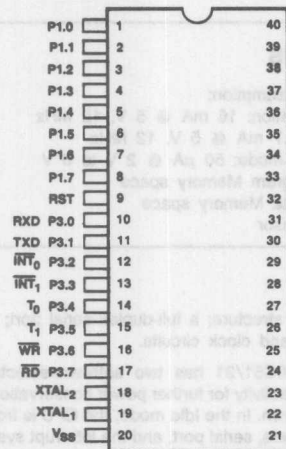


BD007230

CONNECTION DIAGRAMS Top View

DIPs

PLCC

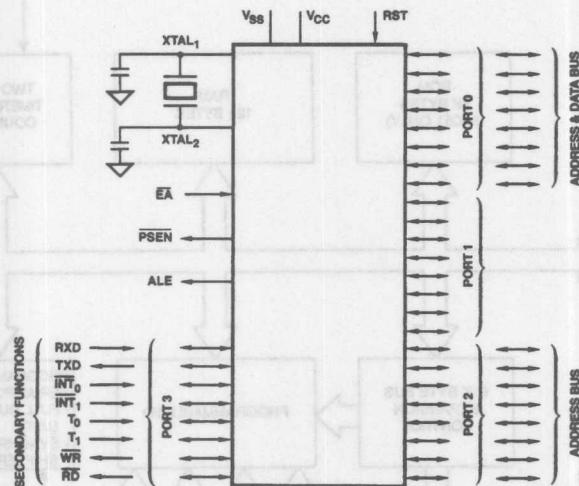


CD005551

CD009440

Note: Pin 1 is marked for orientation.

LOGIC SYMBOL



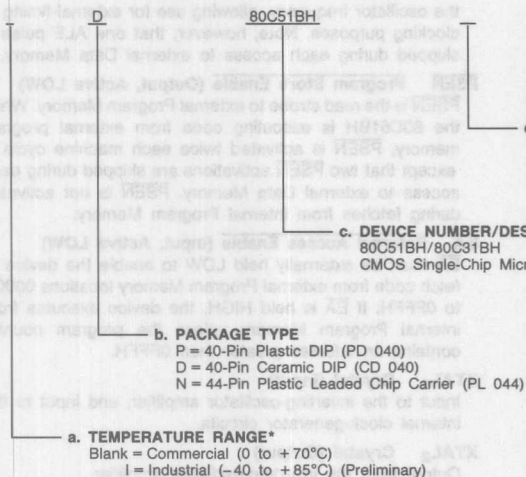
LS001323

ORDERING INFORMATION

Commodity Products

AMD commodity products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:

- Temperature Range
- Package Type
- Device Number
- Speed Option
- Optional Processing



- TEMPERATURE RANGE*
Blank = Commercial (0 to +70°C)
I = Industrial (-40 to +85°C) (Preliminary)

Valid Combinations

P, D, N	80C51BH
	80C51BH-1
	80C31BH
	80C31BH-1

*This device will also be available in Military temperature range. See MOS Microprocessors and Peripherals Military Handbook (Order #09275A/0) for preliminary electrical performance characteristics.

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released valid combinations, and to obtain additional data on AMD's standard military grade products.

Port Pin	Alternate Function
P0.0	LED (power output port)
P0.1	TXD (serial output port)
P0.2	INT0 (external interrupt 0)
P0.3	INT1 (external interrupt 1)
P0.4	T0 (Timer 0 external input)
P0.5	T1 (Timer 1 external input)
P0.6	WR (external Data Memory write strobe)
P0.7	RD (external Data Memory read strobe)

Port 0 is also the multiplexed LOW-order address and data bus during accesses to external Program and Data Memory. In this application it uses strong internal pullups when emitting "1"s. Port 0 also outputs the code bytes during program verification in the 80C51BH. External pullups are required during program verification.

Port 1 (Bidirectional)

Port 1 is an 8-bit bidirectional I/O port with internal pullups. The Port 1 output buffers can sink/source four LS TTL inputs. Port 1 pins that have "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 1 pins that are externally being pulled LOW will source current (I_{IL} on the data sheet) because of the internal pullups.

Port 1 also receives the LOW-order address bytes during program verification.

Port 2 (Bidirectional)

Port 2 is an 8-bit bidirectional I/O port with internal pullups. The Port 2 output buffers can sink/source four LS TTL inputs. Port 2 pins having "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 2 pins externally being pulled LOW will source current (I_{IL}) because of the internal pullups.

Port 2 emits the HIGH-order address byte during fetches from external Program Memory and during accesses to external Data Memory that use 16-bit addresses (MOVX @DPTR). In this application it uses strong internal pullups when emitting "1"s. During accesses to external data memory that use 8-bit addresses (MOVX @Ri), Port 2 emits the contents of the P2 Special Function register.

Port 2 also receives the HIGH-order address bits during ROM verification.

Port 3 (Bidirectional)

Port 3 is an 8-bit bidirectional I/O port with internal pullups. The Port 3 output buffers can sink/source four LS TTL inputs. Port 3 pins that have "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 3 pins externally being pulled LOW will source current (I_{IL}) because of the pullups.

Port 3 also serves the functions of various special features as listed below:

Port Pin	Alternate Function
P3.0	RxD (serial input port)
P3.1	TxD (serial output port)
P3.2	$\overline{INT_0}$ (External interrupt 0)
P3.3	$\overline{INT_1}$ (external interrupt 1)
P3.4	T ₀ (Timer 0 external input)
P3.5	T ₁ (Timer 1 external input)
P3.6	\overline{WR} (external Data Memory write strobe)
P3.7	\overline{RD} (external Data Memory read strobe)

an external capacitor to V_{CC}.

ALE Address Latch Enable (Output, Active HIGH)

Address Latch Enable output pulse for latching the LOW byte of the address during accesses to external memory.

In normal operation ALE is emitted at a constant rate of 1/6 the oscillator frequency, allowing use for external timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external Data Memory.

PSEN Program Store Enable (Output, Active LOW)

PSEN is the read strobe to external Program Memory. When the 80C51BH is executing code from external program memory, PSEN is activated twice each machine cycle — except that two PSEN activations are skipped during each access to external Data Memory. PSEN is not activated during fetches from internal Program Memory.

EA External Access Enable (Input, Active LOW)

EA must be externally held LOW to enable the device to fetch code from external Program Memory locations 0000H to 0FFFFH. If EA is held HIGH, the device executes from internal Program Memory unless the program counter contains an address greater than 0FFFFH.

XTAL₁ Crystal (Input)

Input to the inverting-oscillator amplifier, and input to the internal clock-generator circuits.

XTAL₂ Crystal (Output)

Output from the inverting-oscillator amplifier.

V_{CC} Power Supply

Supply voltage during normal, idle, and power-down operations.

V_{SS} Circuit Ground

Pin 1	NC
Pin 2	XTAL ₁
Pin 3	XTAL ₂
Pin 4	V _{CC}
Pin 5	GND
Pin 6	EA
Pin 7	PSEN
Pin 8	ALE
Pin 9	P0
Pin 10	P0
Pin 11	P0
Pin 12	P0
Pin 13	P0
Pin 14	P0
Pin 15	P0
Pin 16	P0
Pin 17	P0
Pin 18	P0
Pin 19	P0
Pin 20	P0
Pin 21	P0
Pin 22	P0
Pin 23	P0
Pin 24	P0
Pin 25	P0
Pin 26	P0
Pin 27	P0
Pin 28	P0
Pin 29	P0
Pin 30	P0
Pin 31	P0
Pin 32	P0
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Pin 39	P0
Pin 40	P0
Pin 41	P0
Pin 42	P0
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Pin 83	P0
Pin 84	P0
Pin 85	P0
Pin 86	P0
Pin 87	P0
Pin 88	P0
Pin 89	P0
Pin 90	P0
Pin 91	P0
Pin 92	P0
Pin 93	P0
Pin 94	P0
Pin 95	P0
Pin 96	P0
Pin 97	P0
Pin 98	P0
Pin 99	P0
Pin 100	P0

FUNCTIONAL DESCRIPTION

Oscillator Characteristics

XTAL₁ and XTAL₂ are the input and output, respectively, of an inverting amplifier which is configured for use as an on-chip oscillator (see Figure 1). Either a quartz crystal or ceramic resonator may be used.

To drive the device from an external clock source, XTAL₁ should be driven while XTAL₂ is left unconnected (see Figure 2). There are no requirements on the duty cycle of the external-clock signal since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum HIGH and LOW times specified on the data sheet must be observed.

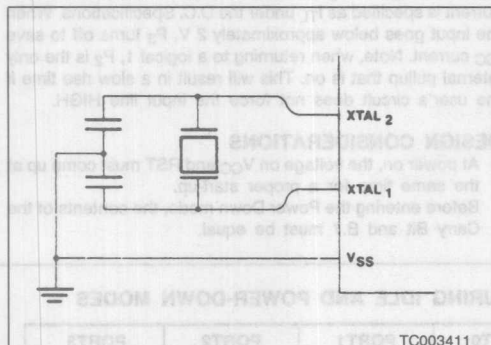


Figure 1. Crystal Oscillator

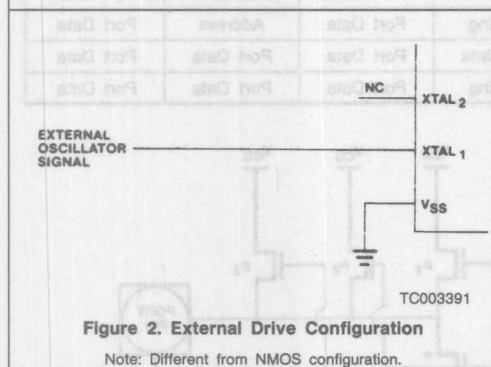


Figure 2. External Drive Configuration

Note: Different from NMOS configuration.

Idle and Power-Down Operation

Figure 3 shows the internal Idle and Power-Down clock configuration. As illustrated, Power-Down operation freezes the oscillator. Idle mode operation shows the interrupt, serial port, and timer blocks to continue to function while the clock to the CPU is halted.

These special modes are activated by software via the Special Function Register, PCON (Table 1). Its hardware address is 87H; PCON is not bit-addressable.

If "1"s are written to PD and IDL at the same time, PD takes precedence. The reset value of PCON is "0XXX0000".

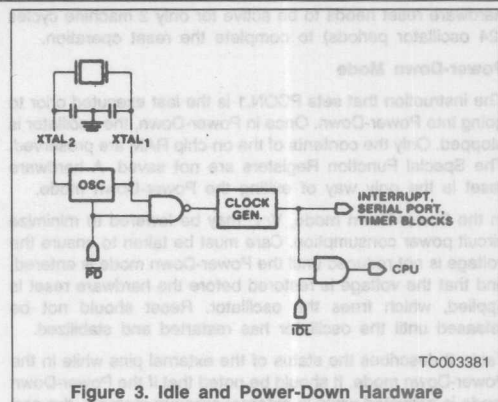


Figure 3. Idle and Power-Down Hardware

TABLE 1. PCON (Power Control Register)

(MSB)						(LSB)
SMOD	-	-	-	GF1	GF0	PD IDL

Symbol	Position	Name and Description
SMOD	PCON.7	Double-baud-rate bit. When set to a 1, the baud rate is doubled when the serial port is being used in either modes 1, 2, or 3.
-	PCON.6	(Reserved)
-	PCON.5	(Reserved)
-	PCON.4	(Reserved)
GF1	PCON.3	General-purpose flag bit
GF0	PCON.2	General-purpose flag bit
PD	PCON.1	Power-Down bit. Setting this bit activates power-down operation.
IDL	PCON.0	Idle-mode bit. Setting this bit activates idle-mode operation.

Idle Mode

The instruction that sets PCON.0 is the last instruction executed in the normal operating mode before Idle mode is activated. Once in the Idle mode, the CPU status is preserved in its entirety: the Stack Pointer, Program Counter, Program Status Word, Accumulator, RAM, and all other registers maintain their data during Idle. Table 2 describes the status of the external pins during Idle mode.

There are two ways to terminate the Idle mode. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating Idle mode. The interrupt is serviced, and following RETI, the next instruction to be executed will be the one following the instruction that wrote a 1 to PCON.0.

The flag bits GF0 and GF1 may be used to determine whether the interrupt was received during normal execution or during the Idle mode. For example, the instruction that writes to PCON.0 can also set or clear one or both flag bits. When Idle mode is terminated by an enabled interrupt, the service routine can examine the status of the flag bits.

The second way of terminating the Idle mode is with a hardware reset. Since the oscillator is still running, the

Power-Down Mode

In the Power-Down mode, V_{CC} may be lowered to minimize circuit power consumption. Care must be taken to ensure the voltage is not reduced until the Power-Down mode is entered, and that the voltage is restored before the hardware reset is applied, which frees the oscillator. Reset should not be released until the oscillator has restarted and stabilized.

Table 2 describes the status of the external pins while in the Power-Down mode. It should be noted that if the Power-Down mode is activated while in external program memory, the port data that is held in the Special Function Register P₂ is restored to Port 2. If the data is a 1, the port pin is held HIGH during the Power-Down mode by the strong pullup, P₁, shown in Figure 4.

80C51BH I/O Ports

The I/O port drive of the 80C51BH is similar to the 8051. The I/O buffers for Ports 1, 2, and 3 are implemented as shown in Figure 4.

When the port latch contains a 0, all pFETs in Figure 4 are off while the nFET is turned on. When the port latch makes a 0-to-1 transition, the nFET turns off. The strong pullup pFET, P₁, turns on for two oscillator periods, pulling the output HIGH very rapidly. As the output line is drawn HIGH, pFET P₃ turns on through the inverter to supply the I_{OH} source current. This inverter and P₃ form a latch which holds the 1 and is supported by P₂.

When Port 2 is used as an address port, for access to external program of data memory, any address bit that contains a 1 will have its strong pullup turned on for the entire duration of the external memory access.

When an I/O pin on Ports 1, 2, or 3 is used as an input, the user should be aware that the external circuit must sink current during the logical 1-to-0 transition. The maximum sink current is specified as I_{TL} under the D.C. Specifications. When the input goes below approximately 2 V, P_3 turns off to save I_{CC} current. Note, when returning to a logical 1, P_2 is the only internal pullup that is on. This will result in a slow rise time if the user's circuit does not force the input line HIGH.

DESIGN CONSIDERATIONS

- At power on, the voltage on V_{CC} and RST must come up at the same time for a proper start-up.
- Before entering the Power Down mode, the contents of the Carry Bit and B.7 must be equal.

TABLE 2. STATUS OF THE EXTERNAL PINS DURING IDLE AND POWER-DOWN MODES

Mode	Program Memory	ALE	PSEN	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Port Data	Port Data	Port Data	Port Data
Idle	External	1	1	Floating	Port Data	Address	Port Data
Power-Down	Internal	0	0	Port Data	Port Data	Port Data	Port Data
Power-Down	External	0	0	Floating	Port Data	Port Data	Port Data

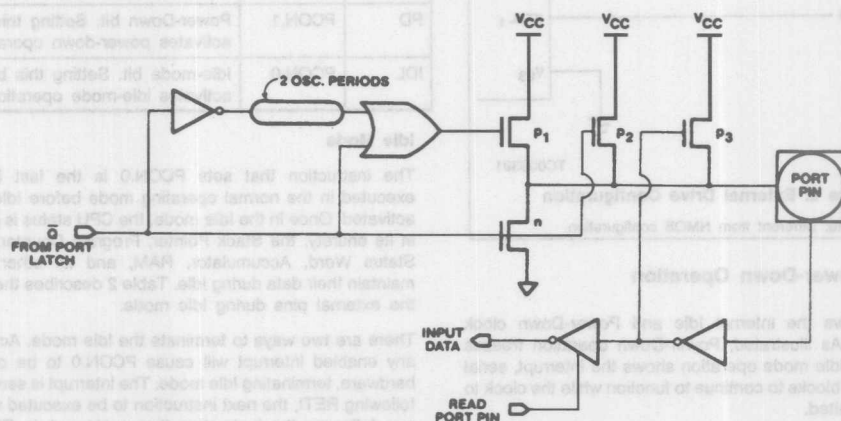


Figure 4. I/O Buffers in the 80C51BH (Ports 1, 2, 3)

ABSOLUTE MAXIMUM RATINGS

Storage Temperature -65°C to +150°C
 Voltage on Any Pin to V_{SS} -0.5 V to $V_{CC} + 0.5$ V
 Voltage on V_{CC} to V_{SS} -0.5 V to 6.5 V
 Power Dissipation 200 mW

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices
 Temperature (T_A) 0 to +70°C
 Supply Voltage (V_{CC}) +4 V to +6 V
 Ground (V_{SS}) 0 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over operating ranges unless otherwise specified

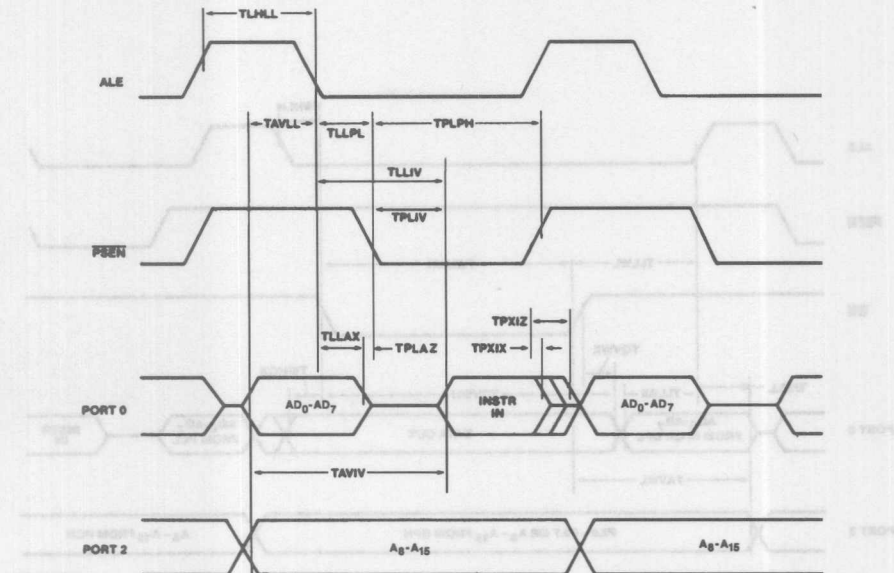
Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Units
V_{IL}	Input LOW Voltage (Except \overline{EA})		-0.5	.2 $V_{CC} - .1$	V
V_{IL1}	Input LOW Voltage (\overline{EA})		-0.5	.2 $V_{CC} - .3$	V
V_{IH}	Input HIGH Voltage (Except XTAL ₁ , RST)		.2 $V_{CC} + .9$	$V_{CC} + 0.5$	V
V_{IH1}	Input HIGH Voltage (XTAL ₁ , RST)		.7 V_{CC}	$V_{CC} + 0.5$	V
V_{OL}	Output LOW Voltage (Ports 1, 2, 3)	$I_{OL} = 1.6$ mA (Note 1)		0.45	V
V_{OL1}	Output LOW Voltage (Port 0, ALE, \overline{PSEN})	$I_{OL} = 3.2$ mA (Note 1)		0.45	V
V_{OH}	Output HIGH Voltage (Ports 1, 2, 3)	$I_{OH} = -60$ μ A, $V_{CC} = 5$ V $\pm 10\%$	2.4		V
		$I_{OH} = -25$ μ A	.75 V_{CC}		V
		$I_{OH} = -10$ μ A	.9 V_{CC}		V
V_{OH1}	Output HIGH Voltage (Port 0 in External Bus Mode, ALE, \overline{PSEN})	$I_{OH} = -800$ μ A, $V_{CC} = 5$ V $\pm 10\%$	2.4		V
		$I_{OH} = -300$ μ A	.75 V_{CC}		V
		$I_{OH} = -80$ μ A (Note 2)	.9 V_{CC}		V
I_{IL}	Logical 0 Input Current (Ports 1, 2, 3)	$V_{IN} = 0.45$ V		-50	μ A
I_{TL}	Logical 1 to 0 Transition Current (Ports 1, 2, 3)	$V_{IN} = 2$ V		-650	μ A
I_{LI}	Input Leakage Current (Port 0, \overline{EA})	$0.45 < V_{IN} < V_{CC}$		± 10	μ A
RRST	Reset Pulldown Resistor		50	150	k Ω
CIO	Pin Capacitance	Test Freq. = 1 MHz, $T_A = 25^\circ\text{C}$		10	pF
I_{PD}	Power Down Current	$V_{CC} = 2$ to 6 V (Note 3)		50	μ A

MAXIMUM I_{CC} (mA)

Freq. V_{CC}	Operating (Note 4)			Idle (Note 5)		
	4 V	5 V	6 V	4 V	5 V	6 V
3.5 MHz	4.3	5.7	7.5	1.1	1.6	2.2
8.0 MHz	8.3	11	14	1.8	2.7	3.7
12 MHz	12	16	20	2.5	3.7	5
16 MHz	16	20.5	25	3.5	5	6.5

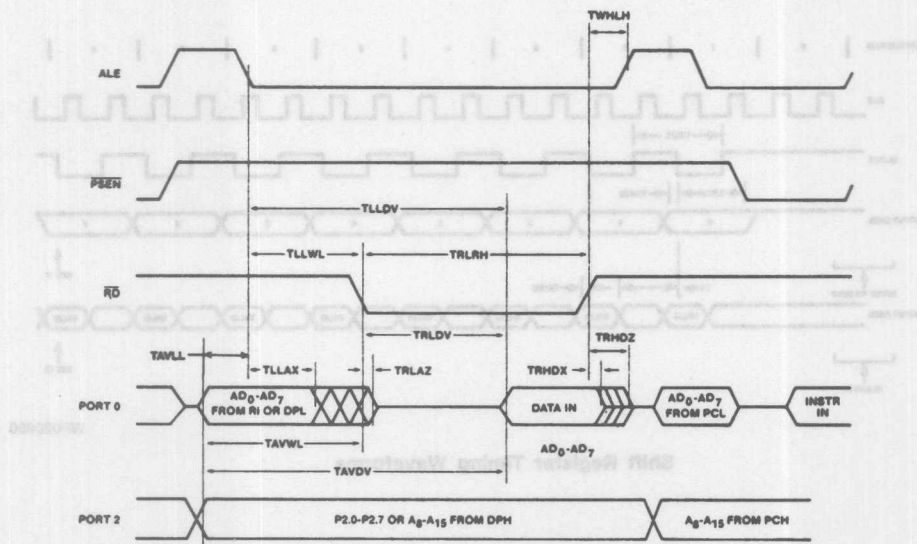
- Notes: 1. Capacitive loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OLS} of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100 pF), the noise pulse on the ALE line may exceed 0.8 V. In such cases it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt-Trigger STROBE input.
2. Capacitive loading on Ports 0 and 2 may cause the V_{OH} on ALE and \overline{PSEN} to momentarily fall before the .9 V_{CC} specification when the address bits are stabilizing.
3. Power-Down I_{CC} is measured with all outputs pins disconnected: \overline{EA} = Port 0 = V_{CC} ; XTAL₂ N.C.; RST = V_{SS} .
4. I_{CC} is measured with all output pins disconnected; XTAL₁ driven with TCLCH, TCHCL = 5 ns, $V_{IL} = V_{SS} + .5$ V, $V_{IH} = V_{CC} - .5$ V; XTAL₂ N.C.; \overline{EA} = RST = Port 0 = V_{CC} .
 I_{CC} would be slightly higher if a crystal oscillator is used.
5. Idle I_{CC} is measured with all output pins disconnected; XTAL₁ driven with TCLCH, TCHCL = 5 ns, $V_{IL} = V_{SS} + .5$ V, $V_{IH} = V_{CC} - .5$ V; XTAL₂ N.C.; Port 0 = V_{CC} ; \overline{EA} = RST = V_{SS} .

SWITCHING WAVEFORMS



WF021961

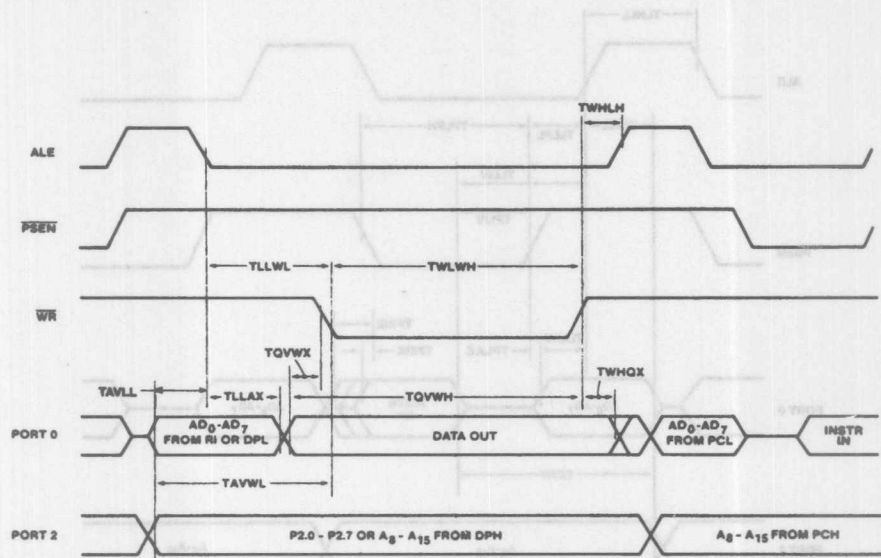
External Program Memory Read Cycle



WF020961

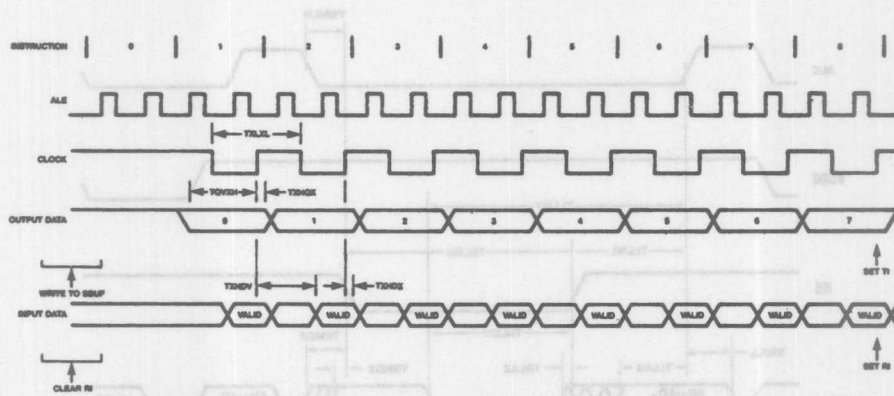
External Data Memory Read Cycle

SWITCHING WAVEFORMS (Cont'd.)



WF020931

External Data Memory Write Cycle

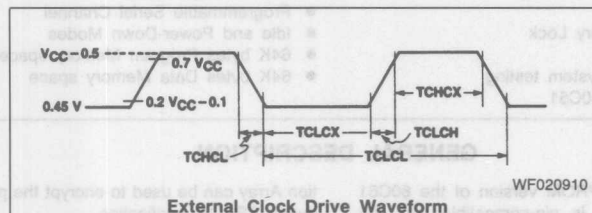


WF020950

Shift Register Timing Waveforms

EXTERNAL CLOCK DRIVE

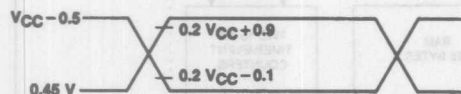
Parameter Symbol	Parameter Description	Min.	Max.	Units
1/TCLCL	Oscillator Frequency	3.5	16	MHz
TCHCX	HIGH Time	20		ns
TCLCX	LOW Time	20		ns
TCLCH	Rise Time		20	ns
TCHCL	Fall Time		20	ns



SERIAL PORT TIMING — SHIFT REGISTER MODE

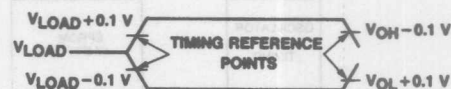
Test Conditions: $T_A = 0^\circ\text{C}$ to 70°C ; $V_{CC} = 5\text{ V} \pm 20\%$; $V_{SS} = 0\text{ V}$; Load Capacitance = 80 pF

Parameter Symbol	Parameter Description	16 MHz Osc.		Variable Oscillator		Units
		Min.	Max.	Min.	Max.	
TXLXL	Serial Port Clock Cycle Time	750		12TCLCL		ns
TQVXH	Output Data Setup to Clock Rising Edge	492		10TCLCL - 133		ns
TXHGX	Output Data Hold After Clock Rising Edge	8		2TCLCL - 117		ns
TXHDX	Input Data Hold After Clock Rising Edge	0		0		ns
TXHDV	Clock Rising Edge to Input Data Valid		492		10TCLCL - 133	ns



AC INPUTS DURING TESTING ARE DRIVEN AT $V_{CC}-0.5$ FOR A LOGIC "1" AND 0.45 V FOR A LOGIC "0." TIMING MEASUREMENTS ARE MADE AT V_{IH} MIN. FOR A LOGIC "1" AND V_{IL} MAX. FOR A LOGIC "0."

AC Testing Input/Output Waveforms

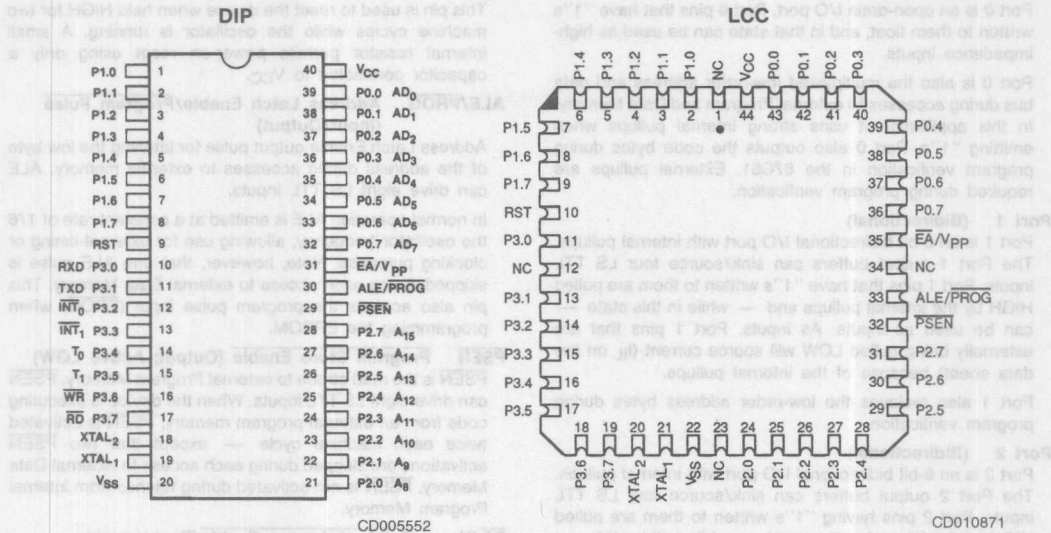


FOR TIMING PURPOSES A PORT PIN IS NO LONGER FLOATING WHEN A 100 mV CHANGE FROM LOAD VOLTAGE OCCURS, AND BEGINS TO FLOAT WHEN A 100 mV CHANGE FROM THE LOADED V_{OH}/V_{OL} LEVEL OCCURS. $I_{OL}/I_{OH} \geq \pm 20\text{ mA}$.

Float Waveform

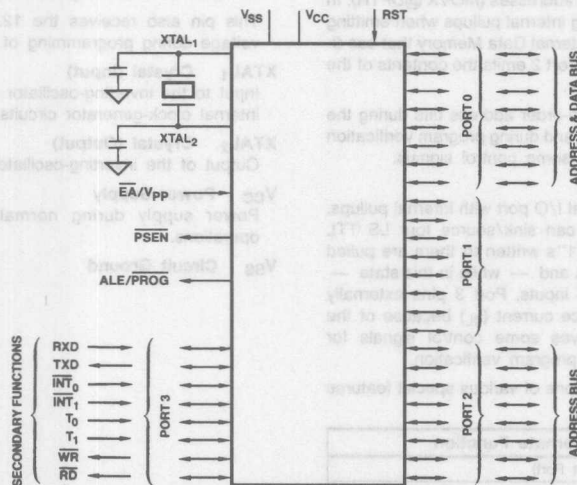
CONNECTION DIAGRAMS

Top View



Note: Pin 1 is marked for orientation.

LOGIC SYMBOL



LS001326

PIN DESCRIPTION

Port 0 (Bidirectional; Open Drain)

Port 0 is an open-drain I/O port. Port 0 pins that have "1"s written to them float, and in that state can be used as high-impedance inputs.

Port 0 is also the multiplexed low-order address and data bus during accesses to external Program and Data Memory. In this application it uses strong internal pullups when emitting "1"s. Port 0 also outputs the code bytes during program verification in the 87C51. External pullups are required during program verification.

Port 1 (Bidirectional)

Port 1 is an 8-bit bidirectional I/O port with internal pullups. The Port 1 output buffers can sink/source four LS TTL inputs. Port 1 pins that have "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 1 pins that are externally being pulled LOW will source current (I_{IL} on the data sheet) because of the internal pullups.

Port 1 also receives the low-order address bytes during program verification.

Port 2 (Bidirectional)

Port 2 is an 8-bit bidirectional I/O port with internal pullups. The Port 2 output buffers can sink/source four LS TTL inputs. Port 2 pins having "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 2 pins externally being pulled LOW will source current (I_{IL}) because of internal pullups.

Port 2 emits the high-order address byte during fetches from external Program Memory and during accesses to external Data Memory that use 16-bit addresses (MOVX @DPTR). In this application it uses strong internal pullups when emitting "1"s. During accesses to external Data Memory that use 8-bit addresses (MOVX @Ri), Port 2 emits the contents of the P2 Special Function register.

Port 2 also receives the high-order address bits during the programming of the EPROM and during program verification of the EPROM, as well as some control signals.

Port 3 (Bidirectional)

Port 3 is an 8-bit bidirectional I/O port with internal pullups. The Port 3 output buffers can sink/source four LS TTL inputs. Port 3 pins having "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 3 pins externally being pulled LOW will source current (I_{IL}) because of the pullups. Port 3 also receives some control signals for EPROM programming and program verification.

Port 3 also serves the functions of various special features as listed below:

Port Pin	Alternate Function
P _{3.0}	RxD (Serial Input Port)
P _{3.1}	TxD (Serial Output Port)
P _{3.2}	INT ₀ (External Interrupt 0)
P _{3.3}	INT ₁ (External Interrupt 1)
P _{3.4}	T ₀ (Timer 0 External Input)
P _{3.5}	T ₁ (Timer 1 External Input)
P _{3.6}	WR (External Data Memory Write Strobe)
P _{3.7}	RD (External Data Memory Read Strobe)

RST Reset (Input; Active HIGH)

This pin is used to reset the device when held HIGH for two machine cycles while the oscillator is running. A small internal resistor permits power-on reset using only a capacitor connected to V_{CC}.

ALE/PROG Address Latch Enable/Program Pulse (Input/Output)

Address Latch Enable output pulse for latching the low byte of the address during accesses to external memory. ALE can drive eight LS TTL inputs.

In normal operation ALE is emitted at a constant rate of 1/6 the oscillator frequency, allowing use for external-timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external Data Memory. This pin also accepts the program pulse input (PROG) when programming the EPROM.

PSEN Program Store Enable (Output; Active LOW)

PSEN is the read strobe to external Program Memory. PSEN can drive eight LS TTL inputs. When the device is executing code from an external program memory, PSEN is activated twice each machine cycle — except that two PSEN activations are skipped during each access to external Data Memory. PSEN is not activated during fetches from internal Program Memory.

EA/Vpp External Access Enable/Programming Voltage (Input; Active LOW)

EA must be externally held LOW to enable the device to fetch code from external Program Memory locations 0000H to 0FFFH. If EA is held HIGH, the 87C51 executes from internal Program Memory unless the program counter contains an address greater than 0FFFH.

This pin also receives the 12.75-V programming supply voltage during programming of the EPROM.

XTAL₁ Crystal (Input)

Input to the inverting-oscillator amplifier, and input to the internal clock-generator circuits.

XTAL₂ Crystal (Output)

Output of the inverting-oscillator amplifier.

VCC Power Supply

Power supply during normal, idle, and power-down operations.

Vss Circuit Ground

PROGRAMMING

The 87C51 can be programmed with the Flashrite algorithm. It differs from other methods in the value used for V_{pp} (programming supply voltage) and in the width and number of the ALE/PROG pulses.

To program the EPROM, either the internal or external oscillator must be running between 4 and 6 MHz, since the internal bus is used to transfer address and program data to the appropriate internal registers. Table 1 shows the various EPROM programming modes.

TABLE 1. EPROM PROGRAMMING MODES FOR THE 87C51

Mode	RST	PSEN	ALE/PROG	EA/V _{pp}	P2.7	P2.6	P3.7	P3.6
Program Code	H	L	L*	V _{pp}	H	L	H	H
Verify Code	H	L	H	V _{ppX}	L	L	H	H
Pgm Encryption Table	H	L	L*	V _{pp}	H	L	H	L
Pgm Lock Bit 1	H	L	L*	V _{pp}	H	H	H	H
Pgm Lock Bit 2	H	L	L*	V _{pp}	H	H	L	L
Read Silicon Signature	H	L	H	H	L	L	L	L

Key: H = Logic HIGH for that pin

L = Logic LOW for that pin

$V_{pp} = 12.75 \text{ V} \pm 0.25 \text{ V}$

$V_{CC} = 5 \text{ V} \pm 10\%$ during programming and verification

$2.0 \text{ V} < V_{ppX} < 13.0 \text{ V}$

*ALE/PROG receives 25 programming pulses while V_{pp} is held at 12.75 V. Each programming pulse is low for 100 μs ($\pm 10\%$ μs) and high for a minimum of 10 μs .

Programming

The programming configuration is shown in Figure 1. The address of the EPROM location to be programmed is applied to Ports 1 and 2 as shown in the figure. The code byte to be programmed into that location is applied to Port 0. Once RST, PSEN, Port 2, and Port 3 are held to the levels indicated in Figure 1, ALE/PROG is pulsed low 25 times as shown in Figure 2.

The maximum voltage applied to the $\overline{\text{EA}}/V_{pp}$ pin must not exceed 13 V at any time as specified for V_{pp} . Even a slight spike can cause permanent damage to the device. The V_{pp} source should thus be well regulated and glitch-free.

When programming, a 0.1 μF capacitor is required across V_{pp} and ground to suppress spurious transients which may damage the device.

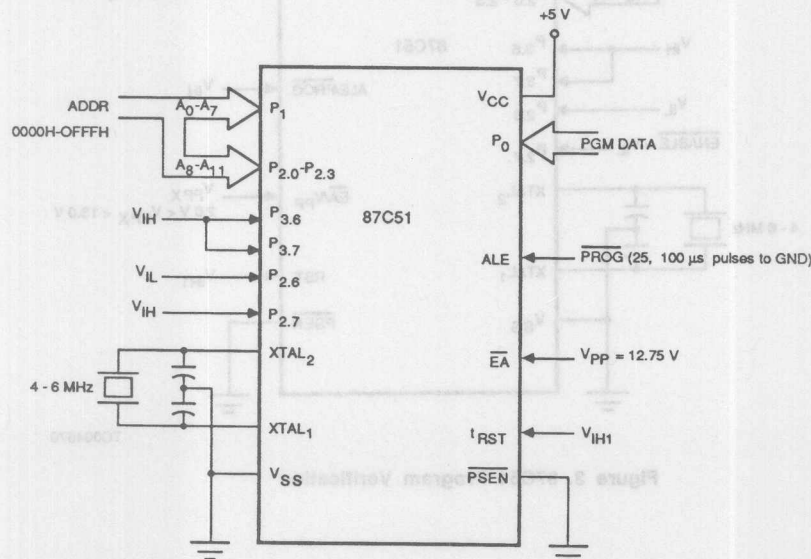


Figure 1. 87C51 Programming Configuration

TC004690

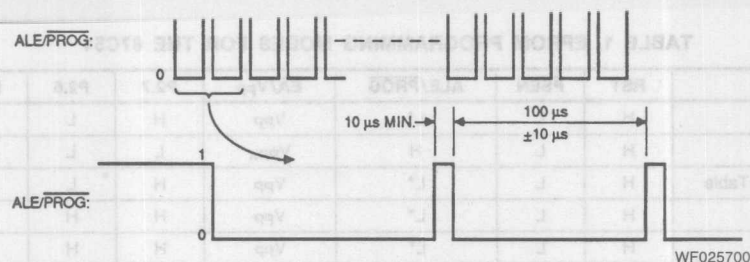


Figure 2. $\overline{\text{PROG}}$ Waveforms

Program Verification

The 87C51 provides a method of reading the programmed code bytes in the EPROM array for program verification. This function is possible as long as Lock Bit 2 has not been programmed.

For program verification, the address of the Program Memory location to be read is applied to Ports 1 and 2 as shown in Figure 3. Once RST, PSEN, Port 2, and Port 3 are held to the levels indicated, the contents of the addressed location will be emitted on Port 0. External pullups are required on Port 0 for this operation. The EPROM programming and verification waveforms provide further details.

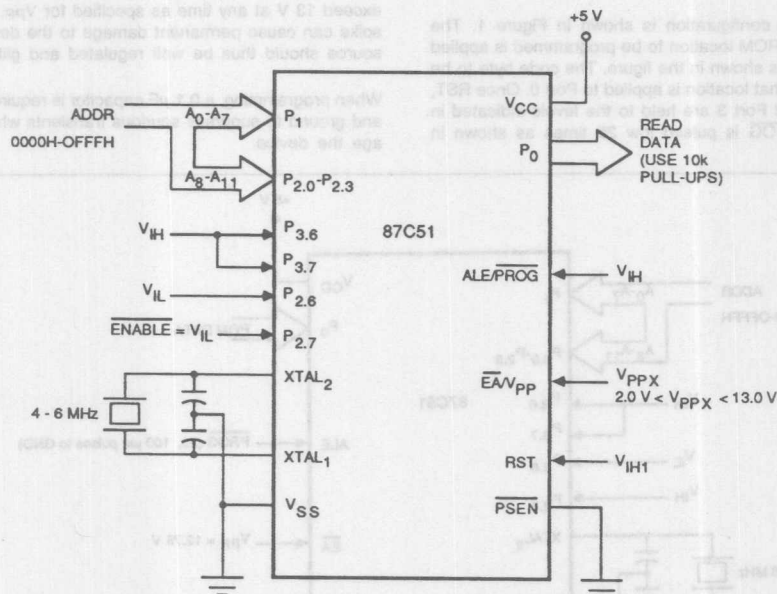


Figure 3. 87C51 Program Verification

Program Encryption Table

The 87C51 features a 32-byte Encryption Array. It can be programmed by the customer, thus encrypting the program code bytes read during EPROM verification. The EPROM verification procedure is performed as usual except that each code byte comes out logically X-NORed with one of the 32 key bytes.

The key byte used is the one whose address corresponds to the lower 5 bits of the EPROM verification address. Thus, when the EPROM is verified starting with address 0000H, all 32 keys in their correct sequence must be known. Unprogrammed bytes have the value FFH. Thus, if the Encryption Table is left unprogrammed, no encryption will be performed, since any byte X-NORed with FFH leaves that byte unchanged.

To program the Encryption Table, programming is set up as usual, except that P3.6 is held LOW, as shown in Table 1. The 25-pulse programming sequence is applied to each address, 00 through 1FH. The programming of these bytes does not affect the standard 4K-byte EPROM array. When the Encryption Table is programmed, the Program Verify operation will produce only encrypted data.

The Encryption Table cannot be directly read. The programming of Lock Bit 2 will disable further Encryption Table programming.

Security Lock Bits

The 87C51 contains two Lock Bits which can be programmed to obtain additional security features. P = Programmed and U = Unprogrammed.

Lock Bit 1	Lock Bit 2	Result
U	U	Normal Operation
U	P	<ul style="list-style-type: none"> Externally fetched code cannot access internal Program Memory All further Programming disabled (except Lock Bit 1)
P	U	Reserved
P	P	<ul style="list-style-type: none"> Externally fetched code cannot access internal Program Memory All further Programming disabled Program Verification disabled

To program the Lock Bits, the 25-pulse programming sequence is repeated using the levels shown in Table 1. After Lock Bit 2 is programmed, further programming of the Code Memory and Encryption Table is disabled. However, Lock Bit 1 may still be programmed, providing the highest level of security available on the 87C51.

When Lock Bit 1 is programmed, the logic level at the \overline{EA} pin is sampled and latched during reset. If the device is powered up without a reset, the latch initializes to a random value, and holds that value until reset is activated. It is necessary that the latched value of \overline{EA} be in agreement with the current logic level at that pin in order for the device to function properly.

Silicon Signature Verification

AMD supports silicon signature verification for the 87C51. The manufacturer code and part code can be read from the device before any programming is done to enable the EPROM Programmer to recognize the device.

To read the silicon signature, the external pins are set up as shown in Figure 4. This procedure is the same as a normal verification except that P3.6 and P3.7 are pulled to a logic LOW. The values returned are:

Manufacturer Code	Address: 0030H	Code: 01H
Part Code	Address: 0031H	Code: B0H

Code 01H indicates AMD as the manufacturer. Code B0H indicates the device type is the 87C51.

ONCE Mode

The ONCE (ON-Circuit Emulation) Mode facilitates testing and debugging of systems using the 87C51 without the 87C51

having to be removed from the circuit. The ONCE Mode is invoked by:

1. Pulling ALE LOW while RST is held HIGH, and \overline{PSEN} is HIGH.
2. Holding ALE LOW as RST is de-activated.

While the device is in ONCE Mode, the Port 0 pins go into a float state, and the other port pins and ALE and \overline{PSEN} are weakly pulled HIGH. The oscillator circuit remains active. While the 87C51 is in this mode, an emulator or test CPU can be used to drive the circuit. Normal operation is restored when a Hardware Reset is applied.

Erase Characteristics

Light and other forms of electromagnetic radiation can lead to erasure of the EPROM when exposed for extended periods of time.

Wavelengths of light shorter than 4000 angstroms, such as sunlight or indoor fluorescent lighting, can ultimately cause inadvertent erasure and should, therefore, not be allowed to expose the EPROM for lengthy durations (approximately one week in sunlight or three years in room-level fluorescent lighting). It is suggested that the window be covered with an opaque label if an application is likely to subject the device to this type of radiation.

It is recommended that ultraviolet light (of 2537 angstroms) be used to a dose of at least 15 W-sec/cm² when erasing the EPROM. An ultraviolet lamp rated at 12,000 μ W/cm² held one inch away for 20–30 minutes should be sufficient.

EPROM erasure leaves the Program Memory in an "all ones" state.

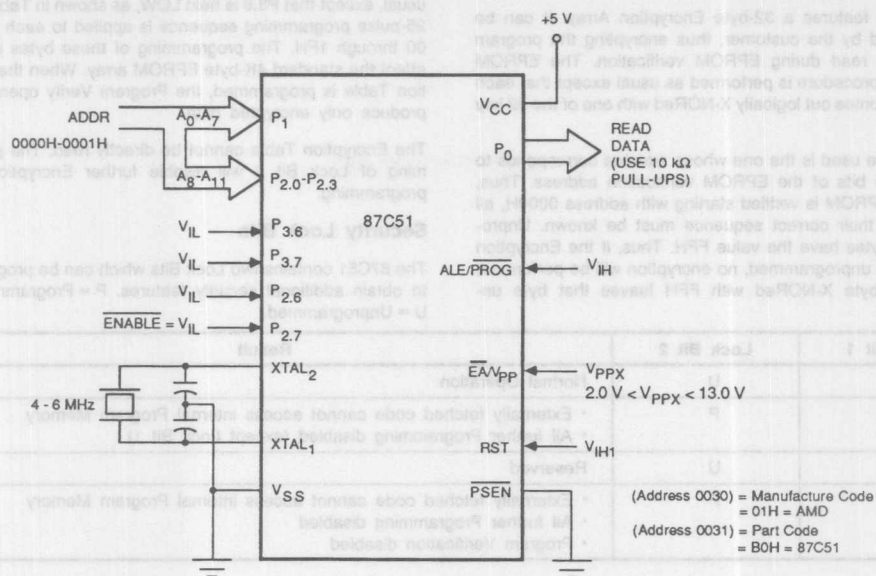


Figure 4. 87C51 Silicon Signature Verification Configuration

Oscillator Characteristics

XTAL₁ and XTAL₂ are the input and output, respectively, of an inverting amplifier which is configured for use as an on-chip oscillator (see Figure 5). Either a quartz crystal or ceramic resonator may be used.

To drive the device from an external clock source, XTAL₁ should be driven while XTAL₂ is left unconnected (see Figure 6). There are no requirements on the duty cycle of the external clock signal since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum HIGH and LOW times specified on the data sheet must be observed.

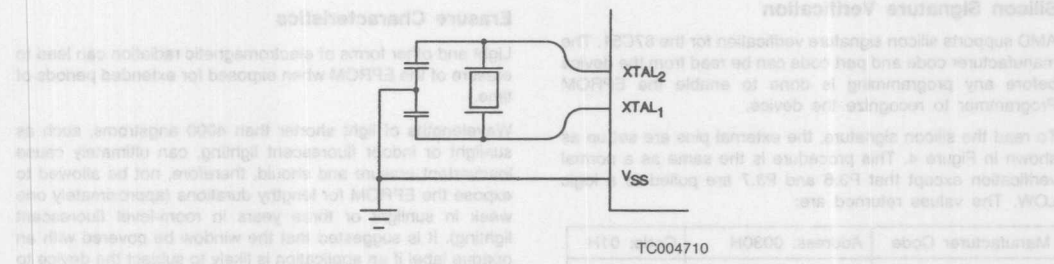


Figure 5. Crystal Oscillator

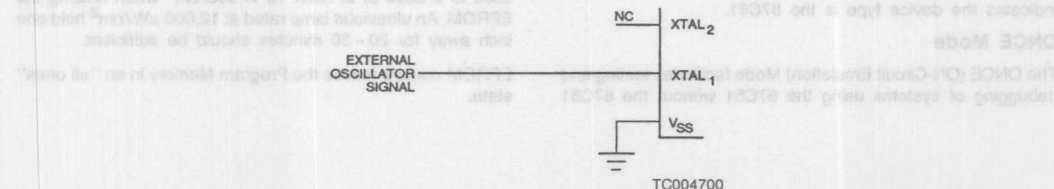


Figure 6. External Drive Configuration

ABSOLUTE MAXIMUM RATINGS

Storage Temperature -65 to +150°C
 Voltage on \overline{EA}/V_{PP} Pin to V_{SS} -0.5 to +13.0 V
 Voltage on V_{CC} to V_{SS} -0.5 to +6.5 V
 Voltage on Any Other Pin to V_{SS} -0.5 to +6.5 V
 Power Dissipation 200 mW

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A) 0 to +70°C
 Supply Voltage (V_{CC}) +4.5 to +5.5 V
 Ground (V_{SS}) 0 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over operating range

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Unit
V_{IL}	Input LOW Voltage (Except \overline{EA})		-0.5	$0.2 V_{CC} - 0.1$	V
V_{IL1}	Input LOW Voltage (\overline{EA})		0	$0.2 V_{CC} - 0.3$	V
V_{IH}	Input HIGH Voltage (Except XTAL ₁ , RST)		$0.2 V_{CC} + 0.9$	$V_{CC} + 0.5$	V
V_{IH1}	Input HIGH Voltage to XTAL ₁ , RST		$0.7 V_{CC}$	$V_{CC} + 0.5$	V
V_{OL}	Output LOW Voltage (Ports 1, 2, 3)	$I_{OL} = 1.6$ mA (Note 1)		0.45	V
V_{OL1}	Output LOW Voltage (Port 0, ALE, \overline{PSEN})	$I_{OL} = 3.2$ mA (Note 1)		0.45	V
V_{OH}	Output HIGH Voltage (Ports 1, 2, 3), ALE, \overline{PSEN}	$I_{OH} = -60$ μ A $V_{CC} = 5$ V $\pm 10\%$	2.4		V
		$I_{OH} = -10$ μ A	$0.9 V_{CC}$		
V_{OH1}	Output HIGH Voltage (Port 0 in External Bus Mode)	$I_{OH} = -800$ μ A $V_{CC} = 5$ V $\pm 10\%$	2.4		V
		$I_{OH} = -80$ μ A (Note 2)	$0.9 V_{CC}$		
I_{IL}	Logical 0 Input Current (Ports 1, 2, 3)	$V_{IN} = 0.45$ V		-50	μ A
I_{TL}	Logical 1-to-0 Transition Current (Ports 1, 2, 3)	(Note 3)		-650	μ A
I_{LI}	Input Leakage Current (Port 0)	$V_{IN} = V_{IL}$ or V_{IH}		± 10	μ A
I_{CC}	Power Supply Current: Active Mode @ 12 MHz (Note 4) Idle Mode @ 12 MHz (Note 4) Power-Down Mode	(Note 5)		25 4 50	mA μ A
RRST	Reset Pulldown Resistor		50	300	k Ω
C_{IO}	Pin Capacitance	Test Freq = 1 MHz, $T_A = 25^\circ\text{C}$		10	pF

- Notes: 1. Capacitive loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL} s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100 pF), the noise pulse on the ALE line may exceed 0.8 V. In such cases it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input.
2. Capacitive loading on Ports 0 and 2 may cause the V_{OH} on ALE and \overline{PSEN} to momentarily fall below the $0.9 V_{CC}$ specification when the address bits are stabilizing.
3. Pins of Ports 1, 2, and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V_{IN} is approximately 2 V.
4. I_{CCMAX} at other frequencies is given by:
 Active Mode: $I_{CCMAX} = 0.94 \times \text{Freq} + 13.71$
 Idle Mode: $I_{CCMAX} = 0.14 \times \text{Freq} + 2.31$
 where Freq is the external oscillator frequency in MHz. I_{CCMAX} is given in mA.
5. Active Mode I_{CC} is measured with all output pins disconnected; XTAL₁ driven with TCLCH, TCHCL = 5 ns, $V_{IL} = V_{SS} + 0.5$ V, $V_{IH} = V_{CC} - 0.5$ V; XTAL₂ N.C.; $\overline{EA} = \text{RST} = \text{Port 0} = V_{CC}$.
 Idle Mode I_{CC} is measured with all output pins disconnected; XTAL₁ driven with TCLCH, TCHCL = 5 ns, $V_{IL} = V_{SS} + 0.5$ V, $V_{IH} = V_{CC} - 0.5$ V; XTAL₂ = N.C.; Port 0 = V_{CC} ; $\overline{EA} = \text{RST} = V_{SS}$.
 Power-Down Mode I_{CC} is measured with all outputs pins disconnected; $\overline{EA} = \text{Port 0} = V_{CC}$; XTAL₂ N.C.; RST = V_{SS} .

SWITCHING CHARACTERISTICS over operating range
(Load Capacitance for Port 0, ALE, and PSEN = 100 pF, Load Capacitance for All Other Outputs = 80 pF)

Parameter Symbol	Parameter Description	12-MHz Osc.		Variable Oscillator		Unit
		Min.	Max.	Min.	Max.	
1/TCLCL	Oscillator Frequency			3.5	12	MHz
TLHLL	ALE Pulse Width	127		2TCLCL-40		ns
TAVLL	Address Valid to ALE LOW	28		TCLCL-55		ns
TLLAX	Address Hold After ALE LOW	48		TCLCL-35		ns
TLLIV	ALE LOW to Valid Instr. In		234		4TCLCL-100	ns
TLLPL	ALE LOW to PSEN LOW	43		TCLCL-40		ns
TPLPH	PSEN Pulse Width	205		3TCLCL-45		ns
TPLIV	PSEN LOW to Valid Instr. In		145		3TCLCL-105	ns
TPXIX	Input Instr. Hold After PSEN	0		0		ns
TPXIZ	Input Instr. Float After PSEN		59		TCLCL-25	ns
TAVIV	Address to Valid Instr. In		312		5TCLCL-105	ns
TPLAZ	PSEN LOW to Address Float		10		10	ns
TRLRH	RD Pulse Width	400		6TCLCL-100		ns
TWLWH	WR Pulse Width	400		6TCLCL-100		ns
TRLDV	RD LOW to Valid Data In		252		5TCLCL-165	ns
TRHDX	Data Hold After RD	0		0		ns
TRHDZ	Data Float After RD		97		2TCLCL-70	ns
TLLDV	ALE LOW to Valid Data In		517		8TCLCL-150	ns
TAVDV	Address to Valid Data In		585		9TCLCL-165	ns
TLLWL	ALE LOW to RD or WR LOW	200	300	3TCLCL-50	3TCLCL+50	ns
TAVWL	Address Valid to RD or WR LOW	203		4TCLCL-130		ns
TQVWX	Data Valid to WR Transition	23		TCLCL-60		ns
TQVWH	Data Valid to WR HIGH	433		7TCLCL-150		ns
TWHQX	Data Hold After WR	33		TCLCL-50		ns
TRLAZ	RD LOW to Address Float		0		0	ns
TWHLH	RD or WR HIGH to ALE HIGH	43	123	TCLCL-40	TCLCL+40	ns

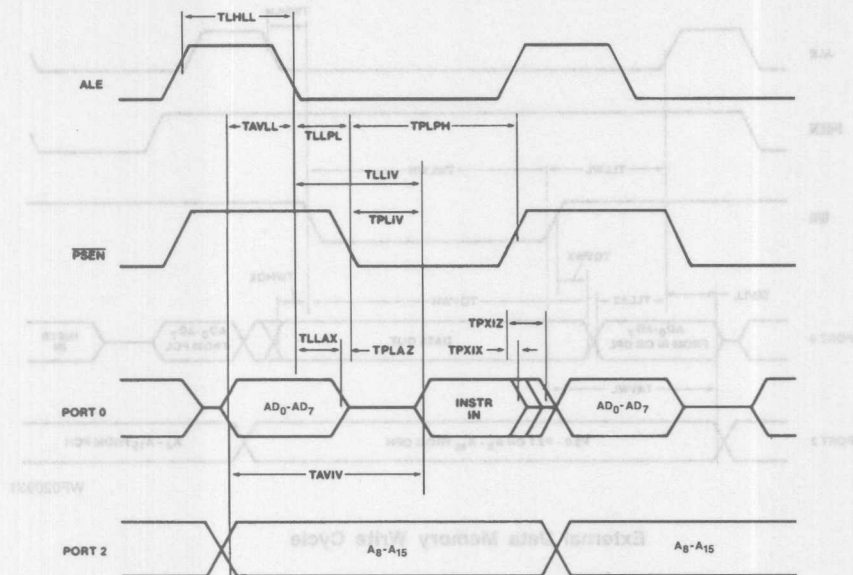
SWITCHING WAVEFORMS

KEY TO SWITCHING WAVEFORMS

WAVEFORM	INPUTS	OUTPUTS
	MUST BE STEADY	WILL BE STEADY
	MAY CHANGE FROM H TO L	WILL BE CHANGING FROM H TO L
	MAY CHANGE FROM L TO H	WILL BE CHANGING FROM L TO H
	DON'T CARE; ANY CHANGE PERMITTED	CHANGING; STATE UNKNOWN
	DOES NOT APPLY	CENTER LINE IS HIGH IMPEDANCE "OFF" STATE

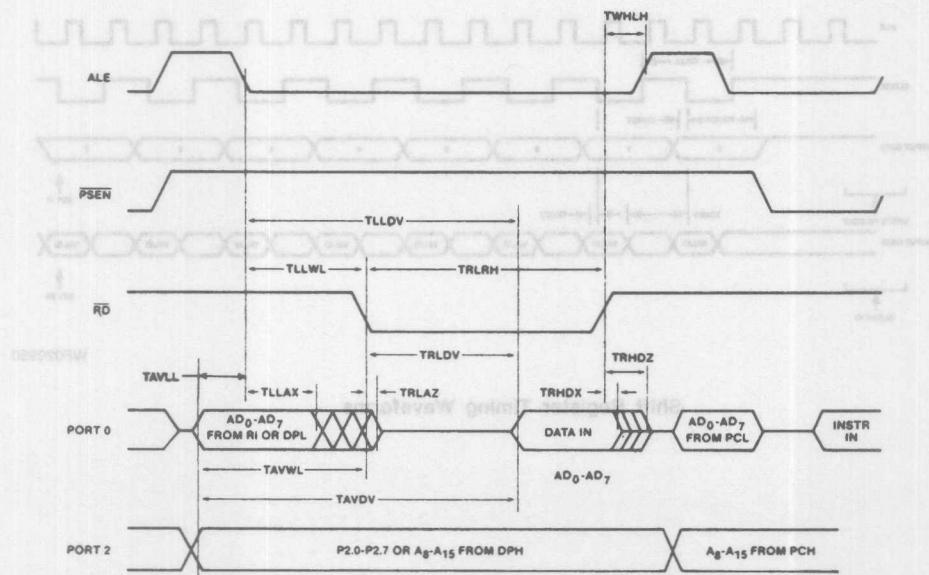
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SWITCHING WAVEFORMS



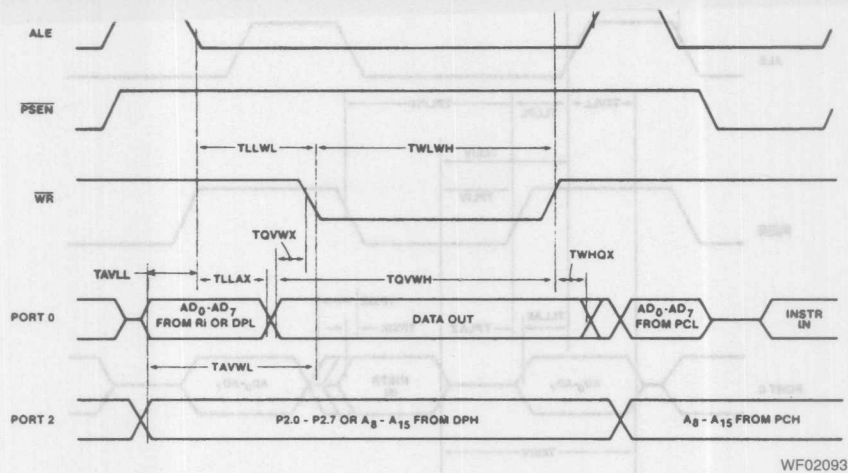
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External Program Memory Read Cycle



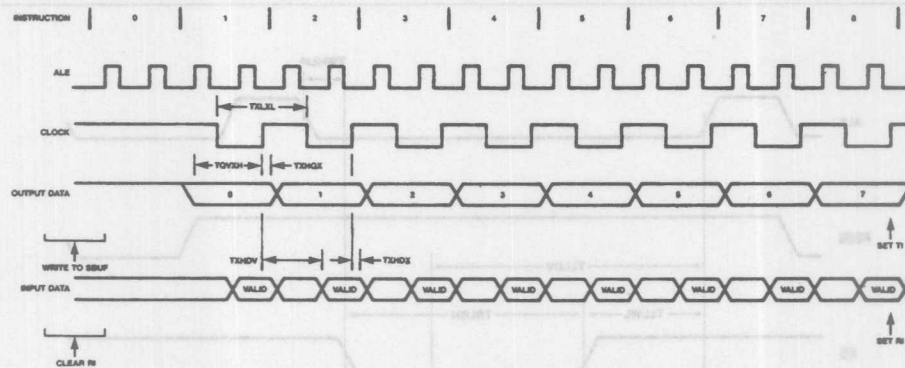
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External Data Memory Read Cycle



WF020931

External Data Memory Write Cycle

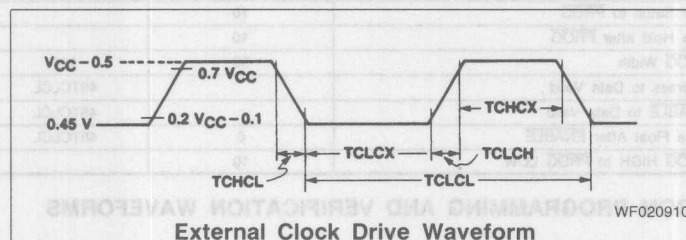


WF020950

Shift Register Timing Waveforms

EXTERNAL CLOCK DRIVE

Parameter Symbol	Parameter Description	Min.	Max.	Unit
1/TCLCL	Oscillator Frequency	3.5	12	MHz
TCHCX	HIGH Time	20		ns
TCLCX	LOW Time	20		ns
TCLCH	Rise Time		20	ns
TCHCL	Fall Time		20	ns

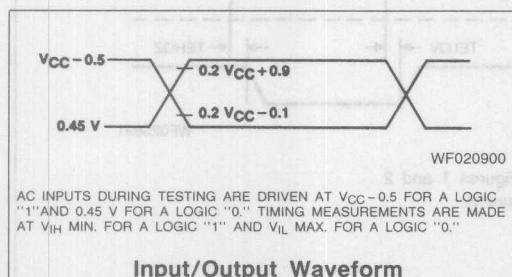


SERIAL PORT TIMING — SHIFT REGISTER MODE

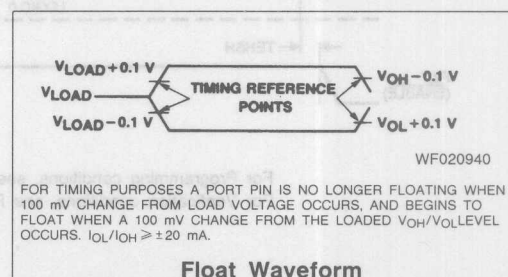
(Test Conditions: $T_A = 0$ to $+70^\circ\text{C}$; $V_{CC} = 5\text{ V} \pm 10\%$; $V_{SS} = 0\text{ V}$; Load Capacitance = 80 pF)

Parameter Symbol	Parameter Description	12 MHz Osc.		Variable Oscillator		Unit
		Min.	Max.	Min.	Max.	
TXLXL	Serial Port Clock Cycle Time	1.0		12TCLCL		μs
TQVXH	Output Data Setup to Clock Rising Edge	700		10TCLCL-133		ns
TXHQX	Output Data Hold After Clock Rising Edge	50		2TCLCL-117		ns
TXHDX	Input Data Hold After Clock Rising Edge	0		0		ns
TXHDV	Clock Rising Edge to Input Data Valid		700		10TCLCL-133	ns

AC Testing



AC INPUTS DURING TESTING ARE DRIVEN AT $V_{CC}-0.5$ FOR A LOGIC "1" AND 0.45 V FOR A LOGIC "0." TIMING MEASUREMENTS ARE MADE AT $V_{IH}\text{ MIN.}$ FOR A LOGIC "1" AND $V_{IL}\text{ MAX.}$ FOR A LOGIC "0."



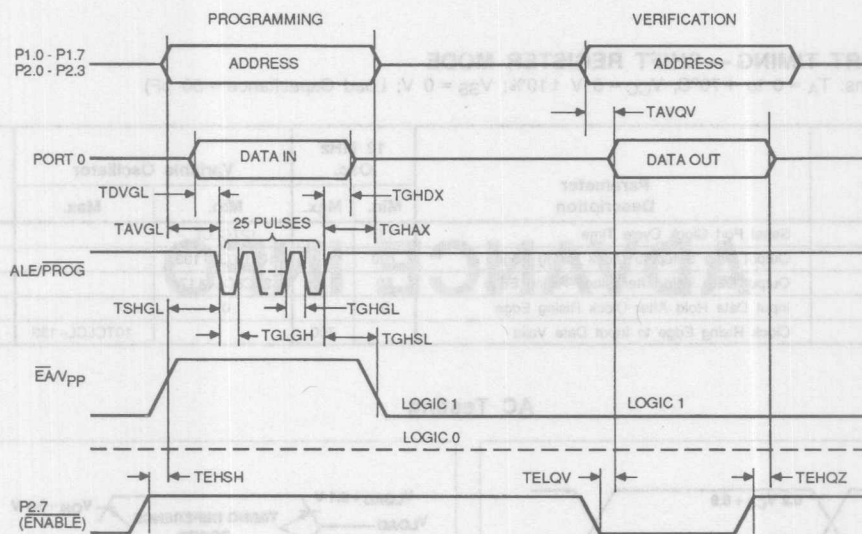
FOR TIMING PURPOSES A PORT PIN IS NO LONGER FLOATING WHEN A 100 mV CHANGE FROM LOAD VOLTAGE OCCURS, AND BEGINS TO FLOAT WHEN A 100 mV CHANGE FROM THE LOADED V_{OH}/V_{OL} LEVEL OCCURS. $I_{OL}/I_{OH} \geq \pm 20\text{ mA}$.

EPROM PROGRAMMING AND VERIFICATION CHARACTERISTICS

(T_A = +21 to +27°C)

Parameter Symbol	Parameter Description	Min.	Max.	Unit
V _{pp}	Programming Supply Voltage	12.5	13.0	V
I _{pp}	Programming Supply Current		50	mA
1/TCLCL	Oscillator Frequency	4	6	MHz
TAVGL	Address Setup to PROG	48TCLCL		
TGHAX	Address Hold After PROG	48TCLCL		
TDVGL	Data Setup to PROG	48TCLCL		
TGHDX	Data Hold After PROG	48TCLCL		
TEHSH	P _{2.7} (ENABLE) HIGH to V _{pp}	48TCLCL		
TSHGL	V _{pp} Setup to PROG	10		μs
TGHSL	V _{pp} Hold after PROG	10		μs
TGLGH	PROG Width	90	110	μs
TAVQV	Address to Data Valid		48TCLCL	
TELQV	ENABLE to Data Valid		48TCLCL	
TEHQZ	Data Float After ENABLE	0	48TCLCL	
TGHGL	PROG HIGH to PROG LOW	10		μs

EPROM PROGRAMMING AND VERIFICATION WAVEFORMS



WF025691

For Programming conditions, see Figures 1 and 2.

For Verification conditions, see Figure 3.

DESIGNING WITH THE 80C51BH

CMOS Evolves

The original CMOS logic families were the 4000-series and the 74C-series circuits. The 74C-series circuits are functional equivalents to the correspondingly numbered 74-series TTL circuits, but have CMOS logic levels and retain the other well known characteristics of CMOS logic.

These characteristics are: low power consumption, high noise immunity, and slow speed. The low power consumption is inherent to the nature of the CMOS circuit. The noise immunity is due partly to the CMOS logic levels, and partly to the slowness of the circuits. The slow speed was due to the technology used to construct the transistors in the circuit.

This technology is called metal-gate CMOS, because the transistor gates are formed by metal deposition. More importantly, the gates are formed after the drain and source regions have been defined, and must overlap the source and drain somewhat to allow for alignment tolerances. This overlap plus the relatively large size of the transistors result in high electrode capacitance; that is what limits the speed of the circuit.

High-speed CMOS became feasible with the development of the self-aligning silicon-gate technology. In this process, polysilicon gates are deposited **before** the source and drain regions are defined. Then the source and drain regions are formed by ion implantation using the gate itself as a mask for the implantation. This eliminates most of the overlap capacitance. In addition, the process allows smaller transistors, resulting in a significant increase in circuit speed. The 74HC-series of CMOS logic circuits is based on this technology, and has speed comparable to LS TTL, which is to say about 10 times faster than the 74C-series circuits.

The size reduction that contributes to the higher speed also demands an accompanying reduction in the maximum supply voltage. High-speed CMOS is generally limited to 6 V.

What is CMOS?

There are two CMOS processes, one based on an n-well structure and one based on a p-well structure. In the n-well structure, n-type wells are diffused into a p-type substrate. Then the n-channel transistors (nFETs) are built into the substrate and pFETs are built into the n-wells. In the p-well structure, p-type wells are diffused into an n-type substrate. Then the nFETs are built into the wells and pFETs into the substrate. Both processes

have advantages and disadvantages, which are largely unseen by the user.

Lower operating voltages are easier to obtain with the p-well structure than with the n-well structure. But the p-well structure does not easily adapt to an EPROM which would be pin-for-pin compatible with NMOS EPROMs. On the other hand the n-well structure can be based on the solidly founded NMOS process, in which nFETs are built into a p-type substrate. This allows somewhat more than half of the transistors in a CMOS chip to be constructed by processes that are already well characterized.

The 8051 Family in CMOS

The 80C51BH is the CMOS version of the original 8051. The 80C31BH is the ROMless 80C51BH, equivalent to the 8031. These CMOS devices are architecturally identical with their NMOS counterparts, except that they have two added features for reduced power: Idle and Power Down modes of operation.

In most cases an 80C51BH can directly replace the 8051 in existing applications. It can execute the same code at the same speed, accept signals from the same sources, and drive the same loads. However, the 80C51BH covers a wider range of speeds, will emit CMOS logic levels to CMOS loads, and will draw about 1/10 the current of an 8051 (and less in the reduced power modes). Interchangeability between the NMOS and CMOS devices is discussed in more detail in the final section.

It should be noted that the 80C51BH CPU is not static. That means if the clock frequency is too low, the CPU might forget what it was doing. This is because the circuitry uses a number of dynamic nodes. A dynamic node is one that uses the node-to-ground capacitance to form a temporary storage cell. Dynamic nodes are used to reduce the transistor count, and hence the chip area to produce a more economical device.

This is not to say that the on-chip RAM in CMOS micro-controllers is dynamic. It's not. It is the CPU that is dynamic, and that is what imposes the minimum clock frequency specification.

Latchup

Latchup is an SCR-type turn-on phenomenon that is the traditional nemesis of CMOS systems. The substrate, the wells, and the transistors form parasitic pnpn structures within the device. These parasitic structures turn

on like an SCR if a sufficient amount of forward current is driven through one of the junctions. From the circuit designer's point of view it can happen whenever an input or output pin is externally driven a diode drop above V_{CC} or below V_{SS} , by a source that is capable of supplying the required trigger current.

However much of a problem latchup has been in the past, it is good to know that in most recently developed CMOS devices, the current required to trigger latchup is typically well over 100 mA. The 80C51BH is virtually immune to latchup. (References 1 and 2 present a discussion of the latchup mechanisms and the steps that are taken on the chip to guard against it.) Modern CMOS is not immune to latchup, but with trigger currents in the hundreds of mA, latchup is certainly a lot easier to avoid than it once was.

A careless power-up sequence might trigger latchup in the older CMOS families, but it's unlikely to be a major problem in high-speed CMOS. There is still some risk incurred in inserting or removing chips or boards in a CMOS system while the power is on. Also, severe transients, such as inductive kicks or momentary short circuits, can exceed the trigger current for latchup.

For applications in which some latchup risk seems unavoidable, put a small resistor (100 Ω or so) in series with the signal lines to ensure that the trigger current will never be reached. This also helps to control overshoot and RFI.

Logic Levels and Interfacing Problems

CMOS logic levels differ from TTL levels in two ways. First, for equal supply voltages, CMOS gives (and requires) a higher "logic 1" level than TTL. Secondly, CMOS logic levels are V_{CC} (or V_{DD}) dependent, whereas guaranteed TTL logic levels are fixed when V_{CC} is within TTL specs.

Standard 74HC logic levels are as follows:

$$V_{IH, \min} = 70\% \text{ of } V_{CC}$$

$$V_{IL, \max} = 20\% \text{ of } V_{CC}$$

$$V_{OH, \min} = V_{CC} - 0.1V, |I_{OH}| \leq 20 \mu A$$

$$V_{OL, \max} = 0.1V, |I_{OL}| \leq 20 \mu A$$

Figure 9-1 compares 74HC, LS TTL, and 74HCT logic levels with those of the NMOS 8051 and CMOS 80C51BH for $V_{CC} = 5V$.

Output logic levels depend of course on load current, and are normally specified at several load currents. When CMOS and TTL are powered by the same V_{CC} , the logic levels guaranteed on the data sheets indicate that CMOS can drive TTL, but TTL can't drive CMOS. The incompatibility is that the TTL circuit's V_{OH} level is too low to reliably be recognized by the CMOS circuit as a valid V_{IH} . Since NMOS circuits were designed to be TTL-compatible, they have the same incompatibility.

Fortunately, 74HCT-series circuits are available to ease these interfacing problems. They have TTL-compatible logic levels at the inputs and standard CMOS levels at the outputs.

The 80C51BH is designed to work with either TTL or CMOS. Therefore its logic levels are specified very much like 74HCT circuits. That is, its input logic levels are TTL-compatible, and its output characteristics are like standard high-speed CMOS.

Noise Considerations

One of the major reasons for going to CMOS has traditionally been that CMOS is less susceptible to noise than TTL. As previously noted, its low susceptibility to noise is partly due to superior noise margins, and partly due to its slow speed.

Noise margin is the difference between V_{OL} and V_{IL} , or between V_{OH} and V_{IH} . If V_{OH} from a driving circuit is 2.7 V and V_{IH} to the driven circuit is 2.0 V, then the driven circuit has 0.7 V of noise margin at the logic high level. These kinds of comparisons show that an all-CMOS system has wider noise margins than an all-TTL system. Figure 9-2 shows noise margins in CMOS and LS TTL systems when both have $V_{CC} = 5V$; CMOS/CMOS systems have an edge over LS TTL in this respect.

Noise margins can be misleading, however, because they don't say how much noise energy in the circuit it takes to induce a noise voltage of sufficient amplitude to cause a logic error. This involves consideration of the

$V_{CC} = 5V$					
Logic State	74HC	74HCT	LS TTL	8051	80C51BH
V_{IH}	3.5 V	2.0 V	2.0 V	2.0 V	1.9 V
V_{IL}	1.0 V	0.8 V	0.8 V	0.8 V	0.9 V
V_{OH}	4.9 V	4.9 V	2.7 V	2.4 V	4.5 V
V_{OL}	0.1 V	0.1 V	0.5 V	0.45 V	0.45 V

Figure 9-1. Logic Level Comparison. (Output levels are for minimum loading.)

Interface	Noise Margins for $V_{CC} = 5\text{ V}$	
	Logic Low $V_{IL} - V_{OL}$	Logic High $V_{OH} - V_{IH}$
74HC to 74HC	0.9 V	1.4 V
LSTTL to LSTTL	0.3 V	0.7 V
LSTTL to 74HCT	0.3 V	0.7 V
LSTTL to 80C51BH	0.3 V	0.7 V
74HC to 80C51BH	0.8 V	3.0 V
80C51BH to 74HC	0.8 V	1.0 V

Figure 9-2. Noise Margins for CMOS and LS TTL Circuits.

width of the noise pulse as compared with the circuit response speed, and the impedance to ground from the point of noise introduction in the circuit.

When these considerations are included, it is seen that using the slower 74C- and 4000-series circuits with a 12 or 15 V supply voltage does offer a truly improved level of noise immunity, but that high-speed CMOS at 5 V is not significantly better than TTL.

One should not mistake the wider supply voltage tolerance of high-speed CMOS for V_{CC} glitch immunity. Supply voltage tolerance is a dc rating, not a glitch rating.

For any clocked CMOS, and most especially for VLSI CMOS, V_{CC} decoupling is critical. CMOS draws current in extremely sharp spikes at the clock edges. The VHF and UHF components of these spikes are not drawn from the power supply, but from the decoupling capacitor. If the decoupling circuit is not sufficiently low in inductance, V_{CC} will glitch at each clock edge. A 0.1 μF decoupler cap should be used in a minimum-inductance configuration with the microcontroller. A minimum-inductance configuration minimizes the area of the loop formed by the chip (V_{CC} to V_{SS}), the traces to the decoupler cap, and the decoupler cap. PCB designers too often fail to understand that if the traces that connect the decoupler cap to the V_{CC} and V_{SS} pins aren't short and direct, the decoupler loses much of its effectiveness.

Overshoot and ringing in signal lines are potential sources of logic upsets. These can largely be controlled by circuit layout. Inserting small resistors (about 100 Ω) in series with signal lines that seem to need them will also help.

The sharp edges produced by high-speed CMOS can cause RFI problems. The severity of these problems is largely a function of the PCB layout. All RFI problems are not necessarily solved by a better PCB layout. It may well be, for example, that in some RFI sensitive designs, high speed CMOS is simply not the answer. But circuit layout

is a critical factor in the noise performance of any electronic system, and more so in high-speed CMOS systems than others.

Circuit layout techniques for minimizing noise susceptibility and generation are discussed in references 3 and 4.

Unused Pins

CMOS input pins should not be left to float, but should always be pulled to one logic level or the other. If they float, they tend to float into the transition region between 0 and 1, where pull-up and pull-down devices in the input buffer are both conductive. This causes a significant increase in I_{CC} . A similar effect exists in NMOS circuits, but with less noticeable results.

In 80C51BH and 80C31BH designs, unused pins of Ports 1, 2, and 3 can be ignored, because they have internal pull-ups that will hold them at a valid logic-1 level. Port 0 pins are different, however; they do not have internal pull-ups (except during bus operations).

When the 80C51BH is in reset, the Port 0 pins are in a float state unless they are externally pulled up or down. If the device is to be held in reset for just a short time, the transient float state can probably be ignored. When the device comes out of reset, the pins stay afloat unless they are externally pulled either up or down. Alternatively, the software can internally write 0s to whatever Port 0 pins may be unused.

The same considerations are applicable to the 80C31BH when it is in reset. But when the 80C31BH comes out of reset, it commences bus operations, during which the logic levels at all pins are always well defined as high or low.

When the 80C31BH is in the Power Down and Idle modes, however, it is not fetching instructions, and the Port 0 pins will float if not externally pulled high or low. The choice of whether to pull them high or low is the designer's. Normally it is sufficient to pull them up to V_{CC} with 10 k resistors. But if power is going to be removed from circuits that are connected to the bus, it will be advisable to pull the bus pins down (normally with 10 k resistors). Considerations involved in selecting pull-up and pull-down resistor values are as follows.

Pull-up Resistors

If a pull-up resistor is to be used on a Port 0 pin, its minimum value is determined by I_{OL} requirements. If the pin is trying to emit a 0, then it will have to sink the current from the pull-up resistor plus whatever other current may be sourced by other loads connected to the pin, as shown in Figure 9-3a, while maintaining a valid output low (V_{OL}).

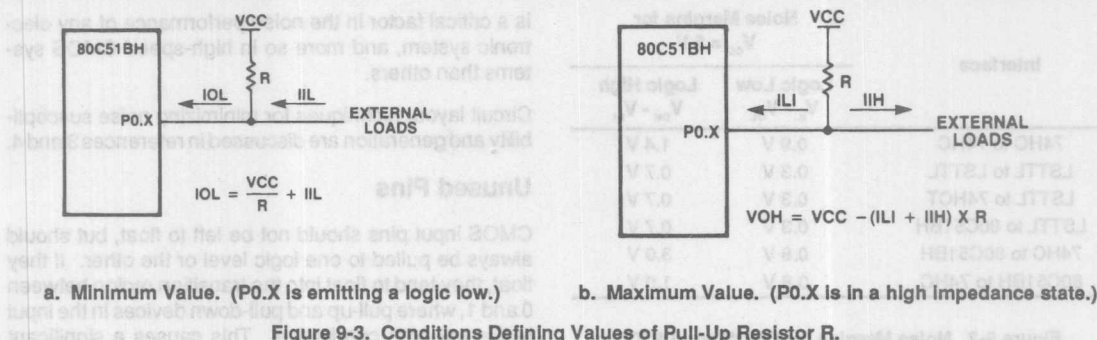


Figure 9-3. Conditions Defining Values of Pull-Up Resistor R .

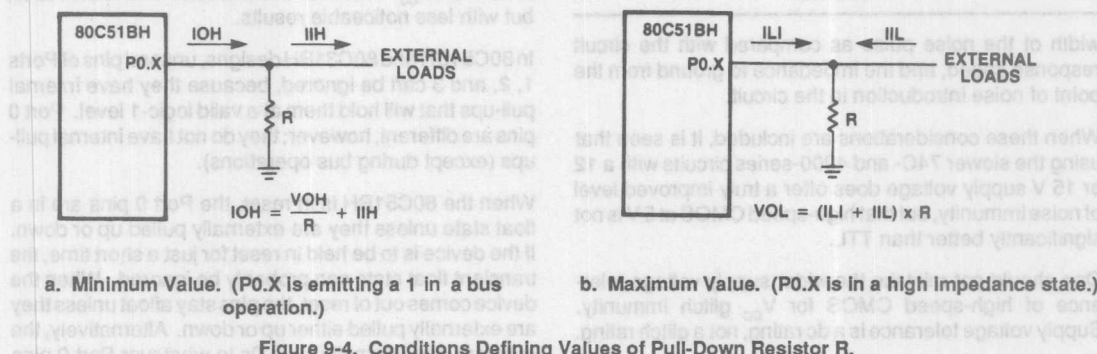


Figure 9-4. Conditions Defining Values of Pull-Down Resistor R .

To guarantee that the pin voltage will not exceed 0.45 V, the resistor should be selected so that I_{OL} doesn't exceed the value specified on the data sheet. In most CMOS applications, the minimum value would be about 2 k.

The maximum value would depend on how fast the pin must pull up after bus operations have ceased, and how high the V_{OH} level must be. The smaller the resistor the faster it pulls up. Its effect on the V_{OH} level is that $V_{OH} = V_{CC} - (I_{LI} + I_{IH}) \times R$. I_{LI} is the input leakage current to the Port 0 pin, and I_{IH} is the input high current to the external loads, as shown in Figure 9-3b. Normally V_{OH} can be expected to reach 0.9 V_{CC} if the pull-up resistance does not exceed about 50 k.

Pull-down Resistors

If a pull-down resistor is to be used on a Port 0 pin, its minimum value is determined by V_{OH} requirements during bus operations, and its maximum value is, in most cases, determined by leakage current.

During bus operations, the port uses internal pull-ups to emit 1s. The DC Characteristics in the data sheet list guaranteed V_{OH} levels for given I_{OH} currents. (The "-" sign in the I_{OH} value means the pin is sourcing that current to the external load, as shown in Figure 9-4). To ensure the

V_{OH} level listed in the data sheet, the resistor has to satisfy

$$\frac{V_{OH}}{R} + I_{IH} \leq |I_{OH}|$$

where I_{IH} is the input high current to the external loads.

When the pin goes into a high-impedance state, the pull-down resistor will have to sink leakage current from the pin, plus whatever other current may be sourced by other loads connected to the pin, as shown in Figure 9-4b. The Port 0 leakage current is I_{LI} on the data sheet. The resistor should be selected so that the voltage developed across it by these currents will be seen as a logic low by whatever circuits are connected to it (including the 80C51BH). In CMOS/CMOS applications, 50 k is normally a reasonable maximum value.

Drive Capability of the Internal Pull-ups

There's an important difference between NMOS and CMOS port drivers. The pins of Ports 1, 2 and 3 of the CMOS parts each have three pull-ups: strong, normal, and weak, as shown in Figure 9-5. The strong pull-up (P1) is only used during 0-to-1 transitions, to hasten the transition. The weak pull-up (P2) is on whenever the bit latch contains a 1. The "normal" pull-up (P3) is controlled by the pin voltage itself.

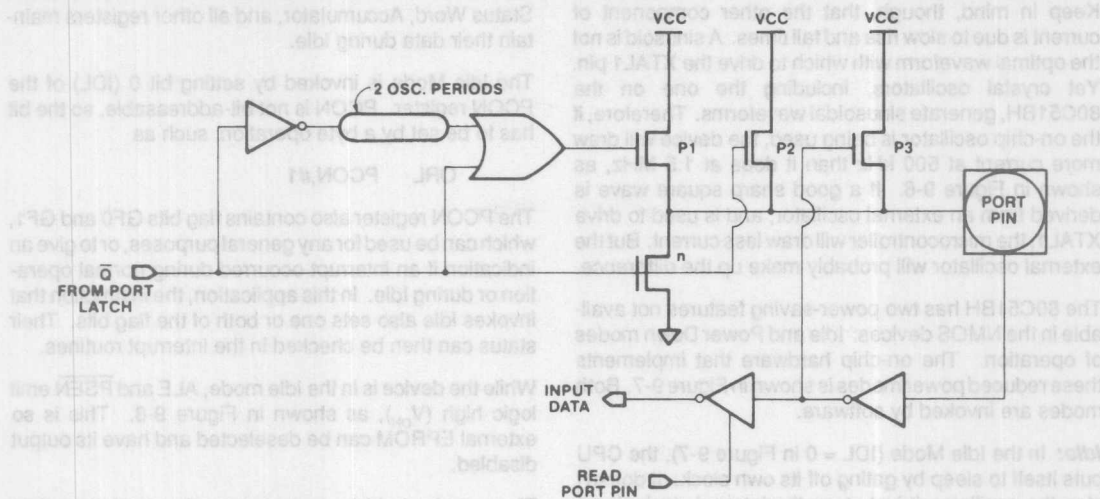


Figure 9-5. 80C51BH Output Drivers for Ports 1, 2 and 3.

The reason that P3 is controlled by the pin voltage is that if the pin is being used as an input, and the external source pulls it to a low, then turning off P3 makes for a lower I_{IL} . The data sheet shows an " I_{IL} " specification. This is the current that P3 will source during the time the pin voltage is making its 1-to-0 transition. This is what I_{IL} would be if an input low at the pin didn't turn P3 off.

Note, however, that this P3 turn-off mechanism puts a restriction on the drive capacity of the pin if it's being used as an output. If you're trying to output a logic high, and the external load pulls the pin voltage below the pin's $V_{IH,min}$ spec, P3 might turn off, leaving only the weak P2 to provide drive to the load. To prevent this happening, you need to ensure that the load doesn't draw more than the I_{OH} spec for a valid V_{OH} . The idea is to make sure the pin voltage never falls below its own $V_{IH,min}$ specification.

Power Consumption

The main reason for going to CMOS, of course, is to conserve power. There are other reasons, but this is the main one. Conserving power doesn't mean just reducing the electric bill; nor does it necessarily relate to battery operation, although battery operation without CMOS is pretty unhandy. The main reason for conserving power is to be able to put more functionality into a smaller space. Reduced power consumption allows the use of smaller and lighter power supplies. With less heat generated, denser packaging of circuit components is possible, and expensive fans and blowers can usually be eliminated. A cooler running chip is also more reliable, since most

random and wearout failures relate to die temperature. And finally, the lower power dissipation allows more functions to be integrated onto the chip.

CMOS consumes less power than NMOS because when CMOS is in a stable state, there is no path of conduction from V_{CC} to V_{SS} except through various leakage paths. CMOS does draw current when it is changing states. How much current is drawn depends on how often and how quickly CMOS changes states.

During logical transitions, CMOS circuits draw current in sharp spikes that are made up of two components. One is the current that flows during the transition time when pull-up and pull-down FETs are both active. The average (dc) value of this component is larger when the transition times of the input signals are longer. For this reason, if the current draw is a critical factor in the design, slow rise and fall times should be avoided, even when the system speed doesn't seem to justify a need for nanosecond switching speeds.

The other component is the current that charges stray and load capacitance at the nodes of a CMOS logic gate. The average value of this current spike is its area (integral over time) multiplied by its repetition rate. Its area is the amount of charge it takes to raise the node capacitance, C , to V_{CC} . That amount of charge is just $C \times V_{CC}$. So the average value of the current spike is $C \times V_{CC} \times f$, where f is the clock frequency. This component of current increases linearly with clock frequency.

Keep in mind, though, that the other component of current is due to slow rise and fall times. A sinusoid is not the optimal waveform with which to drive the XTAL1 pin. Yet crystal oscillators, including the one on the 80C51BH, generate sinusoidal waveforms. Therefore, if the on-chip oscillator is being used, the device will draw more current at 500 kHz than it does at 1.5 MHz, as shown in Figure 9-6. If a good sharp square wave is derived from an external oscillator, and is used to drive XTAL1, the microcontroller will draw less current. But the external oscillator will probably make up the difference.

The 80C51BH has two power-saving features not available in the NMOS devices: Idle and Power Down modes of operation. The on-chip hardware that implements these reduced power modes is shown in Figure 9-7. Both modes are invoked by software.

Idle: In the Idle Mode (IDL = 0 in Figure 9-7), the CPU puts itself to sleep by gating off its own clock. It doesn't stop the oscillator; it just stops the internal clock signal from getting to the CPU. Since the CPU draws 80 to 90 percent of the chip's power, shutting it off represents a fairly significant power savings. The on-chip peripherals (timers, serial port, interrupts, etc.) and RAM continue to function as normal. The CPU status is preserved in its entirety: the Stack Pointer, Program Counter, Program

Status Word, Accumulator, and all other registers maintain their data during Idle.

The Idle Mode is invoked by setting bit 0 (IDL) of the PCON register. PCON is not bit-addressable, so the bit has to be set by a byte operation, such as

```
ORL PCON,#1
```

The PCON register also contains flag bits GF0 and GF1, which can be used for any general purposes, or to give an indication if an interrupt occurred during normal operation or during Idle. In this application, the instruction that invokes Idle also sets one or both of the flag bits. Their status can then be checked in the interrupt routines.

While the device is in the Idle mode, ALE and $\overline{\text{PSEN}}$ emit logic high (V_{OH}), as shown in Figure 9-8. This is so external EPROM can be deselected and have its output disabled.

The port pins hold the logical states they had at the time the Idle was activated. If the device was executing out of external program memory, Port 0 is left in a high impedance state and Port 2 continues to emit the high byte of the program counter (using the strong pull-ups to emit 1s). If the device was executing out of internal program memory, Ports 0 and 2 continue to emit whatever is in the P0 and P2 registers.

There are two ways to terminate Idle. Activation of any enabled interrupt will cause the hardware to clear bit 0 of the PCON register, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that invoked Idle.

The other way is with a hardware reset. Since the clock oscillator is still running, RST only needs to be held active for two machine cycles (24 oscillator periods) to complete the reset. Note that this exit from Idle writes 1s to all the ports, initializes all SFRs to their reset values, and restarts program execution from location 0.

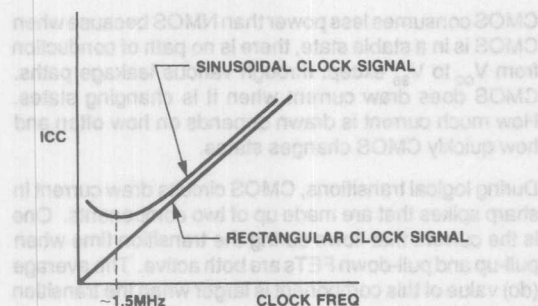


Figure 9-6. 80C51BH ICC vs Clock Frequency

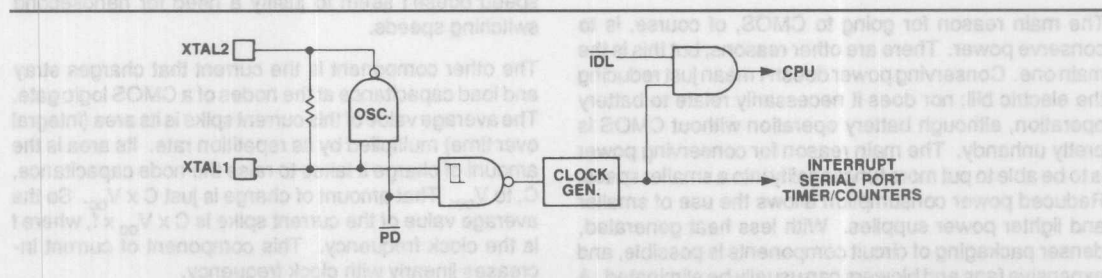


Figure 9-7. Oscillator and Clock Circuitry Showing Idle and Power Down Hardware.

Power Down: In the Power Down Mode ($\overline{PD} = 0$ in Figure 9-7), the CPU puts the whole chip to sleep by turning off the oscillator. In case it was running from an external oscillator, it also gates off the path to the internal phase generators, so no internal clock is generated even if the external oscillator is still running. The on-chip RAM, however, saves its data, as long as V_{CC} is maintained. In this mode, the only I_{CC} that flows is leakage, which is normally in the micro-amp range.

The Power Down Mode is invoked by setting bit 1 in the PCON register, using a byte instruction such as

```
ORL    PCON,#2
```

While the device is in Power Down, ALE and \overline{PSEN} emit lows (V_{OL}), as shown in Figure 9-8. ALE and \overline{PSEN} are designed to emit lows so that power can be removed from the rest of the circuit, if desired, while the 80C51BH is in its Power Down mode.

The port pins continue to emit whatever data was written to them. Note that Port 2 emits its P2 register data even if execution was from external program memory. Port 0 also emits its P0 register data, but if execution was from external program memory, the P0 register data is FF. The oscillator is stopped, and the part remains in this state as long as V_{CC} is held, and until it receives an external reset signal.

The only exit from Power Down is a hardware reset. Since the oscillator was stopped, RST must be held active long enough for the oscillator to re-start and stabilize. Then the reset function initializes all the Special Function Registers (ports, timers, etc.) to their reset values, and re-starts the program from location 0. Therefore, timer reloads, interrupt enables, baud rates, port status, etc. need to be re-established. Reset does not affect the content of the on-chip data RAM. If V_{CC} was held during Power Down, the RAM data is still good.

Using the Power Down Mode

The software-invoked Power Down feature offers a means of reducing the power consumption to a mere trickle in systems which are to remain dormant for some period of time, while retaining important data. The user should give some thought to what state the port pins should be left in during the time the clock is stopped, and write those values to the port latches before invoking Power Down.

If V_{CC} is going to be held to the entire circuit, values should be written to the port latches that would deselect peripherals before invoking Power Down. For example, if external memory is being used, the P2 SFR should be loaded with a value which will not generate an active chip select to any memory device.

In some applications, V_{CC} to part of the system may be shut off during Power Down, so that even quiescent and standby currents are eliminated. Signal lines that connect to those chips must be brought to a logic low, whether the chip in question is CMOS, NMOS, or TTL, before V_{CC} is shut off to them. CMOS pins have parasitic pn junctions to V_{CC} , which will be forward biased if V_{CC} is reduced to zero while the pin is held at a logic high. NMOS pins often have FETs that look like diodes to V_{CC} . TTL circuits may actually be damaged by an input high if $V_{CC} = 0$. That's why the 80C51BH outputs low at ALE and \overline{PSEN} during Power Down.

Figure 9-9 shows a circuit that can be used to turn V_{CC} off to part of the system during Power Down. The circuit will ensure that the secondary circuit is not de-energized until after the 80C31BH is in Power Down, and that the 80C31BH does not receive a reset (terminating the Power Down mode) before the secondary circuit is re-energized. Therefore, the program memory itself can be part of the secondary circuit.

Pin	Internal Execution		External Execution	
	Idle	Power Down	Idle	Power Down
ALE	1	0	1	0
\overline{PSEN}	1	0	1	0
P0	SFR data	SFR data	high-Z	high-Z
P1	SFR data	SFR data	SFR data	SFR data
P2	SFR data	SFR data	PCH	SFR data
P3	SFR data	SFR data	SFR data	SFR data

Figure 9-8. Status of Pins in Idle and Power Down Modes. ("SFR data" means the port pins emit their internal register data. "PCH" is the high byte of the program counter.)

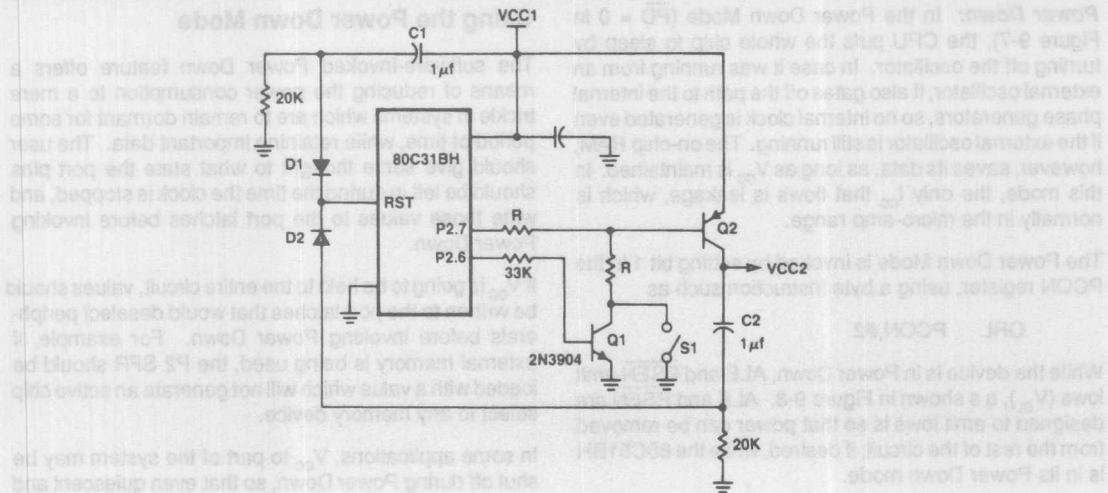


Figure 9-9. The 80C31BH De-energizes Part of the Circuit (V_{cc2}) During Power Down.
(Selections of R and Q2 depend on V_{cc2} current draw.)

In Figure 9-9, when V_{cc} is switched on to the 80C31BH, capacitor C1 provides a power-on reset. The reset function writes 1s to all the port pins. The 1 at P2.6 turns Q1 on, enabling V_{cc} to the secondary circuit through transistor Q2. As the 80C31BH comes out of reset, Port 2 commences emitting the high byte of the Program Counter, which results in the P2.7 and P2.6 pins outputting 0s. The 0 at P2.7 ensures continuation of V_{cc} to the secondary circuit.

The system software must now write a 1 to P2.7 and a 0 to P2.6 in the Port 2 SFR, P2. These values will not appear at the Port 2 pins as long as the device is fetching instructions from external program memory. However, whenever the 80C31BH goes into Power Down, these values will appear at the port pins, and will shut off both transistors, disabling V_{cc} to the secondary circuit.

Closing the switch S1 re-energizes the secondary circuit, and at the same time sends a reset through C2 to the 80C31BH to wake it up. The diode D1 is to prevent C1 from hogging current from C2 during this secondary reset. D2 prevents C2 from discharging through the RST pin when V_{cc} to the secondary circuit goes to zero.

Using Power MOSFETs to Control V_{cc}

Power MOSFETs are gaining in popularity and availability. The easiest way to control V_{cc} is with a Logic Level pFET, as shown in Figure 9-10a. This circuit allows the full V_{cc} to be used to turn the device on. Unfortunately, power pFETs are not economically competitive with bipolar transistors of comparable ratings.

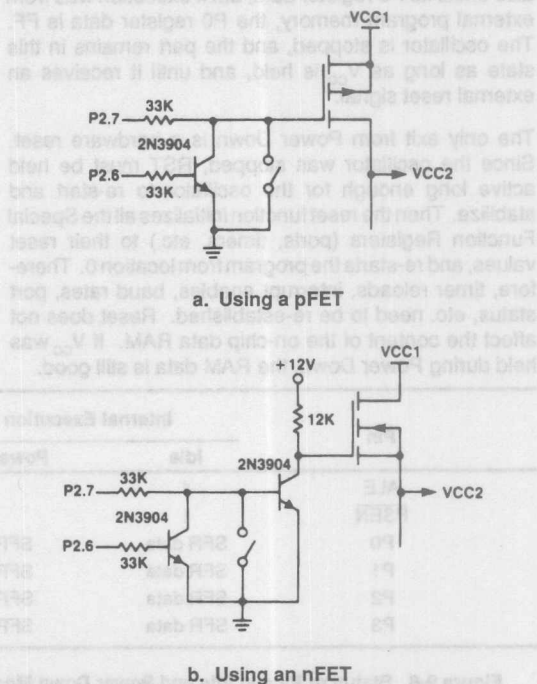


Figure 9-10. Using Power MOSFETs to Control V_{cc2}

Power nFETs are both economical and available, and can be used in this application if a dc supply of higher voltage is available to drive the gate. Figure 9-10b shows how to implement a V_{CC} switch using a power nFET and a (nominally) +12 V supply. The problem here is that if the device is on, its source voltage is +5 V. To maintain the on state, the gate has to be another 5 or 10V above that. The "12V" supply is not particularly critical. A minimally filtered, unregulated rectifier will suffice.

Battery Backup Systems

Here we consider circuits that normally draw power from the ac line, but switch to battery operation in the event of a power failure. We assume that in battery operation high-current loads will be allowed to die along with the ac power. The system may continue then with reduced functionality, monitoring a control transducer, perhaps, or driving an LCD. Or it may go into a bare-bones survival mode, in which critical data is saved but nothing else happens till ac power is restored.

In any case, it is necessary to have some early warning of an impending power failure so that the system can arrange an orderly transfer to battery power. Early warning systems can operate by monitoring either the ac line voltage or the unregulated rectifier output, or even by monitoring the regulated dc voltage.

Monitoring the ac line voltage gives the earliest warning. That way you can know within one or two half-cycles of line frequency that ac power is down. In most cases you then have at least another half-cycle of line frequency before the regulated V_{CC} starts to fall. In a half-cycle of line frequency, an 80C51BH can execute about 5,000 instructions—plenty of time to arrange an orderly transfer of power.

The circuit in Figure 9-11 uses a Zener diode to test the line voltage each half cycle, and a junction transistor to pass the information on the the 80C51BH. Obviously a voltage comparator with a suitable reference source can perform the same function, if one prefers. If the line voltage reaches an acceptably high level, it breaks over Z1, drives Q1 to saturation, and interrupts the 80C51BH. The interrupt would be transition-activated, in this application. The interrupt service routine reloads one of the 80C51BH's timers to a value that will make it roll over in something between one and two half-cycles of line frequency. As long as the line voltage is healthy, the timer never rolls over, because it is reloaded every half cycle. If there is a single half cycle in which the line voltage doesn't reach a high enough level to generate the interrupt, the timer rolls over and generates a timer interrupt.

The timer interrupt then commences the transition to battery backup. Critical data needs to be copied into protected RAM. Signals to circuits that are going to lose power must be written to logic low. Protected circuits (those powered by V_{CC2}) that communicate with unprotected circuits must be deselected. The microcontroller itself may be put into Idle, so that it can continue some level of interrupt-driven functionality, or it may be put into Power Down.

Note that if the CPU is going to invoke Power Down, the Special Function Registers may also need to be copied into protected RAM, since the reset that terminates the Power Down mode will also initialize all the SFRs to their reset values.

The circuit in Figure 9-11 does not show a wake-up mechanism. A number of choices are available, however. A pushbutton could be used to generate an interrupt, if the CPU is in Idle, or to activate reset, if the CPU is in Power Down.

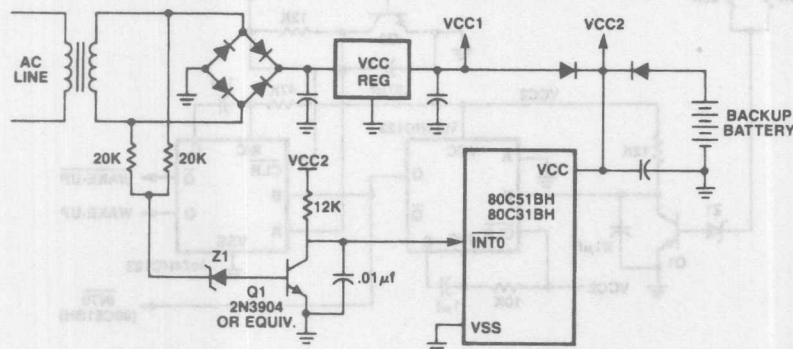


Figure 9-11. Power Failure Detector with Battery Backup.
(When ac power fails, V_{CC1} goes down and V_{CC2} is held.)

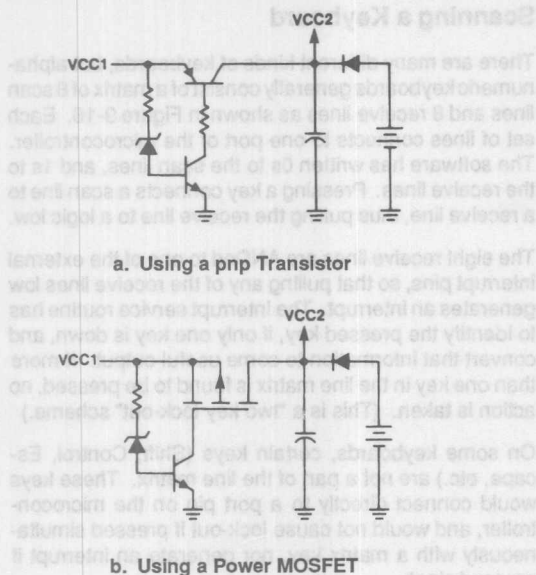


Figure 9-13. Power Switchover Circuits.

Power Switchover Circuits

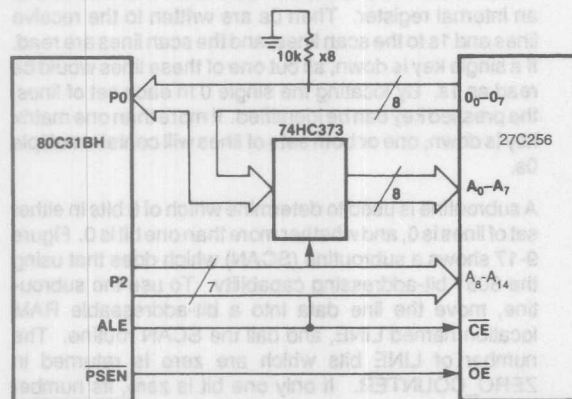
Battery backup systems need to have a way for the protected circuits to draw power from the line-operated power supply when that source is available, and to switch over to battery power when required. The switchover

circuit is simple if the entire system is to be battery powered in the event of a line power outage. In that case a pair of diodes suffice, as shown in Figure 9-12, provided $V_{CC(min)}$ specs are still met after the diode drop has been subtracted from its respective power source.

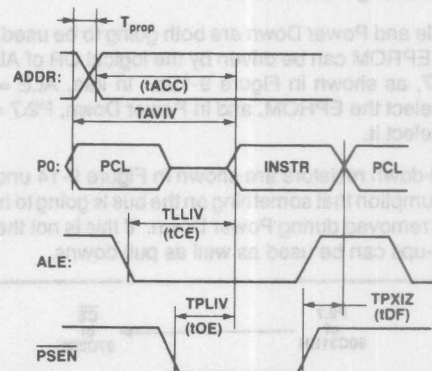
The situation becomes more complicated when part of the circuit is going to be allowed to die when the ac power goes out. In that case it is difficult to maintain equal V_{CC} s to protected and unprotected circuits (and possibly dangerous not to). The problem can be alleviated by using a Schottky diode instead of a 1N4001, for its lower forward voltage drop. The 1N5820, for example, has a forward drop of about 0.35 V at 1A. Other solutions are to use a transistor or power MOSFET switch, as shown in Figure 9-13. With minor modifications this switch can be controlled by port pins.

80C31BH + CMOS EPROM

The 27C256 is AMD's 32K-byte CMOS EPROM. It requires an external address latch, and can be used with the 80C31BH as shown in Figure 9-14a. In most 8031 + 27256 (NMOS) applications, the Chip Enable (CE) pin is hardwired to ground (since it's normally the only program memory on the bus). This can be done with the CMOS versions as well, but there is some advantage in connecting CE to ALE, as shown in Figure 9-14. The advantage is that if the 80C31BH is put into Idle mode, since ALE goes to a 1 in that mode, the 27C256 will be deselected and go into a low-current standby mode.



a. Circuit



b. Timing Waveforms

Figure 9-14. 80C31BH + 27C256

The timing waveforms for this configuration are shown in Figure 9-14b. The signals and timing parameters in parentheses are those of the 27C256 and the others are of the 80C31BH, except T_{prop} is a parameter of the address latch. The requirements for timing compatibility are

TAVIV - $T_{prop} > t_{ACC}$
TLLIV > $t_{\overline{CE}}$
TPLIV > t_{OE}
TPXIZ > t_{DF}

If the application is going to use the Power Down mode then there is another consideration: In Idle, $ALE = \overline{PSEN} = 1$, and in Power Down, $ALE = \overline{PSEN} = 0$. In a realistic application there are likely to be more chips in the circuit than are shown in Figure 9-14, and it is likely that the nonessential ones will have their V_{CC} removed while the CPU is in Power Down. In that case the EPROM and the address latch should be among the chips that have V_{CC} removed, and logic lows are exactly what are required at ALE and \overline{PSEN} .

But if V_{CC} is going to be maintained to the EPROM during Power Down, then it will be necessary to deselect the EPROM when the CPU is in Power Down. If Idle is never invoked, \overline{CE} of the EPROM can be connected to P2.7 of the 80C31BH, as shown in Figure 9-15a. In normal operation, P2.7 will be emitting the MSB of the Program Counter, which is 0 if the program contains less than 32K of code. Then when the CPU goes into Power Down, the Port 2 pins emit P2 SFR data, which puts a 1 at P2.7, thus deselecting the EPROM.

If Idle and Power Down are both going to be used, \overline{CE} of the EPROM can be driven by the logical OR of ALE and P2.7, as shown in Figure 9-15b. In Idle, $ALE = 1$ will deselect the EPROM, and in Power Down, P2.7 = 1 will deselect it.

Pull-down resistors are shown in Figure 9-14 under the assumption that something on the bus is going to have its V_{CC} removed during Power Down. If this is not the case, pull-ups can be used as well as pull-downs.

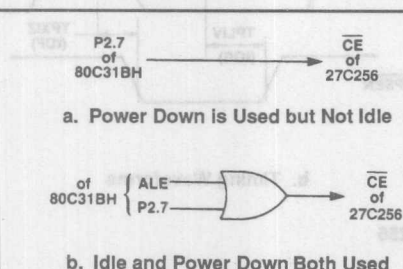


Figure 9-15. Modifications to 80C31/27C256 Interface

Scanning a Keyboard

There are many different kinds of keyboards, but alphanumeric keyboards generally consist of a matrix of 8 scan lines and 8 receive lines as shown in Figure 9-16. Each set of lines connects to one port of the microcontroller. The software has written 0s to the scan lines, and 1s to the receive lines. Pressing a key connects a scan line to a receive line, thus pulling the receive line to a logic low.

The eight receive lines are ANDed to one of the external interrupt pins, so that pulling any of the receive lines low generates an interrupt. The interrupt service routine has to identify the pressed key, if only one key is down, and convert that information to some useful output. If more than one key in the line matrix is found to be pressed, no action is taken. (This is a "two key lock-out" scheme.)

On some keyboards, certain keys (Shift, Control, Escape, etc.) are not a part of the line matrix. These keys would connect directly to a port pin on the microcontroller, and would not cause lock-out if pressed simultaneously with a matrix key, nor generate an interrupt if pressed singly.

Normally the microcontroller would be in Idle mode when a key has not been pressed, and another task is not in progress. Pressing a matrix key generates an interrupt, which terminates the Idle. The interrupt service routine would first call a 30 ms (or so) delay to debounce the key, and then set about the task of identifying which key is down.

First, the current state of the receive lines is latched into an internal register. Then 0s are written to the receive lines and 1s to the scan lines, and the scan lines are read. If a single key is down, all but one of these lines would be read as 1s. By locating the single 0 in each set of lines, the pressed key can be identified. If more than one matrix key is down, one or both sets of lines will contain multiple 0s.

A subroutine is used to determine which of 8 bits in either set of lines is 0, and whether more than one bit is 0. Figure 9-17 shows a subroutine (SCAN) which does that using the 8051 bit-addressing capability. To use the subroutine, move the line data into a bit-addressable RAM location named LINE, and call the SCAN routine. The number of LINE bits which are zero is returned in ZERO_COUNTER. If only one bit is zero, its number (1 through 8) is returned in ZERO_BIT.

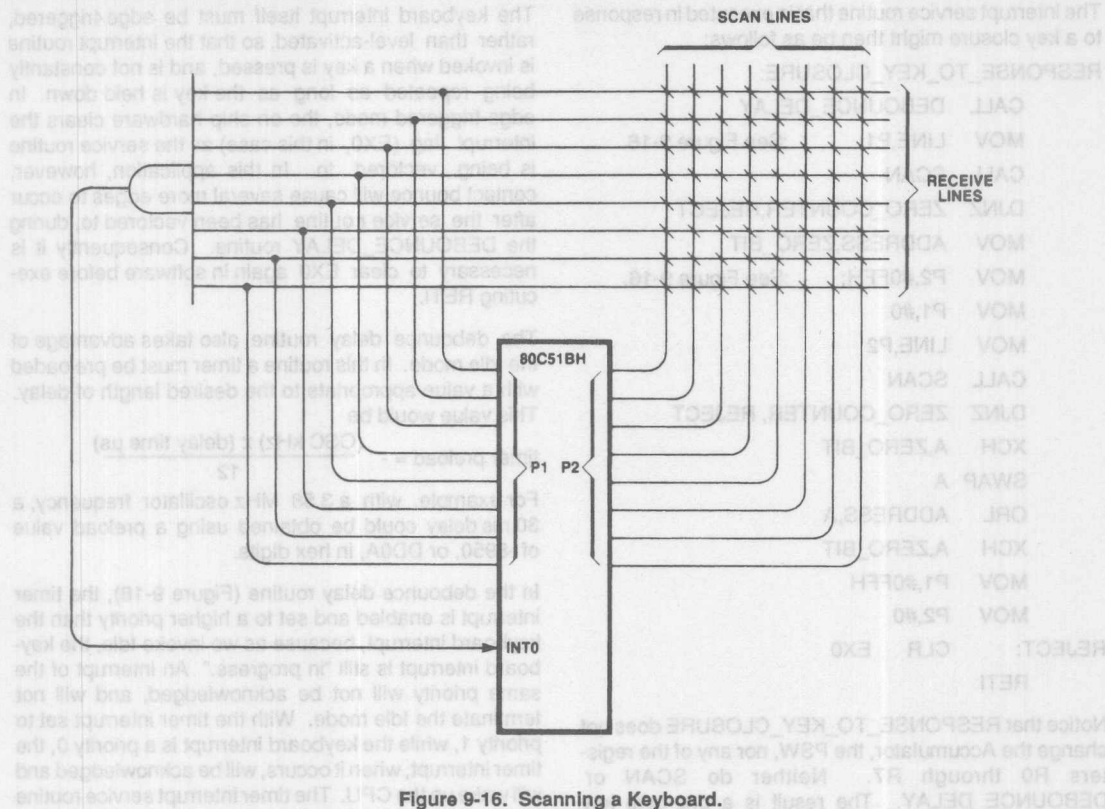


Figure 9-16. Scanning a Keyboard.

```

SCAN:  MOV     ZERO_COUNTER,#0      ; ZERO_COUNTER counts the number of 0s in LINE.
        JB     LINE.0,ONE           ; Test LINE bit 0.
        INC     ZERO_COUNTER        ; If LINE.0 = 0, increment ZERO_COUNTER
        MOV     ZERO_BIT,#1         ; and record that line number 1 is active.
ONE:    JB     LINE.1,TWO           ; Procedure continues for other LINE bits.
        INC     ZERO_COUNTER
        MOV     ZERO_BIT,#2         ; Line number 2 is active.
TWO:    JB     LINE.2,THREE
        INC     ZERO_COUNTER
        MOV     ZERO_BIT,#3         ; Line number 3 is active.
THREE:  JB     LINE.3,FOUR
        INC     ZERO_COUNTER
        MOV     ZERO_BIT,#4         ; Line number 4 is active.
FOUR:   JB     LINE.4,FIVE
        INC     ZERO_COUNTER
        MOV     ZERO_BIT,#5         ; Line number 5 is active.
FIVE:   JB     LINE.5,SIX
        INC     ZERO_COUNTER
        MOV     ZERO_BIT,#6         ; Line number 6 is active.
SIX:    JB     LINE.6,SEVEN
        INC     ZERO_COUNTER
        MOV     ZERO_BIT,#7         ; Line number 7 is active.
SEVEN:  JB     LINE.7,EIGHT
        INC     ZERO_COUNTER
        MOV     ZERO_BIT,#8         ; Line number 8 is active.
EIGHT:  RET

```

Figure 9-17. Subroutine SCAN Determines which of Eight Bits in LINE is 0.

The interrupt service routine that is executed in response to a key closure might then be as follows:

```
RESPONSE_TO_KEY_CLOSURE:
    CALL DEBOUNCE_DELAY
    MOV LINE,P1; ;See Figure 9-16.
    CALL SCAN
    DJNZ ZERO_COUNTER,REJECT
    MOV ADDRESS,ZERO_BIT
    MOV P2,#0FFH; ;See Figure 9-16.
    MOV P1,#0
    MOV LINE,P2
    CALL SCAN
    DJNZ ZERO_COUNTER, REJECT
    XCH A,ZERO_BIT
    SWAP A
    ORL ADDRESS,A
    XCH A,ZERO_BIT
    MOV P1,#0FFH
    MOV P2,#0
REJECT: CLR EX0
    RETI
```

Notice that RESPONSE_TO_KEY_CLOSURE does not change the Accumulator, the PSW, nor any of the registers R0 through R7. Neither do SCAN or DEBOUNCE_DELAY. The result is a one-byte key address (ADDRESS) which identifies the pressed key. The key's scan line number is in the upper nibble of ADDRESS, and its receive line number is in the lower nibble. ADDRESS can be used in a look-up table to generate a key code to transmit to a host computer, and/or to a display device.

```
DEBOUNCE_DELAY:
    MOV TL1,#TL1_PRELOAD ; Preload low byte.
    MOV TH1,#TH1_PRELOAD ; Preload high byte.
    SETB ET1 ; Enable Timer 1 interrupt.
    SETB PT1 ; Set Timer 1 interrupt to high priority.
    SETB TR1 ; Start timer running.
    ORL PCON,#1 ; Invoke Idle mode.
;
; The next instruction will not be executed until the delay times out.
;
    CLR TR1 ; Stop the timer.
    CLR PT1 ; Back to priority 0 (if desired).
    CLR ET1 ; Disable Timer 1 interrupt (if desired).
    RET ; Continue keyboard scan.
```

The keyboard interrupt itself must be edge-triggered, rather than level-activated, so that the interrupt routine is invoked when a key is pressed, and is not constantly being repeated as long as the key is held down. In edge-triggered mode, the on-chip hardware clears the interrupt flag (EX0, in this case) as the service routine is being vectored to. In this application, however, contact bounce will cause several more edges to occur after the service routine has been vectored to, during the DEBOUNCE_DELAY routine. Consequently it is necessary to clear EX0 again in software before executing RETI.

The debounce delay routine also takes advantage of the Idle mode. In this routine a timer must be preloaded with a value appropriate to the desired length of delay. This value would be

$$\text{timer preload} = - \frac{(\text{OSC kHz}) \times (\text{delay time } \mu\text{s})}{12}$$

For example, with a 3.58 MHz oscillator frequency, a 30 ms delay could be obtained using a preload value of -8950, or DD0A, in hex digits.

In the debounce delay routine (Figure 9-18), the timer interrupt is enabled and set to a higher priority than the keyboard interrupt, because as we invoke Idle, the keyboard interrupt is still "in progress." An interrupt of the same priority will not be acknowledged, and will not terminate the Idle mode. With the timer interrupt set to priority 1, while the keyboard interrupt is a priority 0, the timer interrupt, when it occurs, will be acknowledged and will wake up the CPU. The timer interrupt service routine does not itself have to do anything. The service routine might be nothing more than a single RETI instruction. RETI from the timer interrupt service routine then returns execution to the debounce delay routine, which shuts down the timer and returns execution to the keyboard service routine.

Figure 9-18. Subroutine DEBOUNCE_DELAY Puts the 80C51BH into Idle During the Delay Time.

Driving an LCD

An LCD (Liquid Crystal Display) consists of a backplane and any number of segments or dots which will be used to form the displayed image. Applying a voltage (nominally 4 to 5 V) between any segment and the backplane causes the segment to darken. The only catch is that the polarity of the applied voltage has to be periodically reversed, or else a chemical reaction takes place in the LCD which causes deterioration and eventual failure of the liquid crystal.

To prevent this from happening, the backplane and all the segments are driven with an ac signal, which is derived from a rectangular voltage waveform. If a segment is to be "off", it is driven by the same waveform as the backplane. Thus it is always at backplane potential. If the segment is to be "on", it is driven with a waveform that is the inverse of the backplane waveform. Thus it has about 5 V of periodically changing polarity between it and the backplane.

With a little software overhead, the 80C51BH can perform this task without the need for additional LCD drivers. The only drawback is that each LCD segment uses up one port pin, and the backplane uses one more. If more than, say, two 7-segment digits are being driven, there aren't many port pins left for other tasks. Nevertheless, assuming a given application leaves enough port pins available to support this task, the considerations for driving the LCD are as follows.

Suppose, for example, it is a 2-digit display with a decimal point. One port (TENS_DIGIT) connects to the seven segments of the tens digit plus the backplane. Another port (ONES_DIGIT) connects to a decimal point plus the seven segments of the ones digit.

One of the 80C51BH timers is used to mark off half-periods of the drive voltage waveform. The LCD drive waveform should have a rep rate between 30 and 100 Hz, but it's not very critical. A half-period of 12 ms will set the rep rate to about 42 Hz. The preload/reload value to get 12 ms to rollover is the 2's complement negative of the oscillator frequency in kHz: If the oscillator frequency is 3.58 MHz, the reload value is -3850, or F204 in hex digits.

Now, the 80C51BH would normally be in Idle, to conserve power, during the time that the LCD and other tasks are not requiring servicing. When the timer rolls over, it generates an interrupt that brings the 80C51BH out of Idle. The service routine reloads the timer (for the next rollover), and inverts the logic levels of all the pins that are connected to the LCD. It might look like this:

LCD_DRIVE_INTERRUPT:

```
MOV  TL1,#LOW(-XTAL_FREQ)
MOV  TH1,#HIGH(-XTAL_FREQ)
XRL  TENS_DIGIT,#0FFH
XRL  ONES_DIGIT,#0FFH
RETI
```

To update the display, one would use a look-up table to generate the characters. In the table, "on" segments are represented as 1s, and "off" segments as 0s. The backplane bit is represented as a 0. The quantity to be displayed is stored in RAM as a BCD value. The look-up table operates on the low nibble of the BCD value, and produces the bit pattern that is to be written to either the ones digit or the tens digit. Before the new patterns can be written to the LCD, the LCD drive interrupt has to be disabled. That is to prevent a polarity reversal from taking place between the times the two digits are written. An update subroutine is shown in Figure 9-19.

```
UPDATE_LCD:
CLR    ET1                ; Disable LCD drive interrupt.
MOV    DPTR,#TABLE_ADDRESS ; Look-up table begins at TABLE_ADDRESS.
MOV    A,BCD_VALUE        ; Digits to be displayed.
SWAP   A                  ; Move tens digit to low nibble.
ANL    A,#0FH             ; Mask off high nibble.
MOVC   A,@A+DPTR          ; Tens digit pattern to accumulator.
MOV    TENS_DIGIT,A       ; Update LCD tens digit.
MOV    A,BCD_VALUE        ; Digits to be displayed.
ANL    A,#0FH             ; Mask off tens digit.
MOVC   A,@A+DPTR          ; Ones digit pattern to accumulator.
MOV    C,DECIMAL_POINT    ; Add decimal point to segment
MOV    ACC.7,C            ; pattern. Update LCD decimal point
MOV    ONES_DIGIT,A       ; and ones digit.
SETB   ET1               ; Re-enable LCD drive interrupt.
RET
```

Figure 9-19. UPDATE_LCD Routine Writes Two Digits to an LCD.

Using an LCD Driver

As was noted, driving an LCD directly with an 80C51BH uses a lot of port pins. LCD drivers are available in CMOS to interface an 80C51BH to a 4-digit display using only seven of the 80C51BH's I/O pins. Basically, the 80C51BH tells the LCD driver what digit is to be displayed (four bits) and what position it is to be displayed in (two bits), and toggles a Chip Select pin to tell the driver to latch this information. The LCD driver generates the display characters (hex digits), and takes care of the polarity reversals using its own RC oscillator to generate the timing. Figure 9-20 shows an 80C51BH working with an ICM7211M to drive a 4-digit LCD; the software that updates the display is shown in Figure 9-21.

One could equally well send information to the LCD driver over the bus by setting up the Accumulator with the digit select and data input bits, and executing a MOVX @ R0,A instruction. The LCD-driver chip select would be driven by the CPU WR signal. This is a little easier in software than the direct bit manipulation shown in Figure 9-20. However, it uses more I/O pins, unless there is already some external memory involved. In that case, no extra pins are used up by adding the LCD driver to the bus.

Resonant Transducers

Analog transducers are often used to convert the value of a physical property, such as temperature, pressure,

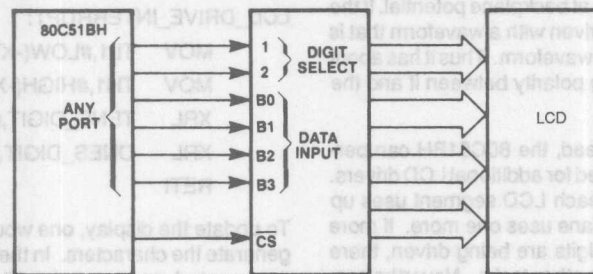


Figure 9-20. Using an LCD Driver

```

UPDATE_LCD:
MOV     A,DISPLAY_HI           ; High byte of 4-digit display.
SETB    DIGIT_SELECT_2         ; Select leftmost digit of LCD.
SETB    DIGIT_SELECT_1         ; (digit address = 11B.)
CALL    SHIFT_AND_LOAD         ; High nibble of high byte to selected digit.
CLR     DIGIT_SELECT_1         ; Select second digit of LCD (address = 10B).
CALL    SHIFT_AND_LOAD         ; Low nibble of high byte to selected digit.
MOV     A,DISPLAY_LO           ; Low byte of 4-digit display.
CLR     DIGIT_SELECT_2         ; Select third digit of LCD.
SETB    DIGIT_SELECT_1         ; (Digit address = 01B.)
CALL    SHIFT_AND_LOAD         ; High nibble of low byte to selected digit.
CLR     DIGIT_SELECT_1         ; Select fourth digit (address = 00B).
CALL    SHIFT_AND_LOAD         ; Low nibble of low byte to selected digit.
RET

SHIFT_AND_LOAD:
RLC     A                       ; MSB to carry bit (CY).
MOV     DATA_INPUT_B3,C       ; CY to Data Input pin B3.
RLC     A                       ; Next bit to CY.
MOV     DATA_INPUT_B2,C       ; CY to Data Input pin B2.
RLC     A                       ; Next bit to CY.
MOV     DATA_INPUT_B1,C       ; CY to Data Input pin B1.
RLC     A                       ; Last bit to CY.
MOV     DATA_INPUT_B0,C       ; CY to Data Input pin B0.
CLR     CHIP_SELECT             ; Toggle Chip Select.
SETB    CHIP_SELECT            ; 0-to-1 transition latches info.
RET
  
```

Figure 9-21. UPDATE_LCD Routine Writes Four Digits to an LCD Driver.

etc., to an analog voltage. These kinds of transducers then require an analog-to-digital converter to put the measurement into a form that is compatible with a digital control system. Another kind of transducer is now becoming available that encodes the value of the physical property into a signal that can be directly read by a digital control system. These devices are called resonant transducers.

Resonant transducers are oscillators whose frequency depends in a known way on the physical property being measured. These devices output a train of rectangular pulses whose repetition rate encodes the value of the quantity being measured. The pulses can in most cases be fed directly into the 80C51BH, which then measures either the frequency or period of the incoming signal, basing the measurement on the accuracy of its own clock oscillator. The 80C51BH can even do this in its sleep, that is, in Idle.

When the frequency or period measurement is completed, the 80C51BH wakes itself up for a very short time to perform a sanity check on the measurement and convert it in software to any scaling of the measured quantity that may be desired. The software conversion can include corrections for nonlinearities in the transducer's transfer function.

Resolution is also controlled by software, and can even be dynamically varied to meet changing needs as a situation becomes more critical. For example, in a process controller, resolution can be increased ("fine tune" the control) as the process approaches its target.

The nominal reference frequency of the output signal from these devices is in the range of 20 Hz to 500 kHz, depending on the design. Transducers are available that have a full-scale frequency shift of 2 to 1. The transducer operates from a supply voltage range of 3 V to 20 V, which means it can operate from the same supply voltage as the 80C51BH. At 5 V, the transducer draws less than 5 mA (reference 5). It can normally be connected directly to one of the 80C51BH port pins, as shown in Figure 9-22.

Frequency Measurements

Measuring a frequency means counting pulses for a known sample time. Two timer/counters can be used, one to mark off the sample time and one to count pulses. If the frequency being counted doesn't exceed 50 kHz or so, one may equally well connect the transducer signal to one of the external interrupt pins, and count pulses in software. That frees up one timer, with very little cost in CPU time.

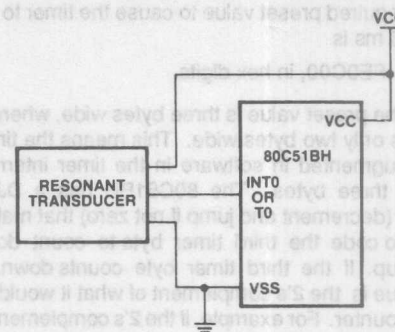


Figure 9-22. Resonant Transducer Does Not Require an A/D converter.

The count that is directly obtained is $T \times F$, where T is the sample time and F is the frequency. The full scale range is $T \times (F_{\text{max}} - F_{\text{min}})$. For n -bit resolution

$$1 \text{ LSB} = \frac{T \times (F_{\text{max}} - F_{\text{min}})}{2^n}$$

Therefore the sample time required for n -bit resolution is

$$T = \frac{2^n}{F_{\text{max}} - F_{\text{min}}}$$

For example, 8-bit resolution in the measurement of a frequency that varies between 7 kHz and 9 kHz would require, according to this formula, a sample time of 128 ms. The maximum acceptable frequency count would be $128 \text{ ms} \times 9 \text{ kHz} = 1152$ counts. The minimum would be 896 counts. Subtracting 896 from each frequency count (or presetting the frequency counter to $-896 = 0\text{FC80H}$) would allow the frequency to be reported on a scale of 0 to FF in hex digits.

To implement the measurement, one timer is used to establish the sample time. The timer is preset to a value that causes it to roll over at the end of the sample time, generating an interrupt and waking the CPU from its Idle mode. The required preset value is the 2's complement negative of the sample time measured in machine cycles. The conversion from sample time to machine cycles is to multiply it by 1/12 the clock frequency. For example, if the clock frequency is 12 MHz, then a sample time of 128 ms is

$$(128 \text{ ms}) \times (12000 \text{ kHz})/12 = 128000 \text{ machine cycles.}$$

Then the required preset value to cause the timer to roll over in 128 ms is

- 128000 = FE0C00, in hex digits.

Note that the preset value is three bytes wide, whereas the timer is only two bytes wide. This means the timer must be augmented in software in the timer interrupt routine to three bytes. The 80C51BH has a DJNZ instruction (decrement and jump if not zero) that makes it easier to code the third timer byte to count down instead of up. If the third timer byte counts down, its reload value is the 2's complement of what it would be for an up-counter. For example, if the 2's complement of the sample time is FE0C00, then the reload value for the third timer byte would be 02, instead of FE. The timer interrupt routine might then be:

TIMER_INTERRUPT_ROUTINE:

```
DJNZ THIRD_TIMER_BYTE,OUT
MOV TL0,#0
MOV TH0,#0CH
MOV THIRD_TIMER_BYTE,#2
MOV FREQUENCY,COUNTER_LO
```

;Preset COUNTER to -896:

```
MOV COUNTER_LO,#80H
MOV COUNTER_HI,#0FCH
```

OUT: RETI

At this point the value of the frequency of the transducer signal, measured to 8-bit resolution, is contained in FREQUENCY. Note that the timer can be reloaded on the fly. Note too that for 8-bit resolution only the low byte of the frequency counter needs to be read, since the high byte is necessarily 0. However, one may want to test the high byte to ensure that it is 0, as a sanity check on the data. Both bytes, of course must be reloaded.

Period Measurements

Measuring the period of the transducer signal means measuring the total elapsed time over a known number, N, of transducer pulses. The quantity that is directly measured is NT, where T is the period of the transducer signal in machine cycles. The relationship between T in machine cycles and the transducer frequency F in arbitrary frequency units is

$$T = \frac{F_{xtal}}{F} \times (1/12)$$

where Fxtal is the 80C51BH clock frequency, in the same units as F.

The full scale range then is Nx(Tmax - Tmin). For n-bit resolution

$$1 \text{ LSB} = \frac{Nx(T_{max}-T_{min})}{2^n}$$

Therefore the number of periods over which the elapsed time should be measured is

$$N = \frac{2^n}{T_{max}-T_{min}}$$

However, N must also be an integer. It is logical to evaluate the above formula (don't forget Tmax and Tmin have to be in machine cycles) and select for N the next higher integer. This selection gives a period measurement that has somewhat more than n-bit resolution, but it can be scaled back if desired.

For example, suppose an 8-bit resolution is wanted in the measurement of the period of a signal with a frequency that varies from 7.1 to 9 kHz. If the clock frequency is 12 MHz, Tmax is (12000 kHz/7.1 kHz) x (1/12) = 141 machine cycles. Tmin is 111 machine cycles. The required value for N, then, is 256/(141-111) = 8.53 periods, according to the formula. Using N = 9 periods will give a maximum NT value of 141 x 9 = 1269 machine cycles. The minimum NT will be 111 x 9 = 999 machine cycles. A lookup table can be used to scale these values back to a range of 0 to 255, giving precisely the 8-bit resolution desired.

To implement the measurement, one timer is used to measure the elapsed time, NT. The transducer is connected to one of the external interrupt pins, and this interrupt is configured to the transition-activated mode. In the transition-activated mode every 1-to-0 transition in the transducer output will generate an interrupt. The interrupt routine counts transducer pulses, and when it gets to the predetermined N, it reads and clears the timer. For the specific example cited above, the interrupt routine might be:

INTERRUPT_RESPONSE:

```
DJNZ N,OUT
MOV N,#9
CLR EA
CLR TR1
MOV NT_LO,TL1
MOV NT_HI,TH1
MOV TL1,#9
MOV TH1,#0
SETB TR1
SETB EA
CALL LOOKUP_TABLE
```

OUT: RETI

In this routine a pulse counter N is decremented from its preset value, 9, to 0. When the counter gets to 0 it is reloaded to 9. Then all interrupts are blocked for a short time while the timer is read and cleared. The timer is stopped during the read and clear operations, so "clearing" it actually means presetting it to 9, to make up for the 9 machine cycles that are missed while the timer is stopped.

The subroutine LOOKUP_TABLE is used to scale the measurement back to the desired 8-bit resolution. It can also include built-in corrections for errors or nonlinearities in the transducer's transfer function.

The subroutine uses the MOV A, @ A + DPTR instruction to access the table, which contains 270 entries commencing at the 16-bit address referred to as TABLE. The subroutine must compute the address of the table entry that corresponds to the measured value of NT. This address is

$DPTR = TABLE + NT - NTMIN$,

where $NTMIN = 999$, in this specific example.

LOOKUP_TABLE:

```
PUSH ACC
PUSH PSW
MOV A, #LOW(TABLE-NTMIN)
ADD A, NT_LO
MOV DPL, A
MOV A, #HIGH(TABLE-NTMIN)
ADDC A, NT_HI
MOV DPH, A
CLR A
MOVC A, @A + DPTR
MOV PERIOD, A
POP PSW
POP ACC
RET
```

At this point the value of the period of the transducer signal, measured to 8-bit resolution, is contained in PERIOD.

Pulse Width Measurements

The 80C51BH timers have an operating mode, called the "gate" mode, that is particularly suited to pulse-width measurements, and is useful in these applications if the transducer signal has a fixed duty cycle.

In this mode, the timer is turned on by the on-chip circuitry in response to an input high at the external interrupt pin, and off by an input low, and it can do this while the

80C51BH is in Idle. (The "gate" mode of timer operation is described in Chapter Two, Timer/Counters.) The external interrupt itself can be enabled, so the same 1-to-0 transition from the transducer that turns off the timer also generates an interrupt. The interrupt routine then reads and resets the timer.

The advantage of this method is that the transducer signal has direct access to the timer gate, with the result that variations in interrupt response time have no effect on the measurement.

Resonant transducers that are designed to fully exploit the gate mode have an internal divide-by-N circuit that fixes the duty cycle at 50% and lowers the output frequency to the range of 250 to 500 Hz (to control RFI). The transfer function between transducer period and measured value is approximately linear, with known and repeatable error functions.

NMOS/CMOS Interchangeability

The CMOS version of the 8051 is architecturally identical with the NMOS version, but there are nevertheless some important differences between them of which the designer should be aware. In addition, some applications require interchangeability between NMOS and CMOS parts. The differences are as follows:

External Clock Drive: To drive the NMOS 8051 with an external clock signal, one normally grounds the XTAL1 pin and drives the XTAL2 pin. To drive the CMOS 8051 with an external clock signal, one must drive the XTAL1 pin and leave the XTAL2 pin unconnected. The reason for the difference is that in the NMOS 8051, the XTAL2 pin drives the internal clocking circuits, whereas in the CMOS version, the XTAL1 pin drives the internal clocking circuits.

There are several ways to design an external clock drive to work with both types. For low clock frequencies (below 6 MHz), the NMOS 8051 can be driven the same way as the CMOS version, namely, through XTAL1 with XTAL2 unconnected. Another way is to drive both XTAL1 and XTAL2, that is drive XTAL1 and use an external inverter to derive from XTAL1 a signal with which to drive XTAL2.

In either case, a 74HC or 74HCT circuit makes an excellent driver for XTAL1 and/or XTAL2, because neither the NMOS nor the CMOS XTAL pins have TTL-like input logic levels.

Unused Pins: Unused pins of Ports 1, 2, and 3 can be ignored in both NMOS and CMOS designs. The internal pull-ups will put them into a defined state. Unused Port 0 pins in 8051 applications can be ignored, even if they're floating. But in 80C51BH applications, these pins

should not be left afloat. They can be externally pulled up or down, or they can be internally pulled down by writing 0s to them.

8031/80C31BH designs may or may not need pull-ups on Port 0. Pull-ups aren't needed for program fetches, because in bus operations the pins are actively pulled high or low by either the 8031 or the external program memory. But they are needed for the CMOS part if the Idle or Power Down mode is invoked, because in these modes, Port 0 floats.

Logic Levels: If V_{CC} is between 4.5 V and 5.5 V, an input signal that meets the NMOS 8051 input logic levels will also meet the CMOS 80C51BH input logic levels (except for XTAL1/XTAL2 and RST). For the same V_{CC} condition, the CMOS device will reach or surpass the output logic levels of the NMOS device. The NMOS device will not necessarily reach the output logic levels of the CMOS device. This is an important consideration if NMOS/CMOS interchangeability must be maintained in an otherwise CMOS system.

NMOS 8051 outputs that have internal pull-ups (ports 1, 2 and 3) "typically" reach 4 V or more if I_{OH} is 0, but not fast enough to meet timing specs. Adding an external pull-up resistor will ensure the logic level, but still not the timing, as shown in Figure 9-23. If timing is an issue, the best way to interface NMOS to CMOS is through a 74HCT circuit.

Idle and Power Down: The Idle and Power Down modes exist only on the CMOS devices, but if one wishes to preserve the capability of interchanging NMOS and CMOS 8051s, the software has to be designed so that the NMOS parts will respond in an acceptable manner when a CMOS reduced power mode is invoked.

For example, an instruction that invokes Power Down can be followed by a "JMP \$":

```
CLR EA
ORL PCON,#2
JMP $
```

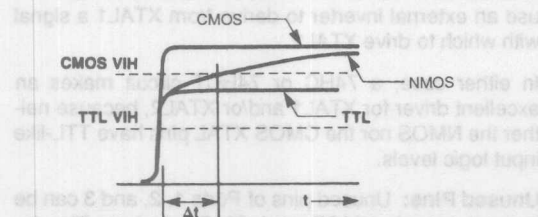


Figure 9-23. Transition Shows Unspecified Delay (Δt) in NMOS to 74HC Logic.

The CMOS and NMOS parts will respond to this sequence of code differently. The CMOS part, going into a normal CMOS Power Down Mode, will stop fetching instructions until it gets a hardware reset. The NMOS part will go through the motions of executing the ORL instruction, and then fetch the JMP instruction. It will continue fetching and executing JMP \$ until hardware reset.

Maintaining NMOS/CMOS 8051 interchangeability in response to Idle requires more planning. The NMOS part will not respond to the instruction that puts the CMOS part into Idle, so that instruction needs to be followed by a software Idle. This would be an idling loop which would be terminated by the same conditions that would terminate the CMOS hardware Idle. Then when the CMOS device goes into Idle, the NMOS version executes the idling loop, until either a hardware reset or an enabled interrupt is received. Now if Idle is terminated by an interrupt, execution for the CMOS device will proceed after RETI from the instruction following the one that invoked Idle. The instruction following the one that invoked Idle is the idling loop that was inserted for the NMOS device. At this point, both the NMOS and CMOS devices must be able to fall through the loop to continue execution.

One way to achieve the desired effect is to define a "fake" Idle flag, and set it just before going into Idle. The instruction that invokes Idle is followed by a software idle:

```
SETB IDLE
ORL PCON,#1
JB IDLE,$
```

Now the interrupt that terminates the CMOS Idle must also break the software idle. It does so by clearing the "Idle" bit:

```
...
CLR IDLE
RETI
```

Note too that the PCON register in the NMOS 8051 contains only one bit, SMOD, whereas the PCON register in CMOS contains SMOD plus four other bits. Two of those other bits are general purpose flags. Maintaining NMOS/CMOS interchangeability requires that these flags not be used.

References

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80C52T2/80C32T2

CMOS Single-Chip Microcontroller



PRELIMINARY

DISTINCTIVE CHARACTERISTICS

- CMOS extensions to the 80C51
- 256 Bytes of RAM
- 8K Bytes of ROM (80C52T2 only)
- 16-MHz Operation
- All Original 80C51 Features Are Retained
 - 32 I/O Lines
 - Two 16-Bit Timer/Counters
 - Five Source, Two Level Interrupt
 - 64K Bytes Program Memory Space
 - Full-Duplex Serial Port
 - Power-Down & Idle Modes
 - On-Chip Oscillator/Clock Circuit
 - 64K Bytes Data Memory Space

GENERAL DESCRIPTION

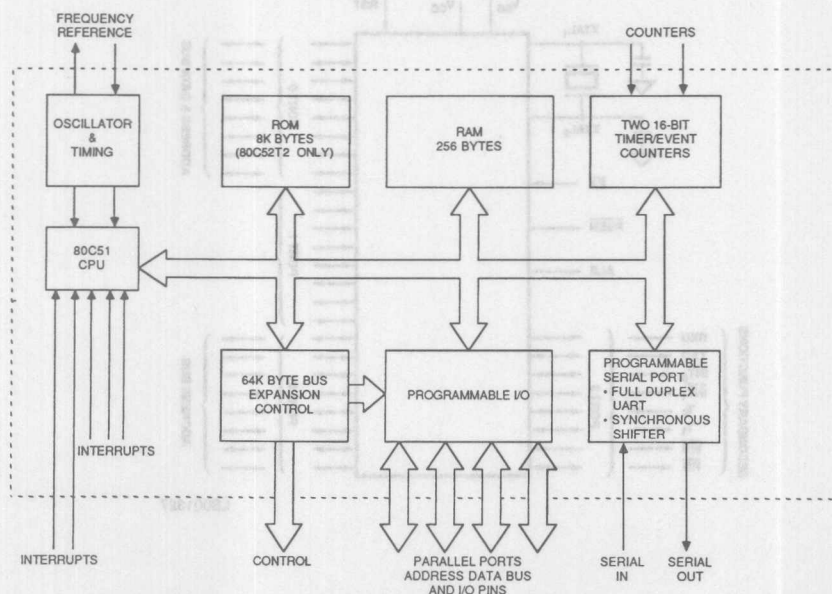
The 80C52T2 and 80C32T2 are two-timer versions of the 80C52 and 80C32, respectively. The 80C52T2 contains 8K bytes of ROM, 256 bytes of RAM, and is a functional superset of the 80C51. It is pin-compatible and function-compatible with the 80C52 except that it does not contain the third timer (Timer 2). The 80C32T2 is the ROMless version of the 80C52T2.

The 80C52T2 and 80C32T2 are offered in 40-pin DIP and 44-pin PLCC packages. As with the 80C521/80C321, the

PLCC package contains three additional supply connections (pins 1, 23, and 34) which greatly improve noise margins over packages with a single V_{CC} and V_{SS} connection.

Consult the 80C521/80C321 data sheet (PID# 09136B) for full spec information on the 80C52T2/80C32T2, including DC and Switching Characteristics.

SIMPLIFIED BLOCK DIAGRAM



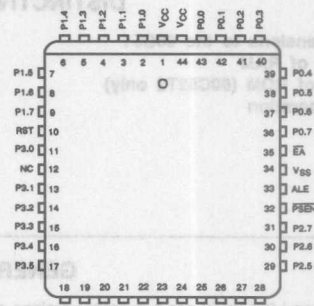
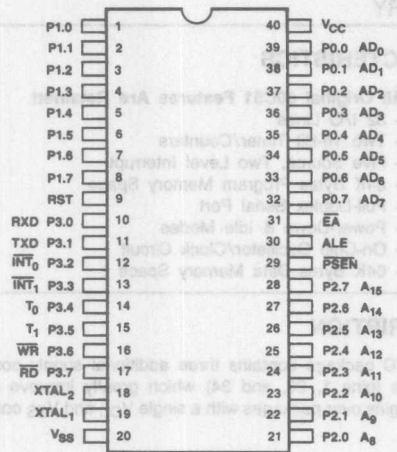
BD007214

CONNECTION DIAGRAMS

Top View

DIPs

PLCC

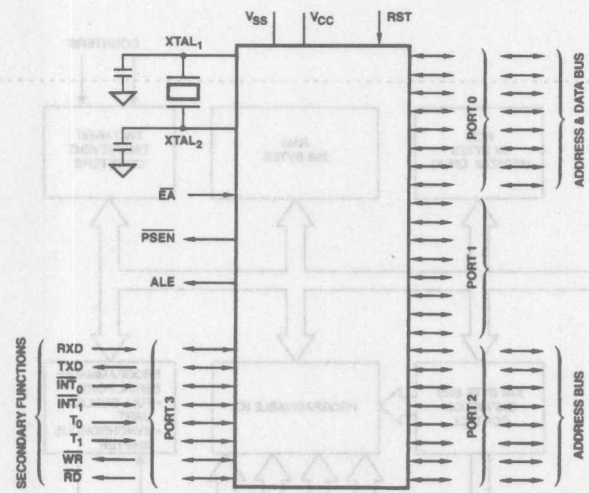


CD005551

CD009441

Note: Pin 1 is marked for orientation.

LOGIC SYMBOL



LS001327

ORDERING INFORMATION

Commodity Products

AMD commodity products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:

- Temperature Range
- Package Type
- Device Number
- Number of Timers
- Speed Option
- Optional Processing

P

80C52

T2

-1

f. OPTIONAL PROCESSING

Blank = Standard processing

e. SPEED OPTION

-1 = 3.5 to 16 MHz

d. NUMBER OF TIMERS

T2 = Two Timers (0 and 1)

c. DEVICE NUMBER/DESCRIPTION

80C52T2/80C32T2

CMOS Single-Chip Microcontroller

b. PACKAGE TYPE

P = 40-Pin Plastic DIP (PD 040)

N = 44-Pin Plastic Leaded Chip Carrier (PL 044)

a. TEMPERATURE RANGE

Blank = Commercial (0 to +70°C)

Valid Combinations

Valid Combinations

P, N

80C52T2-1

80C32T2-1

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released valid combinations, and to obtain additional data on AMD's standard military grade products.

80C521/80C321

CMOS Single-Chip Microcontroller



PRELIMINARY

DISTINCTIVE CHARACTERISTICS

- CMOS extensions to the 80C51
- 256 Bytes of RAM
- 8K Bytes of ROM (80C521 only)
- Programmable Watchdog Timer
- Dual Data Pointers
- Software Reset
- All Original 80C51 Features Are Retained
 - 32 I/O Lines
 - Two 16-Bit Timer/Counters
 - Five Source, Two Level Interrupt
 - 64K Bytes Program Memory Space
 - Full-Duplex Serial Port
 - Power-Down & Idle Modes
 - On-Chip Oscillator/Clock Circuit
 - 64K Bytes Data Memory Space

GENERAL DESCRIPTION

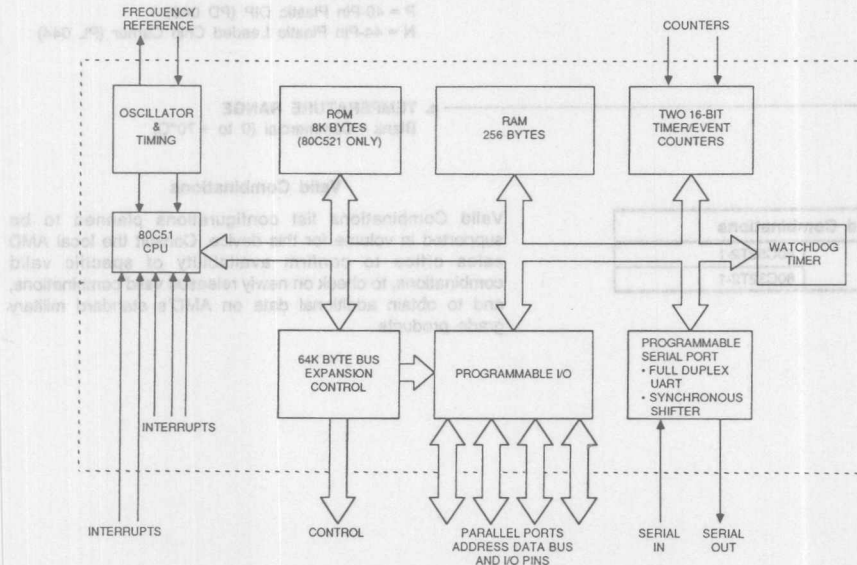
The 80C521 and 80C321 Microcontrollers are fully instruction-set-compatible and pin-compatible enhancements of the 80C51/80C31. The 80C521 contains 8K bytes of ROM, 256 bytes of RAM, a programmable Watchdog Timer, and Dual Data Pointers. The Watchdog Timer can be programmed to times ranging from 128 microseconds to four full seconds at 12 MHz.

The Dual Data Pointer structure speeds access to external memory by providing two identical 16-bit data pointers with

a fast switching mechanism, rather than a single data pointer as in the rest of the 8051 Family. The 80C321 is a ROM-less version of the 80C521.

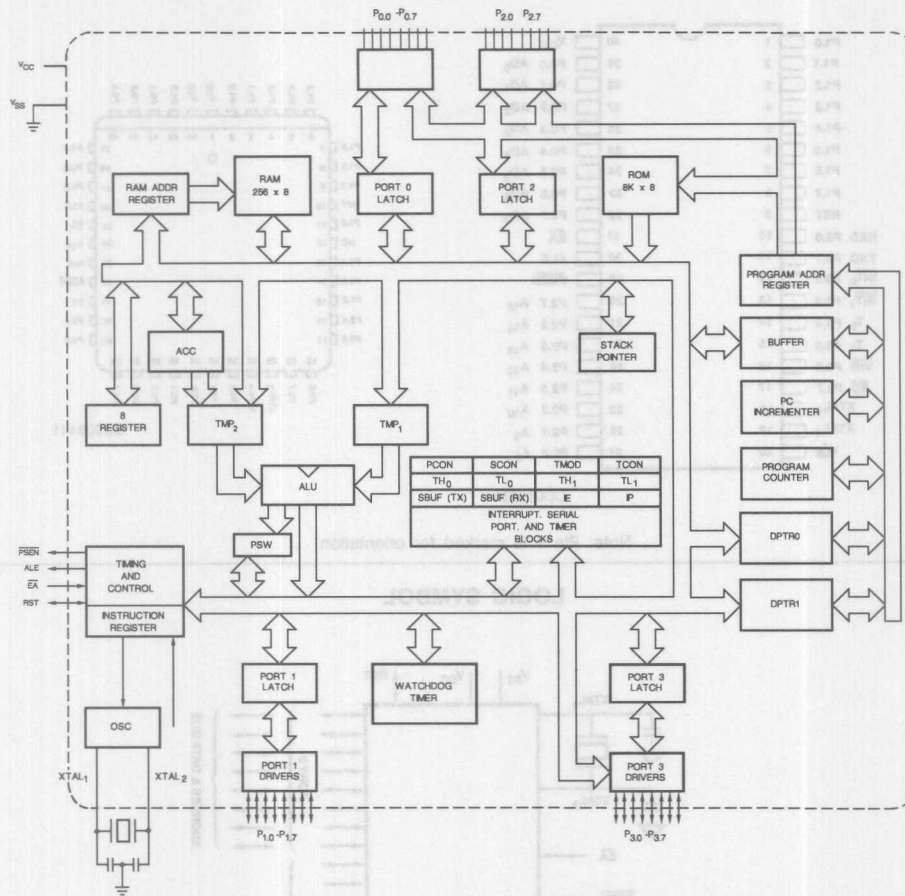
The 80C521/80C321 is socket-compatible with the 80C52/80C32 if the third timer (Timer 2) on the 80C52/80C32 is not used, and in the case of the PLCC Package, if the extra V_{CC} and V_{SS} connections are considered. The PLCC Package offers improved noise margins over packages with a single V_{CC} and V_{SS} connection.

SIMPLIFIED BLOCK DIAGRAM



BD007211

DETAILED BLOCK DIAGRAM

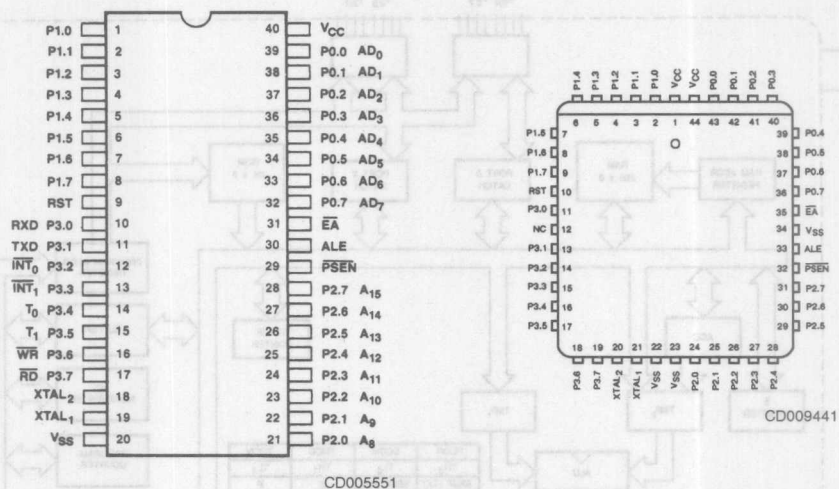


BD004096

CONNECTION DIAGRAMS Top View

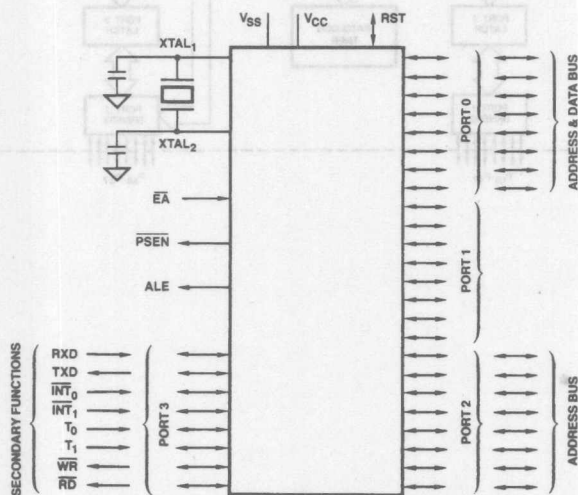
DIPs

PLCC



Note: Pin 1 is marked for orientation.

LOGIC SYMBOL



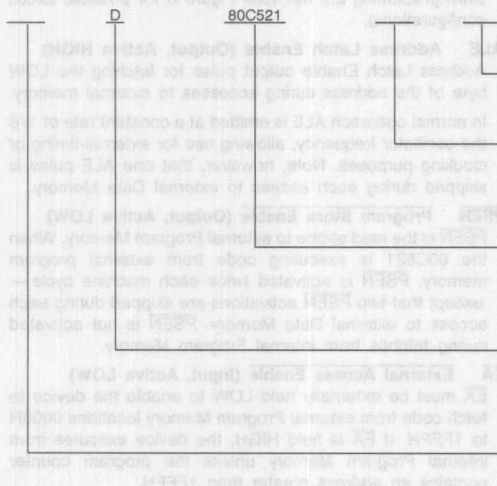
LS001324

ORDERING INFORMATION

Commodity Products

AMD commodity products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of:

- Temperature Range
- Package Type
- Device Number
- Speed Option
- Optional Processing



e. OPTIONAL PROCESSING
Blank = Standard processing

d. SPEED OPTION
Blank = 3.5 to 12 MHz
- 1 = 3.5 to 16 MHz

c. DEVICE NUMBER/DESCRIPTION
80C521/80C321
CMOS Single-Chip Microcontroller

b. PACKAGE TYPE
P = 40-Pin Plastic DIP (PD 040)
D = 40-Pin Ceramic DIP (CD 040)
N = 44-Pin Plastic Leaded Chip Carrier (PL 044)

a. TEMPERATURE RANGE
Blank = Commercial (0 to +70°C)

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local AMD sales office to confirm availability of specific valid combinations, to check on newly released valid combinations, and to obtain additional data on AMD's standard military grade products.

Valid Combinations	
P, D, N	80C521
	80C521-1
	80C321
	80C321-1

Port Pin	Alternate Function
P0.0	P0.0 (serial input port)
P0.1	P0.1 (serial output port)
P0.2	INT0 (external interrupt 0)
P0.3	INT1 (external interrupt 1)
P0.4	T0 (Timer 0 external input)
P0.5	T1 (Timer 1 external input)
P0.6	WR (external Data Memory write strobe)
P0.7	RD (external Data Memory read strobe)

PIN DESCRIPTION

Port 0 (Bidirectional, Open Drain)

Port 0 is an open-drain bidirectional I/O port. Port 0 pins that have "1"s written to them float, and in that state can be used as high-impedance inputs.

Port 0 is also the multiplexed LOW-order address and data bus during accesses to external Program and Data Memory. In this application it uses strong internal pullups when emitting "1"s. Port 0 also outputs the code bytes during program verification in the 80C521. External pullups are required during program verification.

Port 1 (Bidirectional)

Port 1 is an 8-bit bidirectional I/O port with internal pullups. The Port 1 output buffers can sink/source four LSTTL inputs. Port 1 pins that have "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 1 pins that are externally being pulled LOW will source current (I_{IL} on the data sheet) because of the internal pullups.

Port 1 also receives the LOW-order address bytes during program verification.

Port 2 (Bidirectional)

Port 2 is an 8-bit bidirectional I/O port with internal pullups. The Port 2 output buffers can sink/source four LSTTL inputs. Port 2 pins having "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 2 pins externally being pulled LOW will source current (I_{IL}) because of the internal pullups.

Port 2 emits the HIGH-order address byte during fetches from external Program Memory and during accesses to external Data Memory that use 16-bit addresses (MOVX @DPTR). In this application it uses strong internal pullups when emitting "1"s. During accesses to external data memory that use 8-bit addresses (MOVX @Ri), Port 2 emits the contents of the P2 Special Function Register. Port 2 also receives the HIGH-order address bits during ROM verification.

Port 3 (Bidirectional)

Port 3 is an 8-bit bidirectional I/O port with internal pullups. The Port 3 output buffers can sink/source four LSTTL inputs. Port 3 pins that have "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 3 pins externally being pulled LOW will source current (I_{IL}) because of the pullups.

Port 3 also serves the functions of various special features as listed below:

Port Pin	Alternate Function
P3.0	RxD (serial input port)
P3.1	TxD (serial output port)
P3.2	$\overline{INT_0}$ (External interrupt 0)
P3.3	$\overline{INT_1}$ (external interrupt 1)
P3.4	T ₀ (Timer 0 external input)
P3.5	T ₁ (Timer 1 external input)
P3.6	\overline{WR} (external Data Memory write strobe)
P3.7	\overline{RD} (external Data Memory read strobe)

RST Reset (Input/Output, Active HIGH)

A HIGH on this pin — for two machine cycles while the oscillator is running — resets the device. An internal diffused resistor to V_{SS} permits power-on reset, using only an external capacitor to V_{CC}.

Immediately prior to a Watchdog Reset or Software Reset, this pin is pulled HIGH for one state time. The internal pull-up can be overdriven by an external driver capable of sinking/sourcing 2.5 mA (see Figure 6 for possible circuit configurations).

ALE Address Latch Enable (Output, Active HIGH)

Address Latch Enable output pulse for latching the LOW byte of the address during accesses to external memory.

In normal operation ALE is emitted at a constant rate of 1/6 the oscillator frequency, allowing use for external-timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external Data Memory.

PSEN Program Store Enable (Output, Active LOW)

PSEN is the read strobe to external Program Memory. When the 80C521 is executing code from external program memory, PSEN is activated twice each machine cycle — except that two PSEN activations are skipped during each access to external Data Memory. PSEN is not activated during fetches from internal Program Memory.

EA External Access Enable (Input, Active LOW)

EA must be externally held LOW to enable the device to fetch code from external Program Memory locations 0000H to 1FFFFH. If EA is held HIGH, the device executes from internal Program Memory unless the program counter contains an address greater than 1FFFFH.

The 80C521 internally latches the value of the EA pin at the falling edge of the reset pulse on the RST pin during a Hardware or Power-on Reset. Once latched, the EA value cannot be changed except by a Hardware reset.

XTAL1 Crystal (Input)

Input to the inverting-oscillator amplifier, and input to the internal clock-generator circuits.

XTAL2 Crystal (Output)

Output from the inverting-oscillator amplifier.

VCC Power Supply

Supply voltage during normal, idle, and power-down operations.

VSS Circuit Ground

FUNCTIONAL DESCRIPTION

Program Memory

The 80C521 has 64K bytes of Program Memory space. The lower 8K bytes (addresses 0000H to 1FFF) may reside on-chip. Instructions residing at addresses beyond 1FFF will always be fetched externally. When the External Access (EA) pin is held LOW, all code-fetch operations take place externally to the 80C521.

Data Memory

The 80C521 can address 64K bytes of Data Memory external to the chip. The "MOVX" instructions are used to access the external Data Memory.

The internal data memory is comprised of three physically distinct memory spaces. They are the lower 128 bytes of RAM,

the upper 128 bytes of RAM, and the 128 byte Special Function Register (SFR) space. The lower 128 bytes of RAM can be accessed through direct addressing (i.e., MOV addr, data), or indirect addressing (i.e., MOV @ Ri). The upper 128 bytes of RAM (locations 80H through FFH) can be accessed only through indirect addressing modes. The Special Function Register space, while physically distinct from the upper 128 bytes of RAM, shares addresses with the upper 128 bytes of RAM. The SFR space may be accessed through direct addressing modes only.

The first 32 bytes of RAM contain four register banks, each of which contains eight general-purpose registers. The next 16 bytes (locations 20H through 2FH) contain 128 directly addressable bit locations. The stack may be located anywhere in the internal RAM space and may be up to 256 bytes in length.

SPECIAL FUNCTION REGISTER MAP

Addr (HEX)	Symbol	Name	Default After Power-On Reset
* 80	P0	Port 0	11111111
* 81	SP	Stack Pointer	00000111
82	DPL	Data Pointer Low	00000000
83	DPH	Data Pointer High	00000000
+ 84	DPL1	Data Pointer Low 1	00000000
+ 85	DPH1	Data Pointer High 1	00000000
+ 86	DPS	Data Pointer Selection	00000000
87	PCON	Power Control	0XX00000
* 88	TCN	Timer/Counter Control	00000000
89	TMOD	Timer/Counter Mode Control	00000000
8A	TL0	Timer/Counter 0 Low Byte	00000000
8B	TL1	Timer/Counter 1 Low Byte	00000000
8C	TH0	Timer/Counter 0 High Byte	00000000
8D	TH1	Timer/Counter 1 High Byte	00000000
* 90	P1	Port 1	11111111
* 98	SCON	Serial Control	00000000
99	SBUF	Serial Data Buffer	Indeterminate
* A0	P2	Port 2	11111111
* A8	IE	Interrupt Enable Control	0XX00000
+ A9	WDS	Watchdog Selection	00000000
+ AA	WDK	Watchdog Key	00000000
* B0	P3	Port 3	11111111
* B8	IP	Interrupt Priority Control	XXX00000
* D0	PSW	Program Status Word	00000000
* E0	ACC	Accumulator	00000000
* F0	B	B Register	00000000

* Bit Addressable

* New SFRs defined on the 80C521/80C321

Basic Timing Definitions

Instructions in the 8051 Family execute in either one, two, or four machine cycles. A machine cycle is comprised of six state times with each state comprised of two clock cycles; thus, a machine cycle lasts 12 clock cycles. With an external oscillator running at 12 MHz, a machine cycle lasts 1 μ s. At 16 MHz, a machine cycle lasts 750 ns.

Reset Operation

The 80C521/80C321 may be reset by four different methods: (1) Power-On Reset, (2) Hardware Reset, (3) Watchdog Reset, and (4) Software Reset.

1) **Power-on Reset** occurs when the RST pin is wired to V_{CC} using an external capacitor, and V_{CC} is activated.

2) **Hardware Reset** occurs when the oscillator is running and the RST pin is held HIGH for two or more machine cycles.

3) **Watchdog Reset** occurs when the count value of the Watchdog Timer is allowed to exceed the programmed value, resulting in an overflow signal that resets the chip in two machine cycles.

4) **Software Reset** occurs when the software writes a Keyed sequence to the Key register of the Watchdog Timer. This causes a Watchdog Reset to be immediately generated.

After Power-On Reset, the SFRs have the values indicated in the Special Function Register Map Section, and the contents of the Internal RAM are undefined. Hardware Reset is the same as Power-On Reset except that the contents of the Internal RAM are preserved. A Hardware Reset has priority over a Watchdog Reset or a Software Reset. The Watchdog Reset puts the 80C521 into the same state as the Hardware Reset except that the Reset Cause (RC) bit in the Watchdog Selection (WDS) register is set to a one. The Software Reset is functionally equivalent to the Watchdog Reset.

Watchdog Timer

The Watchdog Timer (WDT) is a specially designed timer unit that will reset the chip upon reaching a pre-programmed time interval. It operates independently of the two general purpose timer/counters and is dedicated specifically to the watchdog function. The Watchdog Timer allows safe recovery from problems resulting from unexpected input conditions, external events, or programming anomalies.

The WDT is disabled following any reset. While disabled, the WDT time interval may be programmed. The WDT is enabled by a sequence of two write operations.

Once enabled, the WDT cannot be stopped (i.e., disabled) except by one of the four Reset types described in the last section. Furthermore, while the WDT is enabled, the WDT time interval cannot be modified. The WDT, however, may be cleared by software at any time with the same sequence of two write operations. The clearing operation causes the present count of the WDT to be set to zero, but it does not stop the WDT from incrementing.

If the count in the WDT ever reaches the pre-programmed value, the WDT will overflow, resetting the chip in two machine cycles. This is a Watchdog Reset. Additionally, if a system error condition is discovered, software may intentionally generate an immediate reset via the WDT, using a special sequence of write operations. This is a Software Reset.

A Watchdog Reset or Software Reset will set a special "cause" bit, allowing differentiation between these two Reset types and the Hardware or Power-On Reset types. Neither Watchdog Reset nor the Software Reset modify the contents of the Internal RAM. The Watchdog Reset will cause the RST pin to be pulled high during S1P1 and S1P2 of the first cycle of the two-cycle reset, providing a hardware indication that a reset is imminent.

Two 8-bit Special Function Registers are associated with the WDT. They are as follows:

Watchdog Selection — (WDS) — Address: A9 (Hex)

Watchdog Key — (WDK) — Address: AA (Hex)

Watchdog Selection — (WDS) — Address: A9H

The Watchdog Selection register allows the time interval of the WDT to be programmed and retains the cause of the most recent reset. This register is Read/Write, but its contents cannot be changed once the WDT has been enabled. Its default value after a Hardware or Power-On Reset = 00H. Its default value after a Watchdog Reset or Software Reset = 80H. This is the only register on the 80C521 whose initialization value differs between the two reset groups.

(MSB)				(LSB)			
RC	—	TV	—	PT3	PT2	PT1	PT0
7	6	5	4	3	2	1	0

Bits 3-0 — Programmed Time — (PT3 – PT0)

The value contained in these bits at the time the Watchdog Timer is enabled determines the time interval of the WDT. The time interval is a multiple of the input clock period. The times are decoded as follows:

Programmable Watchdog Timing Intervals

PT3-PT0	12 MHz	16 MHz	Clock Divide Ratio
0 0000	128 μ s	96 μ s	1536
1 0001	256 μ s	192 μ s	3072
2 0010	512 μ s	384 μ s	6144
3 0011	1.024 ms	768 μ s	12288
4 0100	2.048 ms	1.536 ms	24576
5 0101	4.096 ms	3.072 ms	49152
6 0110	8.192 ms	6.144 ms	98304
7 0111	16.384 ms	12.288 ms	196608
8 1000	32.768 ms	24.576 ms	393216
9 1001	65.536 ms	49.152 ms	786432
A 1010	131.072 ms	98.304 ms	1572864
B 1011	262.144 ms	196.608 ms	3145728
C 1100	524.288 ms	393.216 ms	6291456
D 1101	1.049 sec.	786.432 ms	12582912
E 1110	2.097 sec.	1.573 sec.	25165824
F 1111	4.194 sec.	3.146 sec.	50331648

If the Programmed Time bits are read while the WDT is disabled, they will show the last value written. Once the WDT is enabled, these bits will show the programmed time of the WDT and cannot be modified.

Bit 4

Reserved. Will return an unidentified value when read.

Bit 5 — Timer Verification — (TV)

This bit reflects Bit 12 of the internal counter within the Watchdog Timer. It will toggle every 8.192 ms at 12 MHz. This bit is Read-only.

Bit 6

Reserved. Will return an unidentified value when read.

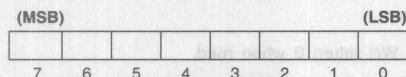
Bit 7 — Reset Cause — (RC)

The Reset Cause bit indicates the cause of the last reset of the 80C521. If a Power-On or Hardware Reset occurs, the bit is set to a zero by the reset circuitry. If a Watchdog or Software Reset occurs, the bit is set to a one by the reset circuitry. Like the Programmed Time bits, this bit may not be modified once the WDT is enabled. Writing this bit does not affect any chip function.

Watchdog Key — (WDK) — Address: AAH

This register controls the enabling and clearing of the Watchdog Timer. The writing of an A5H followed by the writing of a 5AH to this register enables the WDT to begin incrementing. It is not a requirement that the writes be on consecutive instructions, thus interrupts do not have to be disabled. Once the WDT is enabled, it may be cleared at any time by the writing of the same sequence. The clearing operation causes the present count of the WDT to be cleared, but does not stop the WDT from incrementing.

This is a Write-only register. Read operations are not defined and will not affect the WDT circuitry.



The enabling/clearing operation of the Watchdog Timer is accomplished by writing a keyed sequence of values to the WDK register. The Keyed Sequence is comprised of two stages (see Figure 1).



Data Pointer High — (DPH) — Address: 83H

DPH is a Read/Write register that contains the high byte of Data Pointer 2. It may be accessed at any time with an instruction that specifies a direct byte as a source or destination. However, 82H in the DPH register must be set to 0 before any of the six explicit "DPTR" instructions will access this register. The default at reset is 00H.

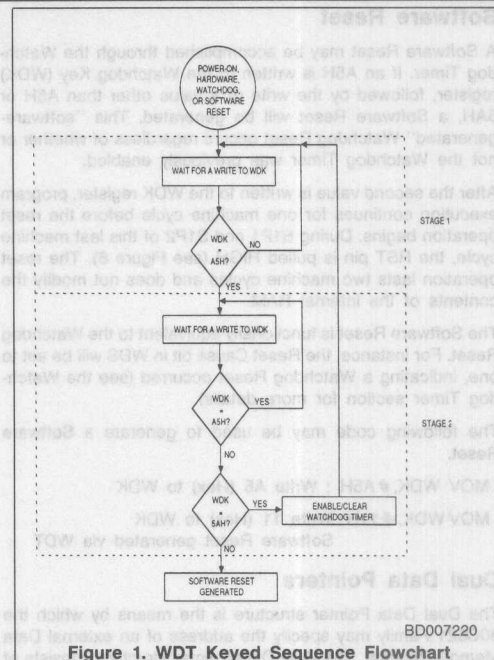


Figure 1. WDT Keyed Sequence Flowchart

The Keyed Sequence is in Stage 1 after all forms of reset, or following any Watchdog enable or clear operation. In Stage 1 all values written to the WDK register are ignored except A5H. An A5H causes the Keyed Sequence to enter Stage 2.

Once Stage 2 is entered, the next write to the WDK register prompts one of the following actions: 1) If the next write is again an A5H, the Keyed Sequence remains in Stage 2; 2) If the next write is a 5AH, the WDT is enabled/cleared, and the Keyed Sequence re-enters Stage 1; or, 3) If the next write is any other value, a Software Reset via the WDT is generated.

Example of Write Operations to WDK:

Write		Action Taken After Second Write
1st	2nd	
11	18	No action taken, Keyed Sequence still in Stage 1
A5	A5	Keyed Sequence enters Stage 2 and remains there
A5	5A	WDT is enabled/cleared, Sequence reenters Stage 1
A5	11	Software Reset occurs via the WDT

The two-stage feature, together with the Software Reset, greatly reduces the chance of an instruction sequence accidentally clearing the Watchdog Timer. Furthermore, while still allowing a Software Reset to be initiated, the two-stage feature reduces the chance of unintentionally generating a Software Reset.

Software Reset

A Software Reset may be accomplished through the Watchdog Timer. If an A5H is written to the Watchdog Key (WDK) register, followed by the write of a value other than A5H or 5AH, a Software Reset will be generated. This "software-generated" Watchdog Reset occurs regardless of whether or not the Watchdog Timer was previously enabled.

After the second value is written to the WDK register, program execution continues for one machine cycle before the reset operation begins. During S1P1 and S1P2 of this last machine cycle, the RST pin is pulled HIGH (see Figure 6). The reset operation lasts two machine cycles and does not modify the contents of the internal RAM.

The Software Reset is functionally equivalent to the Watchdog Reset. For instance, the Reset Cause bit in WDS will be set to one, indicating a Watchdog Reset occurred (see the Watchdog Timer section for more details).

The following code may be used to generate a Software Reset.

```
MOV WDK,#A5H ; Write A5 (Hex) to WDK
MOV WDK,#11H; Write 11 (Hex) to WDK
                Software Reset generated via WDT
```

Dual Data Pointers

The Dual Data Pointer structure is the means by which the 80C521 Family may specify the address of an external Data Memory location. The Dual Data Pointer structure consists of two 16-bit registers that address external memory, and a single 8-bit register that allows the program code to selectively switch between them. They are located in the Special Function Register space at the following addresses:

82H Data Pointer Low	-(DPL)	} Data Pointer 0 (DPTR0)
83H Data Pointer High	-(DPH)	
84H Data Pointer Low 1	-(DPL1)	} Data Pointer 1 (DPTR1)
85H Data Pointer High 1	-(DPH1)	
86H Data Pointer Selection	-(DPS)	

Data Pointer 0 (DPTR0) is the original data pointer on the standard 80C51 (formerly referred to as DPTR). Data Pointer 1 (DPTR1) is an additional data pointer with identical characteristics. Instructions that refer to "DPTR" refer to the data pointer that is currently selected in the Data Pointer Selection (DPS) register. The six instructions that reference "DPTR" are as follows:

INC DPTR	; Increments the data pointer by 1
MOV DPTR,#data16	; Loads DPTR with a 16-bit constant
MOVC A, @A + DPTR	; Move code byte relative to DPTR to Acc
MOVX A, @DPTR	; Move external RAM (16-bit address) to Acc
MOVX @DPTR, A	; Move Acc to external RAM (16-bit address)
JMP @A + DPTR	; Jump indirect relative to DPTR

It is also possible to access each data pointer on a byte-by-byte basis by specifying its low or high byte in an instruction that accesses the Special Function Registers. These instruc-

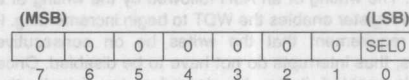
tions can be executed at any time regardless of which of the two data pointers is currently selected. Three examples are as follows:

```
MOV DPH,R3 ; Move the contents of Register 3 into DPH
MOV A,DPL1 ; Move the contents of DPL1 into the Acc
PUSH DPH1 ; Push the contents of DPH1 onto the stack
```

The Dual Data Pointer structure saves both time and code space by eliminating the need for frequent loading and unloading of a single data pointer. For instance, block move operations in external memory can be more efficiently implemented by using DPTR0 as the source address, and DPTR1 as the destination address. The Dual Data Pointer structure enhances this operation considerably.

Data Pointer Selection — (DPS) — Address: 86H

This register determines which of the two data pointers is currently "selected." Once a data pointer is selected, the six "DPTR" instructions refer only and always to that data pointer until another data pointer is selected. Upon reset, the default data pointer (DPTR0) will be selected, thus retaining compatibility with existing 8051 Family devices. The switch between data pointers may be accomplished with a single cycle instruction (such as: INC DPS or MOV DPS,A). The default value at reset = 00H. This is a Read/Write register.



Bit 0 — Select 0 — (SELO)

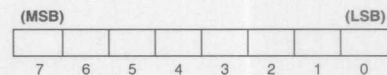
If this bit is 0, the original data pointer, DPTR0, is selected. If this bit is 1, DPTR1 is selected. This bit may be written by software at any time. When read, its current value is presented.

Bits 7-1

Reserved. Will return 0 when read.

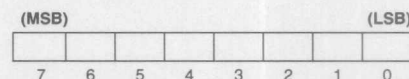
Data Pointer Low — (DPL) — Address: 82H

DPL is a Read/Write register that contains the low byte of Data Pointer 0. It may be accessed at any time with an instruction that specifies a direct byte as a source of destination. However, SELO in the DPS register must be set to 0 before any of the six explicit "DPTR" instructions will access this register. The default at reset = 00H.



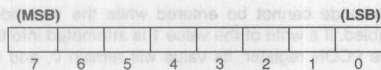
Data Pointer High — (DPH) — Address: 83H

DPH is a Read/Write register that contains the high byte of Data Pointer 0. It may be accessed at any time with an instruction that specifies a direct byte as a source or destination. However, SELO in the DPS register must be set to 0 before any of the six explicit "DPTR" instructions will access this register. The default at reset = 00H.



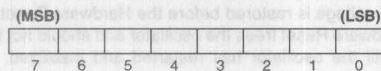
Data Pointer Low 1 — (DPL1) — Address: 84H

DPL1 is a Read/Write register that contains the low byte of Data Pointer 1. It may be accessed at any time with an instruction that specifies a direct byte as a source or destination. However, SEL0 in the DPS register must be set to 1 before any of the six explicit "DPTR" instructions will access this register. The default at reset = 00H.



Data Pointer High 1 — (DPH1) — Address: 85H

DPH1 is a Read/Write register that contains the high byte of Data Pointer 1. It may be accessed at any time with an instruction that specifies a direct byte as a source or destination. However, SEL0 in the DPS register must be set to 1 before any of the six explicit "DPTR" instructions will access this register. The default at reset = 00H.



Dual Data Pointer Example

To load both data pointers after reset:

Method-1:

```
MOV DPL, #data8    ; load low byte of DPTR0
MOV DPH, #data8    ; load high byte of DPTR0
MOV DPL1, #data8   ; load low byte of DPTR1
MOV DPH1, #data8   ; load high byte of DPTR1
(Data Pointer 0 is still selected.)
```

Method-2:

```
MOV DPTR, #data16  ; load DPTR0 with 16-bit const.
INC DPH            ; switch data pointers
MOV DPTR, #data16  ; load DPTR1 with 16-bit const.
(Data Pointer 1 is now selected.)
```

Oscillator Characteristics

XTAL1 and XTAL2 are the input and output, respectively, of an inverting amplifier which is configured for use as an on-chip oscillator (see Figure 2). Either a quartz crystal or ceramic resonator may be used.

To drive the device from an external clock source, XTAL1 should be driven while XTAL2 is left unconnected (see Figure 3). There are no requirements on the duty cycle of the external-clock signal since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum HIGH and LOW times specified on the data sheet must be observed.

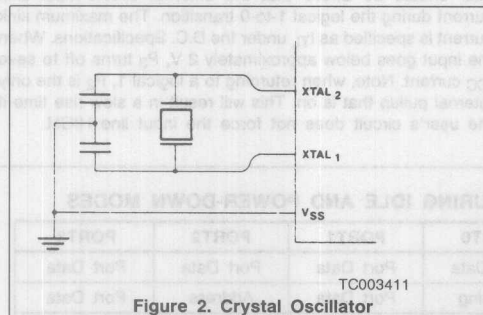
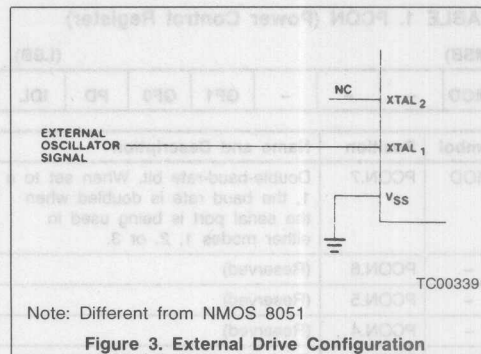


Figure 2. Crystal Oscillator



Note: Different from NMOS 8051

Figure 3. External Drive Configuration

Idle and Power-Down Operation

Figure 4 shows the internal operation of the Idle and Power-Down circuitry. Power-Down operation disconnects the clock source from all internal chip circuitry. Idle mode operation allows the interrupt, serial port, timers, and watchdog circuitry to continue to function, while the CPU is stopped. If the Watchdog Timer is enabled, Power-Down operation is not possible.

These special modes are activated by software via the Special Function Register, PCON (Table 1). Its hardware address is 87H; PCON is not bit-addressable.

If "1"s are written to PD and IDL at the same time, PD takes precedence. The reset value of PCON is "0XXX0000".

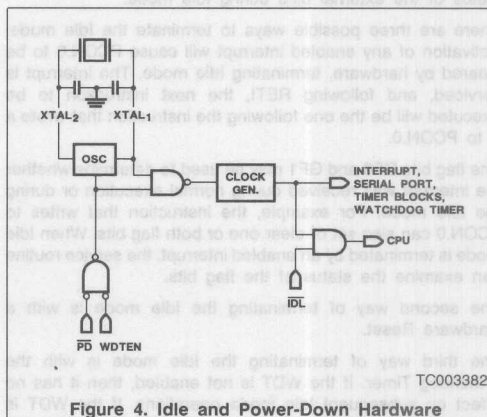


Figure 4. Idle and Power-Down Hardware

TABLE 1. PCON (Power Control Register)

(MSB)				(LSB)			
SMOD	-	-	-	GF1	GF0	PD	IDL
Symbol	Position	Name and Description					
SMOD	PCON.7	Double-baud-rate bit. When set to a 1, the baud rate is doubled when the serial port is being used in either modes 1, 2, or 3.					
-	PCON.6	(Reserved)					
-	PCON.5	(Reserved)					
-	PCON.4	(Reserved)					
GF1	PCON.3	General-purpose flag bit					
GF0	PCON.2	General-purpose flag bit					
PD	PCON.1	Power-Down bit. Setting this bit activates power-down operation.					
IDL	PCON.0	Idle-mode bit. Setting this bit activates idle-mode operation.					

Idle Mode

The instruction that sets PCON.0 is the last instruction executed in the normal operating mode before Idle mode is activated. Once in the Idle mode, the CPU status is preserved in its entirety: the Stack Pointer, Program Counter, Program Status Word, Accumulator, RAM, and all other registers in the 80C521 maintain their data during Idle. Table 2 describes the status of the external pins during Idle mode.

There are three possible ways to terminate the Idle mode. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating Idle mode. The interrupt is serviced, and following RETI, the next instruction to be executed will be the one following the instruction that wrote a 1 to PCON.0.

The flag bits GF0 and GF1 may be used to determine whether the interrupt was received during normal execution or during the Idle mode. For example, the instruction that writes to PCON.0 can also set or clear one or both flag bits. When Idle mode is terminated by an enabled interrupt, the service routine can examine the status of the flag bits.

The second way of terminating the Idle mode is with a Hardware Reset.

The third way of terminating the Idle mode is with the Watchdog Timer. If the WDT is not enabled, then it has no effect on subsequent Idle mode operations. If the WDT is enabled before Idle mode is entered, it will continue to increment in the normal fashion. If the WDT overflows, the 80C521 will experience a Watchdog Reset and Idle mode will be terminated. If Idle mode is terminated by any method other than a reset, the Watchdog Timer will continue to run.

Power-Down Mode

The instruction that sets PCON.1 is the last executed prior to going into Power-Down. Once in Power-Down, the oscillator is stopped. The contents of the on-chip RAM are preserved. The Special Function Registers are saved, until a Hardware Reset is generated. A hardware reset is the only way of exiting the Power-Down mode.

Power-Down mode cannot be entered while the Watchdog Timer is enabled. If a write of the value 1 is attempted into the PD bit of the PCON register, its value will remain 0, and no Power-Down operation will take place. To enter Power-Down mode, the Watchdog Timer must first be disabled via a Hardware Reset, Software Reset, or Watchdog Reset. After reset, the Watchdog Timer is disabled, allowing Power-Down mode to be entered.

In the Power-Down mode, V_{CC} may be lowered to minimize circuit power consumption. Care must be taken to ensure the voltage is not reduced until the Power-Down mode is entered, and that the voltage is restored before the Hardware Reset is applied. Hardware Reset frees the oscillator and should not be released until the oscillator has restarted and stabilized.

Table 2 describes the status of the external pins while in the Power-Down mode. It should be noted that if the Power-Down mode is activated while in external program memory, the port data that is held in the Special Function Register P₂ is restored to Port 2. If the data is a 1, the port pin is held HIGH during the Power-Down mode by the strong pullup, P₁, shown in Figure 5.

80C521 I/O Ports

The I/O port drive of the 80C521 is similar to the 8051. The I/O buffers for Ports 1, 2, and 3 are implemented as shown in Figure 5.

When the port latch contains a 0, all pFETS in Figure 4 are off while the nFET is turned on. When the port latch makes a 0-to-1 transition, the nFET turns off. The strong pullup pFET, P₁, turns on for two oscillator periods, pulling the output HIGH very rapidly. As the output line is drawn HIGH, pFET P₃ turns on through the inverter to supply the I_{OH} source current. This inverter and P₃ form a latch which holds the 1 and is supported by P₂.

When Port 2 is used as an address port, for access to external program or data memory, any address bit that contains a 1 will have its strong pullup turned on for the entire duration of the external memory access.

When an I/O pin on Ports 1, 2, or 3 is used as an input, the user should be aware that the external circuit must sink current during the logical 1-to-0 transition. The maximum sink current is specified as I_{TL} under the D.C. Specifications. When the input goes below approximately 2 V, P₃ turns off to save I_{CC} current. Note, when returning to a logical 1, P₂ is the only internal pullup that is on. This will result in a slow rise time if the user's circuit does not force the input line HIGH.

TABLE 2. STATUS OF THE EXTERNAL PINS DURING IDLE AND POWER-DOWN MODES

Mode	Program Memory	ALE	PSEN	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Port Data	Port Data	Port Data	Port Data
Idle	External	1	1	Floating	Port Data	Address	Port Data
Power-Down	Internal	0	0	Port Data	Port Data	Port Data	Port Data
Power-Down	External	0	0	Floating	Port Data	Port Data	Port Data

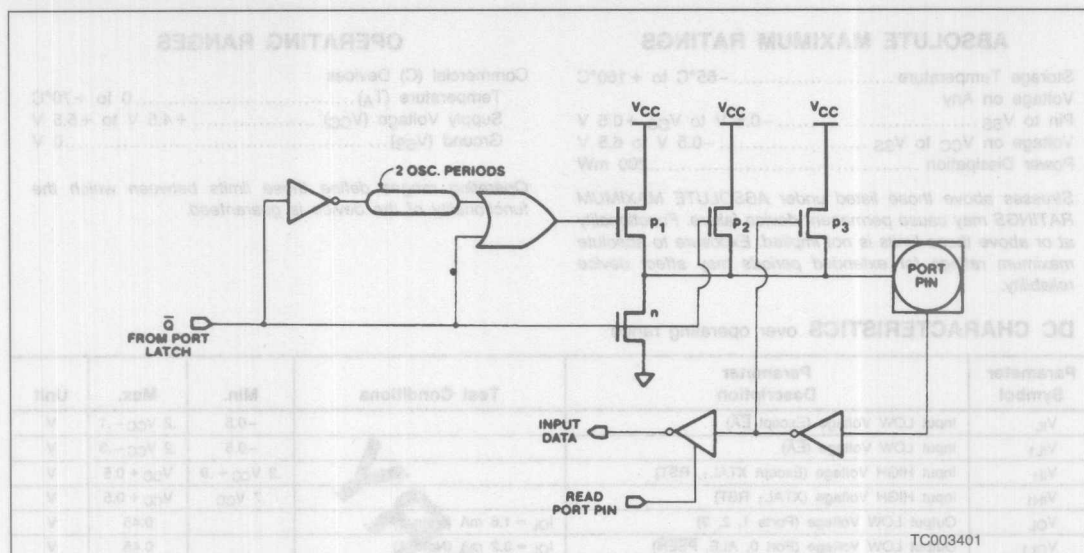
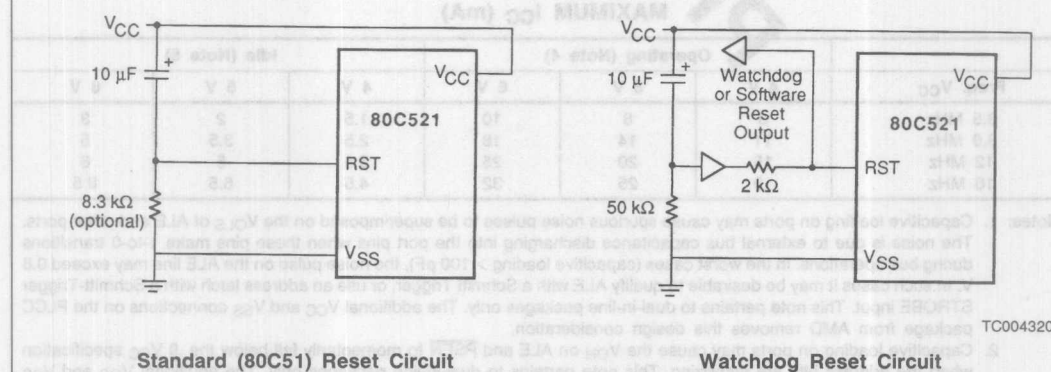


Figure 5. I/O Buffers in the 80C521 (Ports 1, 2, 3)



Standard (80C51) Reset Circuit

Watchdog Reset Circuit

Neither a Watchdog nor a Software Reset will affect the "Standard" reset circuitry, nor can they be sensed by the "Standard" (80C51) reset circuitry.

The reset circuit shown above may be used to sense a Watchdog or Software Reset. For $V_{CC} = 5\text{ V}$, the driver input must be able to source/sink 2.5 mA.

Figure 6. RESET Configurations

ABSOLUTE MAXIMUM RATINGS

Storage Temperature -65°C to +150°C
 Voltage on Any Pin to V_{SS} -0.5 V to $V_{CC} + 0.5$ V
 Voltage on V_{CC} to V_{SS} -0.5 V to 6.5 V
 Power Dissipation 200 mW

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Temperature (T_A) 0 to +70°C
 Supply Voltage (V_{CC}) +4.5 V to +5.5 V
 Ground (V_{SS}) 0 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over operating range

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Unit
V_{IL}	Input LOW Voltage (Except \overline{EA})		-0.5	.2 $V_{CC} - .1$	V
V_{IL1}	Input LOW Voltage (\overline{EA})		-0.5	.2 $V_{CC} - .3$	V
V_{IH}	Input HIGH Voltage (Except XTAL ₁ , RST)		.2 $V_{CC} + .9$	$V_{CC} + 0.5$	V
V_{IH1}	Input HIGH Voltage (XTAL ₁ , RST)		.7 V_{CC}	$V_{CC} + 0.5$	V
V_{OL}	Output LOW Voltage (Ports 1, 2, 3)	$I_{OL} = 1.6$ mA (Note 1)		0.45	V
V_{OL1}	Output LOW Voltage (Port 0, ALE, PSEN)	$I_{OL} = 3.2$ mA (Note 1)		0.45	V
V_{OH}	Output HIGH Voltage (Ports 1, 2, 3)	$I_{OH} = -60$ μ A, $V_{CC} = 5 \pm 10\%$	2.4		V
		$I_{OH} = -25$ μ A	.75 V_{CC}		V
		$I_{OH} = -10$ μ A	.9 V_{CC}		V
V_{OH1}	Output HIGH Voltage (Port 0 in External Bus Mode, ALE, PSEN)	$I_{OH} = -800$ μ A, $V_{CC} = 5 \pm 10\%$	2.4		V
		$I_{OH} = -300$ μ A	.75 V_{CC}		V
		$I_{OH} = -80$ μ A (Note 2)	.9 V_{CC}		V
I_{IL}	Logical 0 Input Current (Ports 1, 2, 3)	$V_{IN} = 0.45$ V		-50	μ A
I_{TL}	Logical 1 to 0 Transition Current (Ports 1, 2, 3)	$V_{IN} = 2$ V		-650	μ A
I_{LI}	Input Leakage Current (Port 0, \overline{EA})	$0.45 < V_{IN} < V_{CC}$		± 10	μ A
RRST	Reset Pulldown Resistor		50	150	k Ω
CIO	Pin Capacitance	Test Freq. = 1 MHz, $T_A = 25^\circ$ C		10	pF
I_{PD}	Power Down Current	$V_{CC} = 2$ to 6 V (Note 3)		50	μ A

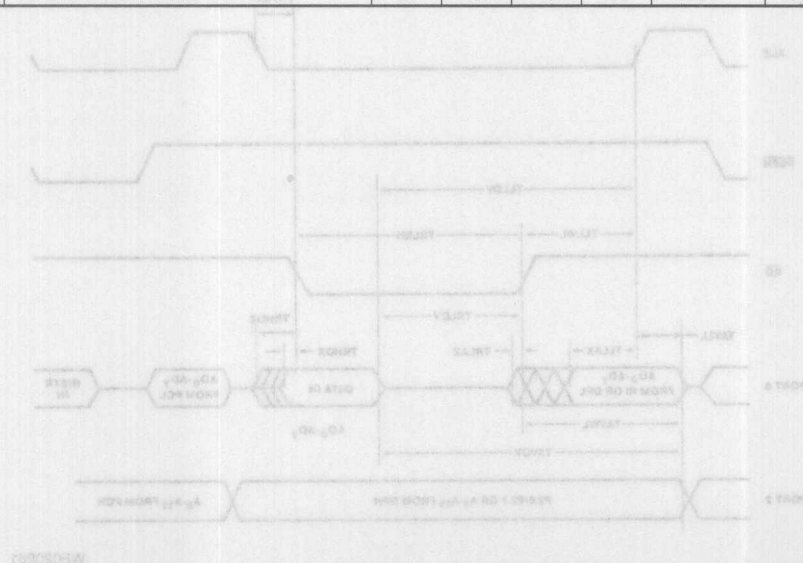
MAXIMUM I_{CC} (mA)

Freq. V_{CC}	Operating (Note 4)			Idle (Note 5)		
	4 V	5 V	6 V	4 V	5 V	6 V
3.5 MHz	6	8	10	1.5	2	3
8.0 MHz	11	14	18	2.5	3.5	5
12 MHz	15	20	25	3.5	5	6
16 MHz	19	25	32	4.5	6.5	8.5

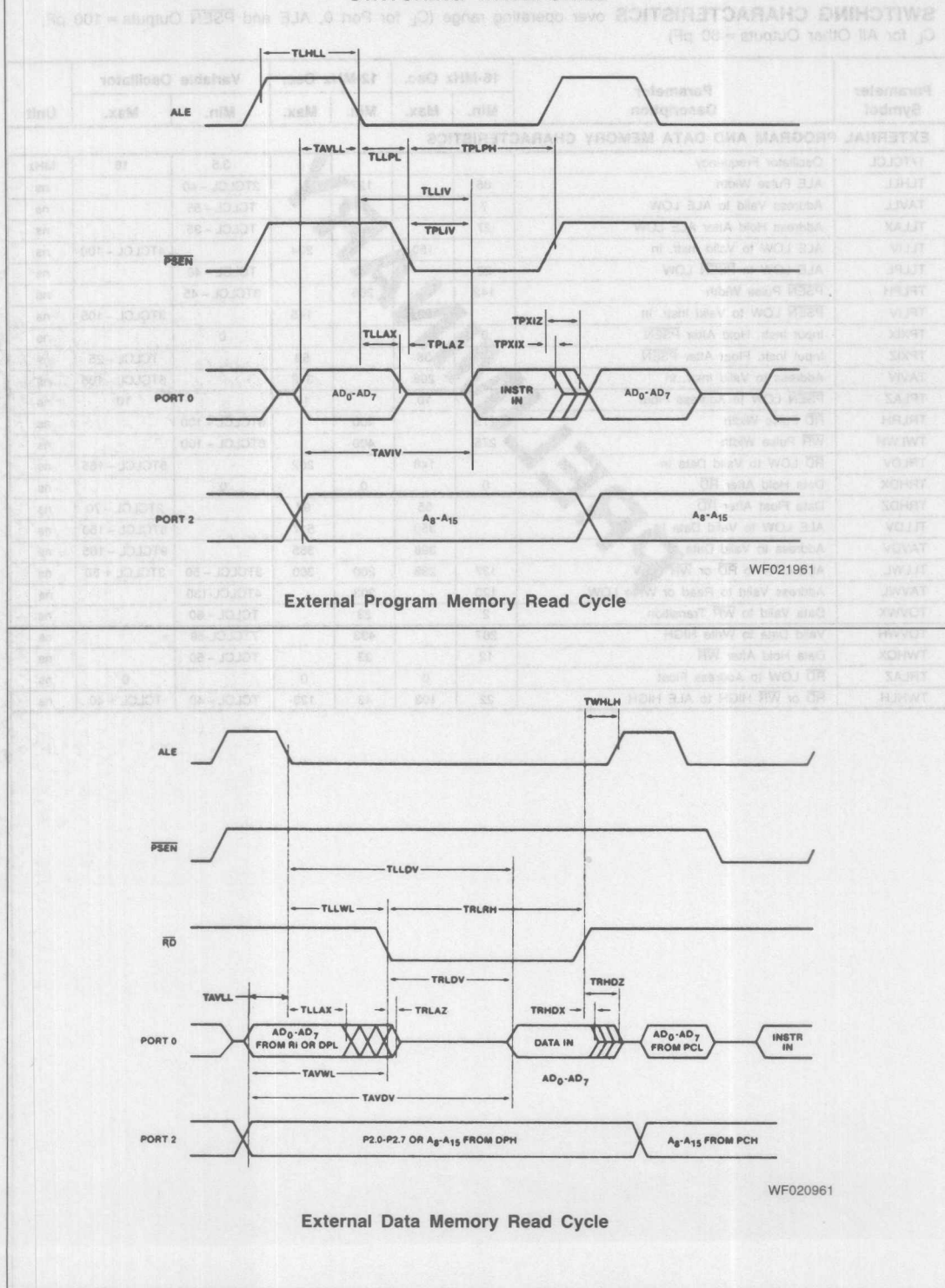
- Notes: 1. Capacitive loading on ports may cause spurious noise pulses to be superimposed on the V_{OLS} of ALE and other ports. The noise is due to external bus capacitance discharging into the port pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100 pF), the noise pulse on the ALE line may exceed 0.8 V. In such cases it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt-Trigger STROBE input. This note pertains to dual-in-line packages only. The additional V_{CC} and V_{SS} connections on the PLCC package from AMD removes this design consideration.
2. Capacitive loading on ports may cause the V_{OH} on ALE and PSEN to momentarily fall below the .9 V_{CC} specification when the address bits are stabilizing. This note pertains to dual-in-line packages only. The additional V_{CC} and V_{SS} connections on the PLCC package from AMD removes this design consideration.
3. Power-Down I_{CC} is measured with all outputs pins disconnected; \overline{EA} = Port 0 = V_{CC} ; XTAL₂ N.C.; RST = V_{SS} .
4. I_{CC} is measured with all output pins disconnected; XTAL₁ driven with TCLCH, TCHCL = 5 ns, $V_{IL} = V_{SS} + .5$ V, $V_{IH} = V_{CC} - .5$ V; XTAL₂ N.C.; \overline{EA} = RST = Port 0 = V_{CC} . Typical values are approximately 50% lower. I_{CC} would be slightly higher if a crystal oscillator is used.
5. Idle I_{CC} is measured with all output pins disconnected; XTAL₁ driven with TCLCH, TCHCL = 5 ns, $V_{IL} = V_{SS} + .5$ V, $V_{IH} = V_{CC} - .5$ V; XTAL₂ N.C.; Port 0 = V_{CC} ; \overline{EA} = RST = V_{SS} , and the Watchdog Timer disabled.

SWITCHING CHARACTERISTICS over operating range (C_L for Port 0, ALE and \overline{PSEN} Outputs = 100 pF;
 C_L for All Other Outputs = 80 pF)

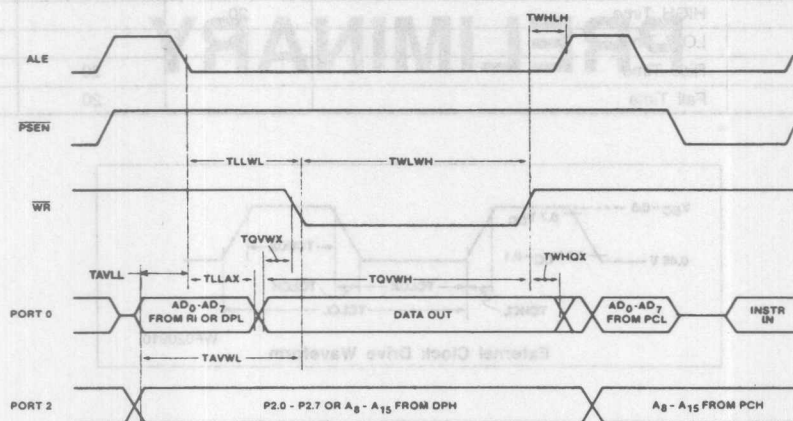
Parameter Symbol	Parameter Description	16-MHz Osc.		12-MHz Osc.		Variable Oscillator		Unit
		Min.	Max.	Min.	Max.	Min.	Max.	
EXTERNAL PROGRAM AND DATA MEMORY CHARACTERISTICS								
1/TCLCL	Oscillator Frequency					3.5	16	MHz
TLHLL	ALE Pulse Width	85		127		2TCLCL – 40		ns
TAVLL	Address Valid to ALE LOW	7		28		TCLCL – 55		ns
TLLAX	Address Hold After ALE LOW	27		48		TCLCL – 35		ns
TLLIV	ALE LOW to Valid Instr. In		150		234		4TCLCL – 100	ns
TLLPL	ALE LOW to PSEN LOW	22		49		TCLCL – 40		ns
TPLPH	PSEN Pulse Width	142		205		3TCLCL – 45		ns
TPLIV	PSEN LOW to Valid Instr. In		80		145		3TCLCL – 105	ns
TPXIX	Input Instr. Hold After PSEN	0		0		0		ns
TPXIZ	Input Instr. Float After PSEN		38		59		TCLCL – 25	ns
TAVIV	Address to Valid Instr. In		208		312		5TCLCL – 105	ns
TPLAZ	PSEN LOW to Address Float		10		10		10	ns
TRLRH	RD Pulse Width	275		400		6TCLCL – 100		ns
TWLWH	WR Pulse Width	275		400		6TCLCL – 100		ns
TRLDV	RD LOW to Valid Data In		148		252		5TCLCL – 165	ns
TRHDX	Data Hold After RD	0		0		0		ns
TRHDZ	Data Float After RD		55		97		2TCLCL – 70	ns
TLLDV	ALE LOW to Valid Data In		350		517		8TCLCL – 150	ns
TAVDV	Address to Valid Data In		398		585		9TCLCL – 165	ns
TLLWL	ALE LOW to RD or WR LOW	137	238	200	300	3TCLCL – 50	3TCLCL + 50	ns
TAVWL	Address Valid to Read or Write LOW	120		203		4TCLCL-130		ns
TQVWX	Data Valid to WR Transition	2		23		TCLCL – 60		ns
TQVWH	Valid Data to Write HIGH	287		433		7TCLCL-59		ns
TWHQX	Data Hold After WR	12		33		TCLCL – 50		ns
TRLAZ	RD LOW to Address Float		0		0		0	ns
TWHLH	RD or WR HIGH to ALE HIGH	22	103	43	123	TCLCL – 40	TCLCL + 40	ns



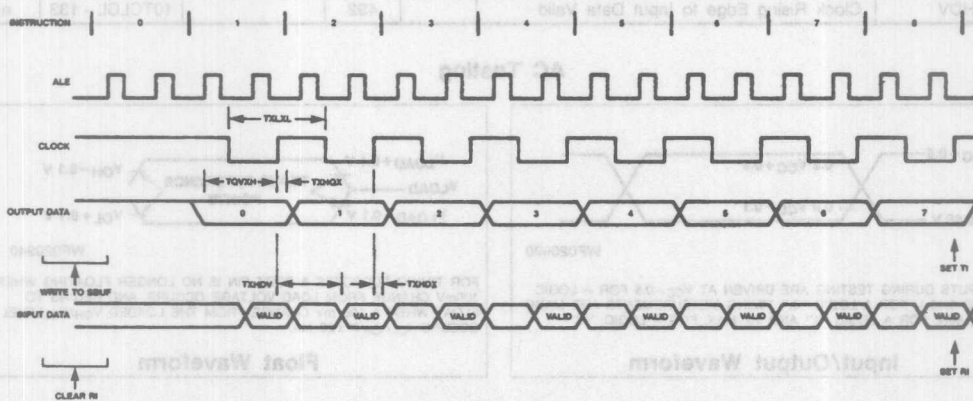
SWITCHING WAVEFORMS



SWITCHING WAVEFORMS (Cont'd.)



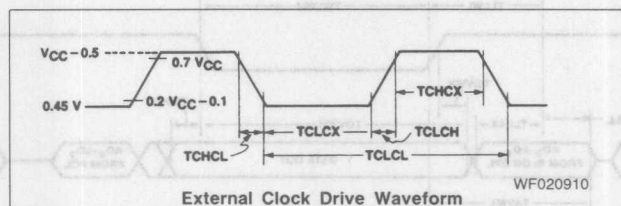
External Data Memory Write Cycle



Shift Register Timing Waveforms

EXTERNAL CLOCK DRIVE

Parameter Symbol	Parameter Description	Min.	Max.	Unit
1/TCLCL	Oscillator Frequency	3.5	16	MHz
TCHCX	HIGH Time	20		ns
TCLCX	LOW Time	20		ns
TCLCH	Rise Time		20	ns
TCHCL	Fall Time		20	ns

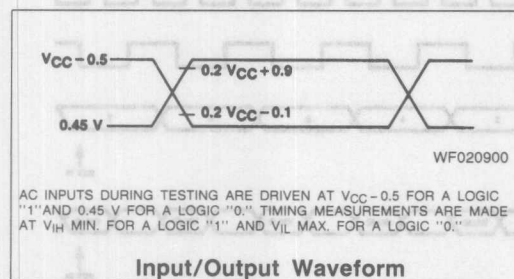


SERIAL PORT TIMING — SHIFT REGISTER MODE

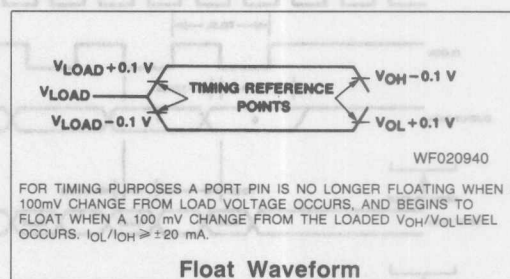
Test Conditions: $T_A = 0^\circ\text{C}$ to 70°C ; $V_{CC} = 5\text{ V} \pm 10\%$; $V_{SS} = 0\text{ V}$; Load Capacitance = 80 pF

Parameter Symbol	Parameter Description	16-MHz Osc.		Variable Oscillator		Unit
		Min.	Max.	Min.	Max.	
TXLXL	Serial Port Clock Cycle Time	750		12TCLCL		ns
TQVXH	Output Data Setup to Clock Rising Edge	492		10TCLCL - 133		ns
TXHQX	Output Data Hold After Clock Rising Edge	0		2TCLCL - 117		ns
TXHDX	Input Data Hold After Clock Rising Edge	0		0		ns
TXHDV	Clock Rising Edge to Input Data Valid		492		10TCLCL - 133	ns

AC Testing

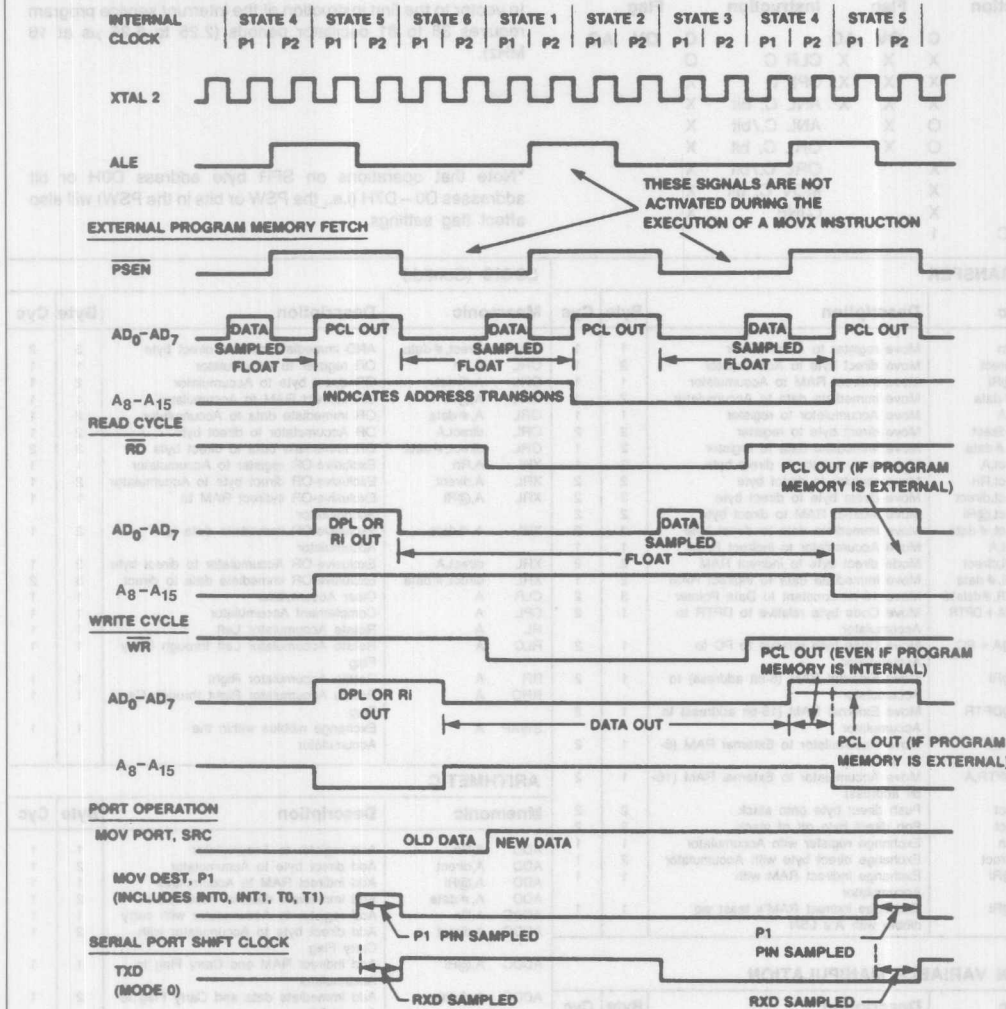


AC INPUTS DURING TESTING ARE DRIVEN AT $V_{CC}-0.5$ FOR A LOGIC "1" AND 0.45 V FOR A LOGIC "0." TIMING MEASUREMENTS ARE MADE AT V_{IH} MIN. FOR A LOGIC "1" AND V_{IL} MAX. FOR A LOGIC "0."



FOR TIMING PURPOSES A PORT PIN IS NO LONGER FLOATING WHEN A 100mV CHANGE FROM LOAD VOLTAGE OCCURS, AND BEGINS TO FLOAT WHEN A 100 mV CHANGE FROM THE LOADED V_{OH}/V_{OL} LEVEL OCCURS. $I_{OL}/I_{OH} \geq \pm 20\text{ mA}$.

CLOCK WAVEFORMS



WF020922

This diagram indicates when signals are clocked internally. The time it takes the signals to propagate to the pins, however, ranges from 25 to 125 ns. This propagation delay is dependent on variables such as temperature and pin loading. Propagation also varies from output to output and component to component. Typically though, ($T_A = 25^\circ\text{C}$, fully loaded) RD and WR propagation delays are approximately 50 ns. The other signals are typically 85 ns. Propagation delays are incorporated in the AC specifications.

TABLE 2. 80C521/80C321 INSTRUCTION SET

Instructions That Affect Flag Setting*

Instruction	Flag			Instruction	Flag		
	C	OV	AC		C	OV	AC
ADD	X	X	X	CLR C	O		
ADDC	X	X	X	CPL C	X		
SUBB	X	X	X	ANL C, bit	X		
MUL	O	X		ANL C, /bit	X		
DIV	O	X		ORL C, bit	X		
DA	X			ORL C, /bit	X		
RRC	X			MOV C, bit	X		
RLC	X			CJNE	X		
SETB C	1						

Interrupt Response Time: To finish execution of current instruction, respond to the interrupt request and push the PC; to vector to the first instruction of the interrupt service program requires 38 to 81 oscillator periods (2.25 to 5.25 μ s at 16 MHz).

*Note that operations on SFR byte address D0H or bit addresses D0 – D7H (i.e., the PSW or bits in the PSW) will also affect flag settings.

DATA TRANSFER					LOGIC (Cont'd.)				
Mnemonic		Description	Byte	Cyc	Mnemonic		Description	Byte	Cyc
MOV	A,Rn	Move register to Accumulator	1	1	ANL	direct, #data	AND immediate data to direct byte	3	2
MOV	A,direct	Move direct byte to Accumulator	2	1	ORL	A,Rn	OR register to Accumulator	1	1
MOV	A,@Ri	Move indirect RAM to Accumulator	1	1	ORL	A,direct	OR direct byte to Accumulator	2	1
MOV	A,#data	Move immediate data to Accumulator	2	1	ORL	A,@Ri	OR indirect RAM to Accumulator	1	1
MOV	Rn,A	Move Accumulator to register	1	1	ORL	A,#data	OR immediate data to Accumulator	2	1
MOV	Rn,direct	Move direct byte to register	2	2	ORL	direct,A	OR Accumulator to direct byte	2	1
MOV	Rn,#data	Move immediate data to register	2	1	ORL	direct,#data	OR immediate data to direct byte	3	2
MOV	direct,A	Move Accumulator to direct byte	2	1	XRL	A,Rn	Exclusive-OR register to Accumulator	1	1
MOV	direct,Rn	Move register to direct byte	2	2	XRL	A,direct	Exclusive-OR direct byte to Accumulator	2	1
MOV	direct,direct	Move direct byte to direct byte	3	2	XRL	A,@Ri	Exclusive-OR indirect RAM to Accumulator	1	1
MOV	direct,@Ri	Move indirect RAM to direct byte	2	2			Accumulator		
MOV	direct,#data	Move immediate data to direct byte	3	2	XRL	A,#data	Exclusive-OR immediate data to Accumulator	2	1
MOV	@Ri,A	Move Accumulator to indirect RAM	1	1			Accumulator		
MOV	@Ri,direct	Move direct byte to indirect RAM	2	2	XRL	direct,A	Exclusive-OR Accumulator to direct byte	2	1
MOV	@Ri,#data	Move immediate data to indirect RAM	2	1	XRL	direct,#data	Exclusive-OR immediate data to direct	3	2
MOV	DPTR,#data16	Move 16-bit constant to Data Pointer	3	2	CLR	A	Clear Accumulator	1	1
MOVC	A,@A + DPTR	Move Code byte relative to DPTR to Accumulator	1	2	CPL	A	Complement Accumulator	1	1
MOVC	A,@A + PC	Move Code byte relative to PC to Accumulator	1	2	RL	A	Rotate Accumulator Left	1	1
MOVX	A,@Ri	Move External RAM (8-bit address) to Accumulator	1	2	RLC	A	Rotate Accumulator Left through Carry Flag	1	1
MOVX	A,@DPTR	Move External RAM (16-bit address) to Accumulator	1	2	RR	A	Rotate Accumulator Right	1	1
MOVX	@Ri,A	Move Accumulator to External RAM (8-bit address)	1	2	RRC	A	Rotate Accumulator Right through Carry Flag	1	1
MOVX	@DPTR,A	Move Accumulator to External RAM (16-bit address)	1	2	SWAP	A	Exchange nibbles within the Accumulator	1	1
PUSH	direct	Push direct byte onto stack	2	2	ARITHMETIC				
POP	direct	Pop direct byte off of stack	2	2					
XCH	A,Rn	Exchange register with Accumulator	1	1	Mnemonic		Description	Byte	Cyc
XCH	A,direct	Exchange direct byte with Accumulator	2	1	ADD	A,Rn	Add register to Accumulator	1	1
XCH	A,@Ri	Exchange indirect RAM with Accumulator	1	1	ADD	A,direct	Add direct byte to Accumulator	2	1
XCHD	A,@Ri	Exchange indirect RAM's least sig nibble with A's LSN	1	1	ADD	A,@Ri	Add indirect RAM to Accumulator	1	1
BOOLEAN VARIABLE MANIPULATION					ADD	A,#data	Add immediate data to Accumulator	2	1
CLR	C	Clear Carry Flag	1	1	ADDC	A,Rn	Add register to Accumulator with carry	1	1
CLR	bit	Clear direct bit	2	1	ADDC	A,direct	Add direct byte to Accumulator with Carry Flag	2	1
SETB	C	Set Carry Flag	1	1	ADDC	A,@Ri	Add indirect RAM and Carry Flag to Accumulator	1	1
SETB	bit	Set direct bit	2	1	ADDC	A,#data	Add immediate data and Carry Flag to Accumulator	2	1
CPL	C	Complement Carry Flag	1	1	SUBB	A,Rn	Subtract register from Accumulator with Borrow	1	1
CPL	bit	Complement direct bit	2	1	SUBB	A,direct	Subtract direct byte from Accumulator with Borrow	2	1
ANL	C,bit	AND direct bit to Carry Flag	2	2	SUBB	A,@Ri	Subtract indirect RAM from Accumulator with Borrow	1	1
ANL	C,/bit	AND complement of direct bit to Carry	2	2	SUBB	A,#data	Subtract immediate data from Accumulator with Borrow	2	1
ORL	C,bit	OR direct bit to Carry Flag	2	2	INC	A	Increment Accumulator	1	1
ORL	C,/bit	OR complement of direct bit to Carry	2	2	INC	Rn	Increment register	1	1
MOV	C,bit	Move direct bit to Carry Flag	2	1	INC	direct	Increment direct byte	2	1
MOV	bit,C	Move Carry flag to direct bit	2	2	INC	@Ri	Increment indirect RAM	1	1
LOGIC					DEC	A	Decrement Accumulator	1	1
ANL	A,Rn	AND register to Accumulator	1	1	DEC	Rn	Decrement register	1	1
ANL	A,direct	AND direct byte to Accumulator	2	1	DEC	direct	Decrement direct byte	2	1
ANL	A,@Ri	AND indirect RAM to Accumulator	1	1	DEC	@Ri	Decrement indirect RAM	1	1
ANL	A,#data	AND immediate data to Accumulator	2	1	INC	DPTR	Increment Data Pointer	1	2
ANL	direct,A	AND Accumulator to direct byte	2	1	MUL	AB	Multiply Accumulator times B	1	4
					DIV	AB	Divide Accumulator by B	1	4
					DA	A	Decimal Adjust Accumulator	1	1

OTHER				CONTROL TRANSFER (SUBROUTINE)											
Mnemonic	Description	Byte	Cyc	Mnemonic	Description	Byte	Cyc								
NOP	No Operation	1	1	ACALL addr11	Absolute Subroutine Call	2	2								
CONTROL TRANSFER (BRANCH)				LCALL addr16	Long Subroutine Call	3	2								
				RET	Return from Subroutine Call	1	2								
				RETI	Return from Interrupt Call	1	2								
				Notes on Data Addressing Modes:											
Mnemonic				Description				Byte				Cyc			
AJMP	addr11	Absolute Jump	2	2	Rn	-Working register R0 – R7 of the currently selected Register bank.									
LJMP	addr16	Long Jump	3	2	direct	-128 internal RAM locations, any I/O port, control, or Special Function Registers.									
SJMP	rel	Short Jump (relative addr)	2	2	@Ri	-Indirect internal RAM location addressed by register R0 or R1.									
JMP	@A + DPTR	Jump indirect relative to the DPTR	1	2	#data	-8-bit constant included in instruction.									
JZ	rel	Jump if Accumulator is zero	2	2	#data16	-16-bit constant included as bytes 2 and 3 of instruction.									
JNZ	rel	Jump if Accumulator is not zero	2	2	bit	-128 software flags, any I/O pin, control, or status bit.									
JC	rel	Jump if Carry Flag is set	2	2	Notes on Program Addressing Modes:										
JNC	rel	Jump if carry is not set	2	2											
JB	bit,rel	Jump relative if direct bit is set	3	2	addr16	-Destination address for LCALL and LJMP may be anywhere within the 64-Kilobyte program memory address space.									
JNB	bit,rel	Jump relative if direct bit is not set	3	2	addr11	-Destination address for ACALL and AJMP will be within the same 2-Kilobyte page of program memory as the first byte of the following instruction.									
JBC	bit,rel	Jump relative if direct bit is set, then clear bit	3	2	rel	-SJMP and all conditional jumps include as 8-bit offset by Range is + 127, -128 bytes relative to first byte of the following instruction.									
CJNE	A,direct,rel	Compare direct byte to Accumulator and Jump if not Equal	3	2											
CJNE	A,#data,rel	Compare immediate to Accumulator and Jump if not Equal	3	2											
CJNE	Rn,#data,rel	Compare immediate to reg and Jump if not Equal	3	2											
CJNE	@Ri,#data,rel	Compare immediate to indirect RAM and Jump if not Equal	3	2											
DJNZ	Rn,rel	Decrement register and Jump if not zero	2	2											
DJNZ	direct,rel	Decrement direct byte and Jump if not zero	3	2											

TABLE 3. INSTRUCTION OPCODES IN HEXADECIMAL ORDER (Cont'd.)

Hex Code	Bytes	Mnemonic	Operands	Hex Code	Bytes	Mnemonic	Operands
00	1	NOP		29	1	ADD	A,R1
01	2	AJMP	Code addr	2A	1	ADD	A,R2
02	3	LJMP	Code addr	2B	1	ADD	A,R3
03	1	RR	A	2C	1	ADD	A,R4
04	1	INC	A	2D	1	ADD	A,R5
05	2	INC	Data addr	2E	1	ADD	A,R6
06	1	INC	@R0	2F	1	ADD	A,R7
07	1	INC	@R1	30	3	JNB	Bit addr,code addr
08	1	INC	R0	31	2	ACALL	Code addr
09	1	INC	R1	32	1	RETI	
0A	1	INC	R2	33	1	RLC	A
0B	1	INC	R3	34	2	ADDC	A,#data
0C	1	INC	R4	35	2	ADDC	A,data addr
0D	1	INC	R5	36	1	ADDC	A,@R0
0E	1	INC	R6	37	1	ADDC	A,@R1
0F	1	INC	R7	38	1	ADDC	A,R0
10	3	JBC	Bit addr,code addr	39	1	ADDC	A,R1
11	2	ACALL	Code addr	3A	1	ADDC	A,R2
12	3	LCALL	Code addr	3B	1	ADDC	A,R3
13	1	RRC	A	3C	1	ADDC	A,R4
14	1	DEC	A	3D	1	ADDC	A,R5
15	2	DEC	Data addr	3E	1	ADDC	A,R6
16	1	DEC	@R0	3F	1	ADDC	A,R7
17	1	DEC	@R1	40	2	JC	Code addr
18	1	DEC	R0	41	2	AJMP	Code addr
19	1	DEC	R1	42	2	ORL	Data addr,A
1A	1	DEC	R2	43	3	ORL	Data addr,#data
1B	1	DEC	R3	44	2	ORL	A,#data
1C	1	DEC	R4	45	2	ORL	A,data addr
1D	1	DEC	R5	46	1	ORL	A,@R0
1E	1	DEC	R6	47	1	ORL	A,@R1
1F	1	DEC	R7	48	1	ORL	A,R0
20	3	JB	Bit addr,code addr	49	1	ORL	A,R1
21	2	AJMP	Code addr	4A	1	ORL	A,R2
22	1	RET		4B	1	ORL	A,R3
23	1	RL	A	4C	1	ORL	A,R4
24	2	ADD	A,#data	4D	1	ORL	A,R5
25	2	ADD	A,data addr	4E	1	ORL	A,R6
26	1	ADD	A,@R0	4F	1	ORL	A,R7
27	1	ADD	A,@R1	50	2	JNC	Code addr
28	1	ADD	A,R0	51	2	ACALL	Code addr

Hex Code	Bytes	Mnemonic	Operands	Hex Code	Bytes	Mnemonic	Operands
52	2	ANL	Data addr,A	AA	2	MOV	R2,data addr
53	3	ANL	Data addr,#data	AB	2	MOV	R3,data addr
54	2	ANL	A,#data	AC	2	MOV	R4,data addr
55	2	ANL	A,data addr	AD	2	MOV	R5,data addr
56	1	ANL	A,@R0	AE	2	MOV	R6,data addr
57	1	ANL	A,@R1	AF	2	MOV	R7,data addr
58	1	ANL	A,R0	B0	2	ANL	C,/bit addr
59	1	ANL	A,R1	B1	2	ACALL	Code addr
5A	1	ANL	A,R2	B2	2	CPL	Bit addr
5B	1	ANL	A,R3	B3	1	CPL	C
5C	1	ANL	A,R4	B4	3	CJNE	A,#data,code addr
5D	1	ANL	A,R5	B5	3	CJNE	A,data addr,code addr
5E	1	ANL	A,R6	B6	3	CJNE	@R0,#data,code addr
5F	1	ANL	A,R7	B7	3	CJNE	@R1,#data,code addr
60	2	JZ	Code addr	B8	3	CJNE	R0,#data,code addr
61	2	AJMP	Code addr	B9	3	CJNE	R1,#data,code addr
62	2	XRL	Data addr,A	BA	3	CJNE	R2,#data,code addr
63	3	XRL	Data addr,#data	BB	3	CJNE	R3,#data,code addr
64	2	XRL	A,#data	BC	3	CJNE	R4,#data,code addr
65	2	XRL	A,data addr	BD	3	CJNE	R5,#data,code addr
66	1	XRL	A,@R0	BE	3	CJNE	R6,#data,code addr
67	1	XRL	A,@R1	BF	3	CJNE	R7,#data,code addr
68	1	XRL	A,R0	C0	2	PUSH	Data addr
6A	1	XRL	A,R2	C1	2	AJMP	Code addr
6B	1	XRL	A,R3	C2	2	CLR	Bit addr
6C	1	XRL	A,R4	C3	1	CLR	C
6D	1	XRL	A,R5	C4	1	SWAP	A
6E	1	XRL	A,R6	C5	2	XCH	A,data addr
6F	1	XRL	A,R7	C6	1	XCH	A,@R0
70	2	JNZ	Code addr	C7	1	XCH	A,@R1
71	2	ACALL	Code addr	C8	1	XCH	A,R0
72	2	ORL	C,bit addr	C9	1	XCH	A,R1
73	1	JMP	@A + DPTR	CA	1	XCH	A,R2
74	2	MOV	A,#data	CB	1	XCH	A,R3
75	3	MOV	Data addr,#data	CC	1	XCH	A,R4
76	2	MOV	@R0,#data	CD	1	XCH	A,R5
77	2	MOV	@R1,#data	CE	1	XCH	A,R6
78	2	MOV	R0,#data	CF	1	XCH	A,R7
79	2	MOV	R1,#data	D0	2	POP	Data addr
7A	2	MOV	R2,#data	D1	2	ACALL	Code addr
7B	2	MOV	R3,#data	D2	2	SETB	Bit addr
7C	2	MOV	R4,#data	D3	1	SETB	C
7D	2	MOV	R5,#data	D4	1	DA	A
7E	2	MOV	R6,#data	D5	3	DJNZ	Data addr,code addr
7F	2	MOV	R7,#data	D6	1	XCHD	A,@R0
80	2	SJMP	Code addr	D7	1	XCHD	A,@R1
81	2	AJMP	Code addr	D8	2	DJNZ	R0,code addr
82	2	ANL	C,bit addr	D9	2	DJNZ	R1,code addr
83	1	MOVC	A,@A + PC	DA	2	DJNZ	R2,code addr
84	1	DIV	AB	DB	2	DJNZ	R3,code addr
85	3	MOV	Data addr,data addr	DC	2	DJNZ	R4,code addr
86	2	MOV	Data addr,@R0	DD	2	DJNZ	R5,code addr
87	2	MOV	Data addr,@R1	DE	2	DJNZ	R6,code addr
88	2	MOV	Data addr,R0	DF	2	DJNZ	R7,code addr
89	2	MOV	Data addr,R1	E0	1	MOVX	A,@DPTR
8A	2	MOV	Data addr,R2	E1	2	AJMP	Code addr
8B	2	MOV	Data addr,R3	E2	1	MOVX	A,@R0
8C	2	MOV	Data addr,R4	E3	1	MOVX	A,@R1
8D	2	MOV	Data addr,R5	E4	1	CLR	A
8E	2	MOV	Data addr,R6	E5	2	MOV	A,data addr
8F	2	MOV	Data addr,R7	E6	1	MOV	A,@R0
90	3	MOV	DPTR,#data	E7	1	MOV	A,@R1
91	2	ACALL	Code addr	E8	1	MOV	A,R0
92	2	MOV	Bit addr,C	E9	1	MOV	A,R1
93	1	MOVC	A,@A + DPTR	EA	1	MOV	A,R2
94	2	SUBB	A,#data	EB	1	MOV	A,R3
95	2	SUBB	A,data addr	EC	1	MOV	A,R4
96	1	SUBB	A,@R0	ED	1	MOV	A,R5
97	1	SUBB	A,@R1	EE	1	MOV	A,R6
98	1	SUBB	A,R0	EF	1	MOV	A,R7
99	1	SUBB	A,R1	F0	1	MOVX	@DPTR,A
9A	1	SUBB	A,R2	F1	2	ACALL	Code addr
9B	1	SUBB	A,R3	F2	1	MOVX	@R0,A
9C	1	SUBB	A,R4	F3	1	MOVX	@R1,A
9D	1	SUBB	A,R5	F4	1	CPL	A
9E	1	SUBB	A,R6	F5	2	MOV	Data addr,A
9F	1	SUBB	A,R7	F6	1	MOV	@R0,A
A0	2	ORL	C,/bit addr	F7	1	MOV	@R1,A
A1	2	AJMP	Code addr	F8	1	MOV	R0,A
A2	2	MOV	C,bit addr	F9	1	MOV	R1,A
A3	1	INC	DPTR	FA	1	MOV	R2,A
A4	1	MUL	AB	FB	1	MOV	R3,A
A5		Reserved		FC	1	MOV	R4,A
A6	2	MOV	@R0,data addr	FD	1	MOV	R5,A
A7	2	MOV	@R1,data addr	FE	1	MOV	R6,A
A8	2	MOV	R0,data addr	FF	1	MOV	R7,A
A9	2	MOV	R1,data addr				

80C541

CMOS Single-Chip Microcontroller

ADVANCE INFORMATION

DISTINCTIVE CHARACTERISTICS

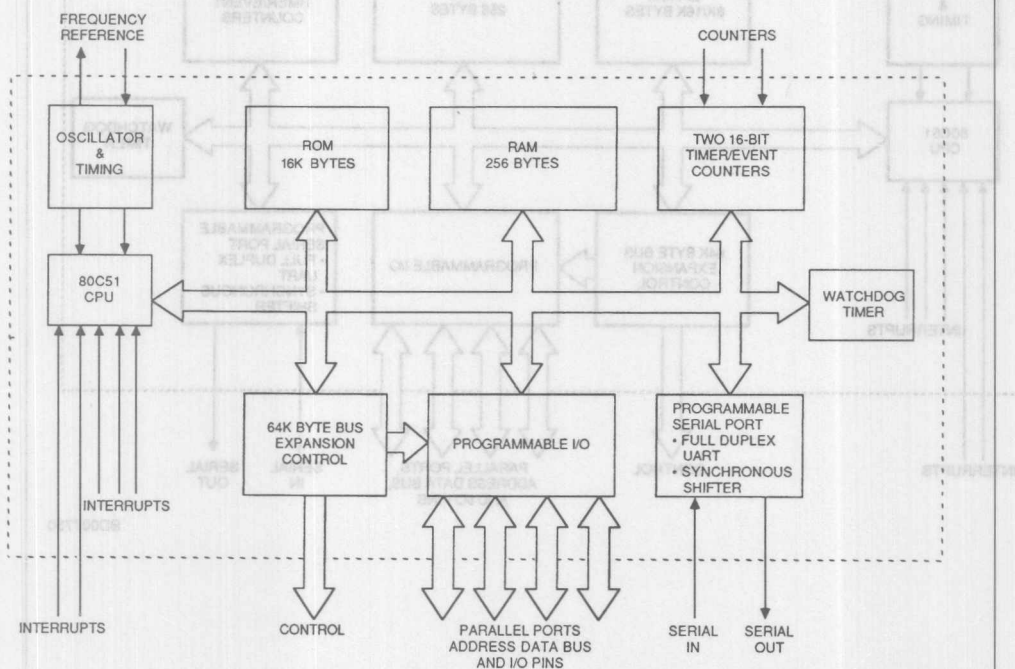
- CMOS extensions to the 80C51
- 256 Bytes of RAM
- 16K Bytes of ROM
- Programmable Watchdog Timer
- Dual Data Pointers
- Software Reset
- All Original 80C51 Features Are Retained
 - 32 I/O Lines
 - Two 16-Bit Timer/Counters
 - Five Source, Two Level Interrupt
 - 64K Bytes Program Memory Space
 - Full-Duplex Serial Port
 - Power-Down & Idle Modes
 - On-Chip Oscillator/Clock Circuit
 - 64K Bytes Data Memory Space

GENERAL DESCRIPTION

The 80C541 Microcontroller is a fully instruction-set-compatible and pin-compatible enhancement of the 80C51. The 80C541 contains 16K bytes of ROM, 256 bytes of RAM, a programmable Watchdog Timer, and Dual Data Pointers. The Watchdog Timer can be programmed to times ranging from 128 microseconds to four full seconds at 12 MHz.

The Dual Data Pointer structure speeds access to external memory by providing two identical 16-bit data pointers with a fast switching mechanism, rather than a single data pointer as in the rest of the 8051 Family. The 80C541 is available in a 40-pin DIP and a 44-pin PLCC.

SIMPLIFIED BLOCK DIAGRAM



BD007212

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10-25

Publication #	Rev.	Amendment
10100	A	/0
Issue Date: January 1988		

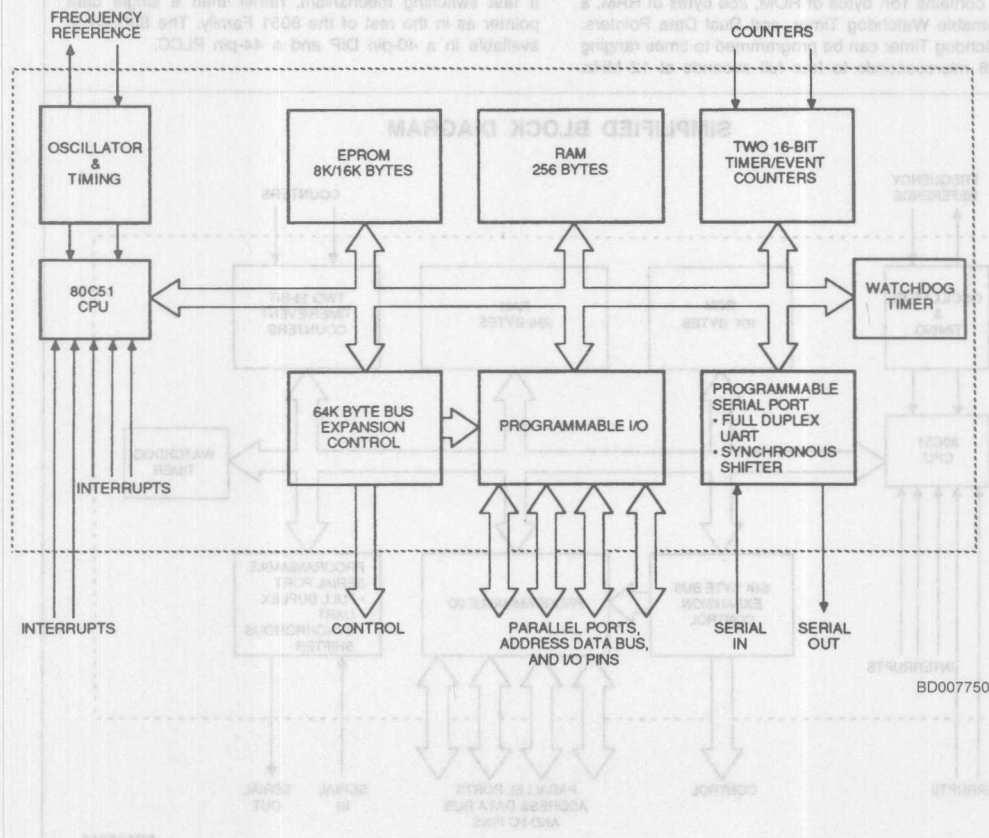
87C521/87C541

Single-Chip 8-Bit Microcontroller with
8K/16K Bytes of EPROM
ADVANCE INFORMATION

DISTINCTIVE CHARACTERISTICS

- CMOS EPROM versions of the 80C521
- 8K/16K bytes of EPROM
- All 80C521 features are retained:
 - 256 bytes of RAM
 - Programmable Watchdog Timer
 - Dual Data Pointers
 - Software Reset
- Flashrite™ EPROM programming
- Two-level Program Memory Lock
- 32-Byte Encryption Array
- Fuse-selectable Watchdog options
- ONCE Mode facilitates system testing
- Pin-compatible with the 80C521/80C541/80C51
- All original 80C51 features are retained:
 - 32 I/O lines
 - Two 16-bit Timer/Counters
 - Five-source, two-level interrupt
 - 64K bytes Program Memory space
 - Full-duplex serial port
 - Power-Down and Idle modes
 - On-chip oscillator/clock circuit
 - 64K bytes Data Memory space

BLOCK DIAGRAM



BD007750

Flashrite is a trademark of Advanced Micro Devices, Inc.

GENERAL DESCRIPTION

The 87C521/87C541 are the CMOS EPROM versions of the 80C521 Microcontroller. The 87C521 contains 8K bytes of EPROM memory, and the 87C541 contains 16K bytes of EPROM memory. The parts are fully pin-compatible with the 80C521 and retain all features of the 80C521. Their only difference is the amount of EPROM memory they contain.

The 87C521/87C541 EPROM array features a Flashrite programming algorithm that allows the 8K/16K-byte EPROM array to be programmed in about 24 and 48 seconds, respectively. A two-level programmable lock structure provides security by preventing externally fetched code from accessing internal program memory, and by disabling EPROM verification and programming. A 32-byte Encryption Array can be used to encrypt the program code bytes read during EPROM verification.

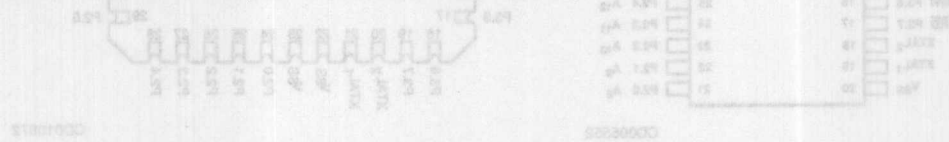
Like the 80C521, the 87C521/87C541 features a programmable Watchdog Timer, 256 bytes of RAM, Dual Data Pointers, and Software Reset. A full description of these features is

contained in the 80C521 data sheet and in the AMD Microcontroller Handbook.

The Watchdog Timer can be programmed for times ranging from 128 microseconds to 4 seconds at 12 MHz. In addition, the 87C521/87C541 contain fuses which can be programmed to increase the reliability of the Watchdog Timer for use in extremely harsh environments. These options allow the Watchdog Timer to be "fixed-on," and its time value to be "hardwired."

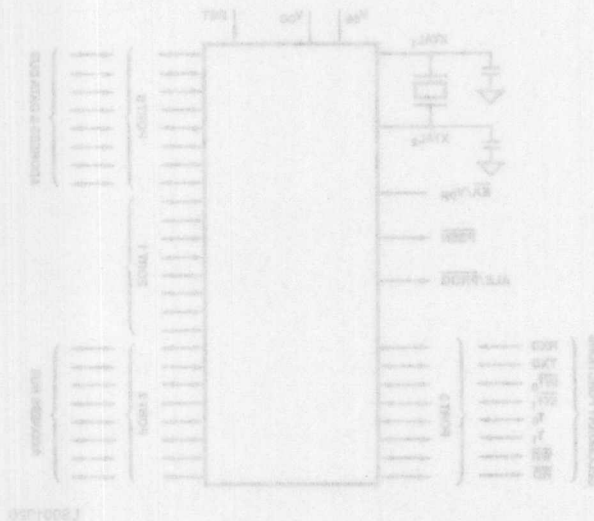
The Dual Data Pointer structure speeds access to external memory by providing two identical 16-bit data pointers with a fast switching mechanism, rather than a single data pointer as in the rest of the 8051 family. A Software Reset mechanism is also provided.

All original features of the 80C51 are retained. For functional details of these features, consult the 8051 Family Architecture chapter in the AMD Microcontroller Handbook (Order No. 09757A).



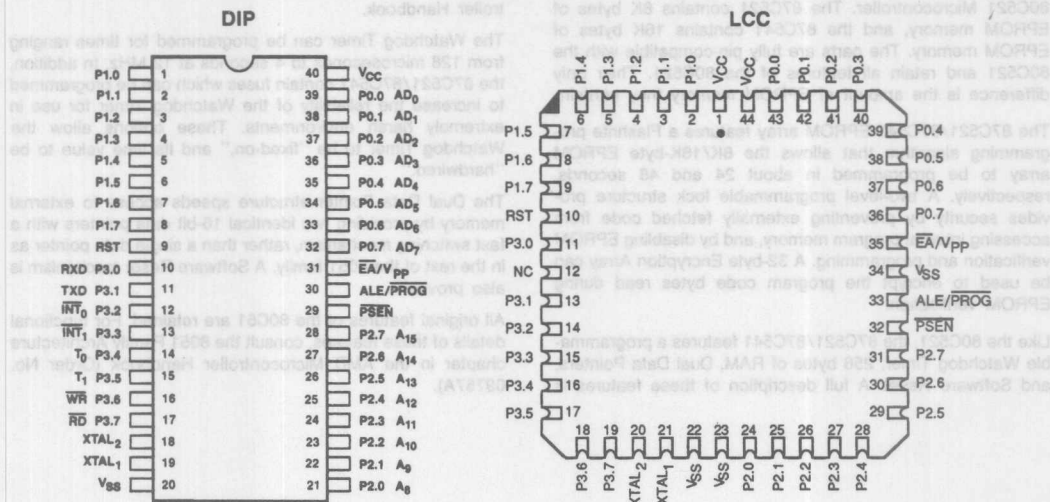
Note: Pin 1 is marked for orientation.

LOGIC SYMBOL



CONNECTION DIAGRAMS

Top View

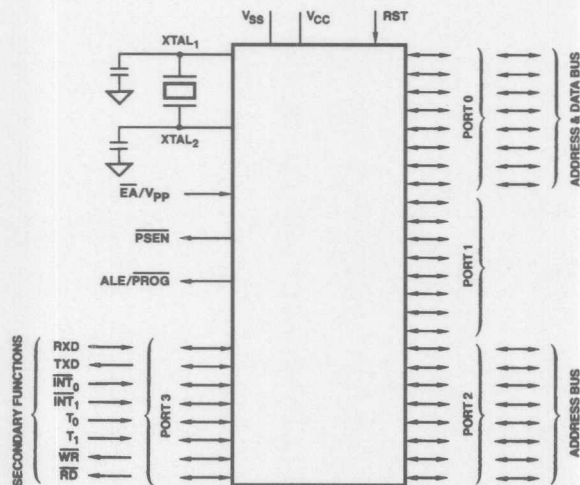


CD005552

CD010872

Note: Pin 1 is marked for orientation.

LOGIC SYMBOL



LS001326

PIN DESCRIPTION

Port 0 (Bidirectional; Open Drain)

Port 0 is an open-drain I/O port. Port 0 pins that have "1"s written to them float, and in that state can be used as high-impedance inputs.

Port 0 is also the multiplexed low-order address and data bus during accesses to external Program and Data Memory. In this application it uses strong internal pullups when emitting "1"s. Port 0 also outputs the code bytes during program verification in the 87C521/87C541. External pullups are required during program verification.

Port 1 (Bidirectional)

Port 1 is an 8-bit bidirectional I/O port with internal pullups. The Port 1 output buffers can sink/source four LS TTL inputs. Port 1 pins that have "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 1 pins that are externally being pulled LOW will source current (I_{IL} on the data sheet) because of the internal pullups.

Port 1 also receives the low-order address bytes during program verification.

Port 2 (Bidirectional)

Port 2 is an 8-bit bidirectional I/O port with internal pullups. The Port 2 output buffers can sink/source four LS TTL inputs. Port 2 pins having "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 2 pins externally being pulled LOW will source current (I_{IL}) because of internal pullups.

Port 2 emits the high-order address byte during fetches from external Program Memory and during accesses to external Data Memory that use 16-bit addresses (MOVX @DPTR). In this application it uses strong internal pullups when emitting "1"s. During accesses to external Data Memory that use 8-bit addresses (MOVX @Ri), Port 2 emits the contents of the P2 Special Function register.

Port 2 also receives the high-order address bits during the programming of the EPROM and during program verification of the EPROM, as well as some control signals.

Port 3 (Bidirectional)

Port 3 is an 8-bit bidirectional I/O port with internal pullups. The Port 3 output buffers can sink/source four LS TTL inputs. Port 3 pins having "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 3 pins externally being pulled LOW will source current (I_{IL}) because of the pullups. Port 3 also receives some control signals for EPROM programming and program verification.

Port 3 also serves the functions of various special features as listed below:

Port Pin	Alternate Function
P _{3.0}	RxD (Serial Input Port)
P _{3.1}	TxD (Serial Output Port)
P _{3.2}	INT ₀ (External Interrupt 0)
P _{3.3}	INT ₁ (External Interrupt 1)
P _{3.4}	T ₀ (Timer 0 External Input)
P _{3.5}	T ₁ (Timer 1 External Input)
P _{3.6}	WR (External Data Memory Write Strobe)
P _{3.7}	RD (External Data Memory Read Strobe)

RST Reset (Input; Active HIGH)

This pin is used to reset the device when held HIGH for two machine cycles while the oscillator is running. A small internal resistor permits power-on reset using only a capacitor connected to V_{CC}.

ALE/PROG Address Latch Enable/Program Pulse (Input/Output)

Address Latch Enable output pulse for latching the low byte of the address during accesses to external memory. ALE can drive eight LS TTL inputs.

In normal operation ALE is emitted at a constant rate of 1/6 the oscillator frequency, allowing use for external-timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external Data Memory. This pin also accepts the program pulse input (PROG) when programming the EPROM.

PSEN Program Store Enable (Output; Active LOW)

PSEN is the read strobe to external Program Memory. PSEN can drive eight LS TTL inputs. When the device is executing code from an external program memory, PSEN is activated twice each machine cycle — except that two PSEN activations are skipped during each access to external Data Memory. PSEN is not activated during fetches from internal Program Memory.

EA/Vpp External Access Enable/Programming Voltage (Input; Active LOW)

EA must be externally held LOW to enable the device to fetch code from external Program Memory locations 0000H to 1FFFFH for the 87C521 and 3FFFFH for the 87C541. If EA is held HIGH, the 87C521/87C541 executes from internal Program Memory unless the program counter exceeds 1FFFFH and 3FFFFH respectively.

This pin also receives the 12.75-V programming supply voltage during programming of the EPROM.

XTAL₁ Crystal (Input)

Input to the inverting-oscillator amplifier, and input to the internal clock-generator circuits.

XTAL₂ Crystal (Output)

Output of the inverting-oscillator amplifier.

VCC Power Supply

Power supply during normal, idle, and power-down operations.

VSS Circuit Ground

PROGRAMMING

The 87C521/87C541 can be programmed with the Flashrite algorithm. It differs from other methods in the value used for V_{pp} (programming supply voltage) and in the width and number of the ALE/PROG pulses.

To program the EPROM, either the internal or external oscillator must be running between 4 and 6 MHz, since the internal bus is used to transfer address and program data to the appropriate internal registers. Table 1 shows the various EPROM programming modes.

TABLE 1. EPROM PROGRAMMING MODES FOR THE 87C521/87C541

Mode	RST	PSEN	ALE/PROG	EA/V _{pp}	P2.7	P2.6	P3.7	P3.6
Program Code	H	L	L*	V _{pp}	H	L	H	H
Verify Code	H	L	H	V _{ppX}	L	L	H	H
Pgm Encryption Table	H	L	L*	V _{pp}	H	L	H	L
Pgm Lock Bit 1	H	L	L*	V _{pp}	H	H	H	H
Pgm Lock Bit 2	H	L	L*	V _{pp}	H	H	L	L
Read Silicon Signature	H	L	H	H	L	L	L	L
Watchdog Fuse Program	H	L	L	V _{pp}	H	H	L	H
Watchdog Fuse Verify	H	L	H	H	L	H	L	H

Key: H = Logic HIGH for that pin

L = Logic LOW for that pin

$V_{pp} = 12.75 \text{ V} \pm 0.25 \text{ V}$

$V_{CC} = 5 \text{ V} \pm 10\%$ during programming and verification

$2.0 \text{ V} < V_{ppX} < 13.0 \text{ V}$

*ALE/PROG receives 25 programming pulses while V_{pp} is held at 12.75 V. Each programming pulse is low for 100 μs ($\pm 10\%$ μs) and high for a minimum of 10 μs .

Programming

The programming configuration for the 87C521 is shown in Figure 1. The address of the EPROM location to be programmed is applied to Ports 1 and 2 as shown in the figure. The programming configuration of the 87C541 is identical except that P2.5 is also used as an address input. The code byte to be programmed into that location is applied to Port 0. Once RST, PSEN, Port 2, and Port 3 are held to the levels

indicated in Figure 1, ALE/PROG is pulsed low 25 times as shown in Figure 2.

The maximum voltage applied to the EA/V_{pp} pin must not exceed 13 V at any time as specified for V_{pp} . Even a slight spike can cause permanent damage to the device. The V_{pp} source should thus be well regulated and glitch-free.

When programming, a 0.1 μF capacitor is required across V_{pp} and ground to suppress spurious transients which may damage the device.

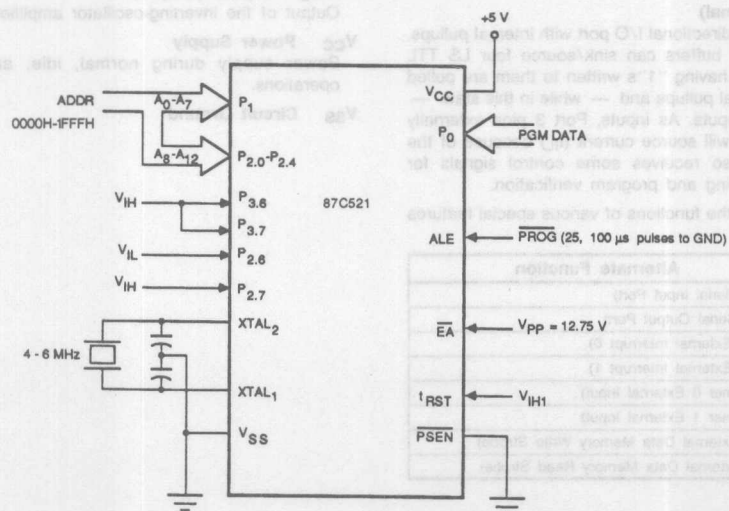


Figure 1. 87C521 Programming Configuration

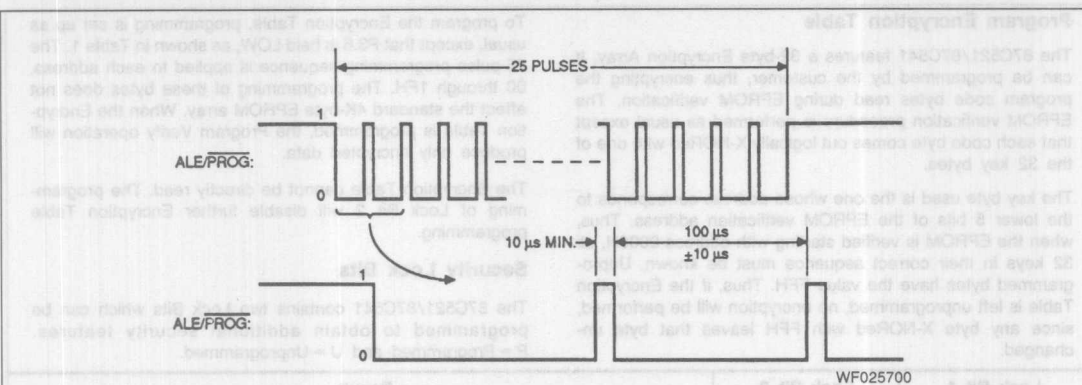


Figure 2. PROG Waveforms

Program Verification

The 87C521/87C541 provides a method of reading the programmed code bytes in the EPROM array for program verification. This function is possible as long as Lock Bit 2 has not been programmed.

For program verification, the address of the Program Memory location to be read is applied to Ports 1 and 2 as shown in

Figure 3. Verification of the 87C541 is identical except that P2.5 is also used as an address input. Once RST, PSEN, Port 2, and Port 3 are held to the levels indicated, the contents of the addressed location will be emitted on Port 0. External pullups are required on Port 0 for this operation. The EPROM programming and verification waveforms provide further details.

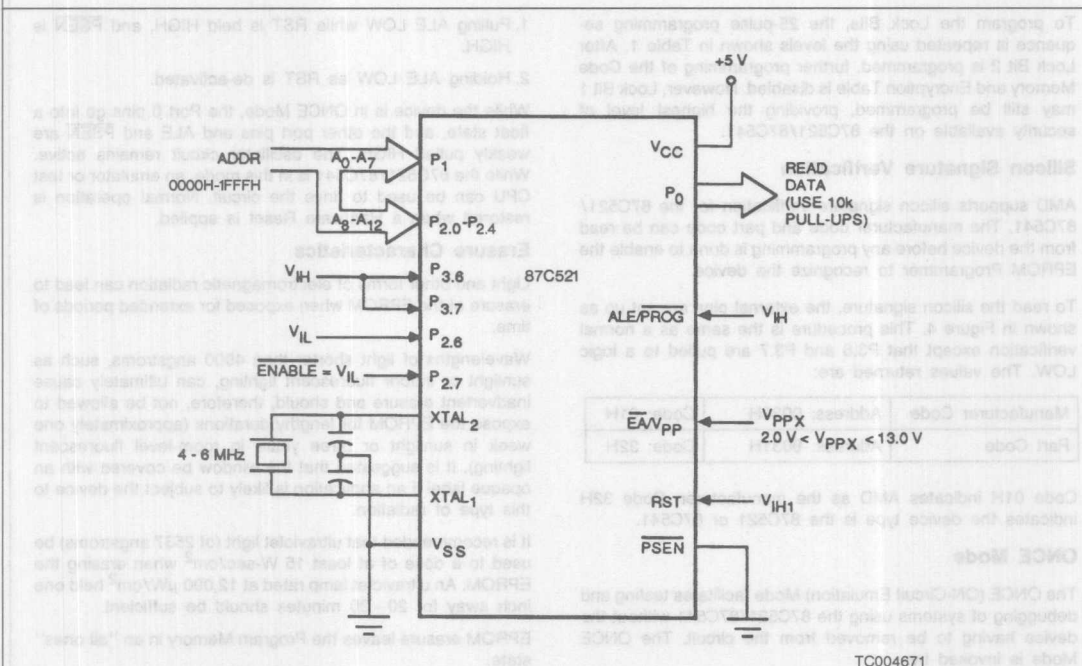


Figure 3. 87C521 Program Verification

Program Encryption Table

The 87C521/87C541 features a 32-byte Encryption Array. It can be programmed by the customer, thus encrypting the program code bytes read during EPROM verification. The EPROM verification procedure is performed as usual except that each code byte comes out logically X-NORed with one of the 32 key bytes.

The key byte used is the one whose address corresponds to the lower 5 bits of the EPROM verification address. Thus, when the EPROM is verified starting with address 0000H, all 32 keys in their correct sequence must be known. Unprogrammed bytes have the value FFH. Thus, if the Encryption Table is left unprogrammed, no encryption will be performed, since any byte X-NORed with FFH leaves that byte unchanged.

Lock Bit 1	Lock Bit 2	Result
U	U	Normal Operation
U	P	<ul style="list-style-type: none">Externally fetched code cannot access internal Program MemoryAll further Programming disabled (except Lock Bit 1)
P	U	Reserved
P	P	<ul style="list-style-type: none">Externally fetched code cannot access internal Program MemoryAll further Programming disabledProgram Verification disabled

To program the Lock Bits, the 25-pulse programming sequence is repeated using the levels shown in Table 1. After Lock Bit 2 is programmed, further programming of the Code Memory and Encryption Table is disabled. However, Lock Bit 1 may still be programmed, providing the highest level of security available on the 87C521/87C541.

Silicon Signature Verification

AMD supports silicon signature verification for the 87C521/87C541. The manufacturer code and part code can be read from the device before any programming is done to enable the EPROM Programmer to recognize the device.

To read the silicon signature, the external pins are set up as shown in Figure 4. This procedure is the same as a normal verification except that P3.6 and P3.7 are pulled to a logic LOW. The values returned are:

Manufacturer Code	Address: 0030H	Code: 01H
Part Code	Address: 0031H	Code: 32H

Code 01H indicates AMD as the manufacturer. Code 32H indicates the device type is the 87C521 or 87C541.

ONCE Mode

The ONCE (ON-Circuit Emulation) Mode facilitates testing and debugging of systems using the 87C521/87C541 without the device having to be removed from the circuit. The ONCE Mode is invoked by:

To program the Encryption Table, programming is set up as usual, except that P3.6 is held LOW, as shown in Table 1. The 25-pulse programming sequence is applied to each address, 00 through 1FH. The programming of these bytes does not affect the standard 4K-byte EPROM array. When the Encryption Table is programmed, the Program Verify operation will produce only encrypted data.

The Encryption Table cannot be directly read. The programming of Lock Bit 2 will disable further Encryption Table programming.

Security Lock Bits

The 87C521/87C541 contains two Lock Bits which can be programmed to obtain additional security features. P = Programmed and U = Unprogrammed.

1. Pulling ALE LOW while RST is held HIGH, and PSEN is HIGH.

2. Holding ALE LOW as RST is de-activated.

While the device is in ONCE Mode, the Port 0 pins go into a float state, and the other port pins and ALE and PSEN are weakly pulled HIGH. The oscillator circuit remains active. While the 87C521/87C541 is in this mode, an emulator or test CPU can be used to drive the circuit. Normal operation is restored when a Hardware Reset is applied.

Erase Characteristics

Light and other forms of electromagnetic radiation can lead to erasure of the EPROM when exposed for extended periods of time.

Wavelengths of light shorter than 4000 angstroms, such as sunlight or indoor fluorescent lighting, can ultimately cause inadvertent erasure and should, therefore, not be allowed to expose the EPROM for lengthy durations (approximately one week in sunlight or three years in room-level fluorescent lighting). It is suggested that the window be covered with an opaque label if an application is likely to subject the device to this type of radiation.

It is recommended that ultraviolet light (of 2537 angstroms) be used to a dose of at least 15 W-sec/cm² when erasing the EPROM. An ultraviolet lamp rated at 12,000 μ W/cm² held one inch away for 20–30 minutes should be sufficient.

EPROM erasure leaves the Program Memory in an "all ones" state.

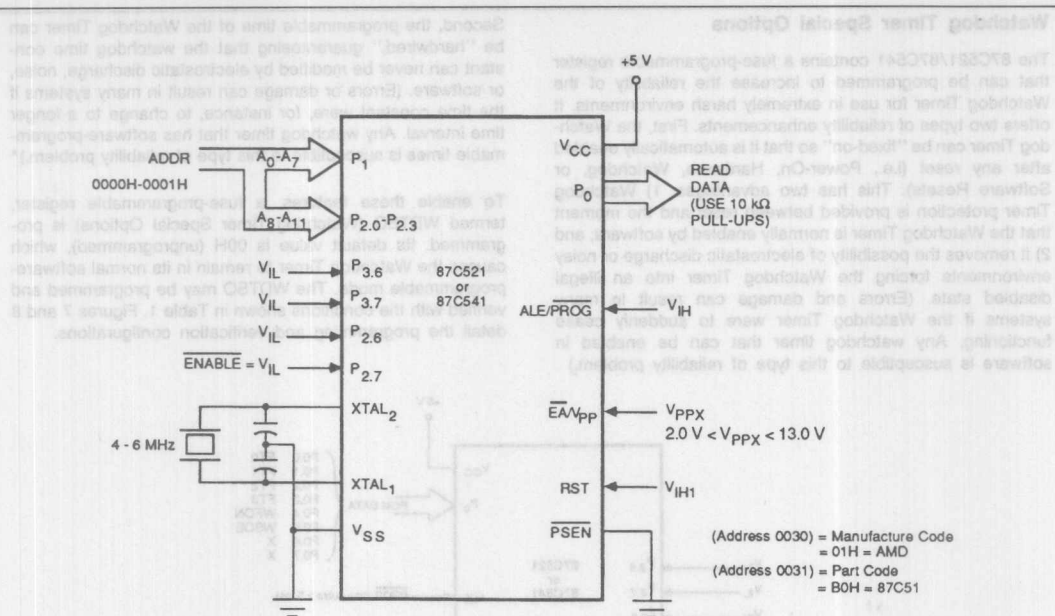


Figure 4. 87C521/87C541 Silicon Signature Verification Configuration

Oscillator Characteristics

XTAL₁ and XTAL₂ are the input and output, respectively, of an inverting amplifier which is configured for use as an on-chip oscillator (see Figure 5). Either a quartz crystal or ceramic resonator may be used.

To drive the device from an external clock source, XTAL₁ should be driven while XTAL₂ is left unconnected (see Figure 6). There are no requirements on the duty cycle of the external clock signal since the input to the internal clocking circuitry is through a divide-by-two flip-flop, but minimum and maximum HIGH and LOW times specified on the data sheet must be observed.

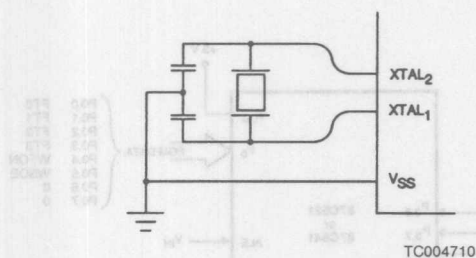


Figure 5. Crystal Oscillator

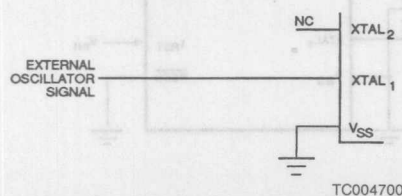


Figure 6. External Drive Configuration

Watchdog Timer Special Options

The 87C521/87C541 contains a fuse-programmable register that can be programmed to increase the reliability of the Watchdog Timer for use in extremely harsh environments. It offers two types of reliability enhancements. First, the Watchdog Timer can be "fixed-on" so that it is automatically enabled after any reset (i.e., Power-On, Hardware, Watchdog, or Software Resets). This has two advantages: 1) Watchdog Timer protection is provided between reset and the moment that the Watchdog Timer is normally enabled by software; and 2) it removes the possibility of electrostatic discharge or noisy environments forcing the Watchdog Timer into an illegal disabled state. (Errors and damage can result in many systems if the Watchdog Timer were to suddenly cease functioning. Any watchdog timer that can be enabled in software is susceptible to this type of reliability problem.)

Second, the programmable time of the Watchdog Timer can be "hardwired," guaranteeing that the watchdog time constant can never be modified by electrostatic discharge, noise, or software. (Errors or damage can result in many systems if the time constant were, for instance, to change to a longer time interval. Any watchdog timer that has software-programmable times is susceptible to this type of reliability problem.)*

To enable these features, a fuse-programmable register, termed WDTSO (Watchdog Timer Special Options) is programmed. Its default value is 00H (unprogrammed), which causes the Watchdog Timer to remain in its normal software-programmable mode. The WDTSO may be programmed and verified with the conditions shown in Table 1. Figures 7 and 8 detail the programming and verification configurations.

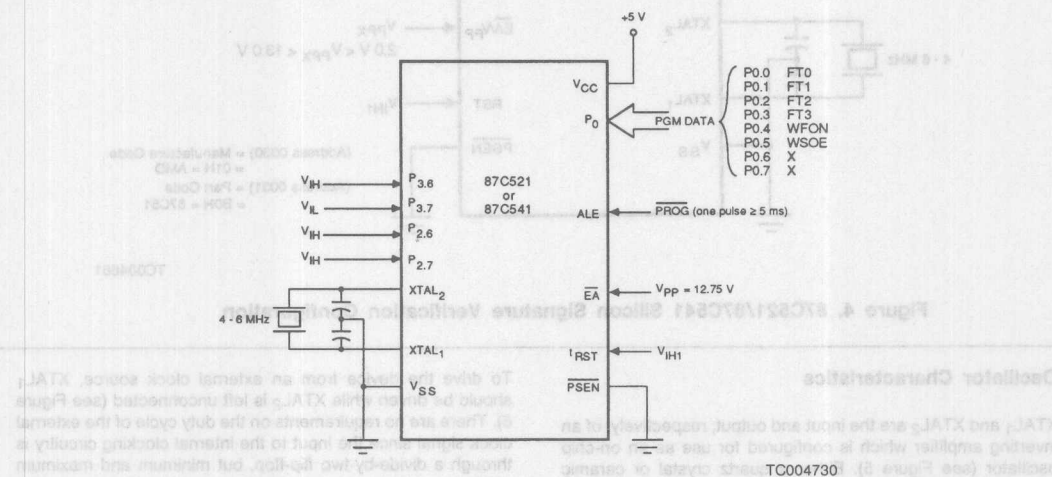


Figure 7. 87C521/87C541 Programming of Watchdog Timer Special Options

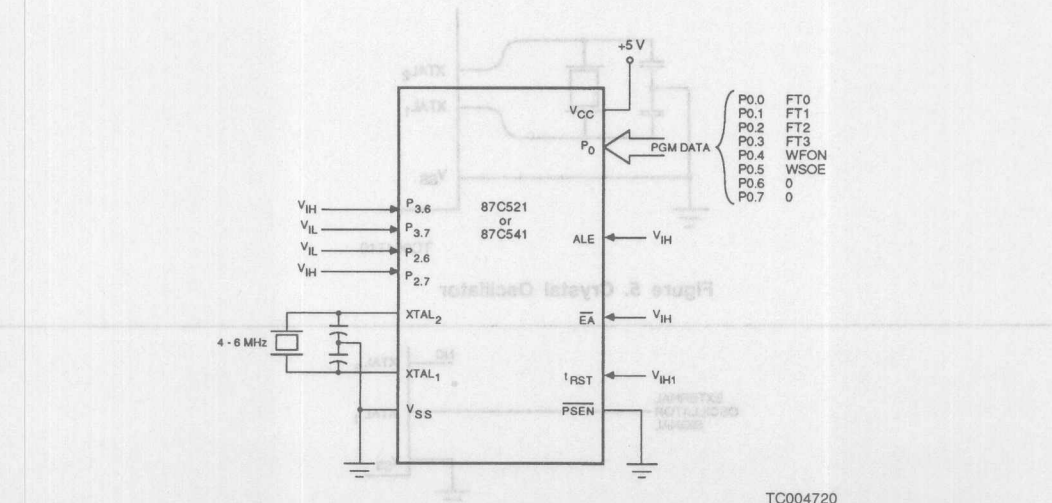


Figure 8. 87C521/87C541 Verification of Watchdog Timer Special Options

*The above conditions are not meant to imply that all software-programmable watchdog timers have identical reliability characteristics. In fact, software-programmable watchdog timers can vary considerably in their degree of reliability based on how well they protect the system from software problems; not just

protection from infinite loops, but more malicious conditions such as execution off instruction boundaries that can set off any number of unexpected events.

Since the WDTSO is fuse-programmed, it is not erasable. The Lock Bits do not affect the programming or verification of the WDTSO.

Watchdog Timer Special Options:

0	0	WSOE	WFON	FT3	FT2	FT1	FT0
7	6	5	4	3	2	1	0

Bits 3-0 Fixed Times 3-0 (FT3-FT0)

If WSOE is programmed, these fuse bits determine the time constant that is hardwired into the Watchdog Timer. The 16 possible values correspond to those of bits PT3-PT0 in the

Watchdog Selection (WDS) register, allowing fixed times from 128 μ s to 4 seconds at 12 MHz. Other times are possible depending on the clock frequency. (See the 80C521 data sheet for full information on the Watchdog Timer.)

If WSOE is programmed, the value in these fuse bits may be read by software via bits PT3-PT0 in the WDS register. (Bits PT3-PT0 in WDS cannot be written if WSOE is programmed.)

From a software standpoint, with WSOE programmed and WFON unprogrammed, the Watchdog Timer will operate exactly as normal except that the PT3-PT0 bits can never be modified.

Fuse-Programmable Watchdog Timer Timing Intervals

FT3-FT0	12 MHz	8 MHz	Clock Divide Ratio
0 0000	128 μ s	192 μ s	1536
1 0001	256 μ s	384 μ s	3072
2 0010	512 μ s	768 μ s	6144
3 0011	1.024 ms	1.536 ms	12288
4 0100	2.048 ms	3.072 ms	24576
5 0101	4.096 ms	6.144 ms	49152
6 0110	8.192 ms	12.288 ms	98304
7 0111	16.384 ms	24.576 ms	196608
8 1000	32.768 ms	49.152 ms	393216
9 1001	65.536 ms	98.304 ms	786432
A 1010	131.072 ms	196.608 ms	1572864
B 1011	262.144 ms	393.216 ms	3145728
C 1100	524.288 ms	786.432 ms	6291456
D 1101	1.049 sec.	1.573 ms	12582912
E 1110	2.097 sec.	3.146 sec.	25165824
F 1111	4.194 sec.	6.292 sec.	50331648

Bit 4 Watchdog Fixed-ON (WFON)

If WSOE is programmed, this fuse bit causes the Watchdog Timer to be permanently enabled. The Watchdog Timer will begin incrementing at the beginning of the first instruction cycle after reset (whether or not valid code is executing).

From a software standpoint, a "fixed-on" Watchdog Timer operates identically to the normal Watchdog Timer that has previously been enabled by software. The WDS register is then read-only, and the Watchdog Timer may be "cleared" but never disabled. To clear the Watchdog Timer, the standard A5-5A sequence is written to WDK (see the 80C521 data sheet for full information). If any reset condition occurs, the Watchdog Timer will be cleared, yet it will remain enabled after the reset is complete. The fact that the Watchdog Timer is fixed-on may be determined from software. In this case, bit 6 of the WDS register will always read as a 1.

If WFON is programmed, the fuse bits FT3-FT0 must be programmed to the desired time constant, since software will be unable to modify any of the programmed time bits PT3-PT0 in WDS while the Watchdog Timer is enabled.

WFON permanently disables Power-Down mode and prevents the Power-Down (PD) bit in PCON from being set. Idle mode may still be entered in the usual way; however, the Watchdog Timer continues to increment in Idle mode.

Bit 5 Watchdog Special Options Enable (WSOE)

This bit enables the fuse options of the Watchdog Timer. When set, bits FT3-FT0 will determine the fixed time in the WDT, and the WFON bit will determine whether the Watchdog Timer is enabled immediately after any reset. If this bit is not programmed, the programming of WFON or FT3-FT0 will have no effect.

WSOE	WFON	FT3-FT0	Comments
0	X	XXXX	WDT is normal mode.
1	0	ABCD	WDT is disabled at Reset, but time is fixed by the ABCD fuse bits.
1	1	ABCD	WDT is enabled at Reset, and time is fixed by the ABCD fuse bits.
Register not programmed			WDT in normal mode.

Bits 7-6

Reserved. Will return 0 during verification.

ABSOLUTE MAXIMUM RATINGS

Storage Temperature -65 to +150°C
 Voltage on EA/V_{PP} Pin to V_{SS} -0.5 to +13.0 V
 Voltage on V_{CC} to V_{SS} -0.5 to +6.5 V
 Voltage on Any Other Pin to V_{SS} -0.5 to +6.5 V
 Power Dissipation 200 mW

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A) 0 to +70°C
 Supply Voltage (V_{CC}) +4.5 to +5.5 V
 Ground (V_{SS}) 0 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

DC CHARACTERISTICS over operating range

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Unit
V _{IL}	Input LOW Voltage (Except EA)		-0.5	0.2 V _{CC} - 0.1	V
V _{IL1}	Input LOW Voltage (EA)		0	0.2 V _{CC} - 0.3	V
V _{IH}	Input HIGH Voltage (Except XTAL ₁ , RST)		0.2 V _{CC} + 0.9	V _{CC} + 0.5	V
V _{IH1}	Input HIGH Voltage to XTAL ₁ , RST		0.7 V _{CC}	V _{CC} + 0.5	V
V _{OL}	Output LOW Voltage (Ports 1, 2, 3)	I _{OL} = 1.6 mA (Note 1)		0.45	V
V _{OL1}	Output LOW Voltage (Port 0, ALE, PSEN)	I _{OL} = 3.2 mA (Note 1)		0.45	V
V _{OH}	Output HIGH Voltage (Ports 1, 2, 3), ALE, PSEN	I _{OH} = -60 µA, V _{CC} = 5 V ± 10%	2.4		V
		I _{OH} = -10 µA	0.9 V _{CC}		
V _{OH1}	Output HIGH Voltage (Port 0 in External Bus Mode)	I _{OH} = -800 µA, V _{CC} = 5 V ± 10%	2.4		V
		I _{OH} = -80 µA (Note 2)	0.9 V _{CC}		
I _{IL}	Logical 0 Input Current (Ports 1, 2, 3)	V _{IN} = 0.45 V		-50	µA
I _{TL}	Logical 1-to-0 Transition Current (Ports 1, 2, 3)	(Note 3)		-650	µA
I _{LI}	Input Leakage Current (Port 0)	V _{IN} = V _{IL} or V _{IH}		±10	µA
I _{CC}	Power Supply Current: Active Mode @ 12 MHz (Note 4) Idle Mode @ 12 MHz (Note 4) Power-Down Mode	(Note 5)		25 4	mA
RRST	Reset Pulldown Resistor		50	300	kΩ
C _{IO}	Pin Capacitance	Test Freq = 1 MHz, T _A = 25°C		10	pF

Notes: 1. Capacitive loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL}s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1-to-0 transitions during bus operations. In the worst cases (capacitive loading > 100 pF), the noise pulse on the ALE line may exceed 0.8 V. In such cases it may be desirable to qualify ALE with a Schmitt Trigger, or use an address latch with a Schmitt Trigger STROBE input.

2. Capacitive loading on Ports 0 and 2 may cause the V_{OH} on ALE and PSEN to momentarily fall below the 0.9 V_{CC} specification when the address bits are stabilizing.

3. Pins of Ports 1, 2, and 3 source a transition current when they are being externally driven from 1 to 0. The transition current reaches its maximum value when V_{IN} is approximately 2 V.

4. I_{CCMAX} at other frequencies is given by:

Active Mode: I_{CCMAX} = 0.94 x Freq + 13.71

Idle Mode: I_{CCMAX} = 0.14 x Freq + 2.31

where Freq is the external oscillator frequency in MHz. I_{CCMAX} is given in mA.

5. Active Mode I_{CC} is measured with all output pins disconnected; XTAL₁ driven with TCLCH, TCHCL = 5 ns, V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5 V; XTAL₂ N.C.; EA = RST = Port 0 = V_{CC}.

Idle Mode I_{CC} is measured with all output pins disconnected; XTAL₁ driven with TCLCH, TCHCL = 5 ns, V_{IL} = V_{SS} + 0.5 V, V_{IH} = V_{CC} - 0.5 V; XTAL₂ = N.C.; Port 0 = V_{CC}; EA = RST = V_{SS}.

Power-Down Mode I_{CC} is measured with all outputs pins disconnected; EA = Port 0 = V_{CC}; XTAL₂ N.C.; RST = V_{SS}.

SWITCHING CHARACTERISTICS over operating range (Load Capacitance for Port 0, ALE, and PSEN = 100 pF, Load Capacitance for All Other Outputs = 80 pF)

Parameter Symbol	Parameter Description	12-MHz Osc.		Variable Oscillator		Unit
		Min.	Max.	Min.	Max.	
1/TCLCL	Oscillator Frequency			3.5	12	MHz
TLHLL	ALE Pulse Width	127		2TCLCL-40		ns
TAVLL	Address Valid to ALE LOW	28		TCLCL-55		ns
TLLAX	Address Hold After ALE LOW	48		TCLCL-35		ns
TLLIV	ALE LOW to Valid Instr. In		234		4TCLCL-100	ns
TLLPL	ALE LOW to PSEN LOW	43		TCLCL-40		ns
TPLPH	PSEN Pulse Width	205		3TCLCL-45		ns
TPDIV	PSEN LOW to Valid Instr. In		145		3TCLCL-105	ns
TPXIX	Input Instr. Hold After PSEN	0		0		ns
TPXIZ	Input Instr. Float After PSEN		59		TCLCL-25	ns
TAVIV	Address to Valid Instr. In		312		5TCLCL-105	ns
TPLAZ	PSEN LOW to Address Float		10		10	ns
TRLRH	RD Pulse Width	400		6TCLCL-100		ns
TWLWH	WR Pulse Width	400		6TCLCL-100		ns
TRLDV	RD LOW to Valid Data In		252		5TCLCL-165	ns
TRHDX	Data Hold After RD	0		0		ns
TRHDZ	Data Float After RD		97		2TCLCL-70	ns
TLLDV	ALE LOW to Valid Data In		517		8TCLCL-150	ns
TAVDV	Address to Valid Data In		585		9TCLCL-165	ns
TLLWL	ALE LOW to RD or WR LOW	200	300	3TCLCL-50	3TCLCL+50	ns
TAVWL	Address Valid to RD or WR LOW	203		4TCLCL-130		ns
TQVWX	Data Valid to WR Transition	23		TCLCL-60		ns
TQVWH	Data Valid to WR HIGH	433		7TCLCL-150		ns
TWHQX	Data Hold After WR	33		TCLCL-50		ns
TRLAZ	RD LOW to Address Float		0		0	ns
TWHLH	RD or WR HIGH to ALE HIGH	43	123	TCLCL-40	TCLCL+40	ns

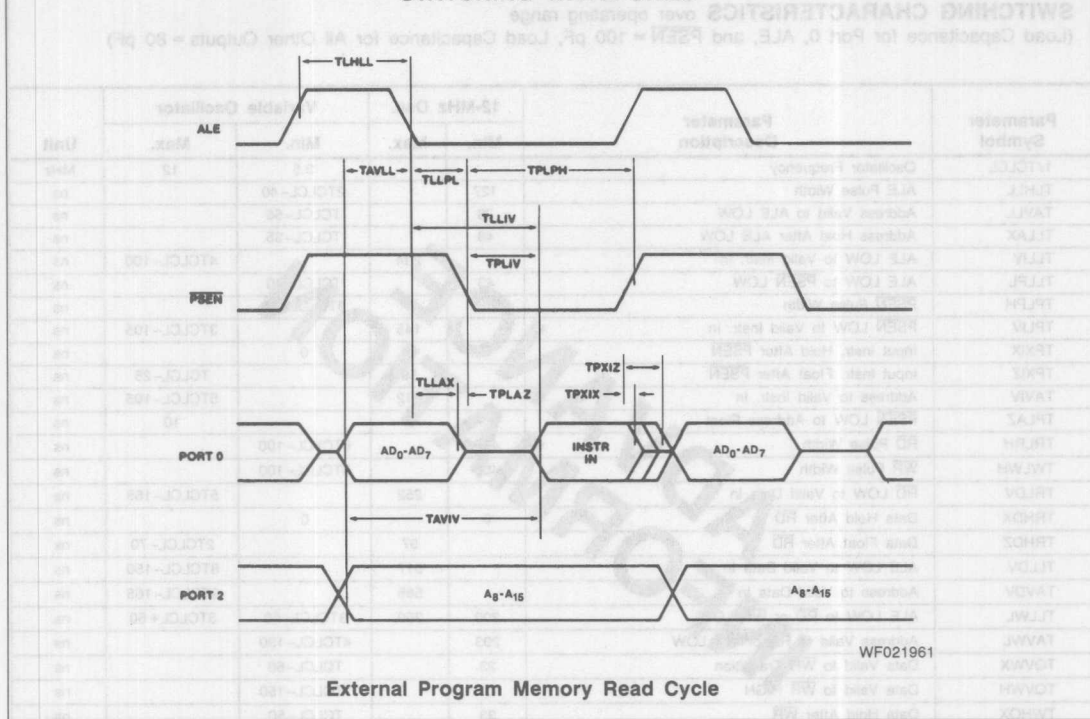
SWITCHING WAVEFORMS

KEY TO SWITCHING WAVEFORMS

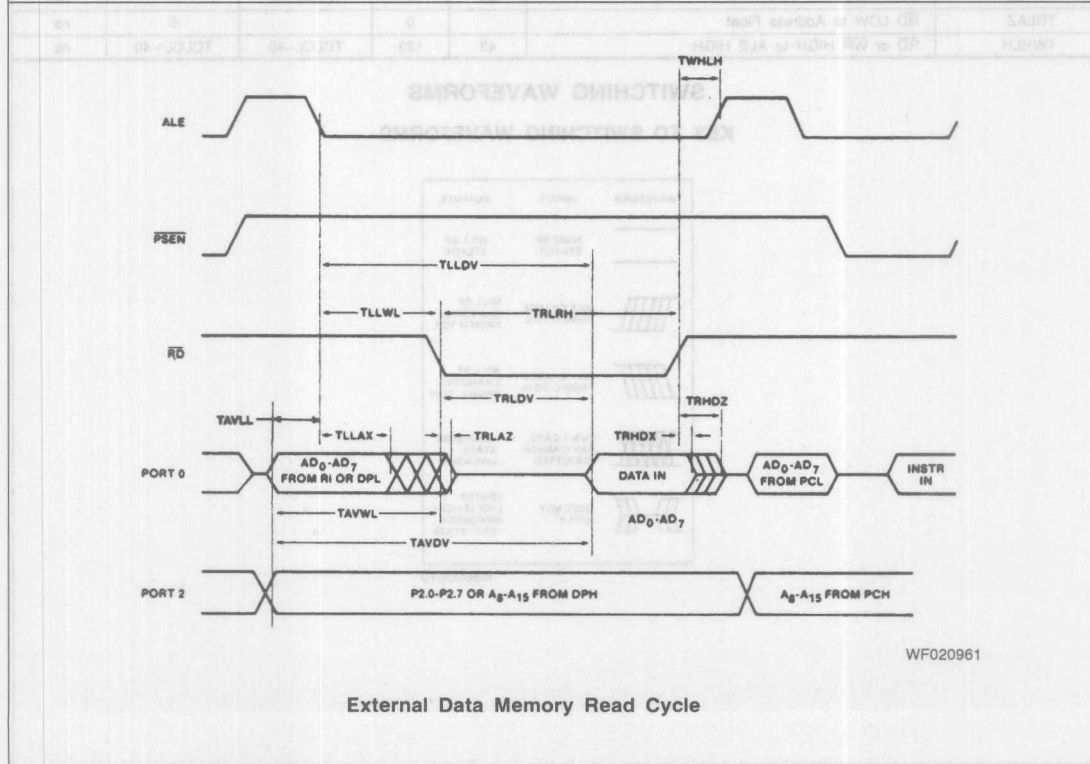
WAVEFORM	INPUTS	OUTPUTS
	MUST BE STEADY	WILL BE STEADY
	MAY CHANGE FROM H TO L	WILL BE CHANGING FROM H TO L
	MAY CHANGE FROM L TO H	WILL BE CHANGING FROM L TO H
	DON'T CARE, ANY CHANGE PERMITTED	CHANGING, STATE UNKNOWN
	DOES NOT APPLY	CENTER LINE IS HIGH IMPEDANCE "OFF" STATE

KS000010

SWITCHING WAVEFORMS

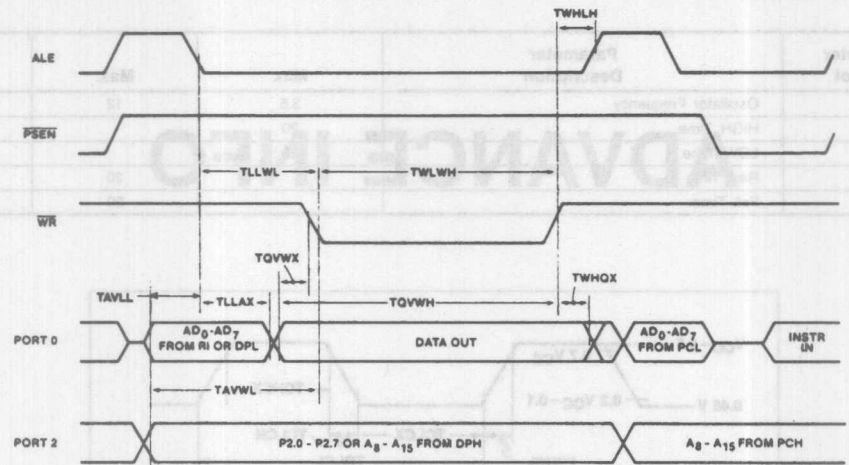


External Program Memory Read Cycle



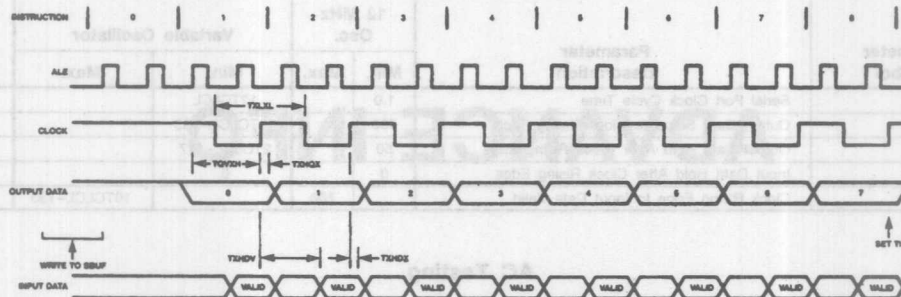
External Data Memory Read Cycle

SWITCHING WAVEFORMS (Cont'd)



WF020931

External Data Memory Write Cycle

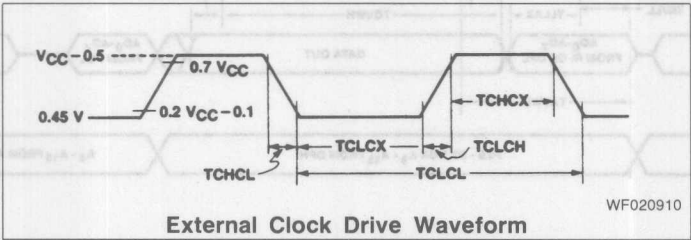


WF020950

Shift Register Timing Waveforms

EXTERNAL CLOCK DRIVE

Parameter Symbol	Parameter Description	Min.	Max.	Unit
1/TCLCL	Oscillator Frequency	3.5	12	MHz
TCHCX	HIGH Time	20		ns
TCLCX	LOW Time	20		ns
TCLCH	Rise Time		20	ns
TCHCL	Fall Time		20	ns

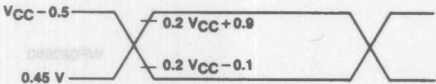


SERIAL PORT TIMING — SHIFT REGISTER MODE

(Test Conditions: $T_A = 0$ to $+70^{\circ}C$; $V_{CC} = 5 V \pm 10\%$; $V_{SS} = 0 V$; Load Capacitance = 80 pF)

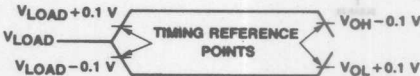
Parameter Symbol	Parameter Description	12 MHz Osc.		Variable Oscillator		Unit
		Min.	Max.	Min.	Max.	
TXLXL	Serial Port Clock Cycle Time	1.0		12TCLCL		μs
TQVXH	Output Data Setup to Clock Rising Edge	700		10TCLCL-133		ns
TXHQX	Output Data Hold After Clock Rising Edge	50		2TCLCL-117		ns
TXHDX	Input Data Hold After Clock Rising Edge	0		0		ns
TXHDV	Clock Rising Edge to Input Data Valid		700		10TCLCL-133	ns

AC Testing



AC INPUTS DURING TESTING ARE DRIVEN AT $V_{CC} - 0.5$ FOR A LOGIC "1" AND $0.45 V$ FOR A LOGIC "0." TIMING MEASUREMENTS ARE MADE AT V_{IH} MIN. FOR A LOGIC "1" AND V_{IL} MAX. FOR A LOGIC "0."

Input/Output Waveform



FOR TIMING PURPOSES A PORT PIN IS NO LONGER FLOATING WHEN A 100 mV CHANGE FROM LOAD VOLTAGE OCCURS, AND BEGINS TO FLOAT WHEN A 100 mV CHANGE FROM THE LOADED V_{OH}/V_{OL} LEVEL OCCURS. $I_{OL}/I_{OH} \geq \pm 20$ mA.

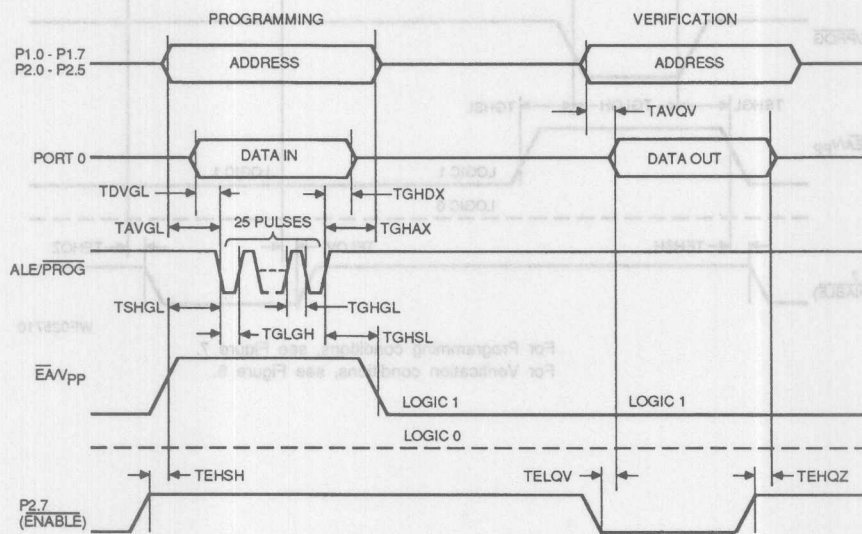
Float Waveform

EPROM PROGRAMMING AND VERIFICATION CHARACTERISTICS

(T_A = +21 to +27°C)

Parameter Symbol	Parameter Description	Min.	Max.	Unit
V _{pp}	Programming Supply Voltage	12.5	13.0	V
I _{pp}	Programming Supply Current		50	mA
1/TCLCL	Oscillator Frequency	4	6	MHz
TAVGL	Address Setup to PROG	48TCLCL		
TGHAX	Address Hold After PROG	48TCLCL		
TDVGL	Data Setup to PROG	48TCLCL		
TGHDX	Data Hold After PROG	48TCLCL		
TEHSH	P _{2.7} (ENABLE) HIGH to V _{pp}	48TCLCL		
TSHGL	V _{pp} Setup to PROG	10		μs
TGHSL	V _{pp} Hold after PROG	10		μs
TGLGH	PROG Width	90	110	μs
TAVQV	Address to Data Valid		48TCLCL	
TELQV	ENABLE to Data Valid		48TCLCL	
TEHQZ	Data Float After ENABLE	0	48TCLCL	
TGHGL	PROG HIGH to PROG LOW	10		μs

EPROM PROGRAMMING AND VERIFICATION WAVEFORMS



WF025692

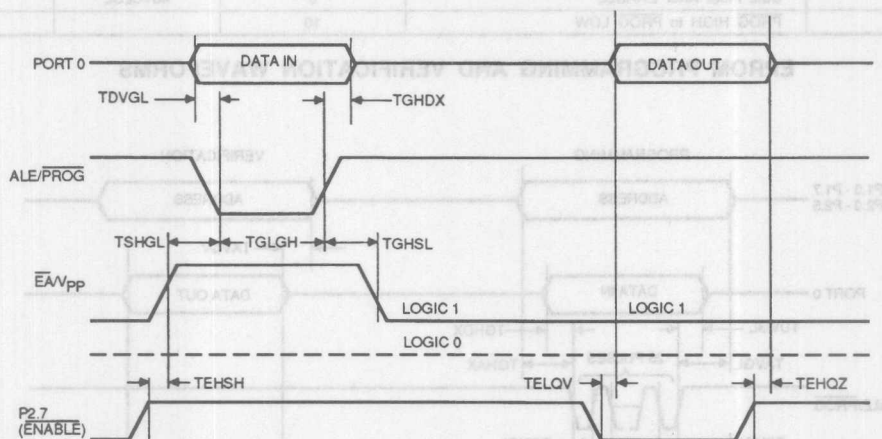
For Programming conditions, see Figures 1 and 2.
For Verification conditions, see Figure 3.

WATCHDOG TIMER FUSE PROGRAMMING AND VERIFICATION CHARACTERISTICS

(T_A = +21 to +27°C)

Parameter Symbol	Parameter Description	Min.	Max.	Unit
V _{pp}	Programming Supply Voltage	12.5	13.0	V
I _{pp}	Programming Supply Current		50	mA
1/TCLCL	Oscillator Frequency	4	6	MHz
TDVGL	Data Setup to PROG	48TCLCL		
TGHDX	Data Hold After PROG	48TCLCL		
TEHSH	P _{2.7} (ENABLE) HIGH to V _{pp}	48TCLCL		
TSHGL	V _{pp} Setup to PROG	10		μs
TGHSL	V _{pp} Hold after PROG	10		μs
TGLGH	PROG Width	5		ms
TELQV	ENABLE to Data Valid		48TCLCL	
TEHQZ	Data Float After ENABLE	0	48TCLCL	
TGHGL	PROG HIGH to PROG LOW	10		μs

WATCHDOG TIMER FUSE PROGRAMMING AND VERIFICATION WAVEFORMS



WF025710

For Programming conditions, see Figure 7.
For Verification conditions, see Figure 8.

80C525/80C325

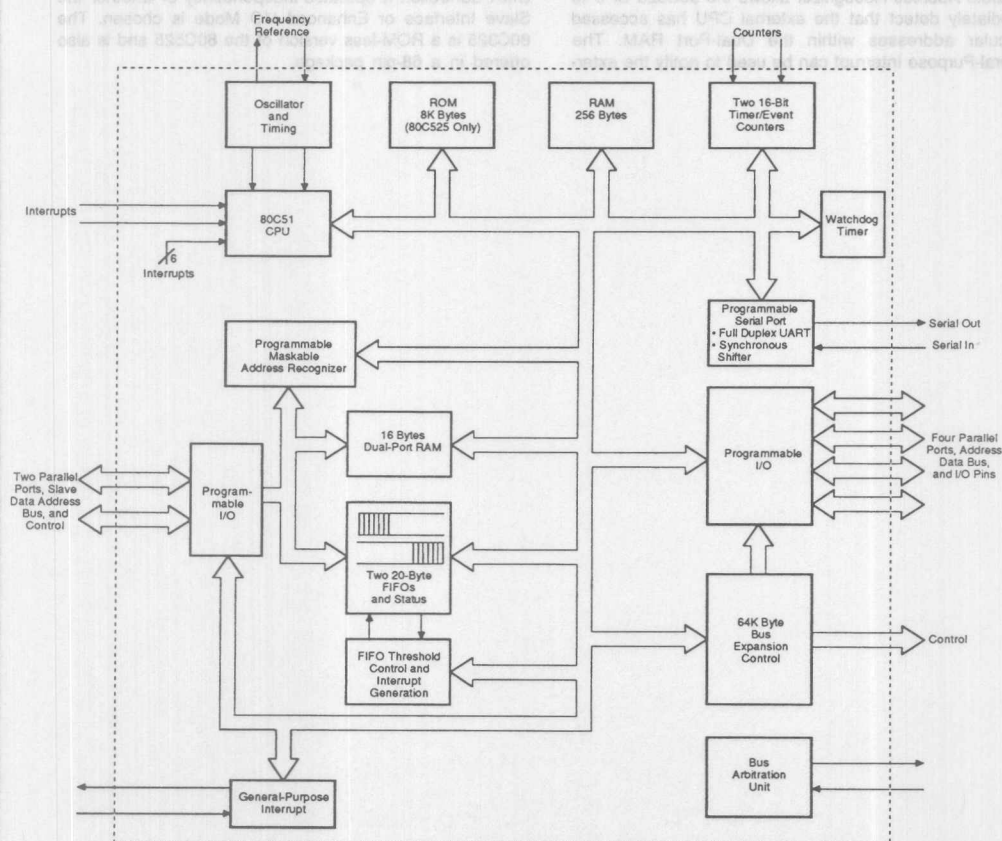
CMOS Single-Chip Microcontroller

ADVANCE INFORMATION

DISTINCTIVE CHARACTERISTICS

- CMOS Extensions to the 80C521 and 80C51
- Slave Interface:
 - 16 bytes of Dual-Port RAM
 - Two 20-byte FIFOs
 - DMA Request and Interrupt Support provided
 - Programmable Maskable Address Recognizer
 - General-Purpose Interrupt (output)
- 6 1/2 total ports on-chip in Enhanced I/O Mode
- Bus Arbitration Unit
- 8 Interrupt Sources
- 80C325 is the ROM-less version of the 80C525
- 68-Pin Package
- All original 80C521 features retained:
 - 8K Bytes of ROM
 - 256 Bytes of RAM
 - Programmable Watchdog Timer
 - Dual Data Pointers
 - Software Reset
 - Two 16-bit Timer/Event Counters
 - Boolean Processor
 - 16-MHz operation
 - 64K bytes Program Memory space
 - 64K bytes Data Memory space

BLOCK DIAGRAM



BD007740

This document contains information on a product under development at Advanced Micro Devices, Inc. The information is intended to help you to evaluate this product. AMD reserves the right to change or discontinue work on this proposed product without notice.

10-43

Publication # 09766
Rev. A
Amendment /0
Issue Date: February 1988

GENERAL DESCRIPTION

The 80C525 Microcontroller is an instruction-set-compatible, functional superset of the 80C521 Microcontroller which is itself a superset of the 80C51. The 80C525 excels at processor-to-processor communication. Using the Slave Interface — which contains 16 bytes of Dual-Port RAM, two 20-byte FIFOs, and interrupt control logic — the 80C525 can easily become a slave peripheral to another processor such as the 80286, 80186, or the 8051. Furthermore, using the Bus Arbitration Unit, the 80C525 can also share its system bus with another processor or DMA controller. The 80C525 can also function in an Enhanced I/O Mode with 6 1/2 ports on-chip if the Slave Interface is not used.

All features of the 80C521 and 80C51 are retained, including 8K bytes of ROM, 256 bytes of RAM, a programmable Watchdog Timer, Dual Data Pointers, Software Reset, two 16-bit Timer/Event Counters, Boolean Processor, and Serial Port.

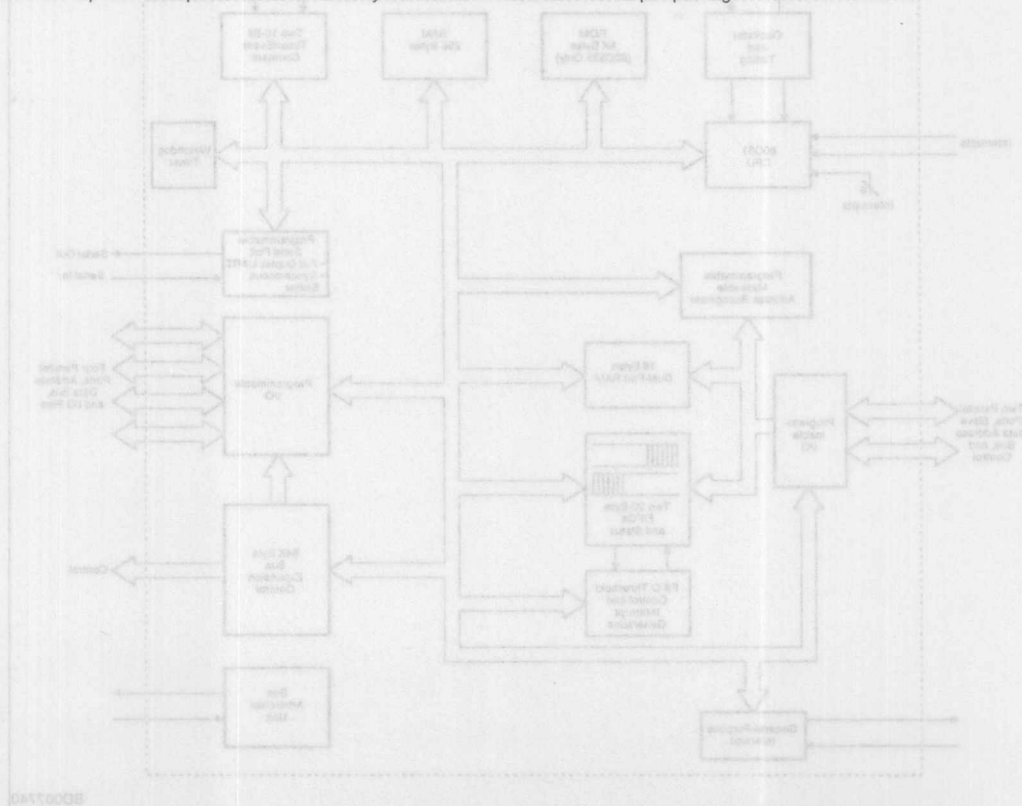
The Interrupt control logic associated with the Slave Interface provides fast, efficient methods of signaling both the 80C525 CPU and an external CPU. The Programmable Maskable Address Recognizer allows the 80C525 CPU to immediately detect that the external CPU has accessed particular addresses within the Dual-Port RAM. The General-Purpose Interrupt can be used to notify the exter-

nal CPU that data or status is available in the Dual-Port RAM or FIFOs.

The FIFOs support both programmed and interrupt-driven I/O. Support for external DMA transfers to and from the FIFOs is also provided. Additionally, full threshold-level detection is provided for each FIFO in order to match the latency of the 80C525 CPU to that of the external CPU or DMA Controller.

The Slave Interface does not use any I/O pins associated with the four original ports on the 80C521, thus leaving these ports available to the 80C525 CPU. If specific functions within the Slave Interface are not needed, the associated pins can be made available for I/O. For applications not requiring the Slave Interface, 2 1/2 ports become available for general I/O. For instance, these ports may be used to replace Ports 0 and 2 which are lost when external ROM is required. The additional ports are functionally equivalent to the standard ports on the 80C51.

The 80C525 also contains a Bus Arbitration Unit that allows the 80C525 CPU to share an external system bus (accessed via Port 0 and Port 2) with another processor or DMA Controller. It operates independently of whether the Slave Interface or Enhanced I/O Mode is chosen. The 80C325 is a ROM-less version of the 80C525 and is also offered in a 68-pin package.



PIN DESCRIPTION

Port 0 (Bidirectional, Open Drain)

Port 0 is an open-drain bidirectional I/O port. Port 0 pins that have "1"s written to them float, and in that state can be used as high-impedance inputs.

Port 0 is also the multiplexed LOW-order address and data bus during accesses to external Program and Data Memory. In this application it uses strong internal pullups when emitting "1"s. Port 0 also outputs the code bytes during program verification in the 80C525. External pullups are required during program verification.

Port 1 (Bidirectional)

Port 1 is an 8-bit bidirectional I/O port with internal pullups. The Port 1 output buffers can sink/source four LSTTL inputs. Port 1 pins that have "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 1 pins that are externally being pulled LOW will source current (I_{IL} on the data sheet) because of the internal pullups.

Port 1 also receives the LOW-order address bytes during program verification.

Port 2 (Bidirectional)

Port 2 is an 8-bit bidirectional I/O port with internal pullups. The Port 2 output buffers can sink/source four LSTTL inputs. Port 2 pins having "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 2 pins externally being pulled LOW will source current (I_{IL}) because of the internal pullups.

Port 2 emits the HIGH-order address byte during fetches from external Program Memory and during accesses to external Data Memory that use 16-bit addresses (MOVX @DPTR). In this application it uses strong internal pullups when emitting "1"s. During accesses to external data memory that use 8-bit addresses (MOVX @Ri), Port 2 emits the contents of the P2 Special Function Register. Port 2 also receives the HIGH-order address bits during ROM verification.

Port 3 (Bidirectional)

Port 3 is an 8-bit bidirectional I/O port with internal pullups. The Port 3 output buffers can sink/source four LSTTL inputs. Port 3 pins that have "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 3 pins externally being pulled LOW will source current (I_{IL}) because of the pullups.

Port 3 also serves the functions of various special features as listed below:

Port Pin	Alternate Function
P _{3.0}	RxD (serial input port)
P _{3.1}	TxD (serial output port)
P _{3.2}	INT ₀ (external interrupt 0)
P _{3.3}	INT ₁ (external interrupt 1)
P _{3.4}	T ₀ (Timer 0 external input)
P _{3.5}	T ₁ (Timer 1 external input)
P _{3.6}	WR (external Data Memory write strobe)
P _{3.7}	RD (external Data Memory read strobe)

Port 4 (Bidirectional)

Port 4 is an 8-bit bidirectional I/O port with internal pullups. The Port 4 buffers can sink/source four LSTTL inputs. Port 4 pins that have "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used

as inputs. As inputs, Port 4 pins externally being pulled LOW will source current (I_{IL}) because of the pullups.

Port 4 also serves the functions of special features as listed below:

Port Pin	Alternate Function
P _{4.0}	D ₀ Slave Data 0
P _{4.1}	D ₁ Slave Data 1
P _{4.2}	D ₂ Slave Data 2
P _{4.3}	D ₃ Slave Data 3
P _{4.4}	D ₄ Slave Data 4
P _{4.5}	D ₅ Slave Data 5
P _{4.6}	D ₆ Slave Data 6
P _{4.7}	D ₇ Slave Data 7

Port 5 (Bidirectional)

Port 5 is an 8-bit bidirectional I/O port with internal pullups. The Port 5 buffers can sink/source four LSTTL inputs. Port 5 pins that have "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 5 pins externally being pulled LOW will source current (I_{IL}) because of the pullups.

Port 5 also serves the functions of special features as listed below:

Port Pin	Alternate Function
P _{5.0}	A ₀ Slave Address 0
P _{5.1}	A ₁ Slave Address 1
P _{5.2}	A ₂ Slave Address 2
P _{5.3}	A ₃ Slave Address 3
P _{5.4}	A ₄ Slave Address 4
P _{5.5}	CS Chip Select
P _{5.6}	SWR Slave Write Strobe
P _{5.7}	SRD Slave Read Strobe

Port 6 (Bidirectional)

Port 6 is a 6-bit bidirectional I/O port with internal pullups. The Port 6 buffers can sink/source four LSTTL inputs. Port 6 pins that have "1"s written to them are pulled HIGH by the internal pullups and — while in this state — can be used as inputs. As inputs, Port 6 pins externally being pulled LOW will source current (I_{IL}) because of the pullups.

Port 6 also serves the functions of special features as listed below:

Port Pin	Alternate Function
P _{6.0}	EFREQ/EFINT Export FIFO DMA Request/Interrupt
P _{6.1}	IFREQ/IFINT Import FIFO DMA Request/Interrupt
P _{6.2}	GPI General-Purpose Interrupt
P _{6.3}	GPIACK General-Purpose Interrupt Acknowledge
P _{6.4}	DACK DMA Acknowledge

SLAVE/PORTS Slave/Ports (Input, Active LOW)

A HIGH value on this pin during the falling edge of the RST pin during a Hardware or Power-on Reset will cause Ports 4, 5, and 6 pins to take on their alternate Slave Interface

functions. A LOW value causes the pins to take on their port functions.

HOLD Hold (Input, Active HIGH)

A HIGH value on this pin requests that the 80C525 enter Hold mode. A LOW value allows the 80C525 to exit Hold mode.

HOLDA Hold Acknowledge (Output, Active HIGH)

A HIGH value on this pin indicates that the 80C525 has entered Hold mode. A LOW value on this pin indicates that the 80C525 has exited HOLD mode.

RST Reset (Input/Output, Active HIGH)

A HIGH on this pin — for two machine cycles while the oscillator is running — resets the device. An internal diffused resistor to V_{SS} permits power-on reset, using only an external capacitor to V_{CC} .

Immediately prior to a Watchdog Reset or Software Reset, this pin is pulled HIGH for one state time. The internal pull-up can be overdriven by an external driver capable of sinking/sourcing 2.5 mA.

ALE Address Latch Enable (Output, Active HIGH)

Address Latch output pulse for latching the LOW byte of the address during accesses to external memory.

In normal operation ALE is emitted at a constant rate of 1/6 the oscillator frequency, allowing use for external-timing or clocking purposes. Note, however, that one ALE pulse is skipped during each access to external Data Memory.

Port Pin	Alternate Function
P0.0	A0 Slave Address 0
P0.1	A1 Slave Address 1
P0.2	A2 Slave Address 2
P0.3	A3 Slave Address 3
P0.4	A4 Slave Address 4
P0.5	CS (Chip Select)
P0.6	SWR Slave Write Strobe
P0.7	SRD Slave Read Strobe

Port 0 is a 8-bit bidirectional I/O port with internal pullups. The Port 0 buffers can sink/source four LSTTL inputs. Port 0 pins that have "1" written to them are pulled HIGH by the internal pullup and — while in this state — can be used as inputs. As inputs, Port 0 pins externally being pulled LOW will source current (I_{OL}) because of the pullup.

Port 0 also serves the functions of special features as listed below.

Port Pin	Alternate Function
P0.0	BRIDGE/PRINT Bypass PFD DMA Request Interrupt
P0.1	BRIDGE/PRINT Bypass PFD DMA Request Interrupt
P0.2	SP General-Purpose Interrupt
P0.3	BRIDGE/PRINT Bypass PFD DMA Request Interrupt
P0.4	BRIDGE/PRINT Bypass PFD DMA Request Interrupt

Port 0 is a 8-bit bidirectional I/O port with internal pullups. The Port 0 buffers can sink/source four LSTTL inputs. Port 0 pins that have "1" written to them are pulled HIGH by the internal pullup and — while in this state — can be used as inputs. As inputs, Port 0 pins externally being pulled LOW will source current (I_{OL}) because of the pullup.

PSEN Program Store Enable (Output, Active LOW)

PSEN is the read strobe to external Program Memory. When the 80C525 is executing code from external program memory, PSEN is activated twice each machine cycle — except that two PSEN activations are skipped during each access to external Data Memory. PSEN is not activated during fetches from internal Program Memory.

EA External Access Enable (Input, Active LOW)

EA must be externally held LOW to enable the device to fetch code from external Program Memory locations 0000H to 1FFFFH. If EA is held HIGH, the device executes from internal Program Memory unless the program counter contains an address greater than 1FFFFH.

The 80C525 internally latches the value of the EA pin at the falling edge of the reset pulse on the RST pin during a Hardware or Power-on Reset. Once latched, the EA value cannot be changed except by a Hardware reset.

XTAL1 Crystal (Input)

Input to the inverting-oscillator amplifier, and input to the internal clock-generator circuits.

XTAL2 Crystal (Output)

Output from the inverting-oscillator amplifier.

VCC Power Supply

Supply voltage during normal, idle, and power-down operations.

VSS Circuit Ground

Port 2 is an 8-bit bidirectional I/O port with internal pullups. The Port 2 buffers can sink/source four LSTTL inputs. Port 2 pins that have "1" written to them are pulled HIGH by the internal pullup and — while in this state — can be used as inputs. As inputs, Port 2 pins externally being pulled LOW will source current (I_{OL}) because of the pullup.

Port 2 also serves the functions of special features as listed below.

Port Pin	Alternate Function
P2.0	RD (external input port)
P2.1	RD (external output port)
P2.2	INT0 (external interrupt 0)
P2.3	INT1 (external interrupt 1)
P2.4	T0 (Timer 0 external input)
P2.5	T1 (Timer 1 external input)
P2.6	WR (external Data Memory write strobe)
P2.7	RD (external Data Memory read strobe)

Port 2 is an 8-bit bidirectional I/O port with internal pullups. The Port 2 buffers can sink/source four LSTTL inputs. Port 2 pins that have "1" written to them are pulled HIGH by the internal pullup and — while in this state — can be used as inputs. As inputs, Port 2 pins externally being pulled LOW will source current (I_{OL}) because of the pullup.

FUNCTIONAL DESCRIPTION

Program Memory

The 80C525 has 64K bytes of Program Memory space. The lower 8K bytes (addresses 0000H to 1FFFFH) may reside on-chip. Instructions residing at addresses beyond 1FFF will always be fetched externally. When the External Access (EA) pin is held LOW, all code-fetch operations take place external to the 80C525.

Data Memory

The 80C525 can address 64K bytes of Data Memory external to the chip. The "MOVX" instructions are used to access the external Data Memory.

The internal Data Memory is comprised of three physically distinct memory spaces. They are the lower 128 bytes of RAM, the upper 128 bytes of RAM, and the 128-byte Special Function Register (SFR) space. The lower 128 bytes of RAM can be accessed through direct addressing (i.e., MOV addr, data), or indirect addressing (i.e., MOV @ Ri). The upper 128 bytes of RAM (locations 80H through FFH) can be accessed only through indirect addressing modes. The Special Function Register space, while physically distinct from the upper 128 bytes of RAM, shares addresses with the upper 128 bytes of RAM. The SFR space may be accessed through direct addressing modes only.

The first 32 bytes of RAM contain four register banks, each of which contains eight general-purpose registers. The next 16 bytes (locations 20H through 2FH) contain 128 directly addressable bit locations. The stack may be located anywhere in the internal RAM space and may be up to 256 bytes in length.

TABLE 1. EXTERNAL REGISTERS

Addr (HEX)	Symbol	Name
00	DPR0	Dual-Port RAM 0
01	DPR1	Dual-Port RAM 1
02	DPR2	Dual-Port RAM 2
03	DPR3	Dual-Port RAM 3
04	DPR4	Dual-Port RAM 4
05	DPR5	Dual-Port RAM 5
06	DPR6	Dual-Port RAM 6
07	DPR7	Dual-Port RAM 7
08	DPR8	Dual-Port RAM 8
09	DPR9	Dual-Port RAM 9
0A	DPR10	Dual-Port RAM 10
0B	DPR11	Dual-Port RAM 11
0C	DPR12	Dual-Port RAM 12
0D	DPR13	Dual-Port RAM 13
0E	DPR14	Dual-Port RAM 14
0F	DPR15	Dual-Port RAM 15
10	IBUF	Import Buffer
11	EBUF	Export Buffer
12	EFS	External FIFO Status
13	EIE	External Interrupt Enable
14	RS	Reset Status

TABLE 2. INTERNAL REGISTERS

Addr (HEX)	Symbol	Name
* 80	P0	Port 0
81	SP	Stack Pointer
82	DPL	Data Pointer Low
83	DPH	Data Pointer High
+ 84	DPL1	Data Pointer Low 1
+ 85	DPH1	Data Pointer High 1
+ 86	DPS	Data Pointer Selection
87	PCON	Power Control
* 88	TCON	Timer Control
89	TMOD	Timer Mode
8A	TL0	Timer 0 Low
8B	TL1	Timer 1 Low
8C	TH0	Timer 0 High
8D	TH1	Timer 1 High
* 90	P1	Port 1
* 98	SCON	Serial Control
99	SBUF	Serial Data Buffer
* A0	P2	Port 2
* A8	IE	Interrupt Enable
+ A9	WDS	Watchdog Selection
+ AA	WDK	Watchdog key
& AB	ARR	Address Recognition Register
& AC	OFE	Output Function Enable
& AD	AIP	Auxiliary Interrupt Priority
& AE	AIE	Auxiliary Interrupt Enable
& AF	AIF	Auxiliary Interrupt Flag
* B0	P3	Port 3
* B8	IP	Interrupt Priority
* & C0	ID0	Internal DPR 0
& C1	ID1	Internal DPR 1
& C2	ID2	Internal DPR 2
& C3	ID3	Internal DPR 3
& C4	ID4	Internal DPR 4
& C5	ID5	Internal DPR 5
& C6	ID6	Internal DPR 6
& C7	ID7	Internal DPR 7
* & C8	ID8	Internal DPR 8
& C9	ID9	Internal DPR 9
& CA	ID10	Internal DPR 10
& CB	ID11	Internal DPR 11
& CC	ID12	Internal DPR 12
& CD	ID13	Internal DPR 13
& CE	ID14	Internal DPR 14
& CF	ID15	Internal DPR 15
* D0	PSW	Program Status
*, & D8	P6	Port 6
* E0	ACC	Accumulator
*, & E8	P4	Port 4
* F0	B	B Register
*, & F8	P5	Port 5
& F9	GPIC	GPI Control
& FA	IFS	Internal FIFO Status
& FB	FES	FIFO Error Status
& FC	IT	Import Thresholds
& FD	ET	Export Thresholds
& FE	IFBUF	Import FIFO Buffer
& FF	EFBUF	Export FIFO Buffer

+ Registers found on both the 80C521 and the 80C525.

& Registers found only on the 80C525.

* Bit Addressable.

87C525

CMOS Single-Chip Microcontroller with 8K Bytes EPROM

ADVANCE INFORMATION

DISTINCTIVE CHARACTERISTICS

- EPROM version of the 80C525
- 8K bytes of EPROM
- Flashrite™ EPROM programming
- Two-level Program Memory Lock
- 32-Byte Encryption Array
- Fuse-Programmable Watchdog options
- ONCE Mode facilitates system testing
- All original 80C525 features retained:
 - 16 bytes of dual-port RAM
 - Two 20-byte FIFOs
 - DMA request and interrupt support provided
 - Programmable Maskable Address Recognizer
 - General-purpose Interrupt (output)
- 6-1/2 total ports on-chip in Enhanced I/O Mode
- Bus Arbitration Unit
- Eight interrupt sources
- 68-pin package
- 256 bytes of RAM
- Programmable Watchdog Timer
- Dual Data Pointers
- Software Reset
- Two 16-bit timer/event counters
- Boolean processor
- 64 K bytes program memory space
- 64 K bytes data memory space

GENERAL DESCRIPTION

The 87C525 is the CMOS EPROM version of the 80C525 microcontroller. The 87C525 is fully pin-compatible with the 80C525 and retains all the features of the 80C525.

The 87C525 EPROM array features a Flashrite programming algorithm that allows the 8K-byte EPROM array to be programmed in about 24 seconds. A two-level programmable lock structure provides security by preventing externally fetched code from accessing internal Program Memory, and can disable EPROM verification and programming. A 32-byte Encryption Array can be used to encrypt the program code bytes read during EPROM verification.

Like the 80C525, the 87C525 features a Slave Interface, 6-1/2 8-bit I/O ports, and a Bus Arbitration Unit. Like the

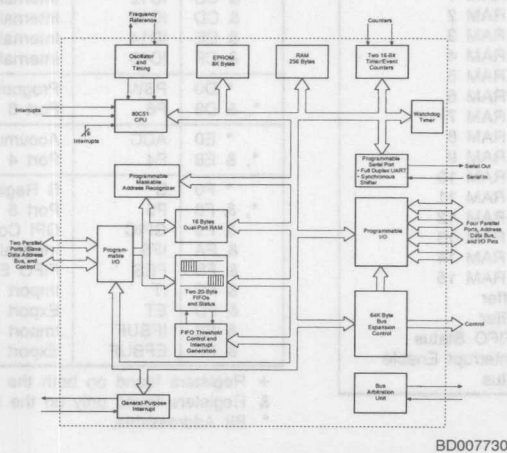
87C521, it also contains a Watchdog Timer and Dual Data Pointers.

The Watchdog Timer can be programmed to times ranging from 128 microseconds to 4 full seconds at 12 MHz. In addition, the 87C525 contains fuses which can be programmed to increase the reliability of the Watchdog Timer for use in extremely harsh environments. These options allow the Watchdog Timer to be "fixed-on" and its time value to be "hardwired."

All original features of the 80C51 are retained. For functional details of these features, consult the 8051 Family Architecture chapter in the AMD Microcontroller Handbook.

The 87C525 is offered in a 68-pin package.

BLOCK DIAGRAM



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Software Routines

DUAL DATA POINTER ROUTINES

The Dual Data Pointer feature enhances the manipulation of external memory by providing an easy way to use two separate 16-bit pointers with external memory and to selectively switch between them. This can increase execution speed of many functions considerably while at the same time reducing the number of required instructions. For instance, in block-move operations in external RAM, Dual Data Pointers can show more than 100% speed improvement using less than 65% of the original code space.

The following registers are associated with the Dual Data Pointers.

Data Pointer Low	(DPL)	} DPTR0 (Original Data Pointer)
Data Pointer High	(DPH)	
Data Pointer Low 1	(DPL1)	} DPTR1 (New Data Pointer)
Data Pointer High 1	(DPH1)	
Data Pointer Selection	(DPS)	

The six instructions that refer to "DPTR" now refer to the data pointer that is currently enabled, either DPTR0 or DPTR1. DPS is used to selectively enable the data pointers.

INC	DPTR	; Increment Data Pointer
MOV	DPTR, #data16	; Loads DPTR with 16-bit constant
MOVC	A, @A+DPTR	; Move code byte relative to DPTR to Acc
MOVX	A, @DPTR	; Move external RAM to Acc
MOVX	@DPTR, A	; Move Acc to external RAM
JMP	@A + DPTR	; Jump indirect relative to DPTR

For complete information on the Dual Data Pointer feature, consult the 80C521/80C321 Data Sheet.

Block Move in External RAM

Data Pointers are used extensively in the 8051 Family when a block of data is moved from a source area to a destination area in external RAM. The following examples illustrate the speed improvement and code space efficiency gained by using the Dual Data Pointer feature.

The first example shows a 32-byte block move executed by a traditional, single data pointer 8051 Family member. Contrast this with the second example which shows a 32-byte block move executed using the Dual Data Pointers.

With Dual Data Pointers, one data pointer can be assigned to the source address and the other to the destination address. The code then switches between the two data pointers without having to save and restore a data pointer. The speed improvement of this 32-byte block move is 115% and uses less than 57% of the original code space.

32-Byte Block Move with a Single Data Pointer

; SH and SL are the High and Low source addresses
; DH and DL are the High and Low destination addresses
; Register R5 contains the number of bytes to be moved

		Bytes/Cycles	
	MOV R5,#32	; 2 1	- 32 bytes to move
	MOV DPTR,#SHSL	; 3 2	- Source address
	MOV R1,#SL	; 2 1	- Initialize source address
	MOV R2,#SH	; 2 1	- Initialize dest. address
	MOV R3,#DL	; 2 1	- Initialize dest. address
	MOV R4,#DH	; 2 1	- Initialize dest. address
LOOP:	MOVX A,@DPTR	; 1 2	- Read byte from source
	MOV R1,DPL	; 2 2	- Save source pointer
	MOV R2,DPH	; 2 2	- Save source pointer
	MOV DPL,R3	; 2 2	- Load dest. pointer
	MOV DPH,R4	; 2 2	- Load dest. pointer
	MOVX @DPTR,A	; 1 2	- Write byte to dest.
	INC DPTR	; 1 2	- Next dest. pointer
	MOV R3,DPL	; 2 2	- Save dest. pointer
	MOV R4,DPH	; 2 2	- Save dest. pointer
	MOV DPL,R1	; 2 2	- Load source pointer
	MOV DPH,R2	; 2 2	- Load source pointer
	INC DPTR	; 1 2	- Next source pointer
	DJNZ R5,LOOP	; 2 2	- Loop till R5=0

32-Byte Block Move with Dual Data Pointers

; SH and SL are the High and Low Source addresses
; DH and DL are the High and Low Destination addresses
; Register R5 contains the number of bytes to move
; DPS = 01 at start (DPTR1 selected)

		Bytes/Cycles	
	MOV R5,#32	; 2 1	- 32 bytes to move
	MOV DPTR,#DHDH	; 3 2	- DPTR1 = Dest. address
	INC DPS	; 2 1	- Switch to DPTR0
	MOV DPTR,#SHSL	; 3 2	- DPTR0 = Source address
LOOP:	MOVX A,@DPTR	; 1 2	- Read byte from source
	INC DPS	; 2 1	- Switch to DPTR1
	MOVX @DPTR,A	; 1 2	- Write byte to dest.
	INC DPTR	; 1 2	- Next dest. pointer
	INC DPS	; 2 1	- Switch to DPTR0
	INC DPTR	; 1 2	- Next source pointer
	DJNZ R5,LOOP	; 2 2	- Loop till R5=0

Suggestion: The fastest way to switch data pointers is to increment the DPS register. Since Bits 7-1 of this register are defined to be zero, the increment (or decrement) operation simply alternates the contents of DPS between 00H and 01H.

32-Byte Block Move Efficiency

	Single Data Pointer	Dual Data Pointers
Instructions	19	11
Bytes	35	20
Cycles	839	390
Time (μs) @16 MHz	629.25	292.5

N-Byte Block Move Efficiency (Where N < 256)

	Single Data Pointer	Dual Data Pointers
Instructions	19	11
Bytes	35	20
Cycles	26N + 6	12N + 6
Time (μs) @16 MHz	0.75 (Cycles)	0.75 (Cycles)

Higher Performance Interrupt Routines

When a frequently occurring interrupt uses a data pointer, the overhead required to store and reload it from the main program can be significant. The performance of interrupt-driven systems can be improved by using the Dual Data Pointer feature to assign a data pointer to a frequently called, time-critical interrupt routine.

In the following code, the Main routine uses only DPTR0. The Interrupt routine stores a byte from the Serial Port into an external RAM buffer for later processing. DPTR1 is dedicated for its use.

```

RESET:      SJMP      START

START:      MOV       DPTR, #MAIN      ; Main routine data pointer
            INC       DPS             ; Switch to DPTR1
            MOV       DPTR, #INT      ; Interrupt data pointer
            ;          ; initialization
            INC       DPS             ; Switch back to DPTR0
            MOV       IE, #90H        ; Enable Serial Port Int.

; Main routine is using DPTR0
;      ...      .....
;      ...      .....
;          ;----->>> Interrupt occurs
; Program continue
;      ...      .....
;      ...      .....
;      ...      .....
;      ...      .....

; Interrupt routine begins at the Serial Port Vector Address

VECTOR:     INC       DPS             ; Switch to DPTR1
            MOV       A, SBUF         ; Read from Serial Port
            MOVX      @DPTR, A        ; Store byte in RAM Buffer
            INC       DPTR            ; Next Dest. Address
            INC       DPS             ; Switch to DPTR0
            RETI                     ; Return from Interrupt

```

Full Duplex Transmit/Receive

Full Duplex Serial Port operation involves simultaneously transmitting and receiving data. Typically a separate transmit buffer and a receive buffer are assigned in the external memory. When a receive interrupt occurs, the data received in the serial port receive register is

saved in the external receive buffer. When data is ready to be transmitted, the data from the external transmit buffer is loaded into the transmit register of the serial port. With two data pointers available, one can be assigned to the transmit buffer and the other to the receive buffer. Thus, the interrupt overhead can be reduced.

```
; Initialize
MOV     DPS,#00H      ; Select DPTR0
MOV     DPTR,#XMTBUF   ; Transmit RAM buffer address
INC     DPS            ; Switch Data Pointers
MOV     DPTR,#RCVBUF   ; Receive RAM buffer address

; Serial Port Interrupt Routine

INT_BEGIN:  JB      RI,RECEIVE  ; Receive a Byte
             JB      TI,TRANSMIT ; Transmit a Byte
             SJMP    ERROR      ; Error - neither bit set

TRANSMIT:   CLR      TI          ; Clear Flag
             MOV     DPS,#00H    ; Select DPTR0
             MOVX    A,@DPTR     ; Load data from memory
             MOV     C,P         ; Move Parity bit to carry bit
             CPL     C           ; Set ODD Parity
             MOV     A.7,C       ; Append to bit 7 in Acc
             MOV     SBUF,A       ; Load data to transmit
             INC     DPTR        ; Next Byte
             RETI

RECEIVE:    CLR      RI          ; Clear Flag
             MOV     A,SBUF       ; Load received byte to Acc
             JNB     P,ERROR      ; Jump if Parity error
             ANL     A,#7FH       ; Mask off Parity bit
             MOV     DPS,#01H    ; Select DPTR1
             MOVX    @DPTR,A     ; Store byte in memory
             INC     DPTR        ; Next byte
             RETI

ERROR:      ...              ; Error Handler
             RETI
```

Tree Structure Manipulation

The Dual Data Pointers can be useful in applications involving data structures containing pointer references, such as trees. For instance in a tree search algorithm, the node currently being searched and its parent may have their addresses stored in the Dual Data Pointers. Even though other required pointers will necessarily be pushed onto the stack, most operations will involve only

the two most recently used data pointers. Thus the search algorithm will execute more quickly.

In Figure 10-1, note that DPTR1 can be used to step through another link at node "Dave", as soon as DPTR0 is through accessing all of the links in leaf-node "Jim". The pointer for node "Randy" is located on the stack at this point.

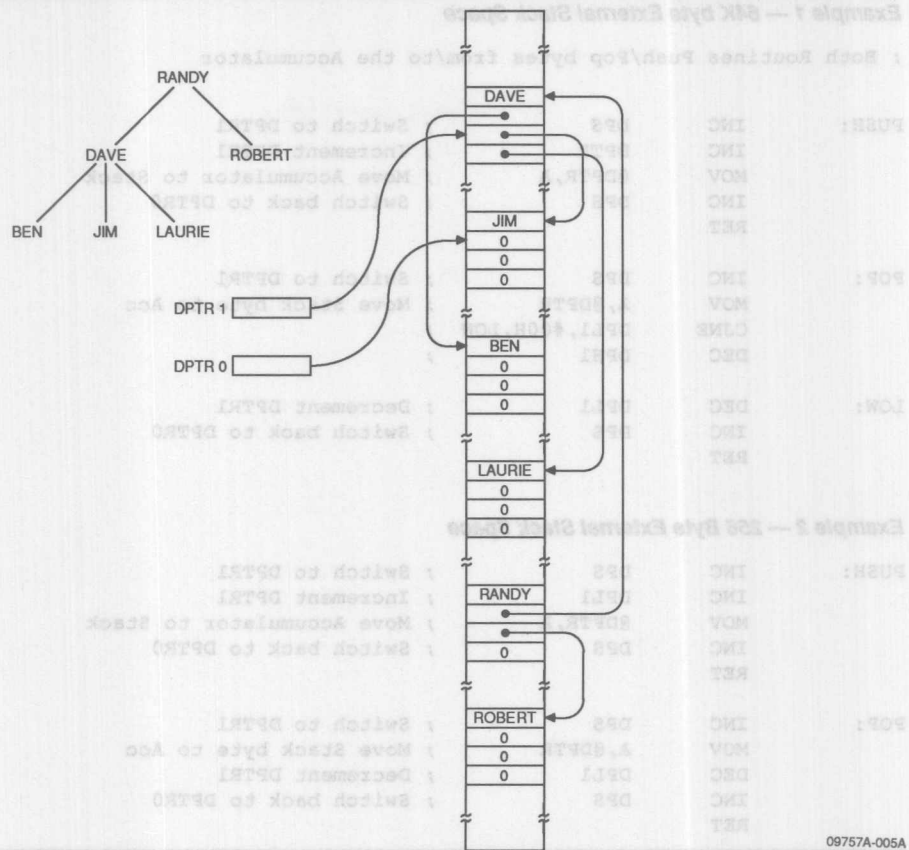


Figure 10-1. Tree Structure in External Memory

ROM Table Access

Use of the Dual Data Pointers need not be limited to manipulations in external RAM. For instance, one or both data pointers can be assigned to ROM tables in program memory space. Table access is then performed with the MOVC instruction. In this way, the base address of a ROM table can reside in one of the data pointers, improving the effective access time.

Creating an External Stack

For applications that require large amounts of data to be stored on a stack, the internal RAM space may not be

sufficient to contain it. This is especially true if the internal RAM is already being used extensively.

With Dual Data Pointers, one data pointer can be assigned specifically to an external stack space in external RAM. The following code provides Push and Pop subroutines using DPTR1 as a stack pointer. Two examples are shown. In the first example the external stack may be up to 64K bytes in length. The second example executes more quickly, but the external stack is limited to 256 bytes.

Example 1 — 64K byte External Stack Space

; Both Routines Push/Pop bytes from/to the Accumulator

```
PUSH:      INC      DPS          ; Switch to DPTR1
           INC      DPTR         ; Increment DPTR1
           MOV      @DPTR,A      ; Move Accumulator to Stack
           INC      DPS          ; Switch back to DPTR0
           RET

POP:        INC      DPS          ; Switch to DPTR1
           MOV      A,@DPTR      ; Move Stack byte to Acc
           CJNE     DPL1,#00H,LOW ;
           DEC      DPH1         ;

LOW:        DEC      DPL1         ; Decrement DPTR1
           INC      DPS          ; Switch back to DPTR0
           RET
```

Example 2 — 256 Byte External Stack Space

```
PUSH:      INC      DPS          ; Switch to DPTR1
           INC      DPL1         ; Increment DPTR1
           MOV      @DPTR,A      ; Move Accumulator to Stack
           INC      DPS          ; Switch back to DPTR0
           RET

POP:        INC      DPS          ; Switch to DPTR1
           MOV      A,@DPTR      ; Move Stack byte to Acc
           DEC      DPL1         ; Decrement DPTR1
           INC      DPS          ; Switch back to DPTR0
           RET
```

WATCHDOG TIMER ROUTINES

The Watchdog Timer (WDT) is a specially designed timer that will reset the chip upon reaching a pre-programmed time interval. Once started it cannot be disabled, except by a reset. It allows safe recovery from problems resulting from electrostatic discharge, external noise, unexpected input conditions or external events, and programming anomalies. Two registers are associated with the Watchdog Timer:

Watchdog Selection (WDS)

Watchdog Key (WDK)

WDS is used to set up the programmed time intervals and indicates the cause of the last reset — a Watchdog or

Software Reset versus a Hardware or Power-on Reset. Sixteen time intervals are programmable varying from 128 μ s to 4 s (at 12 MHz).

WDK is used to enable the Watchdog Timer as well as clear it. When the Watchdog Timer is cleared, its present count is set to zero, but it continues to increment. For complete information on the Watchdog Timer, consult the *80C521/80C321 Data Sheet*.

WDT Enable, Clear, and Reset Cause

The following example shows a method of setting up the Watchdog time value to 16.384 ms assuming a 12 MHz clock. The Watchdog Timer is then enabled.

```
; Enable Watchdog Timer
           MOV      WDS,#07H      ; Set up 16.384 msec
           ;
           MOV      WDK,#A5H      ; Write first key value
           MOV      WDK,#5AH      ; Write second key value
           ; Watchdog timer is 'enabled'
```

Once the Watchdog Timer is enabled, a "clear" sequence should be performed at intervals not exceeding the 16.384 ms time value. The enabling sequence may be used to clear the Watchdog Timer.

```
; Clear Watchdog Timer
MOV     WDK, #A5H    ; Write first key value
MOV     WDK, #5AH    ; Write second key value
                        ; Watchdog Timer is 'cleared'
                        ; but continues to increment.
```

To test whether the last reset was caused by a Watchdog or Software Reset the following code may be used. If the Reset Cause bit is set, then a Watchdog or Software Reset has occurred.

```
; Reset Cause Identification
MOV     A, WDS        ; Read Watchdog Selection reg.
JB      A.7, WDRST     ; Jump if Reset Cause bit is
                        ; set, else continue
WDRST:   ...          ; Notify external circuitry
```

The security of the Watchdog Timer is not adversely affected by interrupts that may occur in between the writing of the 'A5' and '5A' values to the WDK Register. Thus, if necessary, the user may include clear operations within both a main routine and the interrupt routines. Furthermore, the user need not disable interrupts during the enable/clear operations.

Once the 'A5' is written to WDK, the interrupt routine can only affect the Watchdog Timer in three ways: 1) it can go ahead and enable/clear the Watchdog Timer with a '5A'. (The subsequent '5A' written by the main routine will then have no effect); 2) it can write another 'A5'. This affects neither the Watchdog Timer nor the main routine; or 3) it can cause a Software Reset by writing a value other than 'A5' or '5A'. Any routine, though, can be written to generate the Software Reset.

Power-Down Operation

While the Watchdog Timer is enabled, the Power-Down mode is disabled. The user's code may still attempt to enable the power-down operation (by writing a value 1 to the PD bit in the PCON register), however, the PD bit will remain at 0, and the power-down operation will not take place. If the WDT has *not* been enabled, the power-down operation can proceed normally.

To enter Power-Down mode when the WDT is enabled, the WDT must first be disabled via a Hardware Reset, Software Reset, or Watchdog Reset. The easiest is the Software Reset. This can be accomplished by writing an 'A5' to the Watchdog Key (WDK) register followed by a value other than 'A5' or '5A'. This generates an immediate reset, equivalent to a Hardware Reset except that the Reset-Cause bit is set.

CHAPTER 10

Enhanced CMOS Devices

The code below uses the Reset-Cause bit and the Internal RAM (which is not modified by a reset). If the Reset-Cause bit is set, and a special Power-Down-

Status byte in internal RAM contains '88H', then the Power-Down mode will be entered by the program code.

```
; WDS = 7 sets up a Watchdog time of 16.384 msec @ 12 MHz.
; 'A5' followed by '5A' written to WDK enables the WDT.
; RAM location 50H is Power Down Status
; 00 implies Power-Down has not been requested.
; 88 implies Power-Down has been requested.

RESET:  MOV     A,WDS      ; Read Reset cause bit in WDS
        JB      A.7,WDRST  ; Jump if reset caused by WDT
        LJMP    MAIN      ; Go on to the Main Routine

WDRST:  MOV     R0,#50H    ; Address Power Down Status
        CJNE    @R0,#88H,MAIN ; If Power-Down was not
                                ; requested, then jump and
                                ; continue normally
        MOV     PCON,#02H  ; else enter Power-Down Mode

MAIN:   MOV     50H,#00H   ; Clear Power Down Status
        MOV     WDS,#07H  ; Set up time value for WDT
        MOV     WDK,#A5H  ; Write first key value
        MOV     WDK,#5AH  ; Write second key value
        ; .....        ; WDT is now enabled.
; Main Routine Continues..
; In Main Routine whenever Power-Down is required, execute:
        MOV     50H,#88H  ; Request Power Down operation
        MOV     WDK,#A5H  ; Write first key value
        MOV     WDK,#11H  ; Software Reset generated
        NOP        ; Execution begins at RESET
                        ; in 3 machine cycles.
```

Testing the Watchdog Timer

Two methods can be used to verify that the WDT is enabled after the enabling sequence has been written (rather than simply waiting for the WDT to reset to occur.) Method I can be used as a precautionary measure after

the enabling sequence or at various points within the code. It may also be used to confirm the time interval programmed into the WDT for applications that occasionally use different Watchdog time intervals. Method II can be used as a debugging test during program development.

Method I

```

MOV     WDS,#07H      ; Set the Watchdog time to
                        ; 16.384 ms @12 MHz
MOV     WDK,#A5H      ; Write first key value
MOV     WDK,#5AH      ; Write second key value
                        ; WDT should now be enabled
MOV     WDS,#00H      ; Attempt to rewrite contents
                        ; of the WDS Programmed Time
MOV     A,WDS          ; Read contents of WDS into Acc
CJNE    A,#07,ERROR    ; If contents are not 07, then
                        ; jump to ERROR.
...      .....      ; The WDT is enabled and the
                        ; ACC now holds the programmed
                        ; time value that the WDT is
                        ; currently using.

ERROR:   ...      .....      ; Watchdog Timer never received
                        ; the correct 'A5-5A' sequence

```

Method II

```

MOV     WDS,#07H      ; Set the Watchdog time to
                        ; 16.384 ms @12 MHz
MOV     WDK,#A5H      ; Write first key value
MOV     WDK,#5AH      ; Write second key value
                        ; WDT should now be enabled

WAIT:   MOV     A,WDS      ;
JNB     A.5,WAIT      ; Wait 8.192 ms for the TV bit
                        ; to be set
...      .....      ; WDT enabled and incrementing

```

Using the Watchdog Timer as a Standard Timer

The Timer Verification (TV) bit in the WDS register can be used to implement certain types of timer functions through polling. Once the WDT is enabled, the TV bit will toggle every 8.192 ms (at 12 MHz) until either the WDT overflows, or the WDT is cleared. (The TV bit is initially a 0 after any reset.) When the WDT overflows, a WDT

Reset occurs clearing the TV bit. When the WDT is cleared, the TV bit is cleared, but begins toggling again at the same rate. If bits PT3-PT0 are set to '0110' or less, then a WDT Reset will occur before the TV bit toggles.

The following code uses the MAIN polling loop of an application to watch for the TV bit to toggle. It uses the TV bit to output a 25% duty-cycle pulse on Port Pin 1.7 with a period of 1.049 s at 12 MHz.

CHAPTER 10 Enhanced CMOS Devices

```

; R6 If 0, then Pulse is Low
; If 1, then Pulse is High
; LTIME = Low Time, the number of 8.192 ms units equaling
; 786 ms = 96
; HTIME = High Time, the number of 8.192 ms units equaling
; 262 ms = 32
; OLD_TV = A Direct RAM byte whose bit 0 location contains
; the last read value of TV
; R7 Contains number of TV toggles left to go before P1.7
; switches

INIT:      MOV      WDS,#0FH      ; Set the Watchdog time to 4 S
          ; at 12 MHz (safest value)
          CLR      P1.7          ; Set Port Pin to 0
          MOV      R6,00H        ; Pulse is Low
          MOV      R7,LTIME      ; Load Low Time
          MOV      WDK,#A5H      ;
          MOV      WDK,#5AH      ; WDT is now enabled. TV begins
          ; toggling
          MOV      R6,00H        ; Pulse is Low
          MOV      R7,LTIME      ; Load Low Time
          MOV      OLD_TV,#00H   ; Old TV bit equals 0 (TV's
          ; reset value)

MAIN:      ...      ....
          MOV      A,WDS        ;
          MOV      C,A.5        ; Move TV bit to Carry
          MOV      A,OLD_TV      ; Move Old TV bit to ACC.0
          ADDC     A,#00         ; Add TV bit (in Carry) to Old
          ; TV bit
          JB       A.0,TOGGLE    ; If A.0 = 1, then the TV bit
          ; has toggled

CONTINUE:  ...      ....
          ;      ....

TOGGLE:    INC      OLD_TV      ; Toggle Old TV bit in OLD_TV
          ; byte
          DJNZ     R7,CONTINUE   ; If R7 is not 0, then it is
          ; not time to toggle P1.7 yet
          CPL      P1.7         ; Toggle Port Pin
          MOV      WDK,#A5H      ;
          MOV      WDK,#5AH      ; Clear WDT, TV starts again
          CJNE     R6,#00,GO_LOW ; If R6 is 0, then load HTIME
          ; else load LTIME
          MOV      R7,HTIME      ; Load High Time
          INC      R6            ; Pulse is High now
          SJMP     CONTINUE      ;

GO_LOW:    MOV      R7,LTIME      ; Load Low Time
          DEC      R6            ; Pulse is Low now
          SJMP     CONTINUE      ;

```

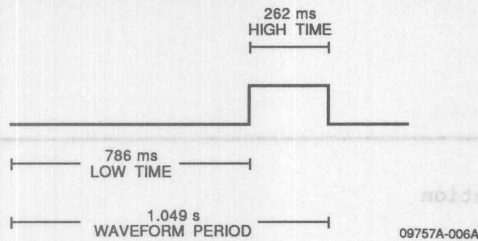


Figure 10-2. P1.7 Output — 25% Duty Cycle

SOFTWARE RESET ROUTINES

A Software Reset may be accomplished through the Watchdog Timer. This “software generated” Watchdog Reset occurs regardless of whether or not the Watchdog

CLR	EA	; Disable all interrupts.
		; Optional
MOV	FLAG, #88H	; Optional
MOV	WDK, #A5H	; Write first key value
MOV	WDK, #11H	; Write a non-A5, non-5A value.
		; Software Reset has now been
		; generated via the WDT.
NOP		; Optional

If the Watchdog Timer is cleared within an interrupt routine, that interrupt should be disabled before executing a Software Reset sequence. If the interrupt occurs between the two writes to WDK, and then clears the Watchdog Timer, a Software Reset will not be generated.

To distinguish between a Watchdog Reset and a Software Reset (or separate causes of a Software Reset), a flag value may be written to internal RAM. This flag can be used in combination with the Reset-Cause bit to distinguish between the reset types. An example of this

Timer was previously enabled. If the Watchdog Timer was enabled, it will be disabled following the reset. The Software Reset is functionally equivalent to the Watchdog Reset.

Two write operations are required to initiate a Software Reset to greatly reduce the chance of unintentional Software Reset generation. More information is available in the *80C521/80C321 Data Sheet*.

Using Software Reset

Whether or not the Watchdog Timer is being used, the Software Reset feature of the Watchdog Timer may be used to increase the reliability of the program code. For instance, the detection of an unusual hardware error can be followed by a jump to the following code which will always cause a Software Reset.

method is shown in the “Power Down Operation” software routine.

After the value ‘11H’ is written to WDK, execution begins at 0000H in three machine cycles. One machine cycle of normal execution takes place after the ‘11H’ is written. Thus, the NOP can be included for safety. Since all registers are initialized during reset, and all external operations take two machine cycles, the only operation that could possibly affect operation after the Software Reset would be a one-cycle write to internal RAM.

Improving Reliability with Software Reset

For additional reliability, the following instruction sequence may be placed in any unused ROM program space:

```

; First unused ROM location
NOP
NOP
;
MOV     WDK, #A5H
MOV     WDK, #00H    ; Software Reset generated
NOP
NOP
;
MOV     WDK, #A5H
MOV     WDK, #00H    ; Software Reset generated
NOP
NOP
;
...      ....      ; Continue repeating the 4-instruction
;      ...      ; sequence
;
SOFTRESET: MOV     WDK, #A5H
MOV     WDK, #00H    ; Software Reset generated
NOP
NOP
SJMP    SOFTRESET    ; Last unused ROM location

```

If the program counter branches to any byte of this code (other than the second byte of the SJMP instruction), a Software Reset will be quickly generated. The NOP

instructions are used to force the program counter to adjust itself to an instruction boundary.

CHAPTER 11

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Third-Party Support Products

INTRODUCTION

A number of support products are available for the 8051 microcontroller family. The following pages present product descriptions of emulators, assemblers, compilers, and programmers from various manufacturers. The material is intended to present a collection of what is

available for AMD-manufactured 8051 Family microcontrollers, but is not necessarily a complete, up-to-date listing of all available products. Further information may be obtained from the individual companies listed and the many other vendors that support 8051 Family products. AMD does not guarantee the specifications of any of the products listed.

Third-Party Support Products

Vendor	Primary 8051 Family Products	Description
Hewlett-Packard 1501 Page Mill Road Palo Alto, CA 94304 (Contact local sales office)	Development System	Company provided, page 11-3
MetaLink Corporation PO Box 1329 Chandler, AZ 85244-1329 (602)926-0797 or (800) 638-2423	Development System	Company provided, page 11-8
American Automation 2651 Dow Avenue Tustin, CA 92680 (714)731-1661	Development System	Company provided, page 11-13
Huntsville Microsystems 4040 S. Memorial Parkway PO Box 12415 Huntsville, AL 35802 (205)881-6005	Development System	Company provided, page 11-14
Applied Microsystems Corp. 5020 148th Ave. N.E. PO Box 97002 Redmond, WA 98073-9702 (206)882-2000 or (800)426-3925 (U.S.) 44-(0)-296-625462 (U.K.)	Development System	Call vendor for details
Kontron Electronics D-8057 Eching/Munich Oskar-von-Miller-Str. 1 West Germany Phone: (0 81 65) 77-0	Development System	Call vendor for details
Nohau Corporation 51 E. Campbell Ave. Suite 107E Campbell, CA 95008 (408)866-1820	Development System	Call vendor for details
Signum Systems 1820 14th Street Suite 203 Santa Monica, CA 90404 (213)450-6096	Development System	Call vendor for details

CHAPTER 11
Third-Party Support Products

Third-Party Support Products (continued)

Vendor	Primary 8051 Family Products	Description
Sophia Systems NS Bldg 2-4-1 Nishishinjuku, Shinjuku-ku Tokyo 160, Japan 03-348-7000	Development System	Call vendor for details
Zax Corporation 2572 White Road Irving, CA 92714 (714)474-1170 or (800)421-0982	Development System	Call vendor for details
Ziltek Corporation 1651 East Edinger Ave. Santa Ana, CA 92705 (714)541-2931	Development System	Call vendor for details
Micro Computer Control PO Box 275 Hopewell, NJ 08525 (609)466-1751	C Compiler, Assembler	Company provided, page 11-15
Archimedes Software 2159 Union Street San Francisco, CA 94123 (415)567-4010	C Compiler, Assembler	Company provided, page 11-20
Scientific Engineering Labs 255 Beacon St., Suite 3D Somerville, MA 02143 (617)625-0288	Pascal Compiler	Call vendor for details
Boston Systems Office 128 Technology Center Waltham, MA 02254-9164 (617)894-7800	PL/M Compiler, Assembler	Call vendor for details
Sysoft SA 6926 Montagnola Switzerland (091)543195	PL/M Compiler, Assembler	Call vendor for details
Cybernetic Micro Systems Box 3000 San Gregorio, CA 94074 (415)726-3000	Simulator, Debugger	Call vendor for details
Microtek Research Box 60337 Sunnyvale, CA 94088 (408)733-2919	Simulator, Assembler	Call vendor for details
Data I/O Contact local sales office or call: (800)247-5700 Dept 401	EPROM-version Programmer	Company provided, page 11-24
Stag Microsystems 1600 Wyatt Drive Santa Clara, CA 95054 (408)988-1118 or (800)227-8836	EPROM-version Programmer	Call vendor for details

HEWLETT-PACKARD DEVELOPMENT SYSTEM

Emulators

Hewlett-Packard offers a wide selection of emulators to support microprocessor and microcontroller-based product development. These emulators provide the essential link between software development and hardware/software integration. Code developed on the HP 64000 system or compatible host computers is executed on the emulation subsystem and user's target system, if available, for real-time debugging and logic analysis.

Hewlett-Packard emulators are part of an integrated set of design and development tools that include Teamwork/SA/RT/SD for structured analysis and design; cross compilers and assemblers/linkers for programming at the most efficient level; directed-syntax softkeys and an easy-to-use, responsive editor to streamline software development and documentation; and analysis subsystems which provide powerful measurements to investigate program execution, timing relationships, system performance, and processor activity.

Universal Development System

HP 64000 products comprise a universal development system that provides development support that includes the 8051 Family of microcontrollers. When additional emulators are introduced to support popular new processors, they are easily integrated with existing HP 64000 real-time analysis tools. This flexibility protects the capital investment in instrumentation, since new projects and goals can be accommodated with low-cost add-ons rather than total replacement of development systems and tools.

System Environment

Hewlett-Packard supports the universal development system with two system platforms; a general-purpose, multiuser computer and a dedicated, stand-alone workstation.

The HP 64000-UX Microprocessor Development Environment is based on the HP 9000 Series 300 general-purpose computer, running the HP-UX* operating system. This workstation platform is common to the design engineering tools of HP Design Center. The multiuser capability of the Series 300 allows for shared hardware and software resources among system users. Multiple window capability allows integration and debug tasks to be viewed simultaneously, for convenient observation of interactive debug information. The HP-UX operating

environment supports user-programmable command files for repetitive and complex test routines. HP 64000-UX systems can be easily connected to other host computers or system resources.

The HP 64000-UX environment is compatible with the dedicated, stand-alone HP 64100A and 64110A Logic Development Stations. The same emulation and analysis card sets for most subsystems are used in both the HP 64000-UX Microprocessor Development Environment. In addition, these hardware platforms can be networked via high-speed link or RS-232 for maximum productivity.

Features

- Real-time emulation for evaluating target system performance and critical timing relationships
- Multiple emulation capabilities for multiprocessor product designs
- Display and modify memory, registers, and I/O ports
- Disassembly of microprocessor instruction set
- Source-line referencing
- Symbolic debugging for emulation and analysis operations
- Compatible and interactive high-performance logic analyzers for hardware, software, and software performance analysis
- Run control, single stepping, run from, and run until
- HP 64000 system resources (disc files, printer, development station keyboard, display, and RS-232 port) can be used to simulate target system I/O
- Emulation memory available from 32 Kbytes to 64 Kbytes
- Memory assigned by blocks to target system or emulation memory over the microprocessor's entire address space; designated as ROM, RAM, or illegal address space.
- User-definable emulator kit for custom emulation support

Measurement System Configuration

An HP 64000 emulation subsystem consists of an emulation control card, emulation pod, and operating software. An emulation bus analyzer is used for tracing activity on the emulation bus in real-time. Trace lists generated by the analyzer may be displayed in the mnemonics of the target processor. Inverse assembler software is included in the emulation software. HP 64856A User Definable Inverse Assembly software package may be used to generate mnemonics for the User Definable Emulator (UDE) and User Definable Preprocessor. Cross assemblers/linkers are available.

**HP-UX is Hewlett-Packard's implementation of the UNIX operating system.*

The analytical functions of the emulator can be expanded with Model 64310A Software Performance Analyzer. Input data from the HP 64310A analyzer is collected from activity on the emulation bus. The performance analyzer provides the macro overview measurements needed for optimizing and modifying code for more efficient software performance.

When complex, detailed logic state analysis is required, the powerful HP 64620S Logic State/Software Analyzer can be integrated directly into the emulator subsystem via HP 64304A Emulation Bus Preprocessor. The added power of software analysis provides traces converted to high-level language source code as well as assembly language or numeric code lists.

For hardware debugging, the powerful HP 64610S High-speed Timing/State Analyzer checks timing relationships, locates glitches, and identifies marginal signals. For high-speed logic designs, the analyzer functions as a 125-MHz state analyzer.

A new dimension of analysis power can be added with the Intermodule Bus (IMB) which links analyzers and emulators. The IMB communicates with the emulator through the HP 64302A Emulation Bus Analyzer. Other analysis subsystems that can be added to the IMB are the HP 64620S Logic State/Software Analyzer, HP 64310A Software Performance Analyzer, HP 64610S High-speed Timing/State Analyzer, and HP 64340 Real-time High-level Software Analyzer. Cross triggering between analyzers enables the designer to make coordinated measurements that help solve complex hardware/software integration problems.

System Architecture

All emulators of the HP 64000 system use a multiple-bus architecture, thus allowing interactive emulation and analysis. The development station host processor communicates with all installed subsystems using the HP 64000 system bus. A separate high-speed emulation bus

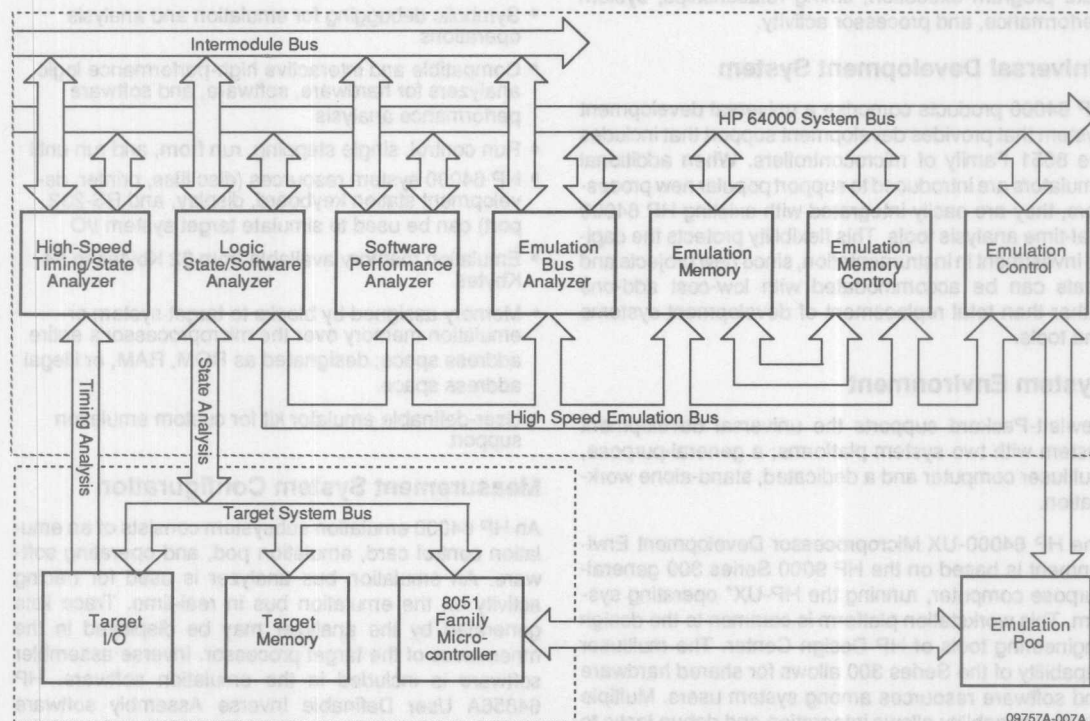


Figure 11-1. System Architecture

carries all transactions required for emulation. Independent operation frees the emulation system from the host system overhead. The intermodule bus controls sophisticated, interactive cross measurements for emulation, state, timing, and performance analysis. Major advantages of the multiple-bus architecture are real-time, transparent emulation and analysis that free the target system for unrestricted execution.

8051/8751/8031/8053/8753 Model 64264S

Model 64264S Emulation Subsystem consists of a control board, pod, and software. Connection to the target system is made with a 305 mm (12 in.) cable that terminates in a 40-pin, low-profile probe. A typical 8051/8751/8053/8753 emulation system includes HP 64264S Emulation Subsystem, HP 64156S Emulation Memory System, and HP 64302A Emulation Bus Analyzer.

Software development support is provided by Model 64855 Cross Assembler/Linker.

Features

- Real-time execution up to 12 MHz independent of emulator/target system memory assignment
- Nonintrusive, real-time traces of 8051 activity for basic analysis and evaluation including access to
 - Program memory
 - Internal and external data memory
 - Accumulator and special-function registers
 - I/O ports 0, 1, 2, and 3
- Disassembly of 8051 instruction set
- Program and external data memory mapped in 256-byte blocks to emulation or target system memory
- Expanded measurements capabilities through interactive operations with other HP 64000 subsystems:
 - Another 8051 emulator or any other HP 64000 emulator
 - HP 64620S Logic State/Software Analyzer
 - HP 64610S High-speed Timing/State Analyzer
 - HP 64310A Software Performance Analyzer

Electrical Specifications

Maximum clock speed: 12 MHz

Inputs: all inputs meet AMD specifications plus approximately 40 pF capacitance; Port 0, low-level input, 0.45 mA; Port 1, Port 2, and Reset, low-level input, 0.1 mA; and $\bar{E}A$, low-level input, 0.5 mA.

Power: 20 mA drawn from the target system; all other power supplies by the development station or card cage.

8051 Cross Assembler/Linker

The HP 64855 Cross Assembler/Linker provides assembly language software development support for the 8051 Family of Microcontrollers. The Model 64855AF is hosted on the HP 64100A/64110A development stations. Model 64855S and the appropriate option provide a cross assembler/linker which executes on both the HP 64100A/64110A development stations and on an HP 9000 series 300 HP-UX or a VAX/VMS host computer system.

Regardless of the host computer execution environment, the cross assembler/linkers produce identical relocatable and absolute code for a given source program. The assembler uses the instruction mnemonics for the 8051 series and generates code for all the defined 8051 instructions. However, due to differences in some pseudo instruction mnemonics and assembler syntax conventions, source programs written for the manufacturer's assembler generally require some modification prior to use with the HP 64855 Cross Assembler/Linker.

Both assemblers/linkers generate the necessary information for symbolic debug in emulation. Programmers can troubleshoot the code using source program line numbers and global symbols, eliminating the task of looking up addresses.

Assembler Directive

"8051" causes the cross assembler/linker to recognize the instruction set of the 8051 Family of Microcontrollers.

Reference Information

Addressing/Operand Field Conventions

8051 Registers — The 8051 microprocessor contains 128 bytes of on-chip RAM (expandable to 65,536 bytes with external RAM chips). Addresses 00H to 1FH in RAM are reserved for 32 general purpose registers arranged in four register banks; R0-R7 indicate the eight working registers; these registers are called the current active bank. The current active bank can be changed to any of the other register banks by specifying the register bank select bits RS0 and RS1 in the program status word.

The stack is also located in the on-chip RAM and the Stack Register points to the top of the stack. On RESET, the stack pointer is set to 07H. The Stack Register cannot exceed 127 (7FH in hex).

There are additional hardware registers for the 8051 which are located on an external RAM chip. The registers and their addresses in external RAM are shown on the following page.

External RAM Registers and Addresses

ACC	Accumulator	0E0H
B	Multiplication	0F0H
DPH/DPL	Data Pointer High/Low	83H/82H
IE	Interrupt Enable	0A8H
IP	Interrupt Priority	0BDH
P0-3	Ports 0-3	80H, 90H, 0A0H, 0B0H
PSW	Program Status Word	0D0H
SBUF/SCON	Serial Buffer/Control	99H/98H
SP	Stack Pointer	81H
TCON/TMOD	Timer Control/Mode	88H/89H
TH0/TL0	Timer 0 High/Low-Byte	8CH/8AH
TH1/TL1	Timer 1 High/Low Byte	8DA/8BH

The HP 64855 Cross Assembler/Linker supports all five addressing modes of the 8051 microprocessor: Immediate, Data, Indirect, Bit, and Code Addressing. The addressing modes are as follows:

Immediate Addressing — Any number, symbol, or expression may be specified as an operand by immediately preceding it with a pound (#) symbol. Examples:

#number, #symbol, #expression, #"ASCII char"

Data Addressing — Data can be obtained from any of the 128 on-chip RAM addresses or a hardware register address. (External RAM data must be obtained by indirect addressing.) The symbol or numeric expression must be of either no segment type or type DSEG (i.e., previously defined to be within the data segment). Data addresses from 0-127 are in RAM and addresses from 128-255 are in hardware registers.

MOV A,76H ;Move contents of address 76H to accumulator.

Indirect Addressing — The address of the operand is pointed to by register R0 or R1 in the active register bank if the indirect address is in on-chip RAM. External code or data memory is addressed by the MOVC or MOVX instructions by using the Data Pointer Register (DPTR). The address within R0 or R1 must be between 0-127. The indirect mode is specified by preceding the register with a (@). For example:

ADD A,@R0 ; Add contents of the on-chip RAM
; Address in R0 to accumulator.

MOVC R0,@DPTR; If DPTR contains 1000H, then
; move the data at address 1000H
; to register R0.

Bit Addressing — The processor can access any bit in the on-chip RAM and other hardware registers. The byte which contains the bit must be defined, followed by the bit

selector (.) and the bit identifier (0-7). Opcodes using a bit address must be defined as type BSEG or no segment type. For example:

SETB 5CH.3 ;Set bit 3 at address 5CH.

Code Addressing — The instruction specifies a new location to jump to in the program code.

Pseudo Instructions

The HP 64855 Assembler/Linker recognizes most of the basic ASM51 Assembler pseudo instructions as have equivalents for many of the others. The following lists the pseudo instructions that are similar to the HP assembler pseudos.

ASM 51 Assembler Pseudos	HP 6400 Equivalent Assembler Pseudos
EJECT	SKIP
END	END
EQU	EQU
IF..ELSE..ENDIF	IF..ELSE..ENDIF
MACRO..ENDM	MACRO..MEND
ORG	ORG

The HP 64855 Cross Assembler/Linker also supports several additional pseudo instructions for the 8051 processor which differ from the general HP 64000 assembler pseudos.

BIT	BIT assigns a bit address to a symbol. This allows the assembler to refer to a specific bit.
BSEG	This selects all data to be in the bit address segment. The locations in the bit address segment must be within the range from 0-255.

CSEG	CSEG invokes the program relocatable counter. (This is default when the assembler is invoked.) The counter can range from 0-65,535.	SET	The SET pseudo is the same as the HP 64000 pseudo; however, the HP 64855 assembler also uses SET to assign a name to one of the 8051's registers.
DATA	DATA assigns an on-chip address to the symbol. The symbol is defined as type DSEG.	XDATA	XDATA assigns an off-chip data address to a symbol and makes the symbol type XSEG.
DB	Stores data by bytes in consecutive memory locations within the code segments starting at the current setting of the program counter.	XSEG	XSEG selects the external data address segment. The values in the location counter range from 0-65,535.
DBIT	DBIT reserves bit address space.	The HP 64855 Cross Assembler/Linker does not support the following HP 64000 pseudo instruction; the alternate pseudo must be used instead.	
DS	This reserves or defines a block of space by types in any segment in memory.	DATA	Use XSEG or DSEG instead.
DSEG	DSEG selects the on-chip data address segment. Addresses range from 0-255.	DEC	Use DECIMAL instead.
DW	Stores data by words in memory. DW is only valid within the CSEG or code segment.		

Special Note:

Hewlett-Packard has just announced a brand new series of low-cost, host-independent emulators. The new HP 64700 Series emulators can be connected

to a variety of hosts including the HP 9000 Series 300 and the PC. Please contact your Hewlett-Packard Sales Representative for an up-to-date list of supported processors.

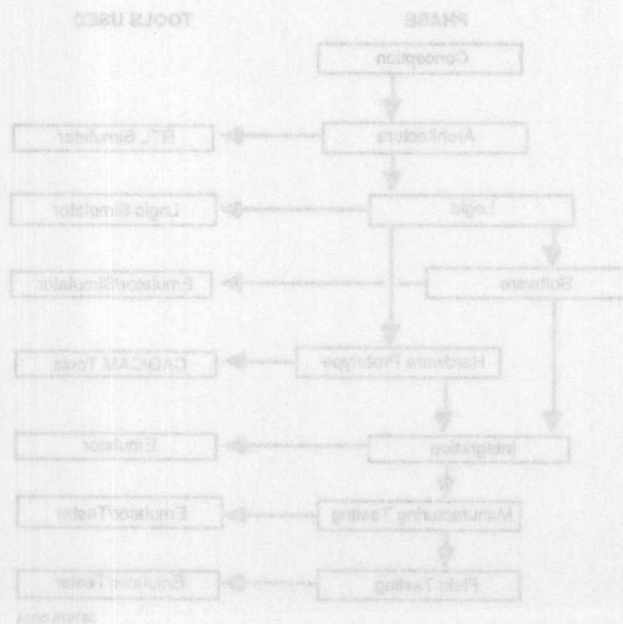


Figure 11-2 Design Cycle

METALINK DEVELOPMENT SYSTEM

The MetaLink Emulator, What is it?

An In-Circuit Emulator is a tool for use in designing systems incorporating microcontrollers. Using this tool, the system designer can interactively control and examine the state of the system at any chosen time. This is essential for speeding up the debugging process and enhancing the system designer's productivity. The tool is easy to use; simply replace the system microcontroller with the emulator probe, which then becomes the in-circuit microcontroller. When the probe is connected to the host computer, the system can be completely controlled.

The emulator provides not only the capabilities of the target processor, but a set of debugging capabilities to facilitate and shorten the debugging process. Why is this important? It is not enough for the emulator to simply behave like the target processor, it must also provide read/write access to all signals and all data to which the microcontroller has access. This includes information which resides inside the microcontroller. Without this access, the engineer may *not* be able to completely control and debug the system.

The many uses of the emulator can be easily visualized after examining a typical system design cycle.

The first use of an emulator in the design cycle is in the software-development phase. The emulator executes the program exactly as the target system would, in real time, and it provides all of the interactive debugging capabilities. Software, developed using the emulator, can be completely debugged, except for the hardware interface, before it is integrated with the system hardware.

The second and major use of an emulator in the design cycle is in the integration of the target software and the system hardware. Even when the hardware and software have each been individually debugged, new problems can surface when they are joined together. The emulator is used, in this case, to solve these potential problems.

After a prototype has been completely debugged, the emulator can then be used to test the specs of the system. Worst case parametric tests can be developed and tested on the prototype. This provides the designer with valuable information about the limitations of the system. It also provides test programs which can be used in the manufacturing process (see below).

The third use of an emulator is in the product-manufacturing phase. The same test routines, used to develop and debug the prototype, or even more comprehensive test routines, can be used to test the finished products. Any non-functioning units can be easily debugged using the emulator's full range of debugging capabilities.

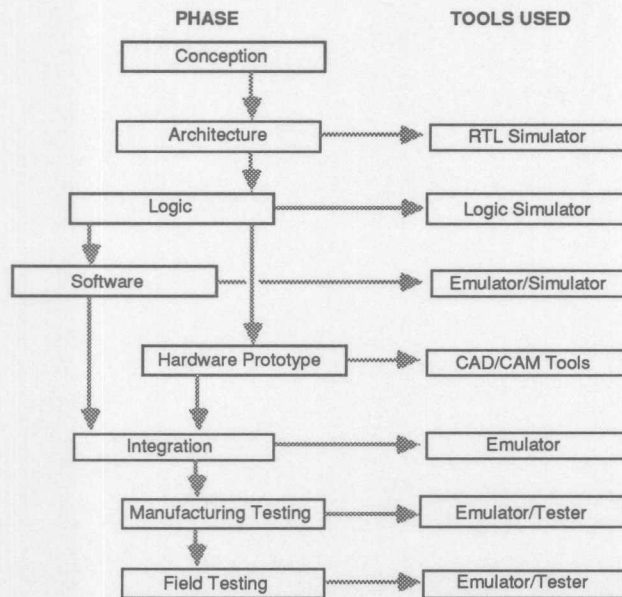


Figure 11-2. Design Cycle

09757A-008A

The fourth use of an emulator is in the field-service phase. The MetaLink emulator can run on any IBM PC or 100% PC-compatible host computer including the PC-compatible portables. Check the end of this description for other operating systems and host computers compatible with the MetaLink emulator. If the field location already has a host computer, the field service team need only carry the emulator module, which easily fits in a briefcase, and some floppy disks. If a host computer is not available, a portable host can be used.

MetaLink MetaICE or MicroICE Emulator

The MetaICE or MicroICE emulator is a PC-based in-circuit emulator, designed for use in developing, testing and debugging designs based on the 8051 Family of single-chip microcontrollers. Using the MetaICE or MicroICE emulator, hardware and software designs can be developed simultaneously. The MetaICE or MicroICE emulator assists in the following phases: software development, integration of target software and system hardware, manufacturing and field service.

The MetaICE or MicroICE emulator may be used with several third-party software cross-assemblers and compilers in the development phase that in the integration phase can also provide symbolic debug capability. These are:

- Cross-Assemblers - MetaLink's, IAR Systems, Enertec, Microtec Research and Intel.
- Compilers - Archimedes Software, IAR Systems and Intel.

Significant features of the MetaICE or MicroICE emulators:

- Serially linked to IBM PC or compatible hosts
- Advanced menu-driven human interface
- Real-time and transparent emulation up to 16 MHz
- Disassembler and single-line assembler
- Examine/modify memory capabilities
- 16 break and trace-trigger conditions
- High Level Language Support

- Supports both modes:
 - Microprocessor
 - Microcomputer
- 9 probe clips
 - 7 External events
 - 1 External trigger input
 - 1 External trigger output
- Up to 128,000 break and trace triggers
- Emulation Memory:
 - 64K Program
 - 64K External data
- Full symbolic debug capability
- Opcode class editor
- Up to 64K pass counts
- Separate program and data-memory mapping in 16-byte blocks
- Experiment editor/compiler
- Trace with 4K frames (MetaICE)
Trace with 2K frames (MicroICE)
 - Start, end and center triggers

Emulator Functions

Various MetaICE or MicroICE emulators can support different versions of the 8051 Family of microcontrollers. See Table 11-1. They will support NMOS and CMOS versions of the devices, up-to a clock rate of 16 MHz, where appropriate. The MetaICE or MicroICE emulator is totally transparent to the users target system and will function at the clock rate specified by the user.

The MetaICE or MicroICE emulator functions from an IBM PC or compatible computer and is controlled by the serial-interface board of the system. The serial-interface operation rate is controlled by the user and the target-system clock rate; 9600 bps is the maximum transfer rate. The user interacts with the keyboard and the PC screen, while the PC's RAM memory provides the resident home for the MetaICE or MicroICE application system and user target program.

Table 11-1. MetaICE or MicroICE Emulator Part/Model Number Listing

Part Number	Model Number	AMD Devices Supported
MC-8031	MicroICE-8031	8031 & 80C31
MC-8052	MicroICE-8052	8031, 8751, 8753, 8051, 8053, 80C31 & 80C51
MI-80515	MetaICE-80515	80515, 80535
MI-80C521	MetaICE-80C521	80C521 & 80C321
MC-80C321	MicroICE-80C321	80C321 & 80C31
MI-80535	MetaICE-80535	80535

User Interface

The MetalICE or MicroICE system uses a menu driven screen format for commands; a menu is structured as follows:

Command1 Command2 Command3
Quick help description of Command1

MENU NAME

Errors, warnings or messages

The first line of the screen contains a list of the command options available for that menu. The second line contains a one-line description of the highlighted command (see below). The middle of the screen contains the menu's name. The line at the bottom of the screen contains any errors, warnings or messages encountered during a command execution.

User Abilities

The MetalICE or MicroICE emulator can perform the following functions and call the following sub-functions:

- Load program code memory from disk files
- Upload program code memory from user target system board
- Download user board external data memory from disk files
- Call the system-configuration menu
- Restore a previously saved system and status
- Store the system and status in a disk file
- Create or execute a macro command file
- Call the interrogate menu
- Call the Help menu
- Terminate a session
- Escape out to and return from the resident operating system

User Interface Selection

The user selection specifies the baud rate used and the communications port (1 or 2) used for communication between the MetalICE or MicroICE emulator module and the host computer. It also includes the mode of operation and the configuration of the external data bus. Most MetalICE or MicroICE emulator models give the user the option to select between External Address Bus Mode (ROMless) and Single-Device Mode (ROM) with various external program/data memory addresses and all or some of the I/O ports.

Interrogation Selection

The Interrogate portion of the MetalICE or MicroICE emulator allows the user to run emulation experiments against the target system, to examine the status of the

system, to set break and trace triggers and to examine/modify data, using the following capabilities:

- Running an emulation experiment
- Single stepping the target
- Resetting the target
- Setting a phantom breakpoint then running an emulation
- Setting up to 16 simple breakpoint/trace triggers or ranges
- Setting the repetition counter
- Setting the trace-trigger type (Start, Center or End)
- Calling the Help menu
- Examination and modification of SFRs and registers
- Examination and modification of internal data memory
- Examination and modification of external data memory
- Examination and modification of code memory
- Viewing the 2K or 4K trace buffer
- Examination and modification of the emulation experiment
- Selecting the 7 probe clips for trace
- Setting up to 16 increment pass-count addresses or ranges
- Escape out to and return from the resident operating system
- Viewing the A/D conversion data
- Turn Trace Trigger ON/OFF (MicroICE)

Experiment Selection

An experiment is the specification of where breakpoints, trace triggers or counts are to occur. It can be described in high-level language, called the Experiment Language, using the MetalICE or MicroICE emulator software. An experiment, then, is simply the Experiment Language text that describes where the breakpoints are to occur. Up to 128,000 complex hardware breakpoints, trace triggers or counts can be set in the MetalICE or MicroICE emulator.

An experiment can be created outside the MetalICE or MicroICE environment by using any available text editor to create an experiment text file. This file can then be read into the MetalICE or MicroICE system and then interacts with the user program to cause those breakpoints, trace-triggers and counts to occur. The experiment uses the *If-then* condition statement as its basic construct. Experiment statements will be of the form:

if (condition) then (action).

The condition represents a breakpoint or trace-trigger specification. Breakpoints or trace-triggers can be specified by any of the following methods:

- A PC address
- A PC address range
- An opcode value
- An opcode class
- A direct byte address
- A direct byte address range
- A direct bit address
- A direct bit address range
- An immediate operand value
- A read or write to bit or direct address
- An external data address
- An external data address range
- Logical AND or OR of the above
- Pass count overflow
- External Input

The action represents the type of event that will occur after the condition has been encountered. The type of action can be specified by any of the following:

- A break
- An enable/trace
- A count
- A count/output trigger

In addition, an Examine/Modify Experiment Editor exists that can be used to examine and modify an experiment specification. In this editor, the user can:

- Edit an experiment
- Compile an experiment to set the breakpoints
- Load an experiment from a disk file
- Store an experiment in a disk file
- Reset the current experiment
- Delete the current experiment
- Call the Opcode Class experiment

Examine/Modify Memory

Using the MetalICE or MicroICE emulator, the user can examine and modify the five memory spaces of the 8051 Family of devices. This examination/modification of memory spaces is broken down into two areas: Program-Code memory and Data memory.

Using the Examine/Modify Program Code Memory is used to examine and modify the contents of the MetalICE

or MicroICE emulator code memory and provide for the following functions:

- Disassembly of the program code (hex or symbolic data)
- Single-line assembly of the program code
- Examination and modification of raw program-code memory data
- Examination and modification of program-code memory mapping
- Selective mapping of the 64K program-code memory to the emulator
- Selective mapping of the 64K program-code memory to the user

The Examine/Modify Memory Data is used to examine and modify the contents of the MetalICE or MicroICE emulator internal-data memory, the external-data memory and the MetalICE or MicroICE emulator table memory. It allows:

- Dumping a block of memory content
- Scanning and modifying each memory, a byte at a time
- Filling a memory block with data
- Moving a block of memory content from one location to another
- Searching each memory for a data pattern
- Verifying and comparing one block of memory data with another
- Examining and modifying the directly addressable bits, which are mapped to the internal-data memory space
- Selective mapping of the 64K external-data memory to the emulator system
- Selective mapping of the 64K external-data memory to the user system

Macro Capabilities

The Macro is used to create and execute macro command files. A macro command file contains groupings of MetalICE or MicroICE commands which, when executed together, perform a macro function. These macro functions are typically repetitious tasks that are performed over and over again in one or many debugging sessions. Using the macro-command facility, the designer can define the macro-command file *once* and then execute it anytime later in the same or even another debugging session.

Symbolic Debug

The MetalICE or MicroICE emulator supports user and pre-defined symbols. The use of a name and not an address can alter the content of bits, bytes and code. In

CHAPTER 11

Third-Party Support Products

addition, five different object-file formats are accepted: standard Intel hex-file format; Intel absolute-object-module format; Microtek Research absolute-output-object modules; IAR, Enertec, Archimedes object modules and MetaLink absolute-object-file format. Standard Intel hex-files can be created by assembling the user's program code with most of the currently available MCS-51 cross assemblers. Intel object-module files can be created by linking/locating modules with Intel's RL51 program. These source modules can be either assembled ASM51 object modules or compiled PLM object modules. MetaLink absolute object files are created by the MetaLink ASM51 Macro Cross Assembler.

System Requirements

Hardware Requirements

- IBM PC or a compatible PC
- Two 5-1/4 in. double-sided/double-density floppy disk drive
- 640K bytes of memory

- RS232C interface board
- RS232 cable with a male connector at the emulator end.
- Emulator power supply
 - 1.5 A + 5 VDC \pm 5% (MicroICE)
 - 1.0 A + 23 VDC \pm 5% (MetalICE)

Software Requirements

- PC DOS version 2.0 or later

High Level Language Support

The MetalICE or MicroICE emulator supports PLM and 'C' language compilers with advanced line number and multi-module capabilities. Line numbers, procedures and multi-module labels may be used for a number of emulator operations including: trace triggers, disassembly, fit, pass counts, etc. Using the MetalICE or MicroICE emulator, the user has the ability to single-step by machine instruction, procedure, line number in the current module, or line-number access all modules.

The Macro is used to create and execute macro commands. A macro command file contains a group of commands which, when executed, perform a macro function. These macro functions are typically repetitive tasks that are performed over and over again in one or many debugging sessions. Using the macro-command facility, the designer can define the macro-command file once and then execute it anytime later in the same or even another debugging session.

Symbolic Debug

The MetalICE or MicroICE emulator supports user and pre-defined symbols. The use of a name and not an address can allow the content of file, bytes and code in

The action represents the type of event that will occur after the condition has been encountered. The type of action can be specified by any of the following:

- A break
- An breakpoint
- A count
- A counter/timer trigger

In addition, an Examination/Modify Experiment Editor exists that can be used to examine and modify an experiment specification. In this editor, the user can:

- Edit an experiment
- Compile an experiment to set the breakpoints
- Load an experiment from a disk file
- Store an experiment in a disk file
- Reset the current experiment
- Delete the current experiment
- Call the Opcode Class experiment

Examination/Modify Memory

Using the MetalICE or MicroICE emulator, the user can examine and modify the live memory spaces of the 8051 family of devices. This examination/modification of memory spaces is broken down into two areas: Program-Code memory and Data memory.

Using the Examination/Modify Program Code Memory is used to examine and modify the contents of the MetalICE

AMERICAN AUTOMATION DEVELOPMENT SYSTEM

EZ-PRO 2.1 Development System

American Automation's EZ-PRO 2.1 Development System is a complete development environment for microprocessor-based systems. Supporting the 8031/8051 family of microcontrollers (and over 70 other microprocessor models), EZ-PRO's integrated tools help to implement and debug microcontroller designs. The system includes the following:

- Cross-assemblers with programmable macro expressions
- Relocating linkers with user-library support
- K&R standardized C-language cross-compilers
- Exceptional symbolic debuggers
- Fast in-circuit emulators
- EPROM programming utilities
- Flexible EPROM programming hardware
- File conversion utilities

American Automation's in-circuit emulators and associated symbolic debuggers form the heart of the EZ-PRO system. The emulators feature transparent, non-invasive emulation with no wait states. Integrated breakpointing and bus-tracing tools pinpoint problems while the interactive assembly/disassembly facility helps to examine and modify the code under test. Using a flexible memory-mapping scheme, software may be tested in any combination of target system and emulator memory; software may also be tested without any target system attached.

The powerful development hardware is backed by an equally powerful suite of software development tools: C-language cross-compilers, macro cross-assemblers, relocating linkers, and the symbolic debugging package. Each package contains several exceptional features.

The C cross-compilers feature rapid compilation and generate tight, fast code. Extensions to the basic C-compiler support the 8051's special features, and 8051-series users may select from one of four memory-saving models, designed to fit generated code into even the tightest of spaces. Assembly-language modules may be intermixed with C modules for even greater speed and compactness.

The EZ-PRO Macro Relocatable Cross-Assemblers feature not only a powerful "macro expression language", but also support a wide range of pseudo-operations. Each assembler conforms exactly to the manufacturer's standard mnemonics.

aaLINK, the EZ-PRO Relocating Linker, assembles output modules from several sources — including the EZ-PRO assemblers and C cross-compilers — into a final executable module. The final output file may be easily modified by changing a command file.

Finally, the tested software may be placed into an 8751-series microcontroller or 27XX-series EPROM using the integrated EPROM programming tools. This, the EZ-PRO system provides a complete development environment.

The emulators connect to a host computer through an RS-232C link. Their modular design permits upgrades both to support new microprocessors and to add new features and extended memory. The 8051-emulator features are listed below.

- A complete symbolic debugging facility
- Advanced breakpointing features
- Fast menu-driven system
- Operates at full clock speed with no wait states
- Fully transparent emulation — all resources available to target system
- 4K Deep Trace (tm) includes trace management
- Complex triggering features include ranging, pass counts, and sequential breakpoints
- Performance analysis tools
- Memory-conserving C cross-compiler
- Macro relocatable cross-assembler
- EPROM programmer supports 8751 series
- Supports NMOS, CMOS, and EPROM versions
- TeleService extended service and TelePresence remote diagnostics available
- Host systems include the IBM PC and IBM-PS/2 series, Sun 3 Workstations and Macintosh development software and systems
- 5-year warranty

American Automation backs each EZ-PRO system with superior customer support. This support includes a 5-year warranty, telephone support, software updates, and the TeleService extended service plan.

HUNTSVILLE MICROSYSTEMS DEVELOPMENT SYSTEM

Huntsville Microsystems has two low-cost in-circuit emulators that support the 8051 family of microcontrollers, the SBE-51 and the SBE-31. Both emulators support 16 MHz real-time emulation from either an internal (emulator) clock or an external (target system) clock or crystal. They also contain a real-time trace, five hardware breakpoints, an in-line assembler and a disassembler; either emulator can be run from a host computer or a dumb terminal. A Relocatable Macro-Cross Assembler and a Symbolic Debugger are available for the IBM PC family computers and compatibles. See Table 11-2 for available emulator packages.

The SBE-51 supports the internal or on-chip program memory versions of the microcontroller such as the 8051, 8751H, 8753H and 8053. It is a true on-chip program-memory emulation and does not require the use of any of the four I/O ports. Thus, the user has exclusive control of all four of these ports. The SBE-51 is a non-intrusive in-circuit emulator and does not use or restrict any of the microcontroller's functions. The unit contains 16K bytes of on-chip program memory (much larger than the 4K bytes of the 8051 or the 8K bytes of the 8053) providing the user with the capability to download much larger programs during the development cycle. The SBE-51 also supports the CMOS version including functions such as idle and power-down mode.

The SBE-31 supports the external or off-chip program memory version of the 8051 family microcontrollers, such as the 8031AH and 80C31BH. The unit contains 64K bytes of emulation memory that may be used for

external program or external data memory. The user's target-system memory may be added to the emulator's memory to complete the 128K byte address space (64K byte program memory, 64K byte data memory). The SBE-31 will also support CMOS designs and CMOS functions.

Features

- Real-time emulation up to 16 MHz with five hardware breakpoints and single step.
- 500 cycles of real-time trace history.
- 16K bytes of program memory (SBE-51)
- 64K bytes of memory, mappable in 2K blocks between program and data memory (SBE-31)
- RS232C interface can operate with a terminal or can be slaved to a host computer.
- Examine/modify memory, registers, flags, timer/counters, I/O ports, stacks and program counter.
- In-line assembler and disassembler.
- Uses internal oscillator or external oscillator or crystal.
- Upload or download Intel hexadecimal files.
- Complete software and hardware debugging facilities.
- Powerful command set includes fill-memory block, move-memory block, compare-memory blocks and test-memory blocks.
- Relocatable Macro-Cross Assembler and Symbolic Debugger for the IBM-PC, XT, AT and compatibles and all CP/M systems.
- Symbolic debugger for PL/M51 and assembly language.

Table 11-2. Emulator Packages

Microcontrollers Supported	Description of Emulator Package	Part
8051AH, 8751H, 8053, 80C51BH, 8753H	Complete development package for IBM PC family computers (includes all five items described below):	IDP-51
	1. 16 MHz Single Board Emulator for 8051 family on-chip internal program memory microcontrollers	SBE-51
	2. Relocatable macro Cross Assembler for IBM PC family computers	HMA-51R
	3. Symbolic Debugger Communications package for IBM PC family computer	SBE-LS51
	4. Power supply for Single-Board Emulator	SBE-PS1
	5. Computer-to-Emulator interface cable (RS232 - Specify if other than male/female cable)	SBE-IC6
8031AH, 80C31BH	Complete development package for IBM PC family computers (includes item 6 below and items 2-4 above)	IDP-31
	6. 16 MHz Single Board Emulator for 8031 off-chip external program memory microcontrollers.	SBE-31
ALL ABOVE	HMI-200 Series Advanced In-Circuit Emulator for the 8051/8031 family. "C" and PL/M51 source level debugger available.	HMI-200-8051

MICRO COMPUTER CONTROL 8051 C COMPILER

General Description

MICRO/C-51 is an MS-DOS based C-like language cross-compiler for the 8051 family of single-chip micro-controllers, including the 80C521 and 80515. It is designed to provide access to all hardware resources of memory maps, interrupts, all on-chip peripherals, and the Boolean processor directly from C.

MICRO/C-51 supports a number of important features that provide direct access to the 8051 architecture:

- Assignment of variables to any of the five 8051 memory maps.
- C-pointer support for all 8051 memory maps.
- Direct C-source access to all special-function registers by name.
- C-source-level handling of 16 hardware-interrupt sources.
- Fast-interrupt context switching to any one of four register banks.

Chip Features Supported

Object Memory Maps

- b-map – on-chip bit addressable (128 bits)
- d-map – on-chip direct access (128 bytes)
- i-map – on-chip indirect access (128/256 bytes)
- p-map – external page zero (256 bytes)
- e-map – external data (64K bytes)
- c-map – external code (64K bytes)

Special Function Registers

- Direct C access to all special-function registers by name.

Boolean Processor

- Direct C access to on-chip bit map and all bit-addressable special-function registers by name.

Interrupts

- Drive any C function directly from any interrupt source.
- Fast interrupt context switching to any one-of-four register banks.

Run-time Features Supported

- Math and memory-map exception handling.
- Expandable pointer access to external memory-mapped hardware devices.

Compile Time Options

- Default object-memory map selection
- Listing control options
- Debug support
 - Function trace
 - Stack monitor
 - Statement labels

Compiler Output

Assembly-language source file compatible with MICRO/ASM-51 relocatable macro assembler. Linkable with user generated assembly or PL/M-51 source files.

C Language Features Supported

MICRO/C-51 V1.0 is a subset implementation of the C language as documented in "The C Programming Language" by Kernighan and Ritchie. Processor specific extensions have been added to support micro-controller hardware resources.

Comments (*/*...*/*)

Identifier names (8 characters)

Constants

- Integer (decimal, octal, hex)
- Character ('x')
- Escape (*\a,\b,\f,\n,\r,\t,\v,\w,\x,\"\'\"'*)

String ("string")

Declared-object types

- bit – 1-bit unsigned (K&R Extension)
- char – 8-bit signed
- int – 16-bit signed
- ptr – 24-bit unsigned pointer to char or integer
- array – single dimensioned char or integer array

func () – function return value

Options:

- Interrupt driven
- Using specified register bank

Storage Classes

- extern – reference to externally declared object
- global – objects defined outside a function
- local – objects defined within a compound statement
- static – restrict global object scope.

Statements

compound	case
if, if-else	default
while	break
do-while	continue
for	return
switch	null

expression

Operators

Unary (*, &, -, !, ~, ++, --)

Multiplicative (*, /, %)

Additive (+, -)

Shift (<<, >>)

Relational (<, >, <=, >=)

Equality (=, !=)

Bitwise (&, ^, |)

Logical (&&, ||)

Conditional (?:)

Assignment (=)

Comma (,)

Preprocessors

Conditions! (#if-#endif up to 16 nested levels)

Include Files (#include up to 8 nested levels)

Macro Definition (#define text replacement)

Separate Compilation and Linkage

Library Functions

getchar, putchar, printf, etc.

Special run-time debug functions supporting debug operation via the on-chip serial port.

Compiler Operation

Input/Output

MICRO/C-51 accepts, as input, a C source file created with a standard text editor. This file must have the extension (.c). Assembly-language source output is sent to "filename.src". Listing and error messages are sent to the MSDOS standard output file, normally the console. Full path name is provided for both source and include files.

Command Line

MICRO/C-51 has a built-in command-line processor that permits various options (switches) to control the compilation process. The format of the command line is as follows.

mcc51 filename.c [/switch...]

Optional switches

- c – include C source in assembly source output file
- dc – set default memory map (c = b,d,i,p,e)
- f – enable function trace
- ln – C source listing control (n = 1,2)
- m – enable stack monitor
- p – define processor descriptor file
- wn – set warning report level (n = 0,1,2)
- t – generate statement labels

Sample command line: mcc51 test.c /de/l1/wn0

Sample Program

The following MICRO/C-51 program initializes the 8051 serial-port and baud-rate-control registers and repeatedly calls on the C-library function "printf" to write the specified text string to the serial port.

```
main()
{
    /* setup serial port (1200 BAUD @ 6 MHz) */
    scon = 0x52; /* set serial port control register */
    tmod = 0x20; /* set timer mode register */
    tcon = 0x69; /* set timer control register */
    th1 = 0xf3; /* set timer count */

    while (1) /* loop forever */
        printf("hello, world\n"); /* write to serial port */
}
```

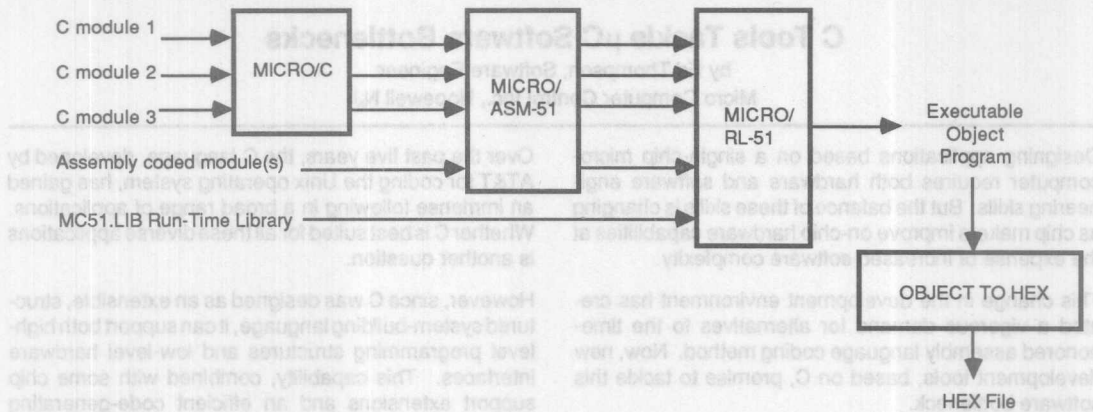


Figure 11-3. Modular Programming Model

Modular Programs

MICRO/C-51 works with C-source modules (files) that contain either a complete program or part of a program. Individual program modules can be compiled or assembled separately to create relocatable object files. The Run-Time Library consists of a series of object modules organized into a library module. Once all the object modules are available, the linker/locator combines the object modules into a single executable program.

Assembler Relocation & Linkage Package

Assembler

- Gives symbolic access to powerful 8051 hardware features.
- Provides software support for many addressing and data allocation capabilities.
- Provides symbol table, cross-reference table, macro capabilities, and conditional assembly.
- Produces object files that can be linked together and located at absolute addresses.

Relocation & Linkage Package

- Links modules generated by the assembler and PL/M51.
- Locates linked object modules at absolute addresses.
- Creates libraries of object modules and has facilities for adding and deleting modules.

- Permits modules to be selectively linked from libraries.
- Converts 8051 objects into symbolic hexadecimal format to facilitate file-loading by symbolic hexadecimal loaders (such as non-Intel PROM programmers).

The Assembler Relocation & Linkage Package is a complete package for writing assembly-language programs to run on the powerful 8051 Family of microcontrollers. It includes the assembler, plus a relocation and linkage package that also contains a librarian, and an object-to-hex converter.

The assembler is a powerful assembly language that provides complete control over any microcontroller in the 8051 Family, enabling production of the most efficient code possible. With the assembler, the user can refer symbolically to many of the useful addressing features of the 8051. For example, symbolic references can be used for bit and byte locations, for 4-bit BCD arithmetic operations, for hardware registers, for I/O ports, for control bits, and for RAM addresses.

In addition, the assembler user can break up code into separately assembled modules, provide conditional-assembly capabilities, and support macros to automate frequently used code sequences.

The relocation and linkage package is used to prepare the program for running. The linker and relocater provides the facilities for combining program modules and assigning absolute addresses. The librarian gathers modules into a library where they can be accessed individually by the linker. The hex converter converts 8051 object modules into hexadecimal form in preparation for loading into ROM.

C Tools Tackle μ C Software Bottlenecks

by Ed Thompson, Software Engineer
Micro Computer Control Inc., Hopewell NJ

Designing applications based on a single-chip microcomputer requires both hardware and software engineering skills. But the balance of these skills is changing as chip makers improve on-chip hardware capabilities at the expense of increased software complexity.

This change in the development environment has created a vigorous demand for alternatives to the time-honored assembly language coding method. Now, new development tools, based on C, promise to tackle this software bottleneck.

To the delight of many a hardware engineer, a wide variety of complex semiconductor devices is finding a welcome home on single-chip microcomputers. These include A/D converters, DMA controllers, intelligent communication receiver/transmitters, pulse-width modulators and event capture circuitry. This steadily growing engineers' wish list of on-chip resources is pushing single-chip microcomputer application in products that only a year ago would have required a boardful of chips.

Accelerating Demands

With this increased integration, however, comes a need for complex interfacing and control programming. Demands on software to control memory, interrupts and sophisticated peripheral devices are outpacing past design methods and leading to the adoption of programming methods once found solely in the realm of microprocessor-based designs.

A key area that is receiving a great deal of interest is the use of high-level languages for single-chip microcomputer program development. Although most of today's microprocessor-based projects use a high-level language as the primary coding language, this consideration has only recently been adopted on single-chip projects.

In the past, the limited size and complexity of the function to be coded and the lack of efficient high-level language compilers have restricted their consideration. But today the high cost of both software development and maintenance and the availability of efficient PC-based high-level language cross-compilers are quickly changing the way single-chip microcomputer programs are being developed.

Over the past five years, the C language, developed by AT&T for coding the Unix operating system, has gained an immense following in a broad range of applications. Whether C is best suited for all these diverse applications is another question.

However, since C was designed as an extensible, structured system-building language, it can support both high-level programming structures and low-level hardware interfaces. This capability, combined with some chip support extensions and an efficient code-generating implementation, make C worthy of consideration in single-chip microcomputer applications. One such implementation is Micro Computer Control's Micro/C-51 C compiler for the 8051 family of single-chip computers.

C comes with a long list of high-level statements and operators used to create structured programs that are quick to develop and easy to understand and maintain. But since C was not designed to cope with the special problems presented by single-chip microcomputers, a few well-chosen extensions are needed to make C a natural for this type of application. Three such extensions, implemented in Micro/C-51, are direct C support for memory maps, interrupts and access to on-chip peripherals.

The architecture of most single-chip microcomputers uses several memory maps. The 8051, being no exception, has no less than three on-chip and three off-chip memory maps. Memory size and access speed differ for each map. A problem arises in controlling the placement of variables in these various memory maps. One way to cope with this problem is to permit each declared C variable to be assigned to any map, thus providing easy adaptation to various target system memory configurations.

In addition to memory maps, interrupts also play an important role in most single-chip microcomputer applications. These interrupts are generated by internal or external peripheral devices, and indicate need for servicing by the processor. In some cases, up to a dozen or more interrupt sources must be serviced quickly. Support for interrupts could take the form of enabling a developer to assign any C function as the target of any interrupt source.

Access to peripheral devices presents a problem in any high-level language. Because single-chip microcomputers are used primarily in control applications, they especially demand a convenient and efficient access method to the increasing variety of on-chip peripherals. Here, a solution is to be able simply to use the name of a peripheral in a C expression to directly access the specified device. With such a simple yet powerful technique, even low-level device drivers become candidates for coding in C.

Software Debugging

With their integrated form of processor, memory and peripherals, single-chip microcomputers typically present a challenge to debugging efforts. Programming in a high-level language not only can reduce the entry of bugs in a program, but also can help in tracking them down.

The introduction of programming errors is reduced in several ways. Most reasonably, the fewer lines of high-level code needed to program a function simply reduces the chance of typographical errors that could go unnoticed. The procedural programming structure offered by C also helps in organizing the programming effort.

Nevertheless, the likelihood of creating a bug-free program is low. To help find the bugs, C debugging options can open the on-chip resources to inspection.

Single-chip microcomputers have proven to be an important product, and undoubtedly a host of new capabilities and architectures will soon emerge. As with microprocessors in the past, programming in a high-level language will help protect a company's investment in software when the time comes to exploit these new chips.

All memory models offer two approaches on how to allocate variables - resident or static. In the resident model, all local "auto variables" are allocated and deallocated dynamically, i.e. they reside on a stack required to support recursive or reentrant functions. In the static model, all function-level variables are forced into static memory with the exception of function arguments which are always on the stack.

The Archimedes Microcontroller C-5051 is available on most popular software development hosts: IBM PC and compatibles, MicroVAX and VAX systems running either VMS or UNIX (Lih or Berkeley). All versions are fully compatible, e.g. compile module 1 on a PC, module 2 on a MicroVAX/VMS system and link them on a VAX/VMS system.

Several Memory Models

The Archimedes Microcontroller C-5051 kit has several memory models to best meet the requirements of different microcontroller designs, similar to 8051 small and large

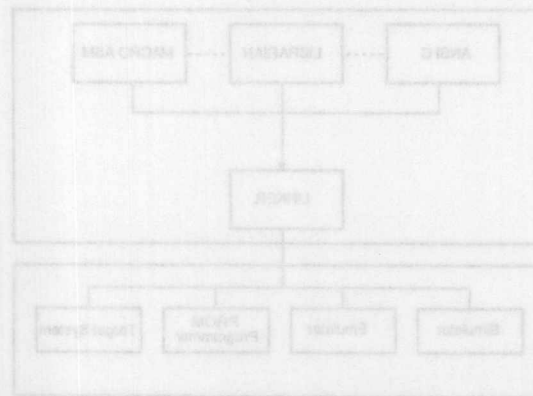


Figure 11-4. CXC

ARCHIMEDES C-8051 COMPILER

The Archimedes Microcontroller C-8051 Cross Compiler Kit supports software development for any chip based on the 8-bit 8051 microcontroller instruction set, e.g. 8051, 80C521, 80515 and other proliferation chips.

The C-8051 Kit consists of several pieces. The ANSI-standard C-compiler gives all the traditional high-level language advantages – faster coding, debugging and code maintenance resulting in more reliable code. The macroassembler is useful in optimizing any time-critical sections of code. It also preserves assembly code investment by reassembling existing source code with the Archimedes assembler (which is linkable with C code). The assembler is highly compatible with other 8051 assemblers. A librarian creates and maintains libraries. The linker combines C and assembly modules and places code and data at the right locations. The linker's numerous output formats make it quick and easy to support standard PROM programmers and emulators. (See Figure 11-4.)

Archimedes Microcontroller C-8051 is available on most popular software development hosts: IBM PC and compatibles, MicroVAX and VAX systems running either VMS or UNIX (Ultrix or Berkeley). All versions are fully compatible, e.g. compile module 1 on a PC, module 2 on a MicroVAX/Ultrix system and link them on a VAX/VMS system.

Several Memory Models

The Archimedes Microcontroller C-8051 Kit has several memory models to best meet the requirements of different microcontroller designs, similar to 8086 small and large

models. Memory models range from a small model using only the internal RAM (128/256 bytes) of an 8051 Family chip to a bankswitching model supporting up to 8 Mbytes of code. The different C-51 memory models are:

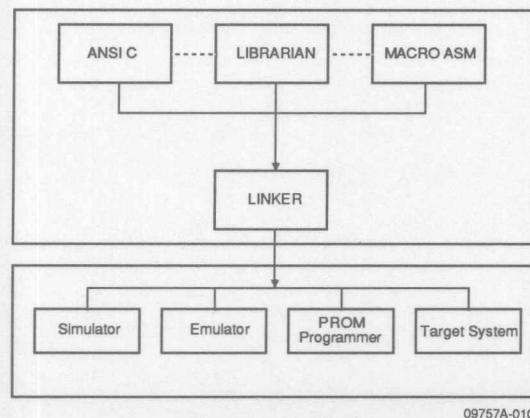
Small (single-chip) memory model: Supports 8051 configurations using internal RAM only. C variables and the run-time stack reside within internal RAM (128 or 256 bytes).

Medium (expanded) memory model: Supports microcontroller applications with a combined total of 64K code and data. Requires that the Program Status Enable signal (PSEN) is AND-ed together with the Read Data signal (\overline{RD}), to create a uniform 64K address space. C variables and the run-time stack reside in external data memory.

Large (expanded) memory model: Supports microcontroller applications with 64K of code and 64K of data. C variables and the run-time stack reside in external data memory.

Banked memory model: Supports microcontroller applications with 64K of data and up to 8 Mbytes of code. C variables and the run-time stack reside in external data memory.

All memory models offers two approaches on how to allocate variables - reentrant or static. In the reentrant modes, all local "auto variables" are allocated and deallocated dynamically, i.e. they reside on a stack required to support recursive or reentrant functions. In the static modes, all function-level variables are forced into static memory with the exception of function arguments which are always on the stack.



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Figure 11-4. C Kit

Table 11-3. Overview of Memory Models

Memory Model	Banked Reentrant	Banked Static	Expanded Reentrant	Expanded Static	Small Reentrant	Small Static
Typical chip	8031	8031	8031	8031	8051	8051
External RAM	Yes	Yes	Yes	Yes	No	No
Code Area	>1M	>1M	64K	64K	64K	64K
Recursion	Yes	No	Yes	No	Yes	No
C Interrupt Routines	Yes	Limited	Yes	Limited	Yes	Limited
C Variable Area	Ext. RAM (64K)	Ext. RAM (64K)	Ext. RAM (64K)	Ext. RAM (64K)	Int. RAM (256)	Int. RAM (256)
Relative Speed	Low	Low	Low	Medium	Medium	High
Relative Code Compactness	Medium	Medium	Medium	Medium	Medium	High

PROMable Code

PROMable code is a must for microcontroller applications. Archimedes supports PROMable code fully, including statically initialized data and static data without explicit initializers set to zero. The compiler has a simple invocation at compile time (-P) to automatically generate PROMable code.

C-Libraries

CHARACTER HANDLING <ctype.h>

isalnum, isalpha, iscntrl, isdigit, islower, isprint, ispunct, isspace, isupper, tolower, toupper

NON-LOGICAL JUMPS <setjmp.h>

longjmp, setjmp

FORMATTED INPUT/OUTPUT <stdio.h>

getchar, printf, putchar, sprintf, _formatted_write

GENERAL UTILITIES <stdlib.h>

exit, calloc, free, malloc, realloc

STRING HANDLING <string.h>

strcat, strcmp, strcpy, strlen, strncat, strncmp, strncpy

MATHEMATICS <math.h>

atan, atan2, cos, exp, log, log10, pow, sin, sqrt, tan

Archimedes C-8051 Compiler provides the most important C-library functions for stand alone "embedded microcontroller applications". 'printf' can be used to make debugging easier or as the starting point for writing applications-specific display device drivers. Advanced math routines speed up number-intensive applications.

In addition, the C system contains C run-time libraries that are divided into 100+ small modules. By design, only those routines required by a particular program are called in at link-time to minimize run-time requirements (minimum 500 bytes; 2-3 kbytes for a typical application). All library routines are reentrant.

Fast Compilation

Single pass compilation, without any unnecessary assembly step, compiles 7000 lines of C source code in less than 30 seconds on a Compaq 386 system.

Fast Testing

ANSI-standard C makes it possible to compile 'generic' C source code with different ANSI-standard C-compilers. Host-resident tools like Microsoft's C-86 compiler and CodeView debugger speed up testing of generic C-8051 code. (See Figure 11-5.)

ANSI-Standard Power and Features

ANSI-standard C has some extra features over and above the traditional K&R C language definition. Function prototyping allows function declarations a la Pascal with the conversion conventions of C. This speeds up software development and produces more efficient code, by avoiding some of the default conversions to 'int' that is typically required in older C compilers. 'Structure' and 'union' assign and 'enum' types give the same facilities enjoyed by Pascal users. Flexible 'auto' initialized aggregates like arrays, structures and unions provide one more option to keep vital data local to a function rather than making everything global.

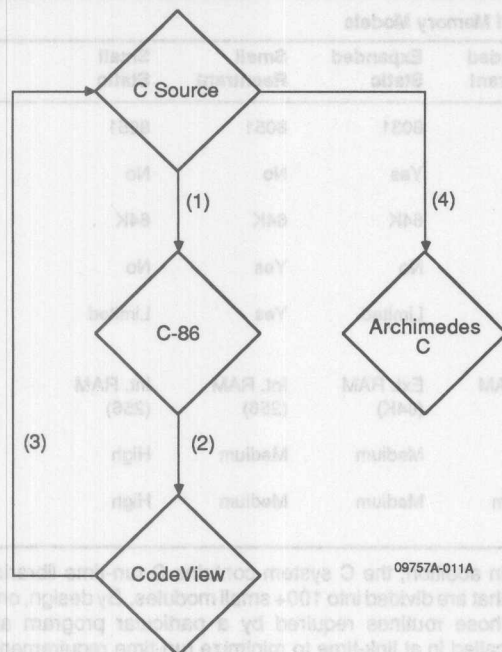


Figure 11-5. Testing using Host Tools like Microsoft C-86

All the Standard ANSI Data Types

Archimedes C-8051 compiler supports all the basic ANSI C elements. Object sizes in bytes:

char	short	int	long	float	pointer/addr
1	1/2	2	4	4	2

"Float" is implemented in the IEEE 32-bit single-precision format.

LINT-type Feature

The software has a built-in advanced type-checking scheme to eliminate difficult to find 'typing errors' and to speed up integrating different modules. The C compiler checks a module, whereas the linker checks consistency of inter-module declarations (down to the last bit of a complex structure). This facilitates interfacing of libraries, or other routines only available in object format, as well as integrating modules written by different programmers.

Error Message System

To speed up error searching the C compiler has a state-of-the-art built-in error message system (invoked by the -V switch). The system indicates the exact source code location and a message describes the error detected:

```

if(i) j++
    ^
"main.c", 870 Error (110): ')' unexpected
  
```

C Language Extensions and Other Specials

The Archimedes C-8051 kit has special C language extensions, or built-in in-line functions, to better take advantage of a chip's special features and speed up development. "input" and "output" provide access to internal RAM/special function registers. Functions like "set bit" and "clear bit" are available to support bit manipulation. Also, functions are available to read blocks of code and data.

The C compiler has several special listing options. It can for instance generate a pure assembly source file (-A option), which can be hand-optimized and then reassembled with the macroassembler. A list file with mixed C source and native assembly code speeds up debugging. The C compiler supports symbols with up to 255 significant characters.

Linker

The linker combines C and assembly modules and automatically links in the necessary C run-time libraries (including the C start-up routine). The flexible linker locates memory segments at absolute or relocatable addresses. The linker's many output options provide fast and easy interfacing with most PROM-programmers and emulators. The Archimedes kit generates symbolic debug information for global and local static variables as well as line numbers. The linker also generates load maps and module/symbol cross-reference listings to make debugging faster.

C - the Right Choice for the Right Project

Why spend months of extra development time to save some money on memory chips? Constantly lower memory prices have reduced the need to save on every byte of memory. Typically, only in high-volume applications, do the cost savings in memory chips from assembly programming justify the extra costs in development time. (See Figure 11-6.)

In low and medium volume applications, C is the right choice. Development time and costs are cut by at least 50% and the product goes out the door faster—all for minimal extra memory costs per system.

C is also the right choice for projects on a tight time schedule and for any products requiring complex software development. Assembly programming might be best if most code is very time-critical.

Archimedes Microcontroller C-8051 Kit comes with both a C compiler and a macroassembler to provide optimal flexibility. C speeds up software development and the macro assembler can be used to optimize time-critical sections of code, where necessary.

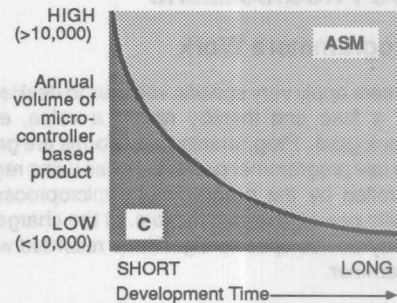


Figure 11-6. C - Right Tool for the Right Project

All data transfer or verification operations take place between the programmer's internal RAM and the device or between the RAM and serial port or floppy drive in the programmer. Because the operation procedure is user-programmer, we will describe data transfer with the most popular data via a serial port rather than programmer to programmer. All of these functions can occur from the programmer front panel or from a remote terminal.

Physical Programmer Operation Steps

- * Load RAM with data from a master device.
- * Press COPY and the programmer will prompt COPY DATA FROM.
- * Select DEVICE and the programmer prompts DEV * ADDRESS TO.
- * Select RAM and the programmer prompts CO DEV-RAM * ADDR.
- * Press START and the programmer will load through the device selection process to identify master device type.
- * Place the master device in the main programmer socket and press START to load data into RAM. From RAM it can be programmed into a device different from the master or stored on floppy disk.
- * Verify RAM against the master device.
- * Program a new device with RAM data.

Data editing is possible while data is in RAM. The programmer allows simple editing on the internal LED command line screen or on a remote terminal or PC. Using PROMlink for full screen editing on a PC allows editing in ASCII or Hex and automatic conversion from one to the other.

Programmer ranges in price from under \$500 to over \$12,000. Along with basic capability, part of the price differential is the result of more established programmer manufacturers establishing a system of seeking semiconductor manufacturers' approvals for device support. Data I/O works closely with the device makers to support a new device before silicon is available. When samples are available the device maker approves device support.

Programmer Controls

Data I/O programmer can obtain data from three sources: a master device, a serial port/disk drive, or from the keyboard. Master devices are first copied into the programmer RAM where the code can be edited at the bit level or copied onto other media. Code can be edited using the integral keyboard or by loading it into a PC and editing it onscreen. On most Data I/O programmers, a standard terminal will also enable the code to be edited on screen.

PROMlink is Data I/O's optional PC-based control software for all of Data I/O's programmers. It enables the user to control any programmer from a single menu system, saving data and configuration files on hard or floppy disk. It allows single bit-editing functions in ASCII or Hex and will convert from one to the other. It also has a simple device labeling function using a standard PC printer.

How Programmers Work

Programmers apply very specific voltages to device pins to "blow" a fuse and thereby record a value, either memory or logical. Programming waveforms are generated from raw programmer power supplies using regulators controlled by the programmer's microprocessor. The specific power, rise and fall, etc. of the charge are specified by device-specific algorithms recorded within the programmer.

Values for programming variables, including pinouts, voltage levels and timing, are stored in firmware or floppy tables. When a particular device is chosen, the programmer uses information stored in these tables to assemble a device-specific programming routine in scratch RAM. Device pinout variations are handled by different device sockets, cartridges or modules on the programmer or pak. Newer programmers such as Data I/O's UniSite can program any device up to 40 pins on one socket. To maximize control speed during programming, the programmer and pak make extensive use of addressable latches for control signals.

Programmers range in price from under \$500 to over \$15,000. Along with basic capability, part of the price differential is the result of more established programmer manufacturers establishing a system of seeking semiconductor manufacturers' approvals for device support. Data I/O works closely with the device makers to support a new device before silicon is available. When samples are available the device maker approves device support.

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identification on most workstation networks, such as PC, UNIX or VAX. This allows centralized device data storage for both engineering and testing groups and facilitates data transfer. An engineer can develop a design at a PC or workstation node and download to a remote programmer.

Device files are generally kept on disk or on master devices. Programmers require updates to be able to program the most current devices and these updates are also provided on firmware, i.e. programmed devices, or floppy disks. Data I/O offers annual update services which automatically keep a programmer at the most current revision.

All data transfer or verification operations take place between the programmer's internal RAM and the device or between the RAM and serial port or floppy drive in the programmer. Because the operation procedure to transfer data via a serial port varies from programmer to programmer, we will describe data transfer with the most widely used system. All of these functions can occur from the programmer front panel or from a remote terminal.

Typical Programmer Operation Steps

- Load RAM with data from a master device.
- Press COPY and the programmer will prompt COPY DATA FROM.
- Select DEVICE and the programmer prompts DEV ^ADDR/SIZE TO.
- Select RAM and the programmer prompts CO DEV>RAM ^ ADDR.
- Press START and the programmer will lead through the device selection process to identify master device type.
- Place the master device in the main programmer socket and press START to load data into RAM. From RAM it can be programmed into a device different from the master or stored on floppy disk.
- Verify RAM against the master device.
- Program a new device with RAM data.

Data editing is possible while data is in RAM. The programmer allows simple bit editing on the internal LED command line screen or on a remote terminal or PC. Using PROMlink for full screen editing on a PC allows editing/input in ASCII or Hex and automatic conversion from one to the other.

Set programming allows the downloading of an entire data file into RAM (up to a maximum of 512K bytes on most programmers with 1 Mbyte coming soon) in one operation. The data is automatically split according to word width into as many devices as required, which are then programmed sequentially.

Programmer Types and Technology

An "Engineering" programmer is generally a stand-alone one-device-at-a-time programmer. Models are available that do memory only, logic only or memory and logic.

Inexpensive memory-only programmers are often appropriate for the first-time user. They are usually in the \$1,000 range for a name brand and generally support MOS/CMOS EPROMs and EEPROMs up to 512K bits. The better ones support 8-, 16- and 32-bit-wide words and may be run from the front panel keyboard or by an optional PC interface.

Universal logic and memory programmers are the "workhorse" engineering programmers. Most engineers prefer them for their flexibility and adaptability to future device needs. They generally consist of a mainframe unit containing the power supply, primary microprocessor, memory, keypad and control functions. Modules or paks are then added to characterize the mainframe for memory, multiple memory or logic (see page 11-26). The most popular units translate data from 29 or more popular formats and have up to 1 Mbyte of internal RAM.

Functional Specifications for the Data I/O 29B System:

- General Architecture: Microprocessor controlled
- Data RAM: 256 x 8 standard, upgrades available to 1 Mbyte
- Programming Support: GangPak, LogicPak, UniPak 2B, MOSPak, and programming modules
- Keyboard: 16-key hexadecimal and 9-key functional
- Functional keys:

Copy: Used to move a block of data to or from a serial port, RAM, or device. Works in conjunction with source/destination keys.

Verify: Used to make a byte-by-byte comparison of a block of data. Used with source/destination keys.

Select: Prepares the programmer to accept codes for select functions.

Edit: Allows viewing and changing of data at individually selected RAM address locations

- Display: 16-character alphanumeric
- Input/Output: Serial RS-232C and 20mA current loop
- Baud Rates: 50, 75, 110, 134.5, 150, 300, 600, 1200, 1800, 2000, 2400, 3600, 4800, 7200, 9600
- Remote Control: PROMlink (MS-DOS) optional
Computer Remote Control (CRC)
Terminal Remote Control (SRC)
- Translation Formats: 29 available
- Handler Capability: Optional handler port is available for binning and control signals

Pin-driver technology programmers are the newest programming technology. They use a dedicated voltage driver for each pin, enabling each programming socket pin to be configured by software to execute device-specific information including voltage, current, logic level, ground and Vcc outputs.

Gang programmers or gang programming paks have a master socket and usually seven slave sockets. They are useful in the engineering environment or limited production runs, to run small batches of identical parts or to do set programming. In the set-programming mode, most gang programmers allow several sets to be programmed at once.

Production programmers are high-throughput programming and test fixtures intended for the production floor. For devices that program rapidly, the most common method is serial programming, whereby a single-socket programmer is connected to an automatic device handler that runs chips individually by a programming/test head. Most memory devices program most efficiently on a parallel programmer whereby 10 or 20 devices are loaded into individual programming/test sockets and are programmed at once. More recently designed models such as Data I/O's Series 1000 have "rails" whereby the device sockets are aligned end to end and entire tubes can be smoothly loaded, programmed and unloaded. Sophisticated production programmers such as Data I/O's Series 1000 can also serialize devices in specified areas of device memory, label devices and provide simple code-editing capability.

The programming pass also includes tests for continuity, incorrectly inserted devices and a data comparison with RAM. On programmers like the Series 1000, full programming pass/fail statistical data is accumulated by time of day, socket and device. Calibration is automatic and production statistics can be stored on disk.

CHAPTER 11

Third Party Support Products

In-circuit programming entails programming a device or devices already mounted on a board. The programmable devices are soldered in place and programmed through a specially designed edge-connector. Boards must be designed from the beginning to accommodate the technology and to protect microprocessors from higher voltages. For certain types of applications the additional effort can be worth it. Typical reasons for adopting an in-circuit design include the elimination of additional device handling and increased board reliability. Specific reasons for avoiding individual device programming include the following:

- High device count per board statistically increases the chance of physically damaged devices during handling.

- Frequently updated code, requiring excess removal, downtime or additional boards to control the board float.
- Surface-mount devices particularly defy modifications if they are not in-circuit programmable.
- Soldered-in designs, especially military design specs which often require soldered-in devices, are difficult or impossible to remove.

Data I/O supports the full line of programmable products from AMD including the 8751H and 8753H microcontrollers. Programming support will soon be added for the 87C51, 87C521 and 87C541.

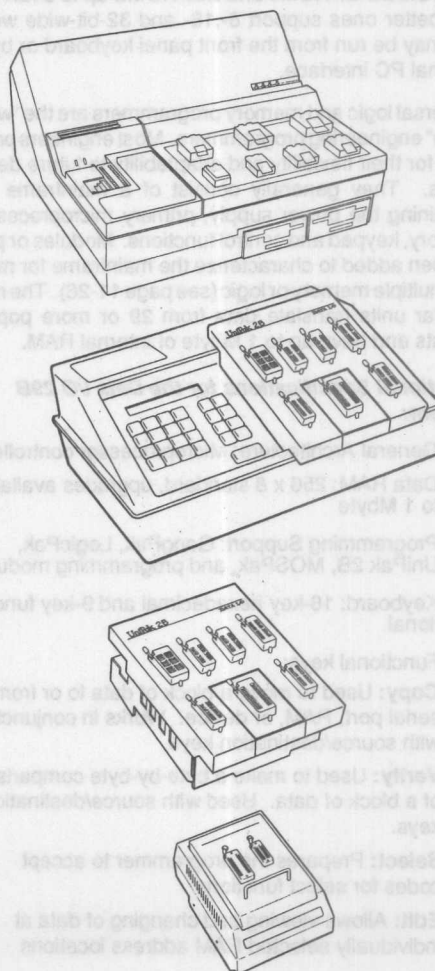
Programmer Systems Overviews

Unisite 40 supports every microcontroller, PROM, EPROM, EEPROM, PLD, IFL and FPLA that fits in its 40-pin DIP socket. The optional ChipSite module adds a single site for PLCCs, LCCs and SOICs. Unisite 40 uses universal pin drivers to drive each pin to any state needed to program and test a programmable device. The system provides 128K bytes of RAM and two disk drives as standard; 1 Mbyte of internal memory is available on order. Updates are provided on 3 1/2" floppy disks.

The 29B System provides a universal system for programming, testing and verifying a variety of memory and logic devices. The 29B can be tailored to specific programming needs by selecting the appropriate programming pak, shown below, and simply plugging it into the 29B.

Programming Paks

- **Unipak 2B** programs more than 1200 devices, including MOS and CMOS EPROMs and EEPROMs, fuse link, AIM and DEAP bipolar PROMs. Simple pinout cartridges are available for 40-pin microcomputers and parts with non-standard pinouts and unique package types (LCC, PLCC).
- **LogicPak** combined with appropriate plug-in adapters, allows you to design, program and functionally test more than 440 different logic devices.



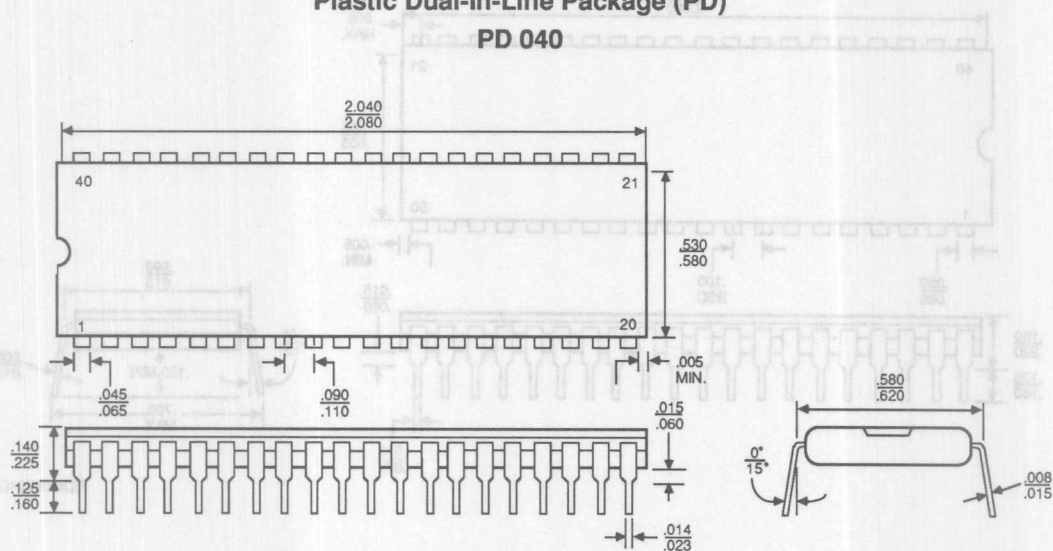
CHAPTER 12

Package Outlines	12-1
Plastic Dual-in-Line Package	12-1
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Ceramic Leadless Chip Carriers	12-5

PHYSICAL DIMENSIONS*

Plastic Dual-In-Line Package (PD)

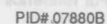
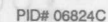
PD 040



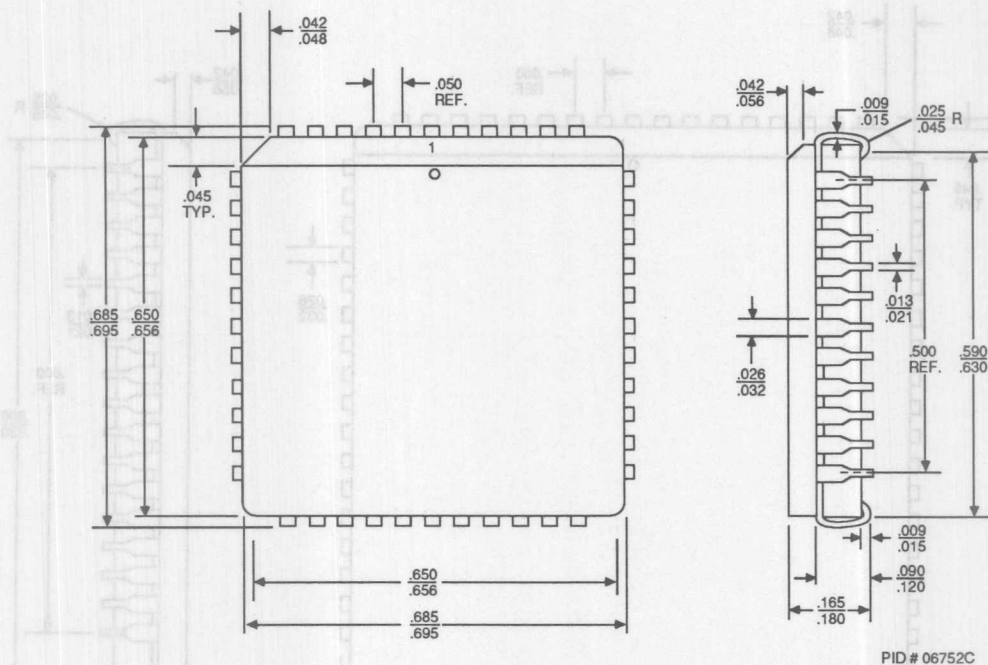
PID# 06823B

* For reference only.

NOTE: Package dimensions are given in inches. To convert to millimeters, multiply by 25.4.

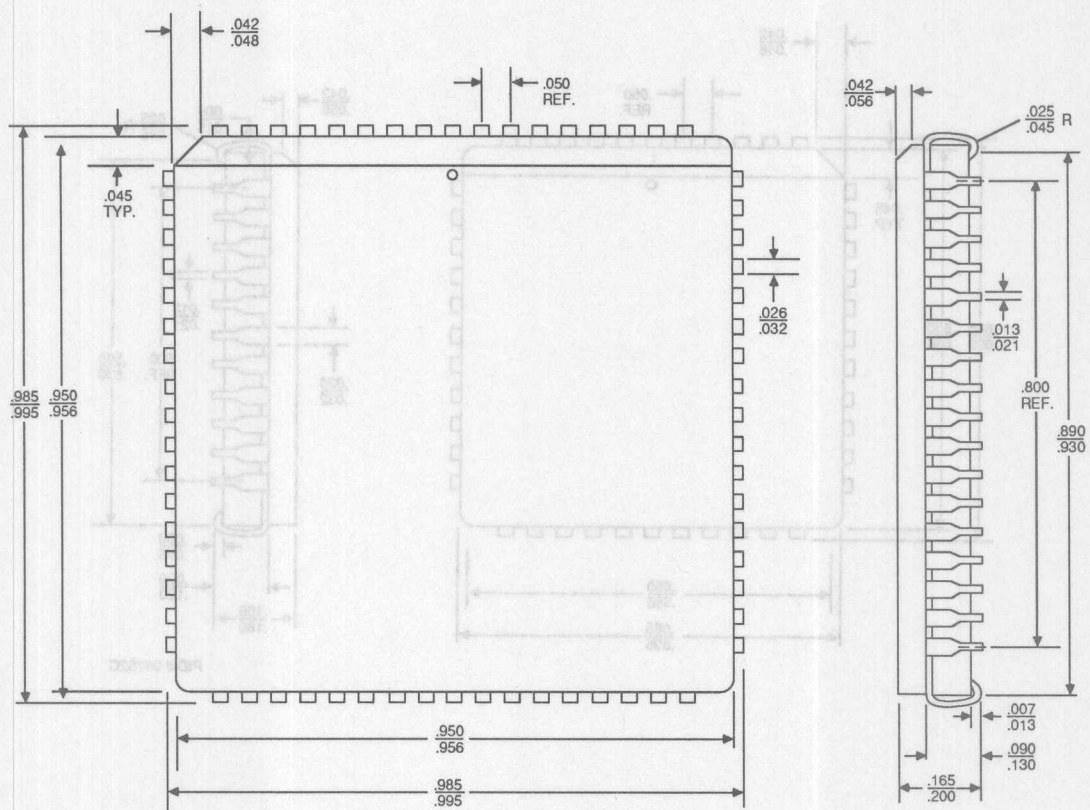
CDV 040

Plastic Leaded Chip Carrier (PL)
PL 044



NOTE: Package dimensions are given in inches. To convert to millimeters, multiply by 25.4.

Plastic Leaded Chip Carrier (PL) (Continued)

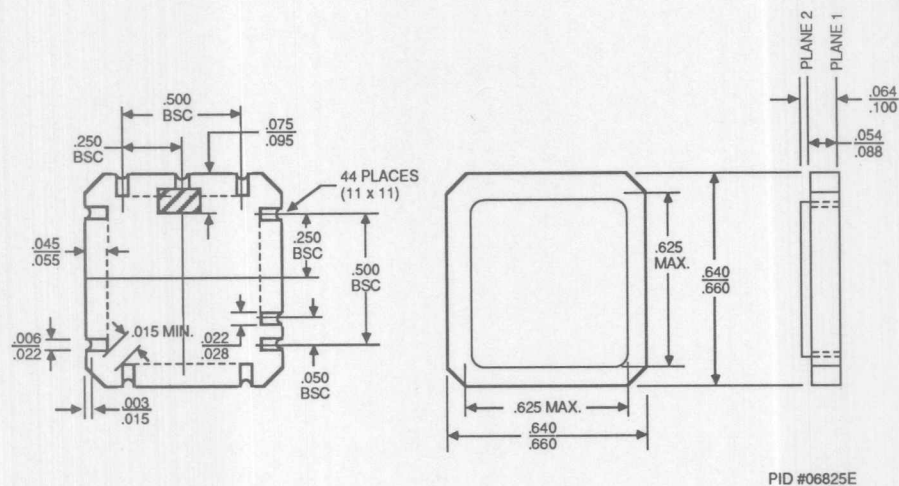
PL 068

PID # 067531

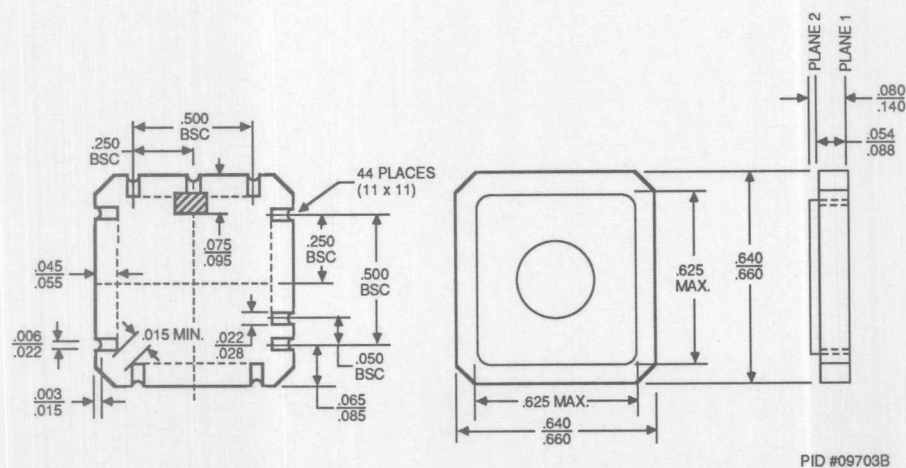
NOTE: Package dimensions are given in inches. To convert to millimeters, multiply by 25.4.

Ceramic Leadless Chip Carriers (CL/CLV)

CL 044

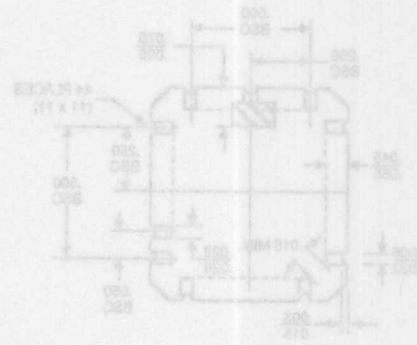
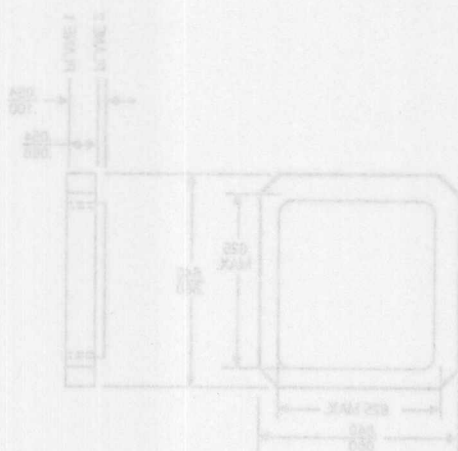


CLV 044



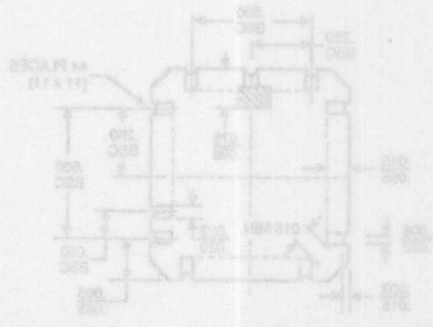
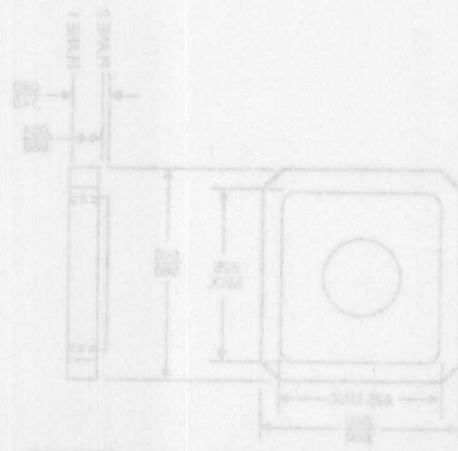
NOTE: Package dimensions are given in inches. To convert to millimeters, multiply by 25.4.

CL 044
Ceramic Leadless Carriers (CLCLV)
NOTES



CL 044

CLV 044



CLV 044

NOTE: Package dimensions are given in inches. To convert to millimeters, multiply by 25.4.